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RENESAS

User's Manual

78K0S/KY1+

8-bit Single-Chip Microcontrollers

μPD78F9210 μPD78F9211 μPD78F9212
μPD78F9210(A) μPD78F9211(A) μPD78F9212(A)
μPD78F9210(A2) μPD78F9211(A2) μPD78F9212(A2)
μPD78F9510 μPD78F9511 μPD78F9512

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[MEMO]

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NOTES FOR CMOS DEVICES

(1) VOLTAGE APPLICATION WAVEFORM AT INPUT PIN: Waveform distortion due to input noise or a reflected wave may cause malfunction. If the input of the CMOS device stays in the area between VIL (MAX) and VIH (MIN) due to noise, etc., the device may malfunction. Take care to prevent chattering noise from entering the device when the input level is fixed, and also in the transition period when the input level passes through the area between VIL (MAX) and VIH (MIN).

(2) HANDLING OF UNUSED INPUT PINS: Unconnected CMOS device inputs can be cause of malfunction. If an input pin is unconnected, it is possible that an internal input level may be generated due to noise, etc., causing malfunction. CMOS devices behave differently than Bipolar or NMOS devices. Input levels of CMOS devices must be fixed high or low by using pull-up or pull-down circuitry. Each unused pin should be connected to VDD or GND via a resistor if there is a possibility that it will be an output pin. All handling related to unused pins must be judged separately for each device and according to related specifications governing the device.

(3) PRECAUTION AGAINST ESD: A strong electric field, when exposed to a MOS device, can cause destruction of the gate oxide and ultimately degrade the device operation. Steps must be taken to stop generation of static electricity as much as possible, and quickly dissipate it when it has occurred. Environmental control must be adequate. When it is dry, a humidifier should be used. It is recommended to avoid using insulators that easily build up static electricity. Semiconductor devices must be stored and transported in an anti-static container, static shielding bag or conductive material. All test and measurement tools including work benches and floors should be grounded. The operator should be grounded using a wrist strap. Semiconductor devices must not be touched with bare hands. Similar precautions need to be taken for PW boards with mounted semiconductor devices.

(4) STATUS BEFORE INITIALIZATION: Power-on does not necessarily define the initial status of a MOS device. Immediately after the power source is turned ON, devices with reset functions have not yet been initialized. Hence, power-on does not guarantee output pin levels, I/O settings or contents of registers. A device is not initialized until the reset signal is received. A reset operation must be executed immediately after power-on for devices with reset functions.

(5) POWER ON/OFF SEQUENCE: In the case of a device that uses different power supplies for the internal operation and external interface, as a rule, switch on the external power supply after switching on the internal power supply. When switching the power supply off, as a rule, switch off the external power supply and then the internal power supply. Use of the reverse power on/off sequences may result in the application of an overvoltage to the internal elements of the device, causing malfunction and degradation of internal elements due to the passage of an abnormal current. The correct power on/off sequence must be judged separately for each device and according to related specifications governing the device.

(6) INPUT OF SIGNAL DURING POWER OFF STATE : Do not input signals or an I/O pull-up power supply while the device is not powered. The current injection that results from input of such a signal or I/O pull-up power supply may cause malfunction and the abnormal current that passes in the device at this time may cause degradation of internal elements. Input of signals during the power off state must be judged separately for each device and according to related specifications governing the device.

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INTRODUCTION

Target Readers

This manual is intended for user engineers who wish to understand the functions of the 78K0S/KY1+ in order to design and develop its application systems and programs.

The target devices are the following subseries products.

<R>

- 78K0S/KY1+: μPD78F9210, 78F9211, 78F9212, 78F9210(A), 78F9211(A), 78F9212(A), 78F9210(A2), 78F9211(A2), 78F9212(A2), 78F9511, 78F9512

Purpose

This manual is intended to give users on understanding of the functions described in the **Organization** below.

Organization

Two manuals are available for 78K0S/KY1+: this manual and the Instruction Manual (common to the 78K/0S Series).

78K0S/KY1+ User's Manual	78K/0S Series Instructions User's Manual
• Pin functions • Internal block functions • Interrupts • Other internal peripheral functions • Electrical specifications	• CPU function • Instruction set • Instruction description

How to Use This Manual

It is assumed that the readers of this manual have general knowledge of electrical engineering, logic circuits, and microcontrollers.

◊ To understand the overall functions of 78K0S/KY1+

→ Read this manual in the order of the **CONTENTS**. The mark <R> shows major revised points. The revised points can be easily searched by copying an "<R>" in the PDF file and specifying it in the "Find what:" field.

◊ How to read register formats

→ For a bit number enclosed in angle brackets (<>), the bit name is defined as a reserved word in the RA78K0S, and is defined as an sfr variable using the #pragma sfr directive in the CC78K0S.

◊ To learn the detailed functions of a register whose register name is known

→ See **APPENDIX B REGISTER INDEX**.

◊ To learn the details of the instruction functions of the 78K/0S Series

→ Refer to **78K/0S Series Instructions User's Manual (U11047E)** separately available.

◊ To learn the electrical specifications of the 78K0S/KY1+

→ See **CHAPTER 19** and **CHAPTER 20 ELECTRICAL SPECIFICATIONS**.

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Conventions

Data significance:	Higher digits on the left and lower digits on the right
Active low representation:	$\overline{\times\times\times}$ (overscore over pin or signal name)
Note:	Footnote for item marked with **Note** in the text
Caution:	Information requiring particular attention
Remark:	Supplementary information
Numerical representation:	Binary ... ×××× or ××××B
	Decimal ... ××××
	Hexadecimal ... ××××H

Related Documents The related documents indicated in this publication may include preliminary versions. However, preliminary versions are not marked as such.

Documents Related to Devices

Document Name	Document No.
78K0S/KY1+ User's Manual	This manual
78K/0S Series Instructions User's Manual	U11047E

<R> **Documents Related to Development Software Tools (User's Manuals)**

Document Name		Document No.
RA78K0S Ver.2.00 Assembler Package	Operation	U17391E
	Language	U17390E
	Structured Assembly Language	U17389E
CC78K0S Ver.2.00 C Compiler	Operation	U17416E
	Language	U17415E
SM+ System Simulator	Operation	U18601E
	User Open Interface	U18212E
ID78K0S-QB Ver.3.00 Integrated Debugger	Operation	U18493E
PM+ Ver.6.30		U18416E

Documents Related to Development Hardware Tools (User's Manuals)

Document Name	Document No.
QB-78K0SKX1 In-Circuit Emulator	U18219E
QB-MINI2 On-Chip Debug Emulator with Programming Function	U18371E

Documents Related to Flash Memory Writing (User's Manuals)

Document Name		Document No.
PG-FP5 Flash Memory Programmer		U18865E
<R> QB-Programmer Programming GUI	Operation	U18527E

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Other Related Documents

Document Name	Document No.
SEMICONDUCTOR SELECTION GUIDE - Products and Packages -	X13769X
Semiconductor Device Mount Manual	**Note**
Quality Grades on NEC Semiconductor Devices	C11531E
NEC Semiconductor Device Reliability/Quality Control System	C10983E
Guide to Prevent Damage for Semiconductor Devices by Electrostatic Discharge (ESD)	C11892E

Note See the “Semiconductor Device Mount Manual” website (http://www.necel.com/pkg/en/mount/index.html).

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CHAPTER 1 OVERVIEW

1.1 Features

O 78K0S CPU core

O ROM and RAM capacities

Item / Part number	Program Memory (Flash Memory)	Memory (Internal High-Speed RAM)
<R> μPD78F9210, 78F9510	1 KB	128 bytes
<R> μPD78F9211, 78F9511	2 KB	
<R> μPD78F9212, 78F9512	4 KB	

O Minimum instruction execution time: 0.2 μs (with 10 MHz@4.0 to 5.5 V operation)

O Clock

- High-speed system clock … Selected from the following three sources
  - Ceramic/crystal resonator: 2 to 10 MHz (Standard product, (A) grade product)
    2 to 8 MHz ((A2) grade product)
  - External clock: 2 to 10 MHz (Standard product, (A) grade product)
    2 to 8 MHz ((A2) grade product)
  - High-speed internal oscillator: 8 MHz ±3% (–10 to +70°C),
    8 MHz ±5% (Standard product, (A) grade product: –40 to +85°C, (A2) grade product: –40 to +125°C)
- Low-speed internal oscillator 240 kHz (TYP.) … Watchdog timer, timer clock in intermittent operation

O I/O ports: 14 (CMOS I/O: 13, CMOS input: 1)

O Timer: 3 channels

- 16-bit timer/event counter: 1 channel … Timer output × 1, capture input × 2
- 8-bit timer: 1 channel … PWM output × 1
- Watchdog timer: 1 channel … Operable with low-speed internal oscillation clock

O On-chip power-on-clear (POC) circuit (A reset is automatically generated when the voltage drops to 2.1 V (TYP.) or below)

O 10-bit resolution A/D converter (μPD78F921x only): 4 channels

O On-chip low voltage detector (LVI) circuit (An interrupt/reset (selectable) is generated when the detection voltage is reached)

- Detection voltage: Selectable from ten levels between 2.35 and 4.3 V

O Single-power-supply flash memory

- Flash self programming enabled
- Software protection function: Protected from outside party copying (no flash reading command)
- Time required for writing by dedicated flash memory programmer: Approximately 3 seconds (4 KB)
  ∗ Flash programming on mass production lines supported

O Safety function

- Watchdog timer operated by clock independent from CPU
  … A hang-up can be detected even if the system clock stops
- Supply voltage drop detectable by LVI
  … Appropriate processing can be executed before the supply voltage drops below the operation voltage
- Equipped with option byte function
  … Important system operation settings set in hardware

O Assembler and C language supported

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O Enhanced development environment

- Support for full-function emulator (IECUBE), simplified emulator (MINICUBE2), and simulator

O Supply voltage: V_{DD} = 2.0 to 5.5 V

∗ Use these products in the following voltage range because the detection voltage (V_{POC}) of the POC circuit is the supply voltage range.

Standard product, (A) grade product: 2.2 to 5.5 V, (A2) grade product: 2.26 to 5.5 V

O Operating temperature range:

- Standard product, (A) grade product: T_A = –40 to +85°C
- (A2) grade product: T_A = –40 to +125°C

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<R> 1.2 Ordering Information

Part Number

μPD78F9 ××× - ×× (×) - ××× -×

	Semiconductor component	
-A	Lead-free	Product contains no lead in any area (Terminal finish is Sn/Bi plating)
-AX		Product contains no lead in any area (Terminal finish is Ni/Pd/Au plating)

	Quality grades
Blank	Standard (for ordinary electronic systems)
(A)	Special (for high-reliability electronic systems)
(A2)	

	Package type
MA-FAA	16-pin Plastic SSOP
GR-JJG	
CS-CAB	16-pin Plastic SDIP
FH-2A2	16-pin WLBGA

	High-speed RAM	Flash memory	A/D converter
210	128 bytes	1 K bytes	Mounted
510			Not mounted
211		2 K bytes	Mounted
511			Not mounted
212		4 K bytes	Mounted
512			Not mounted

	Product type
F	Flash memory versions

Please refer to "Quality Grades on NEC Semiconductor Devices" (Document No. C11531E) published by NEC Electronics Corporation to know the specification of the quality grade on the device and its recommended applications.

[Part number list]

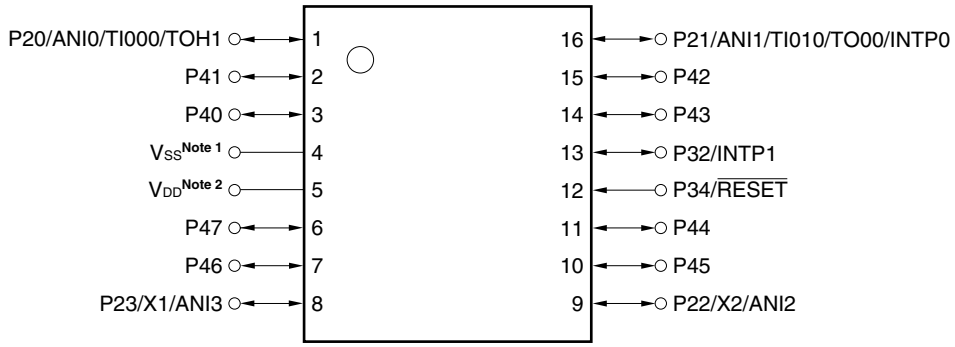
μPD78F9210MA-FAA-AX	μPD78F9211MA-FAA-AX	μPD78F9212MA-FAA-AX
μPD78F9210MA(A)-FAA-AX	μPD78F9211GRMA(A)-FAA-AX	μPD78F9212MA(A)-FAA-AX
μPD78F9210MA(A2)-FAA-AX	μPD78F9211MA(A2)-FAA-AX	μPD78F9212MA(A2)-FAA-AX
μPD78F9210GR-JJG-A	μPD78F9211GR-JJG-A	μPD78F9212GR-JJG-A
μPD78F9210GR(A)-JJG-A	μPD78F9211GR(A)-JJG-A	μPD78F9212GR(A)-JJG-A
μPD78F9210GR(A2)-JJG-A	μPD78F9211GR(A2)-JJG-A	μPD78F9212GR(A2)-JJG-A
μPD78F9510GR-JJG-A	μPD78F9511GR-JJG-A	μPD78F9512GR-JJG-A
μPD78F9210CS-CAB-A	μPD78F9211CS-CAB-A	μPD78F9212CS-CAB-A
μPD78F9210FH-2A2-A	μPD78F9211FH-2A2-A	μPD78F9212FH-2A2-A

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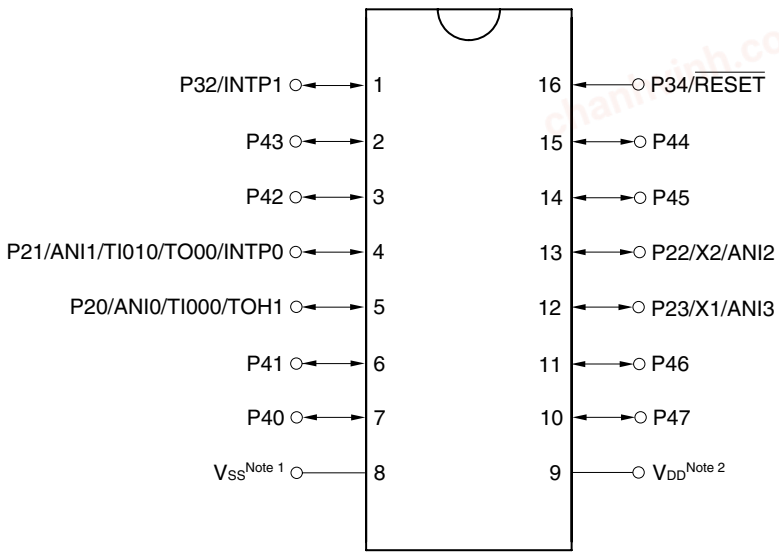
1.3 Pin Configuration (Top View)

1.3.1 μPD78F921x

- 16-pin plastic SSOP



- 16-pin plastic SDIP

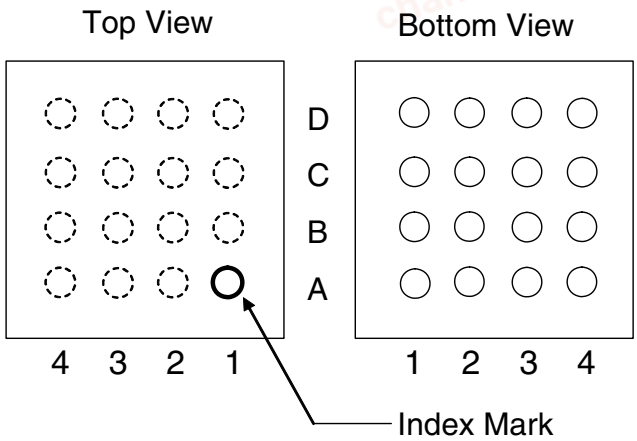


Notes 1. In μPD78F921x, V_{SS} functions alternately as the ground potential of the A/D converter. Be sure to connect V_{SS} to a stabilized GND (= 0 V).

2. In μPD78F921x, V_{DD} functions alternately as the A/D converter reference voltage input. When using the A/D converter, stabilize V_{DD} at the supply voltage used (2.7 to 5.5 V).

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• 16-pin WLBGA (2.24×1.93)



Pin No.	Name	Pin No.	Name
A1	P20/ANI0/TI000/TOH1	C1	P42
A2	V_{SS} Note1	C2	P43
A3	P47	C3	P34/$\overline{\text{RESET}}$
A4	P23/X1/ANI3	C4	P45
B1	P41	D1	P21/ANI1/TI010/TO000/INTP0
B2	P40	D2	P32/INTP1
B3	V_{DD} Note2	D3	P44
B4	P46	D4	P22/X2/ANI2

Pin Name

ANI0 to ANI3:	Analog input	TI000, TI010:	Timer input
INTP0, INTP1:	External interrupt input	TO00, TOH1:	Timer output
P20 to P23:	Port 2	V_{DD} Note 2:	Power supply
P32, P34:	Port 3	V_{SS} Note 1:	Ground
P40 to P47:	Port 4	X1, X2:	Crystal oscillator (X1 input clock)
$\overline{\text{RESET}}$:	Reset		

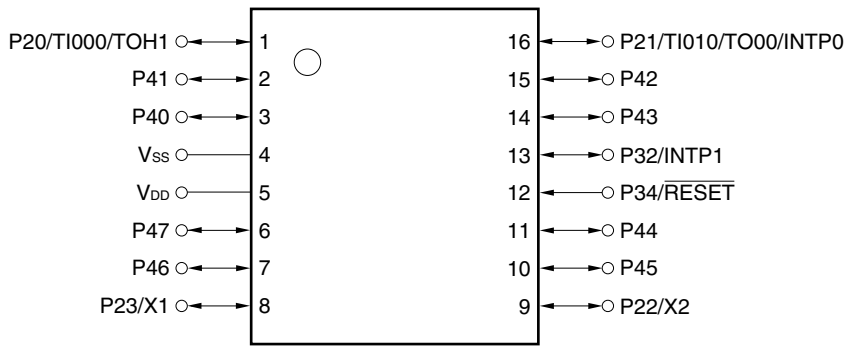
Notes 1. In μPD78F921x, V_{SS} functions alternately as the ground potential of the A/D converter. Be sure to connect V_{SS} to a stabilized GND (= 0 V).

2. In μPD78F921x, V_{DD} functions alternately as the A/D converter reference voltage input. When using the A/D converter, stabilize V_{DD} at the supply voltage used (2.7 to 5.5 V).

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<R> **1.3.2 μPD78F951x**

- 16-pin plastic SSOP



Pin Name

INTP0, INTP1:	External interrupt input	TI000, TI010:	Timer input
P20 to P23:	Port 2	TO00, TOH1:	Timer output
P32, P34:	Port 3	V_{DD}:	Power supply
P40 to P47:	Port 4	V_{SS}:	Ground
$\overline{RESET}$:	Reset	X1, X2:	Crystal oscillator (X1 input clock)

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1.4 78K0S/Kx1+ Product Lineup

The following table shows the product lineup of the 78K0S/Kx1+.

Item \ Part Number		78K0S/KU1+	78K0S/KY1+	78K0S/KA1+		78K0S/KB1+
Number of pins		10 pins	16 pins	20 pins		30/32 pins
<R> Internal memory	Flash memory	1 KB, 2 KB, 4 KB		2 KB	4 KB, 8 KB	4 KB, 8 KB
	RAM	128 bytes		128 bytes	256 bytes	256 bytes
Supply voltage		V_{DD} = 2.0 to 5.5 V[Note 1]				
Minimum instruction execution time		0.20 μs (10 MHz, V_{DD} = 4.0 to 5.5 V) 0.33 μs (6 MHz, V_{DD} = 3.0 to 5.5 V) 0.40 μs (5 MHz, V_{DD} = 2.7 to 5.5 V) 1.0 μs (2 MHz, V_{DD} = 2.0 to 5.5 V)				
System clock (oscillation frequency)		High-speed internal oscillation (8 MHz (TYP.)) Crystal/ceramic oscillation (2 to 10 MHz)[Note 2] External clock input oscillation (2 to 10 MHz)				
Clock for TMH1 and WDT (oscillation frequency)		Low-speed internal oscillation (240 kHz (TYP.))				
Port	CMOS I/O	7	13	15		24
	CMOS input	1	1	1		1
	CMOS output	–	–	1		1
Timer	16-bit (TM0)	1 ch[Note 3]				
	8-bit (TMH)	1 ch				
	8-bit (TM8)	–		1 ch		
	WDT	1 ch				
Serial interface		–		LIN-Bus-supporting UART: 1 ch		
A/D converter[Note 4]		10 bits: 4 ch (2.7 to 5.5 V)[Note 4]				
Multiplier (8 bits × 8 bits)		–				Provided
Interrupts	Internal	5[Note 5]		9		
	External	2		4		
Reset	$\overline{\text{RESET}}$ pin	Provided				
	POC	2.1 V (TYP.)				
	LVI	Provided (selectable by software)				
	WDT	Provided				
Operating temperature range		Standard product: –40 to +85°C	Standard product, (A) grade product: –40 to +85°C (A2) grade product: –40 to +125°C			

Notes 1. Use these products in the following voltage range because the detection voltage (V_{POC}) of the power-on-clear (POC) circuit is the supply voltage range.
Standard product, (A) grade product: 2.2 to 5.5 V, (A2) grade product: 2.26 to 5.5 V

<R> **2.** μPD78F950x does not support the crystal/ceramic oscillation.

3. The product without A/D converter (μPD78F950x) in the 78K0S/KU1+ is not supported.

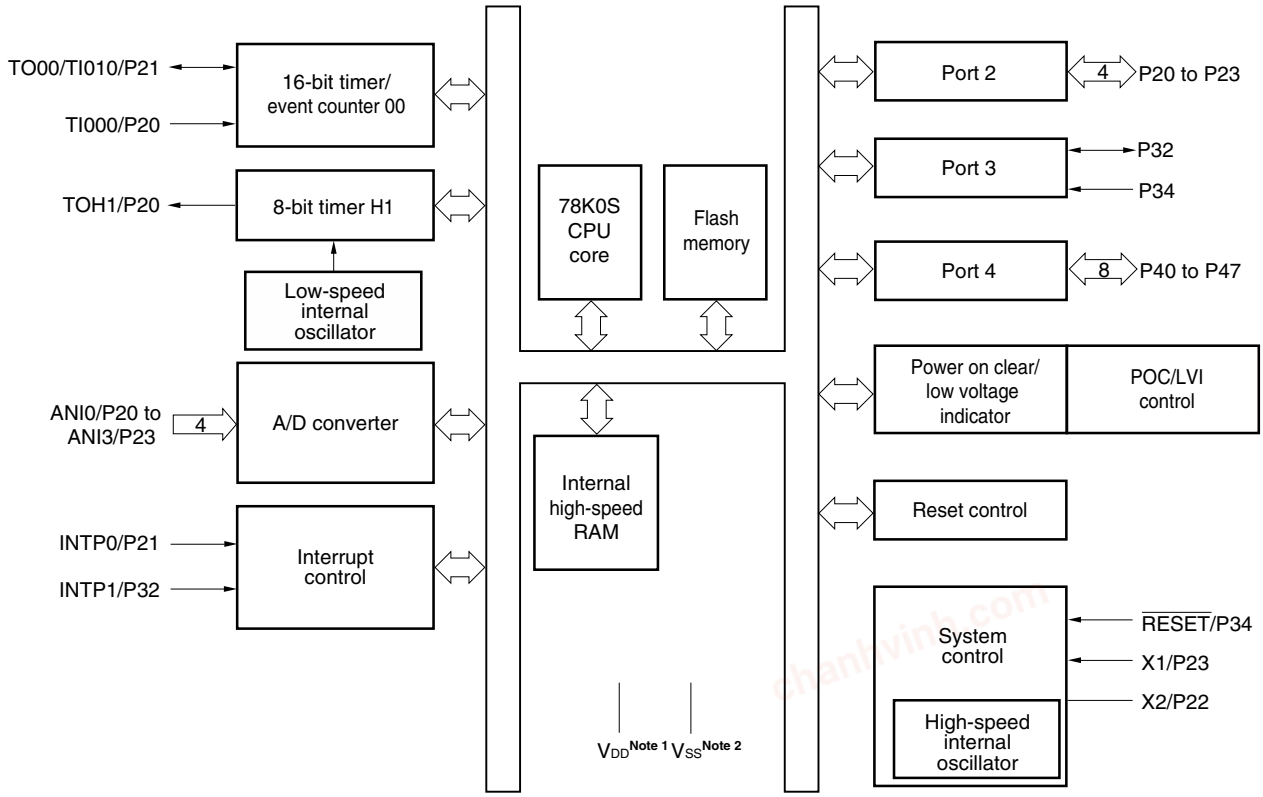
4. The product without A/D converter (μPD78F95xx) is provided for the 78K0S/KU1+ and 78K0S/KY1+ respectively.

5. There are 2 and 4 factors for the products without A/D converter in the 78K0S/KU1+ and 78K0S/KY1+, respectively.

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1.5 Block Diagram

1.5.1 μPD78F921x

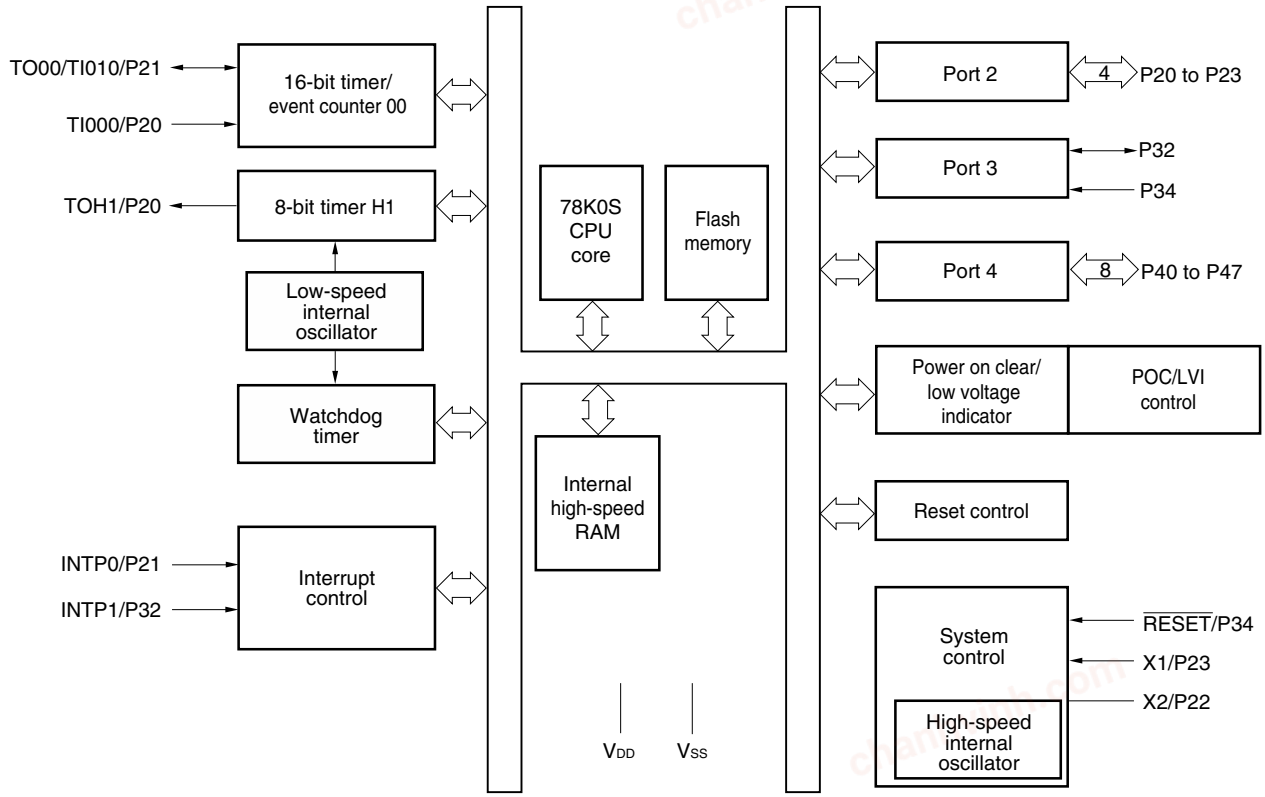


Notes 1. In μPD78F921x, V_{DD} functions alternately as the A/D converter reference voltage input. When using the A/D converter, stabilize V_{DD} at the supply voltage used (2.7 to 5.5 V).

2. In μPD78F921x, V_{SS} functions alternately as the ground potential of the A/D converter. Be sure to connect V_{SS} to a stabilized GND (= 0 V).

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<R> **1.5.2 μPD78F951x**



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1.6 Functional Outline

<R>

Item		μPD78F9210 μPD78F9510	μPD78F9211 μPD78F9511	μPD78F9212 μPD78F9512
Internal memory	Flash memory	1 KB	2 KB	4 KB
	High-speed RAM	128 bytes		
Memory space		64 KB		
X1 input clock (oscillation frequency)		Crystal/ceramic/external clock input: 10 MHz (V_{DD} = 2.0 to 5.5 V)		
Internal oscillation clock	High speed (oscillation frequency)	Internal oscillation: 8 MHz (TYP.)		
	Low speed (for TMH1 and WDT)	Internal oscillation: 240 kHz (TYP.)		
General-purpose registers		8 bits × 8 registers		
Instruction execution time		0.2 μs/0.4 μs/0.8 μs/1.6 μs/3.2 μs (X1 input clock: f_X = 10 MHz)		
I/O port		Total: 14 pins CMOS I/O: 13 pins CMOS input: 1 pin		
Timer		• 16-bit timer/event counter: 1 channel • 8-bit timer (timer H1): 1 channel • Watchdog timer: 1 channel		
	Timer output	2 pins (PWM: 1 pin)		
<R> A/D converter (μPD78F921x only)		10-bit resolution × 4 channels		
Vectored interrupt sources	External	2		
<R>	Internal	μPD78F921x: 5, μPD78F951x: 4		
Reset		• Reset by $\overline{\text{RESET}}$ pin • Internal reset by watchdog timer • Internal reset by power-on-clear • Internal reset by low-voltage detector		
Supply voltage		V_{DD} = 2.0 to 5.5 V[Note]		
Operating temperature range		Standard product, (A) grade product: −40 to +85°C (A2) grade product: −40 to +125°C		
Package		• 16-pin plastic SSOP • 16-pin plastic SDIP • 16-pin WLBGA (2.24 × 1.93)		

Note Use these products in the following voltage range because the detection voltage (V_{POC}) of the power-on-clear (POC) circuit is the supply voltage range.
Standard product, (A) grade product: 2.2 to 5.5 V, (A2) grade product: 2.26 to 5.5 V

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CHAPTER 2 PIN FUNCTIONS

2.1 Pin Function List

2.1.1 μPD78F921x

(1) Port pins

Pin Name	I/O	Function		After Reset	Alternate-Function Pin
P20	I/O	Port 2. 4-bit I/O port. Can be set to input or output mode in 1-bit units. An on-chip pull-up resistor can be connected by setting software.		Input	ANI0/TI000/TOH1
P21					ANI1/TI010/ TO00/INTP0
P22[Note]					X2/ANI2[Note]
P23[Note]					X1/ANI3[Note]
P32	I/O	Port 3	Can be set to input or output mode in 1-bit units. An on-chip pull-up resistor can be connected by setting software.	Input	INTP1
P34[Note]	Input		Input only	Input	$\overline{\text{RESET}}$[Note]
P40 to P47	I/O	Port 4. 8-bit I/O port. Can be set to input or output mode in 1-bit units. An on-chip pull-up resistor can be connected by setting software.		Input	–

Note For the setting method for pin functions, see **CHAPTER 15 OPTION BYTE**.

Caution The P22/X2/ANI2 and P23/X1/ANI3 pins are pulled down during reset.

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(2) Non-port pins

Pin Name	I/O	Function	After Reset	Alternate-Function Pin
INTP0	Input	External interrupt input for which the valid edge (rising edge, falling edge, or both rising and falling edges) can be specified	Input	P21/ANI1/TI010/TO00
INTP1				P32
TI000	Input	External count clock input to 16-bit timer/event counter 00. Capture trigger input to capture registers (CR000 and CR010) of 16-bit timer/event counter 00	Input	P20/ANI0/TOH1
TI010		Capture trigger input to capture register (CR000) of 16-bit timer/event counter 00		P21/ANI1/TO00/INTP0
TO00	Output	16-bit timer/event counter 00 output	Input	P21/ANI1/TI010/INTP0
TOH1	Output	8-bit timer H1 output	Input	P20/ANI0/TI000
ANI0	Input	Analog input of A/D converter	Input	P20/TI000/TOH1
ANI1				P21/TI010/TO00/INTP0
ANI2[Note]				P22/X2[Note]
ANI3[Note]				P23/X1[Note]
$\overline{\text{RESET}}$ [Note]	Input	System reset input	Input	P34[Note]
X1[Note]	Input	Connection of crystal/ceramic oscillator for system clock oscillation. External clock input	–	P23/ANI3[Note]
X2[Note]	–	Connection of crystal/ceramic oscillator for system clock oscillation.	–	P22/ANI2[Note]
V_{DD}	–	Positive power supply	–	–
V_{SS}	–	Ground potential	–	–

Note For the setting method for pin functions, see **CHAPTER 15 OPTION BYTE**.

Caution The P22/X2/ANI2 and P23/X1/ANI3 pins are pulled down during reset.

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<R> 2.1.2 μPD78F951x

(1) Port pins

Pin Name	I/O	Function		After Reset	Alternate-Function Pin
P20	I/O	Port 2. 4-bit I/O port. Can be set to input or output mode in 1-bit units. An on-chip pull-up resistor can be connected by setting software.		Input	TI000/TOH1
P21					TI010/TO00/ INTP0
P22[Note]					X2[Note]
P23[Note]					X1[Note]
P32	I/O	Port 3	Can be set to input or output mode in 1-bit units. An on-chip pull-up resistor can be connected by setting software.	Input	INTP1
P34[Note]	Input		Input only	Input	$\overline{\text{RESET}}$[Note]
P40 to P47	I/O	Port 4. 8-bit I/O port. Can be set to input or output mode in 1-bit units. An on-chip pull-up resistor can be connected by setting software.		Input	–

(2) Non-port pins

Pin Name	I/O	Function	After Reset	Alternate-Function Pin
INTP0	Input	External interrupt input for which the valid edge (rising edge, falling edge, or both rising and falling edges) can be specified	Input	P21 /TI010/ TO00
INTP1				P32
TI000	Input	External count clock input to 16-bit timer/event counter 00. Capture trigger input to capture registers (CR000 and CR010) of 16-bit timer/event counter 00	Input	P20 /TOH1
TI010		Capture trigger input to capture register (CR000) of 16-bit timer/event counter 00		P21/TO00/ INTP0
TO00	Output	16-bit timer/event counter 00 output	Input	P21/TI010/ INTP0
TOH1	Output	8-bit timer H1 output	Input	P20/TI000
$\overline{\text{RESET}}$ [Note]	Input	System reset input	Input	P34[Note]
X1[Note]	Input	Connection of crystal/ceramic oscillator for system clock oscillation. External clock input	–	P23[Note]
X2[Note]	–	Connection of crystal/ceramic oscillator for system clock oscillation.	–	P22[Note]
V_{DD}	–	Positive power supply	–	–
V_{SS}	–	Ground potential	–	–

Note For the setting method for pin functions, see CHAPTER 15 OPTION BYTE.

Caution The P22/X2 and P23/X1 pins are pulled down during reset.

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2.2 Pin Functions

2.2.1 P20 to P23 (Port 2)

P20 to P23 constitute a 4-bit I/O port. In addition to the function as I/O port pins, these pins also have a function to input an analog signal to the A/D converter, input/output a timer signal, and input an external interrupt request signal.

P22 and P23 also function as the X2/ANI2 and X1/ANI3, respectively. For the setting method for pin functions, see **CHAPTER 15 OPTION BYTE**.

These pins can be set to the following operation modes in 1-bit units.

(1) Port mode

P20 to P23 function as a 4-bit I/O port. Each bit of this port can be set to the input or output mode by using port mode register 2 (PM2). In addition, an on-chip pull-up resistor can be connected to the port by using pull-up resistor option register 2 (PU2).

(2) Control mode

P20 to P23 function to input an analog signal to the A/D converter, input/output a timer signal, and input an external interrupt request signal.

<R> **(a) ANI0 to ANI3 (μPD78F921x only)**

These are the analog input pins of the A/D converter. When using these pins as analog input pins, refer to **9.6 Cautions for A/D converter (5) ANI0/P20 to ANI3/P23**.

(b) TI000

This pin inputs an external count clock to 16-bit timer/event counter 00, or a capture trigger signal to the capture registers (CR000 and CR010) of 16-bit timer/event counter 00.

(c) TI010

This pin inputs a capture trigger signal to the capture register (CR000) of 16-bit timer/event counter 00.

(d) TO00

This pin outputs a signal from 16-bit timer/event counter 00.

(e) TOH1

This pin outputs a signal from 8-bit timer H1.

(f) INTP0

This is an external interrupt request input pin for which the valid edge (rising edge, falling edge, or both rising and falling edges) can be specified.

Caution The P22/X2/ANI2 and P23/X1/ANI3 pins are pulled down during reset.

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2.2.2 P32 and P34 (Port 3)

P32 is a 1-bit I/O port. In addition to the function as an I/O port pin, this pin also has a function to input an external interrupt request signal.

P34 is a 1-bit input-only port. This pin is also used as a $\overline{\text{RESET}}$ pin, and when the power is turned on, this is the reset function.

For the setting method for pin functions, see **CHAPTER 15 OPTION BYTE**.

When P34 is used as an input port pin, connect the pull-up resistor.

P32 and P34 can be set to the following operation modes in 1-bit units.

(1) Port mode

P32 functions as a 1-bit I/O port. This pin can be set to the input or output mode by using port mode register 3 (PM3). In addition, an on-chip pull-up resistor can be connected to the port by using pull-up resistor option register 3 (PU3).

P34 functions as a 1-bit input-only port.

(2) Control mode

P32 functions as an external interrupt request input pin (INTP1) for which the valid edge (rising edge, falling edge, or both rising and falling edges) can be specified.

2.2.3 P40 to P47 (Port 4)

P40 to P47 constitute an 8-bit I/O port. Each bit of this port can be set to the input or output mode by using port mode register 4 (PM4). In addition, an on-chip pull-up resistor can be connected to the port by using pull-up resistor option register 4 (PU4).

2.2.4 $\overline{\text{RESET}}$

This pin inputs an active-low system reset signal. When the power is turned on, this is the reset function, regardless of the option byte setting.

2.2.5 X1 and X2

These pins connect an oscillator to oscillate the X1 input clock.

X1 and X2 also function as the P23/ANI3 and P22/ANI2, respectively. For the setting method for pin functions, see **CHAPTER 15 OPTION BYTE**.

Supply an external clock to X1.

Caution The P22/X2/ANI2 and P23/X1/ANI3 pins are pulled down during reset.

2.2.6 V_{DD}

This is the positive power supply pin.

In μPD78F921x, V_{DD} functions alternately as the A/D converter reference voltage input. When using the A/D converter, stabilize V_{DD} at the supply voltage used (2.7 to 5.5 V).

2.2.7 V_{SS}

This is the ground pin.

In μPD78F921x, V_{SS} functions alternately as the ground potential of the A/D converter. Be sure to connect V_{SS} to a stabilized GND (= 0 V).

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2.3 Pin I/O Circuits and Connection of Unused Pins

Table 2-1 shows I/O circuit type of each pin and the connections of unused pins.
For the configuration of the I/O circuit of each type, refer to **Figures 2-1** and **2-2**.

Table 2-1. Types of Pin I/O Circuits and Connection of Unused Pins (μPD78F921x)

Pin Name	I/O Circuit Type	I/O	Recommended Connection of Unused Pin
P20/ANI0/TI000/TOH1	11	I/O	Input: Individually connect to V_{DD} or V_{SS} via resistor. Output: Leave open.
P21/ANI1/TI010/TO00/INTP0			
P22/ANI2/X2	36		Input: Individually connect to V_{SS} via resistor. Output: Leave open.
P23/ANI3/X1			
P32/INTP1	8-A		Input: Individually connect to V_{DD} or V_{SS} via resistor. Output: Leave open.
P34/$\overline{\text{RESET}}$	2	Input	Connect to V_{DD} via resistor.
P40 to P47	8-A	I/O	Input: Individually connect to V_{DD} or V_{SS} via resistor. Output: Leave open.

<R>

Table 2-2. Types of Pin I/O Circuits and Connection of Unused Pins (μPD78F951x)

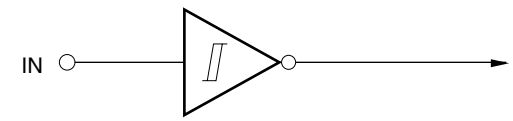
Pin Name	I/O Circuit Type	I/O	Recommended Connection of Unused Pin
P20/TI000/TOH1	11-H	I/O	Input: Individually connect to V_{DD} or V_{SS} via resistor. Output: Leave open.
P21/TI010/TO00/INTP0			
P22/X2	36-A		Input: Individually connect to V_{SS} via resistor. Output: Leave open.
P23/X1			
P32/INTP1	8-A		Input: Individually connect to V_{DD} or V_{SS} via resistor. Output: Leave open.
P34/$\overline{\text{RESET}}$	2	Input	Connect to V_{DD} via resistor.
P40 to P47	8-A	I/O	Input: Individually connect to V_{DD} or V_{SS} via resistor. Output: Leave open.

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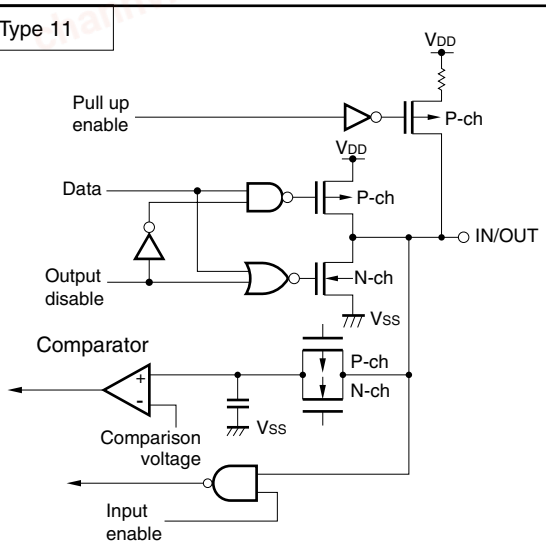
Figure 2-1. Pin I/O Circuits (1/2)

Type 2

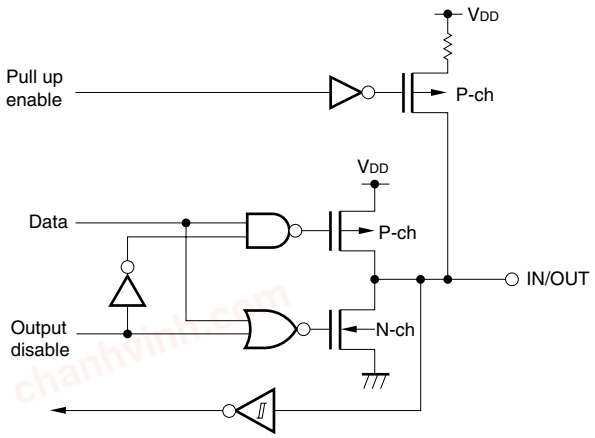


Schmitt-triggered input with hysteresis characteristics

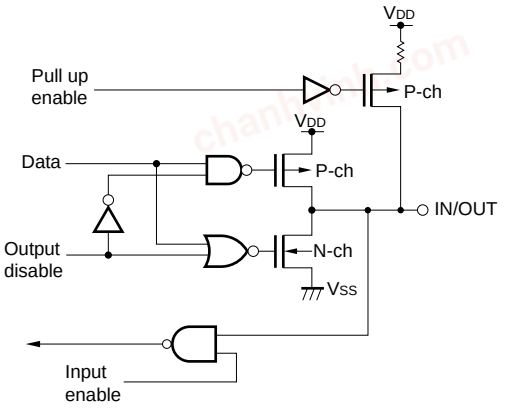
Type 11



Type 8-A



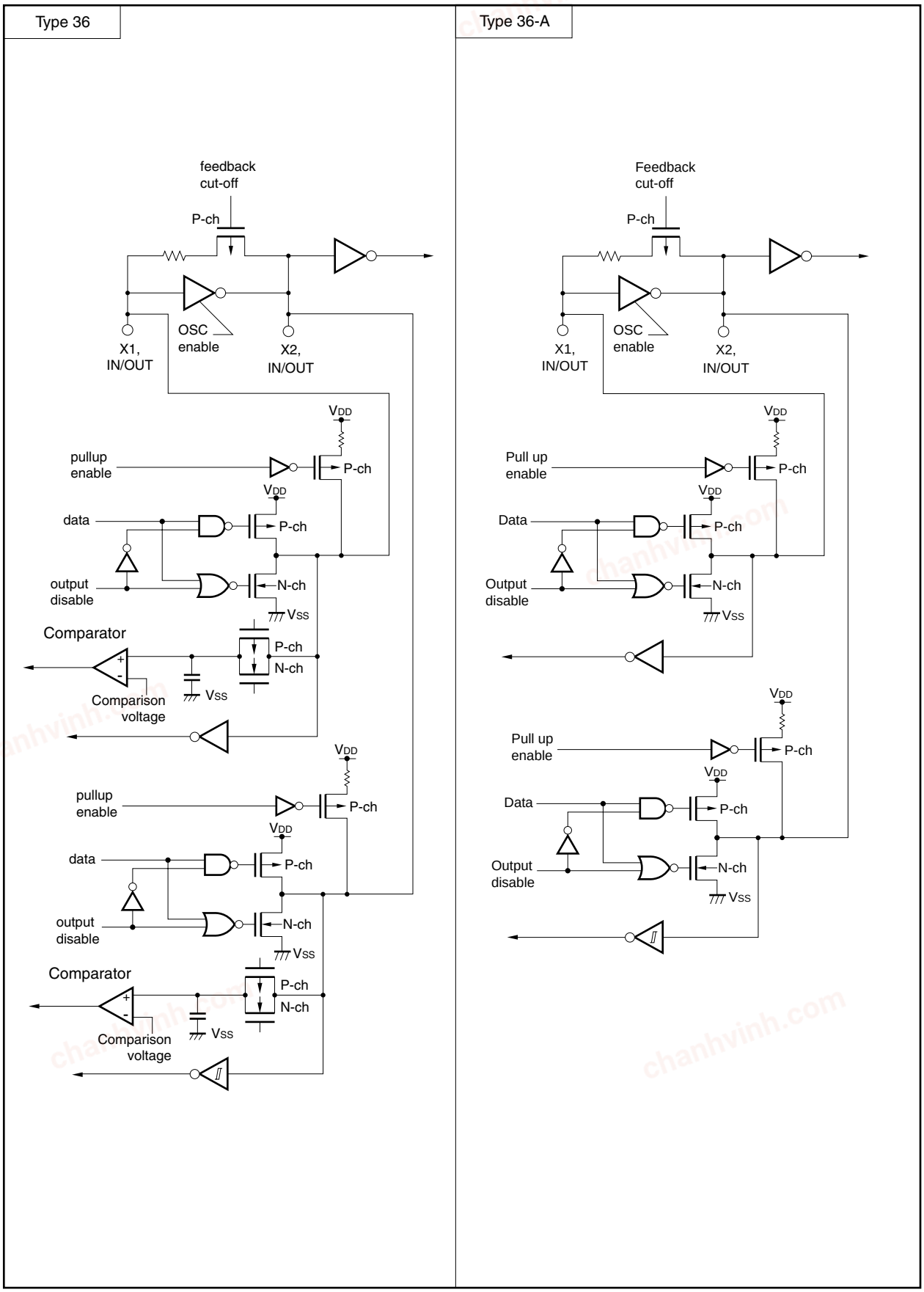
Type 11-H



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Figure 2-1. Pin I/O Circuits (2/2)



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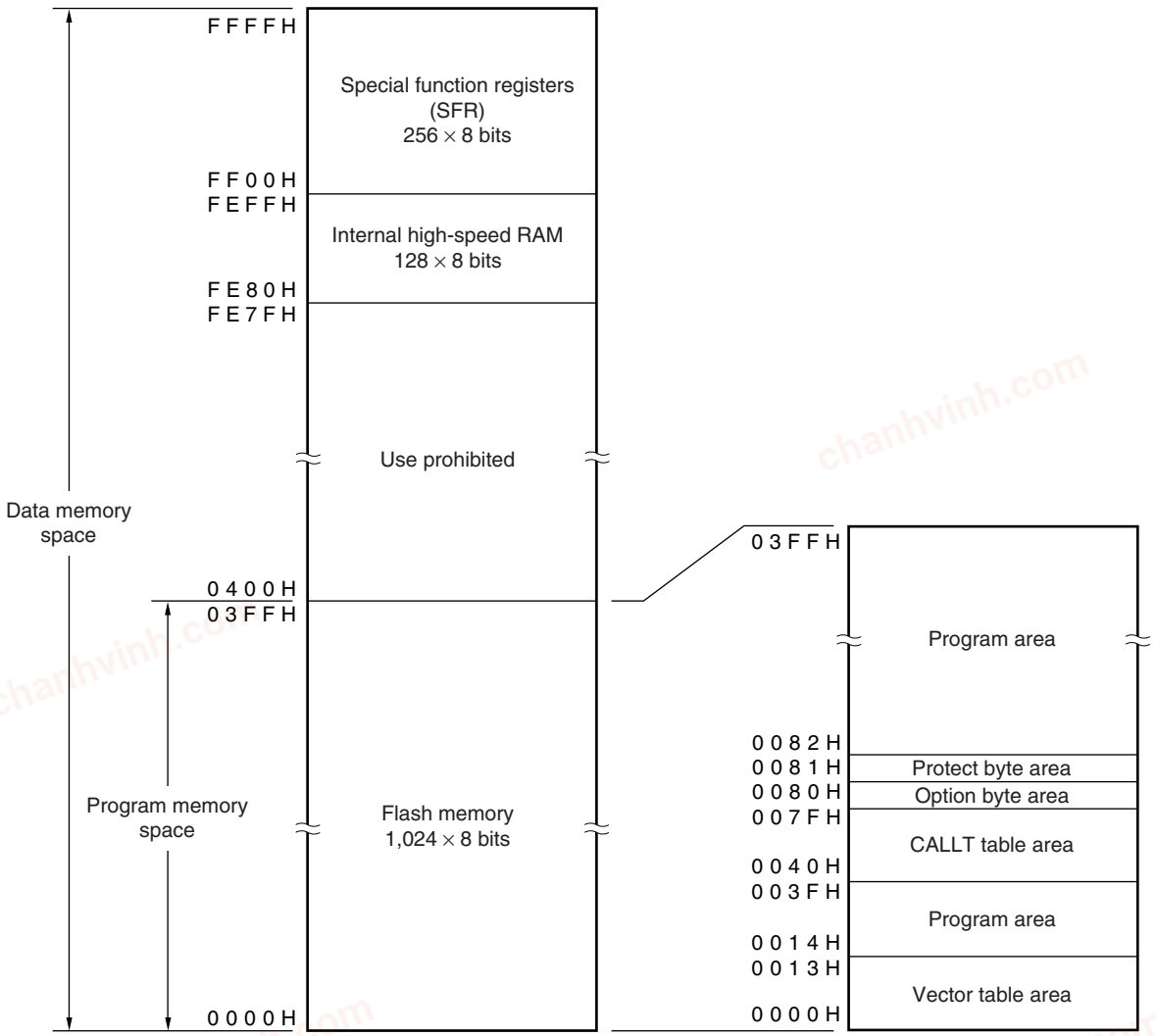
CHAPTER 3 CPU ARCHITECTURE

3.1 Memory Space

The 78K0S/KY1+ can access up to 64 KB of memory space. Figures 3-1 to 3-3 show the memory maps.

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Figure 3-1. Memory Map (μPD78F9210, 78F9510)

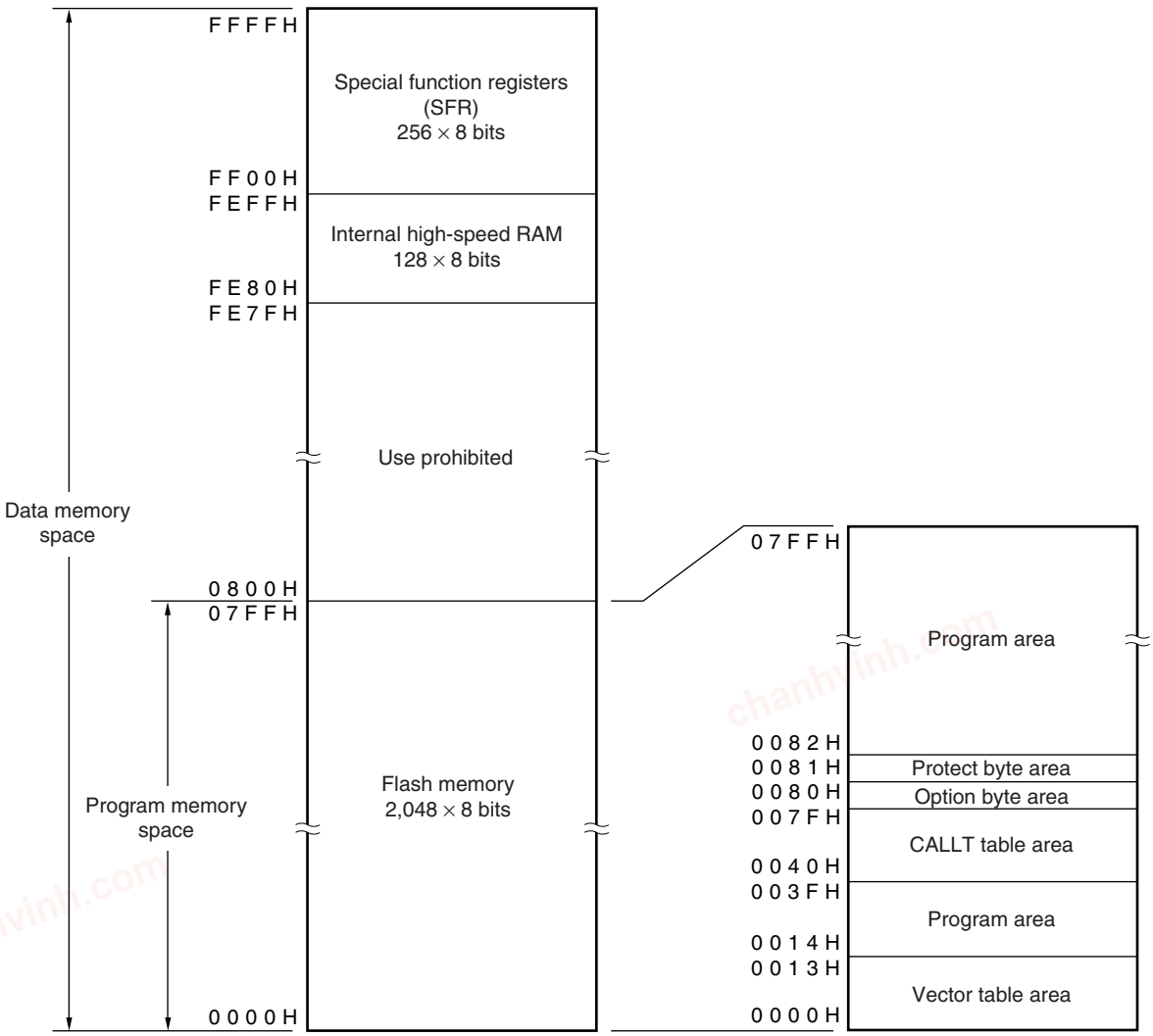


Remark The option byte and protect byte are 1 byte each.

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Figure 3-2. Memory Map (μPD78F9211, 78F9511)

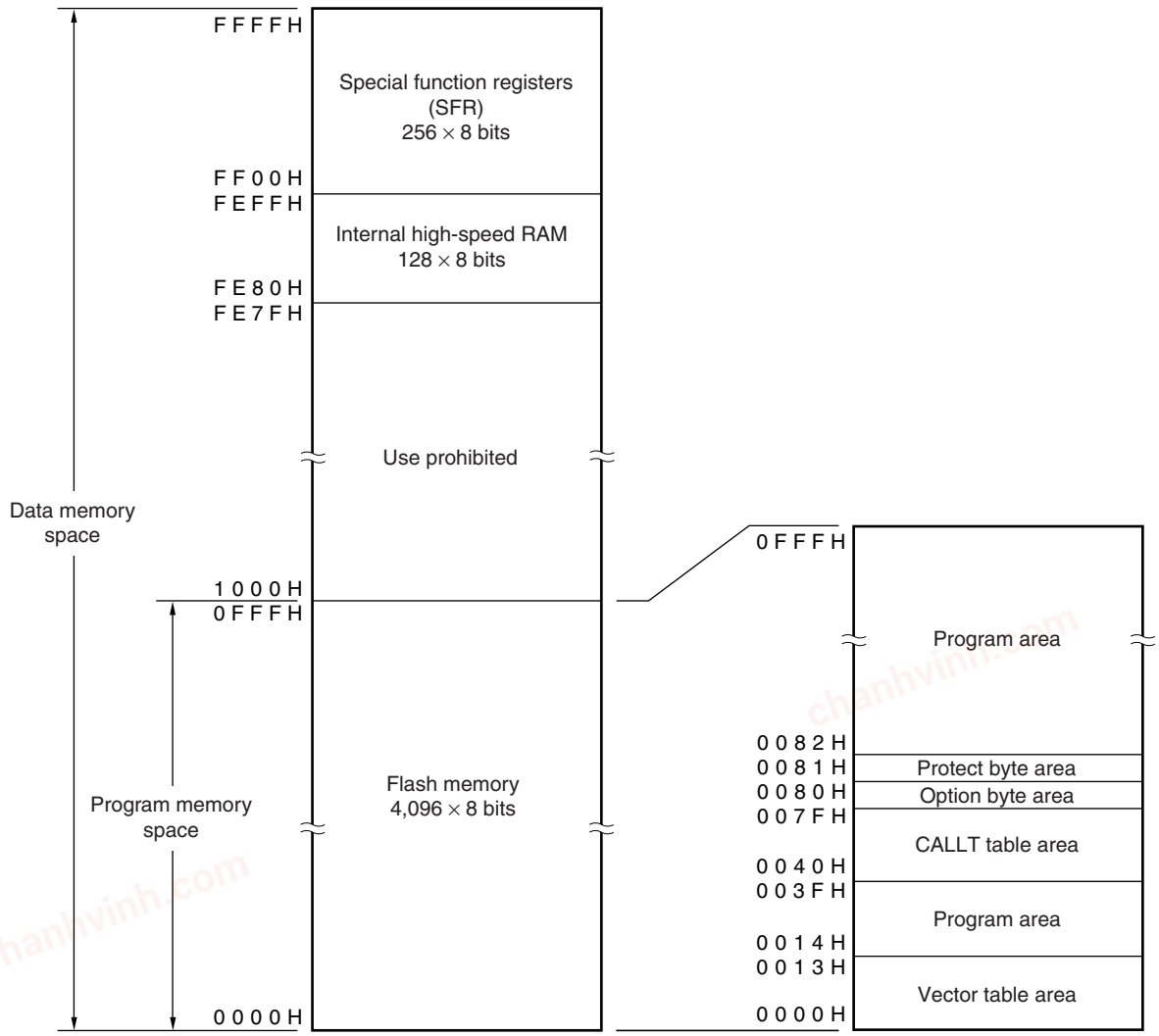


Remark The option byte and protect byte are 1 byte each.

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Figure 3-3. Memory Map (μPD78F9212, 78F9512)



Remark The option byte and protect byte are 1 byte each.

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3.1.1 Internal program memory space

The internal program memory space stores programs and table data. This space is usually addressed by the program counter (PC).

The 78K0S/KY1+ provide the following internal ROMs (or flash memory) containing the following capacities.

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Table 3-1. Internal ROM Capacity

Part Number	Internal ROM	
	Structure	Capacity
μPD78F9210, 78F9510	Flash memory	1,024 × 8 bits
μPD78F9211, 78F9511		2,048 × 8 bits
μPD78F9212, 78F9512		4,096 × 8 bits

The following areas are allocated to the internal program memory space.

(1) Vector table area

The 20-byte area of addresses 0000H to 0013H is reserved as a vector table area. This area stores program start addresses to be used when branching by RESET or interrupt request generation. Of a 16-bit address, the lower 8 bits are stored in an even address, and the higher 8 bits are stored in an odd address.

Table 3-2. Vector Table

Vector Table Address	Interrupt Request	Vector Table Address	Interrupt Request
0000H	Reset	000CH	INTTMH1
0006H	INTLVI	000EH	INTTM000
0008H	INTP0	0010H	INTTM010
000AH	INTP1	0012H[Note]	INTAD[Note]

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Note μPD78F921x only

(2) CALLT instruction table area

The subroutine entry address of a 1-byte call instruction (CALLT) can be stored in the 64-byte area of addresses 0040H to 007FH.

(3) Option byte area

The option byte area is the 1-byte area of address 0080H. For details, refer to **CHAPTER 15 OPTION BYTE**.

(4) Protect byte area

The protect byte area is the 1-byte area of address 0081H. For details, refer to **CHAPTER 16 FLASH MEMORY**.

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3.1.2 Internal data memory space

128-byte internal high-speed RAM is provided in the 78K0S/KY1+.

The internal high-speed RAM can also be used as a stack memory.

3.1.3 Special function register (SFR) area

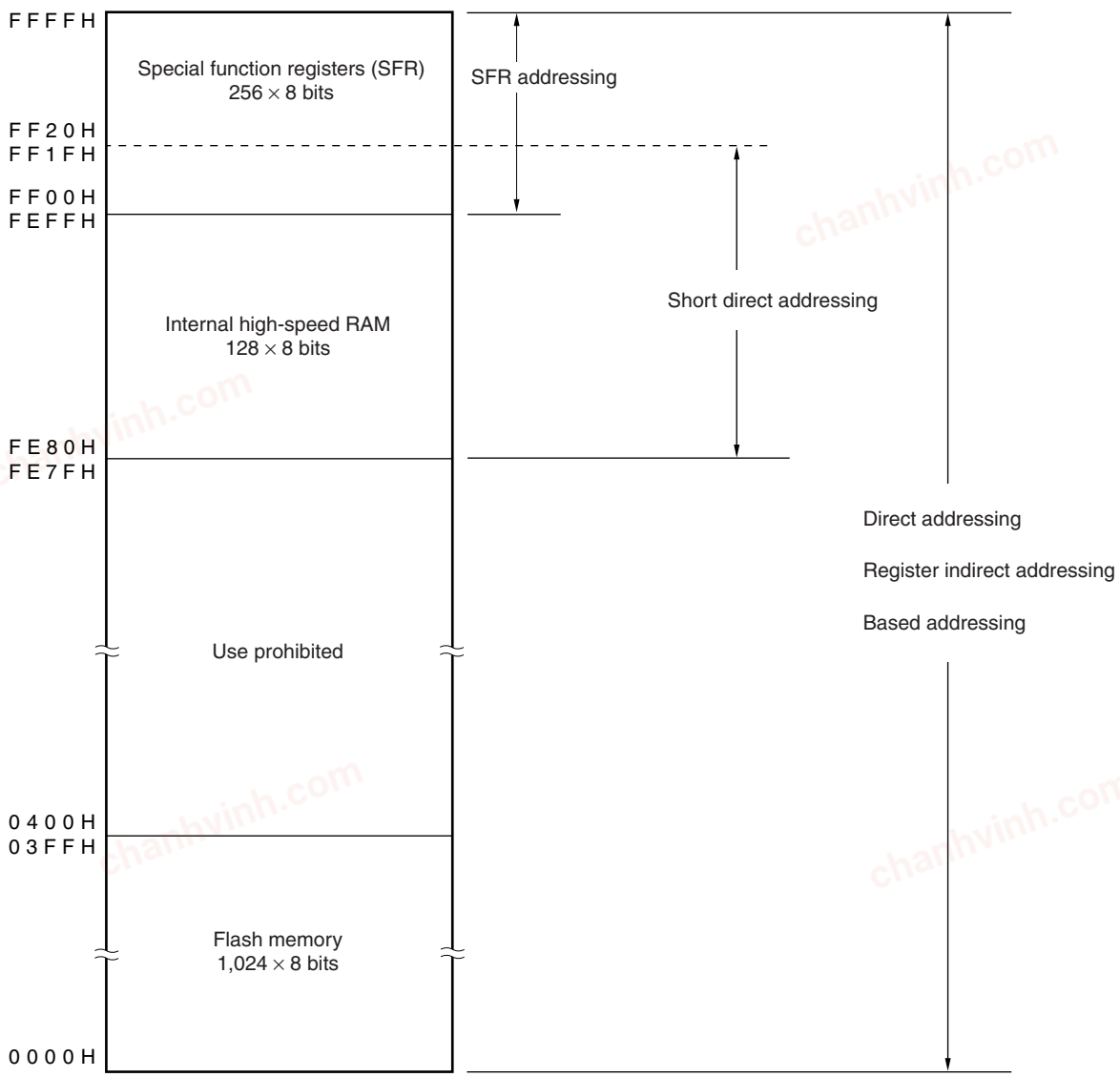
Special function registers (SFRs) of on-chip peripheral hardware are allocated to the area of FF00H to FFFFH (see **Table 3-3**).

3.1.4 Data memory addressing

The 78K0S/KY1+ are provided with a wide range of addressing modes to make memory manipulation as efficient as possible. The area (FE80H to FEFFH) which contains a data memory and the special function register (SFR) area can be accessed using a unique addressing mode in accordance with each function. Figures 3-4 to 3-6 illustrate the data memory addressing.

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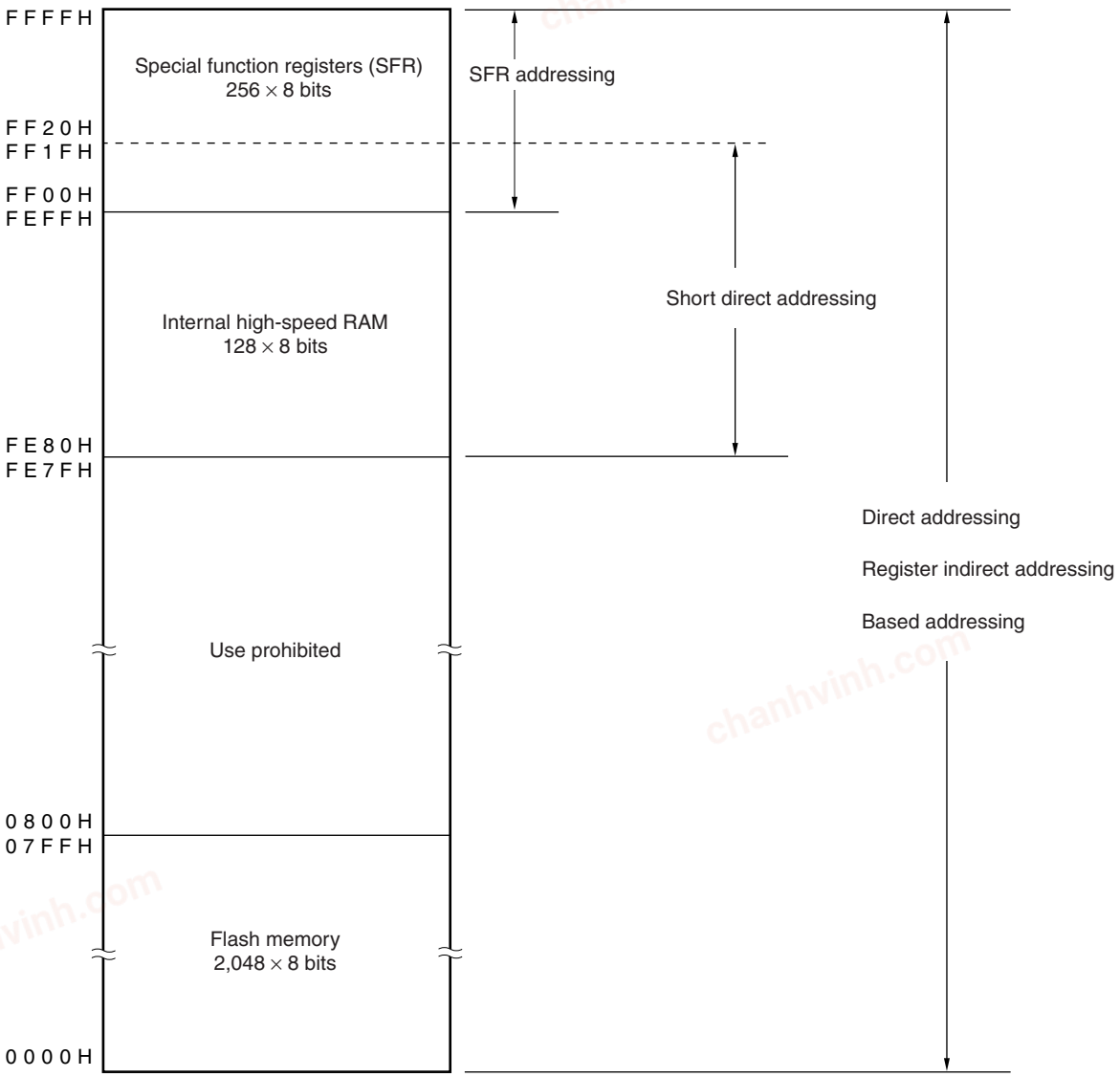
Figure 3-4. Data Memory Addressing (μPD78F9210, 78F9510)



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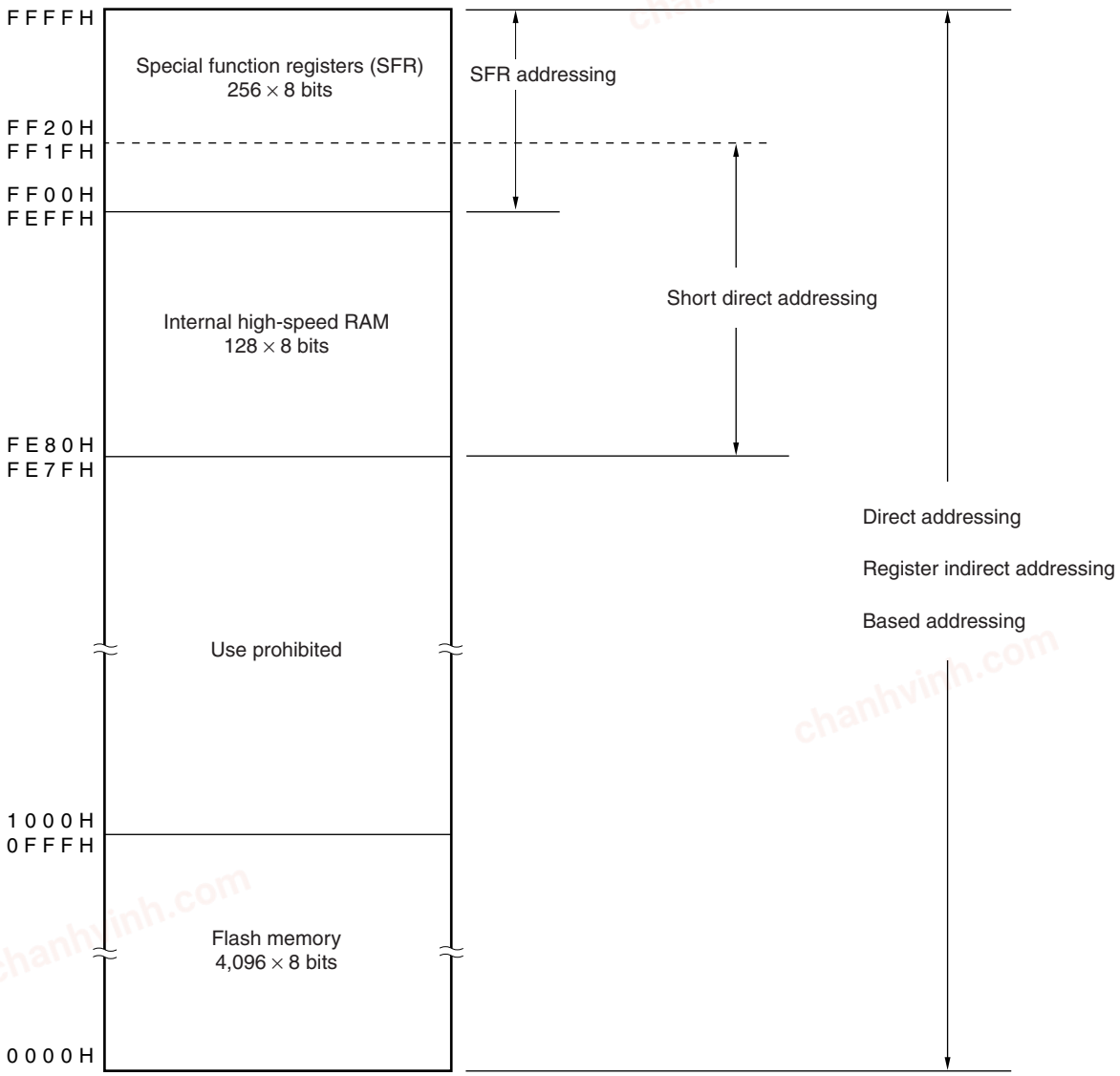
Figure 3-5. Data Memory Addressing (μPD78F9211, 78F9511)



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Figure 3-6. Data Memory Addressing (μPD78F9212, 78F9512)



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3.2 Processor Registers

The 78K0S/KY1+ provide the following on-chip processor registers.

3.2.1 Control registers

The control registers have special functions to control the program sequence statuses and stack memory. The control registers include a program counter, a program status word, and a stack pointer.

(1) Program counter (PC)

The program counter is a 16-bit register which holds the address information of the next program to be executed.

In normal operation, the PC is automatically incremented according to the number of bytes of the instruction to be fetched. When a branch instruction is executed, immediate data or register contents are set.

Reset signal generation sets the reset vector table values at addresses 0000H and 0001H to the program counter.

Figure 3-7. Program Counter Configuration

	15															0
PC	PC15	PC14	PC13	PC12	PC11	PC10	PC9	PC8	PC7	PC6	PC5	PC4	PC3	PC2	PC1	PC0

(2) Program status word (PSW)

The program status word is an 8-bit register consisting of various flags to be set/reset by instruction execution.

Program status word contents are stored in stack area upon interrupt request generation or PUSH PSW instruction execution and are restored upon execution of the RETI and POP PSW instructions.

Reset signal generation sets PSW to 02H.

Figure 3-8. Program Status Word Configuration

	7							0
PSW	IE	Z	0	AC	0	0	1	CY

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(a) Interrupt enable flag (IE)

This flag controls interrupt request acknowledge operations of the CPU.

When IE = 0, the interrupt disabled (DI) status is set. All interrupt requests are disabled.

When IE = 1, the interrupt enabled (EI) status is set. Interrupt request acknowledgment is controlled with an interrupt mask flag for various interrupt sources.

This flag is reset to 0 upon DI instruction execution or interrupt acknowledgment and is set to 1 upon EI instruction execution.

(b) Zero flag (Z)

When the operation result is zero, this flag is set to 1. It is reset to 0 in all other cases.

(c) Auxiliary carry flag (AC)

If the operation result has a carry from bit 3 or a borrow at bit 3, this flag is set to 1. It is reset to 0 in all other cases.

(d) Carry flag (CY)

This flag stores overflow and underflow that have occurred upon add/subtract instruction execution. It stores the shift-out value upon rotate instruction execution and functions as a bit accumulator during bit operation instruction execution.

(3) Stack pointer (SP)

This is a 16-bit register to hold the start address of the memory stack area. Only the internal high-speed RAM area can be set as the stack area (Other than the internal high-speed RAM area cannot be set as the stack area).

Figure 3-9. Stack Pointer Configuration

	15															0
SP	SP15	SP14	SP13	SP12	SP11	SP10	SP9	SP8	SP7	SP6	SP5	SP4	SP3	SP2	SP1	SP0

The SP is decremented before writing (saving) to the stack memory and is incremented after reading (restoring) from the stack memory.

Each stack operation saves/restores data as shown in Figures 3-10 and 3-11.

Cautions 1. Since reset signal generation makes the SP contents undefined, be sure to initialize the SP before using the stack memory.

2. Stack pointers can be set only to the high-speed RAM area, and only the lower 10 bits can be actually set.

Thus, if the stack pointer is specified to 0FF00H, it is converted to 0FB00H in the high-speed RAM area, since 0FF00H is in the SFR area and not in the high-speed RAM area.

When the value is actually pushed onto the stack, 1 is subtracted from 0FB00H to become 0FAFFH, but since that value is not in the high-speed RAM area, it is converted to 0FEFFH, which is the same value as when 0FF00H is set to the stack pointer.

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Figure 3-10. Data to Be Saved to Stack Memory

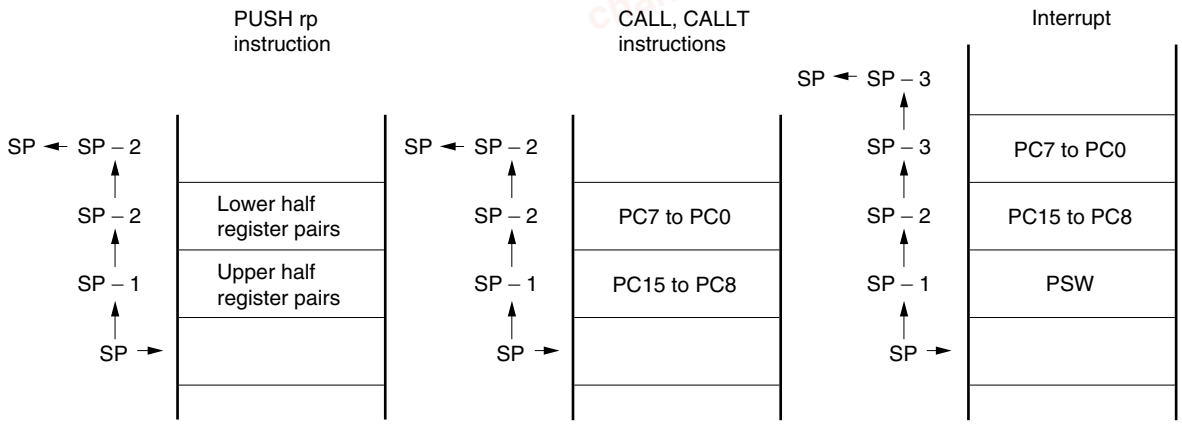
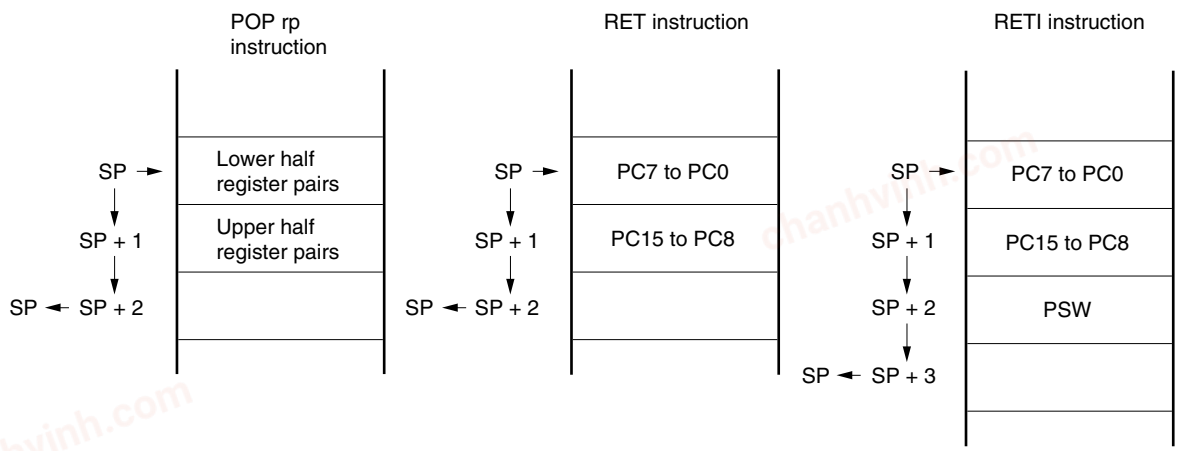


Figure 3-11. Data to Be Restored from Stack Memory



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3.2.2 General-purpose registers

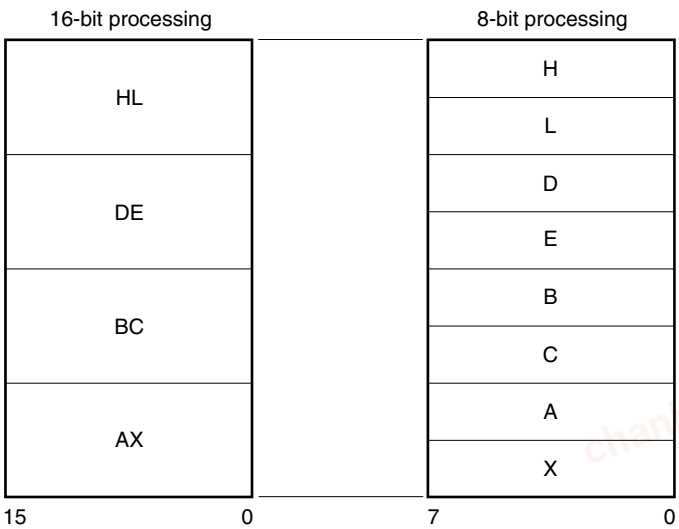
A general-purpose register consists of eight 8-bit registers (X, A, C, B, E, D, L, and H).

In addition each register being used as an 8-bit register, two 8-bit registers in pairs can be used as a 16-bit register (AX, BC, DE, and HL).

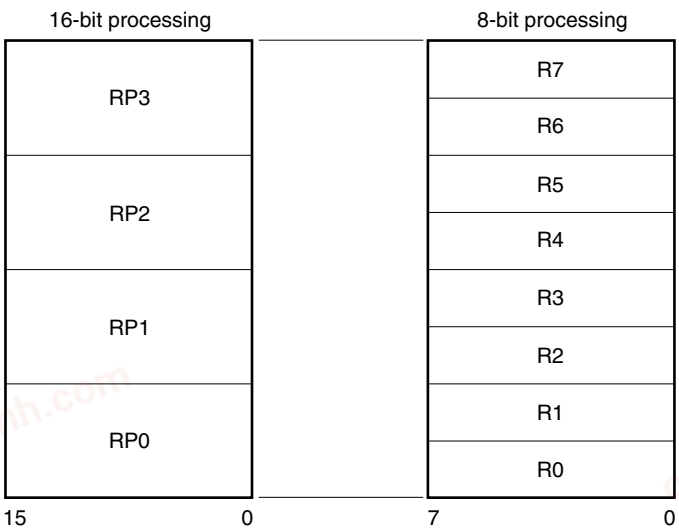
Registers can be described in terms of function names (X, A, C, B, E, D, L, H, AX, BC, DE, and HL) and absolute names (R0 to R7 and RP0 to RP3).

Figure 3-12. General-Purpose Register Configuration

(a) Function names



(b) Absolute names



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3.2.3 Special function registers (SFRs)

Unlike the general-purpose registers, each special function register has a special function.

The special function registers are allocated to the 256-byte area FF00H to FFFFH.

The special function registers can be manipulated, like the general-purpose registers, with operation, transfer, and bit manipulation instructions. Manipulatable bit units (1, 8, and 16) differ depending on the special function register type.

Each manipulation bit unit can be specified as follows.

- 1-bit manipulation
  Describes a symbol reserved by the assembler for the 1-bit manipulation instruction operand (sfr.bit). This manipulation can also be specified with an address and bit.

- 8-bit manipulation
  Describes a symbol reserved by the assembler for the 8-bit manipulation instruction operand (sfr). This manipulation can also be specified with an address.

- 16-bit manipulation
  Describes a symbol reserved by the assembler for the 16-bit manipulation instruction operand. When specifying an address, describe an even address.

Table 3-3 lists the special function registers. The meanings of the symbols in this table are as follows:

- Symbol
  Indicates the addresses of the implemented special function registers. It is defined as a reserved word in the RA78K0S, and is defined as an sfr variable using the #pragma sfr directive in the CC78K0S. Therefore, these symbols can be used as instruction operands if an assembler or integrated debugger is used.

- R/W
  Indicates whether the special function register can be read or written.
  R/W: Read/write
  R: Read only
  W: Write only

- Number of bits manipulated simultaneously
  Indicates the bit units (1, 8, and 16) in which the special function register can be manipulated.

- After reset
  Indicates the status of the special function register when a reset is input.

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Table 3-3. Special Function Registers (1/3)

Address	Symbol	Bit No.								R/W	Number of Bits Manipulated Simultaneously			After Reset	Reference page
		7	6	5	4	3	2	1	0		1	8	16		
FF00H, FF01H	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–
FF02H	P2	0	0	0	0	P23	P22	P21	P20	R/W Note 1	√	√	–	00H	69
FF03H	P3	0	0	0	P34	0	P32	0	0		√	√	–	00H	69
FF04H	P4	P47	P46	P45	P44	P43	P42	P41	P40		√	√	–	00H	69
FF05H to FF0DH	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–
FF0EH	CMP01	–	–	–	–	–	–	–	–	R/W	–	√	–	00H	133
FF0FH	CMP11	–	–	–	–	–	–	–	–		–	√	–	00H	133
FF10H, FF11H	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–
FF12H	TM00	–	–	–	–	–	–	–	–		–	–	√ Note 2	0000H	92
FF13H		–	–	–	–	–	–	–	–						
FF14H	CR000	–	–	–	–	–	–	–	–	R/W	–	–	√ Note 2	0000H	92
FF15H		–	–	–	–	–	–	–	–						
FF16H	CR010	–	–	–	–	–	–	–	–		–	–	√ Note 2	0000H	94
FF17H		–	–	–	–	–	–	–	–						
FF18H	ADCR Note 3	–	–	–	–	–	–	–	–	R	–	–	√ Note 2	Undefined	164
FF19H		0	0	0	0	0	0	–	–						
FF1AH	ADCRH Note 3	–	–	–	–	–	–	–	–		–	√	–		165
FF1BH to FF21H	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–
FF22H	PM2	1	1	1	1	PM23	PM22	PM21	PM20	R/W	√	√	–	FFH	68, 100, 136, 165
FF23H	PM3	1	1	1	1	1	PM32	1	1		√	√	–	FFH	68
FF24H	PM4	PM47	PM46	PM45	PM44	PM43	PM42	PM41	PM40		√	√	–	FFH	68
FF25H to FF31H	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–
FF32H	PU2	0	0	0	0	PU23	PU22	PU21	PU20	R/W	√	√	–	00H	71
FF33H	PU3	0	0	0	0	0	PU32	0	0		√	√	–	00H	71
FF34H	PU4	PU47	PU46	PU45	PU44	PU43	PU42	PU41	PU40	R/W	√	√	–	00H	71
FF35H to FF47H	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–
FF48H	WDTM	0	1	1	WDCS 4	WDCS 3	WDCS 2	WDCS 1	WDCS 0	R/W	–	√	–	67H	149
FF49H	WDTE	–	–	–	–	–	–	–	–		–	√	–	9AH	150

Notes 1. Only P34 is an input-only port.

2. A 16-bit access is possible only by the short direction addressing.

3. μPD78F921x only

Remark For a bit name enclosed in angle brackets (<>), the bit name is defined as a reserved word in the RA78K0S, and is defined as an sfr variable using the #pragma sfr directive in the CC78K0S.

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Table 3-3. Special Function Registers (2/3)

Address	Symbol	Bit No.								R/W	Number of Bits Manipulated Simultaneously			After Reset	Reference page
		7	6	5	4	3	2	1	0		1	8	16		
FF50H	LVIM	<LVION>	0	0	0	0	0	<LVIMD>	<LVIF>		√	√	–	00H Note 1	210
FF51H	LVIS	0	0	0	0	LVIS3	LVIS2	LVIS1	LVIS0		–	√	–	00H Note 1	211
FF52H, FF53H	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–
FF54H	RESF	0	0	0	WDTRF	0	0	0	LVIRF	R	–	√	–	00H Note 2	204
FF55H to FF57H	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–
FF58H	LSRCM	0	0	0	0	0	0	0	<LSRSTOP>	R/W	√	√	–	00H	77
FF59H to FF5FH	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–
FF60H	TMC00	0	0	0	0	TMC003	TMC002	TMC001	<OVF00>	R/W	√	√	–	00H	95
FF61H	PRM00	ES110	ES100	ES010	ES000	0	0	PRM001	PRM000		√	√	–	00H	99
FF62H	CRC00	0	0	0	0	0	CRC002	CRC001	CRC000		√	√	–	00H	97
FF63H	TOC00	0	<OSPT00>	<OSPE00>	TOC004	<LVS00>	<LVR00>	TOC001	<TOE00>		√	√	–	00H	98
FF64H to FF6FH	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–
FF70H	TMHMD1	<TMHE1>	CKS12	CKS11	CKS10	TMMD11	TMMD10	<TOLEV1>	<TOEN1>	R/W	√	√	–	00H	134
FF71H to FF7FH	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–
FF80H	ADM Note 3	<ADCS>	0	FR2	FR1	FR0	0	0	<ADCE>	R/W	√	√	–	00H	161
FF81H	ADS Note 3	0	0	0	0	0	0	ADS1	ADS0		√	√	–	00H	164
FF82H, FF83H	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–
FF84H	PMC2 Note 3	0	0	0	0	PMC23	PMC22	PMC21	PMC20	R/W	√	√	–	00H	69, 100, 136, 165
FF85H to FF9FH	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–

Notes 1. Retained only after a reset by LVI.

2. Varies depending on the reset cause.

3. μPD78F921x only

Remark For a bit name enclosed in angle brackets (<>), the bit name is defined as a reserved word in the RA78K0S, and is defined as an sfr variable using the #pragma sfr directive in the CC78K0S.

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Table 3-3. Special Function Registers (3/3)

Address	Symbol	Bit No.								R/W	Number of Bits Manipulated Simultaneously			After Reset	Reference page
		7	6	5	4	3	2	1	0		1	8	16		
FFA0H	PFCMD	REG7	REG6	REG5	REG4	REG3	REG2	REG1	REG0	W	–	√	–	Undefined	237
FFA1H	PFS	0	0	0	0	0	WEPRERR	VCERR	FPRERR	R/W	√	√	–	00H	237
FFA2H	FLPMC	0	PRSELF4	PRSELF3	PRSELF2	PRSELF1	PRSELF0	0	FLSPM		–	√	–	Undefined	236
FFA3H	FLCMD	0	0	0	0	0	FLCMD2	FLCMD1	FLCMD0		√	√	–	00H	239
FFA4H	FLAPL	FLAP7	FLAP6	FLAP5	FLAP4	FLAP3	FLAP2	FLAP1	FLAP0		√	√	–	Undefined	240
FFA5H	FLAPH	0	0	0	0	FLAP11	FLAP10	FLAP9	FLAP8		√	√	–		240
FFA6H	FLAPHC	0	0	0	0	FLAPC11	FLAPC10	FLAPC9	FLAPC8		√	√	–	00H	240
FFA7H	FLAPLC	FLAPC7	FLAPC6	FLAPC5	FLAPC4	FLAPC3	FLAPC2	FLAPC1	FLAPC0		√	√	–		240
FFA8H	FLW	FLW7	FLW6	FLW5	FLW4	FLW3	FLW2	FLW1	FLW0		–	√	–		241
FFA9H to FFDFH	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–
FFE0H	IF0	<ADIF> Note 1	<TMIF010>	<TMIF000>	<TMIFH1>	<PIF1>	<PIF0>	<LVIIF>	0	R/W	√	√	–	00H	180
FFE1H to FFE3H	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–
FFE4H	MK0	<ADMK> Note 1	<TMMK010>	<TMMK000>	<TMMKH1>	<PMK1>	<PMK0>	<LVIMK>	1	R/W	√	√	–	FFH	181
FFE5H to FFEBH	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–
FFECH	INTM0	0	0	ES11	ES10	ES01	ES00	0	0	R/W	–	√	–	00H	181
FFEDH to FFF2H	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–
FFF3H	PPCC	0	0	0	0	0	0	PPCC1	PPCC0	R/W	√	√	–	02H	76
FFF4H	OSTS	0	0	0	0	0	0	OSTS1	OSTS0		–	√	–	Undefined Note 2	78, 189
FFF5H to FFFAH	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–
FFFBH	PCC	0	0	0	0	0	0	PCC1	0	R/W	√	√	–	02H	76
FFFCH to FFFFH	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–

Notes 1. μPD78F921x only

2. The oscillation stabilization time that elapses after release of reset is selected by the option byte. For details, refer to **CHAPTER 15 OPTION BYTE**.

Remark For a bit name enclosed in angle brackets (<>), the bit name is defined as a reserved word in the RA78K0S, and is defined as an sfr variable using the #pragma sfr directive in the CC78K0S.

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3.3 Instruction Address Addressing

An instruction address is determined by the program counter (PC) contents. The PC contents are normally incremented (+1 for each byte) automatically according to the number of bytes of an instruction to be fetched each time another instruction is executed. When a branch instruction is executed, the branch destination address information is set to the PC to branch by the following addressing (for details of each instruction, refer to **78K/0S Series Instructions User's Manual (U11047E)**).

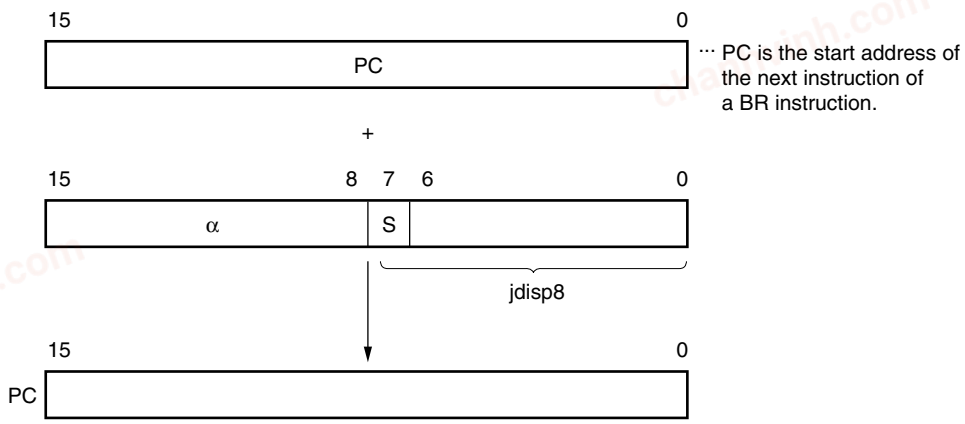
3.3.1 Relative addressing

[Function]

The value obtained by adding 8-bit immediate data (displacement value: jdisp8) of an instruction code to the start address of the following instruction is transferred to the program counter (PC) to branch. The displacement value is treated as signed two's complement data (–128 to +127) and bit 7 becomes the sign bit. In other words, the range of branch in relative addressing is between –128 and +127 of the start address of the following instruction.

This function is carried out when the BR $addr16 instruction or a conditional branch instruction is executed.

[Illustration]



When S = 0, α indicates that all bits are "0".
When S = 1, α indicates that all bits are "1".

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3.3.2 Immediate addressing

[Function]

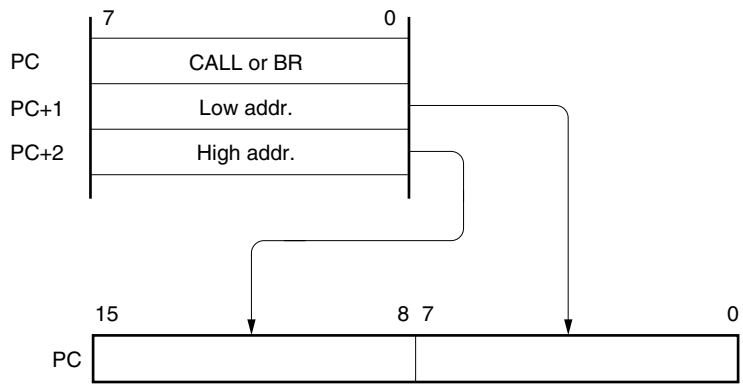
Immediate data in the instruction word is transferred to the program counter (PC) to branch.

This function is carried out when the CALL !addr16 and BR !addr16 instructions are executed.

CALL !addr16 and BR !addr16 instructions can be used to branch to all the memory spaces.

[Illustration]

In case of CALL !addr16 and BR !addr16 instructions



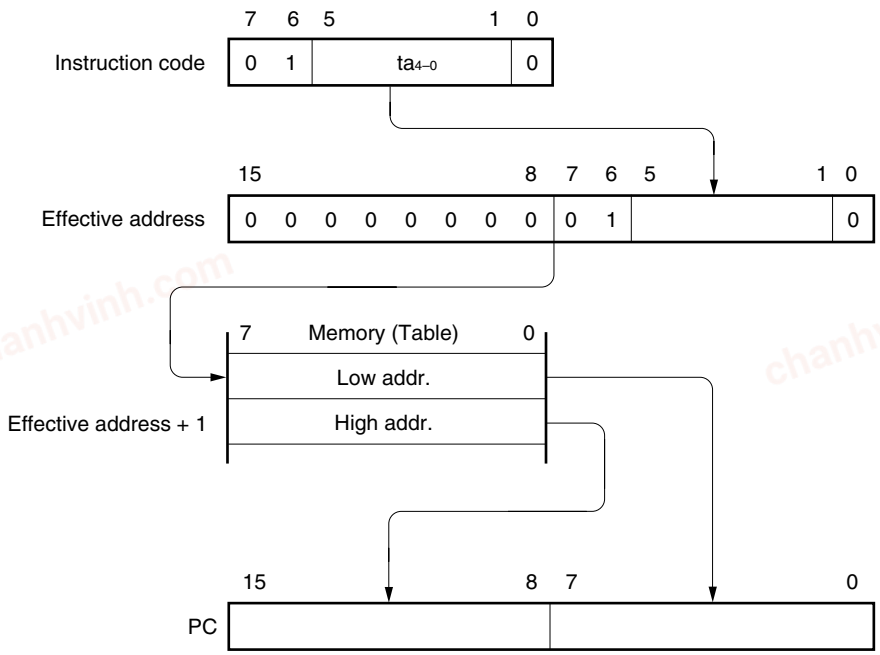
3.3.3 Table indirect addressing

[Function]

The table contents (branch destination address) of the particular location to be addressed by the immediate data of an instruction code from bit 1 to bit 5 are transferred to the program counter (PC) to branch.

Table indirect addressing is carried out when the CALLT [addr5] instruction is executed. This instruction can be used to branch to all the memory spaces according to the address stored in the memory table 40H to 7FH.

[Illustration]



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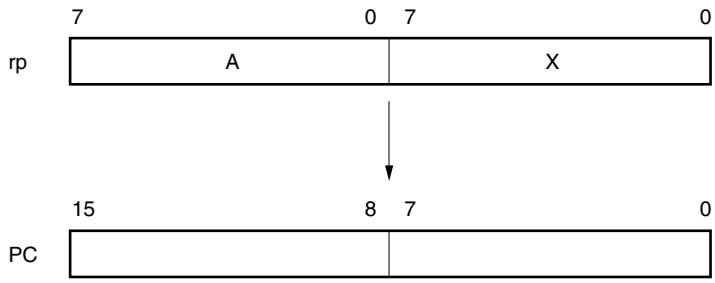
3.3.4 Register addressing

[Function]

The register pair (AX) contents to be specified with an instruction word are transferred to the program counter (PC) to branch.

This function is carried out when the BR AX instruction is executed.

[Illustration]



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3.4 Operand Address Addressing

The following methods (addressing) are available to specify the register and memory to undergo manipulation during instruction execution.

3.4.1 Direct addressing

[Function]

The memory indicated by immediate data in an instruction word is directly addressed.

[Operand format]

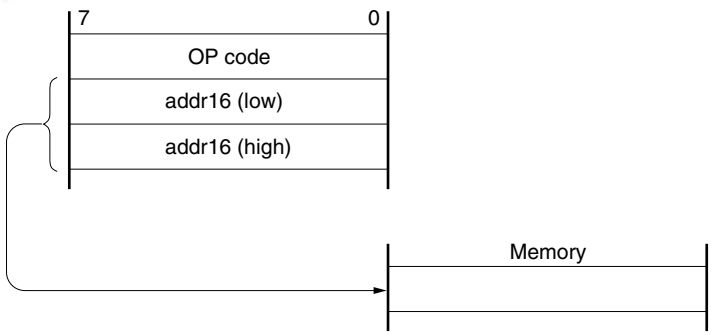
Identifier	Description
addr16	Label or 16-bit immediate data

[Description example]

MOV A, !FE80H; When setting !addr16 to FE80H

Instruction code	0	0	1	0	1	0	0	1	OP code
	1	0	0	0	0	0	0	0	80H
	1	1	1	1	1	1	1	0	FEH

[Illustration]



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3.4.2 Short direct addressing

[Function]

The memory to be manipulated in the fixed space is directly addressed with the 8-bit data in an instruction word.

The fixed space where this addressing is applied is the 160-byte space FE80H to FF1FH (FE80H to FEFFH (internal high-speed RAM) + FF00H to FF1FH (special function registers)).

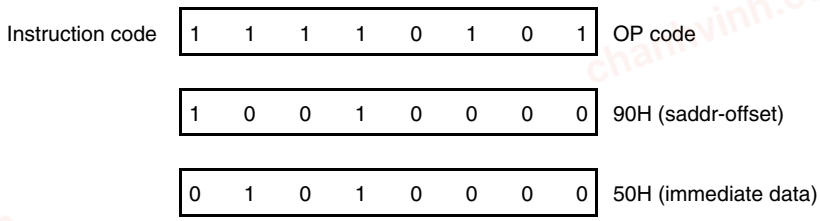
The SFR area where short direct addressing is applied (FF00H to FF1FH) is a part of the total SFR area. In this area, ports which are frequently accessed in a program and a compare register of the timer counter are mapped, and these SFRs can be manipulated with a small number of bytes and clocks.

When 8-bit immediate data is at 80H to FFH, bit 8 of an effective address is cleared to 0. When it is at 00H to 1FH, bit 8 is set to 1. See **[Illustration]** below.

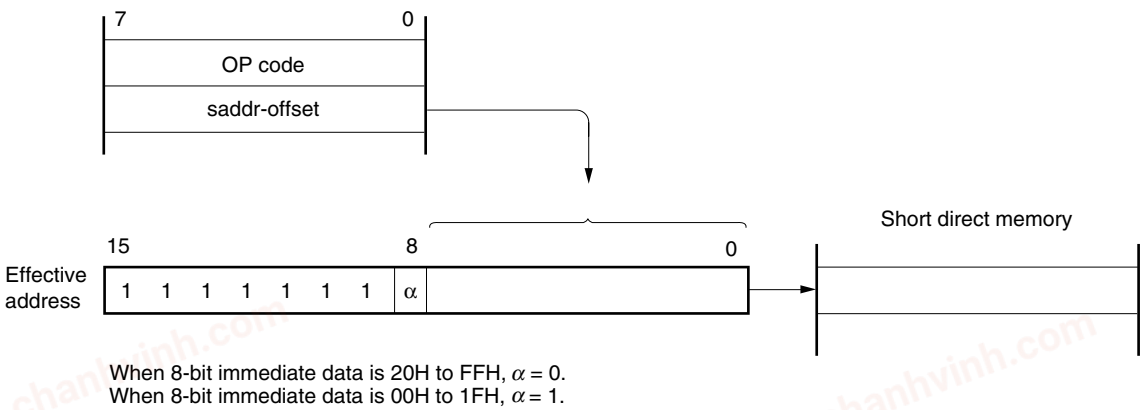
Identifier	Description
saddr	Label or FE80H to FF1FH immediate data
saddrp	Label or FE80H to FF1FH immediate data (even address only)

[Description example]

```
EQU DATA1 0FE90H  ; DATA1 shows FE90H of a saddr area,
MOV DATA1, #50H   ; When setting the immediate data to 50H
```



[Illustration]



When 8-bit immediate data is 20H to FFH, $\alpha = 0$.
When 8-bit immediate data is 00H to 1FH, $\alpha = 1$.

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3.4.3 Special function register (SFR) addressing

[Function]

A memory-mapped special function register (SFR) is addressed with the 8-bit immediate data in an instruction word.

This addressing is applied to the 256-byte space FF00H to FFFFH. However, SFRs mapped at FF00H to FF1FH are accessed with short direct addressing.

[Operand format]

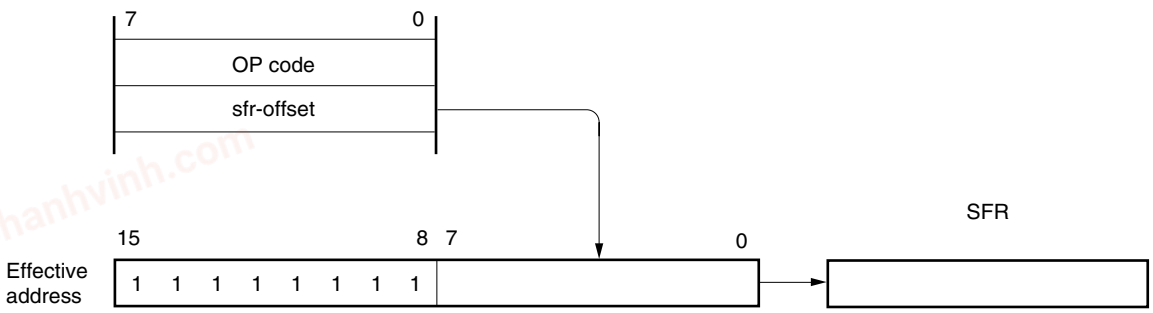
Identifier	Description
sfr	Special function register name

[Description example]

MOV PM0, A; When selecting PM0 for sfr

Instruction code	1	1	1	0	0	1	1	1
	0	0	1	0	0	0	0	0

[Illustration]



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3.4.4 Register addressing

[Function]

A general-purpose register is accessed as an operand.

The general-purpose register to be accessed is specified with the register specify code and functional name in the instruction code.

Register addressing is carried out when an instruction with the following operand format is executed. When an 8-bit register is specified, one of the eight registers is specified with 3 bits in the instruction code.

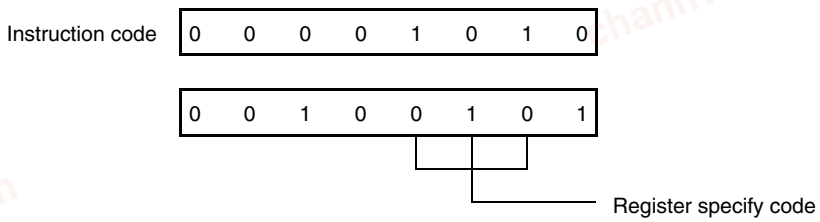
[Operand format]

Identifier	Description
r	X, A, C, B, E, D, L, H
rp	AX, BC, DE, HL

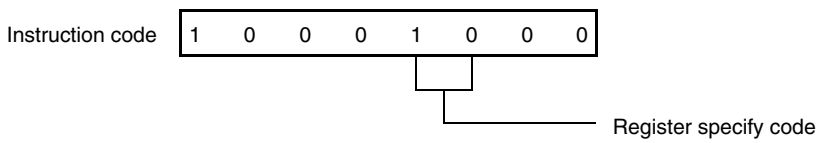
'r' and 'rp' can be described with absolute names (R0 to R7 and RP0 to RP3) as well as function names (X, A, C, B, E, D, L, H, AX, BC, DE, and HL).

[Description example]

MOV A, C; When selecting the C register for r



INCW DE; When selecting the DE register pair for rp



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3.4.5 Register indirect addressing

[Function]

The memory is addressed with the contents of the register pair specified as an operand. The register pair to be accessed is specified with the register pair specify code in the instruction code. This addressing can be carried out for all the memory spaces.

[Operand format]

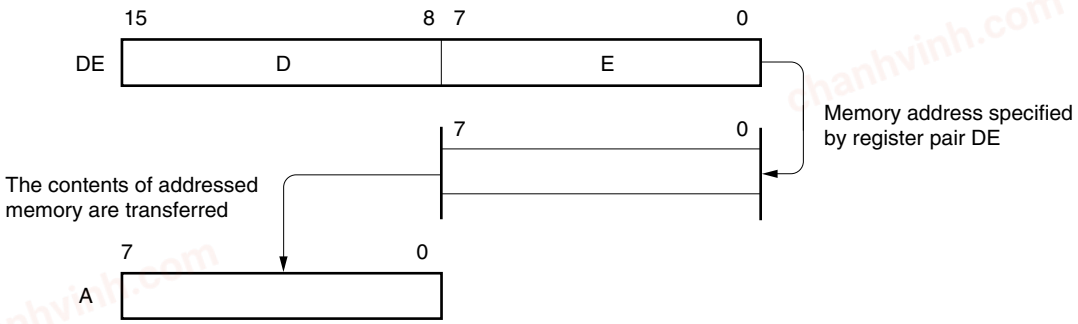
Identifier	Description
–	[DE], [HL]

[Description example]

MOV A, [DE]; When selecting register pair [DE]

Instruction code	0	0	1	0	1	0	1	1

[Illustration]



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3.4.6 Based addressing

[Function]

8-bit immediate data is added to the contents of the base register, that is, the HL register pair, and the sum is used to address the memory. Addition is performed by expanding the offset data as a positive number to 16 bits. A carry from the 16th bit is ignored. This addressing can be carried out for all the memory spaces.

[Operand format]

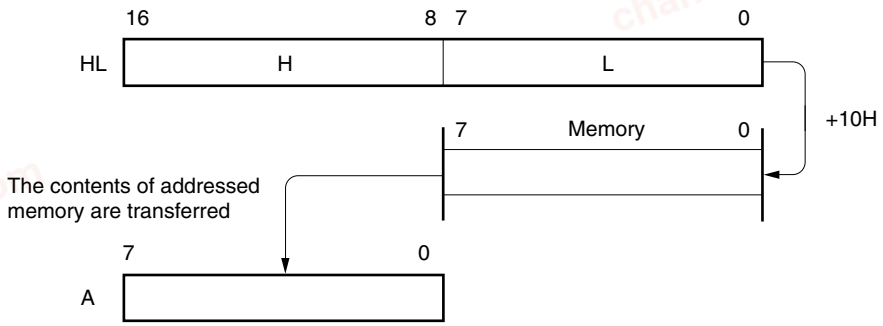
Identifier	Description
–	[HL+byte]

[Description example]

MOV A, [HL+10H]; When setting byte to 10H

Instruction code	0	0	1	0	1	1	0	1
	0	0	0	1	0	0	0	0

[Illustration]



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3.4.7 Stack addressing

[Function]

The stack area is indirectly addressed with the stack pointer (SP) contents.

This addressing method is automatically employed when the PUSH, POP, subroutine call, and return instructions are executed or the register is saved/restored upon interrupt request generation.

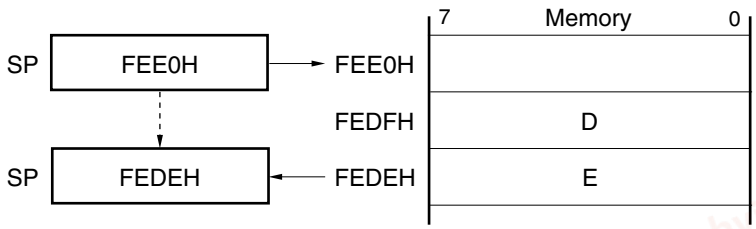
Stack addressing can be used to access the internal high-speed RAM area only.

[Description example]

In the case of PUSH DE

Instruction code	1	0	1	0	1	0	1	0

[Illustration]



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CHAPTER 4 PORT FUNCTIONS

4.1 Functions of Ports

The 78K0S/KY1+ has the ports shown in Figure 4-1, which can be used for various control operations. Table 4-1 shows the functions of each port.

In addition to digital I/O port functions, each of these ports has an alternate function. For details, refer to **CHAPTER 2 PIN FUNCTIONS**.

Figure 4-1. Port Functions

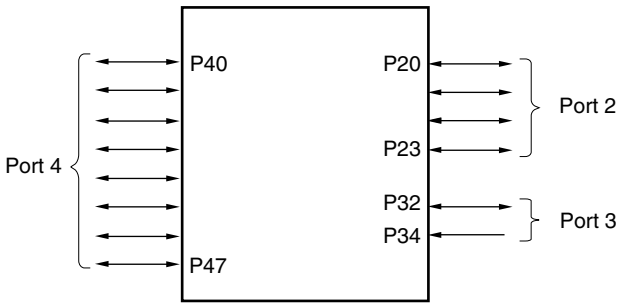


Table 4-1. Port Functions

Pin Name	I/O	Function		After Reset	Alternate-Function Pin
P20	I/O	Port 2. 4-bit I/O port. Can be set to input or output mode in 1-bit units. On-chip pull-up resistor can be connected by setting software.		Input	ANI0 Note 2/TI000/TOH1
P21					ANI1 Note 2/TI010/TO00/INTP0
P22 Note 1					X2/ANI2 Notes 1,2
P23 Note 1					X1/ANI3 Notes 1,2
P32	I/O	Port 3	Can be set to input or output mode in 1-bit units. On-chip pull-up resistor can be connected by setting software.	Input	INTP1
P34 Note 1	Input		Input only	Input	$\overline{\text{RESET}}$ Note 1
P40 to P47	I/O	Port 4. 8-bit I/O port. Can be set to input or output mode in 1-bit units. On-chip pull-up resistor can be connected setting software.		Input	–

Notes 1. For the setting method for pin functions, see **CHAPTER 15 OPTION BYTE**.

<R> **2.** μPD78F921x only

Caution The P22/X2/ANI2 and P23/X1/ANI3 pins are pulled down during reset.

Remarks 1. P22 and P23 can be allocated when the high-speed internal oscillation is selected as the system clock.

2. P22 can be allocated when an external clock input is selected as the system clock.

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4.2 Port Configuration

Ports consist of the following hardware units.

Table 4-2. Configuration of Ports

Item	Configuration
Control registers	Port mode registers (PM2 to PM4) Port registers (P2 to P4) Port mode control register 2 (PMC2) (μPD78F921x only) Pull-up resistor option registers (PU2 to PU4)
Ports	Total: 14 (CMOS I/O: 13, CMOS input: 1)
Pull-up resistor	Total: 13

4.2.1 Port 2

Port 2 is a 4-bit I/O port with an output latch. Each bit of this port can be set to the input or output mode by using port mode register 2 (PM2). When the P20 to P23 pins are used as an input port, an on-chip pull-up resistor can be connected in 1-bit units by using pull-up resistor option register 2 (PU2).

This port can also be used for A/D converter analog input[Note], timer I/O, and external interrupt request input.

The P22 and P23 pins are also used as the X2 and X1 pins of the system clock oscillator. The functions of the P22 and P23 pins differ, therefore, depending on the selected system clock oscillator. The following three system clock oscillators can be used.

(1) High-speed internal oscillator

The P22 and P23 pins can be used as I/O port pins or analog input pins to the A/D converter[Note].

(2) Crystal/ceramic oscillator

The P22 and P23 pins cannot be used as I/O port pins or analog input pins to the A/D converter[Note] because they are used as the X2 and X1 pins.

(3) External clock input

The P22 pin can be used as an I/O port pin or an analog input pin to the A/D converter[Note].

The P23 pin is used as the X1 pin to input an external clock, and therefore it cannot be used as an I/O port pin or an analog input pin to the A/D converter[Note].

The system clock oscillation is selected by the option byte. For details, refer to **CHAPTER 15 OPTION BYTE**.

Reset signal generation sets port 2 to the input mode.

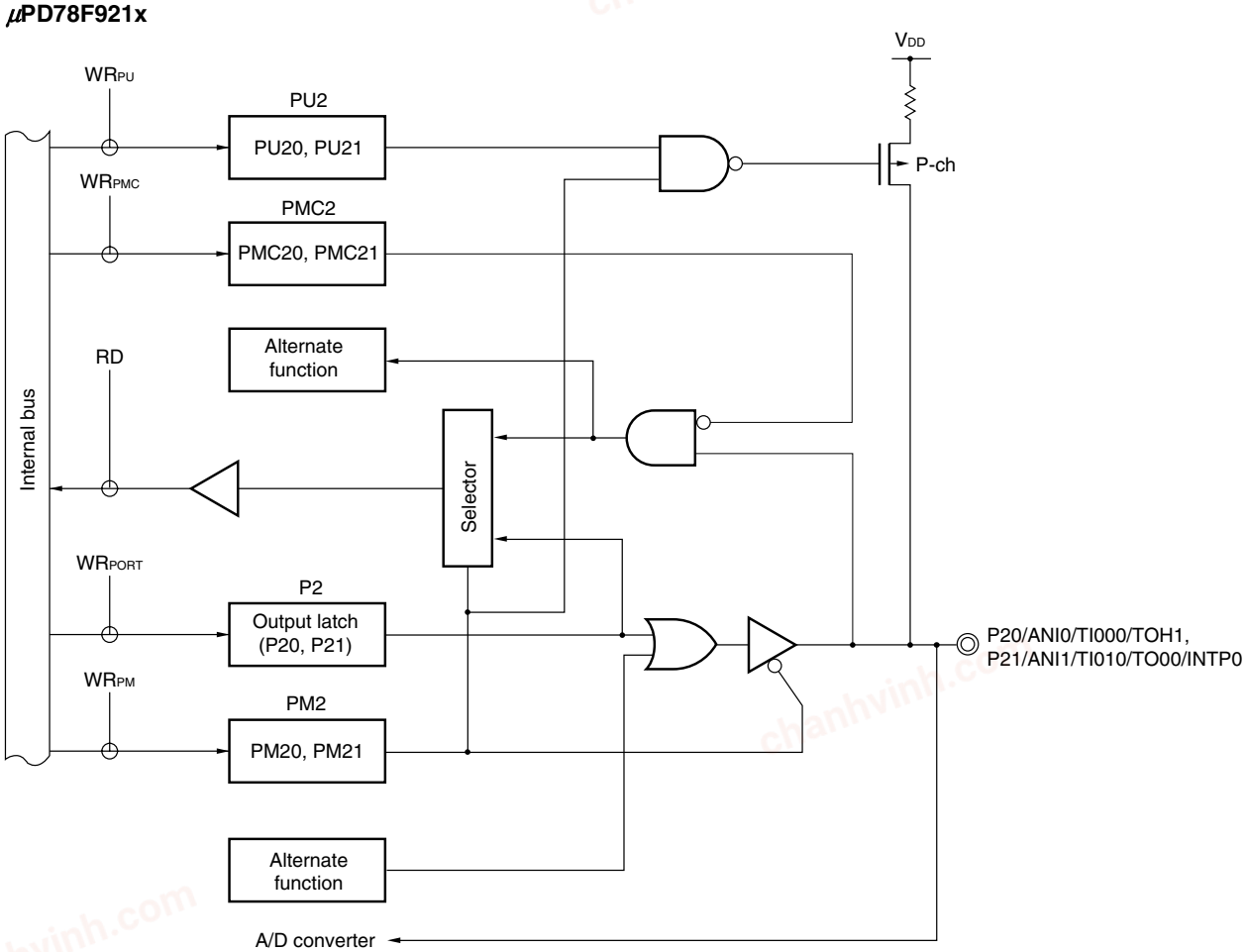
Figures 4-2 to 4-4 show the block diagrams of port 2.

<R> **Note** μPD78F921x only

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Figure 4-2. Block Diagram of P20 and P21 (1/2)

(1) μPD78F921x

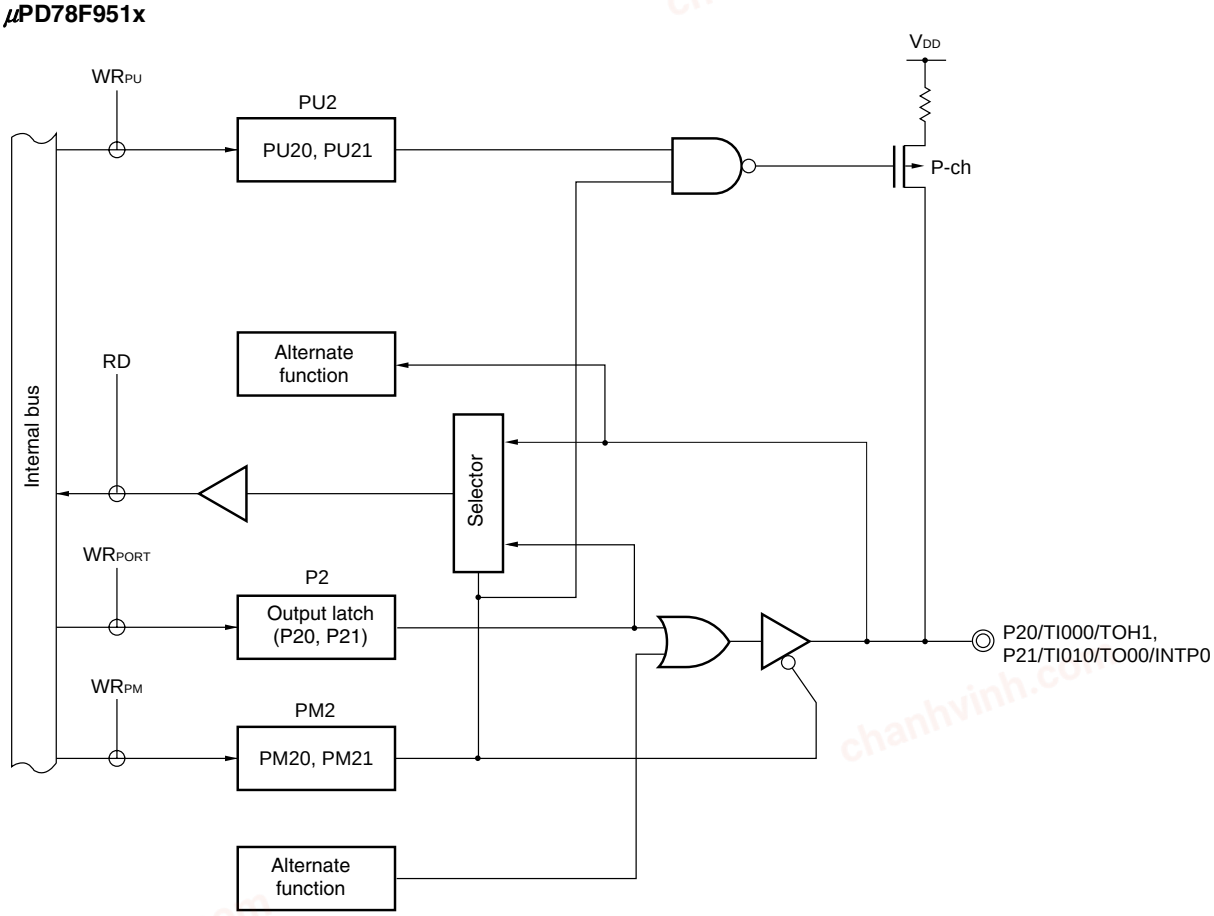


P2: Port register 2
PU2: Pull-up resistor option register 2
PM2: Port mode register 2
PMC2: Port mode control register 2
RD: Read signal
WR××: Write signal

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Figure 4-2. Block Diagram of P20 and P21 (2/2)

<R> **(2) μPD78F951x**

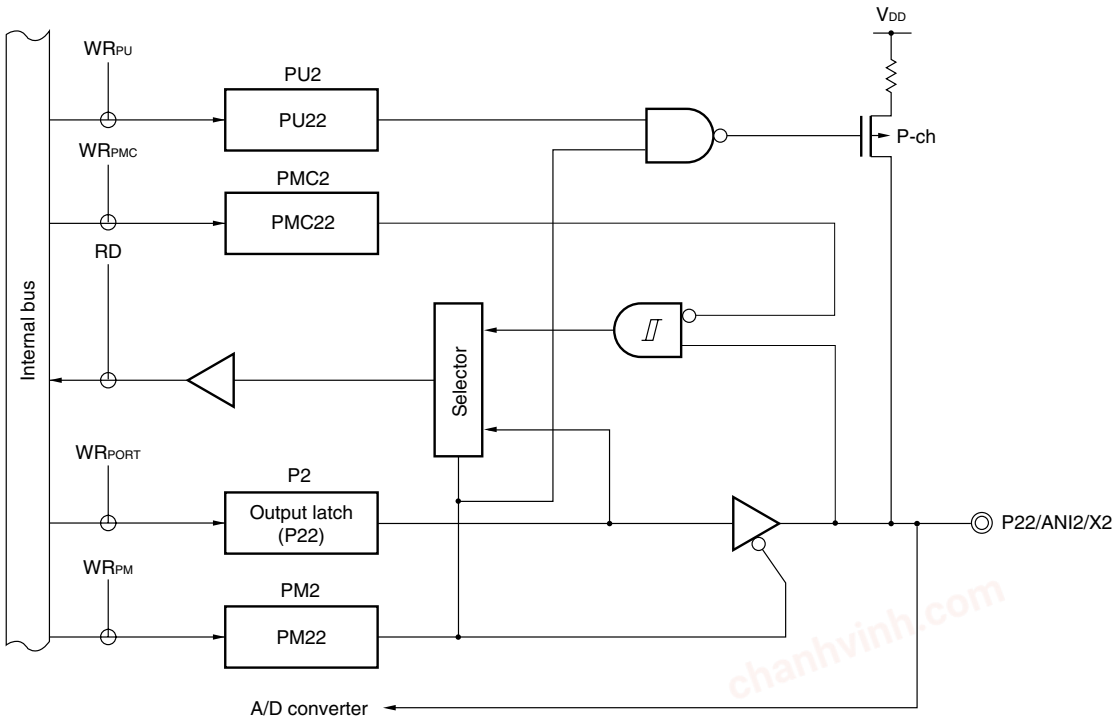


P2: Port register 2
PU2: Pull-up resistor option register 2
PM2: Port mode register 2
RD: Read signal
WR××: Write signal

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Figure 4-3. Block Diagram of P22 (1/2)

(1) μPD78F921x

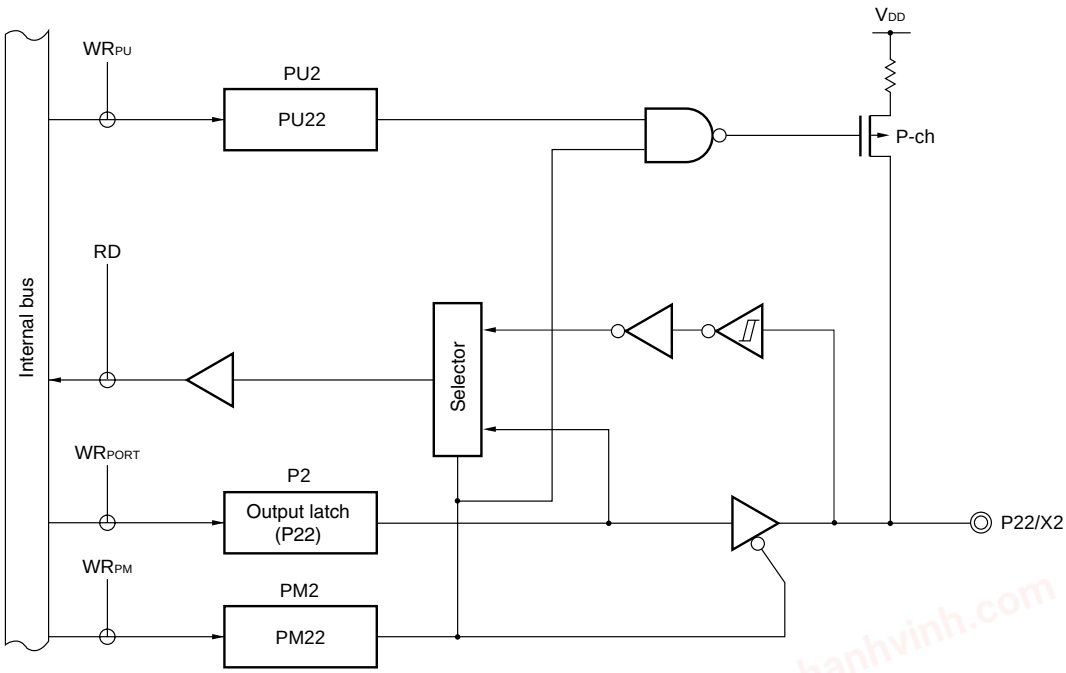


P2: Port register 2
PU2: Pull-up resistor option register 2
PM2: Port mode register 2
PMC2: Port mode control register 2
RD: Read signal
WR××: Write signal

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Figure 4-3. Block Diagram of P22 (2/2)

<R> **(2) μPD78F951x**

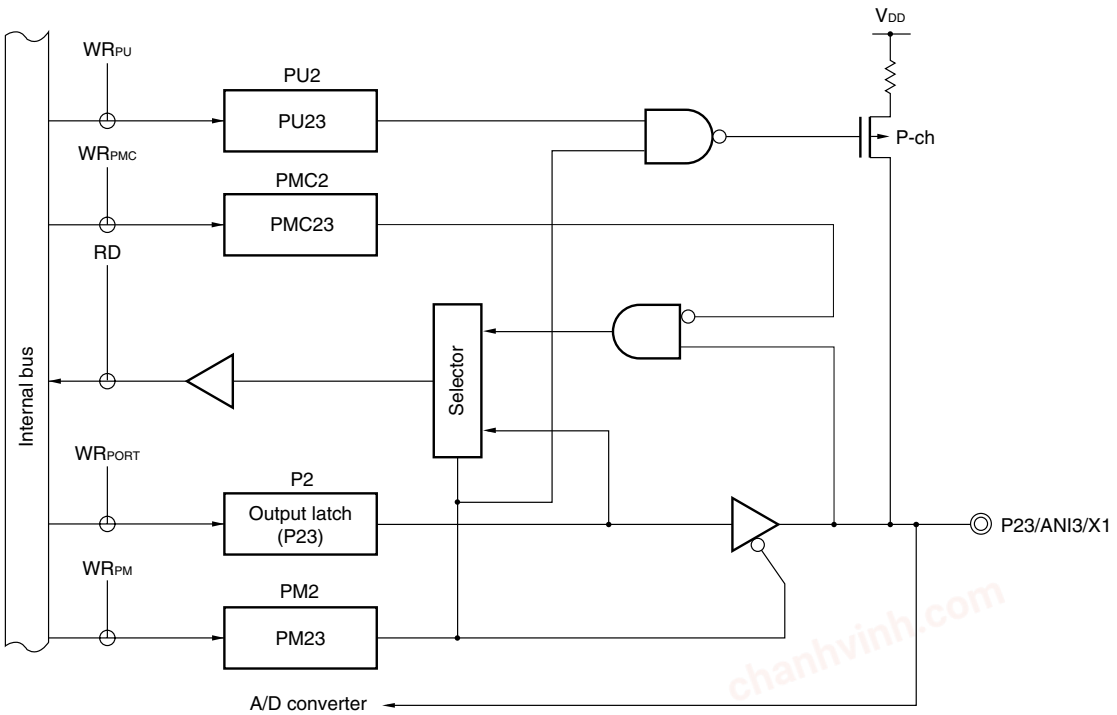


P2: Port register 2
PU2: Pull-up resistor option register 2
PM2: Port mode register 2
RD: Read signal
WR××: Write signal

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Figure 4-4. Block Diagram of P23 (1/2)

(1) μPD78F921x

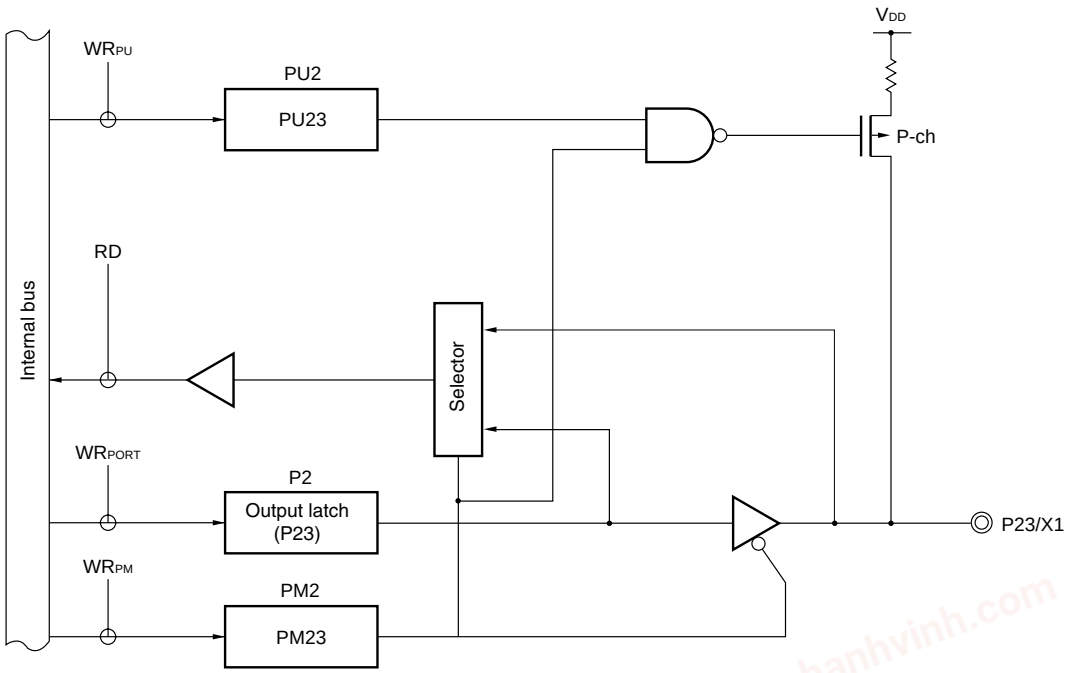


P2: Port register 2
PU2: Pull-up resistor option register 2
PM2: Port mode register 2
PMC2: Port mode control register 2
RD: Read signal
WR××: Write signal

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Figure 4-4. Block Diagram of P23 (2/2)

<R> **(2) μPD78F951x**



P2: Port register 2
PU2: Pull-up resistor option register 2
PM2: Port mode register 2
RD: Read signal
WR××: Write signal

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4.2.2 Port 3

The P32 pin is a 1-bit I/O port with an output latch. This pin can be set to the input or output mode by using port mode register 3 (PM3). When this pin is used as an input port, an on-chip pull-up resistor can be connected in 1-bit units by using pull-up resistor option register 3 (PU3). This pin can also be used for external interrupt request input.

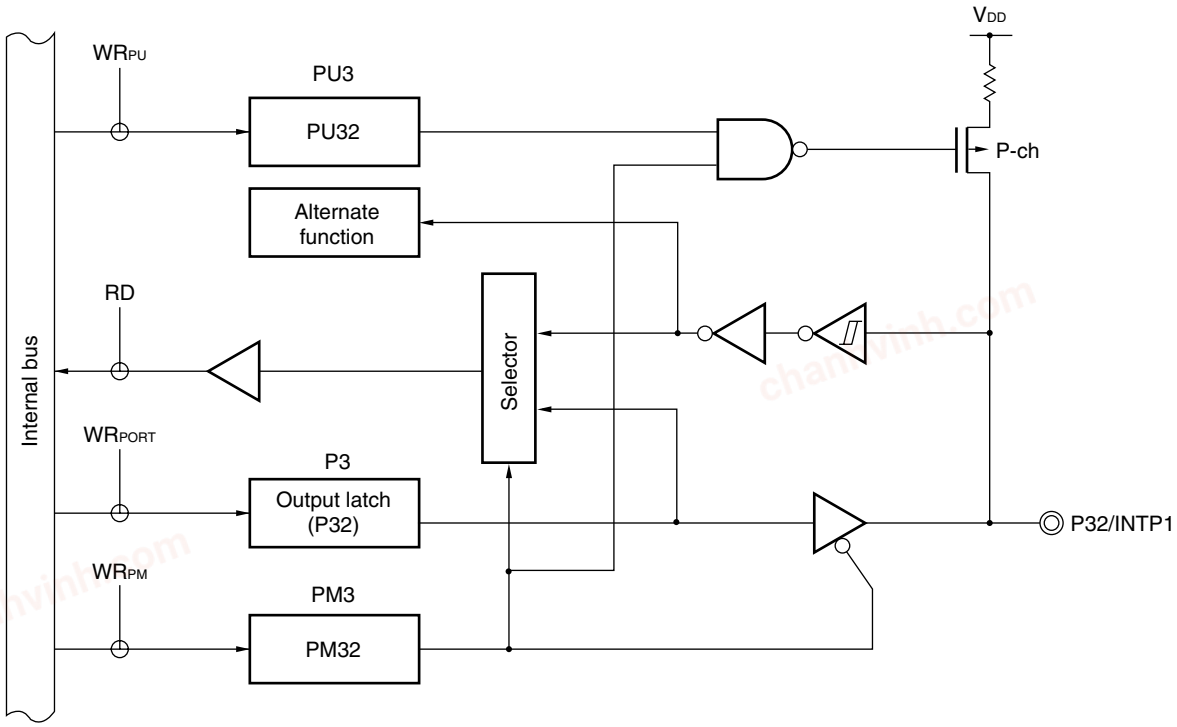
The P32 pin is a Reset signal generation sets port 3 to the input mode.

The P34 pin is a 1-bit input-only port. This pin is also used as a $\overline{\text{RESET}}$ pin, and when the power is turned on, this is the reset function. For the setting method for pin functions, see **CHAPTER 15 OPTION BYTE**.

When P34 is used as an input port pin, connect the pull-up resistor.

Figures 4-5 and 4-6 show the block diagrams of port 3.

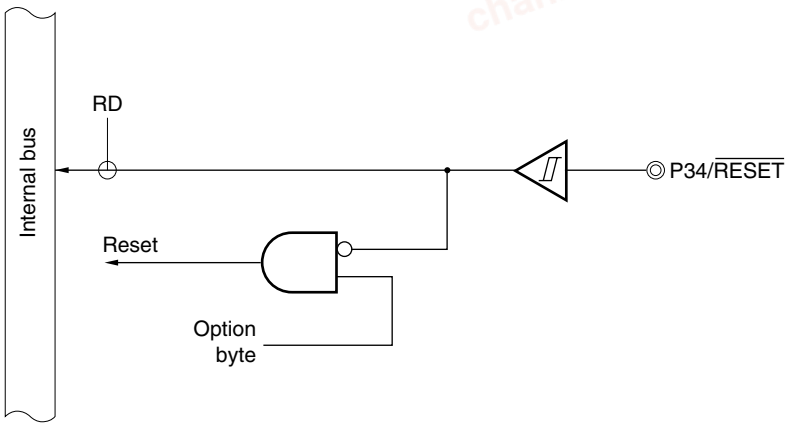
Figure 4-5. Block Diagram of P32



P3: Port register 3
PU3: Pull-up resistor option register 3
PM3: Port mode register 3
RD: Read signal
WR××: Write signal

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Figure 4-6. Block Diagram of P34



RD: Read signal

Caution Because the P34 pin functions alternately as the $\overline{\text{RESET}}$ pin, if it is used as an input port pin, the function to input an external reset signal to the $\overline{\text{RESET}}$ pin cannot be used. The function of the port is selected by the option byte. For details, refer to CHAPTER 15 OPTION BYTE.
Also, since the option byte is referenced after the reset release, if low level is input to the $\overline{\text{RESET}}$ pin before the referencing, then the reset state is not released. When it is used as an input port pin, connect the pull-up resistor.

4.2.3 Port 4

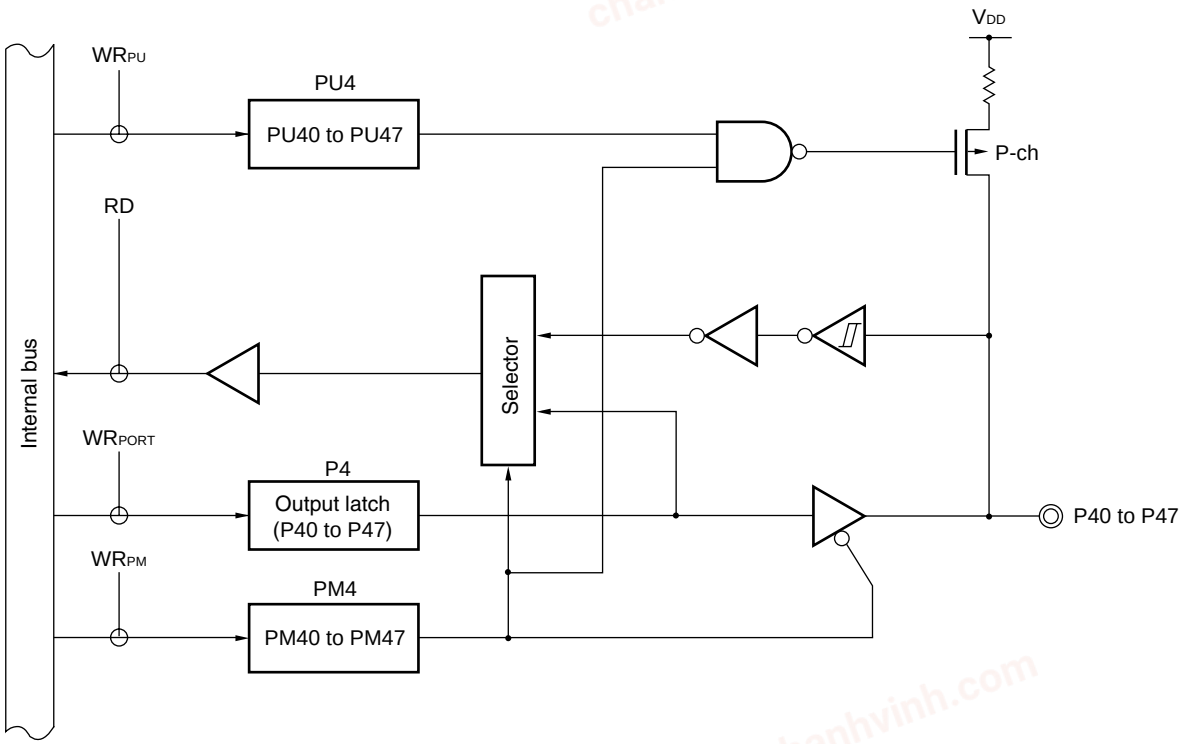
Port 4 is an 8-bit I/O port with an output latch. Each bit of this port can be set to the input or output mode by using port mode register 4 (PM4). When the P40 to P47 pins are used as an input port, an on-chip pull-up resistor can be connected in 1-bit units by using pull-up resistor option register 4 (PU4).

Reset signal generation sets port 4 to the input mode.

Figure 4-7 shows the block diagram of port 4.

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Figure 4-7. Block Diagram of P40 to P47



P4: Port register 4
PU4: Pull-up resistor option register 4
PM4: Port mode register 4
RD: Read signal
WR××: Write signal

4.3 Registers Controlling Port Functions

The ports are controlled by the following four types of registers.

- Port mode registers (PM2 to PM4)
- Port registers (P2 to P4)
<R> - Port mode control register 2 (PMC2) (μPD78F921x only)
- Pull-up resistor option registers (PU2 to PU4)

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(1) Port mode registers (PM2 to PM4)

These registers are used to set the corresponding port to the input or output mode in 1-bit units.

Each port mode register can be set by a 1-bit or 8-bit memory manipulation instruction.

Reset signal generation sets these registers to FFH.

When a port pin is used as an alternate-function pin, set its port mode register and output latch as shown in Table 4-3.

Caution Because P21 and P32 are also used as external interrupt pins, the corresponding interrupt request flag is set if each of these pins is set to the output mode and its output level is changed. To use the port pin in the output mode, therefore, set the corresponding interrupt mask flag to 1 in advance.

Figure 4-8. Format of Port Mode Register

Address: FF22H, After reset: FFH, R/W

Symbol	7	6	5	4	3	2	1	0
PM2	1	1	1	1	PM23	PM22	PM21	PM20

Address: FF23H, After reset: FFH, R/W

Symbol	7	6	5	4	3	2	1	0
PM3	1	1	1	1	1	PM32	1	1

Address: FF24H, After reset: FFH, R/W

Symbol	7	6	5	4	3	2	1	0
PM4	PM47	PM46	PM45	PM44	PM43	PM42	PM41	PM40

PMmn	Selection of I/O mode of Pmn pin (m = 2 to 4; n = 0 to 7)
0	Output mode (output buffer ON)
1	Input mode (output buffer OFF)

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(2) Port registers (P2 to P4)

These registers are used to write data to be output from the corresponding port pin to an external device connected to the chip.

When a port register is read, the pin level is read in the input mode, and the value of the output latch of the port is read in the output mode.

P20 to P23, P32, and P40 to P47 are set by using a 1-bit or 8-bit memory manipulation instruction.

Reset signal generation sets these registers to 00H.

Figure 4-9. Format of Port Register

Address: FF02H, After reset: 00H (Output latch) R/W

Symbol	7	6	5	4	3	2	1	0
P2	0	0	0	0	P23	P22	P21	P20

Address: FF03H, After reset: 00H[Note] (Output latch) R/W[Note]

Symbol	7	6	5	4	3	2	1	0
P3	0	0	0	P34	0	P32	0	0

Address: FF04H, After reset: 00H (Output latch) R/W

Symbol	7	6	5	4	3	2	1	0
P4	P47	P46	P45	P44	P43	P42	P41	P40

Pmn	m = 2 to 4; n = 0 to 7	
	Controls of output data (in output mode)	Input data read (in input mode)
0	Output 0	Input low level
1	Output 1	Input high level

Note Because P34 is read-only, its reset value is undefined.

<R>

(3) Port mode control register 2 (PMC2) (μPD78F921x only)

This register specifies the port/alternate function (except the A/D converter function) mode or the A/D converter mode.

Each bit of the PMC2 register corresponds to each pin of port 2 and can be specified in 1-bit units.

PMC2 is set by using a 1-bit or 8-bit memory manipulation instruction.

Reset signal generation sets PMC2 to 00H.

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Figure 4-10. Format of Port Mode Control Register 2 (μPD78F921x only)

Address: FF84H, After reset: R/W

Symbol	7	6	5	4	3	2	1	0
PMC2	0	0	0	0	PMC23	PMC22	PMC21	PMC20

PMC2n	Specification of operation mode (n = 0 to 3)
0	Port/alternate-function (except the A/D converter function) mode
1	A/D converter mode

Caution When PMC20 to PMC23 are set to 1, the port function on the P20/ANI0 to P23/ANI3 pins cannot be used. Moreover, be sure to set the pull-up resistor option registers (PU20 to PU23) to 0 for the pins set to A/D converter mode.

Table 4-3. Setting of Port Mode Register, Port Register (Output Latch), and Port Mode Control Register When Alternate Function Is Used

Port Name	Alternate-Function Pin		PM××	P××	PMC2n (n = 0 to 3) Note
	Name	I/O			
P20	ANI0 Note	Input	1	×	1
	TI000	Input	1	×	0
	TOH1	Output	0	0	0
P21	ANI1 Note	Input	1	×	1
	TI010	Input	1	×	0
	TO00	Output	0	0	0
	INTP0	Input	1	×	0
P22	ANI2 Note	Input	1	×	1
P23	ANI3 Note	Input	1	×	1
P32	INTP1	Input	1	×	–

<R> **Note** μPD78F921x only

Remark ×: don't care
PM××: Port mode register, P××: Port register (output latch of port)
PMC2×: Port mode control register

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(4) Pull-up resistor option registers (PU2 to PU4)

These registers are used to specify whether an on-chip pull-up resistor is connected to P20 to P23, P32, and P40 to P47. By setting PU2 to PU4, an on-chip pull-up resistor can be connected to the port pin corresponding to the bit of PU2 to PU4.

PU2 to PU4 are set by using a 1-bit or 8-bit memory manipulation instruction.

Reset signal generation set these registers to 00H.

Figure 4-11. Format of Pull-up Resistor Option Register

Address: FF32H, After reset: 00H R/W

Symbol	7	6	5	4	3	2	1	0
PU2	0	0	0	0	PU23	PU22	PU21	PU20

Address: FF33H, After reset: 00H R/W

Symbol	7	6	5	4	3	2	1	0
PU3	0	0	0	0	0	PU32	0	0

Address: FF34H, After reset: 00H R/W

Symbol	7	6	5	4	3	2	1	0
PU4	PU47	PU46	PU45	PU44	PU43	PU42	PU41	PU40

PUmn	Selection of connection of on-chip pull-up resistor of Pmn (m = 2 to 4; n = 0 to 7)
0	Does not connect on-chip pull-up resistor
1	Connects on-chip pull-up resistor

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4.4 Operation of Port Function

The operation of a port differs, as follows, depending on the setting of the I/O mode.

Caution Although a 1-bit memory manipulation instruction manipulates 1 bit, it accesses a port in 8-bit units. Therefore, the contents of the output latch of a pin in the input mode, even if it is not subject to manipulation by the instruction, are undefined in a port with a mixture of inputs and outputs.

4.4.1 Writing to I/O port

(1) In output mode

A value can be written to the output latch by a transfer instruction. In addition, the contents of the output latch are output from the pin. Once data is written to the output latch, it is retained until new data is written to the output latch.

When a reset signal is generated, cleans the data in the output latch.

(2) In input mode

A value can be written to the output latch by a transfer instruction. Because the output buffer is off, however, the pin status remains unchanged.

Once data is written to the output latch, it is retained until new data is written to the output latch.

When a reset signal is generated, cleans the data in the output latch.

4.4.2 Reading from I/O port

(1) In output mode

The contents of the output latch can be read by a transfer instruction. The contents of the output latch remain unchanged.

(2) In input mode

The pin status can be read by a transfer instruction. The contents of the output latch remain unchanged.

4.4.3 Operations on I/O port

(1) In output mode

An operation is performed on the contents of the output latch and the result is written to the output latch. The contents of the output latch are output from the pin.

Once data is written to the output latch, it is retained until new data is written to the output latch.

Reset signal generation clears the data in the output latch.

(2) In input mode

The pin level is read and an operation is performed on its contents. The operation result is written to the output latch. However, the pin status remains unchanged because the output buffer is off.

When a reset signal is generated, cleans the data in the output latch.

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CHAPTER 5 CLOCK GENERATORS

5.1 Functions of Clock Generators

The clock generators include a circuit that generates a clock (system clock) to be supplied to the CPU and peripheral hardware, and a circuit that generates a clock (interval time generation clock) to be supplied to the watchdog timer and 8-bit timer H1 (TMH1).

5.1.1 System clock oscillators

The following three types of system clock oscillators are used.

- High-speed internal oscillator
  This circuit internally oscillates a clock of 8 MHz (TYP.). Its oscillation can be stopped by execution of the STOP instruction.
  If the High-speed internal oscillator is selected to supply the system clock, the X1 and X2 pins can be used as I/O port pins.

- Crystal/ceramic oscillator
  This circuit oscillates a clock with a crystal/ceramic oscillator connected across the X1 and X2 pins. It can oscillate a clock of 2 MHz to 10 MHz. Oscillation of this circuit can be stopped by execution of the STOP instruction.

- External clock input circuit
  This circuit supplies a clock from an external IC to the X1 pin. A clock of 2 MHz to 10 MHz can be supplied. Internal clock supply can be stopped by execution of the STOP instruction.
  If the external clock input is selected as the system clock, the X2 pin can be used as an I/O port pin.

The system clock source is selected by using the option byte. For details, refer to **CHAPTER 15 OPTION BYTE**.
When using the X1 and X2 pins as I/O port pins, refer to **CHAPTER 4 PORT FUNCTIONS** for details.

5.1.2 Clock oscillator for interval time generation

The following circuit is used as a clock oscillator for interval time generation.

- Low-speed internal oscillator
  This circuit oscillates a clock of 240 kHz (TYP.). Its oscillation can be stopped by using the low-speed internal oscillation mode register (LSRCM) when it is specified by the option byte that its oscillation can be stopped by software.

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5.2 Configuration of Clock Generators

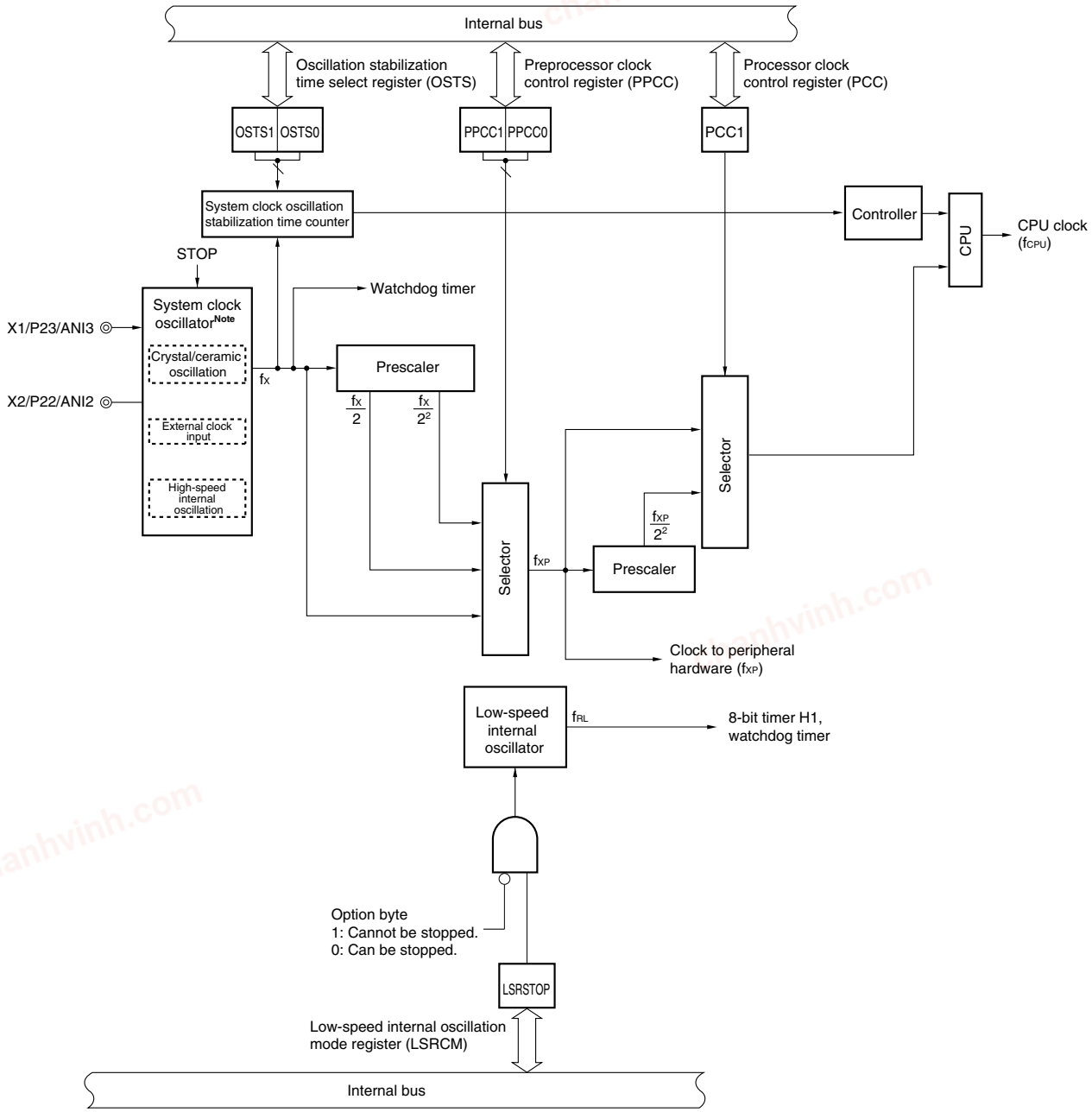
The clock generators consist of the following hardware.

Table 5-1. Configuration of Clock Generators

Item	Configuration
Control registers	Processor clock control register (PCC) Preprocessor clock control register (PPCC) Low-speed internal oscillation mode register (LSRCM) Oscillation stabilization time select register (OSTS)
Oscillators	Crystal/ceramic oscillator High-speed internal oscillator External clock input circuit Low-speed internal oscillator

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Figure 5-1. Block Diagram of Clock Generators



Note Select the high-speed internal oscillator, crystal/ceramic oscillator, or external clock input circuit as the system clock source by using the option byte.

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5.3 Registers Controlling Clock Generators

The clock generators are controlled by the following four registers.

- Processor clock control register (PCC)
- Preprocessor clock control register (PPCC)
- Low-speed internal oscillation mode register (LSRCM)
- Oscillation stabilization time select register (OSTS)

(1) Processor clock control register (PCC) and preprocessor clock control register (PPCC)

These registers are used to specify the division ratio of the system clock.

PCC and PPCC are set by using a 1-bit or 8-bit memory manipulation instruction.

Reset signal generation sets PCC and PPCC to 02H.

Figure 5-2. Format of Processor Clock Control Register (PCC)

Address: FFFBH, After reset: 02H, R/W

Symbol	7	6	5	4	3	2	1	0
PCC	0	0	0	0	0	0	PCC1	0

Figure 5-3. Format of Preprocessor Clock Control Register (PPCC)

Address: FFF3H, After reset: 02H, R/W

Symbol	7	6	5	4	3	2	1	0
PPCC	0	0	0	0	0	0	PPCC1	PPCC0

PPCC1	PPCC0	PCC1	Selection of CPU clock (f_{CPU}) Note 1
0	0	0	f_X
0	1	0	$f_X/2$ Note 2
0	0	1	$f_X/2^2$
1	0	0	$f_X/2^2$ Note 3
0	1	1	$f_X/2^3$ Note 2
1	0	1	$f_X/2^4$ Note 3
Other than above			Setting prohibited

<R>

Notes 1. The setting range of the CPU clock differs depending on the supply voltage to be used. Be sure to refer to CPU clock and peripheral clock frequencies described in AC Characteristics in CHAPTER 19 and CHAPTER 20.

2. If PPCC = 01H, the clock (f_{XP}) supplied to the peripheral hardware is $f_X/2$.

3. If PPCC = 02H, the clock (f_{XP}) supplied to the peripheral hardware is $f_X/2^2$.

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The fastest instruction of the 78K0S/KY1+ is executed in two CPU clocks. Therefore, the relationship between the CPU clock (f_{CPU}) and the minimum instruction execution time is as shown in Table 5-2.

Table 5-2. Relationship between CPU Clock and Minimum Instruction Execution Time

CPU Clock (f_{CPU}) Note	Minimum Instruction Execution Time: $2/f_{CPU}$	
	High-speed internal oscillation clock (at 8.0 MHz (TYP.))	Crystal/ceramic oscillation clock or external clock input (at 10.0 MHz)
f_X	0.25 μs	0.2 μs
$f_X/2$	0.5 μs	0.4 μs
$f_X/2^2$	1.0 μs	0.8 μs
$f_X/2^3$	2.0 μs	1.6 μs
$f_X/2^4$	4.0 μs	3.2 μs

Note The CPU clock (high-speed internal oscillation clock, crystal/ceramic oscillation clock, or external clock input) is selected by the option byte.

(2) Low-speed internal oscillation mode register (LSRCM)

This register is used to select the operation mode of the low-speed internal oscillator (240 kHz (TYP.)).

This register is valid when it is specified by the option byte that the low-speed internal oscillator can be stopped by software. If it is specified by the option byte that the low-speed internal oscillator cannot be stopped by software, setting of this register is invalid, and the low-speed internal oscillator continues oscillating. In addition, the source clock of WDT is fixed to the low-speed internal oscillator. For details, refer to **CHAPTER 8 WATCHDOG TIMER**.

LSRCM can be set by using a 1-bit or 8-bit memory manipulation instruction.

Reset signal generation sets LSRCM to 00H.

Figure 5-4. Format of Low-Speed internal oscillation Mode Register (LSRCM)

Address: FF58H, After reset: 00H, R/W

Symbol	7	6	5	4	3	2	1	<0>
LSRCM	0	0	0	0	0	0	0	LSRSTOP

LSRSTOP	Oscillation/stop of low-speed internal oscillator
0	Low-speed internal oscillates
1	Low-speed internal oscillator stops

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(3) Oscillation stabilization time select register (OSTS)

This register is used to select oscillation stabilization time of the clock supplied from the oscillator when the STOP mode is released. The wait time set by OSTS is valid only when the crystal/ceramic oscillation clock is selected as the system clock and after the STOP mode is released. If the high-speed internal oscillator or external clock input is selected as the system clock source, no wait time elapses.

The system clock oscillator and the oscillation stabilization time that elapses after power application or release of reset are selected by the option byte. For details, refer to **CHAPTER 15 OPTION BYTE**.

OSTS is set by using an 8-bit memory manipulation instruction.

Figure 5-5. Format of Oscillation Stabilization Time Select Register (OSTS)

Address: FFF4H, After reset: Undefined, R/W

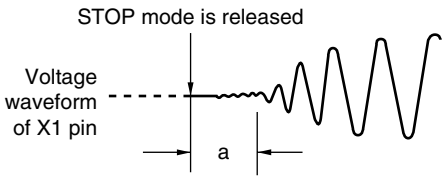
Symbol	7	6	5	4	3	2	1	0
OSTS	0	0	0	0	0	0	OSTS1	OSTS0

OSTS1	OSTS0	Selection of oscillation stabilization time
0	0	2^{10}/fx (102.4 μs)
0	1	2^{12}/fx (409.6 μs)
1	0	2^{15}/fx (3.27 ms)
1	1	2^{17}/fx (13.1 ms)

Cautions 1. To set and then release the STOP mode, set the oscillation stabilization time as follows.

Expected oscillation stabilization time of resonator ≤ Oscillation stabilization time set by OSTS

2. The wait time after the STOP mode is released does not include the time from the release of the STOP mode to the start of clock oscillation ("a" in the figure below), regardless of whether STOP mode was released by reset signal generation or interrupt generation.



3. The oscillation stabilization time that elapses on power application or after release of reset is selected by the option byte. For details, refer to CHAPTER 15 OPTION BYTE.

Remarks 1. ( ): fx = 10 MHz

2. Determine the oscillation stabilization time of the resonator by checking the characteristics of the resonator to be used.

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5.4 System Clock Oscillators

The following three types of system clock oscillators are available.

- High-speed internal oscillator: Internally oscillates a clock of 8 MHz (TYP.).
- Crystal/ceramic oscillator: Oscillates a clock of 2 MHz to 10 MHz.
- External clock input circuit: Supplies a clock of 2 MHz to 10 MHz to the X1 pin.

5.4.1 High-speed internal oscillator

The 78K0S/KY1+ include a high-speed internal oscillator (8 MHz (TYP.)).

If the high-speed internal oscillation is selected by the option byte as the clock source, the X1 and X2 pins can be used as I/O port pins.

For details of the option byte, refer to **CHAPTER 15 OPTION BYTE**. For details of I/O ports, refer to **CHAPTER 4 PORT FUNCTIONS**.

5.4.2 Crystal/ceramic oscillator

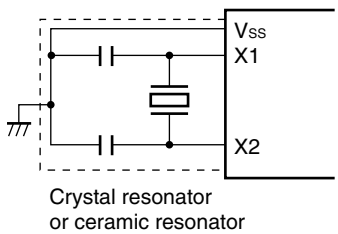
The crystal/ceramic oscillator oscillates using a crystal or ceramic resonator connected between the X1 and X2 pins.

If the crystal/ceramic oscillator is selected by the option byte as the system clock source, the X1 and X2 pins are used as crystal or ceramic resonator connection pins.

For details of the option byte, refer to **CHAPTER 15 OPTION BYTE**. For details of I/O ports, refer to **CHAPTER 4 PORT FUNCTIONS**.

Figure 5-6 shows the external circuit of the crystal/ceramic oscillator.

Figure 5-6. External Circuit of Crystal/Ceramic Oscillator



Caution When using the crystal/ceramic oscillator, wire as follows in the area enclosed by the broken lines in Figure 5-6 to avoid an adverse effect from wiring capacitance.

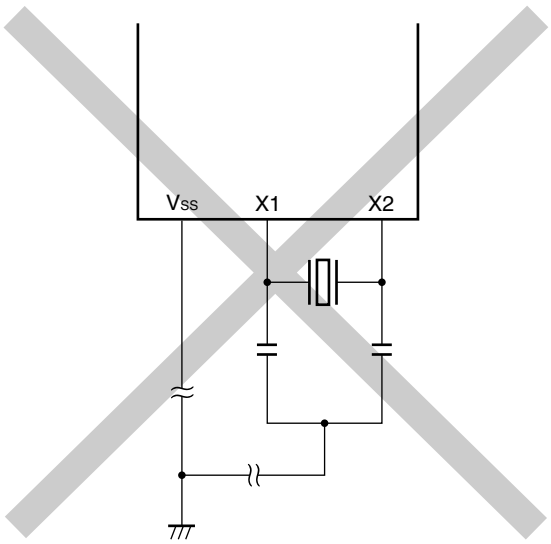
- **Keep the wiring length as short as possible.**
- **Do not cross the wiring with the other signal lines. Do not route the wiring near a signal line through which a high fluctuating current flows.**
- **Always make the ground point of the oscillator capacitor the same potential as Vss. Do not ground the capacitor to a ground pattern through which a high current flows.**
- **Do not fetch signals from the oscillator.**

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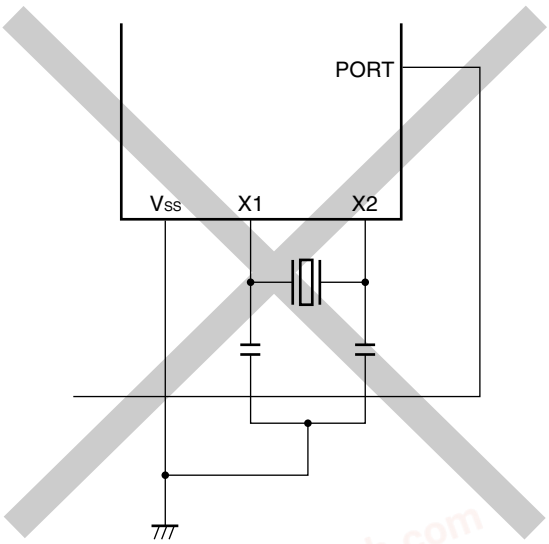
Figure 5-7 shows examples of incorrect resonator connection.

Figure 5-7. Examples of Incorrect Resonator Connection (1/2)

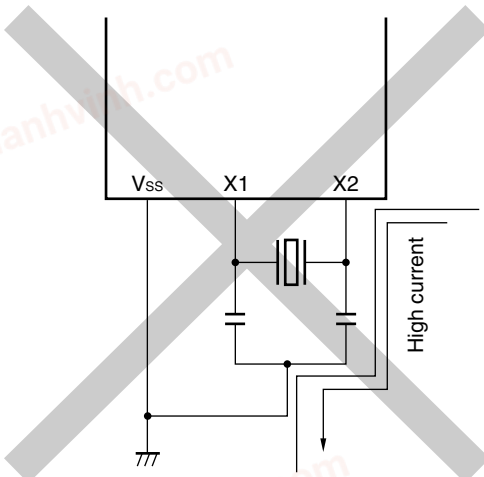
(a) Too long wiring of connected circuit



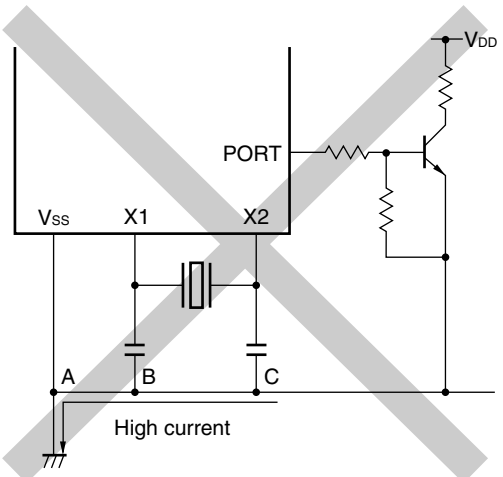
(b) Crossed signal lines



(c) Wiring near high fluctuating current



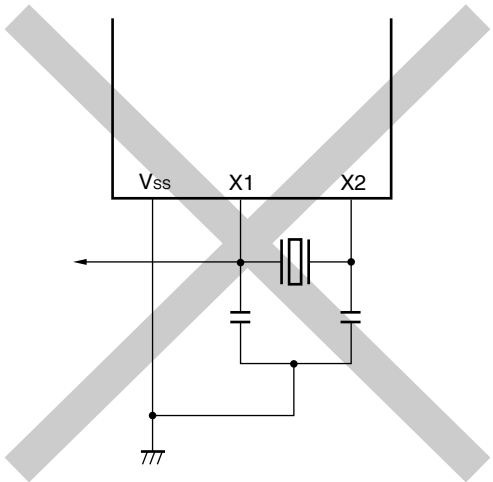
(d) Current flowing through ground line of oscillator (Potential at points A, B, and C fluctuates.)



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Figure 5-7. Examples of Incorrect Resonator Connection (2/2)

(e) Signals are fetched



5.4.3 External clock input circuit

This circuit supplies a clock from an external IC to the X1 pin.

If external clock input is selected by the option byte as the system clock source, the X2 pin can be used as an I/O port pin.

For details of the option byte, refer to **CHAPTER 15 OPTION BYTE**. For details of I/O ports, refer to **CHAPTER 4 PORT FUNCTIONS**.

5.4.4 Prescaler

The prescaler divides the clock (f_X) output by the system clock oscillator to generate a clock (f_{XP}) to be supplied to the peripheral hardware. It also divides the clock to peripheral hardware (f_{XP}) to generate a clock to be supplied to the CPU.

Remark The clock output by the oscillator selected by the option byte (high-speed internal oscillator, crystal/ceramic oscillator, or external clock input circuit) is divided. For details of the option byte, refer to **CHAPTER 15 OPTION BYTE**.

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5.5 Operation of CPU Clock Generator

A clock (f_{CPU}) is supplied to the CPU from the system clock (f_X) oscillated by one of the following three types of oscillators.

- High-speed internal oscillator: Internally oscillates a clock of 8 MHz (TYP.).
- Crystal/ceramic oscillator: Oscillates a clock of 2 MHz to 10 MHz.
- External clock input circuit: Supplies a clock of 2 MHz to 10 MHz to X1 pin.

The system clock oscillator is selected by the option byte. For details of the option byte, refer to **CHAPTER 15 OPTION BYTE**.

(1) High-speed internal oscillator

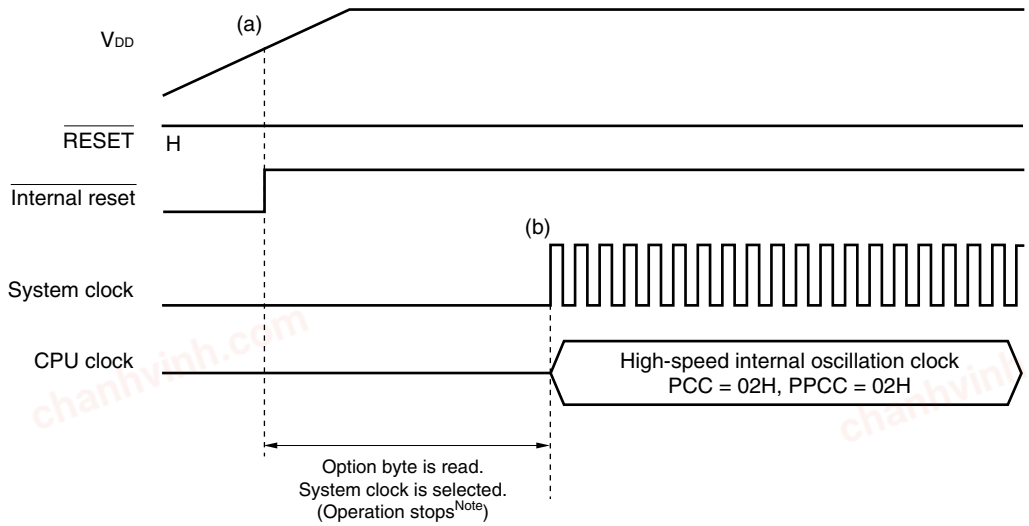
When the high-speed internal oscillation is selected by the option byte, the following is possible.

- Shortening of start time
  If the high-speed internal oscillator is selected as the oscillator, the CPU can be started without having to wait for the oscillation stabilization time of the system clock. Therefore, the start time can be shortened.
- Improvement of expandability
  If the high-speed internal oscillator is selected as the oscillator, the X1 and X2 pins can be used as I/O port pins. For details, refer to **CHAPTER 4 PORT FUNCTIONS**.

Figures 5-8 and 5-9 show the timing chart and status transition diagram of the default start by the high-speed internal oscillation.

Remark When the high-speed internal oscillation is used, the clock accuracy is ±5%.

Figure 5-8. Timing Chart of Default Start by High-Speed Internal Oscillation



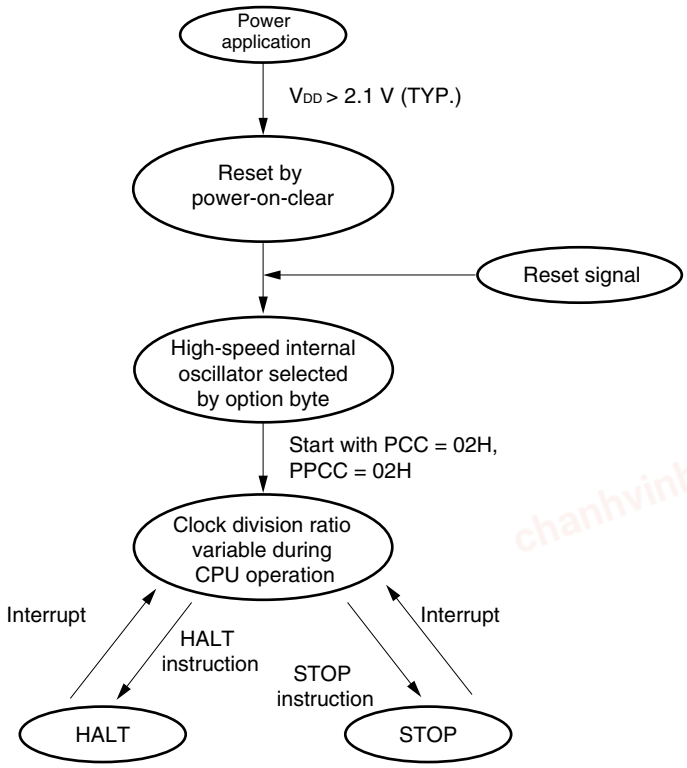
Note Operation stop time is 277 μs (MIN.), 544 μs (TYP.), and 1.075 ms (MAX.).

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(a) The internal reset signal is generated by the power-on-clear function on power application, the option byte is referenced after reset, and the system clock is selected.

(b) The option byte is referenced and the system clock is selected. Then the high-speed internal oscillation clock operates as the system clock.

Figure 5-9. Status Transition of Default Start by High-Speed internal oscillation



Remark PCC: Processor clock control register
PPCC: Preprocessor clock control register

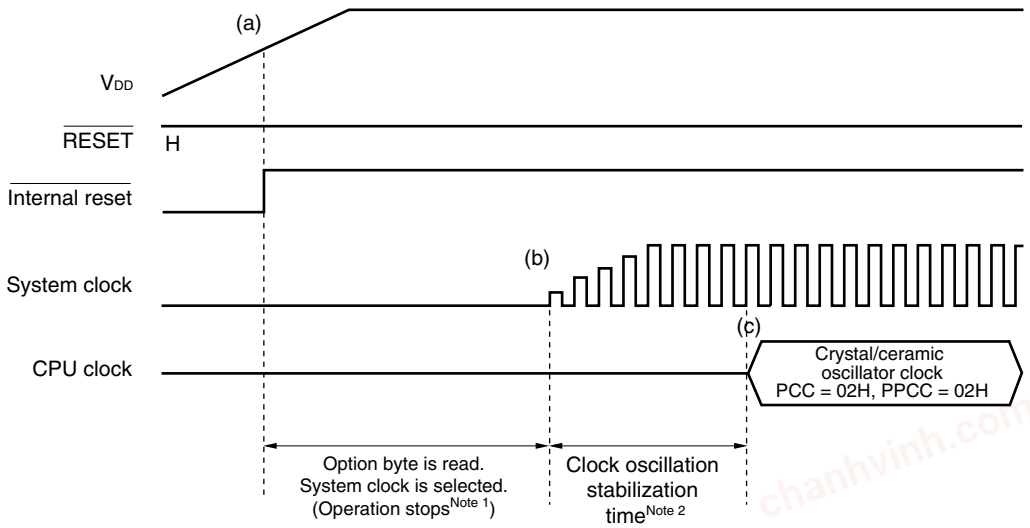
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(2) Crystal/ceramic oscillator

If crystal/ceramic oscillation is selected by the option byte, a clock frequency of 2 MHz to 10 MHz can be selected and the accuracy of processing is improved because the frequency deviation is small, as compared with high-speed internal oscillation (8 MHz (TYP.)).

Figures 5-10 and 5-11 show the timing chart and status transition diagram of default start by the crystal/ceramic oscillator.

Figure 5-10. Timing Chart of Default Start by Crystal/Ceramic Oscillator



Notes 1. Operation stop time is 276 μs (MIN.), 544 μs (TYP.), and 1.074 ms (MAX.).

2. The clock oscillation stabilization time for default start is selected by the option byte. For details, refer to **CHAPTER 15 OPTION BYTE**. The oscillation stabilization time that elapses after the STOP mode is released is selected by the oscillation stabilization time select register (OSTS).

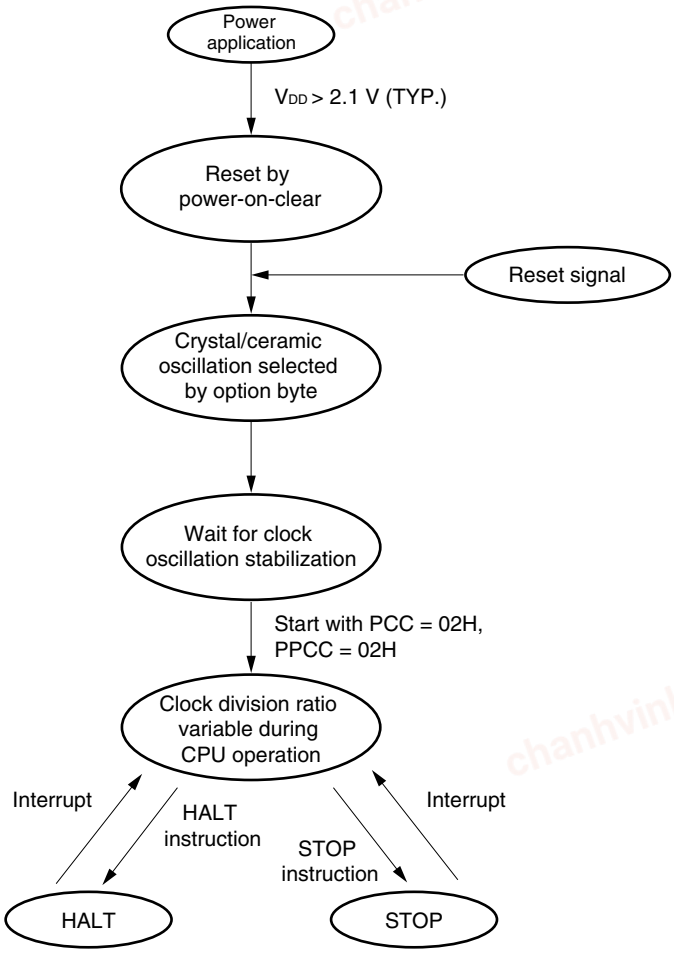
(a) The internal reset signal is generated by the power-on-clear function on power application, the option byte is referenced after reset, and the system clock is selected.

(b) After high-speed internal oscillation clock is generated, the option byte is referenced and the system clock is selected. In this case, the crystal/ceramic oscillator clock is selected as the system clock.

(c) If the system clock is the crystal/ceramic oscillator clock, it starts operating as the CPU clock after clock oscillation is stabilized. The wait time is selected by the option byte. For details, refer to **CHAPTER 15 OPTION BYTE**.

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Figure 5-11. Status Transition of Default Start by Crystal/Ceramic Oscillation



Remark PCC: Processor clock control register
PPCC: Preprocessor clock control register

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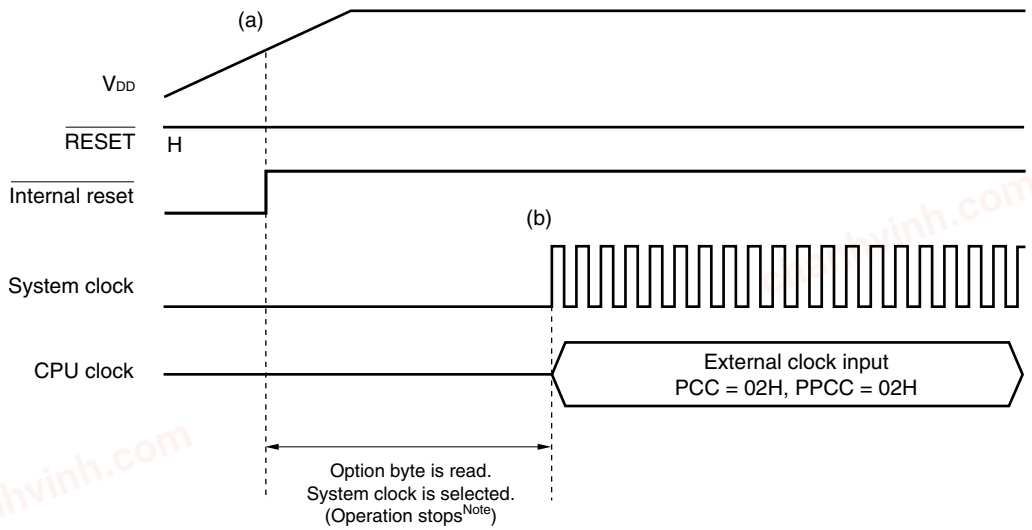
(3) External clock input circuit

If external clock input is selected by the option byte, the following is possible.

- High-speed operation
  The accuracy of processing is improved as compared with high-speed internal oscillation (8 MHz (TYP.)) because an oscillation frequency of 2 MHz to 10 MHz can be selected and an external clock with a small frequency deviation can be supplied.
- Improvement of expandability
  If the external clock input circuit is selected as the oscillator, the X2 pin can be used as an I/O port pin. For details, refer to **CHAPTER 4 PORT FUNCTIONS**.

Figures 5-12 and 5-13 show the timing chart and status transition diagram of default start by external clock input.

Figure 5-12. Timing of Default Start by External Clock Input



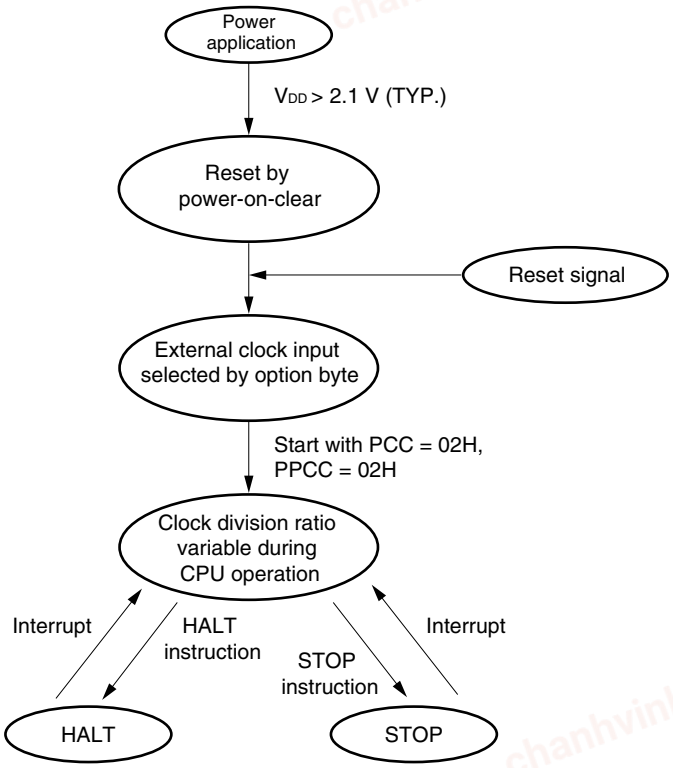
Note Operation stop time is 277 μs (MIN.), 544 μs (TYP.), and 1.075 ms (MAX.).

(a) The internal reset signal is generated by the power-on-clear function on power application, the option byte is referenced after reset, and the system clock is selected.

(b) The option byte is referenced and the system clock is selected. Then the external clock operates as the system clock.

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Figure 5-13. Status Transition of Default Start by External Clock Input



Remark PCC: Processor clock control register
PPCC: Preprocessor clock control register

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5.6 Operation of Clock Generator Supplying Clock to Peripheral Hardware

The following two types of clocks are supplied to the peripheral hardware.

- Clock to peripheral hardware (f_{XP})
- Low-speed internal oscillation clock (f_{RL})

(1) Clock to peripheral hardware

The clock to the peripheral hardware is supplied by dividing the system clock (f_X). The division ratio is selected by the pre-processor clock control register (PPCC).

Three types of frequencies are selectable: "f_X", "$f_X/2$", and "$f_X/2^2$". Table 5-3 lists the clocks supplied to the peripheral hardware.

Table 5-3. Clocks to Peripheral Hardware

PPCC1	PPCC0	Selection of clock to peripheral hardware (f_{XP})
0	0	f_X
0	1	$f_X/2$
1	0	$f_X/2^2$
1	1	Setting prohibited

(2) Low-speed internal oscillation clock

The low-speed internal oscillator of the clock oscillator for interval time generation is always started after release of reset, and oscillates at 240 kHz (TYP.).

It can be specified by the option byte whether the low-speed internal oscillator can or cannot be stopped by software. If it is specified that the low-speed internal oscillator can be stopped by software, oscillation can be started or stopped by using the low-speed internal oscillation mode register (LSRCM). If it is specified that it cannot be stopped by software, the clock source of WDT is fixed to the low-speed internal oscillation clock (f_{RL}).

The low-speed internal oscillator is independent of the CPU clock. If it is used as the source clock of WDT, therefore, a hang-up can be detected even if the CPU clock is stopped. If the low-speed internal oscillator is used as a count clock source of 8-bit timer H1, 8-bit timer H1 can operate even in the standby status.

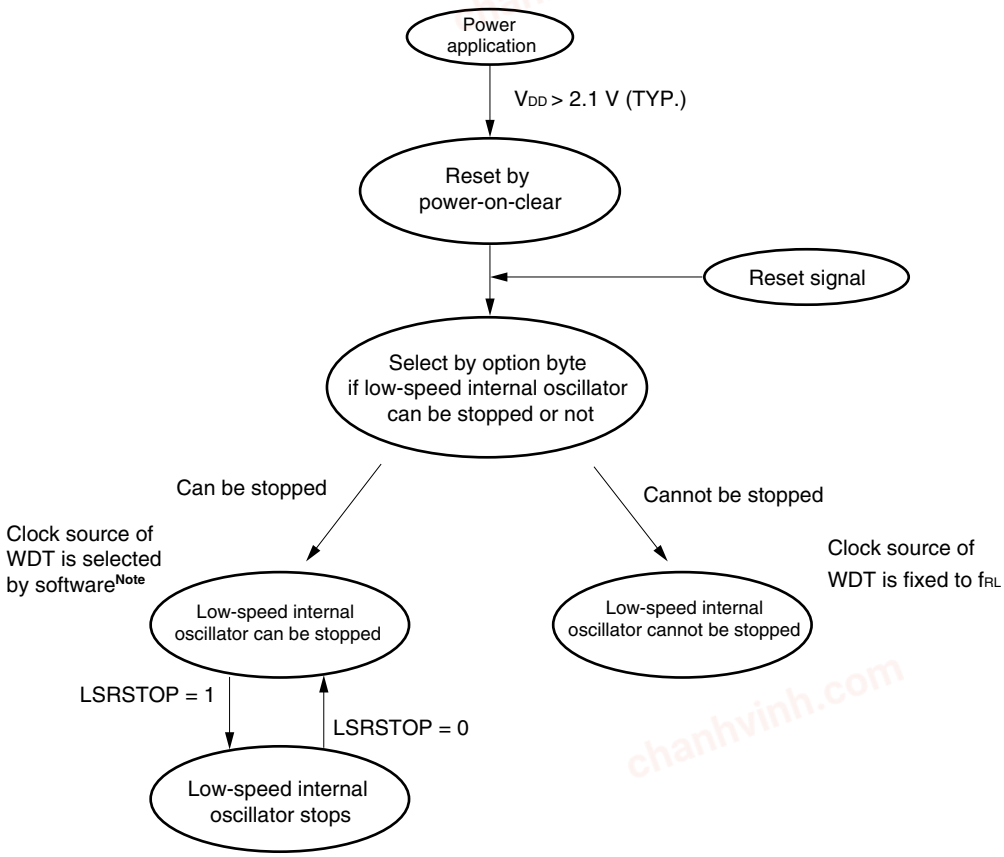
Table 5-4 shows the operation status of the low-speed internal oscillator when it is selected as the source clock of WDT and the count clock of 8-bit timer H1. Figure 5-14 shows the status transition of the low-speed internal oscillator.

Table 5-4. Operation Status of Low-Speed Internal Oscillator

Option Byte Setting		CPU Status	WDT Status	TMH1 Status
Can be stopped by software	LSRSTOP = 1	Operation mode	Stopped	Stopped
	LSRSTOP = 0		Operates	Operates
	LSRSTOP = 1	Standby	Stopped	Stopped
	LSRSTOP = 0		Stopped	Operates
Cannot be stopped		Operation mode	Operates	
		Standby		

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Figure 5-14. Status Transition of Low-Speed Internal Oscillator



Note The clock source of the watchdog timer (WDT) is selected from f_X or f_{RL}, or it may be stopped. For details, refer to **CHAPTER 8 WATCHDOG TIMER**.

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CHAPTER 6 16-BIT TIMER/EVENT COUNTER 00

6.1 Functions of 16-bit Timer/Event Counter 00

16-bit timer/event counter 00 has the following functions.

(1) Interval timer

16-bit timer/event counter 00 generates interrupt requests at the preset time interval.

- Number of counts: 2 to 65536

(2) External event counter

16-bit timer/event counter 00 can measure the number of pulses with a high-/low-level width of valid level pulse width or more of a signal input externally.

- Valid level pulse width: $2/f_{XP}$ or more

(3) Pulse width measurement

16-bit timer/event counter 00 can measure the pulse width of an externally input signal.

- Valid level pulse width: $2/f_{XP}$ or more

(4) Square-wave output

16-bit timer/event counter 00 can output a square wave with any selected frequency.

- Cycle: (2 to 65536) $\times$ 2 $\times$ count clock cycle

(5) PPG output

16-bit timer/event counter 00 can output a square wave that have arbitrary cycle and pulse width.

- 1 < Pulse width < Cycle $\leq$ 65536

(6) One-shot pulse output

16-bit timer/event counter 00 can output a one-shot pulse for which output pulse width can be set to any desired value.

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6.2 Configuration of 16-bit Timer/Event Counter 00

16-bit timer/event counter 00 consists of the following hardware.

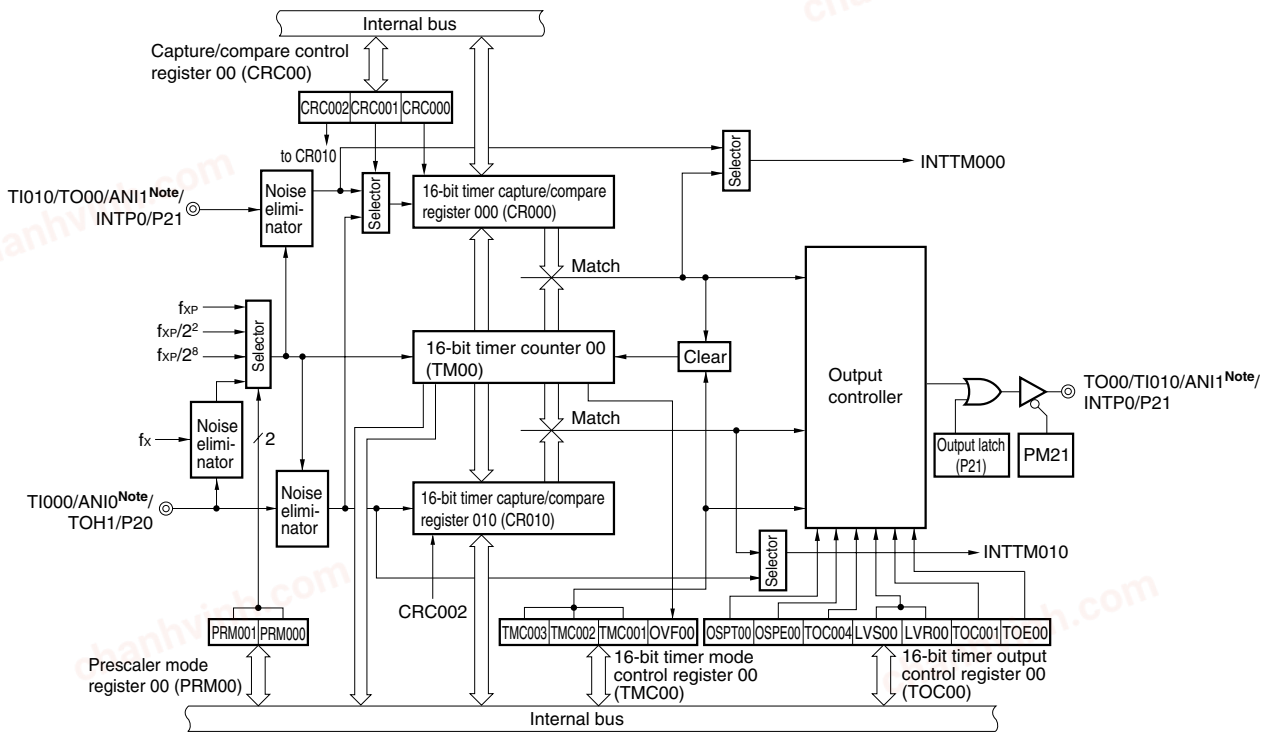
Table 6-1. Configuration of 16-bit Timer/Event Counter 00

Item	Configuration
Timer counter	16-bit timer counter 00 (TM00)
Register	16-bit timer capture/compare registers 000, 010 (CR000, CR010)
Timer input	TI000, TI010
Timer output	TO00, output controller
Control registers	16-bit timer mode control register 00 (TMC00) Capture/compare control register 00 (CRC00) 16-bit timer output control register 00 (TOC00) Prescaler mode register 00 (PRM00) Port mode register 2 (PM2) Port register 2 (P2) Port mode control register 2 (PMC2) (μPD78F921x only)

<R>

Figure 6-1 shows a block diagram of these counters.

Figure 6-1. Block Diagram of 16-bit Timer/Event Counter 00



<R>

Note μPD78F921x only

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(1) 16-bit timer counter 00 (TM00)

TM00 is a 16-bit read-only register that counts count pulses.

The counter is incremented in synchronization with the rising edge of the count clock. If the count value is read during operation, input of the count clock is temporarily stopped, and the count value at that point is read.

Figure 6-2. Format of 16-bit Timer Counter 00 (TM00)

Address: FF12H, FF13H After reset: 0000H R

Symbol	FF13H								FF12H							
	7	6	5	4	3	2	1	0	7	6	5	4	3	2	1	0
TM00																

The count value is reset to 0000H in the following cases.

<1> If a reset signal is generated
<2> If TMC003 and TMC002 are cleared
<3> If the valid edge of TI000 is input in the clear & start mode entered by inputting the valid edge of TI000
<4> If TM00 and CR000 match in the clear & start mode entered on a match between TM00 and CR000
<5> If OSPT00 is set to 1 in the one-shot pulse output mode

Cautions 1. Even if TM00 is read, the value is not captured by CR010.

2. When TM00 is read, count misses do not occur, since the input of the count clock is temporarily stopped and then resumed after the read.

(2) 16-bit timer capture/compare register 000 (CR000)

CR000 is a 16-bit register which has the functions of both a capture register and a compare register. Whether it is used as a capture register or as a compare register is set by bit 0 (CRC000) of capture/compare control register 00 (CRC00).

CR000 is set by 16-bit memory manipulation instruction.

A reset signal generation clears CR000 to 0000H.

Figure 6-3. Format of 16-bit Timer Capture/Compare Register 000 (CR000)

Address: FF14H, FF15H After reset: 0000H R/W

Symbol	FF15H								FF14H							
	7	6	5	4	3	2	1	0	7	6	5	4	3	2	1	0
CR000																

- **When CR000 is used as a compare register**

  The value set in CR000 is constantly compared with the 16-bit timer/counter 00 (TM00) count value, and an interrupt request (INTTM000) is generated if they match. It can also be used as the register that holds the interval time then TM00 is set to interval timer operation.

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- **When CR000 is used as a capture register**

  It is possible to select the valid edge of the TI000 pin or the TI010 pin as the capture trigger. Setting of the TI000 or TI010 valid edge is performed by means of prescaler mode register 00 (PRM00) (refer to **Table 6-2**).

Table 6-2. CR000 Capture Trigger and Valid Edges of TI000 and TI010 Pins

(1) TI000 pin valid edge selected as capture trigger (CRC001 = 1, CRC000 = 1)

CR000 Capture Trigger	TI000 Pin Valid Edge		
		ES010	ES000
Falling edge	Rising edge	0	1
Rising edge	Falling edge	0	0
No capture operation	Both rising and falling edges	1	1

(2) TI010 pin valid edge selected as capture trigger (CRC001 = 0, CRC000 = 1)

CR000 Capture Trigger	TI010 Pin Valid Edge		
		ES110	ES100
Falling edge	Falling edge	0	0
Rising edge	Rising edge	0	1
Both rising and falling edges	Both rising and falling edges	1	1

Remarks 1. Setting ES010, ES000 = 1, 0 and ES110, ES100 = 1, 0 is prohibited.

2. ES010, ES000: Bits 5 and 4 of prescaler mode register 00 (PRM00)
ES110, ES100: Bits 7 and 6 of prescaler mode register 00 (PRM00)
CRC001, CRC000: Bits 1 and 0 of capture/compare control register 00 (CRC00)

Cautions 1. Set CR000 to other than 0000H in the clear & start mode entered on match between TM00 and CR000. This means a 1-pulse count operation cannot be performed when this register is used as an external event counter. However, in the free-running mode and in the clear & start mode using the valid edge of the TI000 pin, if CR000 is set to 0000H, an interrupt request (INTTM000) is generated when CR000 changes from 0000H to 0001H after an overflow (FFFFH).

2. If the new value of CR000 is less than the value of 16-bit timer counter 0 (TM00), TM00 continues counting, overflows, and then starts counting from 0 again. If the new value of CR000 is less than the old value, therefore, the timer must be reset to be restarted after the value of CR000 is changed.

3. The value of CR000 after 16-bit timer/event counter 00 has stopped is not guaranteed.

4. The capture operation may not be performed for CR000 set in compare mode even if a capture trigger is input.

5. When using P21 as the input pin (TI010) of the valid edge, it cannot be used as a timer output pin (TO00). When using P21 as the timer output pin (TO00), it cannot be used as the input pin (TI010) of the valid edge.

6. If the register read period and the input of the capture trigger conflict when CR000 is used as a capture register, the capture trigger input takes precedence and the read data is undefined. Also, if the count stop of the timer and the input of the capture trigger conflict, the capture trigger is undefined.

7. Changing the CR000 setting may cause a malfunction. To change the setting, refer to 6.5 Cautions Related to 16-bit Timer/Event Counter 00 (17) Changing compare register during timer operation.

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(3) 16-bit timer capture/compare register 010 (CR010)

CR010 is a 16-bit register which has the functions of both a capture register and a compare register. Whether it is used as a capture register or a compare register is set by bit 2 (CRC002) of capture/compare control register 00 (CRC00).

CR010 is set by 16-bit memory manipulation instruction.

Reset signal generation clears CR010 to 0000H.

Figure 6-4. Format of 16-bit Timer Capture/Compare Register 010 (CR010)

Address: FF16H, FF17H After reset: 0000H R/W

Symbol	FF17H								FF16H							
	7	6	5	4	3	2	1	0	7	6	5	4	3	2	1	0
CR010																

- **When CR010 is used as a compare register**

  The value set in CR010 is constantly compared with the 16-bit timer counter 00 (TM00) count value, and an interrupt request (INTTM010) is generated if they match.

- **When CR010 is used as a capture register**

  It is possible to select the valid edge of the TI000 pin as the capture trigger. The TI000 valid edge is set by means of prescaler mode register 00 (PRM00) (refer to **Table 6-3**).

Table 6-3. CR010 Capture Trigger and Valid Edge of TI000 Pin (CRC002 = 1)

CR010 Capture Trigger	TI000 Pin Valid Edge		
		ES010	ES000
Falling edge	Falling edge	0	0
Rising edge	Rising edge	0	1
Both rising and falling edges	Both rising and falling edges	1	1

Remarks 1. Setting ES010, ES000 = 1, 0 is prohibited.

2. ES010, ES000: Bits 5 and 4 of prescaler mode register 00 (PRM00)
CRC002: Bit 2 of capture/compare control register 00 (CRC00)

Cautions 1. In the free-running mode and in the clear & start mode using the valid edge of the TI000 pin, if CR010 is set to 0000H, an interrupt request (INTTM010) is generated when CR010 changes from 0000H to 0001H after an overflow (FFFFH).

2. If the new value of CR010 is less than the value of 16-bit timer counter 00 (TM00), TM00 continues counting, overflows, and then starts counting from 0 again. If the new value of CR010 is less than the old value, therefore, the timer must be reset to be restarted after the value of CR010 is changed.

3. The value of CR010 after 16-bit timer/event counter 00 has stopped is not guaranteed.

4. The capture operation may not be performed for CR010 set in compare mode even if a capture trigger is input.

5. If the register read period and the input of the capture trigger conflict when CR010 is used as a capture register, the capture trigger input takes precedence and the read data is undefined. Also, if the timer count stop and the input of the capture trigger conflict, the capture data is undefined.

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Caution 6. Changing the CR010 setting during TM00 operation may cause a malfunction. To change the setting, refer to 6.5 Cautions Related to 16-bit Timer/Event Counter 00 (17) Changing compare register during timer operation.

6.3 Registers to Control 16-bit Timer/Event Counter 00

The following seven types of registers are used to control 16-bit timer/event counter 00.

- 16-bit timer mode control register 00 (TMC00)
- Capture/compare control register 00 (CRC00)
- 16-bit timer output control register 00 (TOC00)
- Prescaler mode register 00 (PRM00)
- Port mode register 2 (PM2)
- Port register 2 (P2)

<R>
- Port mode control register 2 (PMC2) (μPD78F921x only)

(1) 16-bit timer mode control register 00 (TMC00)

This register sets the 16-bit timer operating mode, the 16-bit timer counter 00 (TM00) clear mode, and output timing, and detects an overflow.

TMC00 is set by a 1-bit or 8-bit memory manipulation instruction.

Reset signal generation sets the value of TMC00 to 00H.

Caution 16-bit timer counter 00 (TM00) starts operating as soon as values other than 0 and 0 (operation stop mode) are set to TMC002 and TMC003, respectively. Set TMC002 and TMC003 to 0 and 0 to stop operation.

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Figure 6-5. Format of 16-bit Timer Mode Control Register 00 (TMC00)

Address: FF60H After reset: 00H R/W

Symbol	7	6	5	4	3	2	1	<0>
TMC00	0	0	0	0	TMC003	TMC002	TMC001	OVF00

TMC003	TMC002	TMC001	Operating mode and clear mode selection	TO00 inversion timing selection	Interrupt request generation
0	0	0	Operation stop (TM00 cleared to 0)	No change	Not generated
0	0	1			
0	1	0	Free-running mode	Match between TM00 and CR000 or match between TM00 and CR010	< When operating as compare register > Generated on match between TM00 and CR000, or match between TM00 and CR010 < When operating as capture register > Generated on TI000 pin and TI010 pin valid edge
0	1	1		Match between TM00 and CR000, match between TM00 and CR010 or TI000 pin valid edge	
1	0	0	Clear & start occurs on valid edge of TI000 pin	–	
1	0	1			
1	1	0	Clear & start occurs on match between TM00 and CR000	Match between TM00 and CR000 or match between TM00 and CR010	
1	1	1		Match between TM00 and CR000, match between TM00 and CR010 or TI000 pin valid edge	

OVF00	Overflow detection of 16-bit timer counter 00 (TM00)
0	Overflow not detected
1	Overflow detected

Cautions
1. **The timer operation must be stopped before writing to bits other than the OVF00 flag.**
2. **If the timer is stopped, timer counts and timer interrupts do not occur, even if a signal is input to the TI000/TI010 pins.**
3. **Except when the valid edge of the TI000 pin is selected as the count clock, stop the timer operation before setting STOP mode or system clock stop mode; otherwise the timer may malfunction when the system clock starts.**
4. **Set the valid edge of the TI000 pin with bits 4 and 5 of prescaler mode register 00 (PRM00) after stopping the timer operation.**
5. **If the clear & start mode entered on a match between TM00 and CR000, clear & start mode at the valid edge of the TI000 pin, or free-running mode is selected, when the set value of CR000 is FFFFH and the TM00 value changes from FFFFH to 0000H, the OVF00 flag is set to 1.**
6. **Even if the OVF00 flag is cleared before the next count clock is counted (before TM00 becomes 0001H) after the occurrence of a TM00 overflow, the OVF00 flag is re-set and clearance becomes invalid.**
7. **The capture operation is performed at the fall of the count clock. An interrupt request input (INTTM0n0), however, occurs at the rise of the next count clock.**

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Remark TM00: 16-bit timer counter 00
CR000: 16-bit timer capture/compare register 000
CR010: 16-bit timer capture/compare register 010

(2) Capture/compare control register 00 (CRC00)

This register controls the operation of the 16-bit capture/compare registers (CR000, CR010).
CRC00 is set by a 1-bit or 8-bit memory manipulation instruction.
Reset signal generation sets the value of CRC00 to 00H.

Figure 6-6. Format of Capture/Compare Control Register 00 (CRC00)

Address: FF62H After reset: 00H R/W

Symbol	7	6	5	4	3	2	1	0
CRC00	0	0	0	0	0	CRC002	CRC001	CRC000

CRC002	CR010 operating mode selection
0	Operate as compare register
1	Operate as capture register

CRC001	CR000 capture trigger selection
0	Capture on valid edge of TI010 pin
1	Capture on valid edge of TI000 pin by reverse phase[Note]

CRC000	CR000 operating mode selection
0	Operate as compare register
1	Operate as capture register

Note When the CRC001 bit value is 1, capture is not performed if both the rising and falling edges have been selected as the valid edges of the TI000 pin.

Cautions 1. The timer operation must be stopped before setting CRC00.
2. When the clear & start mode entered on a match between TM00 and CR000 is selected by 16-bit timer mode control register 00 (TMC00), CR000 should not be specified as a capture register.
3. To ensure the reliability of the capture operation, the capture trigger requires a pulse longer than two cycles of the count clock selected by prescaler mode register 00 (PRM00) (refer to Figure 6-18).

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(3) 16-bit timer output control register 00 (TOC00)

This register controls the operation of the 16-bit timer/event counter output controller. It sets timer output F/F set/reset, output inversion enable/disable, 16-bit timer/event counter 00 timer output enable/disable, one-shot pulse output operation enable/disable, and output trigger of one-shot pulse by software.

TOC00 is set by a 1-bit or 8-bit memory manipulation instruction.

Reset signal generation sets the value of TOC00 to 00H.

Figure 6-7. Format of 16-bit Timer Output Control Register 00 (TOC00)

Address: FF63H After reset: 00H R/W

Symbol	7	<6>	<5>	4	<3>	<2>	1	<0>
TOC00	0	OSPT00	OSPE00	TOC004	LVS00	LVR00	TOC001	TOE00

OSPT00	One-shot pulse output trigger control via software
0	No one-shot pulse output trigger
1	One-shot pulse output trigger

OSPE00	One-shot pulse output operation control
0	Successive pulse output mode
1	One-shot pulse output mode[Note]

TOC004	Timer output F/F control using match of CR010 and TM00
0	Disables inversion operation
1	Enables inversion operation

LVS00	LVR00	Timer output F/F status setting
0	0	No change
0	1	Timer output F/F reset (0)
1	0	Timer output F/F set (1)
1	1	Setting prohibited

TOC001	Timer output F/F control using match of CR000 and TM00
0	Disables inversion operation
1	Enables inversion operation

TOE00	Timer output control
0	Disables output (output fixed to level 0)
1	Enables output

Note The one-shot pulse output mode operates correctly only in the free-running mode and the mode in which clear & start occurs at the TI000 pin valid edge. In the mode in which clear & start occurs on a match between TM00 and CR000, one-shot pulse output is not possible because an overflow does not occur.

Cautions 1. Timer operation must be stopped before setting other than OSPT00.

2. If LVS00 and LVR00 are read, 0 is read.

3. OSPT00 is automatically cleared after data is set, so 0 is read.

4. Do not set OSPT00 to 1 other than in one-shot pulse output mode.

5. A write interval of two cycles or more of the count clock selected by prescaler mode register 00 (PRM00) is required, when OSPT00 is set to 1 successively.

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Caution 6. When TOE00 is 0, set TOE00, LVS00, and LVR00 at the same time with the 8-bit memory manipulation instruction. When TOE00 is 1, LVS00 and LVR00 can be set with the 1-bit memory manipulation instruction.

(4) Prescaler mode register 00 (PRM00)

This register is used to set the 16-bit timer counter 00 (TM00) count clock and the TI000, TI010 pin input valid edges.

PRM00 is set by a 1-bit or 8-bit memory manipulation instruction.

Reset signal generation sets the value of PRM00 to 00H.

Figure 6-8. Format of Prescaler Mode Register 00 (PRM00)

Address: FF61H After reset: 00H R/W

Symbol	7	6	5	4	3	2	1	0
PRM00	ES110	ES100	ES010	ES000	0	0	PRM001	PRM000

ES110	ES100	TI010 pin valid edge selection
0	0	Falling edge
0	1	Rising edge
1	0	Setting prohibited
1	1	Both falling and rising edges

ES010	ES000	TI000 pin valid edge selection
0	0	Falling edge
0	1	Rising edge
1	0	Setting prohibited
1	1	Both falling and rising edges

PRM001	PRM000	Count clock selection
0	0	f_{XP} (10 MHz)
0	1	$f_{XP}/2^2$ (2.5 MHz)
1	0	$f_{XP}/2^8$ (39.06 kHz)
1	1	TI000 pin valid edge[Note]

Remarks 1. f_{XP}: Oscillation frequency of clock supplied to peripheral hardware

2. ( ): f_{XP} = 10 MHz

Note The external clock requires a pulse longer than two cycles of the internal count clock (f_{XP}).

Cautions 1. Always set data to PRM00 after stopping the timer operation.

2. If the valid edge of the TI000 pin is to be set as the count clock, do not set the clear/start mode and the capture trigger at the valid edge of the TI000 pin.

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Cautions 3. In the following cases, note with caution that the valid edge of the TI0n0 pin is detected.

<1> Immediately after a system reset, if a high level is input to the TI0n0 pin, the operation of 16-bit timer counter 00 (TM00) is enabled

→ If the rising edge or both rising and falling edges are specified as the valid edge of the TI0n0 pin, a rising edge is detected immediately after the TM00 operation is enabled.

<2> If the TM00 operation is stopped while the TI0n0 pin is at high level, TM00 operation is then enabled after a low level is input to the TI0n0 pin

→ If the falling edge or both rising and falling edges are specified as the valid edge of the TI0n0 pin, a falling edge is detected immediately after the TM00 operation is enabled.

<3> If the TM00 operation is stopped while the TI0n0 pin is at low level, TM00 operation is then enabled after a high level is input to the TI0n0 pin

→ If the rising edge or both rising and falling edges are specified as the valid edge of the TI0n0 pin, a rising edge is detected immediately after the TM00 operation is enabled.

4. The sampling clock used to eliminate noise differs when the valid edge of TI000 is used as the count clock and when it is used as a capture trigger. In the former case, the count clock is f_{XP}, and in the latter case the count clock is selected by prescaler mode register 00 (PRM00). The capture operation is not performed until the valid edge is sampled and the valid level is detected twice, thus eliminating noise with a short pulse width.

5. When using P21 as the input pin (TI010) of the valid edge, it cannot be used as a timer output pin (TO00). When using P21 as the timer output pin (TO00), it cannot be used as the input pin (TI010) of the valid edge.

Remark n = 0, 1

(5) Port mode register 2 (PM2) and port mode control register 2 (PMC2)[Note]

When using the P21/TO00/TI010/ANI1/INTP0 pin for timer output, clear PM21, the output latch of P21, and PMC21 to 0.

When using the P20/TI000/TOH1/ANI0 and P21/TO00/TI010/ANI1/INTP0 pins as a timer input, set PM20 and PM21 to 1, and clear PMC20 and PMC21 to 0.

At this time, the output latches of P20 and P21 can be either 0 or 1.

PM2 and PMC2 are set by a 1-bit or 8-bit memory manipulation instruction.

Reset signal generation sets the value of PM2 to FFH, and clears the value of PMC2 to 00H.

<R> **Note** μPD78F921x only

Figure 6-9. Format of Port Mode Register 2 (PM2)

Address: FF22H After reset: FFH R/W

Symbol	7	6	5	4	3	2	1	0
PM2	1	1	1	1	PM23	PM22	PM21	PM20

PM2n	P2n pin I/O mode selection (n = 0 to 3)
0	Output mode (output buffer on)
1	Input mode (output buffer off)

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Figure 6-10. Format of Port Mode Control Register 2 (PMC2) (μPD78F921x only)

Address: FF84H After reset: 00H R/W

Symbol	7	6	5	4	3	2	1	0
PMC2	0	0	0	0	PMC23	PMC22	PMC21	PMC20

PMC2n	Specification of operation mode (n = 0 to 3)
0	Port/Alternate-function (except A/D converter) mode
1	A/D converter mode

6.4 Operation of 16-bit Timer/Event Counter 00

6.4.1 Interval timer operation

Setting 16-bit timer mode control register 00 (TMC00) and capture/compare control register 00 (CRC00) as shown in Figure 6-11 allows operation as an interval timer.

Setting

The basic operation setting procedure is as follows.

<1> Set the CRC00 register (see **Figure 6-11** for the set value).
<2> Set any value to the CR000 register.
<3> Set the count clock by using the PRM00 register.
<4> Set the TMC00 register to start the operation (see **Figure 6-11** for the set value).

Caution Changing the CR000 setting during TM00 operation may cause a malfunction. To change the setting, refer to 6.5 Cautions Related to 16-bit Timer/Event Counter 00 (17) Changing compare register during timer operation.

Remark For how to enable the INTTM000 interrupt, see **CHAPTER 10 INTERRUPT FUNCTIONS**.

Interrupt requests are generated repeatedly using the count value set in 16-bit timer capture/compare register 000 (CR000) beforehand as the interval.

When the count value of 16-bit timer counter 00 (TM00) matches the value set to CR000, counting continues with the TM00 value cleared to 0 and the interrupt request signal (INTTM000) is generated.

The count clock of the 16-bit timer/event counter can be selected using bits 0 and 1 (PRM000, PRM001) of prescaler mode register 00 (PRM00).

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Figure 6-11. Control Register Settings for Interval Timer Operation

(a) Capture/compare control register 00 (CRC00)

	7	6	5	4	3	CRC002	CRC001	CRC000
CRC00	0	0	0	0	0	0/1	0/1	0

CR000 used as compare register

(b) Prescaler mode register 00 (PRM00)

	ES110	ES100	ES010	ES000	3	2	PRM001	PRM000
PRM00	0/1	0/1	0/1	0/1	0	0	0/1	0/1

Selects count clock.
Setting invalid (setting “10” is prohibited.)
Setting invalid (setting “10” is prohibited.)

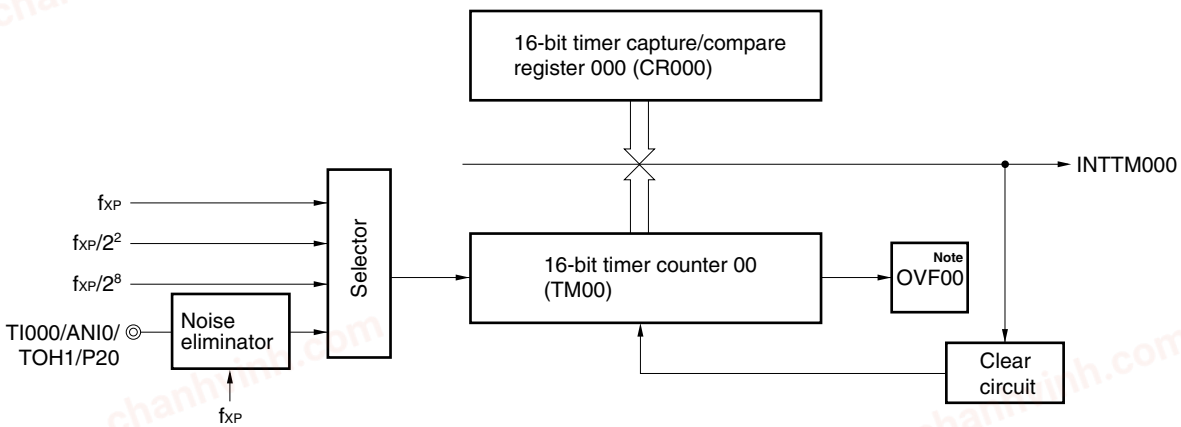
(c) 16-bit timer mode control register 00 (TMC00)

	7	6	5	4	TMC003	TMC002	TMC001	OVF00
TMC00	0	0	0	0	1	1	0/1	0

Clears and starts on match between TM00 and CR000.

Remark 0/1: Setting 0 or 1 allows another function to be used simultaneously with the interval timer. See the description of the respective control registers for details.

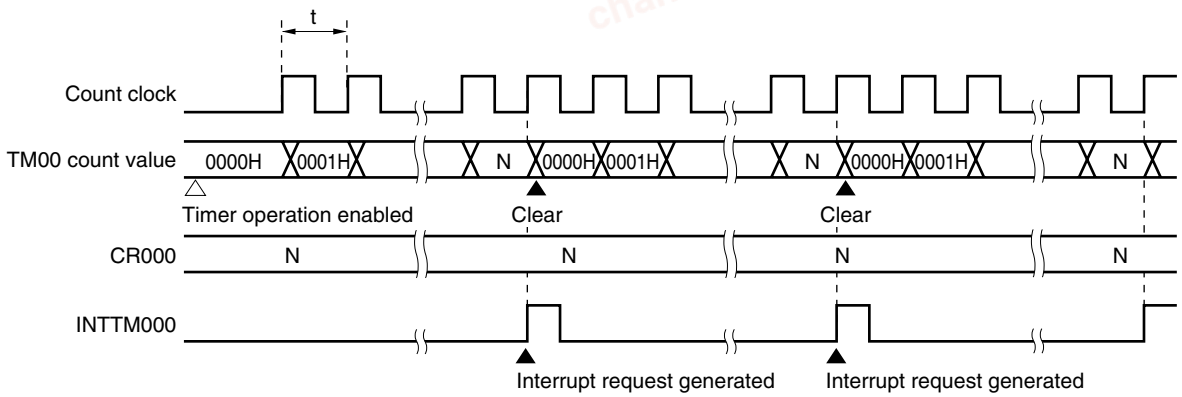
Figure 6-12. Interval Timer Configuration Diagram



Note OVF00 is set to 1 only when 16-bit timer capture/compare register 000 (CR000) is set to FFFFH.

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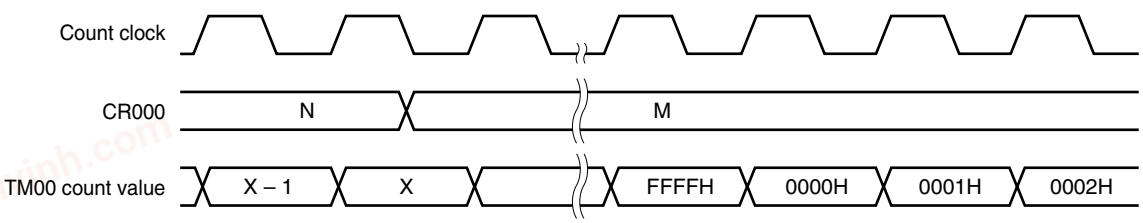
Figure 6-13. Timing of Interval Timer Operation



Remark Interval time = (N + 1) × t
N = 0001H to FFFFH (settable range)

When the compare register is changed during timer count operation, if the value after 16-bit timer capture/compare register 000 (CR000) is changed is smaller than that of 16-bit timer counter 00 (TM00), TM00 continues counting, overflows and then restarts counting from 0. Thus, if the value (M) after the CR000 change is smaller than that (N) before the change, it is necessary to restart the timer after changing CR000.

Figure 6-14. Timing After Change of Compare Register During Timer Count Operation (N → M: N > M)



Remark N > X > M

6.4.2 External event counter operation

Setting

The basic operation setting procedure is as follows.

<1> Set the CRC00 register (see **Figure 6-15** for the set value).
<2> Set the count clock by using the PRM00 register.
<3> Set any value to the CR000 register (0000H cannot be set).
<4> Set the TMC00 register to start the operation (see **Figure 6-15** for the set value).

Remarks 1. For the setting of the TI000 pin, see **6.3 (5) Port mode register 2 (PM2) and port mode control register 2 (PMC2)**.
2. For how to enable the INTTM000 interrupt, see **CHAPTER 10 INTERRUPT FUNCTIONS**.

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The external event counter counts the number of external clock pulses to be input to the TI000 pin with using 16-bit timer counter 00 (TM00).

TM00 is incremented each time the valid edge specified by prescaler mode register 00 (PRM00) is input.

When the TM00 count value matches the 16-bit timer capture/compare register 000 (CR000) value, TM00 is cleared to 0 and the interrupt request signal (INTTM000) is generated.

Input a value other than 0000H to CR000. (A count operation with a pulse cannot be carried out.)

The rising edge, the falling edge, or both edges can be selected using bits 4 and 5 (ES000 and ES010) of prescaler mode register 00 (PRM00).

Because an operation is carried out only when the valid edge of the TI000 pin is detected twice after sampling with the internal clock (f_{XP}), noise with a short pulse width can be removed.

Figure 6-15. Control Register Settings in External Event Counter Mode (with Rising Edge Specified)

(a) Capture/compare control register 00 (CRC00)

	7	6	5	4	3	CRC002	CRC001	CRC000
CRC00	0	0	0	0	0	0/1	0/1	0

CR000 used as compare register

(b) Prescaler mode register 00 (PRM00)

	ES110	ES100	ES010	ES000	3	2	PRM001	PRM000
PRM00	0/1	0/1	0	1	0	0	1	1

Selects external clock.

Specifies rising edge for pulse width detection.

Setting invalid (setting “10” is prohibited.)

(c) 16-bit timer mode control register 00 (TMC00)

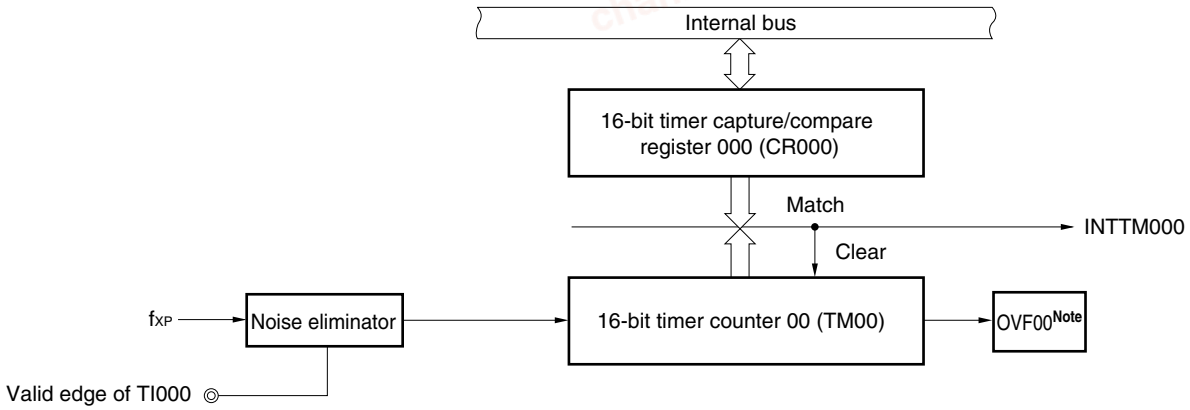
	7	6	5	4	TMC003	TMC002	TMC001	OVF00
TMC00	0	0	0	0	1	1	0/1	0

Clears and starts on match between TM00 and CR000.

Remark 0/1: Setting 0 or 1 allows another function to be used simultaneously with the external event counter. See the description of the respective control registers for details.

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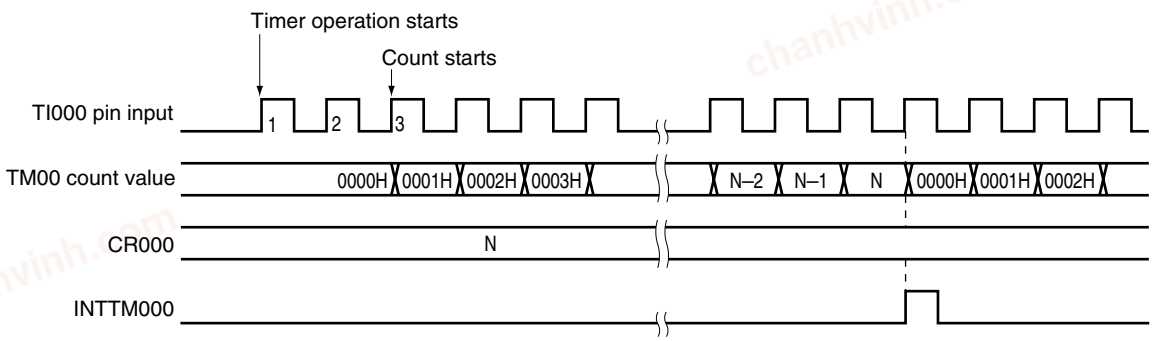
Figure 6-16. External Event Counter Configuration Diagram



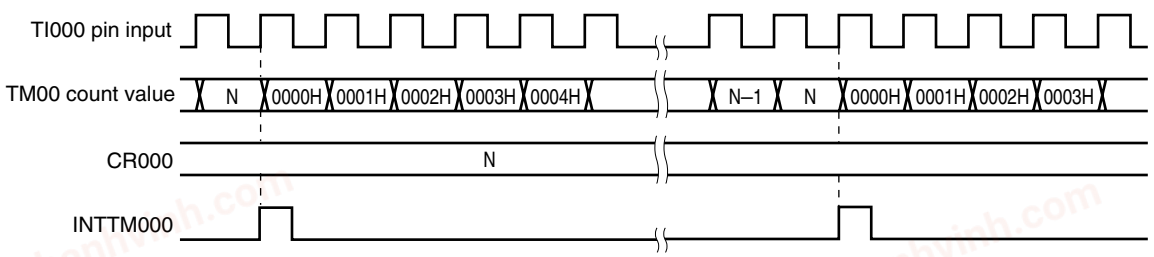
Note OVF00 is 1 only when 16-bit timer capture/compare register 000 (CR000) is set to FFFFH.

Figure 6-17. External Event Counter Operation Timing (with Rising Edge Specified)

(1) INTTM000 generation timing immediately after operation starts
Counting is started after a valid edge is detected twice.



(2) INTTM000 generation timing after INTTM000 has been generated twice



Caution When reading the external event counter count value, TM00 should be read.

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6.4.3 Pulse width measurement operations

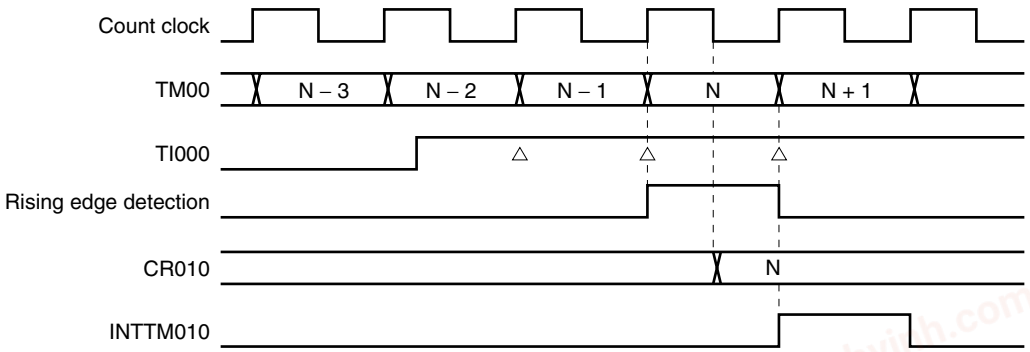
It is possible to measure the pulse width of the signals input to the TI000 pin and TI010 pin using 16-bit timer counter 00 (TM00).

There are two measurement methods: measuring with TM00 used in free-running mode, and measuring by restarting the timer in synchronization with the edge of the signal input to the TI000 pin.

When an interrupt occurs, necessary pulse width is calculable by reading the valid value of the capture register.

The capture operation is not performed until the signal pulse width is sampled in the count clock cycle selected by prescaler mode register 00 (PRM00) and the valid level of the TI000 or TI010 pin is detected twice, thus eliminating noise with a short pulse width (see **Figure 6-18**).

Figure 6-18. CR010 Capture Operation with Rising Edge Specified



Setting

The basic operation setting procedure is as follows.

<1> Set the CRC00 register (see **Figures 6-19**, **6-22**, **6-24**, and **6-26** for the set value).
<2> Set the count clock by using the PRM00 register.
<3> Set the TMC00 register to start the operation (see **Figures 6-19**, **6-22**, **6-24**, and **6-26** for the set value).

Caution To use two capture registers, set the TI000 and TI010 pins.

Remarks 1. For the setting of the TI000 (or TI010) pin, see **6.3 (5) Port mode register 2 (PM2) and port mode control register 2 (PMC2)**.

2. For how to enable the INTTM000 (or INTTM010) interrupt, see **CHAPTER 10 INTERRUPT FUNCTIONS**.

(1) Pulse width measurement with free-running counter and one capture register

Specify both the rising and falling edges as the valid edges of the TI000 pin, by using bits 4 and 5 (ES000 and ES010) of PRM00.

When 16-bit timer counter 00 (TM00) is operated in free-running mode, and the valid edge specified by PRM00 is input, the value of TM00 is taken into 16-bit timer capture/compare register 010 (CR010) and an external interrupt request signal (INTTM010) is set.

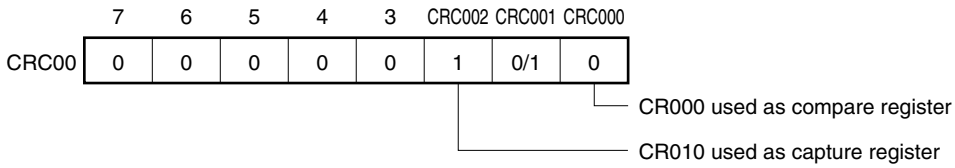
Sampling is performed using the count clock selected by PRM00, and a capture operation is only performed when a valid level of the TI000 pin is detected twice, thus eliminating noise with a short pulse width.

Caution The measurable pulse width in this operation example is up to 1 cycle of the timer counter.

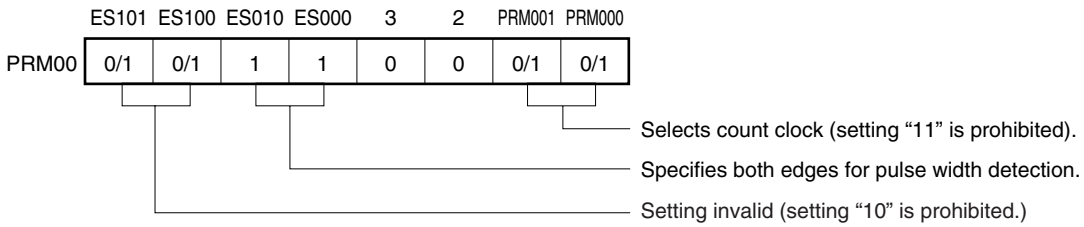
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Figure 6-19. Control Register Settings for Pulse Width Measurement with Free-Running Counter and One Capture Register (When TI000 and CR010 Are Used)

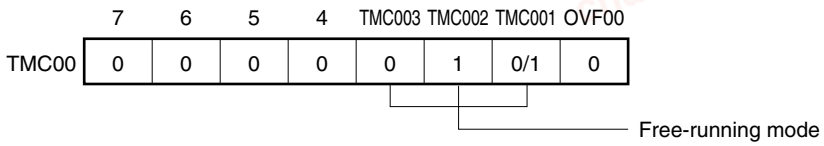
(a) Capture/compare control register 00 (CRC00)



(b) Prescaler mode register 00 (PRM00)

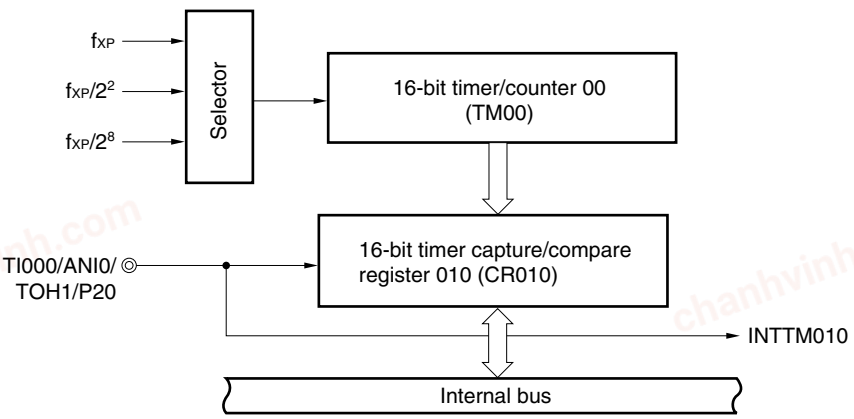


(c) 16-bit timer mode control register 00 (TMC00)



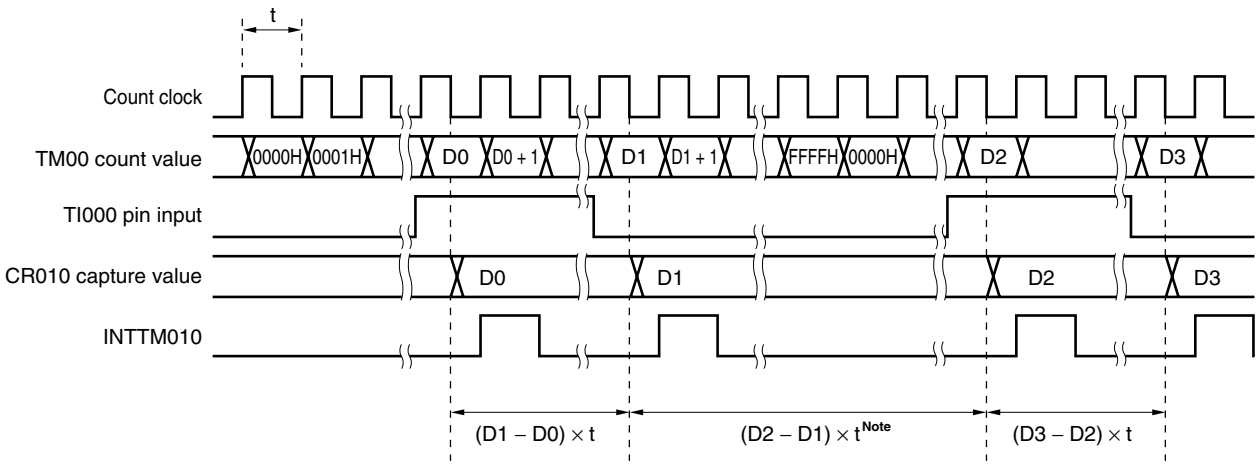
Remark 0/1: Setting 0 or 1 allows another function to be used simultaneously with pulse width measurement. See the description of the respective control registers for details.

Figure 6-20. Configuration Diagram for Pulse Width Measurement by Free-Running Counter



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Figure 6-21. Timing of Pulse Width Measurement Operation by Free-Running Counter and One Capture Register (with Both Edges Specified)



Note The carry flag is set to 1. Ignore this setting.

(2) Measurement of two pulse widths with free-running counter

When 16-bit timer counter 00 (TM00) is operated in free-running mode, it is possible to simultaneously measure the pulse widths of the two signals input to the TI000 pin and the TI010 pin.

Specify both the rising and falling edges as the valid edges of the TI000 and TI010 pins, by using bits 4 and 5 (ES000 and ES010) and bits 6 and 7 (ES100 and ES110) of PRM00.

When the valid edge specified by bits 4 and 5 (ES000 and ES010) of prescaler mode register 00 (PRM00) is input to the TI000 pin, the value of TM00 is taken into 16-bit timer capture/compare register 010 (CR010) and an interrupt request signal (INTTM010) is set.

Also, when the valid edge specified by bits 6 and 7 (ES100 and ES110) of PRM00 is input to the TI010 pin, the value of TM00 is taken into 16-bit timer capture/compare register 000 (CR000) and an interrupt request signal (INTTM000) is set.

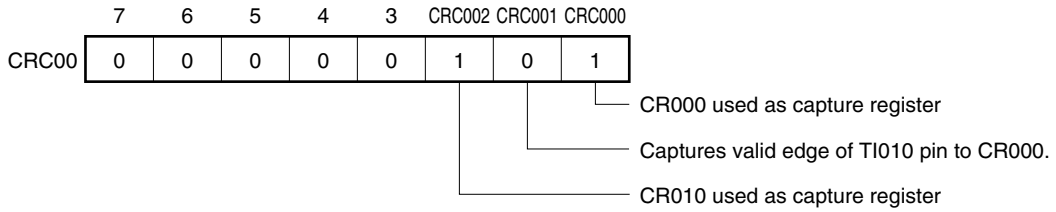
Sampling is performed using the count clock cycle selected by prescaler mode register 00 (PRM00), and a capture operation is only performed when a valid level of the TI000 or TI010 pin is detected twice, thus eliminating noise with a short pulse width.

Caution The measurable pulse width in this operation example is up to 1 cycle of the timer counter.

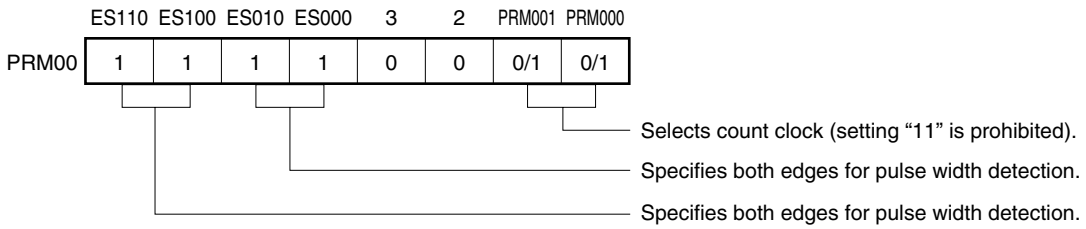
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Figure 6-22. Control Register Settings for Measurement of Two Pulse Widths with Free-Running Counter

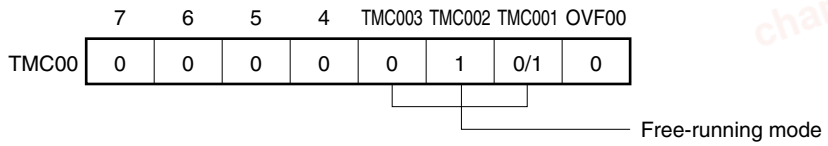
(a) Capture/compare control register 00 (CRC00)



(b) Prescaler mode register 00 (PRM00)



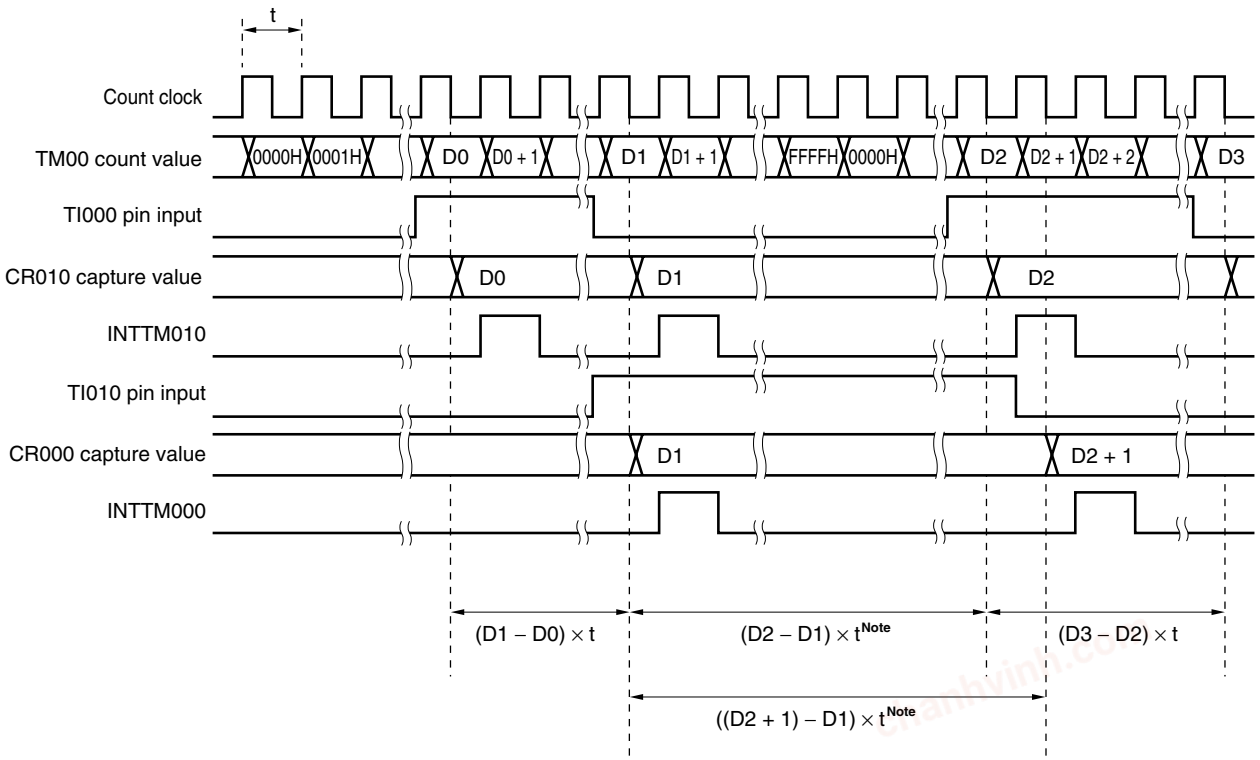
(c) 16-bit timer mode control register 00 (TMC00)



Remark 0/1: Setting 0 or 1 allows another function to be used simultaneously with pulse width measurement. See the description of the respective control registers for details.

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Figure 6-23. Timing of Pulse Width Measurement Operation with Free-Running Counter (with Both Edges Specified)



Note The carry flag is set to 1. Ignore this setting.

(3) Pulse width measurement with free-running counter and two capture registers

When 16-bit timer counter 00 (TM00) is operated in free-running mode, it is possible to measure the pulse width of the signal input to the TI000 pin.

Specify both the rising and falling edges as the valid edges of the TI000 pin, by using bits 4 and 5 (ES000 and ES010) of PRM00.

When the rising or falling edge specified by bits 4 and 5 (ES000 and ES010) of prescaler mode register 00 (PRM00) is input to the TI000 pin, the value of TM00 is taken into 16-bit timer capture/compare register 010 (CR010) and an interrupt request signal (INTTM010) is set.

Also, when the inverse edge to that of the capture operation is input into CR010, the value of TM00 is taken into 16-bit timer capture/compare register 000 (CR000).

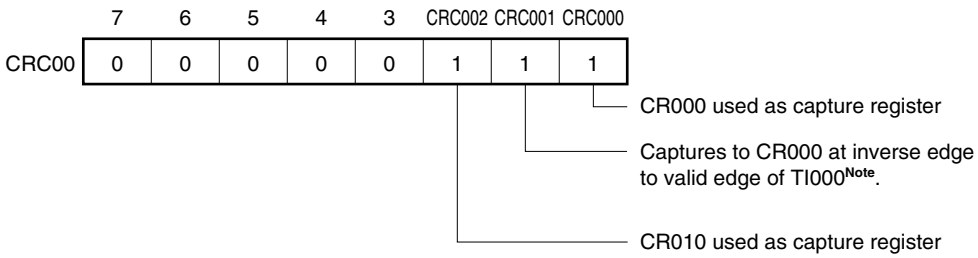
Sampling is performed using the count clock cycle selected by prescaler mode register 00 (PRM00), and a capture operation is only performed when a valid level of the TI000 pin is detected twice, thus eliminating noise with a short pulse width.

Caution The measurable pulse width in this operation example is up to 1 cycle of the timer counter.

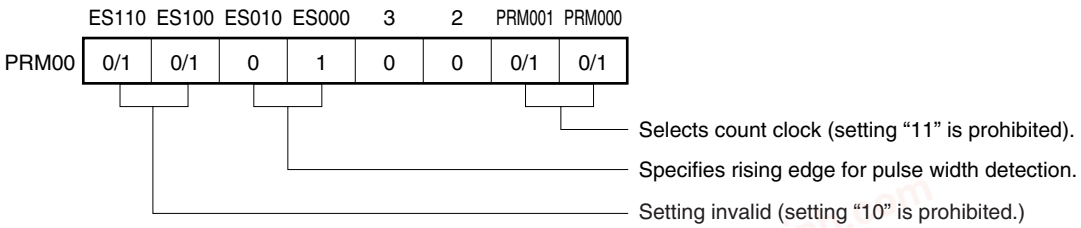
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Figure 6-24. Control Register Settings for Pulse Width Measurement with Free-Running Counter and Two Capture Registers (with Rising Edge Specified)

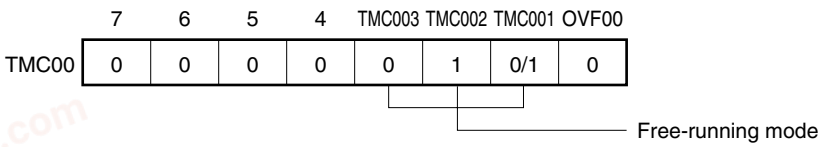
(a) Capture/compare control register 00 (CRC00)



(b) Prescaler mode register 00 (PRM00)



(c) 16-bit timer mode control register 00 (TMC00)

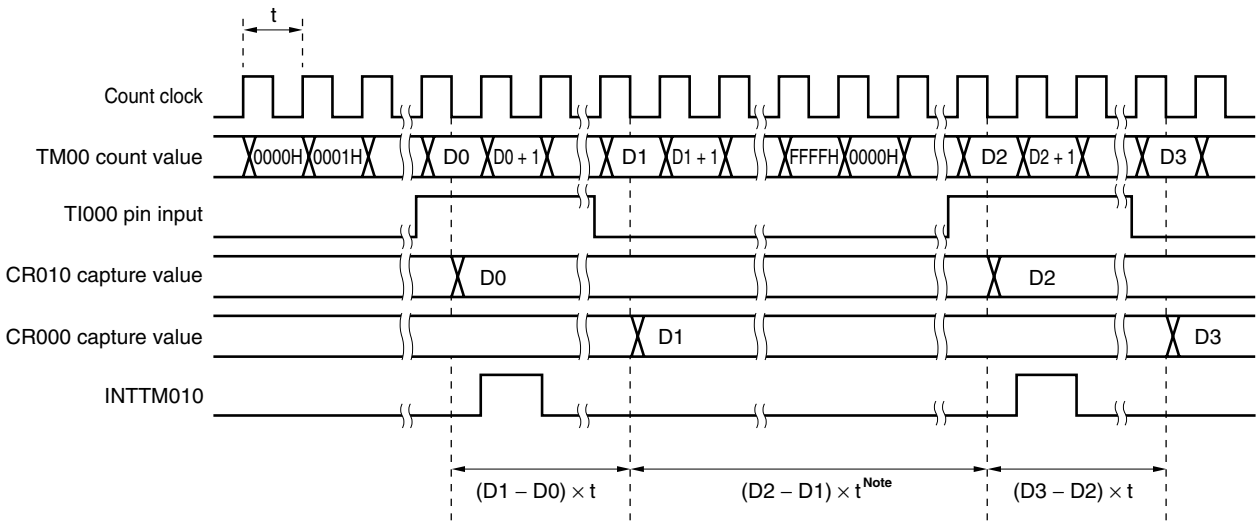


Note If the valid edge of TI000 is specified to be both the rising and falling edges, 16-bit timer capture/compare register 000 (CR000) cannot perform the capture operation. When the CRC001 bit value is 1, the TM00 count value is not captured in the CR000 register when a valid edge of the TI010 pin is detected, but the input from the TI010 pin can be used as an external interrupt source because INTTM000 is generated at that timing.

Remark 0/1: Setting 0 or 1 allows another function to be used simultaneously with pulse width measurement. See the description of the respective control registers for details.

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Figure 6-25. Timing of Pulse Width Measurement Operation by Free-Running Counter and Two Capture Registers (with Rising Edge Specified)



Note The carry flag is set to 1. Ignore this setting.

(4) Pulse width measurement by means of restart

Specify both the rising and falling edges as the valid edges of the TI000 pin, by using bits 4 and 5 (ES000 and ES010) of PRM00.

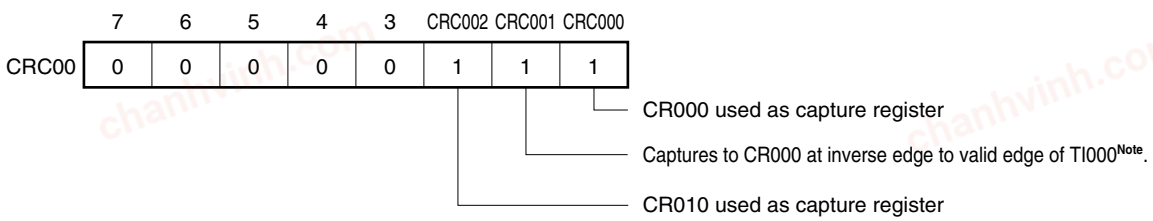
When input of a valid edge to the TI000 pin is detected, the count value of 16-bit timer/counter 00 (TM00) is taken into 16-bit timer capture/compare register 010 (CR010), and then the pulse width of the signal input to the TI000 pin is measured by clearing TM00 and restarting the count.

Sampling is performed at the interval selected by prescaler mode register 00 (PRM00) and a capture operation is only performed when a valid level of the TI000 pin is detected twice, thus eliminating noise with a short pulse width.

Caution The measurable pulse width in this operation example is up to 1 cycle of the timer counter.

Figure 6-26. Control Register Settings for Pulse Width Measurement by Means of Restart (with Rising Edge Specified) (1/2)

(a) Capture/compare control register 00 (CRC00)

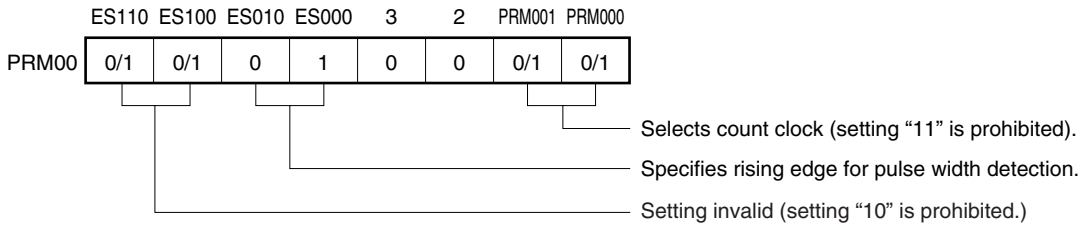


Note If the valid edge of TI000 is specified to be both the rising and falling edges, 16-bit timer capture/compare register 000 (CR000) cannot perform the capture operation.

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Figure 6-26. Control Register Settings for Pulse Width Measurement by Means of Restart (with Rising Edge Specified) (2/2)

(b) Prescaler mode register 00 (PRM00)



(c) 16-bit timer mode control register 00 (TMC00)

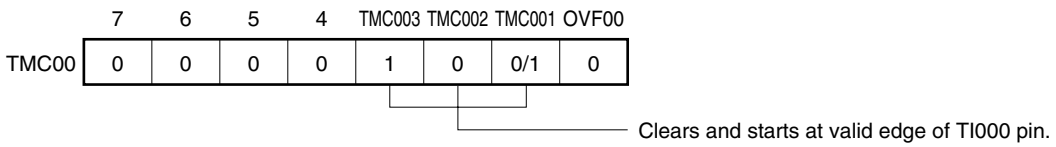
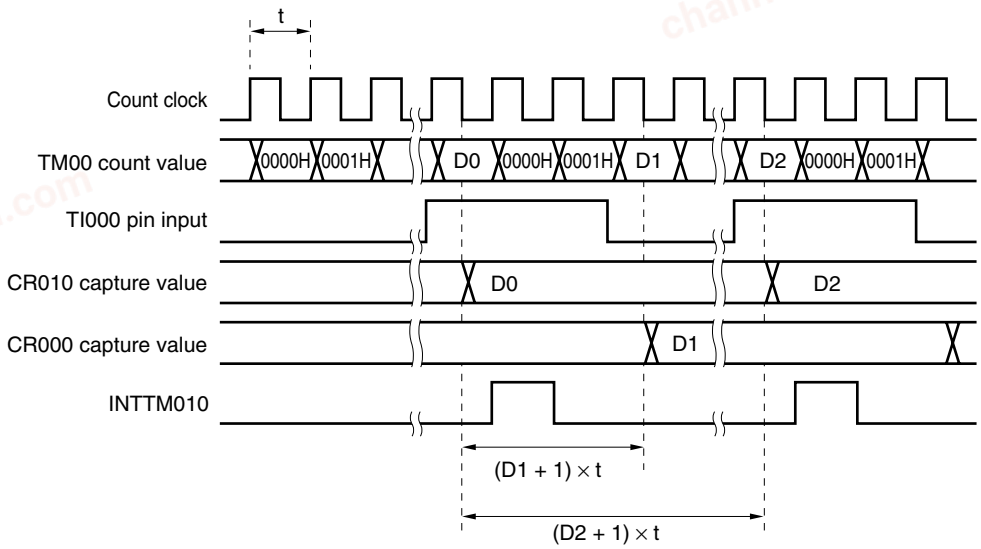


Figure 6-27. Timing of Pulse Width Measurement Operation by Means of Restart (with Rising Edge Specified)



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6.4.4 Square-wave output operation

Setting

The basic operation setting procedure is as follows.

<1> Set the count clock by using the PRM00 register.
<2> Set the CRC00 register (see **Figure 6-28** for the set value).
<3> Set the TOC00 register (see **Figure 6-28** for the set value).
<4> Set any value to the CR000 register (0000H cannot be set).
<5> Set the TMC00 register to start the operation (see **Figure 6-28** for the set value).

Caution Changing the CR000 setting during TM00 operation may cause a malfunction. To change the setting, refer to 6.5 Cautions Related to 16-bit Timer/Event Counter 00 (17) Changing compare register during timer operation.

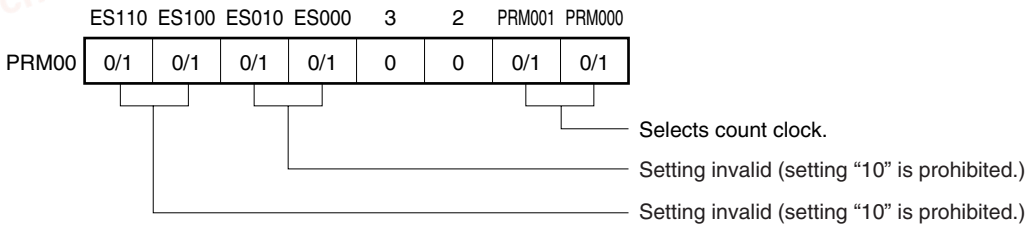
Remarks 1. For the setting of the TO00 pin, see **6.3 (5) Port mode register 2 (PM2) and port mode control register 2 (PMC2)**.
2. For how to enable the INTTM000 interrupt, see **CHAPTER 10 INTERRUPT FUNCTIONS**.

A square wave with any selected frequency can be output at intervals determined by the count value preset to 16-bit timer capture/compare register 000 (CR000).

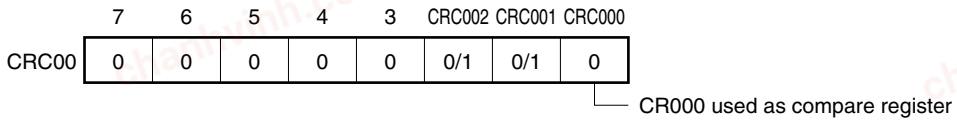
The TO00 pin output status is reversed at intervals determined by the count value preset to CR000 + 1 by setting bit 0 (TOE00) and bit 1 (TOC001) of 16-bit timer output control register 00 (TOC00) to 1. This enables a square wave with any selected frequency to be output.

Figure 6-28. Control Register Settings in Square-Wave Output Mode (1/2)

(a) Prescaler mode register 00 (PRM00)



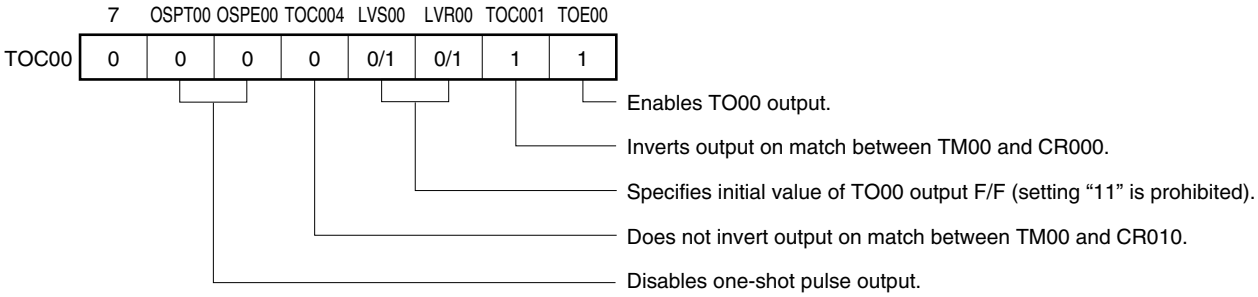
(b) Capture/compare control register 00 (CRC00)



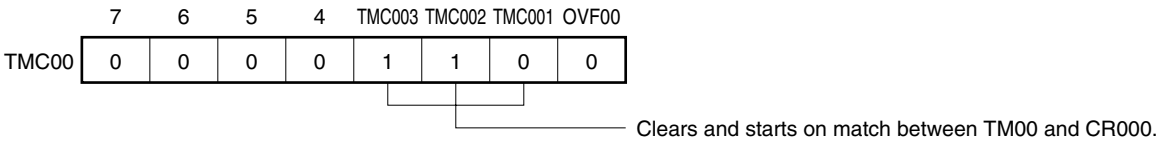
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Figure 6-28. Control Register Settings in Square-Wave Output Mode (2/2)

(c) 16-bit timer output control register 00 (TOC00)

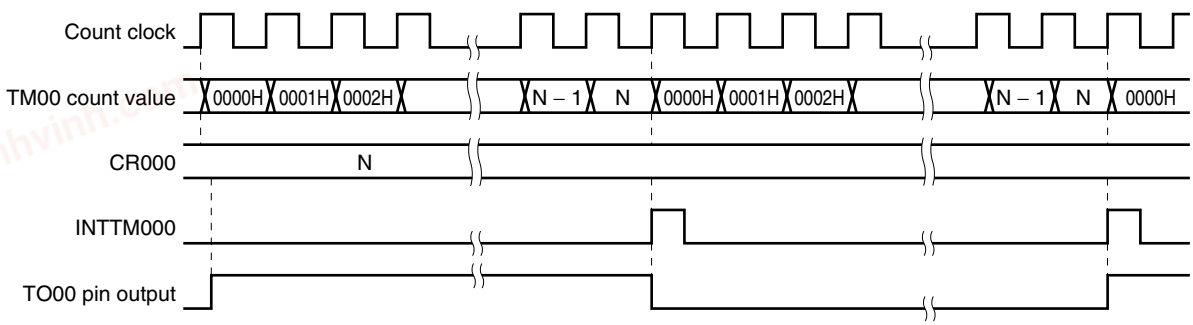


(d) 16-bit timer mode control register 00 (TMC00)



Remark 0/1: Setting 0 or 1 allows another function to be used simultaneously with square-wave output. See the description of the respective control registers for details.

Figure 6-29. Square-Wave Output Operation Timing



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6.4.5 PPG output operations

Setting 16-bit timer mode control register 00 (TMC00) and capture/compare control register 00 (CRC00) as shown in Figure 6-30 allows operation as PPG (Programmable Pulse Generator) output.

Setting

The basic operation setting procedure is as follows.

<1> Set the CRC00 register (see **Figure 6-30** for the set value).
<2> Set any value to the CR000 register as the cycle.
<3> Set any value to the CR010 register as the duty factor.
<4> Set the TOC00 register (see **Figure 6-30** for the set value).
<5> Set the count clock by using the PRM00 register.
<6> Set the TMC00 register to start the operation (see **Figure 6-30** for the set value).

Caution Changing the CRC0n0 setting during TM00 operation may cause a malfunction. To change the setting, refer to 6.5 Cautions Related to 16-bit Timer/Event Counter 00 (17) Changing compare register during timer operation.

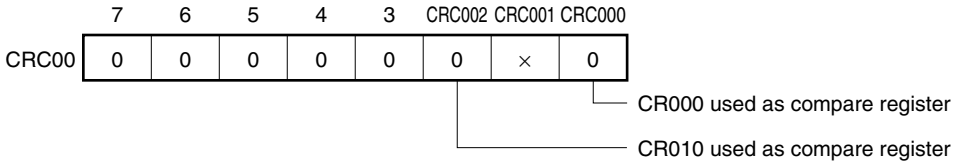
Remarks 1. For the setting of the TO00 pin, see **6.3 (5) Port mode register 2 (PM2) and port mode control register 2 (PMC2)**.
2. For how to enable the INTTM000 interrupt, see **CHAPTER 10 INTERRUPT FUNCTIONS**.
3. n = 0 or 1

In the PPG output operation, rectangular waves are output from the TO00 pin with the pulse width and the cycle that correspond to the count values preset in 16-bit timer capture/compare register 010 (CR010) and in 16-bit timer capture/compare register 000 (CR000), respectively.

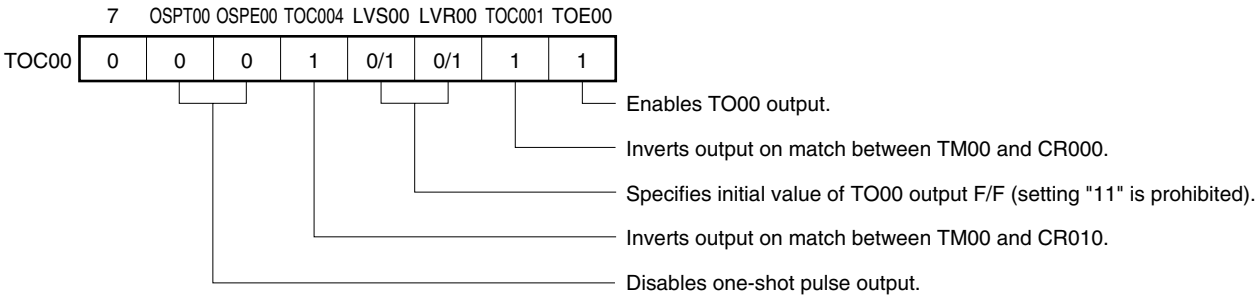
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Figure 6-30. Control Register Settings for PPG Output Operation

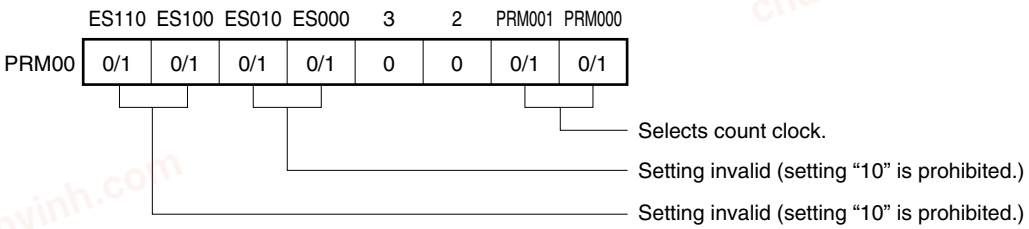
(a) Capture/compare control register 00 (CRC00)



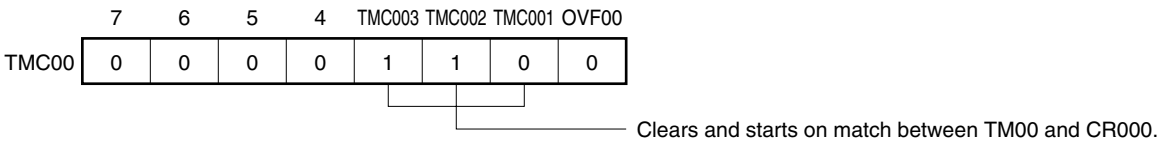
(b) 16-bit timer output control register 00 (TOC00)



(c) Prescaler mode register 00 (PRM00)



(d) 16-bit timer mode control register 00 (TMC00)



Cautions 1. Values in the following range should be set to CR000 and CR010:
0000H < CR010 < CR000 ≤ FFFFH

2. The cycle of the pulse generated through PPG output (CR000 setting value + 1) has a duty of (CR010 setting value + 1)/(CR000 setting value + 1).

Remark ×: Don’t care

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Figure 6-31. Configuration Diagram of PPG Output

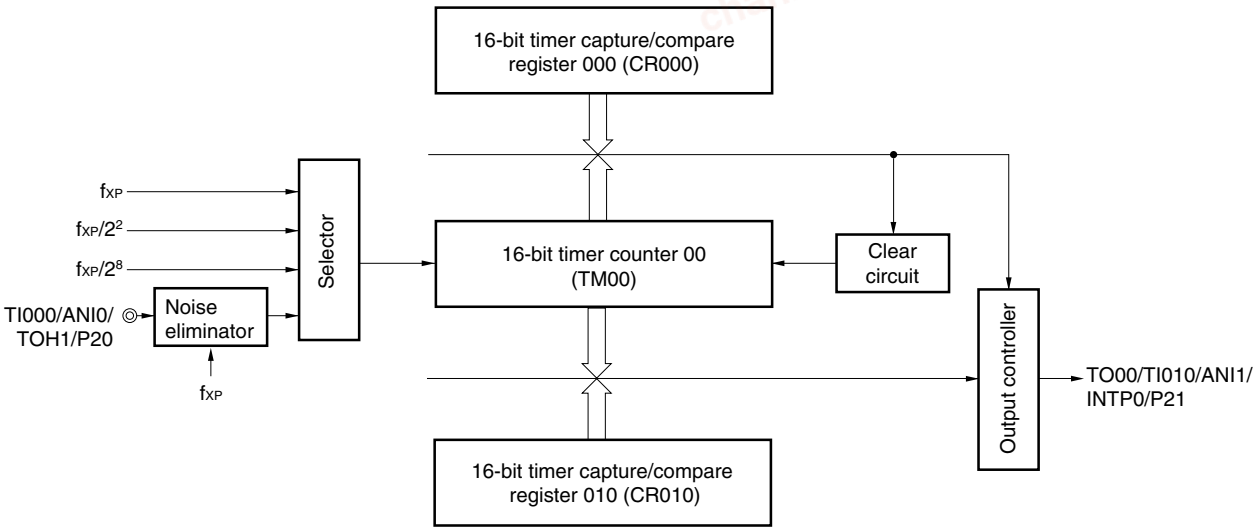
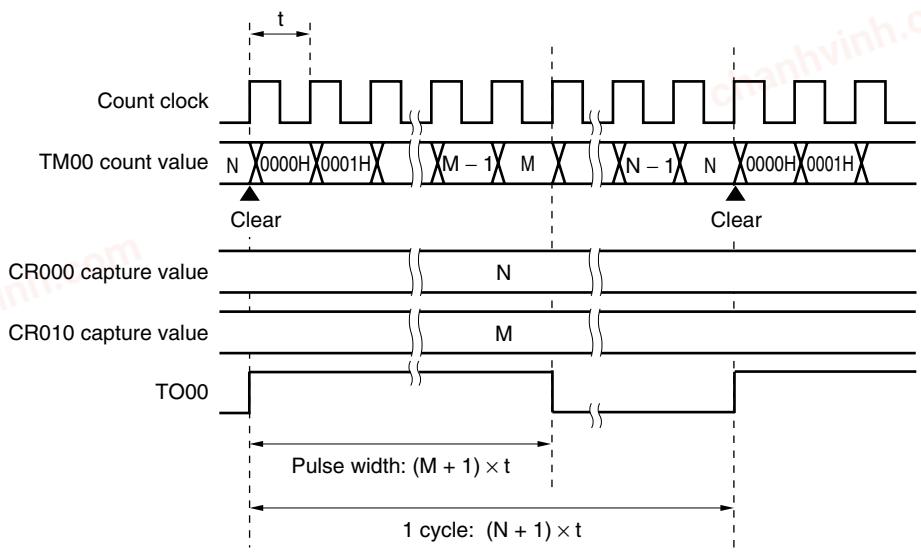


Figure 6-32. PPG Output Operation Timing



Remark 0000H < M < N ≤ FFFFH

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6.4.6 One-shot pulse output operation

16-bit timer/event counter 00 can output a one-shot pulse in synchronization with a software trigger or an external trigger (TI000 pin input).

Setting

The basic operation setting procedure is as follows.

<1> Set the count clock by using the PRM00 register.
<2> Set the CRC00 register (see **Figures 6-33** and **6-35** for the set value).
<3> Set the TOC00 register (see **Figures 6-33** and **6-35** for the set value).
<4> Set any value to the CR000 and CR010 registers (0000H cannot be set).
<5> Set the TMC00 register to start the operation (see **Figures 6-33** and **6-35** for the set value).

Remarks 1. For the setting of the TO00 pin, see **6.3 (5) Port mode register 2 (PM2) and port mode control register 2 (PMC2)**.

2. For how to enable the INTTM000 (if necessary, INTTM010) interrupt, see **CHAPTER 10 INTERRUPT FUNCTIONS**.

(1) One-shot pulse output with software trigger

A one-shot pulse can be output from the TO00 pin by setting 16-bit timer mode control register 00 (TMC00), capture/compare control register 00 (CRC00), and 16-bit timer output control register 00 (TOC00) as shown in Figure 6-33, and by setting bit 6 (OSPT00) of the TOC00 register to 1 by software.

By setting the OSPT00 bit to 1, 16-bit timer/event counter 00 is cleared and started, and its output becomes active at the count value (N) set in advance to 16-bit timer capture/compare register 010 (CR010). After that, the output becomes inactive at the count value (M) set in advance to 16-bit timer capture/compare register 000 (CR000)[Note].

Even after the one-shot pulse has been output, the TM00 register continues its operation. To stop the TM00 register, the TMC003 and TMC002 bits of the TMC00 register must be cleared to 00.

Note The case where N < M is described here. When N > M, the output becomes active with the CR000 register and inactive with the CR010 register. Do not set N to M.

Cautions 1. Do not set the OSPT00 bit to 1 again while the one-shot pulse is being output. To output the one-shot pulse again, wait until the current one-shot pulse output is completed.

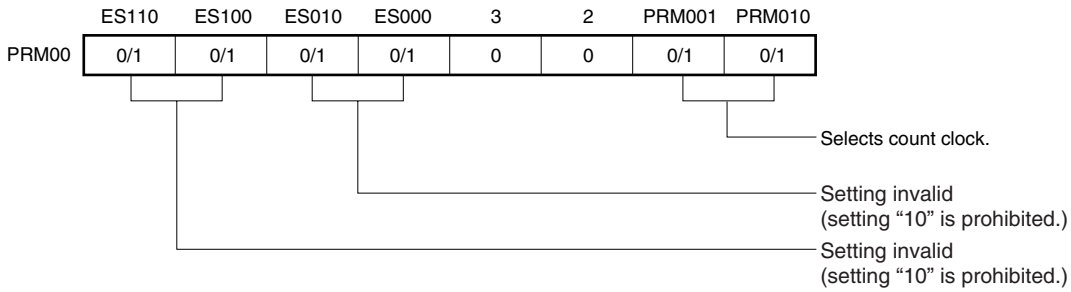
2. When using the one-shot pulse output of 16-bit timer/event counter 00 with a software trigger, do not change the level of the TI000 pin or its alternate-function port pin.

Because the external trigger is valid even in this case, the timer is cleared and started even at the level of the TI000 pin or its alternate-function port pin, resulting in the output of a pulse at an undesired timing.

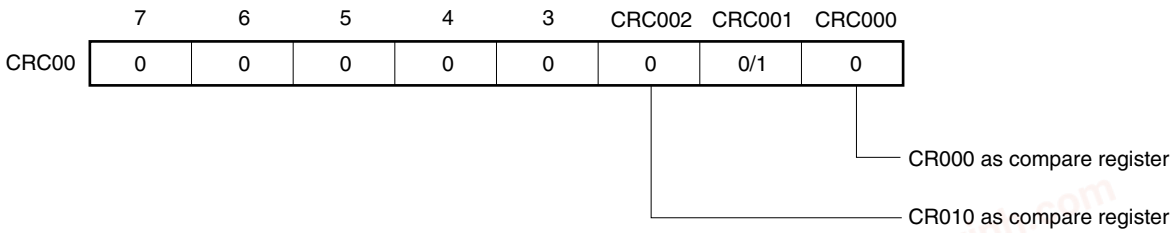
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Figure 6-33. Control Register Settings for One-Shot Pulse Output with Software Trigger

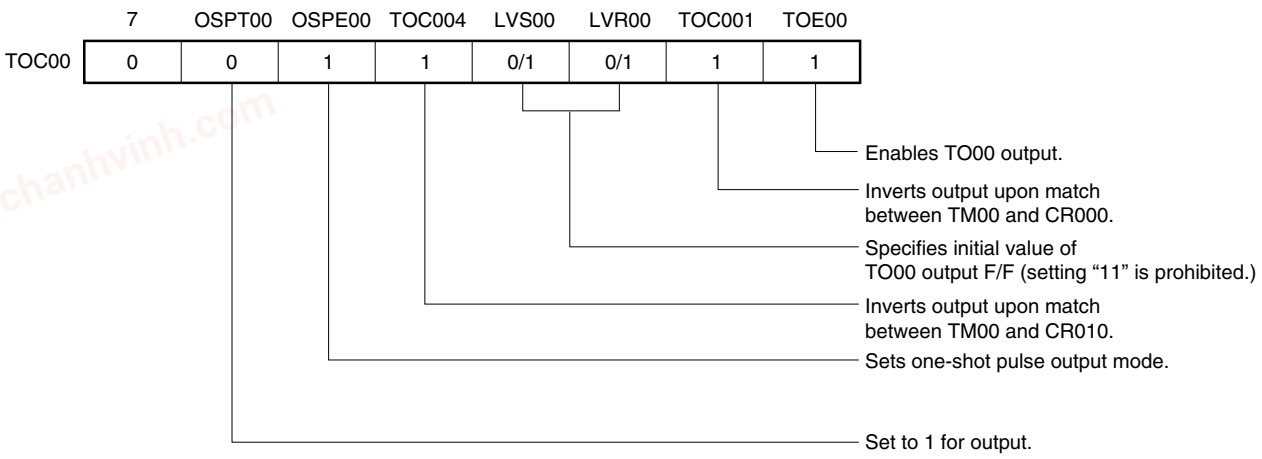
(a) Prescaler mode register 00 (PRM00)



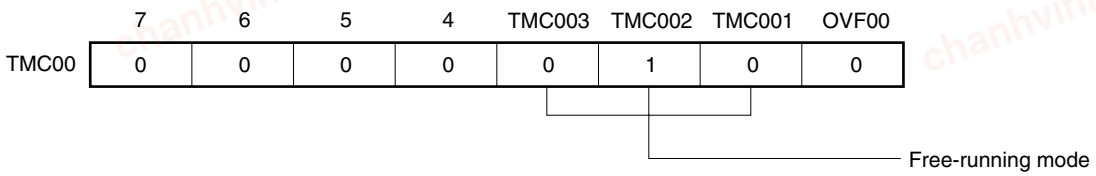
(b) Capture/compare control register 00 (CRC00)



(c) 16-bit timer output control register 00 (TOC00)



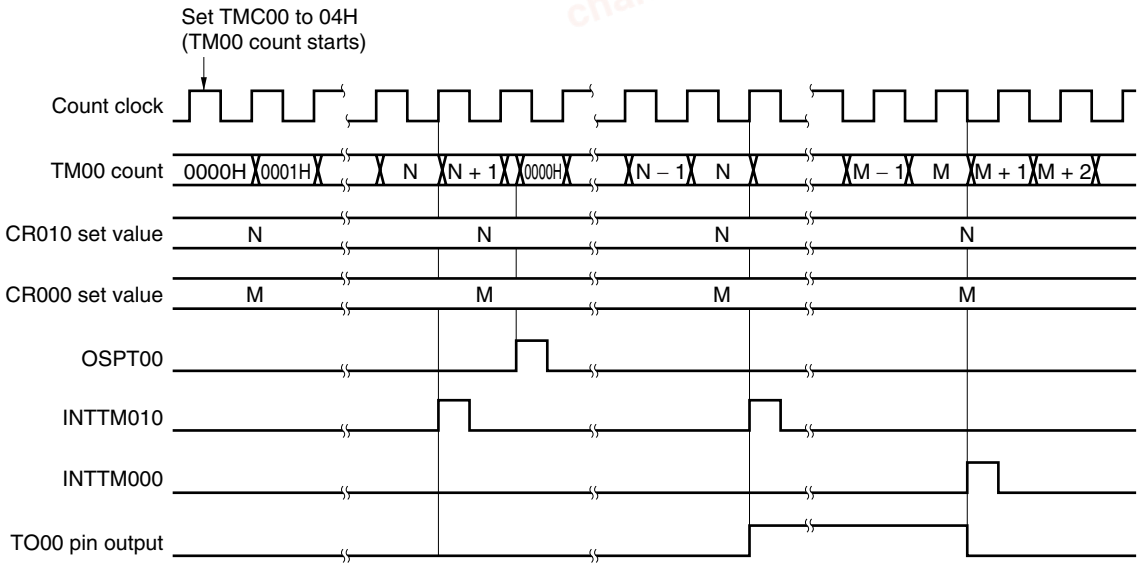
(d) 16-bit timer mode control register 00 (TMC00)



Caution Do not set 0000H to the CR000 and CR010 registers.

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Figure 6-34. Timing of One-Shot Pulse Output Operation with Software Trigger



Caution 16-bit timer counter 00 starts operating as soon as a value other than 00 (operation stop mode) is set to the TMC003 and TMC002 bits.

Remark N < M

(2) One-shot pulse output with external trigger

A one-shot pulse can be output from the TO00 pin by setting 16-bit timer mode control register 00 (TMC00), capture/compare control register 00 (CRC00), and 16-bit timer output control register 00 (TOC00) as shown in Figure 6-35, and by using the valid edge of the TI000 pin as an external trigger.

The valid edge of the TI000 pin is specified by bits 4 and 5 (ES000, ES010) of prescaler mode register 00 (PRM00). The rising, falling, or both the rising and falling edges can be specified.

When the valid edge of the TI000 pin is detected, the 16-bit timer/event counter is cleared and started, and the output becomes active at the count value set in advance to 16-bit timer capture/compare register 010 (CR010). After that, the output becomes inactive at the count value set in advance to 16-bit timer capture/compare register 000 (CR000)[Note].

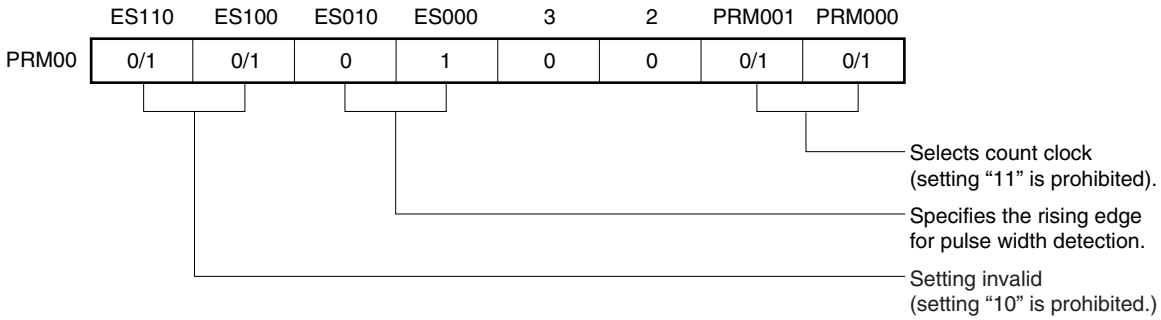
Note The case where N < M is described here. When N > M, the output becomes active with the CR000 register and inactive with the CR010 register. Do not set N to M.

Caution Do not input the external trigger again while the one-shot pulse is output.
To output the one-shot pulse again, wait until the current one-shot pulse output is completed.

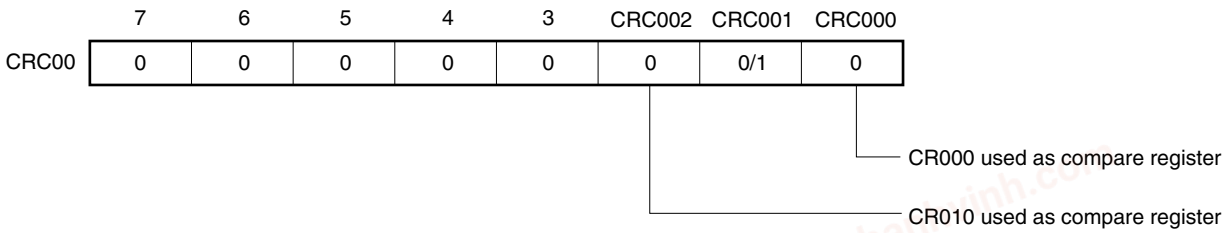
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Figure 6-35. Control Register Settings for One-Shot Pulse Output with External Trigger (with Rising Edge Specified)

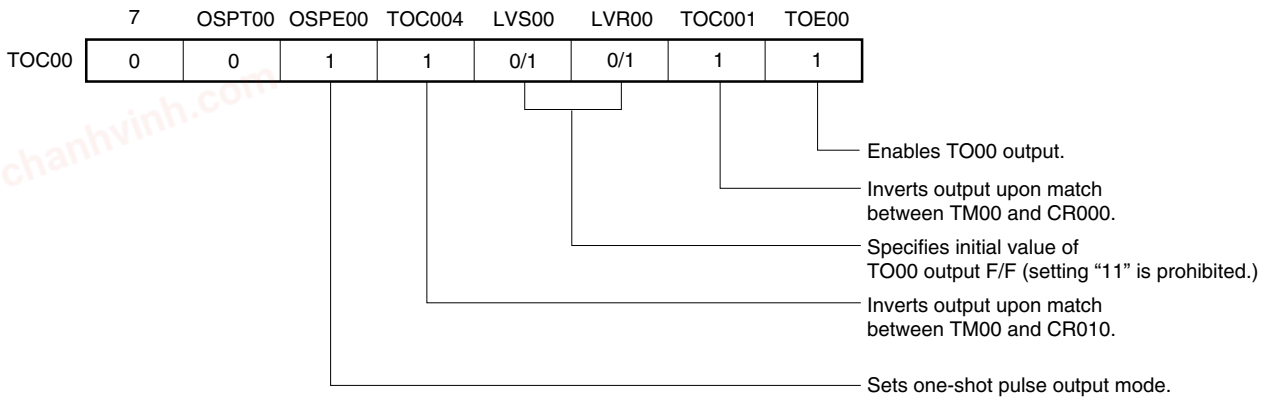
(a) Prescaler mode register 00 (PRM00)



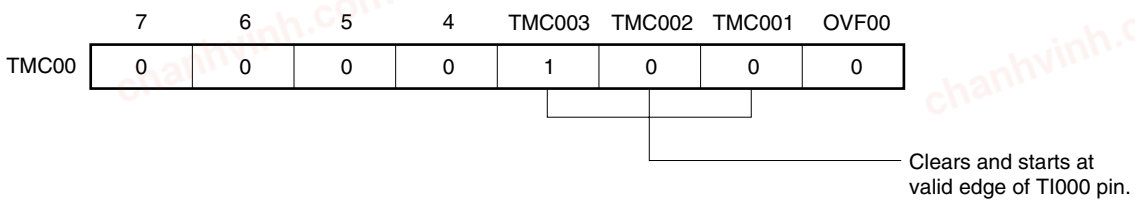
(b) Capture/compare control register 00 (CRC00)



(c) 16-bit timer output control register 00 (TOC00)



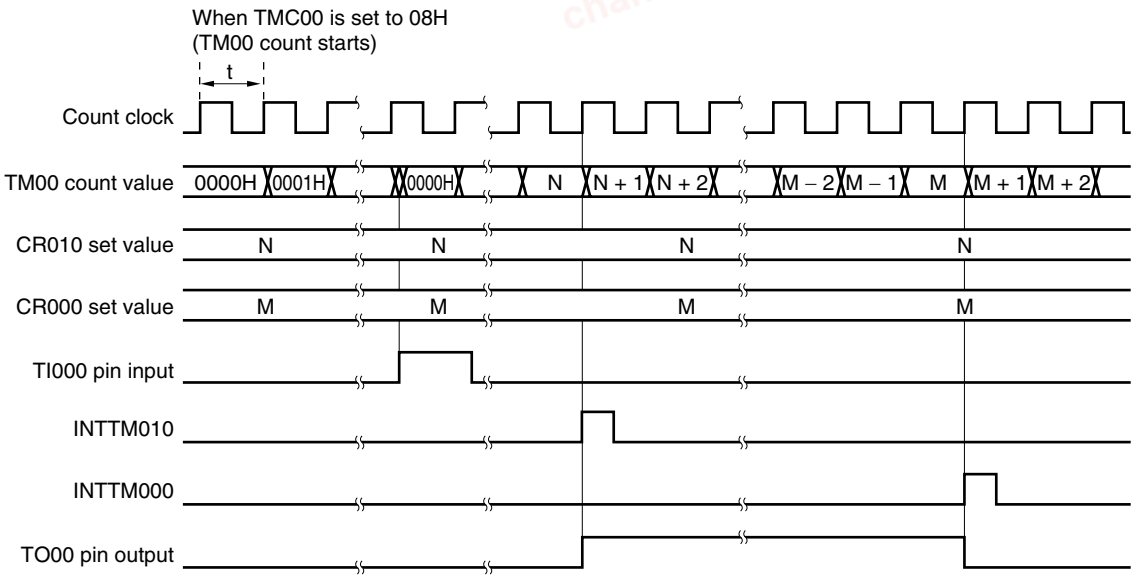
(d) 16-bit timer mode control register 00 (TMC00)



Caution Do not set 0000H to the CR000 and CR010 registers.

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Figure 6-36. Timing of One-Shot Pulse Output Operation with External Trigger (with Rising Edge Specified)



Caution 16-bit timer counter 00 starts operating as soon as a value other than 00 (operation stop mode) is set to the TMC002 and TMC003 bits.

Remark N < M

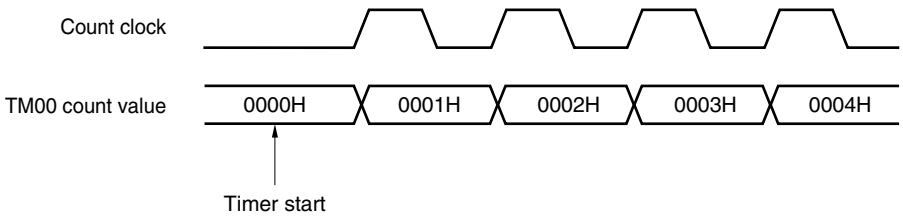
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6.5 Cautions Related to 16-bit Timer/Event Counter 00

(1) Timer start errors

An error of up to one clock may occur in the time required for a match signal to be generated after timer start. This is because 16-bit timer counter 00 (TM00) is started asynchronously to the count clock.

Figure 6-37. Start Timing of 16-bit Timer Counter 00 (TM00)



(2) 16-bit timer counter 00 (TM00) operation

<1> 16-bit timer counter 00 (TM00) starts operating as soon as values other than 0 and 0 (operation stop mode) are set to TMC002 and TMC003, respectively. Set TMC002 and TMC003 to 0 and 0 to stop operation.

<2> Even if TM00 is read, the value is not captured by 16-bit timer capture/compare register 010 (CR010).

<3> When TM00 is read, count misses do not occur, since the input of the count clock is temporarily stopped and then resumed after the read.

<4> If the timer is stopped, timer counts and timer interrupts do not occur, even if a signal is input to the TI000/TI010 pins.

(3) Setting of 16-bit timer capture/compare registers 000, 010 (CR000, CR010)

<1> Set 16-bit timer capture/compare register 000 (CR000) to other than 0000H in the clear & start mode entered on match between TM00 and CR000. This means a 1-pulse count operation cannot be performed when this register is used as an external event counter.

<2> When the clear & start mode entered on a match between TM00 and CR000 is selected, CR000 should not be specified as a capture register.

<3> In the free-running mode and in the clear & start mode using the valid edge of the TI000 pin, if CR0n0 is set to 0000H, an interrupt request (INTTM0n0) is generated when CR0n0 changes from 0000H to 0001H after an overflow (FFFFH).

<4> If the new value of CR0n0 is less than the value of TM00, TM00 continues counting, overflows, and then starts counting from 0 again. If the new value of CR0n0 is less than the old value, therefore, the timer must be reset to be restarted after the value of CR0n0 is changed.

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(4) Capture register data retention

The values of 16-bit timer capture/compare registers 0n0 (CR0n0) after 16-bit timer/event counter 00 has stopped are not guaranteed.

Remark n = 0, 1

(5) Setting of 16-bit timer mode control register 00 (TMC00)

The timer operation must be stopped before writing to bits other than the OVF00 flag.

(6) Setting of capture/compare control register 00 (CRC00)

The timer operation must be stopped before setting CRC00.

(7) Setting of 16-bit timer output control register 00 (TOC00)

<1> Timer operation must be stopped before setting other than OSPT00.

<2> If LVS00 and LVR00 are read, 0 is read.

<3> OSPT00 is automatically cleared after data is set, so 0 is read.

<4> Do not set OSPT00 to 1 other than in one-shot pulse output mode.

<5> A write interval of two cycles or more of the count clock selected by prescaler mode register 00 (PRM00) is required, when OSPT00 is set to 1 successively.

(8) Setting of prescaler mode register 00 (PRM00)

Always set data to PRM00 after stopping the timer operation.

(9) Valid edge setting

Set the valid edge of the TI000 pin with bits 4 and 5 (ES000 and ES010) of prescaler mode register 00 (PRM00) after stopping the timer operation.

(10) One-shot pulse output

One-shot pulse output normally operates only in the free-running mode or in the clear & start mode at the valid edge of the TI000 pin. Because an overflow does not occur in the clear & start mode on a match between TM00 and CR000, one-shot pulse output is not possible.

(11) One-shot pulse output by software

<1> Do not set the OSPT00 bit to 1 again while the one-shot pulse is being output. To output the one-shot pulse again, wait until the current one-shot pulse output is completed.

<2> When using the one-shot pulse output of 16-bit timer/event counter 00 with a software trigger, do not change the level of the TI000 pin or its alternate function port pin.
Because the external trigger is valid even in this case, the timer is cleared and started even at the level of the TI000 pin or its alternate function port pin, resulting in the output of a pulse at an undesired timing.

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<3> Do not set the 16-bit timer capture/compare registers 000 and 010 (CR000 and CR010) to 0000H.

(12) One-shot pulse output with external trigger

<1> Do not input the external trigger again while the one-shot pulse is output.
To output the one-shot pulse again, wait until the current one-shot pulse output is completed.

<2> Do not set the 16-bit timer capture/compare registers 000 and 010 (CR000 and CR010) to 0000H.

(13) Operation of OVF00 flag

<1> The OVF00 flag is also set to 1 in the following case.
Either of the clear & start mode entered on a match between TM00 and CR000, clear & start at the valid edge of the TI000 pin, or free-running mode is selected.

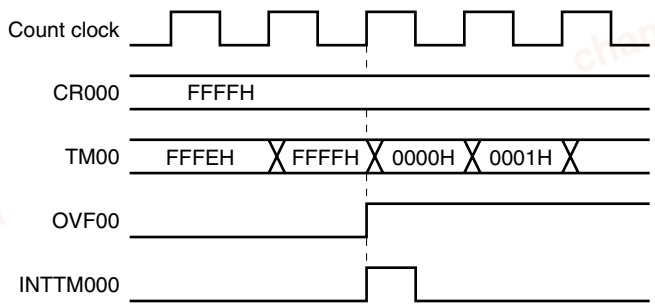
↓

CR000 is set to FFFFH.

↓

When TM00 is counted up from FFFFH to 0000H.

Figure 6-38. Operation Timing of OVF00 Flag



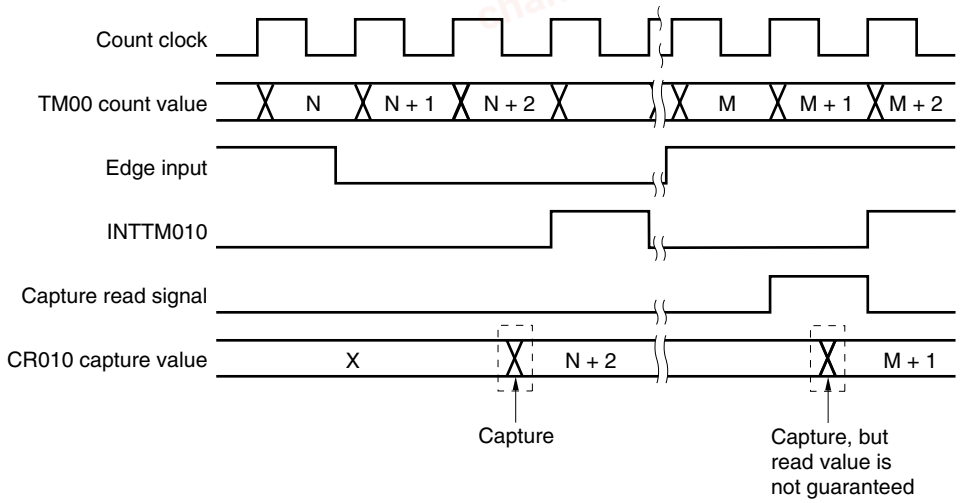
<2> Even if the OVF00 flag is cleared before the next count clock is counted (before TM00 becomes 0001H) after the occurrence of a TM00 overflow, the OVF00 flag is re-set and clearance becomes invalid.

(14) Conflicting operations

If the register read period and the input of the capture trigger conflict when CR000/CR010 is used as a capture register, the capture trigger input takes precedence and the read data is undefined. Also, if the count stop of the timer and the input of the capture trigger conflict, the captured data is undefined.

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Figure 6-39. Capture Register Data Retention Timing



(15) Capture operation

<1> If the valid edge of the TI000 pin is to be set as the count clock, do not set the clear/start mode and the capture trigger at the valid edge of the TI000 pin.

<2> When the CRC001 bit value is 1, capture is not performed in the CR000 register if both the rising and falling edges have been selected as the valid edges of the TI000 pin.

<3> When the CRC001 bit value is 1, the TM00 count value is not captured in the CR000 register when a valid edge of the TI010 pin is detected, but the input from the TI010 pin can be used as an external interrupt source because INTTM000 is generated at that timing.

<4> To ensure the reliability of the capture operation, the capture trigger requires a pulse longer than two cycles of the count clock selected by prescaler mode register 00 (PRM00).

<5> The capture operation is performed at the fall of the count clock. An interrupt request input (INTTM0n0), however, occurs at the rise of the next count clock.

<6> To use two capture registers, set the TI000 and TI010 pins.

Remark n = 0, 1

(16) Compare operation

The capture operation may not be performed for CR0n0 set in compare mode even if a capture trigger is input.

Remark n = 0, 1

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(17) Changing compare register during timer operation

<1> With the 16-bit timer capture/compare register 0n0 (CR0n0) used as a compare register, when changing CR0n0 around the timing of a match between 16-bit timer counter 00 (TM00) and 16-bit timer capture/compare register 0n0 (CR0n0) during timer counting, the change timing may conflict with the timing of the match, so the operation is not guaranteed in such cases. To change CR0n0 during timer counting, INTTM000 interrupt servicing performs the following operation.

<Changing cycle (CR000)>

1. Disable the timer output inversion operation at the match between TM00 and CR000 (TOC001 = 0).
2. Disable the INTTM000 interrupt (TMMK000 = 1).
3. Rewrite CR000.
4. Wait for 1 cycle of the TM00 count clock.
5. Enable the timer output inversion operation at the match between TM00 and CR000 (TOC001 = 1).
6. Clear the interrupt request flag of INTTM000 (TMIF000 = 0).
7. Enable the INTTM000 interrupt (TMMK000 = 0).

<Changing duty (CR010)>

1. Disable the timer output inversion operation at the match between TM00 and CR010 (TOC004 = 0).
2. Disable the INTTM000 interrupt (TMMK000 = 1).
3. Rewrite CR010.
4. Wait for 1 cycle of the TM00 count clock.
5. Enable the timer output inversion operation at the match between TM00 and CR010 (TOC004 = 1).
6. Clear the interrupt request flag of INTTM000 (TMIF000 = 0).
7. Enable the INTTM000 interrupt (TMMK000 = 0).

While interrupts and timer output inversion are disabled (1 to 4 above), timer counting is continued. If the value to be set in CR0n0 is small, the value of TM00 may exceed CR0n0. Therefore, set the value, considering the time lapse of the timer clock and CPU after an INTTM000 interrupt has been generated.

Remark n = 0 or 1

<2> If CR010 is changed during timer counting without performing processing <1> above, the value in CR010 may be rewritten twice or more, causing an inversion of the output level of the TO00 pin at each rewrite.

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(18) Edge detection

<1> In the following cases, note with caution that the valid edge of the TI0n0 pin is detected.

(a) Immediately after a system reset, if a high level is input to the TI0n0 pin, the operation of 16-bit timer counter 00 (TM00) is enabled

→ If the rising edge or both rising and falling edges are specified as the valid edge of the TI0n0 pin, a rising edge is detected immediately after the TM00 operation is enabled.

(b) If the TM00 operation is stopped while the TI0n0 pin is at high level, TM00 operation is then enabled after a low level is input to the TI0n0 pin

→ If the falling edge or both rising and falling edges are specified as the valid edge of the TI0n0 pin, a falling edge is detected immediately after the TM00 operation is enabled.

(c) When the TM00 operation is stopped while the TI0n0 pin is at low level, TM00 operation is then enabled after a high level is input to the TI0n0 pin

→ If the rising edge or both rising and falling edges are specified as the valid edge, of the TI0n0 pin, a rising edge is detected immediately after the TM00 operation is enabled.

Remark n = 0, 1

<2> The sampling clock used to remove noise differs when the valid edge of TI000 is used as the count clock and when it is used as a capture trigger. In the former case, the count clock is f_{XP}, and in the latter case the count clock is selected by prescaler mode register 00 (PRM00). The capture operation is not performed until the valid edge is sampled and the valid level is detected twice, thus eliminating, noise with a short pulse width.

(19) External event counter

<1> The timing of the count start is after two valid edge detections.

<2> When reading the external event counter count value, TM00 should be read.

(20) PPG output

<1> Values in the following range should be set to CR000 and CR010:
0000H < CR010 < CR000 ≤ FFFFH

<2> The cycle of the pulse generated through PPG output (CR000 setting value + 1) has a duty of (CR010 setting value + 1)/(CR000 setting value + 1).

(21) STOP mode or system clock stop mode setting

Except when the valid edge of the TI000 pin is selected as the count clock, stop the timer operation before setting STOP mode or system clock stop mode; otherwise the timer may malfunction when the system clock starts.

(22) P21/TI010/TO00 pin

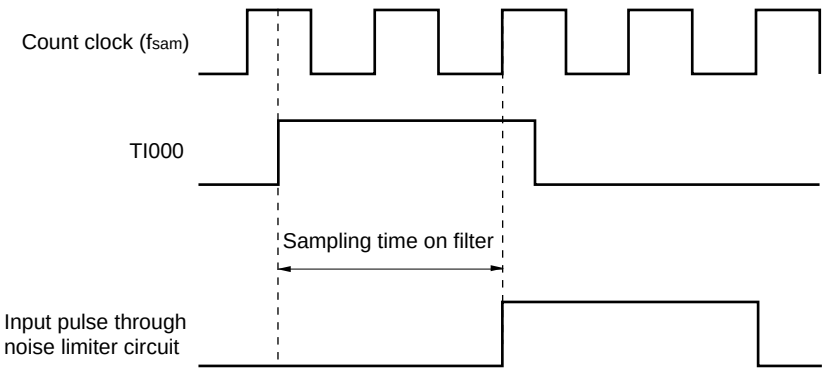
When using P21 as the input pin (TI010) of the valid edge, it cannot be used as a timer output pin (TO00). When using P21 as the timer output pin (TO00), it cannot be used as the input pin (TI010) of the valid edge.

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(23) External clock limitation

<1> When using an input pulse of the TI000 pin as a count clock (external trigger), be sure to input the pulse width which satisfies the AC characteristics. For the AC characteristics, refer to **CHAPTER 19** and **CHAPTER 20 ELECTRICAL SPECIFICATIONS**.

<2> When an external waveform is input to 16-bit timer/event counter 00, it is sampled by the noise limiter circuit and thus an error occurs on the timing to become valid inside the device.



Remark The count clock (f_{sam}) can be selected using bits 0 and 1 (PRM000, PRM001) of prescaler mode register 00 (PRM00).

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CHAPTER 7 8-BIT TIMER H1

7.1 Functions of 8-bit Timer H1

8-bit timer H1 has the following functions.

- Interval timer
- PWM output mode
- Square-wave output

7.2 Configuration of 8-bit Timer H1

8-bit timer H1 consists of the following hardware.

Table 7-1. Configuration of 8-bit Timer H1

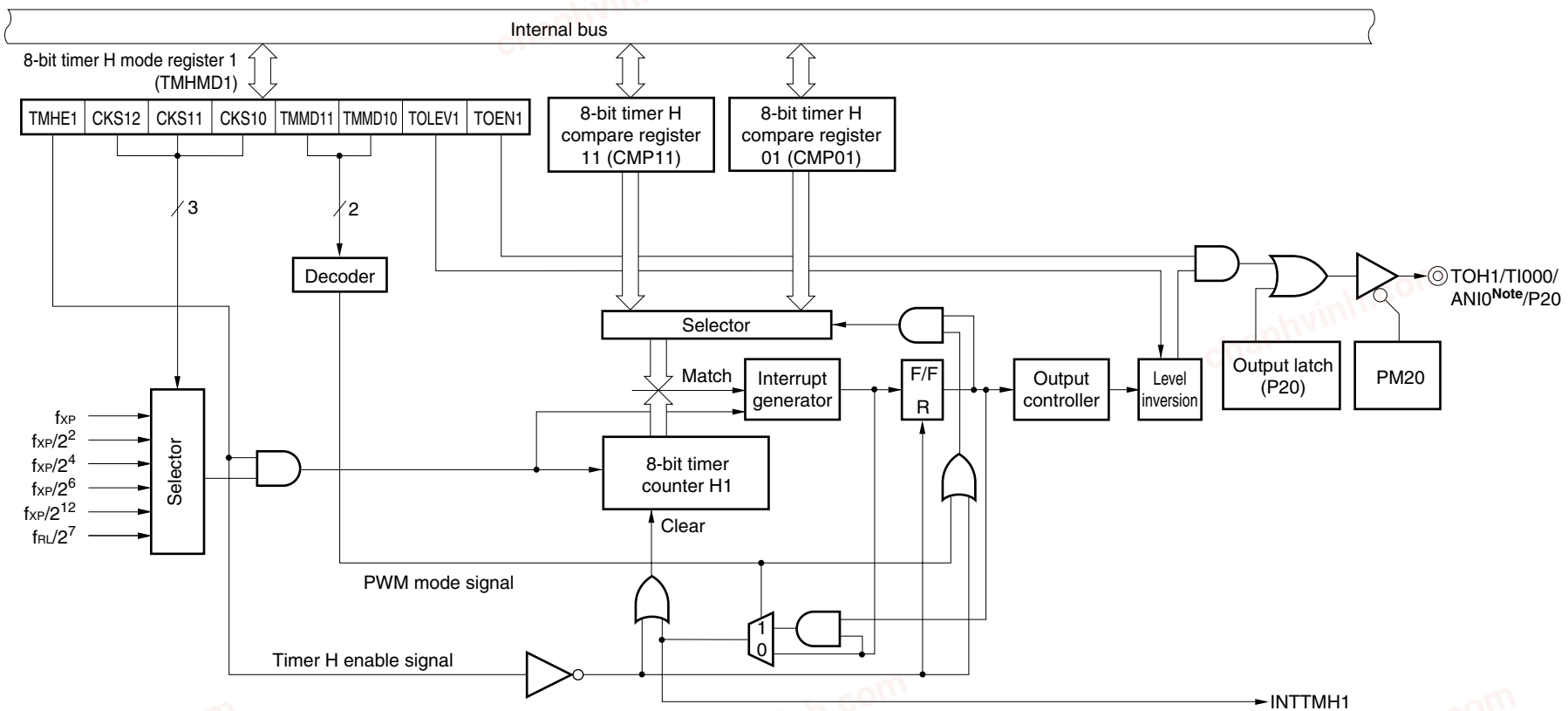
Item	Configuration
Timer register	8-bit timer counter H1
Registers	8-bit timer H compare register 01 (CMP01) 8-bit timer H compare register 11 (CMP11)
Timer output	TOH1
Control registers	8-bit timer H mode register 1 (TMHMD1) Port mode register 2 (PM2) Port register 2 (P2) Port mode control register 2 (PMC2) (μPD78F921x only)

<R>

Figure 7-1 shows a block diagram.

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Figure 7-1. Block Diagram of 8-bit Timer H1



<R> **Note** μPD78F921x only

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(1) 8-bit timer H compare register 01 (CMP01)

This register can be read or written by an 8-bit memory manipulation instruction.

Reset signal generation clears this register to 00H.

Figure 7-2. Format of 8-bit Timer H Compare Register 01 (CMP01)

Address: FF0EH After reset: 00H R/W

Symbol	7	6	5	4	3	2	1	0
CMP01								

Caution CMP01 cannot be rewritten during timer count operation.

(2) 8-bit timer H compare register 11 (CMP11)

This register can be read or written by an 8-bit memory manipulation instruction.

Reset signal generation clears this register to 00H.

Figure 7-3. Format of 8-bit Timer H Compare Register 11 (CMP11)

Address: FF0FH After reset: 00H R/W

Symbol	7	6	5	4	3	2	1	0
CMP11								

CMP11 can be rewritten during timer count operation.

If the CMP11 value is rewritten during timer operation, the compare value after the rewrite takes effect at the timing at which the count value and the compare value before the rewrite match. If the timing at which the count value and compare value match conflicts with the timing of the writing from the CPU to CMP11, the compare value after the rewrite takes effect at the timing at which the next count value and the compare value before the rewrite match.

Caution In the PWM output mode, be sure to set CMP11 when starting the timer count operation (TMHE1 = 1) after the timer count operation was stopped (TMHE1 = 0) (be sure to set again even if setting the same value to CMP11).

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7.3 Registers Controlling 8-bit Timer H1

The following four registers are used to control 8-bit timer H1.

- 8-bit timer H mode register 1 (TMHMD1)
- Port mode register 2 (PM2)
- Port register 2 (P2)
- <R> Port mode control register 2 (PMC2) (μPD78F921x only)

(1) 8-bit timer H mode register 1 (TMHMD1)

This register controls the mode of timer H.

This register can be set by a 1-bit or 8-bit memory manipulation instruction.

Reset signal generation clears this register to 00H.

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Figure 7-4. Format of 8-bit Timer H Mode Register 1 (TMHMD1)

Address: FF70H After reset: 00H R/W

Symbol	<7>	6	5	4	3	2	<1>	<0>
TMHMD1	TMHE1	CKS12	CKS11	CKS10	TMMD11	TMMD10	TOLEV1	TOEN1

TMHE1	Timer operation enable
0	Stop timer count operation (counter is cleared to 0)
1	Enable timer count operation (count operation started by inputting clock)

CKS12	CKS11	CKS10	Count clock (f_{CNT}) selection
0	0	0	f_{XP} (10 MHz)
0	0	1	$f_{XP}/2^2$ (2.5 MHz)
0	1	0	$f_{XP}/2^4$ (625 kHz)
0	1	1	$f_{XP}/2^6$ (156.25 kHz)
1	0	0	$f_{XP}/2^{12}$ (2.44 kHz)
1	0	1	$f_{RL}/2^7$ (1.88 kHz (TYP.))
Other than above			Setting prohibited

TMMD11	TMMD10	Timer operation mode
0	0	Interval timer mode
1	0	PWM output mode
Other than above		Setting prohibited

TOLEV1	Timer output level control (in default mode)
0	Low level
1	High level

TOEN1	Timer output control
0	Disable output
1	Enable output

Cautions 1. When TMHE1 = 1, setting the other bits of the TMHMD1 register is prohibited.

2. In the PWM output mode, be sure to set 8-bit timer H compare register 11 (CMP11) when starting the timer count operation (TMHE1 = 1) after the timer count operation was stopped (TMHE1 = 0) (be sure to set again even if setting the same value to the CMP11 register).

Remarks 1. f_{XP}: Oscillation frequency of clock to peripheral hardware

2. f_{RL}: Low-speed internal oscillation clock oscillation frequency

3. Figures in parentheses apply to operation at f_{XP} = 10 MHz, f_{RL} = 240 kHz (TYP.).

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(2) Port mode register 2 (PM2) and port mode control register 2 (PMC2)[Note]

When using the P20/TOH1/TI000/ANI0 pin for timer output, clear PM20, the output latch of P20, and PMC20 to 0.

PM2 and PMC2 can be set by a 1-bit or 8-bit memory manipulation instruction.

Reset signal generation sets PM2 to FFH, and clears PMC2 to 00H.

<R> **Note** μPD78F921x only

Figure 7-5. Format of Port Mode Register 2 (PM2)

Address: FF22H After reset: FFH R/W

Symbol	7	6	5	4	3	2	1	0
PM2	1	1	1	1	PM23	PM22	PM21	PM20

PM2n	P2n pin I/O mode selection (n = 0 to 3)
0	Output mode (output buffer on)
1	Input mode (output buffer off)

Figure 7-6. Format of Port Mode Control Register 2 (PMC2) (μPD78F921x only)

Address: FF84H After reset: 00H R/W

Symbol	7	6	5	4	3	2	1	0
PMC2	0	0	0	0	PMC23	PMC22	PMC21	PMC20

PMC2n	Specification of operation mode (n = 0 to 3)
0	Port/Alternate-function (except A/D converter) mode
1	A/D converter mode

7.4 Operation of 8-bit Timer H1

7.4.1 Operation as interval timer/square-wave output

When 8-bit timer counter H1 and compare register 01 (CMP01) match, an interrupt request signal (INTTMH1) is generated and 8-bit timer counter H1 is cleared to 00H.

Compare register 11 (CMP11) is not used in interval timer mode. Since a match of 8-bit timer counter H1 and the CMP11 register is not detected even if the CMP11 register is set, timer output is not affected.

By setting bit 0 (TOEN1) of timer H mode register 1 (TMHMD1) to 1, a square wave of any frequency (duty = 50%) is output from TOH1.

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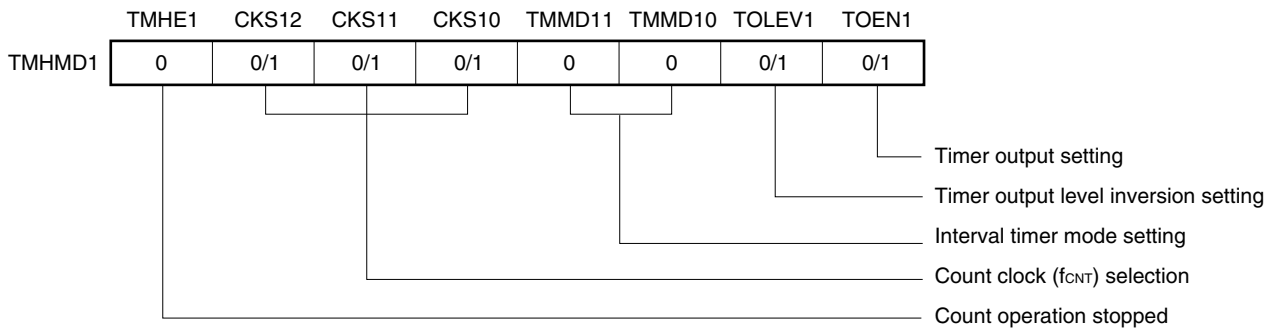
(1) Usage

Generates the INTTMH1 signal repeatedly at the same interval.

<1> Set each register.

Figure 7-7. Register Setting During Interval Timer/Square-Wave Output Operation

(i) Setting timer H mode register 1 (TMHMD1)



(ii) CMP01 register setting

- Compare value (N)

<2> Count operation starts when TMHE1 = 1.

<3> When the values of 8-bit timer counter H1 and the CMP01 register match, the INTTMH1 signal is generated and 8-bit timer counter H1 is cleared to 00H.

Interval time = (N +1)/f_{CNT}

<4> Subsequently, the INTTMH1 signal is generated at the same interval. To stop the count operation, clear TMHE1 to 0.

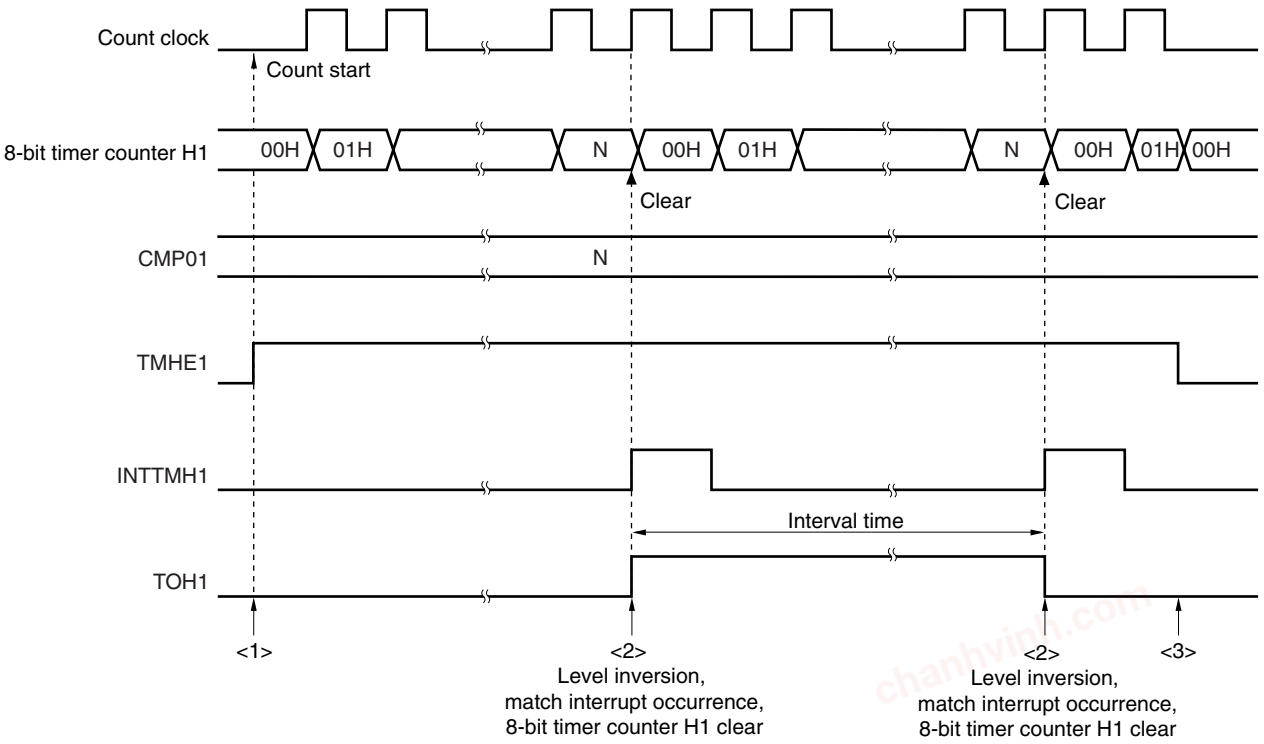
(2) Timing chart

The timing of the interval timer/square-wave output operation is shown below.

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Figure 7-8. Timing of Interval Timer/Square-Wave Output Operation (1/2)

(a) Basic operation (01H ≤ CMP01 ≤ FEH)



<1> The count operation is enabled by setting the TMHE1 bit to 1. The count clock starts counting no more than 1 clock after the operation is enabled.

<2> When the values of 8-bit timer counter H1 and the CMP01 register match, the value of 8-bit timer counter H1 is cleared, the TOH1 output level is inverted, and the INTTMH1 signal is output.

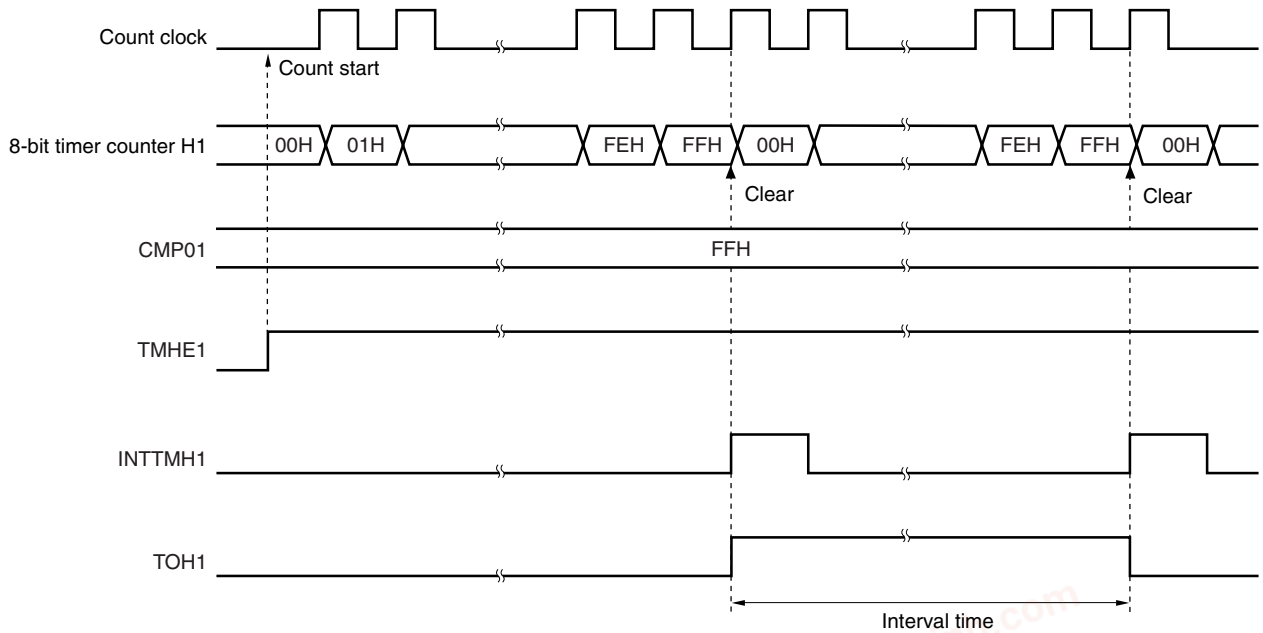
<3> The INTTMH1 signal and TOH1 output become inactive by clearing the TMHE1 bit to 0 during timer H1 operation. If these are inactive from the first, the level is retained.

Remark 01H ≤ N ≤ FEH

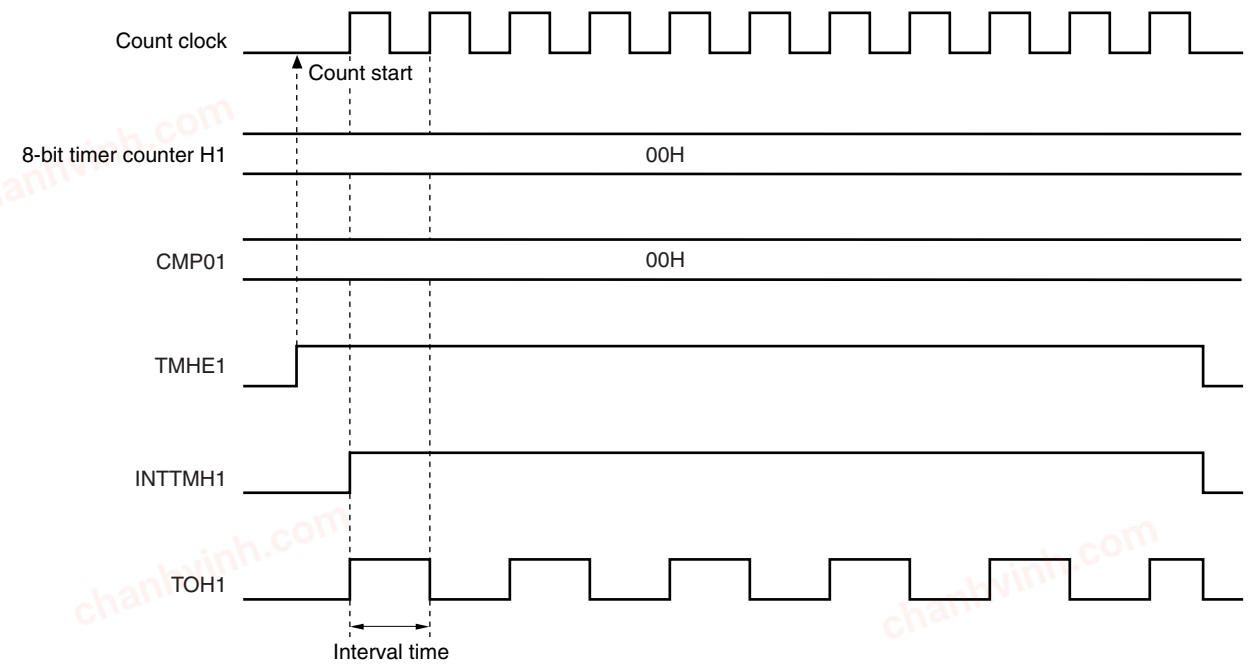
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Figure 7-8. Timing of Interval Timer/Square-Wave Output Operation (2/2)

(b) Operation when CMP01 = FFH



(c) Operation when CMP01 = 00H



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7.4.2 Operation as PWM output mode

In PWM output mode, a pulse with an arbitrary duty and arbitrary cycle can be output.

8-bit timer compare register 01 (CMP01) controls the cycle of timer output (TOH1). Rewriting the CMP01 register during timer operation is prohibited.

8-bit timer compare register 11 (CMP11) controls the duty of timer output (TOH1). Rewriting the CMP11 register during timer operation is possible.

The operation in PWM output mode is as follows.

TOH1 output becomes active and 8-bit timer counter H1 is cleared to 0 when 8-bit timer counter H1 and the CMP01 register match after the timer count is started. TOH1 output becomes inactive when 8-bit timer counter H1 and the CMP11 register match.

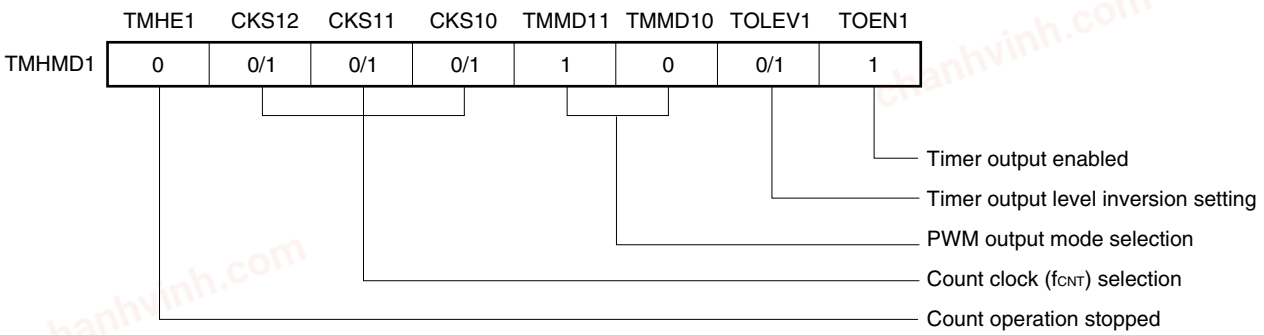
(1) Usage

In PWM output mode, a pulse for which an arbitrary duty and arbitrary cycle can be set is output.

<1> Set each register.

Figure 7-9. Register Setting in PWM Output Mode

(i) Setting timer H mode register 1 (TMHMD1)



(ii) Setting CMP01 register

- Compare value (N): Cycle setting

(iii) Setting CMP11 register

- Compare value (M): Duty setting

Remark 00H ≤ CMP11 (M) < CMP01 (N) ≤ FFH

<2> The count operation starts when TMHE1 = 1.

<3> The CMP01 register is the compare register that is to be compared first after count operation is enabled. When the values of 8-bit timer counter H1 and the CMP01 register match, 8-bit timer counter H1 is cleared, an interrupt request signal (INTTMH1) is generated, and TOH1 output becomes active. At the same time, the compare register to be compared with 8-bit timer counter H1 is changed from the CMP01 register to the CMP11 register.

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<4> When 8-bit timer counter H1 and the CMP11 register match, TOH1 output becomes inactive and the compare register to be compared with 8-bit timer counter H1 is changed from the CMP11 register to the CMP01 register. At this time, 8-bit timer counter H1 is not cleared and the INTTMH1 signal is not generated.

<5> By performing procedures <3> and <4> repeatedly, a pulse with an arbitrary duty can be obtained.

<6> To stop the count operation, set TMHE1 = 0.

If the setting value of the CMP01 register is N, the setting value of the CMP11 register is M, and the count clock frequency is f_{CNT}, the PWM pulse output cycle and duty are as follows.

PWM pulse output cycle = $(N+1)/f_{CNT}$
Duty = Active width : Total width of PWM = (M + 1) : (N + 1)

Cautions 1. In PWM output mode, the setting value for the CMP11 register can be changed during timer count operation. However, three operation clocks (signal selected using the CKS12 to CKS10 bits of the TMHMD1 register) or more are required to transfer the register value after rewriting the CMP11 register value.

2. Be sure to set the CMP11 register when starting the timer count operation (TMHE1 = 1) after the timer count operation was stopped (TMHE1 = 0) (be sure to set again even if setting the same value to the CMP11 register).

(2) Timing chart

The operation timing in PWM output mode is shown below.

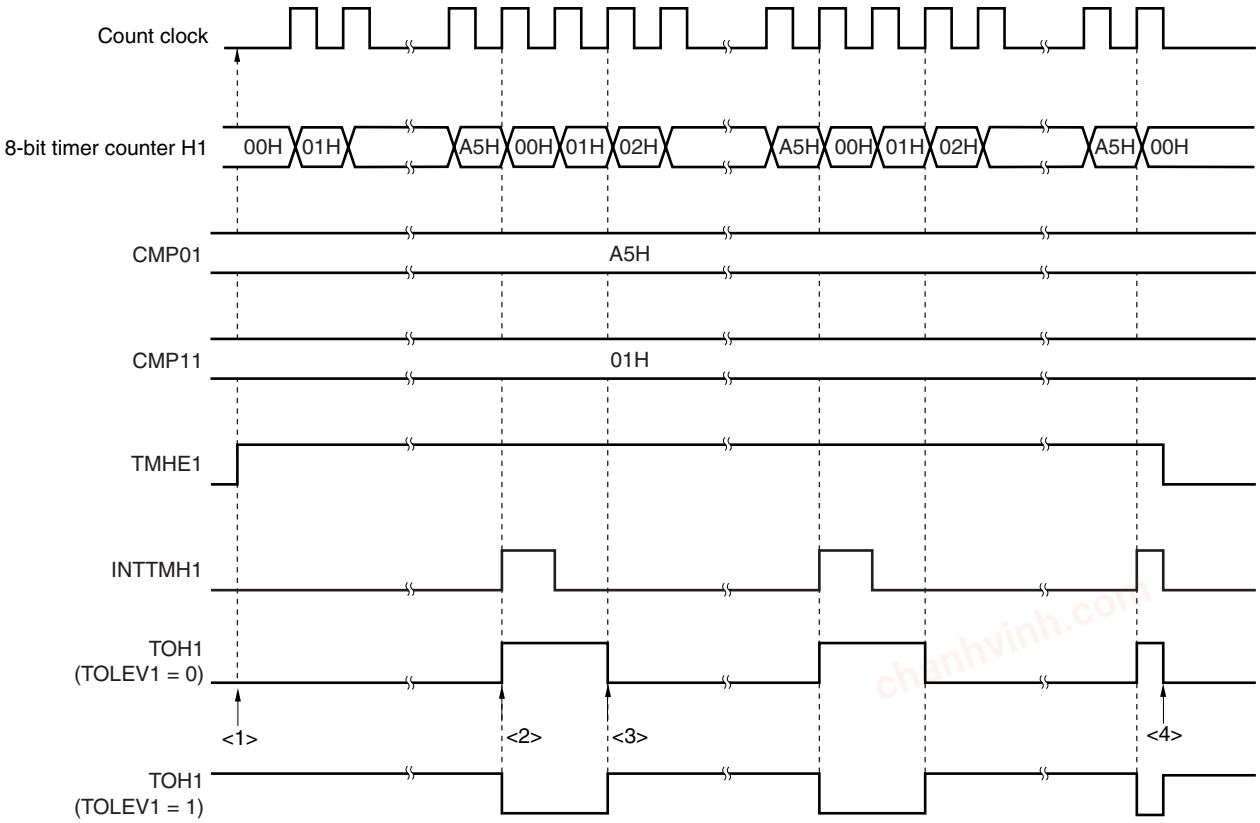
Caution Make sure that the CMP11 register setting value (M) and CMP01 register setting value (N) are within the following range.

00H ≤ CMP11 (M) < CMP01 (N) ≤ FFH

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Figure 7-10. Operation Timing in PWM Output Mode (1/4)

(a) Basic operation (00H < CMP11 < CMP01 < FFH)



<1> The count operation is enabled by setting the TMHE1 bit to 1. Start 8-bit timer counter H1 by masking one count clock to count up. At this time, TOH1 output remains inactive (when TOLEV1 = 0).

<2> When the values of 8-bit timer counter H1 and the CMP01 register match, the TOH1 output level is inverted, the value of 8-bit timer counter H1 is cleared, and the INTTMH1 signal is output.

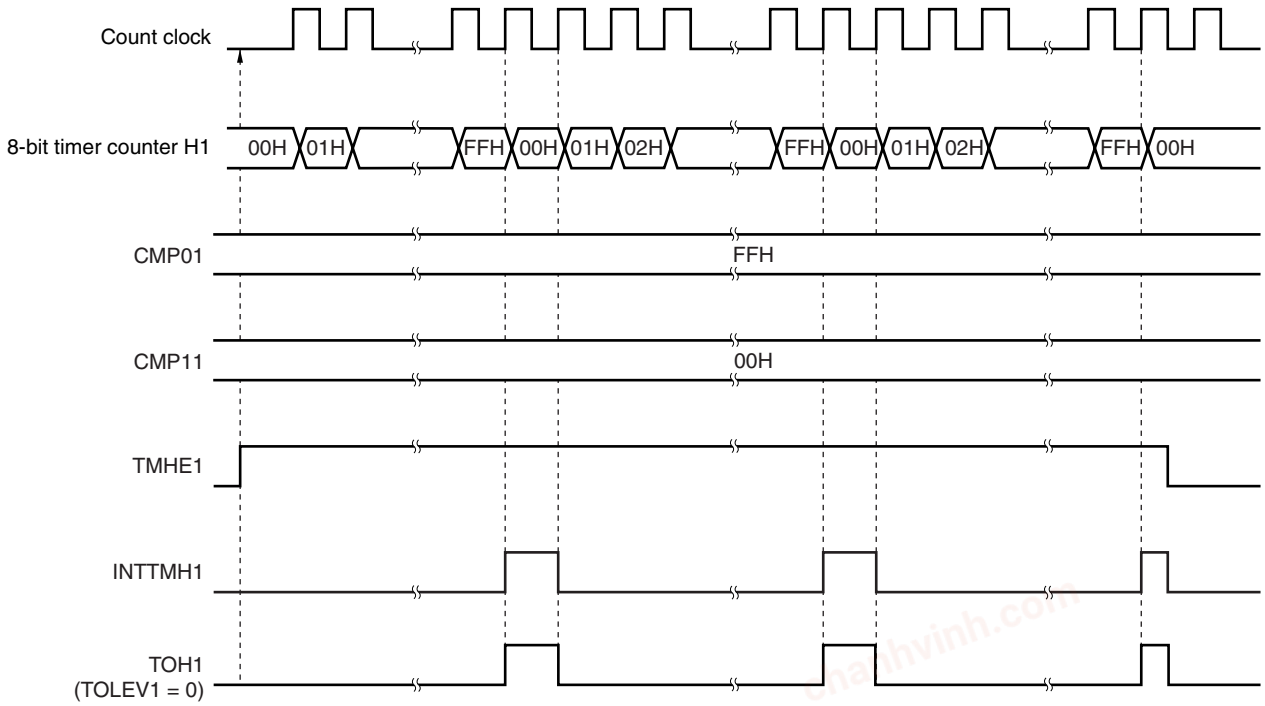
<3> When the values of 8-bit timer counter H1 and the CMP11 register match, the level of the TOH1 output is returned. At this time, the 8-bit timer counter value is not cleared and the INTTMH1 signal is not output.

<4> Clearing the TMHE1 bit to 0 during timer H1 operation makes the INTTMH1 signal and TOH1 output inactive.

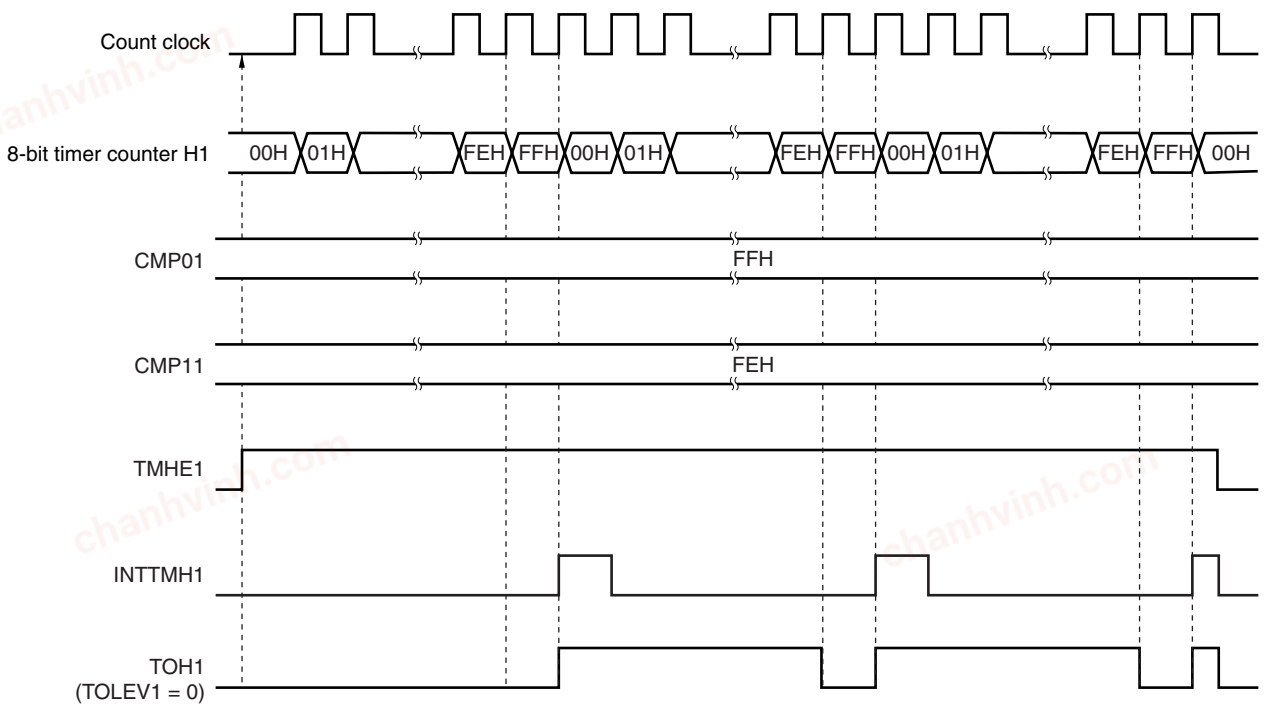
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Figure 7-10. Operation Timing in PWM Output Mode (2/4)

(b) Operation when CMP01 = FFH, CMP11 = 00H



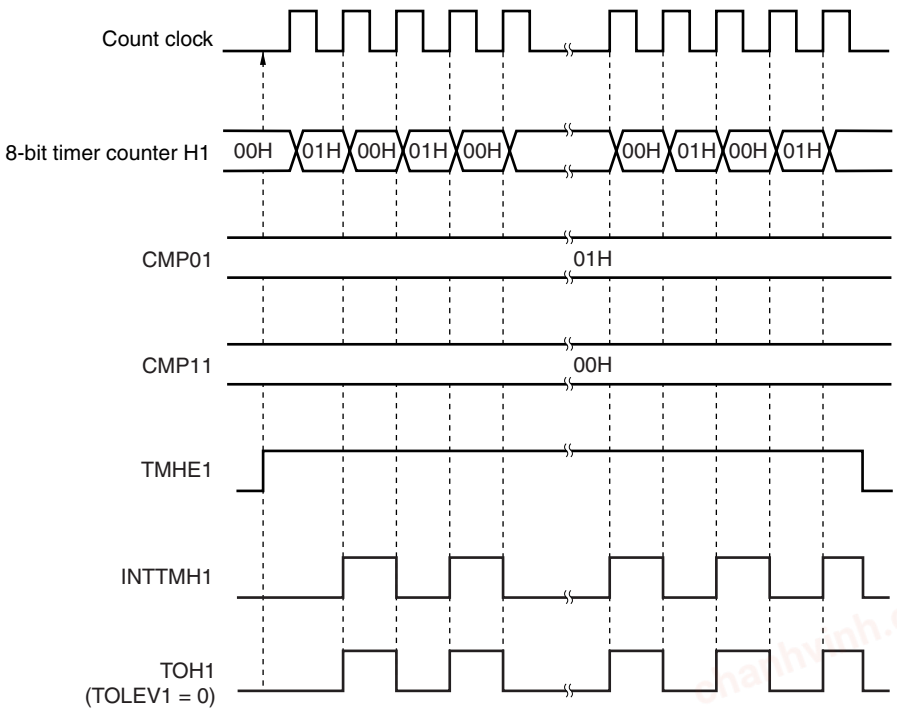
(c) Operation when CMP01 = FFH, CMP11 = FEH



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Figure 7-10. Operation Timing in PWM Output Mode (3/4)

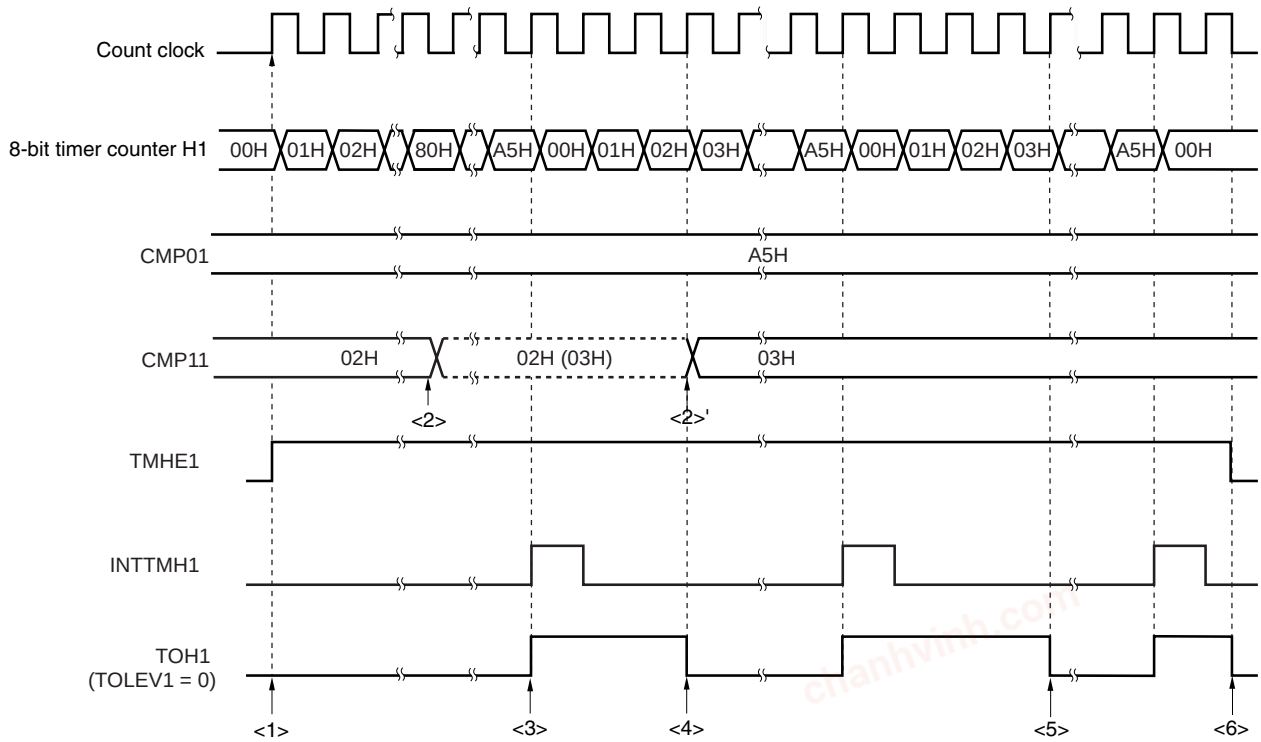
(d) Operation when CMP01 = 01H, CMP11 = 00H



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Figure 7-10. Operation Timing in PWM Output Mode (4/4)

(e) Operation by changing CMP11 (CMP11 = 02H → 03H, CMP01 = A5H)



<1> The count operation is enabled by setting TMHE1 = 1. Start 8-bit timer counter H1 by masking one count clock to count up. At this time, the TOH1 output remains inactive (when TOLEV1 = 0).

<2> The CMP11 register value can be changed during timer counter operation. This operation is asynchronous to the count clock.

<3> When the values of 8-bit timer counter H1 and the CMP01 register match, the value of 8-bit timer counter H1 is cleared, the TOH1 output becomes active, and the INTTMH1 signal is output.

<4> If the CMP11 register value is changed, the value is latched and not transferred to the register. When the values of 8-bit timer counter H1 and the CMP11 register before the change match, the value is transferred to the CMP11 register and the CMP11 register value is changed (<2>').

However, three count clocks or more are required from when the CMP11 register value is changed to when the value is transferred to the register. If a match signal is generated within three count clocks, the changed value cannot be transferred to the register.

<5> When the values of 8-bit timer counter H1 and the CMP11 register after the change match, the TOH1 output becomes inactive. 8-bit timer counter H1 is not cleared and the INTTMH1 signal is not generated.

<6> Clearing the TMHE1 bit to 0 during timer H1 operation makes the INTTMH1 signal and TOH1 output inactive.

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CHAPTER 8 WATCHDOG TIMER

8.1 Functions of Watchdog Timer

The watchdog timer is used to detect an inadvertent program loop. If a program loop is detected, an internal reset signal is generated.

When a reset occurs due to the watchdog timer, bit 4 (WDTRF) of the reset control flag register (RESF) is set to 1. For details of RESF, see **CHAPTER 12 RESET FUNCTION**.

Table 8-1. Loop Detection Time of Watchdog Timer

Loop Detection Time	
During Low-Speed Internal oscillation Clock Operation	During System Clock Operation
$2^{11}/f_{RL}$ (4.27 ms)	$2^{13}/f_X$ (819.2 μs)
$2^{12}/f_{RL}$ (8.53 ms)	$2^{14}/f_X$ (1.64 ms)
$2^{13}/f_{RL}$ (17.07 ms)	$2^{15}/f_X$ (3.28 ms)
$2^{14}/f_{RL}$ (34.13 ms)	$2^{16}/f_X$ (6.55 ms)
$2^{15}/f_{RL}$ (68.27 ms)	$2^{17}/f_X$ (13.11 ms)
$2^{16}/f_{RL}$ (136.53 ms)	$2^{18}/f_X$ (26.21 ms)
$2^{17}/f_{RL}$ (273.07 ms)	$2^{19}/f_X$ (52.43 ms)
$2^{18}/f_{RL}$ (546.13 ms)	$2^{20}/f_X$ (104.86 ms)

Remarks 1. f_{RL}: Low-speed internal oscillation clock oscillation frequency

2. f_X: System clock oscillation frequency

3. Figures in parentheses apply to operation at f_{RL} = 480 kHz (MAX.), f_X = 10 MHz.

The operation mode of the watchdog timer (WDT) is switched according to the option byte setting of the on-chip low-speed internal oscillator as shown in Table 8-2.

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Table 8-2. Option Byte Setting and Watchdog Timer Operation Mode

	Option Byte Setting	
	Low-Speed Internal Oscillator Cannot Be Stopped	Low-Speed Internal Oscillator Can Be Stopped by Software
Watchdog timer clock source	Fixed to f_{RL} Note 1.	• Selectable by software (f_X, f_{RL} or stopped) • When reset is released: f_{RL}
Operation after reset	Operation starts with the maximum interval ($2^{18}/f_{RL}$).	Operation starts with the maximum interval ($2^{18}/f_{RL}$).
Operation mode selection	The interval can be changed only once.	The clock selection/interval can be changed only once.
Features	The watchdog timer cannot be stopped.	The watchdog timer can be stopped Note 2.

Notes 1. As long as power is being supplied, low-speed internal oscillator cannot be stopped (except in the reset period).

2. The conditions under which clock supply to the watchdog timer is stopped differ depending on the clock source of the watchdog timer.

<1> If the clock source is f_X, clock supply to the watchdog timer is stopped under the following conditions.

- When f_X is stopped
- In HALT/STOP mode
- During oscillation stabilization time

<2> If the clock source is f_{RL}, clock supply to the watchdog timer is stopped under the following conditions.

- If the CPU clock is f_X and if f_{RL} is stopped by software before execution of the STOP instruction
- In HALT/STOP mode

Remarks 1. f_{RL}: Low-speed internal oscillation clock oscillation frequency

2. f_X: System clock oscillation frequency

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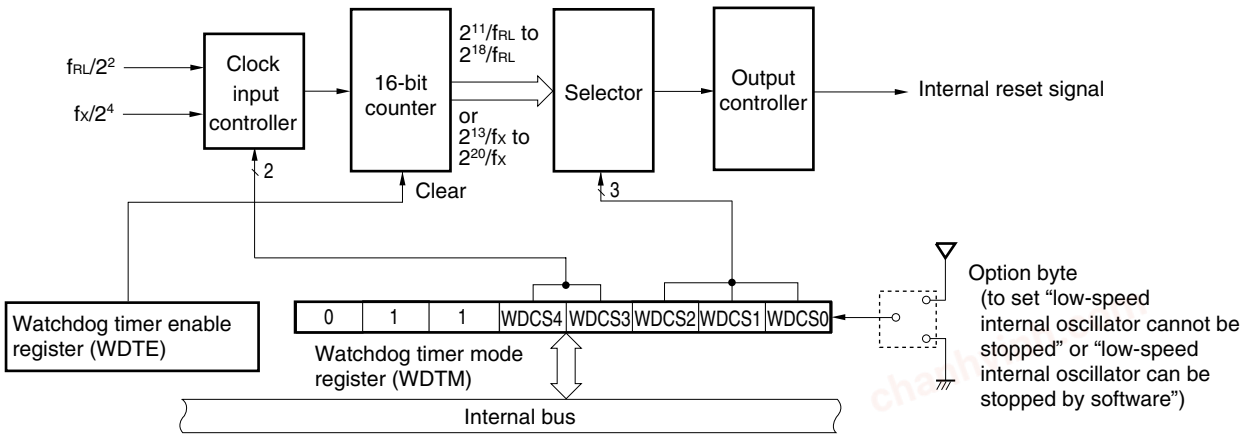
8.2 Configuration of Watchdog Timer

The watchdog timer consists of the following hardware.

Table 8-3. Configuration of Watchdog Timer

Item	Configuration
Control registers	Watchdog timer mode register (WDTM) Watchdog timer enable register (WDTE)

Figure 8-1. Block Diagram of Watchdog Timer



Remarks 1. fRL: Low-speed internal oscillation clock oscillation frequency

2. fx: System clock oscillation frequency

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8.3 Registers Controlling Watchdog Timer

The watchdog timer is controlled by the following two registers.

- Watchdog timer mode register (WDTM)
- Watchdog timer enable register (WDTE)

(1) Watchdog timer mode register (WDTM)

This register sets the overflow time and operation clock of the watchdog timer.

This register can be set by an 8-bit memory manipulation instruction and can be read many times, but can be written only once after reset is released.

Reset signal generation sets this register to 67H.

Figure 8-2. Format of Watchdog Timer Mode Register (WDTM)

Address: FF48H After reset: 67H R/W

Symbol	7	6	5	4	3	2	1	0
WDTM	0	1	1	WDCS4	WDCS3	WDCS2	WDCS1	WDCS0

WDCS4[Note 1]	WDCS3[Note 1]	Operation clock selection
0	0	Low-speed internal oscillation clock (f_{RL})
0	1	System Clock (f_X)
1	×	Watchdog timer operation stopped

WDCS2[Note 2]	WDCS1[Note 2]	WDCS0[Note 2]	Overflow time setting	
			During low-speed internal oscillation clock operation	During system clock operation
0	0	0	$2^{11}/f_{RL}$ (4.27 ms)	$2^{13}/f_X$ (819.2 μs)
0	0	1	$2^{12}/f_{RL}$ (8.53 ms)	$2^{14}/f_X$ (1.64 ms)
0	1	0	$2^{13}/f_{RL}$ (17.07 ms)	$2^{15}/f_X$ (3.28 ms)
0	1	1	$2^{14}/f_{RL}$ (34.13 ms)	$2^{16}/f_X$ (6.55 ms)
1	0	0	$2^{15}/f_{RL}$ (68.27 ms)	$2^{17}/f_X$ (13.11 ms)
1	0	1	$2^{16}/f_{RL}$ (136.53 ms)	$2^{18}/f_X$ (26.21 ms)
1	1	0	$2^{17}/f_{RL}$ (273.07 ms)	$2^{19}/f_X$ (52.43 ms)
1	1	1	$2^{18}/f_{RL}$ (546.13 ms)	$2^{20}/f_X$ (104.86 ms)

Notes 1. If “low-speed internal oscillator cannot be stopped” is specified by the option byte, this cannot be set. The low-speed internal oscillation clock will be selected no matter what value is written.

2. Reset is released at the maximum cycle (WDCS2, 1, 0 = 1, 1, 1).

Caution 1. Set bits 7, 6, and 5 to 0, 1, and 1, respectively. Do not set the other values.

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Cautions 2. After reset is released, WDTM can be written only once by an 8-bit memory manipulation instruction. If writing is attempted a second time, an internal reset signal is generated. However, at the first write, if "1" and "x" are set for WDCS4 and WDCS3 respectively and the watchdog timer is stopped, then the internal reset signal does not occur even if the following are executed.

- **Second write to WDTM**
- **1-bit memory manipulation instruction to WDTE**
- **Writing of a value other than "ACH" to WDTE**

3. WDTM cannot be set by a 1-bit memory manipulation instruction.

4. When using the flash memory programming by self programming, set the overflow time for the watchdog timer so that enough overflow time is secured (Example 1-byte writing: 200 μs MIN., 1-block deletion: 10 ms MIN.).

Remarks 1. f_{RL}: Low-speed internal oscillation clock oscillation frequency

2. f_X: System clock oscillation frequency

3. ×: Don't care

4. Figures in parentheses apply to operation at f_{RL} = 480 kHz (MAX.), f_X = 10 MHz.

(2) Watchdog timer enable register (WDTE)

Writing ACH to WDTE clears the watchdog timer counter and starts counting again.

This register can be set by an 8-bit memory manipulation instruction.

Reset signal generation sets this register to 9AH.

Figure 8-3. Format of Watchdog Timer Enable Register (WDTE)

Address: FF49H After reset: 9AH R/W

Symbol	7	6	5	4	3	2	1	0
WDTE								

Cautions 1. If a value other than ACH is written to WDTE, an internal reset signal is generated.

2. If a 1-bit memory manipulation instruction is executed for WDTE, an internal reset signal is generated.

3. The value read from WDTE is 9AH (this differs from the written value (ACH)).

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8.4 Operation of Watchdog Timer

8.4.1 Watchdog timer operation when "low-speed internal oscillator cannot be stopped" is selected by option byte

The operation clock of watchdog timer is fixed to low-speed internal oscillation clock.

After reset is released, operation is started at the maximum cycle (bits 2, 1, and 0 (WDCS2, WDCS1, WDCS0) of the watchdog timer mode register (WDTM) = 1, 1, 1). The watchdog timer operation cannot be stopped.

The following shows the watchdog timer operation after reset release.

1. The status after reset release is as follows.
   - Operation clock: Low-speed internal oscillation clock
   - Cycle: $2^{18}/f_{RL}$ (546.13 ms: At operation with f_{RL} = 480 kHz (MAX.))
   - Counting starts
2. The following should be set in the watchdog timer mode register (WDTM) by an 8-bit memory manipulation instruction[Notes 1, 2].
   - Cycle: Set using bits 2 to 0 (WDCS2 to WDCS0)
3. After the above procedures are executed, writing ACH to WDTE clears the count to 0, enabling recounting.

Notes 1. The operation clock (low-speed internal oscillation clock) cannot be changed. If any value is written to bits 3 and 4 (WDCS3, WDCS4) of WDTM, it is ignored.

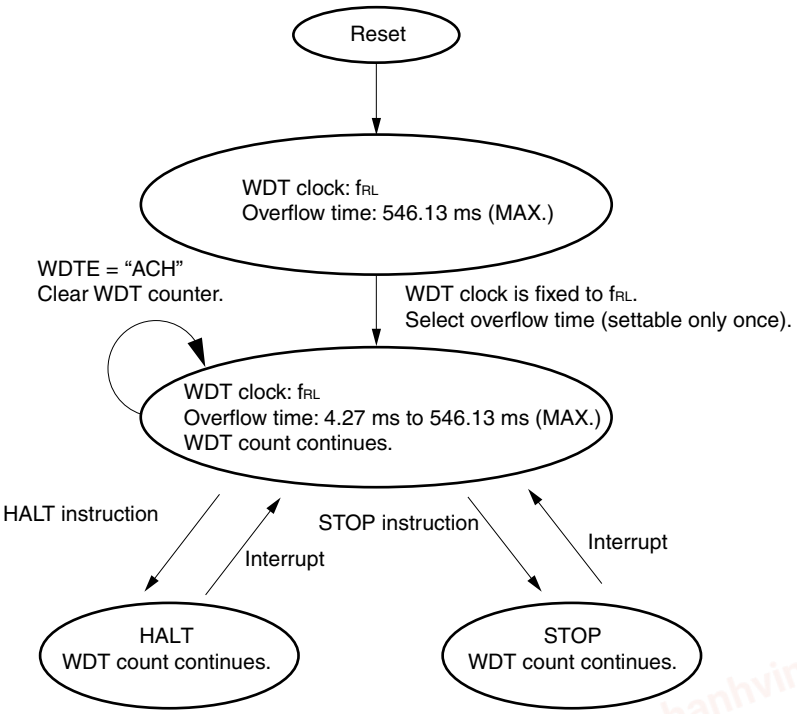
2. As soon as WDTM is written, the counter of the watchdog timer is cleared.

Caution In this mode, operation of the watchdog timer cannot be stopped even during STOP instruction execution. For 8-bit timer H1 (TMH1), a division of the low-speed internal oscillation clock can be selected as the count source, so clear the watchdog timer using the interrupt request of TMH1 before the watchdog timer overflows after STOP instruction execution. If this processing is not performed, an internal reset signal is generated when the watchdog timer overflows after STOP instruction execution.

A status transition diagram is shown below

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Figure 8-4. Status Transition Diagram When "Low-Speed Internal Oscillator Cannot Be Stopped" Is Selected by Option Byte



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8.4.2 Watchdog timer operation when "low-speed internal oscillator can be stopped by software" is selected by option byte

The operation clock of the watchdog timer can be selected as either the low-speed internal oscillation clock or system clock.

After reset is released, operation is started at the maximum cycle of the low-speed internal oscillation clock (bits 2, 1, and 0 (WDCS2, WDCS1, WDCS0) of the watchdog timer mode register (WDTM) = 1, 1, 1).

The following shows the watchdog timer operation after reset release.

1. The status after reset release is as follows.
   - Operation clock: Low-speed internal oscillation clock
   - Cycle: $2^{18}/f_{RL}$ (546.13 ms: At operation with f_{RL} = 480 kHz (MAX.))
   - Counting starts
2. The following should be set in the watchdog timer mode register (WDTM) by an 8-bit memory manipulation instruction[Notes 1, 2, 3].
   - Operation clock: Any of the following can be selected using bits 3 and 4 (WDCS3 and WDCS4).
     Low-speed internal oscillation clock
     Syatem clock (fx)
     Watchdog timer operation stopped
   - Cycle: Set using bits 2 to 0 (WDCS2 to WDCS0)
3. After the above procedures are executed, writing ACH to WDTE clears the count to 0, enabling recounting.

Notes 1. As soon as WDTM is written, the counter of the watchdog timer is cleared.

2. Set bits 7, 6, and 5 to 0, 1, 1, respectively. Do not set the other values.

3. At the first write, If the watchdog timer is stopped by setting WDCS4 and WDCS3 to 1 and ×, respectively, an internal reset signal is not generated even if the following processing is performed.
   - WDTM is written a second time.
   - A 1-bit memory manipulation instruction is executed to WDTE.
   - A value other than ACH is written to WDTE.

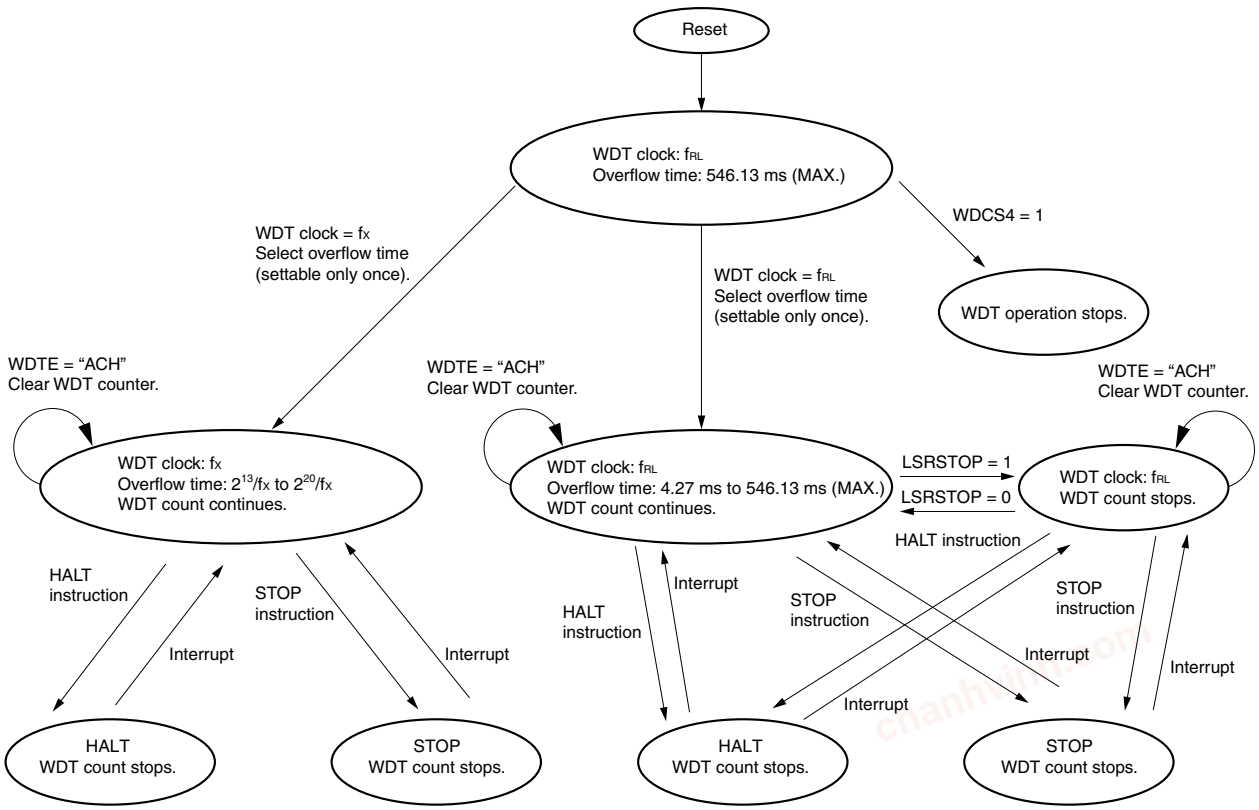
Caution In this mode, watchdog timer operation is stopped during HALT/STOP instruction execution. After HALT/STOP mode is released, counting is started again using the operation clock of the watchdog timer set before HALT/STOP instruction execution by WDTM. At this time, the counter is not cleared to 0 but holds its value.

For the watchdog timer operation during STOP mode and HALT mode in each status, see **8.4.3 Watchdog timer operation in STOP mode** and **8.4.4 Watchdog timer operation in HALT mode**.

A status transition diagram is shown below.

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Figure 8-5. Status Transition Diagram When "Low-Speed Internal Oscillator Can Be Stopped by Software" Is Selected by Option Byte



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8.4.3 Watchdog timer operation in STOP mode (when "low-speed internal oscillator can be stopped by software" is selected by option byte)

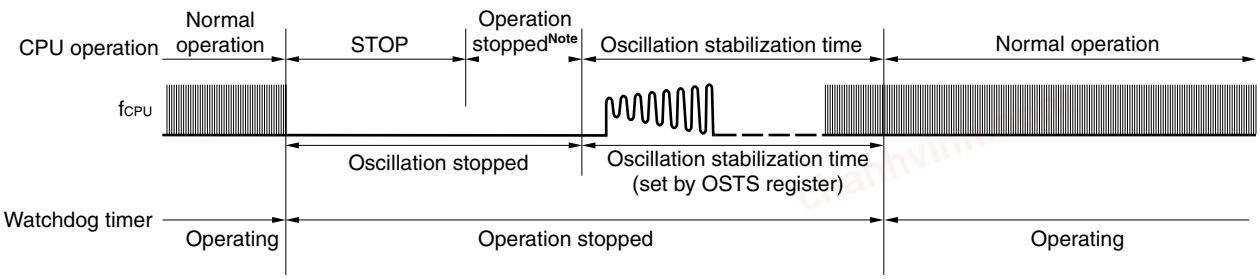
The watchdog timer stops counting during STOP instruction execution regardless of whether the system clock or low-speed internal oscillation clock is being used.

(1) When the watchdog timer operation clock is the system clock (f_X) when the STOP instruction is executed

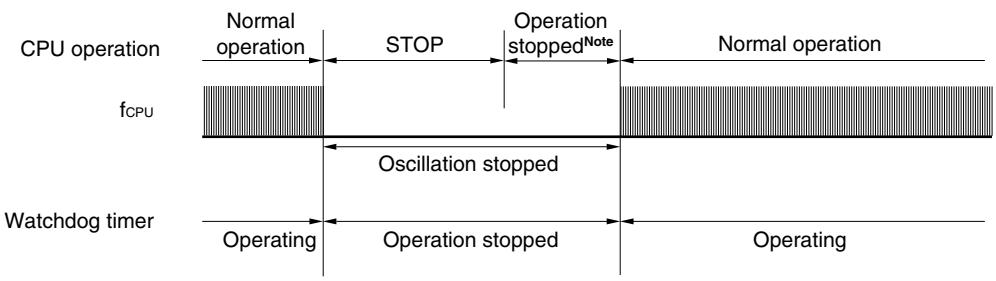
When STOP instruction is executed, operation of the watchdog timer is stopped. After STOP mode is released, operation stops for 34 μs (TYP.) (after waiting for the oscillation stabilization time set by the oscillation stabilization time select register (OSTS) after operation stops in the case of crystal/ceramic oscillation) and then counting is started again using the operation clock before the operation was stopped. At this time, the counter is not cleared to 0 but holds its value.

Figure 8-6. Operation in STOP Mode (WDT Operation Clock: Clock to Peripheral Hardware)

<1> CPU clock: Crystal/ceramic oscillation clock



<2> CPU clock: High-speed internal oscillation clock or external clock input



Note The operation stop time is 17 μs (MIN.), 34 μs (TYP.), and 67 μs (MAX.).

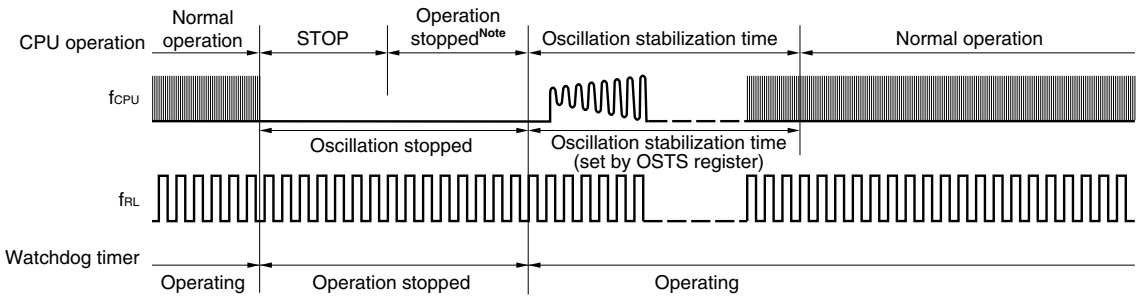
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(2) When the watchdog timer operation clock is the low-speed internal oscillation clock (f_{RL}) when the STOP instruction is executed

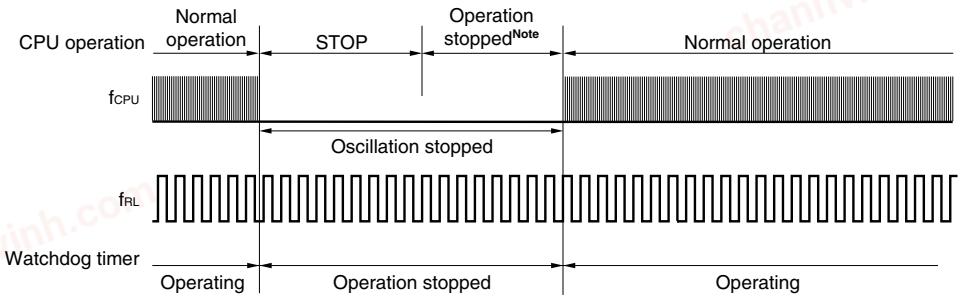
When the STOP instruction is executed, operation of the watchdog timer is stopped. After STOP mode is released, operation stops for 34 μs (TYP.) and then counting is started again using the operation clock before the operation was stopped. At this time, the counter is not cleared to 0 but holds its value.

Figure 8-7. Operation in STOP Mode (WDT Operation Clock: Low-Speed Internal Oscillation Clock)

<1> CPU clock: Crystal/ceramic oscillation clock



<2> CPU clock: High-speed internal oscillation clock or external clock input

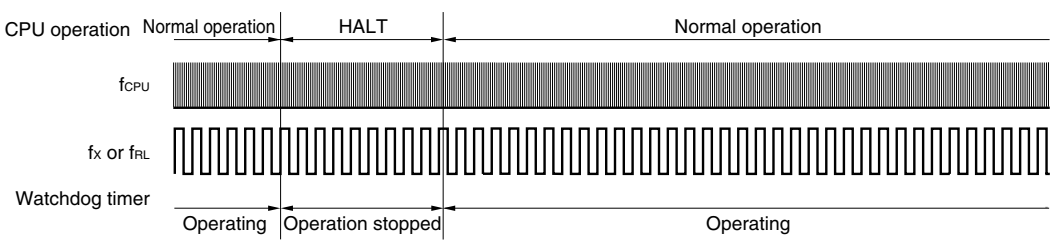


Note The operation stop time is 17 μs (MIN.), 34 μs (TYP.), and 67 μs (MAX.).

8.4.4 Watchdog timer operation in HALT mode (when "low-speed internal oscillator can be stopped by software" is selected by option byte)

The watchdog timer stops counting during HALT instruction execution regardless of whether the operation clock of the watchdog timer is the system clock (f_X) or low-speed internal oscillation clock (f_{RL}). After HALT mode is released, counting is started again using the operation clock before the operation was stopped. At this time, the counter is not cleared to 0 but holds its value.

Figure 8-8. Operation in HALT Mode



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<R>

CHAPTER 9 A/D CONVERTER (μPD78F921x ONLY)

9.1 Functions of A/D Converter

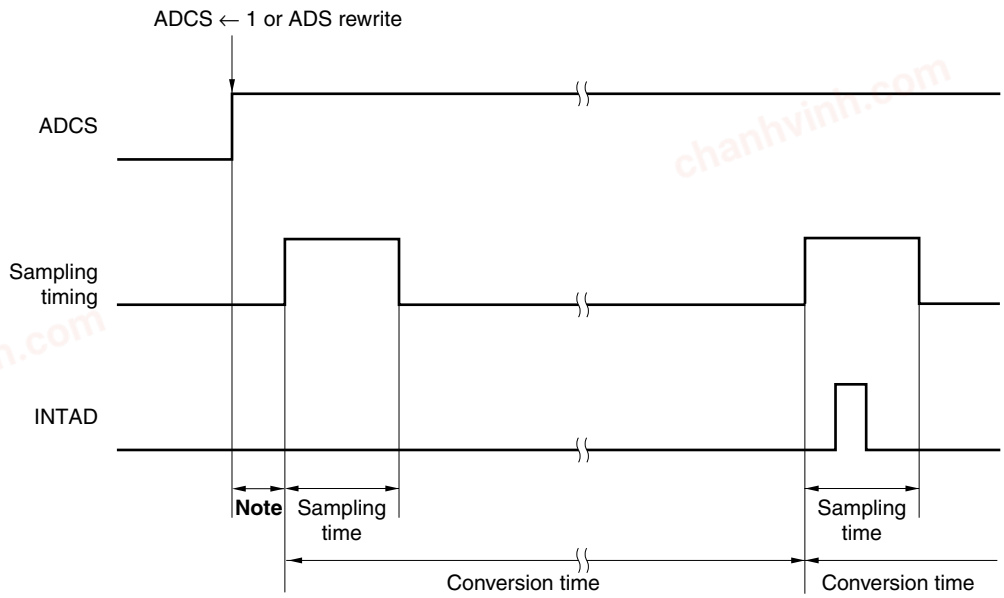
The A/D converter converts an analog input signal into a digital value, and consists of up to four channels (ANI0 to ANI3) with a resolution of 10 bits.

The A/D converter has the following function.

- **10-bit resolution A/D conversion**
  10-bit resolution A/D conversion is carried out repeatedly for one channel selected from analog inputs ANI0 to ANI3. Each time an A/D conversion operation ends, an interrupt request (INTAD) is generated.

Figure 9-1 shows the timing of sampling and A/D conversion, and Table 9-1 shows the sampling time and A/D conversion time.

Figure 9-1. Timing of A/D Converter Sampling and A/D Conversion



Note 2 or 3 clocks are required from the ADCS rising to sampling start.

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Table 9-1. Sampling Time and A/D Conversion Time

Reference Voltage Range[Note 1]	Sampling Time[Note 2]	Conversion Time[Note 3]	f_{XP} = 8 MHz		f_{XP} = 10 MHz		FR2	FR1	FR0
			Sampling Time[Note 2]	Conversion Time[Note 3]	Sampling Time[Note 2]	Conversion Time[Note 3]			
$V_{DD} \geq 4.5$ V	$12/f_{XP}$	$36/f_{XP}$	1.5 μs	4.5 μs	1.2 μs	3.6 μs	0	0	0
$V_{DD} \geq 4.0$ V	$24/f_{XP}$	$72/f_{XP}$	3.0 μs	9.0 μs	2.4 μs	7.2 μs	1	0	0
$V_{DD} \geq 2.85$ V	$96/f_{XP}$	$144/f_{XP}$	12.0 μs	18.0 μs	9.6 μs	14.4 μs	1	1	0
	$48/f_{XP}$	$96/f_{XP}$	6.0 μs	12.0 μs	4.8 μs	9.6 μs	1	0	1
	$48/f_{XP}$	$72/f_{XP}$	6.0 μs	9.0 μs	4.8 μs	7.2 μs	0	1	0
	$24/f_{XP}$	$48/f_{XP}$	3.0 μs	6.0 μs	Setting prohibited Note 4 (2.4 μs)	Setting prohibited Note 4 (4.8 μs)	0	0	1
$V_{DD} \geq 2.7$ V	$176/f_{XP}$	$224/f_{XP}$	22.0 μs	28.0 μs	17.6 μs	22.4 μs	1	1	1
	$88/f_{XP}$	$112/f_{XP}$	11.0 μs	14.0 μs	Setting prohibited Note 4 (8.8 μs)	Setting prohibited Note 4 (11.2 μs)	0	1	1

Notes 1. Be sure to set the FR2, FR1, and FR0, in accordance with the reference voltage so that **Notes 2** and **3** below are satisfied.

Example When $V_{DD} \geq 2.7$ V, f_{XP} = 8 MHz

- The sampling time is 11.0 μs or more and the A/D conversion time is 14.0 μs or more and 100 μs or less.
- Set FR2, FR1, and FR0 = 0, 1, 1 or 1, 1, 1.

2. Set the sampling time as follows.

- $V_{DD} \geq 4.5$ V: 1.0 μs or more
- $V_{DD} \geq 4.0$ V: 2.4 μs or more
- $V_{DD} \geq 2.85$ V: 3.0 μs or more
- $V_{DD} \geq 2.7$ V: 11.0 μs or more

3. Set the A/D conversion time as follows.

- $V_{DD} \geq 4.5$ V: 3.0 μs or more and less than 100 μs
- $V_{DD} \geq 4.0$ V: 4.8 μs or more and less than 100 μs
- $V_{DD} \geq 2.85$ V: 6.0 μs or more and less than 100 μs
- $V_{DD} \geq 2.7$ V: 14.0 μs or more and less than 100 μs

4. Setting is prohibited because the values do not satisfy the condition of **Notes 2** or **3**.

Caution The above sampling time and conversion time do not include the clock frequency error. Select the sampling time and conversion time such that Notes 2 and 3 above are satisfied, while taking the clock frequency error into consideration (an error margin maximum of ±5% when using the high-speed internal oscillator).

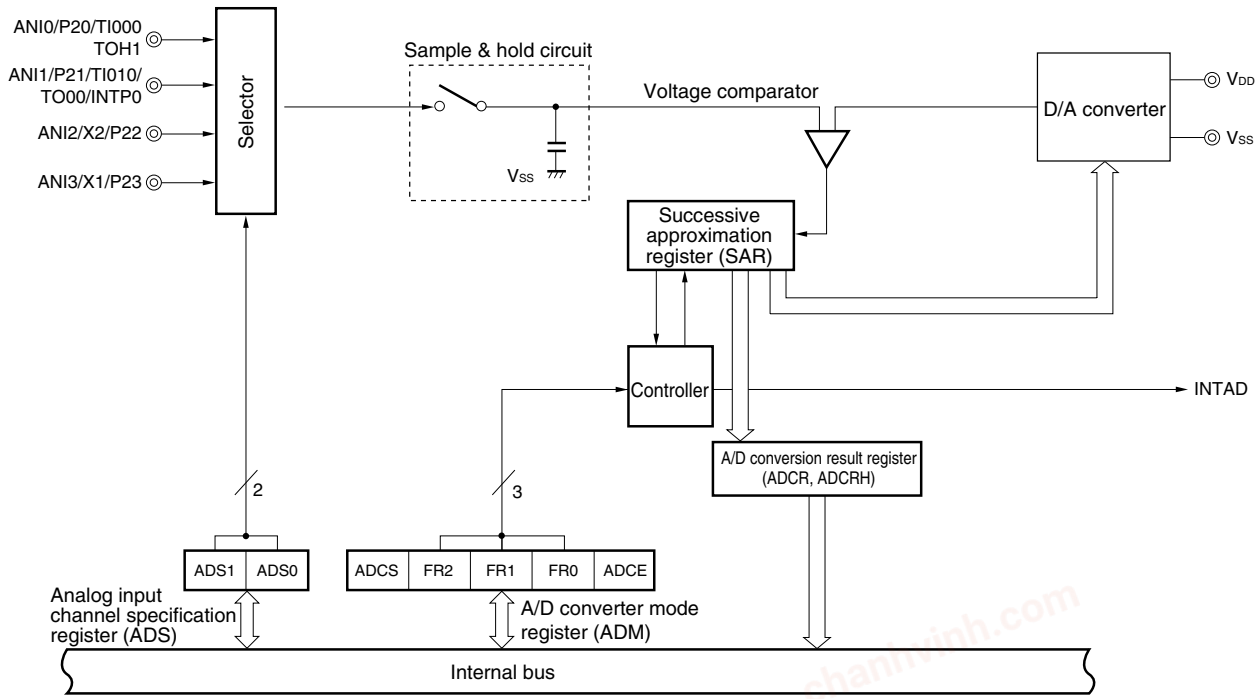
Remarks 1. f_{XP}: Oscillation frequency of clock to peripheral hardware

2. The conversion time refers to the total of the sampling time and the time from successively comparing with the sampling value until the conversion result is output.

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Figure 9-2 shows the block diagram of A/D converter.

Figure 9-2. Block Diagram of A/D Converter



Cautions 1. In μPD78F921x, V_{SS} functions alternately as the ground potential of the A/D converter. Be sure to connect V_{SS} to a stabilized GND (= 0 V).

2. In μPD78F921x, V_{DD} functions alternately as the A/D converter reference voltage input. When using the A/D converter, stabilize V_{DD} at the supply voltage used (2.7 to 5.5 V).

9.2 Configuration of A/D Converter

The A/D converter consists of the following hardware.

(1) ANI0 to ANI3 pins

These are the analog input pins of the 4-channel A/D converter. They input analog signals to be converted into digital signals. Pins other than the one selected as the analog input pin by the analog input channel specification register (ADS) can be used as I/O port pins.

(2) Sample & hold circuit

The sample & hold circuit samples the input signal of the analog input pin selected by the selector when A/D conversion is started, and holds the sampled analog input voltage value during A/D conversion.

(3) D/A converter

The D/A converter is connected between V_{DD} and V_{SS}, and generates a voltage to be compared with the analog input signal.

(4) Voltage comparator

The voltage comparator compares the sampled analog input voltage and the output voltage of the D/A converter.

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(5) Successive approximation register (SAR)

This register compares the sampled analog voltage and the voltage of the D/A converter, and converts the result, starting from the most significant bit (MSB).

When the voltage value is converted into a digital value down to the least significant bit (LSB) (end of A/D conversion), the contents of the SAR register are transferred to the A/D conversion result register (ADCR).

(6) 10-bit A/D conversion result register (ADCR)

The result of A/D conversion is loaded from the successive approximation register to this register each time A/D conversion is completed, and the ADCR register holds the result of A/D conversion in its lower 10 bits (the higher 6 bits are fixed to 0).

(7) 8-bit A/D conversion result register (ADCRH)

The result of A/D conversion is loaded from the successive approximation register to this register each time A/D conversion is completed, and the ADCRH register holds the result of A/D conversion in its higher 8 bits.

(8) Controller

When A/D conversion has been completed, INTAD is generated.

(9) V_{DD} pin

This is the positive power supply pin.

In the 78K0S/KY1+, V_{DD} functions alternately as the A/D converter reference voltage input. When using the A/D converter, stabilize V_{DD} at the supply voltage used (2.7 to 5.5 V).

(10) V_{SS} pin

This is the ground potential pin.

In the 78K0S/KY1+, V_{SS} functions alternately as the ground potential of the A/D converter. Be sure to connect V_{SS} to a stabilized GND (= 0 V).

(11) A/D converter mode register (ADM)

This register is used to set the conversion time of the analog input signal to be converted, and to start or stop the conversion operation.

(12) Analog input channel specification register (ADS)

This register is used to specify the port that inputs the analog voltage to be converted into a digital signal.

(13) Port mode control register 2 (PMC2)

This register is used when the P20/ANI0/TI000/TOH1, P21/ANI1/TI010/TO00/INTP0, P22/ANI2, and P23/ANI3 pins are used as the analog input pins of the A/D converter.

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9.3 Registers Used by A/D Converter

The A/D converter uses the following six registers.

- A/D converter mode register (ADM)
- Analog input channel specification register (ADS)
- 10-bit A/D conversion result register (ADCR)
- 8-bit A/D conversion result register (ADCRH)
- Port mode register 2 (PM2)
- Port mode control register 2 (PMC2)

(1) A/D converter mode register (ADM)

This register sets the conversion time for analog input to be A/D converted, and starts/stops conversion.

ADM can be set by a 1-bit or 8-bit memory manipulation instruction.

Reset signal generation clears this register to 00H.

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Figure 9-3. Format of A/D Converter Mode Register (ADM)

Address: FF80H After reset: 00H R/W

Symbol	<7>	6	5	4	3	2	1	<0>
ADM	ADCS	0	FR2	FR1	FR0	0	0	ADCE

ADCS	A/D conversion operation control
0	Stops conversion operation
1 Note 1	Starts conversion operation

FR2	FR1	FR0	Reference Voltage Range Note 2	Sampling Time Note 3	Conversion Time Note 4	f_{XP} = 8 MHz		f_{XP} = 10 MHz	
						Sampling Time Note 3	Conversion Time Note 4	Sampling Time Note 3	Conversion Time Note 4
0	0	0	$V_{DD} \geq$ 4.5 V	12/f_{XP}	36/f_{XP}	1.5 μs	4.5 μs	1.2 μs	3.6 μs
1	0	0	$V_{DD} \geq$ 4.0 V	24/f_{XP}	72/f_{XP}	3.0 μs	9.0 μs	2.4 μs	7.2 μs
1	1	0	$V_{DD} \geq$ 2.85 V	96/f_{XP}	144/f_{XP}	12.0 μs	18.0 μs	9.6 μs	14.4 μs
1	0	1		48/f_{XP}	96/f_{XP}	6.0 μs	12.0 μs	4.8 μs	9.6 μs
0	1	0		48/f_{XP}	72/f_{XP}	6.0 μs	9.0 μs	4.8 μs	7.2 μs
0	0	1		24/f_{XP}	48/f_{XP}	3.0 μs	6.0 μs	Setting prohibited Note 5 (2.4 μs)	Setting prohibited Note 5 (4.8 μs)
1	1	1	$V_{DD} \geq$ 2.7 V	176/f_{XP}	224/f_{XP}	22.0 μs	28.0 μs	17.6 μs	22.4 μs
0	1	1		88/f_{XP}	112/f_{XP}	11.0 μs	14.0 μs	Setting prohibited Note 5 (8.8 μs)	Setting prohibited Note 5 (11.2 μs)

ADCE	Comparator operation control Note 6
0 Note 1	Stops operation of comparator
1	Enables operation of comparator

Remarks 1. f_{XP}: Oscillation frequency of clock to peripheral hardware

2. The conversion time refers to the total of the sampling time and the time from successively comparing with the sampling value until the conversion result is output.

Notes 1. Even when the ADCE = 0 (comparator operation stopped), the A/D conversion operation starts if the ADCS is set to 1. However, the data of the first conversion is out of the guaranteed-value range, so ignore it.

2. Be sure to set the FR2, FR1, and FR0, in accordance with the reference voltage so that **Notes 3** and **4** below are satisfied.

Example When $V_{DD} \geq$ 2.7 V, f_{XP} = 8 MHz

- The sampling time is 11.0 μs or more and the A/D conversion time is 14.0 μs or more and 100 μs or less.
- Set FR2, FR1, and FR0 = 0, 1, 1 or 1, 1, 1.

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Notes 3. Set the sampling time as follows.

- $V_{DD} \geq 4.5$ V: 1.0 μs or more
- $V_{DD} \geq 4.0$ V: 2.4 μs or more
- $V_{DD} \geq 2.85$ V: 3.0 μs or more
- $V_{DD} \geq 2.7$ V: 11.0 μs or more

4. Set the A/D conversion time as follows.

- $V_{DD} \geq 4.5$ V: 3.0 μs or more and less than 100 μs
- $V_{DD} \geq 4.0$ V: 4.8 μs or more and less than 100 μs
- $V_{DD} \geq 2.85$ V: 6.0 μs or more and less than 100 μs
- $V_{DD} \geq 2.7$ V: 14.0 μs or more and less than 100 μs

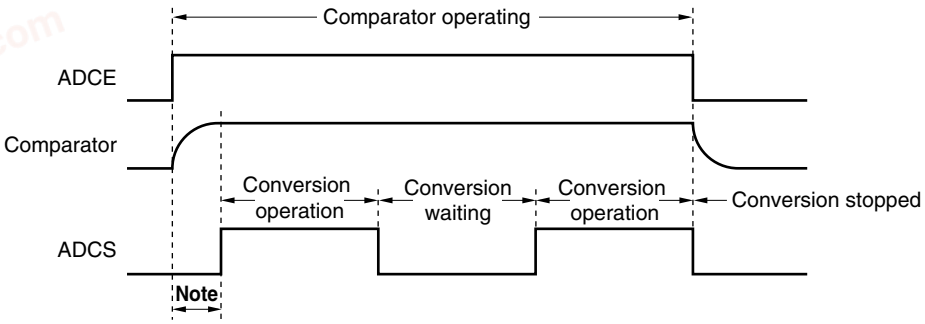
5. Setting is prohibited because the values do not satisfy the condition of **Notes 3** or **4**.

6. The operation of the comparator is controlled by ADCS and ADCE, and it takes 1 μs from operation start to operation stabilization. Therefore, when ADCS is set to 1 after 1 μs or more has elapsed from the time ADCE is set to 1, the conversion result at that time has priority over the first conversion result. If the ADCS is set to 1 without waiting for 1 μs or longer, ignore the first conversion data.

Table 9-2. Settings of ADCS and ADCE

ADCS	ADCE	A/D Conversion Operation
0	0	Stop status (DC power consumption path does not exist)
0	1	Conversion waiting mode (only comparator consumes power)
1	×	Conversion mode

Figure 9-4. Timing Chart When Comparator Is Used



Note The time from the rising of the ADCE bit to the rising of the ADCS bit must be 1 μs or longer to stabilize the internal circuit.

Cautions 1. The above sampling time and conversion time do not include the clock frequency error. Select the conversion time taking the clock frequency error into consideration (an error margin maximum of ±5% when using the high-speed internal oscillator).

2. If a bit other than ADCS of ADM is manipulated while A/D conversion is stopped (ADCS = 0) and then A/D conversion is started, execute two NOP instructions or an instruction equivalent to two machine cycles, and set ADCS to 1.

3. A/D conversion must be stopped (ADCS = 0) before rewriting bits FR0 to FR2.

4. Be sure to clear bits 6, 2, and 1 to 0.

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(2) Analog input channel specification register (ADS)

This register specifies the input port of the analog voltage to be A/D converted.

ADS can be set by a 1-bit or 8-bit memory manipulation instruction.

Reset signal generation clears this register to 00H.

Figure 9-5. Format of Analog Input Channel Specification Register (ADS)

Address: FF81H After reset: 00H R/W

Symbol	7	6	5	4	3	2	1	0
ADS	0	0	0	0	0	0	ADS1	ADS0

ADS1	ADS0	Analog input channel specification
0	0	ANI0
0	1	ANI1
1	0	ANI2
1	1	ANI3

Caution Be sure to clear bits 2 to 7 of ADS to 0.

(3) 10-bit A/D conversion result register (ADCR)

This register is a 16-bit register that stores the A/D conversion result. The higher six bits are fixed to 0. Each time A/D conversion ends, the conversion result is loaded from the successive approximation register, and is stored in ADCR in order starting from bit 1 of FF19H. FF19H indicates the higher 2 bits of the conversion result, and FF18H indicates the lower 8 bits of the conversion result.

ADCR can be read by a 16-bit memory manipulation instruction.

Reset signal generation makes ADCR undefined.

Figure 9-6. Format of 10-bit A/D Conversion Result Register (ADCR)

Address: FF18H, FF19H After reset: Undefined R

Symbol	FF19H								FF18H							
ADCR	0	0	0	0	0	0										

Caution When writing to the A/D converter mode register (ADM) and analog input channel specification register (ADS), the contents of ADCR may become undefined. Read the conversion result following conversion completion before writing to ADM and ADS. Using timing other than the above may cause an incorrect conversion result to be read.

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(4) 8-bit A/D conversion result register (ADCRH)

This register is an 8-bit register that stores the A/D conversion result. It stores the higher 8 bits of a 10-bit resolution result.

ADCRH can be read by an 8-bit memory manipulation instruction.

Reset signal generation makes ADCRH undefined.

Figure 9-7. Format of 8-bit A/D Conversion Result Register (ADCRH)

Address: FF1AH After reset: Undefined R

Symbol	7	6	5	4	3	2	1	0
ADCRH								

(5) Port mode register 2 (PM2) and port mode control register 2 (PMC2)

When using the when the P20/ANI0/TI000/TOH1, P21/ANI1/TI010/TO00/INTP0, P22/ANI2, and P23/ANI3 pins for analog input, set PM20 to PM23 and PMC20 to PMC23 to 1. At this time, the output latches of P20 to P23 may be 0 or 1.

PM2 and PMC2 are set by a 1-bit or 8-bit memory manipulation instruction.

Reset signal generation sets PM2 to 00H and clears PMC2 to FFH.

Figure 9-8. Format of Port Mode Register 2 (PM2)

Address: FF22H After reset: FFH R/W

Symbol	7	6	5	4	3	2	1	0
PM2	1	1	1	1	PM23	PM22	PM21	PM20

PM2n	Pmn pin I/O mode selection (n = 0 to 3)
0	Output mode (output buffer on)
1	Input mode (output buffer off)

Figure 9-9. Format of Port Mode Control Register 2 (PMC2)

Address: FF84H After reset: 00H R/W

Symbol	7	6	5	4	3	2	1	0
PMC2	0	0	0	0	PMC23	PMC22	PMC21	PMC20

PMC2n	Operation mode specification (n = 0 to 3)
0	Port/Alternate-function (except A/D converter) mode
1	A/D converter mode

Caution If PMC20 to PMC23 are set to 1, the P20/ANI0/TI000/TOH1, P21/ANI1/TI010/TO00/INTP0, P22/ANI2, and P23/ANI3 pins cannot be used for any purpose other than the A/D converter function.

Be sure to set the pull-up resistor option registers (PU20 to PU23) to 0 for the pins set to A/D converter mode.

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9.4 A/D Converter Operations

9.4.1 Basic operations of A/D converter

<1> Select one channel for A/D conversion using the analog input channel specification register (ADS).
<2> Set ADCE to 1 and wait for 1 μs or longer.
<3> Execute two NOP instructions or an instruction equivalent to two machine cycles.
<4> Set ADCS to 1 and start the conversion operation.
(<5> to <11> are operations performed by hardware.)
<5> The voltage input to the selected analog input channel is sampled by the sample & hold circuit.
<6> When sampling has been done for a certain time, the sample & hold circuit is placed in the hold state and the input analog voltage is held until the A/D conversion operation has ended.
<7> Bit 9 of the successive approximation register (SAR) is set. The D/A converter voltage tap is set to (1/2) V_{DD} by the tap selector.
<8> The voltage difference between the D/A converter voltage tap and analog input is compared by the voltage comparator. If the analog input is greater than (1/2) AV_{DD}, the MSB of SAR remains set to 1. If the analog input is smaller than (1/2) V_{DD}, the MSB is reset to 0.
<9> Next, bit 8 of SAR is automatically set to 1, and the operation proceeds to the next comparison. The D/A converter voltage tap is selected according to the preset value of bit 9, as described below.
- Bit 9 = 1: (3/4) V_{DD}
- Bit 9 = 0: (1/4) V_{DD}

The voltage tap and analog input voltage are compared and bit 8 of SAR is manipulated as follows.
- Analog input voltage ≥ Voltage tap: Bit 8 = 1
- Analog input voltage < Voltage tap: Bit 8 = 0

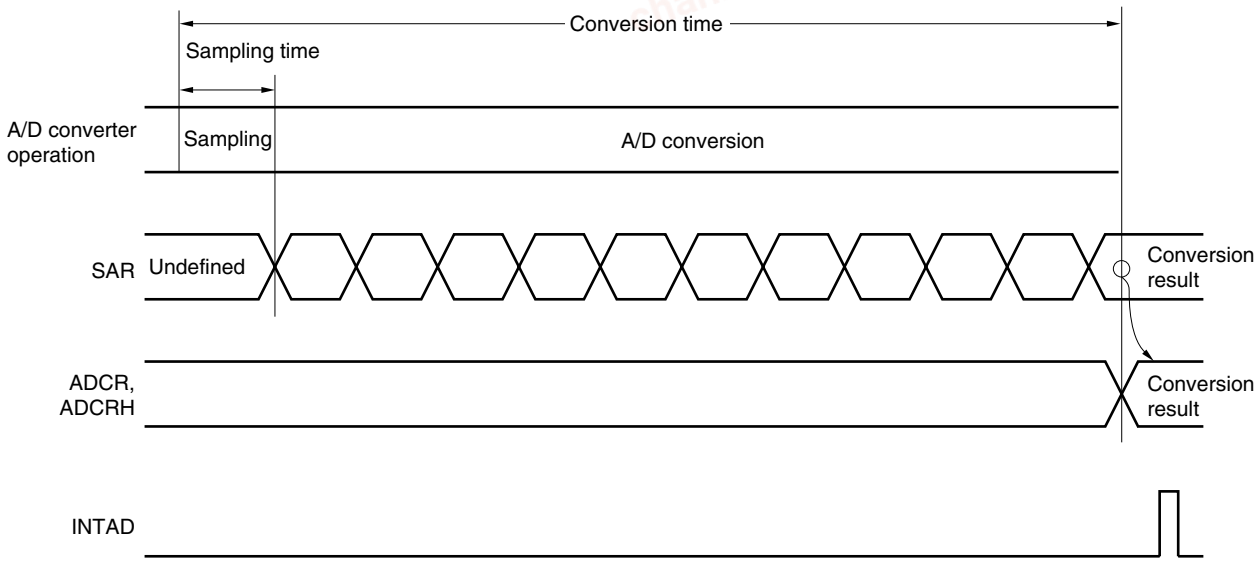
<10> Comparison is continued in this way up to bit 0 of SAR.
<11> Upon completion of the comparison of 10 bits, an effective digital result value remains in SAR, and the result value is transferred to the A/D conversion result register (ADCR, ADCRH) and then latched.
At the same time, the A/D conversion end interrupt request (INTAD) can also be generated.
<12> Repeat steps <5> to <11>, until ADCS is cleared to 0.
To stop the A/D converter, clear ADCS to 0.
To restart A/D conversion from the status of ADCE = 1, start from <3>. To restart A/D conversion from the status of ADCE = 0, start from <2>.

Cautions 1. Make sure the period of <1> to <4> is 1 μs or more.
2. It is no problem if the order of <1> and <2> is reversed.

Remark The following two types of A/D conversion result registers can be used.
- ADCR (16 bits): Stores a 10-bit A/D conversion value.
- ADCRH (8 bits): Stores an 8-bit A/D conversion value.

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Figure 9-10. Basic Operation of A/D Converter



A/D conversion operations are performed continuously until bit 7 (ADCS) of the A/D converter mode register (ADM) is reset (0) by software.

If a write operation is performed to ADM or the analog input channel specification register (ADS) during an A/D conversion operation, the conversion operation is initialized, and if the ADCS bit is set (1), conversion starts again from the beginning.

Reset signal generation makes the A/D conversion result register (ADCR, ADCRH) undefined.

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9.4.2 Input voltage and conversion results

The relationship between the analog input voltage input to the analog input pins (ANI0 to ANI3) and the theoretical A/D conversion result (stored in the 10-bit A/D conversion result register (ADCR)) is shown by the following expression.

$$ADCR = INT\left(\frac{V_{AIN}}{V_{DD}} \times 1024 + 0.5\right)$$

or

$$(ADCR - 0.5) \times \frac{V_{DD}}{1024} \leq V_{AIN} < (ADCR + 0.5) \times \frac{V_{DD}}{1024}$$

where, INT( ): Function which returns integer part of value in parentheses

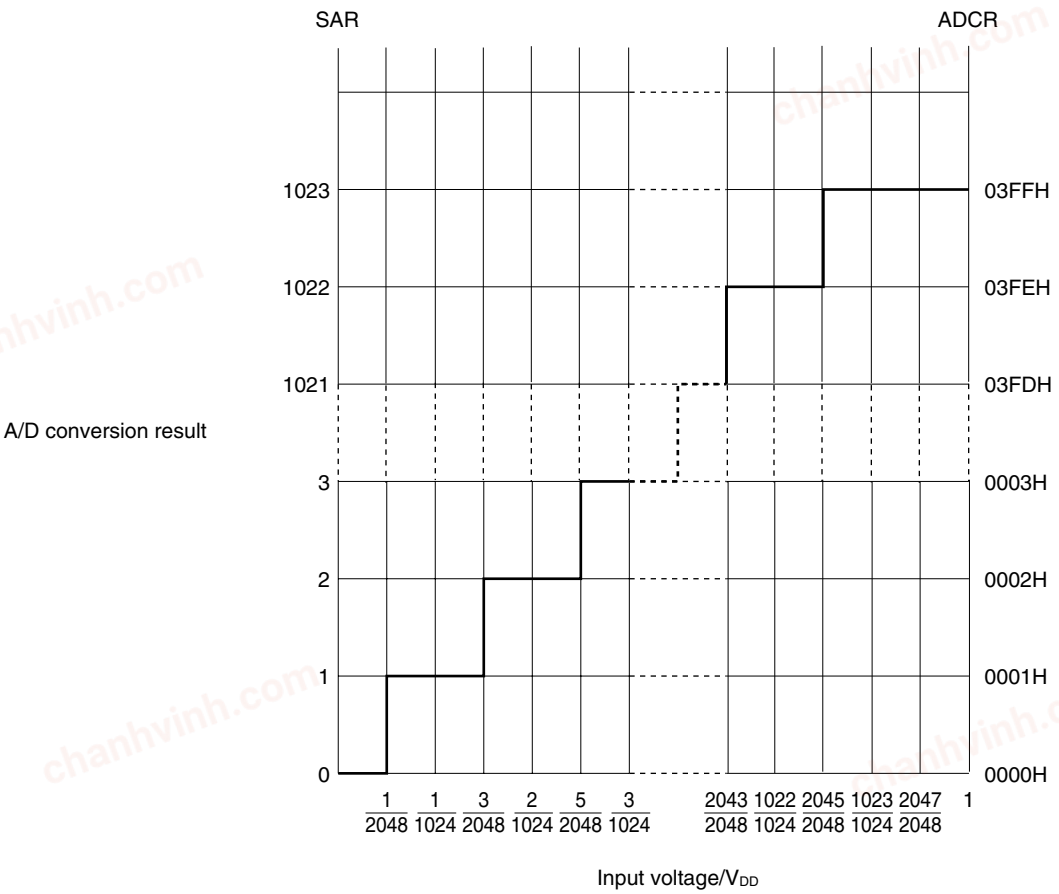
V_{AIN}: Analog input voltage

V_{DD}: V_{DD} pin voltage

ADCR: 10-bit A/D conversion result register (ADCR) value

Figure 9-11 shows the relationship between the analog input voltage and the A/D conversion result.

Figure 9-11. Relationship Between Analog Input Voltage and A/D Conversion Result



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9.4.3 A/D converter operation mode

The operation mode of the A/D converter is the select mode. One channel of analog input is selected from ANI0 to ANI3 by the analog input channel specification register (ADS) and A/D conversion is executed.

(1) A/D conversion operation

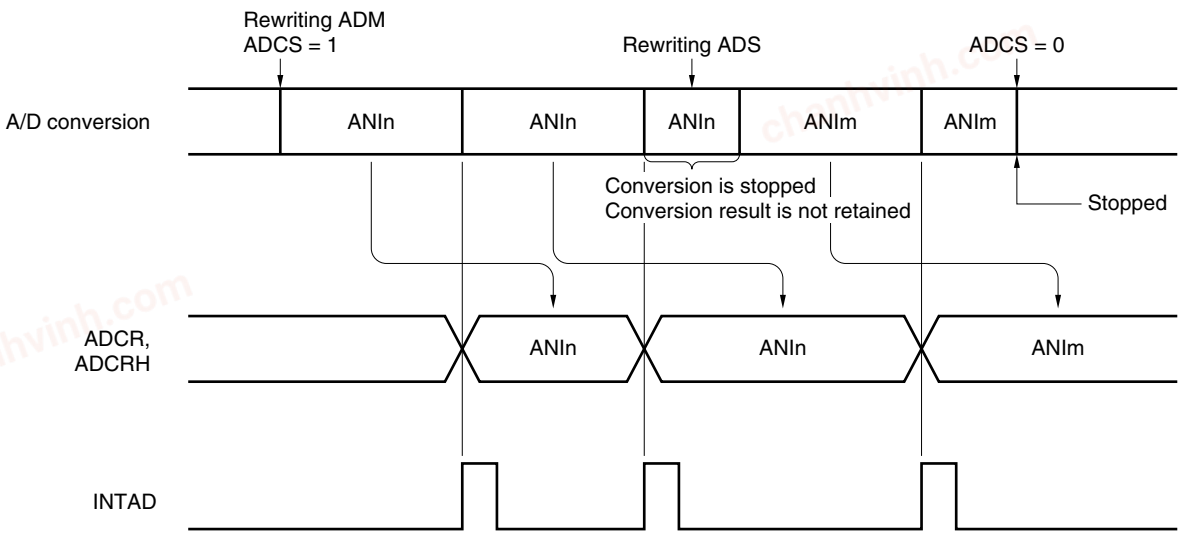
By setting bit 7 (ADCS) of the A/D converter mode register (ADM) to 1, the A/D conversion operation of the voltage, which is applied to the analog input pin specified by the analog input channel specification register (ADS), is started.

When A/D conversion has been completed, the result of the A/D conversion is stored in the A/D conversion result register (ADCR, ADCRH), and an interrupt request signal (INTAD) is generated. Once the A/D conversion has started and when one A/D conversion has been completed, the next A/D conversion operation is immediately started. The A/D conversion operations are repeated until new data is written to ADS.

If ADM or ADS is written during A/D conversion, the A/D conversion operation under execution is stopped and restarted from the beginning.

If 0 is written to ADCS during A/D conversion, A/D conversion is immediately stopped. At this time, the conversion result is undefined.

Figure 9-12. A/D Conversion Operation



Remarks 1. n = 0 to 3

2. m = 0 to 3

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The setting method is described below.

<1> Set bit 0 (ADCE) of the A/D converter mode register (ADM) to 1.
<2> Select the channel and conversion time using bits 1 and 0 (ADS1, ADS0) of the analog input channel specification register (ADS) and bits 5 to 3 (FR2 to FR0) of ADM.
<3> Execute two NOP instructions or an instruction equivalent to two machine cycles.
<4> Set bit 7 (ADCS) of ADM to 1 to start A/D conversion.
<5> An interrupt request signal (INTAD) is generated.
<6> Transfer the A/D conversion data to the A/D conversion result register (ADCR, ADCRH).

<Change the channel>

<7> Change the channel using bits 1 and 0 (ADS1, ADS0) of ADS to start A/D conversion.
<8> An interrupt request signal (INTAD) is generated.
<9> Transfer the A/D conversion data to the A/D conversion result register (ADCR, ADCRH).

<Complete A/D conversion>

<10> Clear ADCS to 0.
<11> Clear ADCE to 0.

Cautions 1. Make sure the period of <1> to <4> is 1 μs or more.
2. It is no problem if the order of <1> and <2> is reversed.
3. <1> can be omitted. However, ignore the data resulting from the first conversion after <4> in this case.
4. The period from <5> to <8> differs from the conversion time set using bits 5 to 3 (FR2 to FR0) of ADM. The period from <7> to <8> is the conversion time set using FR2 to FR0.

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9.5 How to Read A/D Converter Characteristics Table

Here, special terms unique to the A/D converter are explained.

(1) Resolution

This is the minimum analog input voltage that can be identified. That is, the percentage of the analog input voltage per bit of digital output is called 1LSB (Least Significant Bit). The percentage of 1LSB with respect to the full scale is expressed by %FSR (Full Scale Range).

1LSB is as follows when the resolution is 10 bits.

$1LSB = 1/2^{10} = 1/1024$
$= 0.098\%FSR$

Accuracy has no relation to resolution, but is determined by overall error.

(2) Overall error

This shows the maximum error value between the actual measured value and the theoretical value.
Zero-scale error, full-scale error, integral linearity error, and differential linearity errors that are combinations of these express the overall error.
Note that the quantization error is not included in the overall error in the characteristics table.

(3) Quantization error

When analog values are converted to digital values, a ±1/2LSB error naturally occurs. In an A/D converter, an analog input voltage in a range of ±1/2LSB is converted to the same digital code, so a quantization error cannot be avoided.
Note that the quantization error is not included in the overall error, zero-scale error, full-scale error, integral linearity error, and differential linearity error in the characteristics table.

Figure 9-13. Overall Error

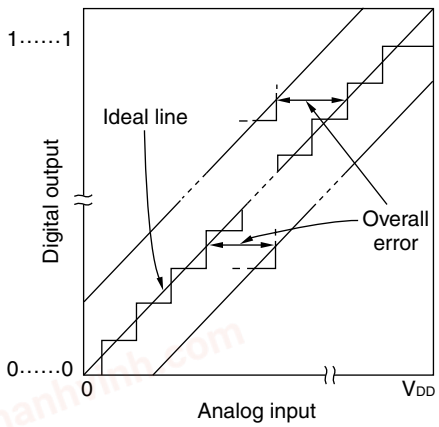
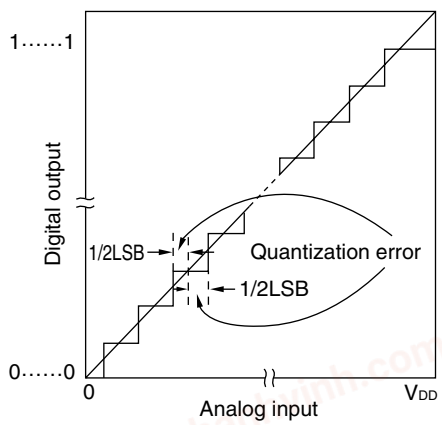


Figure 9-14. Quantization Error



(4) Zero-scale error

This shows the difference between the actual measurement value of the analog input voltage and the theoretical value (1/2LSB) when the digital output changes from 0.....000 to 0.....001.
If the actual measurement value is greater than the theoretical value, it shows the difference between the actual measurement value of the analog input voltage and the theoretical value (3/2LSB) when the digital output changes from 0……001 to 0……010.

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(5) Full-scale error

This shows the difference between the actual measurement value of the analog input voltage and the theoretical value (Full-scale – 3/2LSB) when the digital output changes from 1.....110 to 1.....111.

(6) Integral linearity error

This shows the degree to which the conversion characteristics deviate from the ideal linear relationship. It expresses the maximum value of the difference between the actual measurement value and the ideal straight line when the zero-scale error and full-scale error are 0.

(7) Differential linearity error

While the ideal width of code output is 1LSB, this indicates the difference between the actual measurement value and the ideal value.

Figure 9-15. Zero-Scale Error

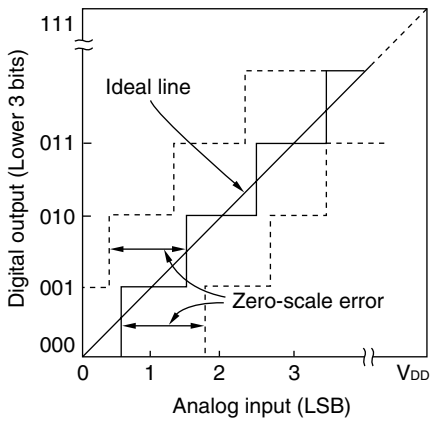


Figure 9-16. Full-Scale Error

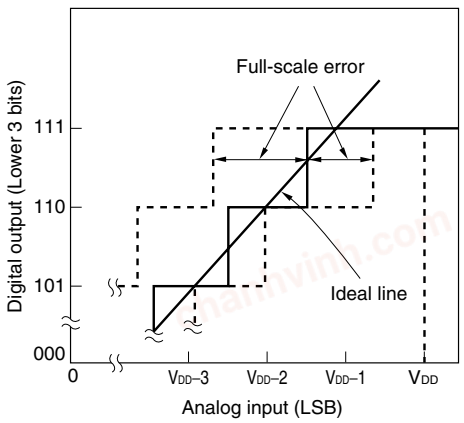


Figure 9-17. Integral Linearity Error

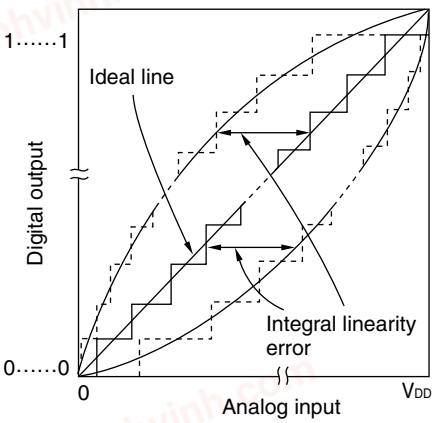
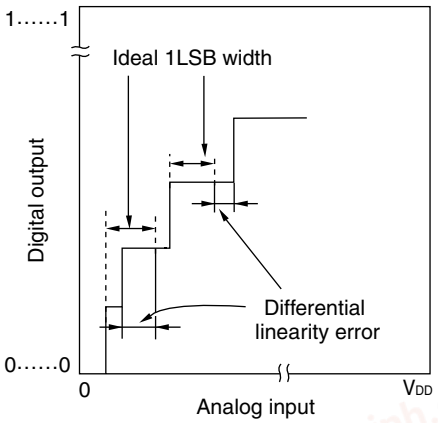


Figure 9-18. Differential Linearity Error



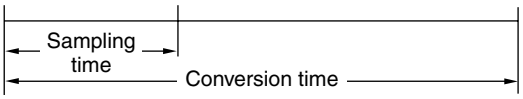
(8) Conversion time

This expresses the time from the start of sampling to when the digital output is obtained.

The sampling time is included in the conversion time in the characteristics table.

(9) Sampling time

This is the time the analog switch is turned on for the analog voltage to be sampled by the sample & hold circuit.



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9.6 Cautions for A/D Converter

(1) Operating current in STOP mode

To satisfy the DC characteristics of the supply current in the STOP mode, clear bit 7 (ADCS) and bit 0 (ADCE) of the A/D converter mode register (ADM) to 0 before executing the STOP instruction.

(2) Input range of ANI0 to ANI3

Observe the rated range of the ANI0 to ANI3 input voltage. If a voltage of V_{DD} or higher and V_{SS} or lower (even in the range of absolute maximum ratings) is input to an analog input channel, the converted value of that channel becomes undefined. In addition, the converted values of the other channels may also be affected.

(3) Conflicting operations

<1> Conflict between A/D conversion result register (ADCR, ADCRH) write and ADCR, ADCRH read by instruction upon the end of conversion

ADCR, ADCRH read has priority. After the read operation, the new conversion result is written to ADCR, ADCRH.

<2> Conflict between ADCR, ADCRH write and A/D converter mode register (ADM) write or analog input channel specification register (ADS) write upon the end of conversion

ADM or ADS write has priority. ADCR, ADCRH write is not performed, nor is the conversion end interrupt signal (INTAD) generated.

(4) Noise countermeasures

To maintain the 10-bit resolution, attention must be paid to noise input to the V_{DD} pin and ANI0 to ANI3 pins.

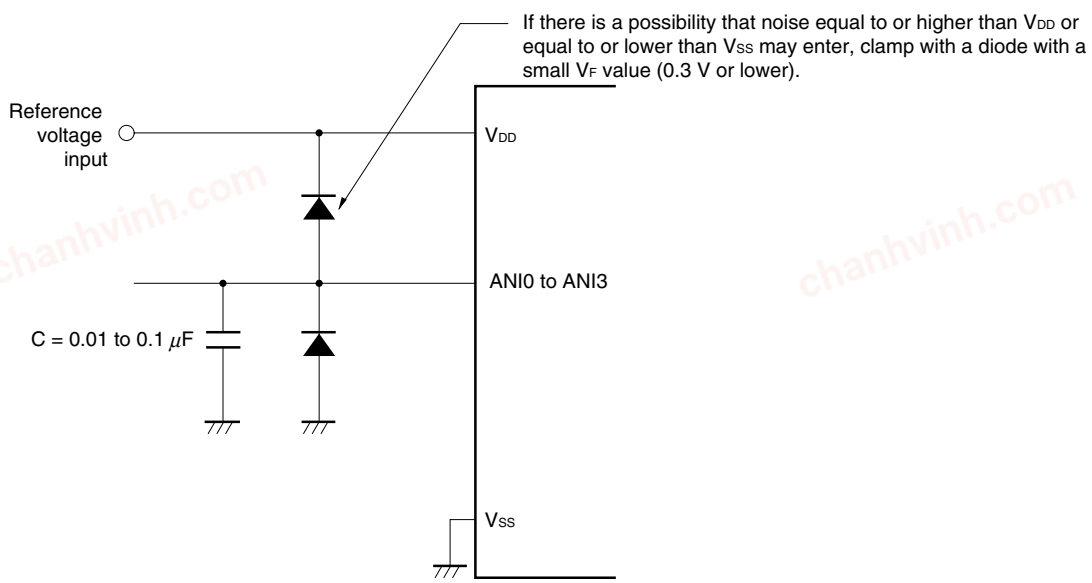
<1> Connect a capacitor with a low equivalent resistance and a high frequency response to the power supply.

<2> Because the effect increases in proportion to the output impedance of the analog input source, it is recommended that a capacitor be connected externally, as shown in Figure 9-19, to reduce noise.

<3> Do not switch the A/D conversion function of the ANI0 to ANI3 pins to their alternate functions during conversion.

<4> The conversion accuracy can be improved by setting HALT mode immediately after the conversion starts.

Figure 9-19. Analog Input Pin Connection



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(5) ANI0/P20 to ANI3/P23

<1> The analog input pins (ANI0 to ANI3) are also used as I/O port pins (P20 to P23).
When A/D conversion is performed with any of ANI0 to ANI3 selected, do not access P20 to P23 while conversion is in progress; otherwise the conversion resolution may be degraded.

<2> If a digital pulse is applied to the pins adjacent to the pins currently used for A/D conversion, the expected value of the A/D conversion may not be obtained due to coupling noise. Therefore, do not apply a pulse to the pins adjacent to the pin undergoing A/D conversion.

(6) Input impedance of ANI0 to ANI3 pins

In this A/D converter, the internal sampling capacitor is charged and sampling is performed during sampling time. Since only the leakage current flows other than during sampling and the current for charging the capacitor also flows during sampling, the input impedance fluctuates during sampling and other statuses.

If the shortest conversion time of the reference voltage is used, to perform sufficient sampling, it is recommended to make the output impedance of the analog input source 1 kΩ or lower, or attach a capacitor of around 0.01 μF to 0.1 μF to the ANI0 to ANI3 pins (see **Figure 9-19**).

When writing the flash memory on-board, supply a stabilized analog voltage to the ANI2 and ANI3 pins, without attaching a capacitor. Because the communication pulse may change and the communication may fail if a capacitor is attached to remove noise.

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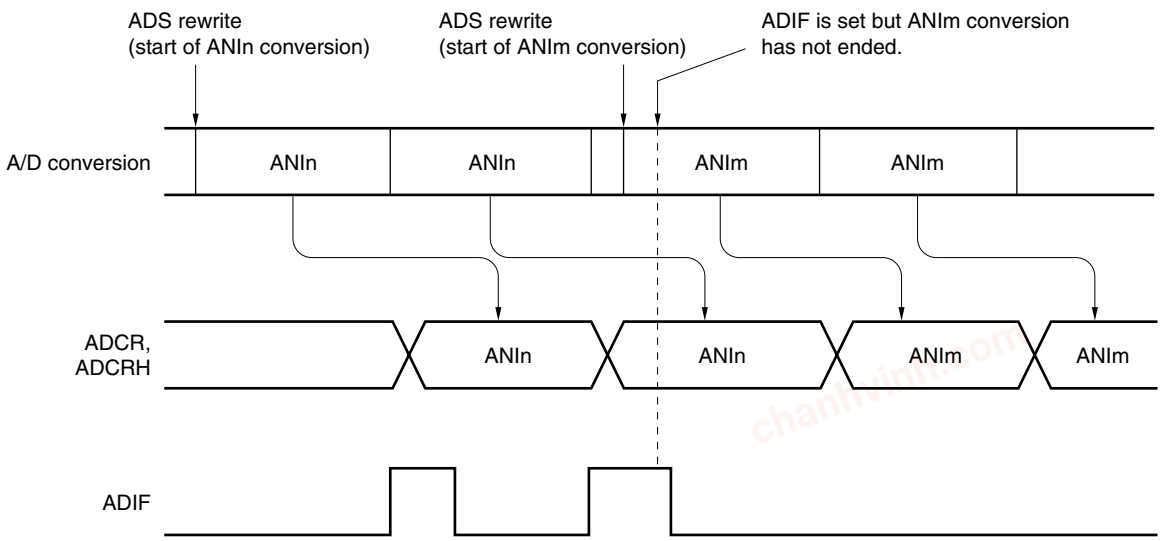
(7) Interrupt request flag (ADIF)

The interrupt request flag (ADIF) is not cleared even if the analog input channel specification register (ADS) is changed.

Therefore, if an analog input pin is changed during A/D conversion, the A/D conversion result and ADIF for the pre-change analog input may be set just before the ADS rewrite. Caution is therefore required since, at this time, when ADIF is read immediately after the ADS rewrite, ADIF is set despite the fact A/D conversion for the post-change analog input has not ended.

When A/D conversion is stopped and then resumed, clear ADIF before the A/D conversion operation is resumed.

Figure 9-20. Timing of A/D Conversion End Interrupt Request Generation



Remarks 1. n = 0 to 3

2. m = 0 to 3

(8) Conversion results just after A/D conversion start

The first A/D conversion value immediately after A/D conversion starts may not fall within the rating range if the ADCS bit is set to 1 within 1 μs after the ADCE bit was set to 1, or if the ADCS bit is set to 1 with the ADCE bit = 0. Take measures such as polling the A/D conversion end interrupt request (INTAD) and removing the first conversion result.

(9) A/D conversion result register (ADCR, ADCRH) read operation

When a write operation is performed to the A/D converter mode register (ADM) and analog input channel specification register (ADS), the contents of ADCR and ADCRH may become undefined. Read the conversion result following conversion completion before writing to ADM and ADS. Using a timing other than the above may cause an incorrect conversion result to be read.

(10) Operating current at conversion waiting mode

The DC characteristic of the operating current during the STOP mode is not satisfied due to the conversion waiting mode (only the comparator consumes power), when bit 7 (ADCS) and bit 0 (ADCE) of the A/D converter mode register (ADM) are set to 0 and 1 respectively.

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(11) Internal equivalent circuit

The equivalent circuit of the analog input block is shown below.

Figure 9-21. Internal Equivalent Circuit of ANIn Pin

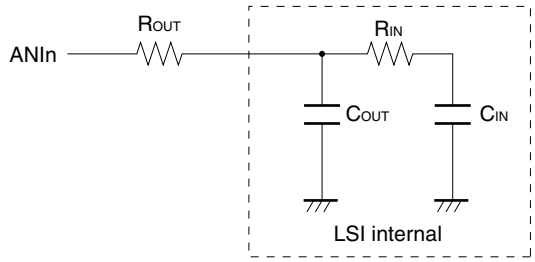


Table 9-3. Resistance and Capacitance Values (Reference Values) of Equivalent Circuit

V_{DD}	R_{OUT}	R_{IN}	C_{OUT}	C_{IN}
$4.5\ V \le V_{DD} \le 5.5\ V$	1 kΩ	3 kΩ	8 pF	15 pF
$2.7\ V \le V_{DD} < 4.5\ V$	1 kΩ	60 kΩ	8 pF	15 pF

Remarks 1. The resistance and capacitance values shown in Table 9-3 are not guaranteed values.

2. n = 0 to 3

3. R_{OUT}: Allowable signal source impedance
R_{IN}: Analog input equivalent resistance
C_{OUT}: Internal pin capacitance
C_{IN}: Analog Input equivalent capacitance

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CHAPTER 10 INTERRUPT FUNCTIONS

10.1 Interrupt Function Types

There are two types of interrupts: maskable interrupts and resets.

- **Maskable interrupts**
  These interrupts undergo mask control. When an interrupt request occurs, the standby release signal occurs, and if an interrupt can be acknowledged then the program corresponding to the address written in the vector table address is executed (vector interrupt servicing). When several interrupt requests are generated at the same time, processing takes place in the priority order of the vector interrupt servicing. For details on the priority order, see Table 10-1.
  There are external sources and internal sources of maskable interrupts.
  - μPD78F921x: external sources: 2, internal sources: 5
  - μPD78F951x: external sources: 2, internal sources: 4

- **Reset**
  The CPU and SFR are returned to their initial states by the reset signal. The causes for reset signal occurrences are shown in Table 10-1.
  When a reset signal occurs, program execution starts from the programs at the addresses written in addresses 0000H and 0001H.

10.2 Interrupt Sources and Configuration

There are a total of seven maskable interrupt sources in μPD78F921x, and six maskable interrupt sources in μPD78F951x, and up to four reset sources (see **Table 10-1**).

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Table 10-1. Interrupt Sources

Interrupt Type	Priority[Note 1]	Interrupt Source		Internal/ External	Vector Table Address	Basic Configuration Type[Note 2]
		Name	Trigger			
Maskable	1	INTLVI	Low-voltage detection[Note 4]	Internal	0006H	(A)
	2	INTP0	Pin input edge detection	External	0008H	(B)
	3	INTP1			000AH	
	4	INTTMH1	Match between TMH1 and CMP01 (when compare register is specified)	Internal	000CH	(A)
	5	INTTM000	Match between TM00 and CR000 (when compare register is specified), TI010 pin valid edge detection (when capture register is specified)		000EH	
	6	INTTM010	Match between TM00 and CR010 (when compare register is specified), TI000 pin valid edge detection (when capture register is specified)		0010H	
	7	INTAD[Note 3]	End of A/D conversion		0012H	
Reset	–	RESET	Reset input	–	0000H	–
		POC	Power-on-clear			
		LVI	Low-voltage detection[Note 5]			
		WDT	WDT overflow			

Notes 1. Priority is the vector interrupt servicing priority order when several maskable interrupt requests are generated at the same time. 1 is the highest and 7 is the lowest.

2. Basic configuration types (A) and (B) correspond to (A) and (B) in Figure 10-1.

<R> **3.** μPD78F921x only

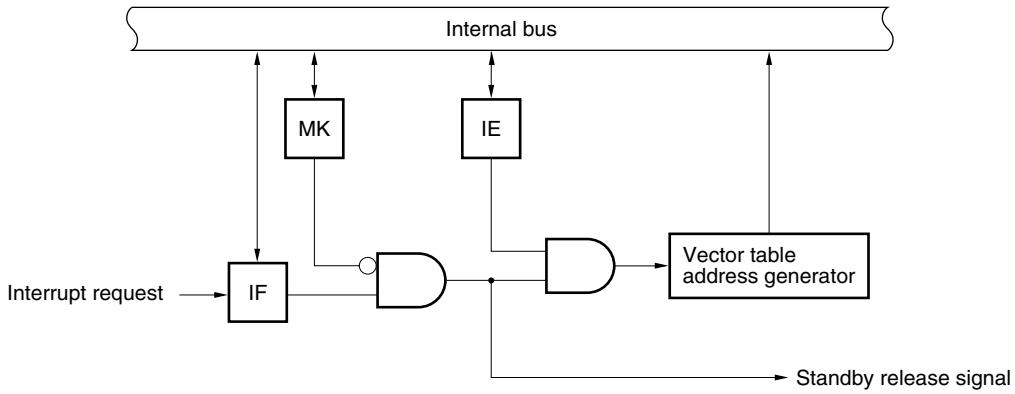
4. When bit 1 (LVIMD) of low-voltage detection register (LVIM) = 0 is selected.

5. When bit 1 (LVIMD) of low-voltage detection register (LVIM) = 1 is selected.

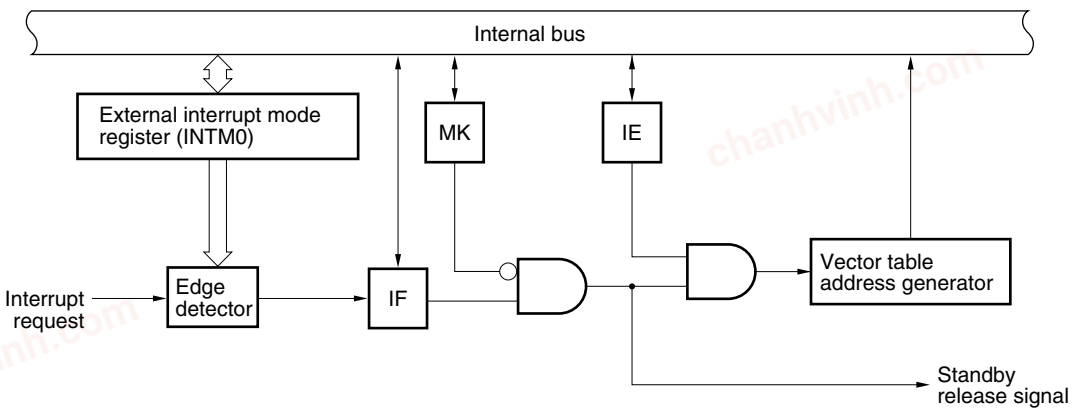
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Figure 10-1. Basic Configuration of Interrupt Function

(A) Internal maskable interrupt



(B) External maskable interrupt



IF: Interrupt request flag
IE: Interrupt enable flag
MK: Interrupt mask flag

10.3 Interrupt Function Control Registers

The interrupt functions are controlled by the following four types of registers.

- Interrupt request flag register 0 (IF0)
- Interrupt mask flag register 0 (MK0)
- External interrupt mode register 0 (INTM0)
- Program status word (PSW)

Table 10-2 lists interrupt requests, the corresponding interrupt request flags, and interrupt mask flags.

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Table 10-2. Interrupt Request Signals and Corresponding Flags

Interrupt Request Signal	Interrupt Request Flag	Interrupt Mask Flag
INTLVI	LVIIF	LVIMK
INTP0	PIF0	PMK0
INTP1	PIF1	PMK1
INTTMH1	TMIFH1	TMMKH1
INTTM000	TMIF000	TMMK000
INTTM010	TMIF010	TMMK010
INTAD[Note]	ADIF[Note]	ADMK[Note]

<R> **Note** μPD78F921x only

(1) Interrupt request flag register 0 (IF0)

An interrupt request flag is set to 1 when the corresponding interrupt request is issued, or when the instruction is executed. It is cleared to 0 by executing an instruction when the interrupt request is acknowledged or when a reset signal is input.

IF0 is set with a 1-bit or 8-bit memory manipulation instruction.

Reset signal generation clears IF0 to 00H.

Figure 10-2. Format of Interrupt Request Flag Register 0 (IF0)

Address: FFE0H After reset: 00H R/W

Symbol	<7>	<6>	<5>	<4>	<3>	<2>	<1>	0
IF0	ADIF[Note]	TMIF010	TMIF000	TMIFH1	PIF1	PIF0	LVIIF	0

××IF×	Interrupt request flag
0	No interrupt request signal has been issued.
1	An interrupt request signal has been issued; an interrupt request status.

<R> **Note** μPD78F921x only

Caution Because P21 and P32 have an alternate function as external interrupt inputs, when the output level is changed by specifying the output mode of the port function, an interrupt request flag is set. Therefore, the interrupt mask flag should be set to 1 before using the output mode.

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(2) Interrupt mask flag register 0 (MK0)

The interrupt mask flag is used to enable and disable the corresponding maskable interrupts.

MK0 is set with a 1-bit or 8-bit memory manipulation instruction.

Reset signal generation sets MK0 to FFH.

Figure 10-3. Format of Interrupt Mask Flag Register 0 (MK0)

Address: FFE4H After reset: FFH R/W

Symbol	<7>	<6>	<5>	<4>	<3>	<2>	<1>	0
MK0	ADMK[Note]	TMMK010	TMMK000	TMMKH1	PMK1	PMK0	LVIMK	1

××MK×	Interrupt servicing control
0	Enables interrupt servicing.
1	Disables interrupt servicing.

<R> **Note** μPD78F921x only

Caution Because P21 and P32 have an alternate function as external interrupt inputs, when the output level is changed by specifying the output mode of the port function, an interrupt request flag is set. Therefore, the interrupt mask flag should be set to 1 before using the output mode.

(3) External interrupt mode register 0 (INTM0)

This register is used to set the valid edge of INTP0 and INTP1.

INTM0 is set with an 8-bit memory manipulation instruction.

Reset signal generation clears INTM0 to 00H.

Figure 10-4. Format of External Interrupt Mode Register 0 (INTM0)

Address: FFECH After reset: 00H R/W

Symbol	7	6	5	4	3	2	1	0
INTM0	0	0	ES11	ES10	ES01	ES00	0	0

ES11	ES10	INTP1 valid edge selection
0	0	Falling edge
0	1	Rising edge
1	0	Setting prohibited
1	1	Both rising and falling edges

ES01	ES00	INTP0 valid edge selection
0	0	Falling edge
0	1	Rising edge
1	0	Setting prohibited
1	1	Both rising and falling edges

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Cautions 1. Be sure to clear bits 0, 1, 6, and 7 to 0.

2. Before setting the INTM0 register, be sure to set the corresponding interrupt mask flag (××MK× = 1) to disable interrupts. After setting the INTM0 register, clear the interrupt request flag (××IF× = 0), then clear the interrupt mask flag (××MK× = 0), which will enable interrupts.

(4) Program status word (PSW)

The program status word is used to hold the instruction execution result and the current status of the interrupt requests. The IE flag, used to enable and disable maskable interrupts, is mapped to PSW.

PSW can be read- and write-accessed in 8-bit units, as well as using bit manipulation instructions and dedicated instructions (EI and DI). When a vectored interrupt is acknowledged, the PSW is automatically saved to a stack, and the IE flag is reset to 0.

Reset signal generation sets PSW to 02H.

Figure 10-5. Program Status Word (PSW) Configuration

Symbol	7	6	5	4	3	2	1	0	After reset
PSW	IE	Z	0	AC	0	0	1	CY	02H

Used in the execution of ordinary instructions

IE	Whether to enable/disable interrupt acknowledgment
0	Disabled
1	Enabled

10.4 Interrupt Servicing Operation

10.4.1 Maskable interrupt request acknowledgment operation

A maskable interrupt request can be acknowledged when the interrupt request flag is set to 1 and the corresponding interrupt mask flag is cleared to 0. If the interrupt enabled status is in effect (when the IE flag is set to 1), then the request is acknowledged as a vector interrupt.

The time required to start the vectored interrupt servicing after a maskable interrupt request has been generated is shown in Table 10-3.

See Figures 10-7 and 10-8 for the interrupt request acknowledgment timing.

Table 10-3. Time from Generation of Maskable Interrupt Request to Servicing

Minimum Time	Maximum Time[Note]
9 clocks	19 clocks

Note The wait time is maximum when an interrupt request is generated immediately before BT and BF instructions.

Remark 1 clock: $\frac{1}{f_{CPU}}$ (f_{CPU}: CPU clock)

When two or more maskable interrupt requests are generated at the same time, they are acknowledged starting from the interrupt request assigned the highest priority.

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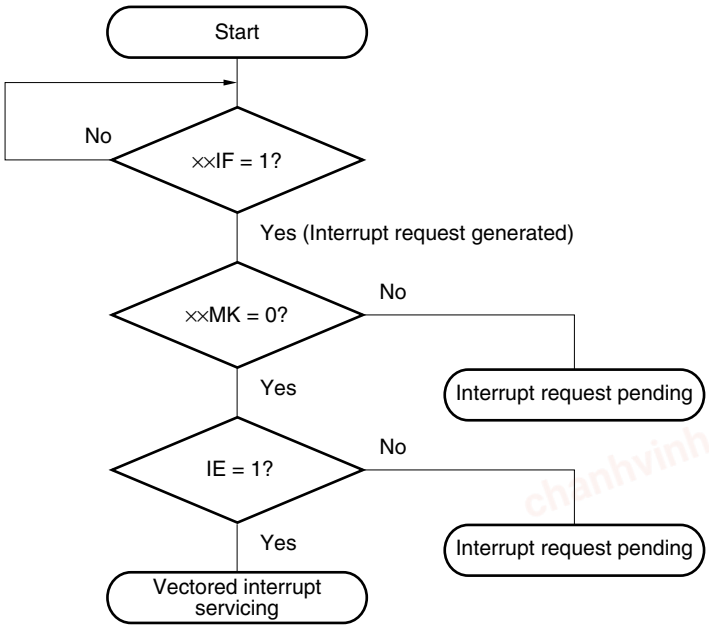
A pending interrupt is acknowledged when a status in which it can be acknowledged is set.

Figure 10-6 shows the algorithm of interrupt request acknowledgment.

When a maskable interrupt request is acknowledged, the contents of the PSW and PC are saved to the stack in that order, the IE flag is reset to 0, and the data in the vector table determined for each interrupt request is loaded to the PC, and execution branches.

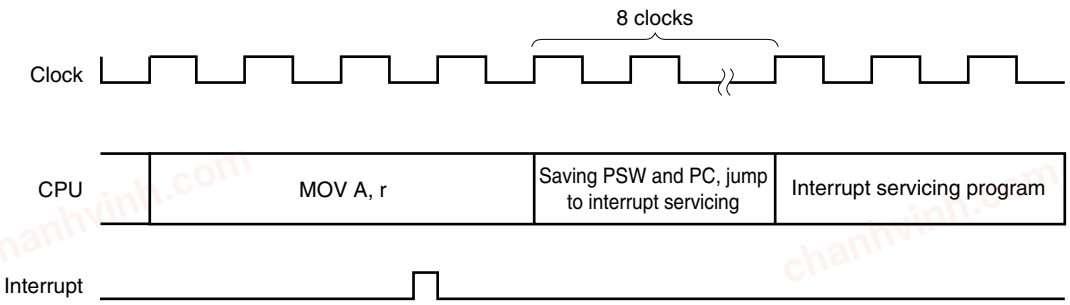
To return from interrupt servicing, use the RETI instruction.

Figure 10-6. Interrupt Request Acknowledgment Processing Algorithm



××IF: Interrupt request flag
××MK: Interrupt mask flag
IE: Flag to control maskable interrupt request acknowledgment (1 = enable, 0 = disable)

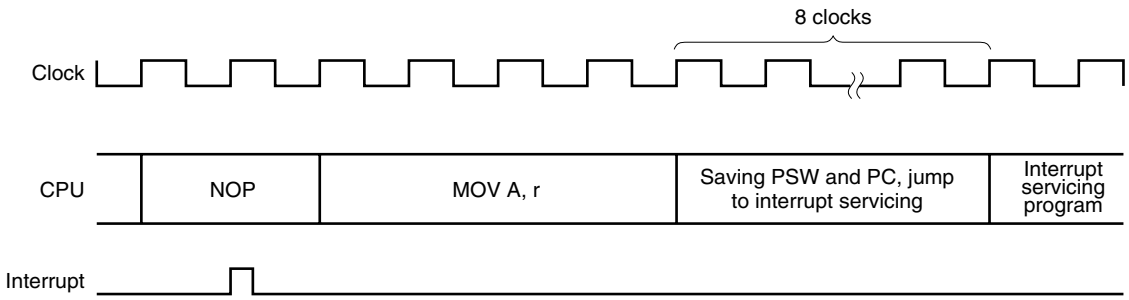
Figure 10-7. Interrupt Request Acknowledgment Timing (Example of MOV A, r)



If an interrupt request flag (××IF) is set before an instruction clock n (n = 4 to 10) under execution becomes n – 1, the interrupt is acknowledged after the instruction under execution is complete. Figure 10-7 shows an example of the interrupt request acknowledgment timing for an 8-bit data transfer instruction MOV A, r. Since this instruction is executed for 4 clocks, if an interrupt occurs for 3 clocks after the instruction fetch starts, the interrupt acknowledgment processing is performed after the MOV A, r instruction is executed.

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Figure 10-8. Interrupt Request Acknowledgment Timing (When Interrupt Request Flag Is Set at Last Clock During Instruction Execution)



If an interrupt request flag (××IF) is set at the last clock of the instruction, the interrupt acknowledgment processing starts after the next instruction is executed.

Figure 10-8 shows an example of the interrupt request acknowledgment timing for an interrupt request flag that is set at the second clock of NOP (2-clock instruction). In this case, the MOV A, r instruction after the NOP instruction is executed, and then the interrupt acknowledgment processing is performed.

Caution Interrupt requests will be held pending while the interrupt request flag register 0 (IF0) or interrupt mask flag register 0 (MK0) are being accessed.

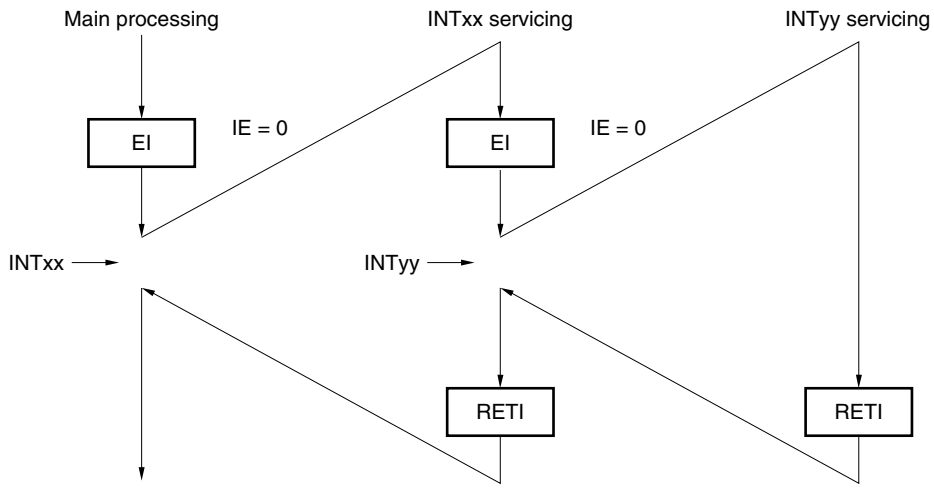
10.4.2 Multiple interrupt servicing

In order to perform multiple interrupt servicing in which another interrupt is acknowledged while an interrupt is being serviced, the interrupt mask function must be used to mask interrupts for which a low priority is to be set.

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Figure 10-9. Example of Multiple Interrupts (1/2)

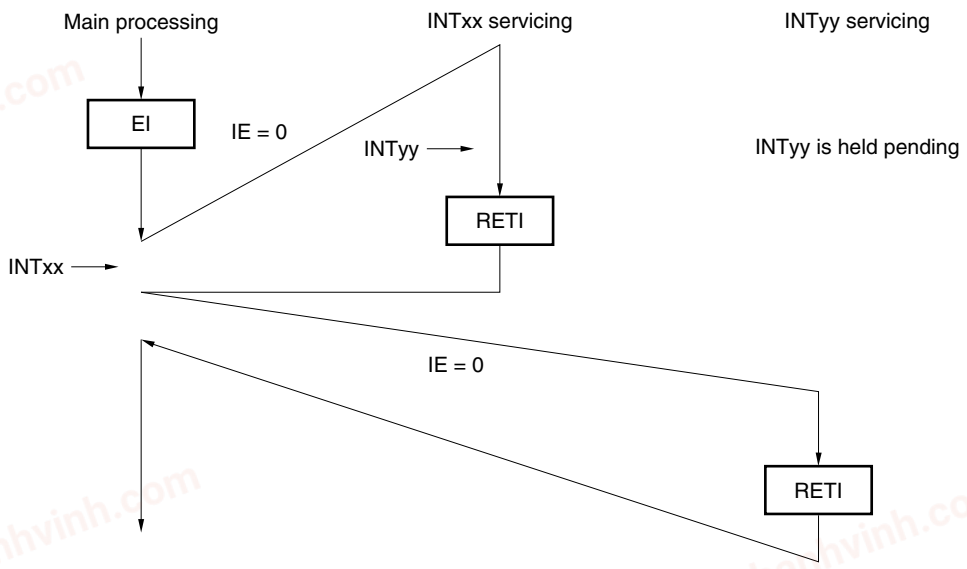
Example 1. Multiple interrupts are acknowledged



During interrupt INTxx servicing, interrupt request INTyy is acknowledged, and multiple interrupts are generated. Before each interrupt request acknowledgment, the EI instruction is issued, the interrupt mask is released, and the interrupt request acknowledgment enable state is set.

Caution Multiple interrupts can be acknowledged even for low-priority interrupts.

Example 2. Multiple interrupts are not generated because interrupts are not enabled



Because interrupts are not enabled in interrupt INTxx servicing (the EI instruction is not issued), interrupt request INTyy is not acknowledged, and multiple interrupts are not generated. The INTyy request is held pending and acknowledged after the INTxx servicing is performed.

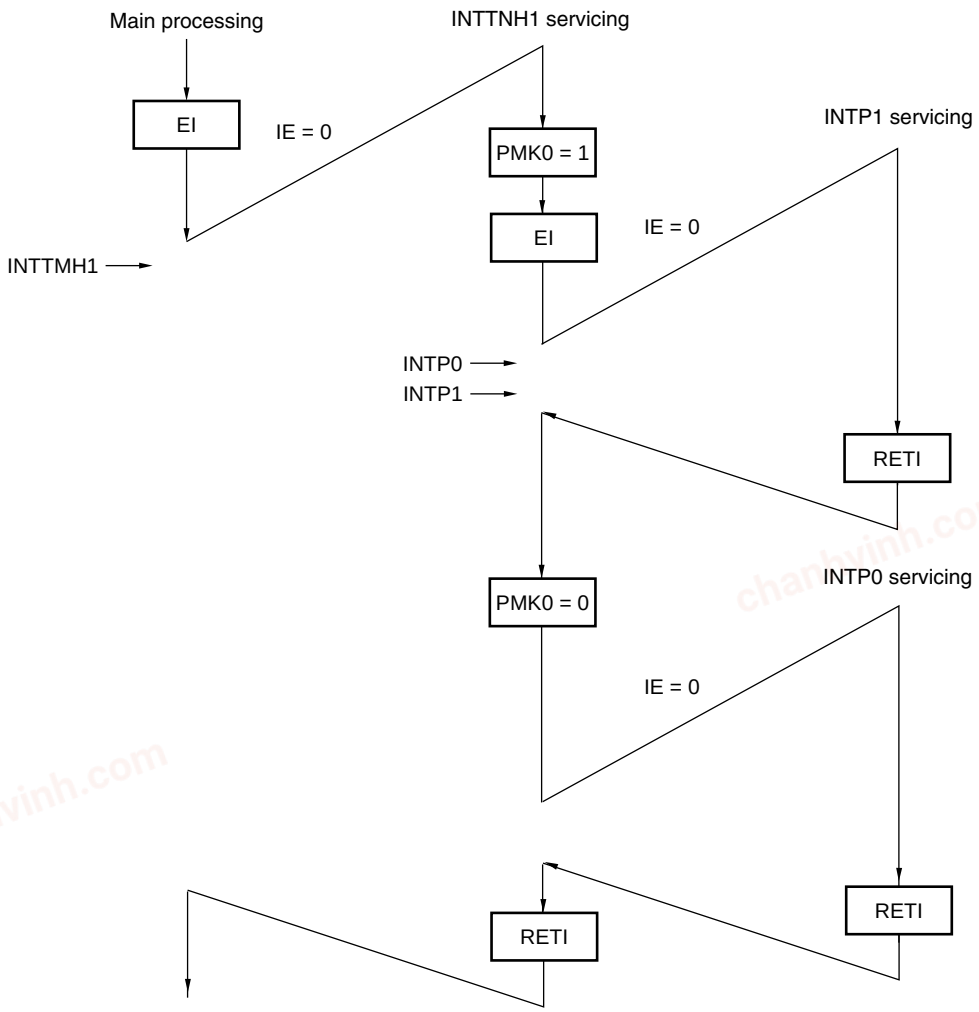
IE = 0: Interrupt request acknowledgment disabled

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Figure 10-9. Example of Multiple Interrupts (2/2)

Example 3. A priority is controlled by the multiple interrupts

The vector interrupt enable state is set for INTP0, INTP1, and INTTMH1.
(Interrupt priority INTP0 > INTP1 > INTTMH1 (refer to **Table10-1**))



In the interrupt INTTMH1 servicing, servicing is performed such that the INTP1 interrupt is given priority, since the INTP0 interrupt was first masked.

Afterwards, once the interrupt mask for INTP0 is released, INTP0 processing through multiple interrupts is performed.

IE = 0: Interrupt request acknowledgment disabled

10.4.3 Interrupt request pending

Some instructions may keep pending the acknowledgment of an instruction request until the completion of the execution of the next instruction even if the interrupt request (maskable interrupt and external interrupt) is generated during the execution. The following shows such instructions (interrupt request pending instruction).

- Manipulation instruction for interrupt request flag register 0 (IF0)
- Manipulation instruction for interrupt mask flag register 0 (MK0)

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CHAPTER 11 STANDBY FUNCTION

11.1 Standby Function and Configuration

11.1.1 Standby function

Table 11-1. Relationship Between Operation Clocks in Each Operation Status

Status / Operation Mode	Low-Speed Internal Oscillator			System Clock	Clock Supplied to Peripheral Hardware
	Note 1	**Note 2**			
		LSRSTOP = 0	LSRSTOP = 1		
Reset	Stopped			Stopped	Stopped
STOP	Oscillating	Oscillating[Note 3]	Stopped		
HALT				Oscillating	Oscillating

Notes 1. When “Cannot be stopped” is selected for low-speed internal oscillator by the option byte.

2. When it is selected that the low-speed internal oscillator “can be stopped by software”, oscillation of the low-speed internal oscillator can be stopped by LSRSTOP.

3. If the operating clock of the watchdog timer is the low-speed internal oscillation clock, the watchdog timer is stopped.

Caution The LSRSTOP setting is valid only when “Can be stopped by software” is set for the low-speed internal oscillator by the option byte.

Remark LSRSTOP: Bit 0 of the low-speed internal oscillation mode register (LSRCM)

The standby function is designed to reduce the operating current of the system. The following two modes are available.

(1) HALT mode

HALT instruction execution sets the HALT mode. In the HALT mode, the CPU operation clock is stopped. Oscillation of the system clock oscillator continues. If the low-speed internal oscillator is operating before the HALT mode is set, oscillation of the clock of the low-speed internal oscillator continues (refer to **Table 11-1**. Oscillation of the low-speed internal oscillation clock (whether it cannot be stopped or can be stopped by software) is set by the option byte). In this mode, the operating current is not decreased as much as in the STOP mode, but the HALT mode is effective for restarting operation immediately upon interrupt request generation and frequently carrying out intermittent operations.

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(2) STOP mode

STOP instruction execution sets the STOP mode. In the STOP mode, the system clock oscillator stops, stopping the whole system, thereby considerably reducing the CPU operating current.

Because this mode can be cleared by an interrupt request, it enables intermittent operations to be carried out. However, select the HALT mode if processing must be immediately started by an interrupt request when the operation stop time[Note] is generated after the STOP mode is released (because an additional wait time for stabilizing oscillation elapses when crystal/ceramic oscillation is used).

Note The operation stop time is 17 μs (MIN.), 34 μs (TYP.), and 67 μs (MAX.).

In either of these two modes, all the contents of registers, flags and data memory just before the standby mode is set are held. The I/O port output latches and output buffer statuses are also held.

Cautions 1. When shifting to the STOP mode, be sure to stop the peripheral hardware operation before executing STOP instruction (except the peripheral hardware that operates on the low-speed internal oscillation clock).

<R> **2. The following sequence is recommended for operating current reduction of the A/D converter in μPD78F921x when the standby function is used: First clear bit 7 (ADCS) and bit 0 (ADCE) of the A/D converter mode register (ADM) to 0 to stop the A/D conversion operation, and then execute the HALT or STOP instruction.**

3. If the low-speed internal oscillator is operating before the STOP mode is set, oscillation of the low-speed internal oscillation clock cannot be stopped in the STOP mode (refer to Table 11-1).

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11.1.2 Registers used during standby

The oscillation stabilization time after the standby mode is released is controlled by the oscillation stabilization time select register (OSTS).

Remark For the registers that start, stop, or select the clock, see **CHAPTER 5 CLOCK GENERATORS**.

(1) Oscillation stabilization time select register (OSTS)

This register is used to select oscillation stabilization time of the clock supplied from the oscillator when the STOP mode is released. The wait time set by OSTS is valid only when the crystal/ceramic oscillation clock is selected as the system clock and after the STOP mode is released. If the high-speed internal oscillation or external clock input is selected as the system clock source, no wait time elapses.

The system clock oscillator and the oscillation stabilization time that elapses after power application or release of reset are selected by the option byte. For details, refer to **CHAPTER 15 OPTION BYTE**.

OSTS is set by using the 8-bit memory manipulation instruction.

Figure 11-1. Format of Oscillation Stabilization Time Select Register (OSTS)

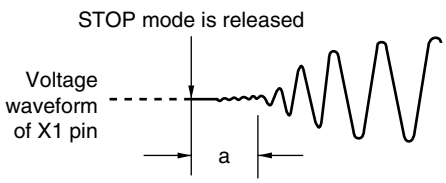
Address: FFF4H, After reset: Undefined, R/W

Symbol	7	6	5	4	3	2	1	0
OSTS	0	0	0	0	0	0	OSTS1	OSTS0

OSTS1	OSTS0	Selection of oscillation stabilization time
0	0	2^{10}/fx (102.4 μs)
0	1	2^{12}/fx (409.6 μs)
1	0	2^{15}/fx (3.27 ms)
1	1	2^{17}/fx (13.1 ms)

Cautions 1. To set and then release the STOP mode, set the oscillation stabilization time as follows. Expected oscillation stabilization time of resonator ≤ Oscillation stabilization time set by OSTS

2. The wait time after the STOP mode is released does not include the time from the release of the STOP mode to the start of clock oscillation ("a" in the figure below), regardless of whether STOP mode was released by reset signal generation or interrupt generation.



3. The oscillation stabilization time that elapses on power application or after release of reset is selected by the option byte. For details, refer to CHAPTER 15 OPTION BYTE.

Remarks 1. ( ): fx = 10 MHz

2. Determine the oscillation stabilization time of the resonator by checking the characteristics of the resonator to be used.

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11.2 Standby Function Operation

11.2.1 HALT mode

(1) HALT mode

The HALT mode is set by executing the HALT instruction.

The operating statuses in the HALT mode are shown below.

Caution Because an interrupt request signal is used to clear the standby mode, if there is an interrupt source with the interrupt request flag set and the interrupt mask flag clear, the standby mode is immediately cleared if set.

Table 11-2. Operating Statuses in HALT Mode

Setting of HALT Mode / Item		Low-Speed Internal Oscillator cannot be stopped[Note 1].	Low-Speed Internal Oscillator can be stopped[Note 1].	
			When Low-Speed Internal Oscillation Continues	When Low-Speed Internal Oscillation Stops
System clock		Clock supply to CPU is stopped.		
CPU		Operation stops.		
Port (latch)		Holds status before HALT mode was set.		
16-bit timer/event counter 00		Operable		
8-bit timer H1	Sets count clock to f_{XP} to $f_{XP}/2^{12}$	Operable		
	Sets count clock to $f_{RL}/2^{7}$	Operable	Operable	Operation stops.
Watchdog timer	"System clock" selected as operating clock	Setting disabled.	Operation stops.	
	"Low-speed internal oscillation clock" selected as operating clock	Operable (Operation continues)	Operation stops.	
A/D converter[Note 2]		Operable		
Power-on-clear circuit		Always operates.		
Low-voltage detector		Operable		
External interrupt		Operable		

Notes 1. "Cannot be stopped" or "Stopped by software" is selected for low-speed internal oscillator by the option byte (for the option byte, see **CHAPTER 15 OPTION BYTE**).

<R> **2.** μPD78F921x only

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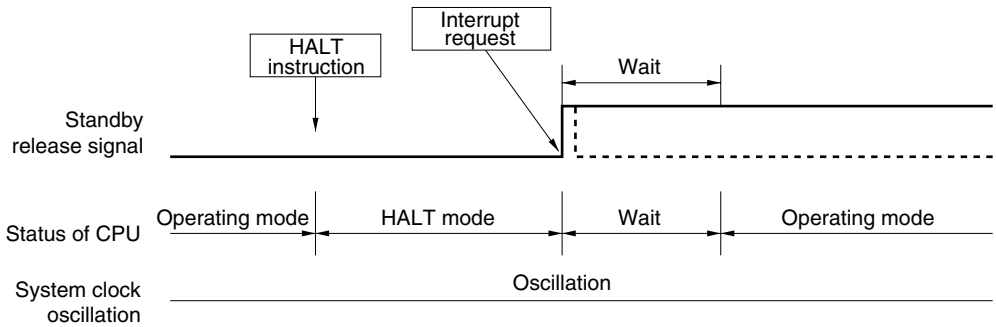
(2) HALT mode release

The HALT mode can be released by the following two sources.

(a) Release by unmasked interrupt request

When an unmasked interrupt request is generated, the HALT mode is released. If interrupt acknowledgment is enabled, vectored interrupt servicing is carried out. If interrupt acknowledgment is disabled, the next address instruction is executed.

Figure 11-2. HALT Mode Release by Interrupt Request Generation



Remarks 1. The broken lines indicate the case when the interrupt request which has released the standby mode is acknowledged.

2. The wait time is as follows:

- When vectored interrupt servicing is carried out: 11 to 13 clocks
- When vectored interrupt servicing is not carried out: 3 to 5 clocks

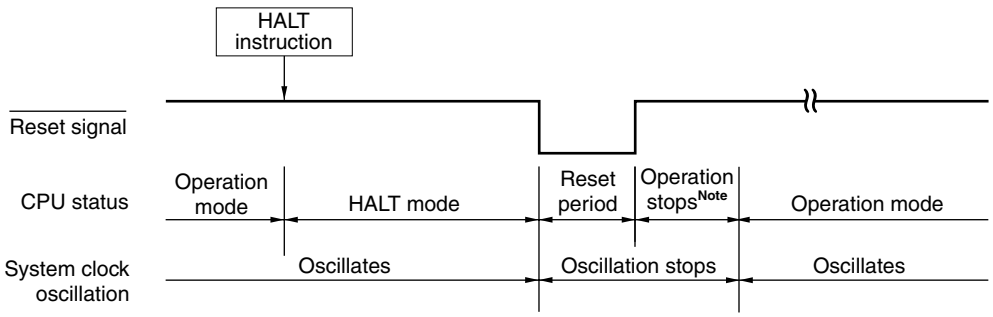
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(b) Release by reset signal generation

When the reset signal is input, HALT mode is released, and then, as in the case with a normal reset operation, the program is executed after branching to the reset vector address.

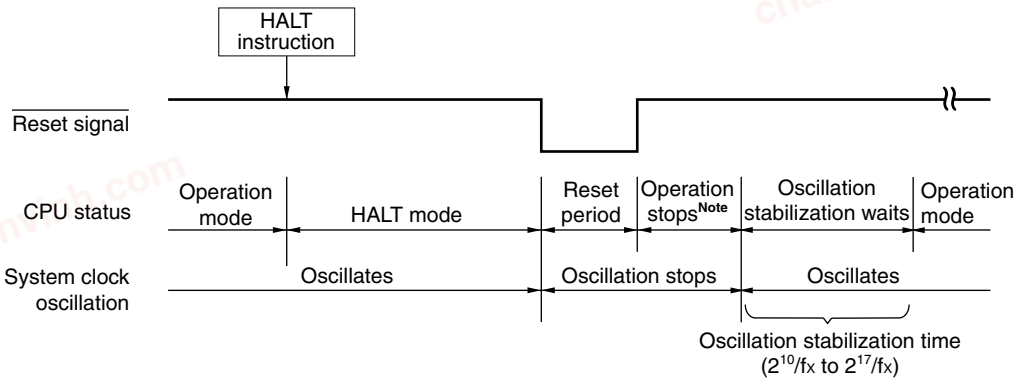
Figure 11-3. HALT Mode Release by Reset Signal Generation

(1) When CPU clock is high-speed internal oscillation clock or external input clock



Note Operation is stopped (277 μs (MIN.), 544 μs (TYP.), 1.075 ms (MAX.)) because the option byte is referenced.

(2) When CPU clock is crystal/ceramic oscillation clock



Note Operation is stopped (276 μs (MIN.), 544 μs (TYP.), 1.074 ms (MAX.)) because the option byte is referenced.

Remark fx: System clock oscillation frequency

Table 11-3. Operation in Response to Interrupt Request in HALT Mode

Release Source	MK××	IE	Operation
Maskable interrupt request	0	0	Next address instruction execution
	0	1	Interrupt servicing execution
	1	×	HALT mode held
Reset signal generation	–	×	Reset processing

×: don't care

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11.2.2 STOP mode

(1) STOP mode setting and operating statuses

The STOP mode is set by executing the STOP instruction.

Caution Because an interrupt request signal is used to clear the standby mode, if there is an interrupt source with the interrupt request flag set and the interrupt mask flag reset, the standby mode is immediately cleared if set. Thus, in the STOP mode, the normal operation mode is restored after the STOP instruction is executed and then the operation is stopped for the duration of 34 μs (TYP.) (after an additional wait time for stabilizing oscillation set by the oscillation stabilization time select register (OSTS) has elapsed when crystal/ceramic oscillation is used).

The operating statuses in the STOP mode are shown below.

Table 11-4. Operating Statuses in STOP Mode

Item \ Setting of STOP Mode		Low-Speed Internal Oscillator cannot be stopped[Note 1].	Low-Speed Internal Oscillator can be stopped[Note 1].	
			When Low-Speed Internal Oscillation Continues	When Low-Speed Internal Oscillation Stops
System clock		Oscillation stops.		
CPU		Operation stops.		
Port (latch)		Holds status before STOP mode was set.		
16-bit timer/event counter 00		Operation stops.		
8-bit timer H1	Sets count clock to f_{XP} to $f_{XP}/2^{12}$	Operation stops.		
	Sets count clock to $f_{RL}/2^{7}$	Operable	Operable	Operation stops.
Watchdog timer	“System clock” selected as operating clock	Setting disabled.	Operation stops.	
	“Low-speed internal oscillation clock” selected as operating clock	Operable (Operation continues)	Operation stops.	
A/D converter[Note 2]		Operation stops.		
Power-on-clear circuit		Always operates.		
Low-voltage detector		Operable		
External interrupt		Operable		

Notes 1. “Cannot be stopped” or “Stopped by software” is selected for low-speed internal oscillator by the option byte (for the option byte, see **CHAPTER 15 OPTION BYTE**).

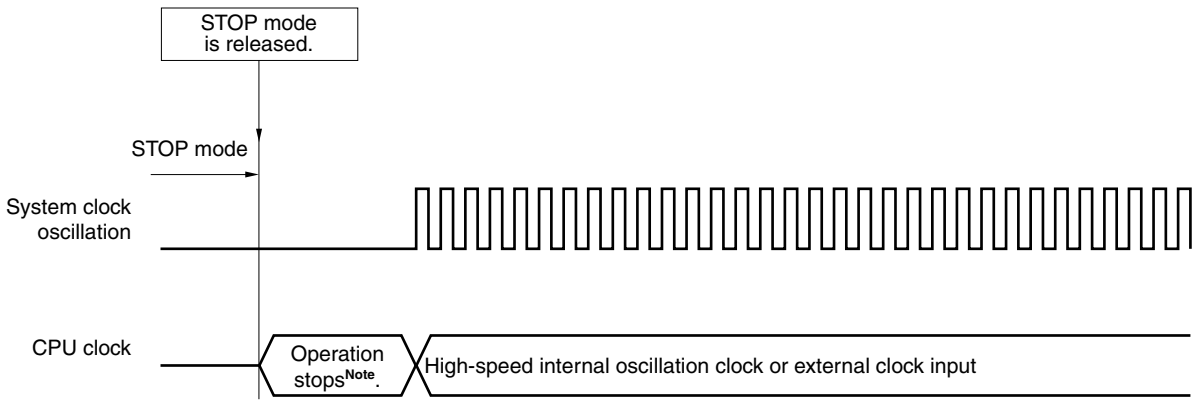
<R> **2.** μPD78F921x only

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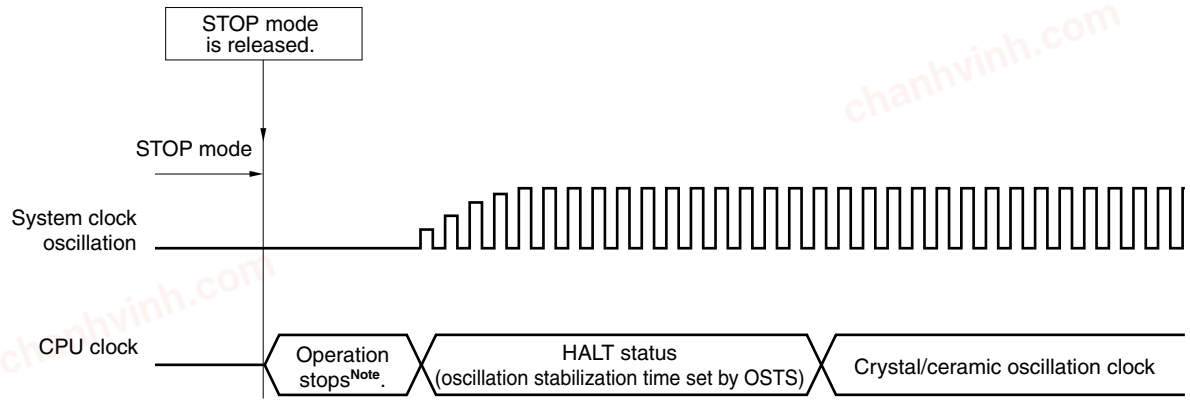
(2) STOP mode release

Figure 11-4. Operation Timing When STOP Mode Is Released

<1> If high-speed internal oscillation clock or external input clock is selected as system clock to be supplied



<2> If crystal/ceramic oscillation clock is selected as system clock to be supplied



Note The operation stop time is 17 μs (MIN.), 34 μs (TYP.), and 67 μs (MAX.).

The STOP mode can be released by the following two sources.

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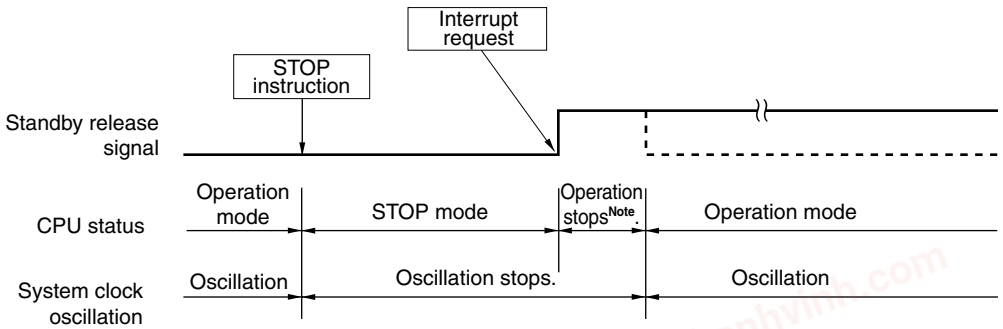
(a) Release by unmasked interrupt request

When an unmasked interrupt request (8-bit timer H1[Note], low-voltage detector, external interrupt request) is generated, the STOP mode is released. After the oscillation stabilization time has elapsed, if interrupt acknowledgment is enabled, vectored interrupt servicing is carried out. If interrupt acknowledgment is disabled, the next address instruction is executed.

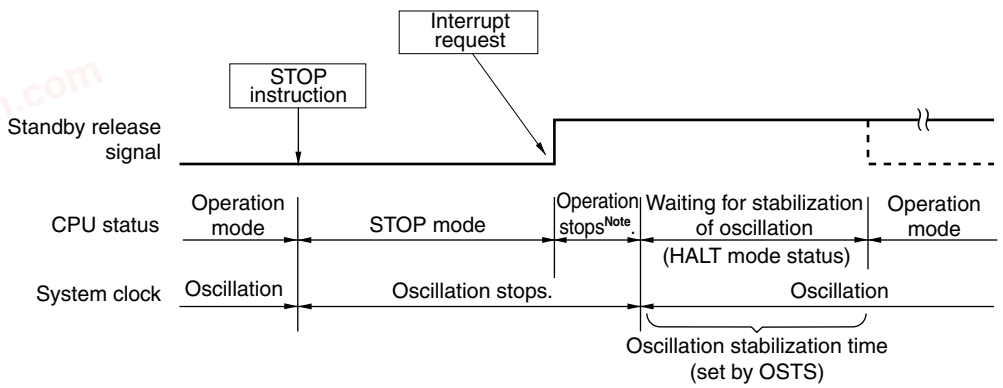
Note Only when sets count clock to $f_{RL}/2^7$

Figure 11-5. STOP Mode Release by Interrupt Request Generation

(1) If CPU clock is high-speed internal oscillation clock or external input clock



(2) If CPU clock is crystal/ceramic oscillation clock



Note The operation stop time is 17 μs (MIN.), 34 μs (TYP.), and 67 μs (MAX.).

Remark The broken lines indicate the case when the interrupt request that has released the standby mode is acknowledged.

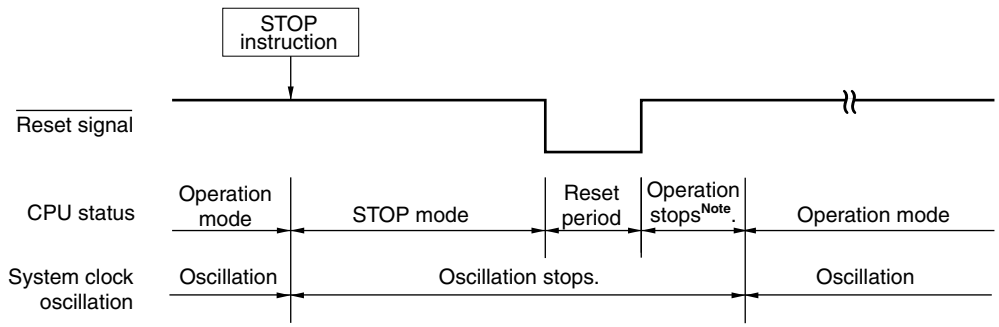
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(b) Release by reset signal generation

When the reset signal is input, STOP mode is released and a reset operation is performed after the oscillation stabilization time has elapsed.

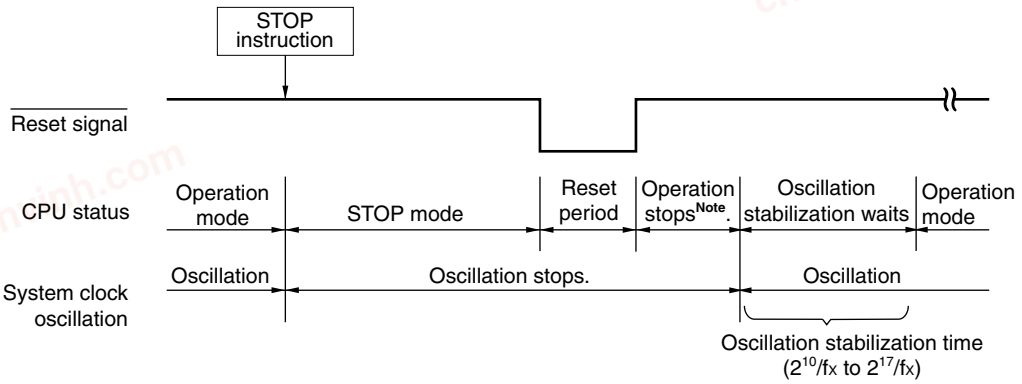
Figure 11-6. STOP Mode Release by Reset signal generation

(1) If CPU clock is high-speed internal oscillation clock or external input clock



Note Operation is stopped (277 μs (MIN.), 544 μs (TYP.), 1.075 ms (MAX.)) because the option byte is referenced.

(2) If CPU clock is crystal/ceramic oscillation clock



Note Operation is stopped (276 μs (MIN.), 544 μs (TYP.), 1.074 ms (MAX.)) because the option byte is referenced.

Remark fx: System clock oscillation frequency

Table 11-5. Operation in Response to Interrupt Request in STOP Mode

Release Source	MK××	IE	Operation
Maskable interrupt request	0	0	Next address instruction execution
	0	1	Interrupt servicing execution
	1	×	STOP mode held
Reset signal generation	–	×	Reset processing

×: don't care

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CHAPTER 12 RESET FUNCTION

The following four operations are available to generate a reset signal.

(1) External reset input via $\overline{\text{RESET}}$ pin
(2) Internal reset by watchdog timer overflows
(3) Internal reset by comparison of supply voltage and detection voltage of power-on-clear (POC) circuit
(4) Internal reset by comparison of supply voltage and detection voltage of low-power-supply detector (LVI)

External and internal resets have no functional differences. In both cases, program execution starts from the programs at the address written in addresses 0000H and 0001H when the reset signal is generated.

A reset is applied when a low level is input to the $\overline{\text{RESET}}$ pin, the watchdog timer overflows, or by POC and LVI circuit voltage detection, and each item of hardware is set to the status shown in Table 14-1. Each pin is high impedance during reset signal generation or during the oscillation stabilization time just after reset release, except for P130, which is low-level output.

When a low level is input to the $\overline{\text{RESET}}$ pin, a reset occurs, and when a high level is input to the $\overline{\text{RESET}}$ pin, the reset is released and the CPU starts program execution after referencing the option byte (after the option byte is referenced and the clock oscillation stabilization time elapses if crystal/ceramic oscillation is selected). A reset generated by the watchdog timer source is automatically released after the reset, and the CPU starts program execution after referencing the option byte (after the option byte is referenced and the clock oscillation stabilization time elapses if crystal/ceramic oscillation is selected). (see **Figures 12-2** to **12-4**). Reset by POC and LVI circuit power supply detection is automatically released when $V_{DD} > V_{POC}$ or $V_{DD} > V_{LVI}$ after the reset, and the CPU starts program execution after referencing the option byte (after the option byte is referenced and the clock oscillation stabilization time elapses if crystal/ceramic oscillation is selected) (see **CHAPTER 13 POWER-ON-CLEAR CIRCUIT** and **CHAPTER 14 LOW-VOLTAGE DETECTOR**).

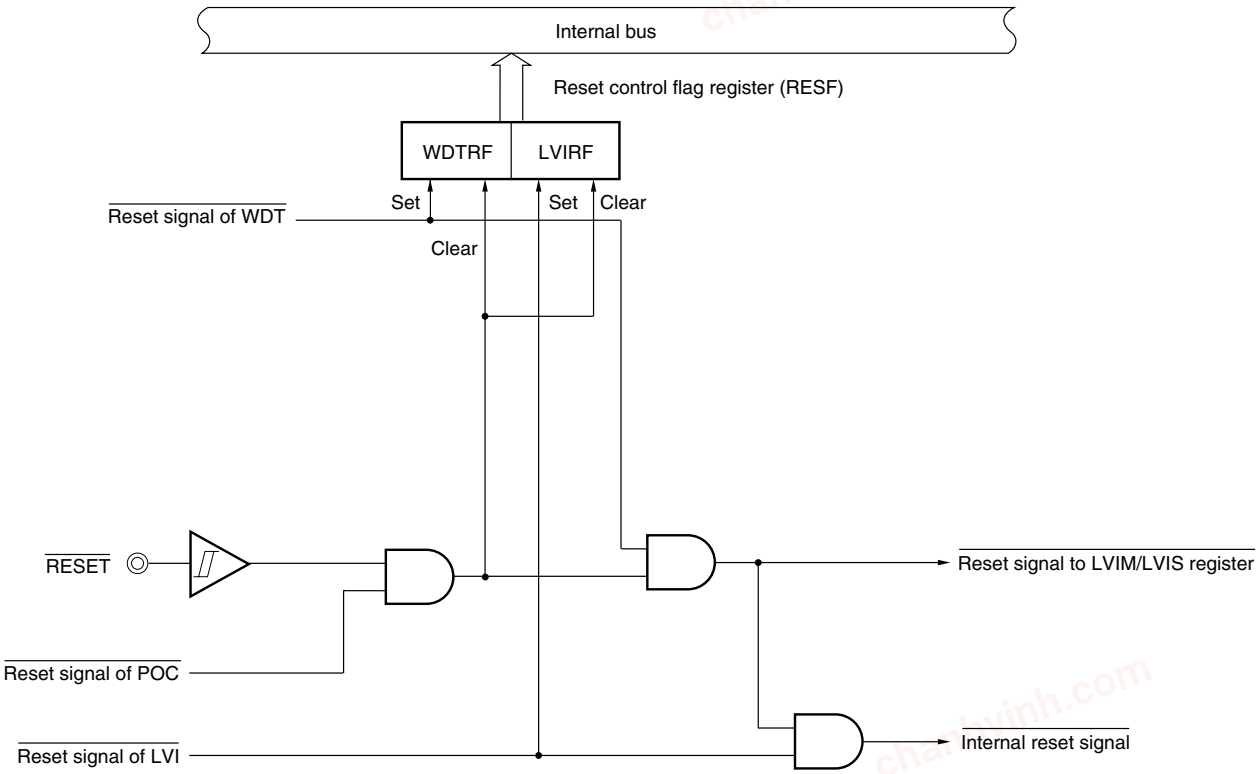
Cautions 1. For an external reset, input a low level for 2 μs or more to the $\overline{\text{RESET}}$ pin.

2. During reset signal generation, the system clock and low-speed internal oscillation clock stop oscillating.

3. When the $\overline{\text{RESET}}$ pin is used as an input-only port pin (P34), the 78K0S/KY1+ is reset if a low level is input to the $\overline{\text{RESET}}$ pin after reset is released by the POC circuit, the LVI circuit and the watchdog timer and before the option byte is referenced again. The reset status is retained until a high level is input to the $\overline{\text{RESET}}$ pin.

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Figure 12-1. Block Diagram of Reset Function



Caution The LVI circuit is not reset by the internal reset signal of the LVI circuit.

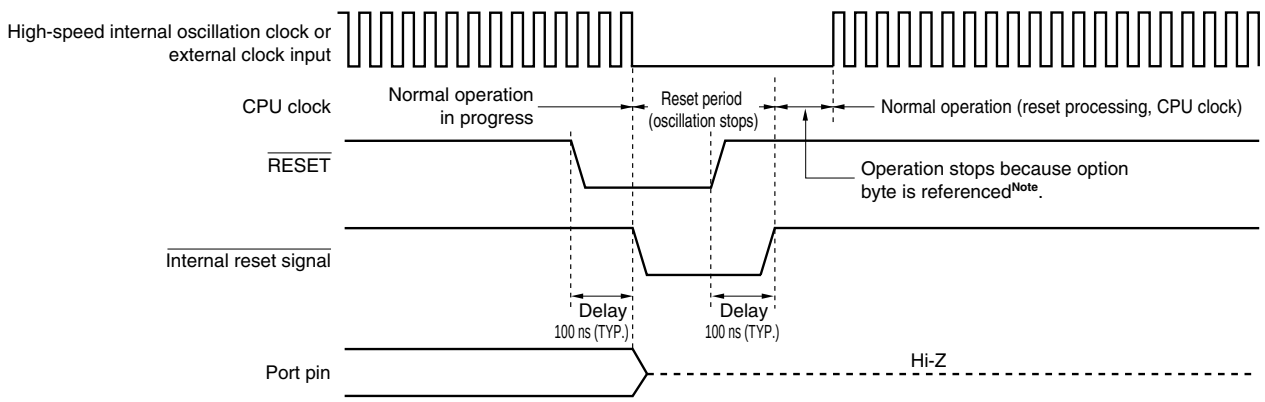
Remarks 1. LVIM: Low-voltage detect register

2. LVIS: Low-voltage detection level select register

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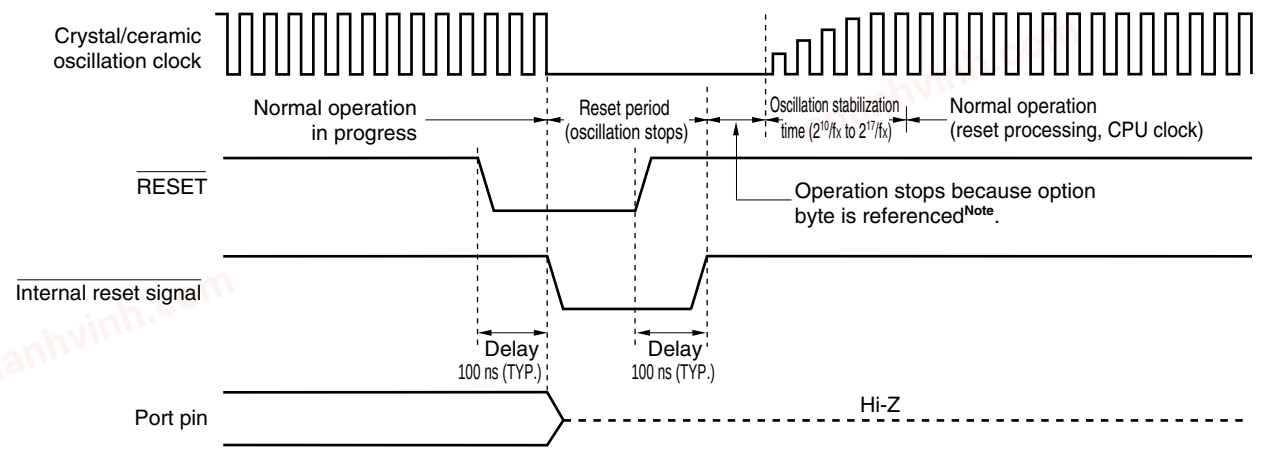
Figure 12-2. Timing of Reset by $\overline{\text{RESET}}$ Input

<1> With high-speed internal oscillation clock or external clock input



Note The operation stop time is 277 μs (MIN.), 544 μs (TYP.), and 1.075 ms (MAX.).

<2> With crystal/ceramic oscillation clock



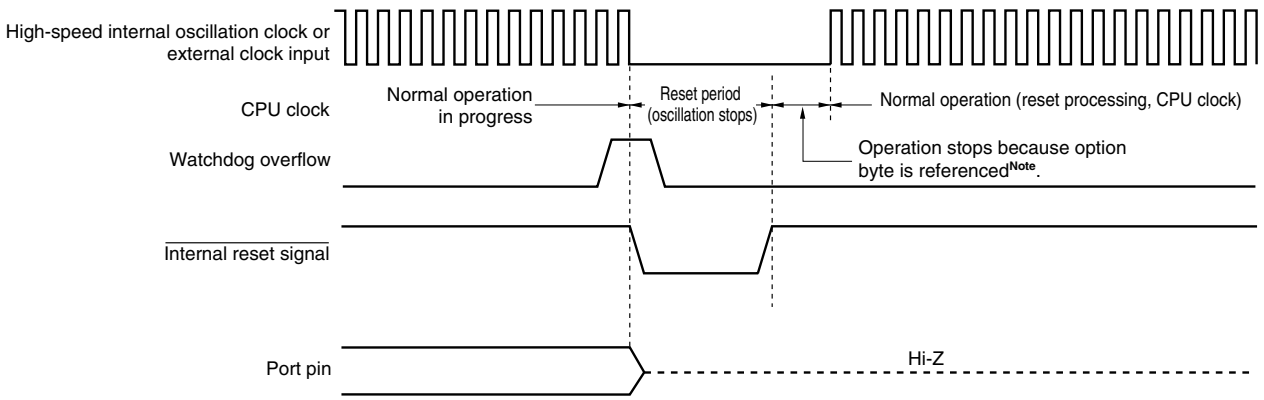
Note The operation stop time is 276 μs (MIN.), 544 μs (TYP.), and 1.074 ms (MAX.).

Remark fx: System clock oscillation frequency

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Figure 12-3. Timing of Reset by Overflow of Watchdog Timer

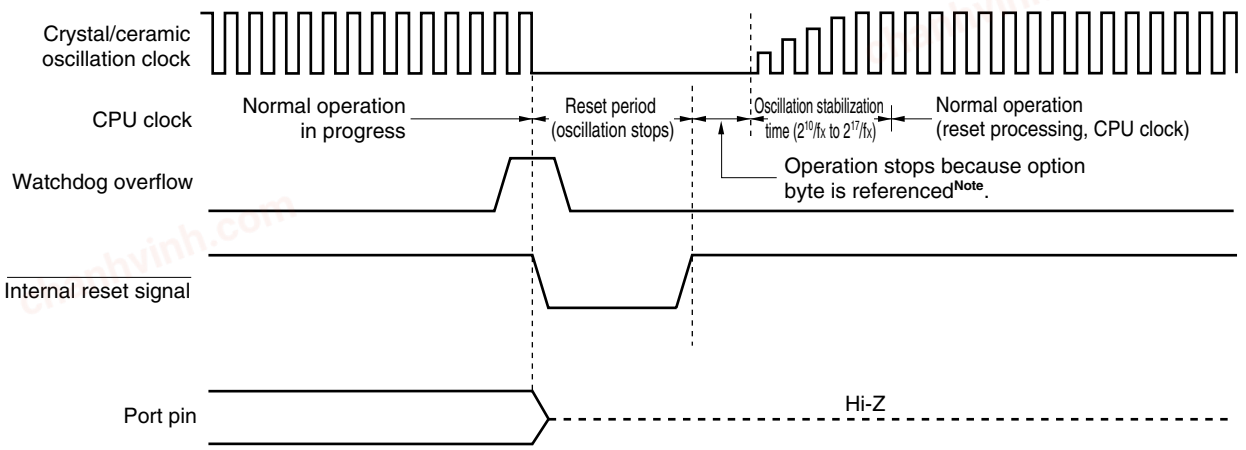
<1> With high-speed internal oscillation clock or external clock input



Note The operation stop time is 277 μs (MIN.), 544 μs (TYP.), and 1.075 ms (MAX.).

Caution The watchdog timer is also reset in the case of an internal reset of the watchdog timer.

<2> With crystal/ceramic oscillation clock



Note The operation stop time is 276 μs (MIN.), 544 μs (TYP.), and 1.074 ms (MAX.).

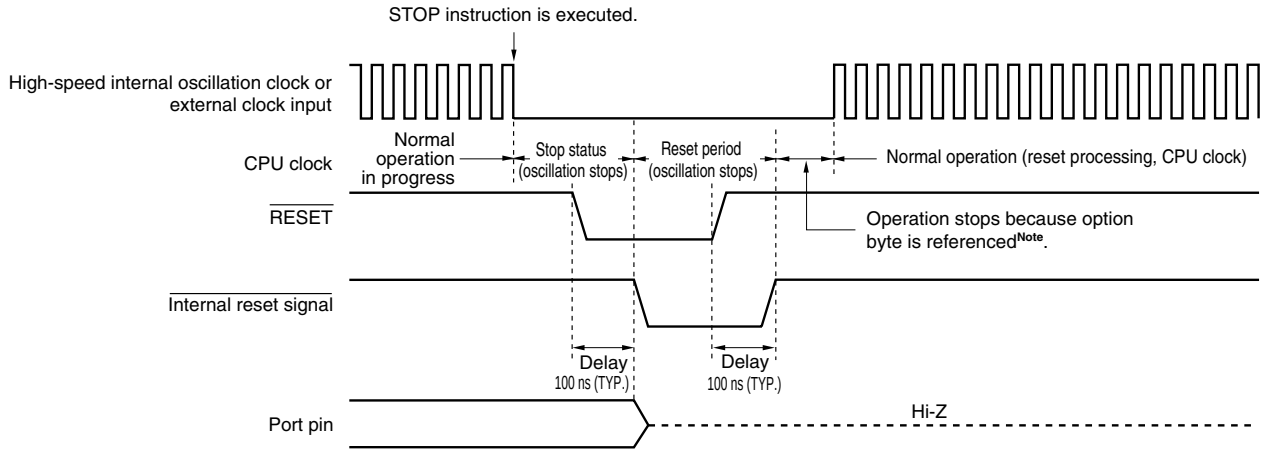
Caution The watchdog timer is also reset in the case of an internal reset of the watchdog timer.

Remark fx: System clock oscillation frequency

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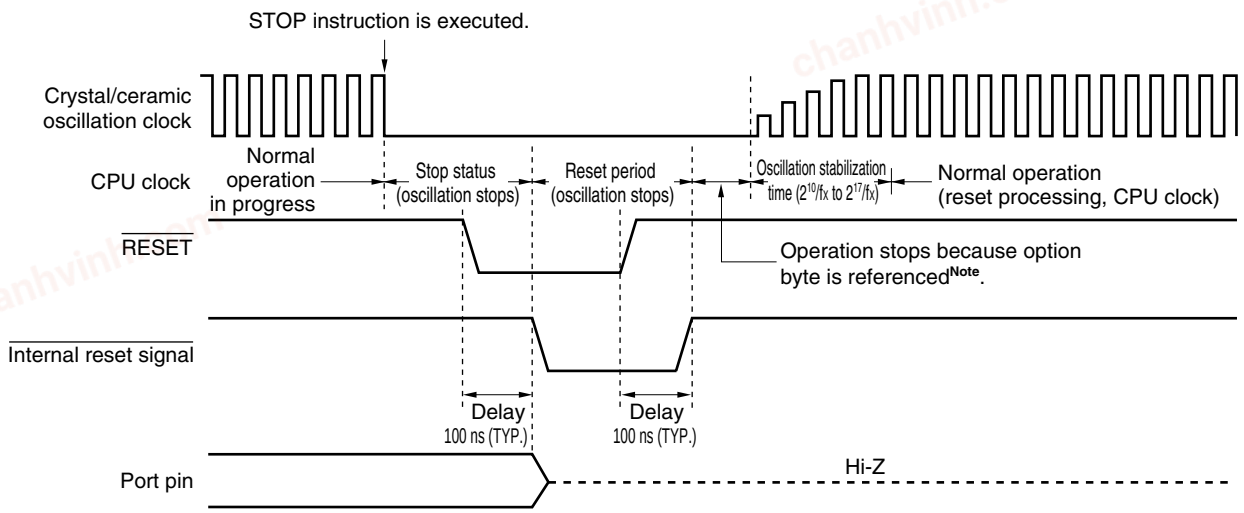
Figure 12-4. Reset Timing by $\overline{\text{RESET}}$ Input in STOP Mode

<1> With high-speed internal oscillation clock or external clock input



Note The operation stop time is 277 μs (MIN.), 544 μs (TYP.), and 1.075 ms (MAX.).

<2> With crystal/ceramic oscillation clock



Note The operation stop time is 276 μs (MIN.), 544 μs (TYP.), and 1.074 ms (MAX.).

Remarks 1. For the reset timing of the power-on-clear circuit and low-voltage detector, refer to **CHAPTER 13 POWER-ON-CLEAR CIRCUIT** and **CHAPTER 14 LOW-VOLTAGE DETECTOR**.

2. fx: System clock oscillation frequency

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Table 12-1. Hardware Statuses After Reset Acknowledgment (1/2)

Hardware		Status After Reset
Program counter (PC) Note 1		Contents of reset vector table (0000H and 0001H) are set.
Stack pointer (SP)		Undefined
Program status word (PSW)		02H
RAM	Data memory	Undefined Note 2
	General-purpose registers	Undefined Note 2
Ports (P2 to P4) (output latches)		00H
Port mode registers (PM2 to PM4)		FFH
Port mode control register (PMC2) Note 3		00H
Pull-up resistor option registers (PU2 to PU4)		00H
Processor clock control register (PCC)		02H
Preprocessor clock control register (PPCC)		02H
Low-speed internal oscillation mode register (LSRCM)		00H
Oscillation stabilization time select register (OSTS)		Undefined
16-bit timer 00	Timer counter 00 (TM00)	0000H
	Capture/compare registers 000, 010 (CR000, CR010)	0000H
	Mode control register 00 (TMC00)	00H
	Prescaler mode register 00 (PRM00)	00H
	Capture/compare control register 00 (CRC00)	00H
	Timer output control register 00 (TOC00)	00H
8-bit timer H1	Compare registers (CMP01, CMP11)	00H
	Mode register 1 (TMHMD1)	00H
Watchdog timer	Mode register (WDTM)	67H
	Enable register (WDTE)	9AH
A/D converter Note 3	Conversion result registers (ADCR, ADCRH)	Undefined
	Mode register (ADM)	00H
	Analog input channel specification register (ADS)	00H

Notes 1. Only the contents of PC are undefined while reset signal generation and while the oscillation stabilization time elapses. The statuses of the other hardware units remain unchanged.

2. The status after reset is held in the standby mode.

<R> **3.** μPD78F921x only

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Table 12-1. Hardware Statuses After Reset Acknowledgment (2/2)

Hardware		Status After Reset
Reset function	Reset control flag register (RESF)	00H[Note]
Low-voltage detector	Low-voltage detection register (LVIM)	00H[Note]
	Low-voltage detection level select register (LVIS)	00H[Note]
Interrupt	Request flag registers (IF0)	00H
	Mask flag registers (MK0)	FFH
	External interrupt mode registers (INTM0)	00H
Flash memory	Flash protect command register (PFCMD)	Undefined
	Flash status register (PFS)	00H
	Flash programming mode control register (FLPMC)	Undefined
	Flash programming command register (FLCMD)	00H
	Flash address pointer L (FLAPL)	Undefined
	Flash address pointer H (FLAPH)	
	Flash address pointer H compare register (FLAPHC)	00H
	Flash address pointer L compare register (FLAPLC)	00H
	Flash write buffer register (FLW)	00H

Note These values change as follows depending on the reset source.

Register \ Reset Source		$\overline{\text{RESET}}$ Input	Reset by POC	Reset by WDT	Reset by LVI
RESF	WDTRF	Cleared (0)	Cleared (0)	Set (1)	Held
	LVIRF			Held	Set (1)
LVIM		Cleared (00H)	Cleared (00H)	Cleared (00H)	Held
LVIS					

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12.1 Register for Confirming Reset Source

Many internal reset generation sources exist in the 78K0S/KY1+. The reset control flag register (RESF) is used to store which source has generated the reset request.

RESF can be read by an 8-bit memory manipulation instruction.

$\overline{\text{RESET}}$ input, reset signal generation by power-on-clear (POC) circuit, and reading RESF clear RESF to 00H.

Figure 12-5. Format of Reset Control Flag Register (RESF)

Address: FF54H After reset: 00H[Note] R

Symbol	7	6	5	4	3	2	1	0
RESF	0	0	0	WDTRF	0	0	0	LVIRF

WDTRF	Internal reset request by watchdog timer (WDT)
0	Internal reset request is not generated, or RESF is cleared.
1	Internal reset request is generated.

LVIRF	Internal reset request by low-voltage detector (LVI)
0	Internal reset request is not generated, or RESF is cleared.
1	Internal reset request is generated.

Note The value after reset varies depending on the reset source.

Caution Do not read data by a 1-bit memory manipulation instruction.

The status of RESF when a reset request is generated is shown in Table 12-2.

Table 12-2. RESF Status When Reset Request Is Generated

Flag \ Reset Source	$\overline{\text{RESET}}$ Input	Reset by POC	Reset by WDT	Reset by LVI
WDTRF	Cleared (0)	Cleared (0)	Set (1)	Held
LVIRF			Held	Set (1)

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CHAPTER 13 POWER-ON-CLEAR CIRCUIT

13.1 Functions of Power-on-Clear Circuit

The power-on-clear circuit (POC) has the following functions.

- Generates internal reset signal at power on.
- Compares supply voltage (V_{DD}) and detection voltage (V_{POC} = 2.1 V (TYP.)), and generates internal reset signal when $V_{DD} < V_{POC}$.
- Compares supply voltage (V_{DD}) and detection voltage (V_{POC} = 2.1 V (TYP.)), and releases internal reset signal when $V_{DD} \geq V_{POC}$.

Cautions 1. If an internal reset signal is generated in the POC circuit, the reset control flag register (RESF) is cleared to 00H.

2. Use these products in the following voltage range because the detection voltage (V_{POC}) of the POC circuit is the supply voltage range.
Standard product, (A) grade product: 2.2 to 5.5 V, (A2) grade product: 2.26 to 5.5 V

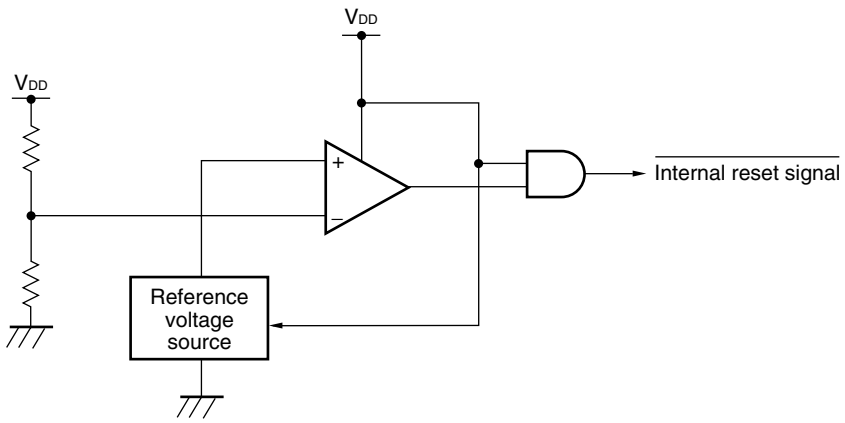
Remark This product incorporates multiple hardware functions that generate an internal reset signal. A flag that indicates the reset cause is located in the reset control flag register (RESF) for when an internal reset signal is generated by the watchdog timer (WDT) or low-voltage-detection (LVI) circuit. RESF is not cleared to 00H and the flag is set to 1 when an internal reset signal is generated by WDT or LVI.
For details of RESF, see **CHAPTER 12 RESET FUNCTION**.

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13.2 Configuration of Power-on-Clear Circuit

The block diagram of the power-on-clear circuit is shown in Figure 13-1.

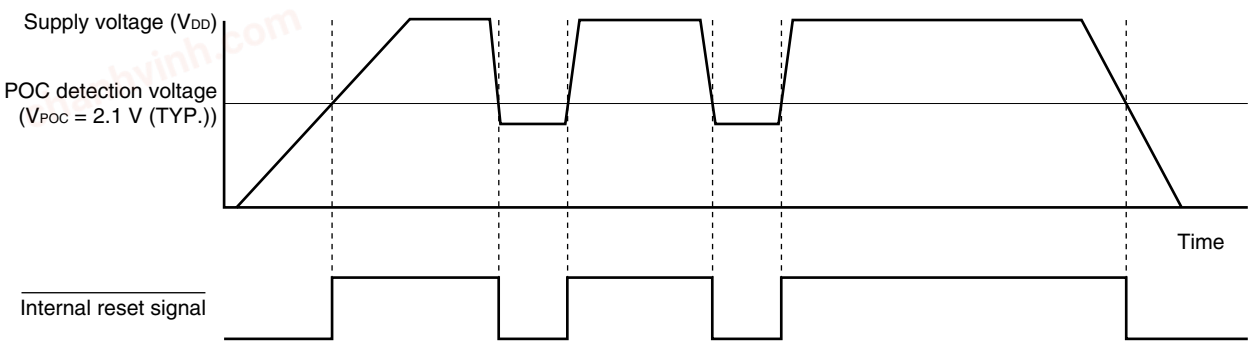
Figure 13-1. Block Diagram of Power-on-Clear Circuit



13.3 Operation of Power-on-Clear Circuit

In the power-on-clear circuit, the supply voltage (V_{DD}) and detection voltage (V_{POC} = 2.1 V (TYP.)) are compared, and an internal reset signal is generated when $V_{DD} < V_{POC}$, and an internal reset is released when $V_{DD} \geq V_{POC}$.

Figure 13-2. Timing of Internal Reset Signal Generation in Power-on-Clear Circuit



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13.4 Cautions for Power-on-Clear Circuit

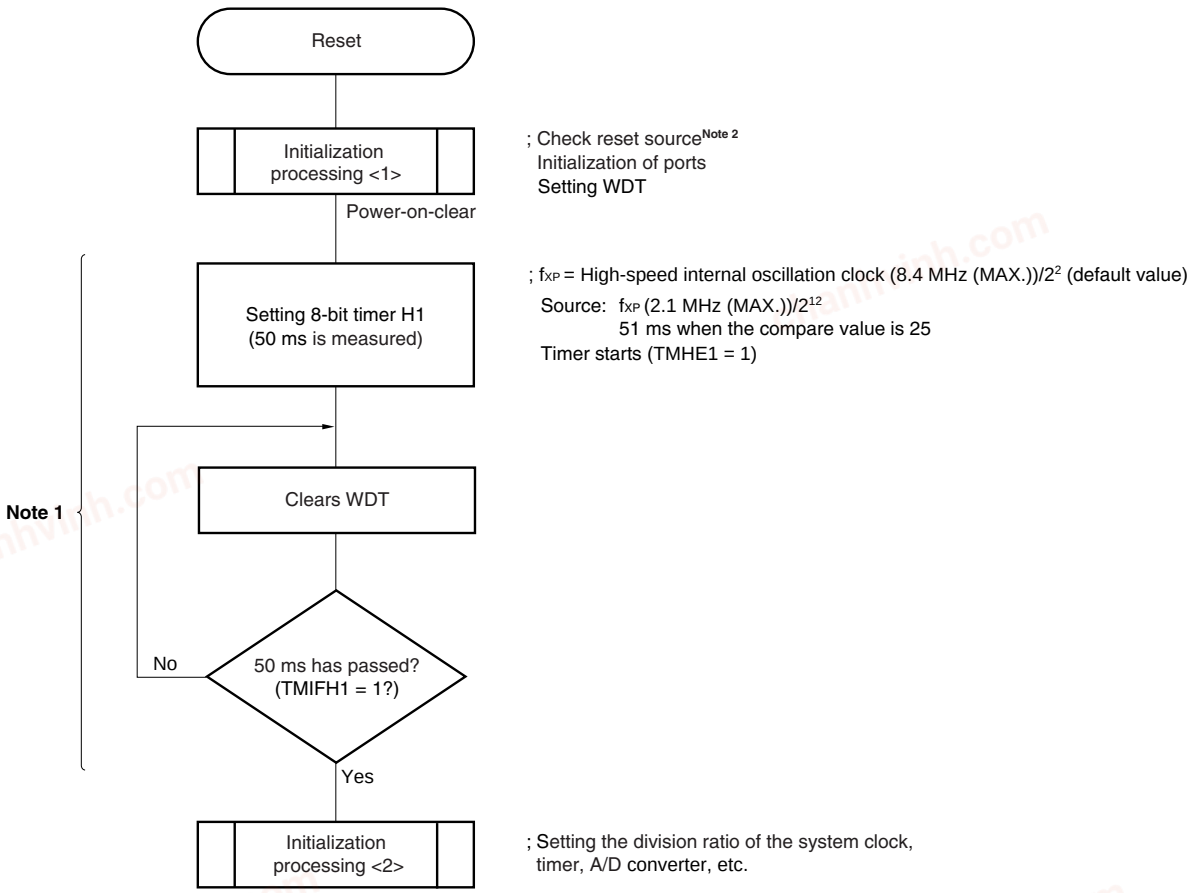
In a system where the supply voltage (V_{DD}) fluctuates for a certain period in the vicinity of the POC detection voltage (V_{POC}), the system may be repeatedly reset and released from the reset status. In this case, the time from release of reset to the start of the operation of the microcontroller can be arbitrarily set by taking the following action.

<Action>

After releasing the reset signal, wait for the supply voltage fluctuation period of each system by means of a software counter that uses a timer, and then initialize the ports.

Figure 13-3. Example of Software Processing After Release of Reset (1/2)

• If supply voltage fluctuation is 50 ms or less in vicinity of POC detection voltage



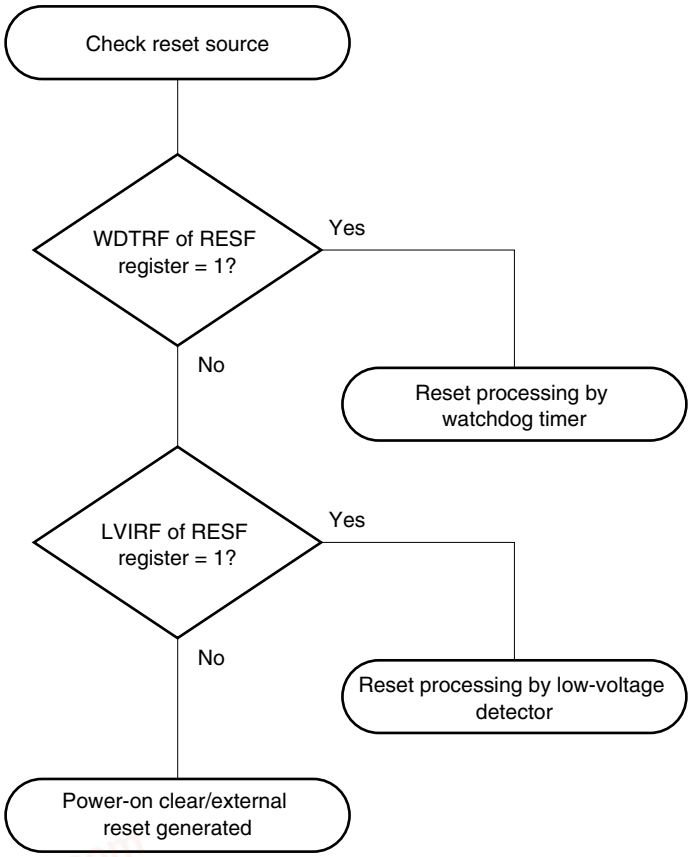
Notes 1. If reset is generated again during this period, initialization processing <2> is not started.

2. A flowchart is shown on the next page.

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Figure 13-3. Example of Software Processing After Release of Reset (2/2)

• Checking reset cause



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CHAPTER 14 LOW-VOLTAGE DETECTOR

14.1 Functions of Low-Voltage Detector

The low-voltage detector (LVI) has following functions.

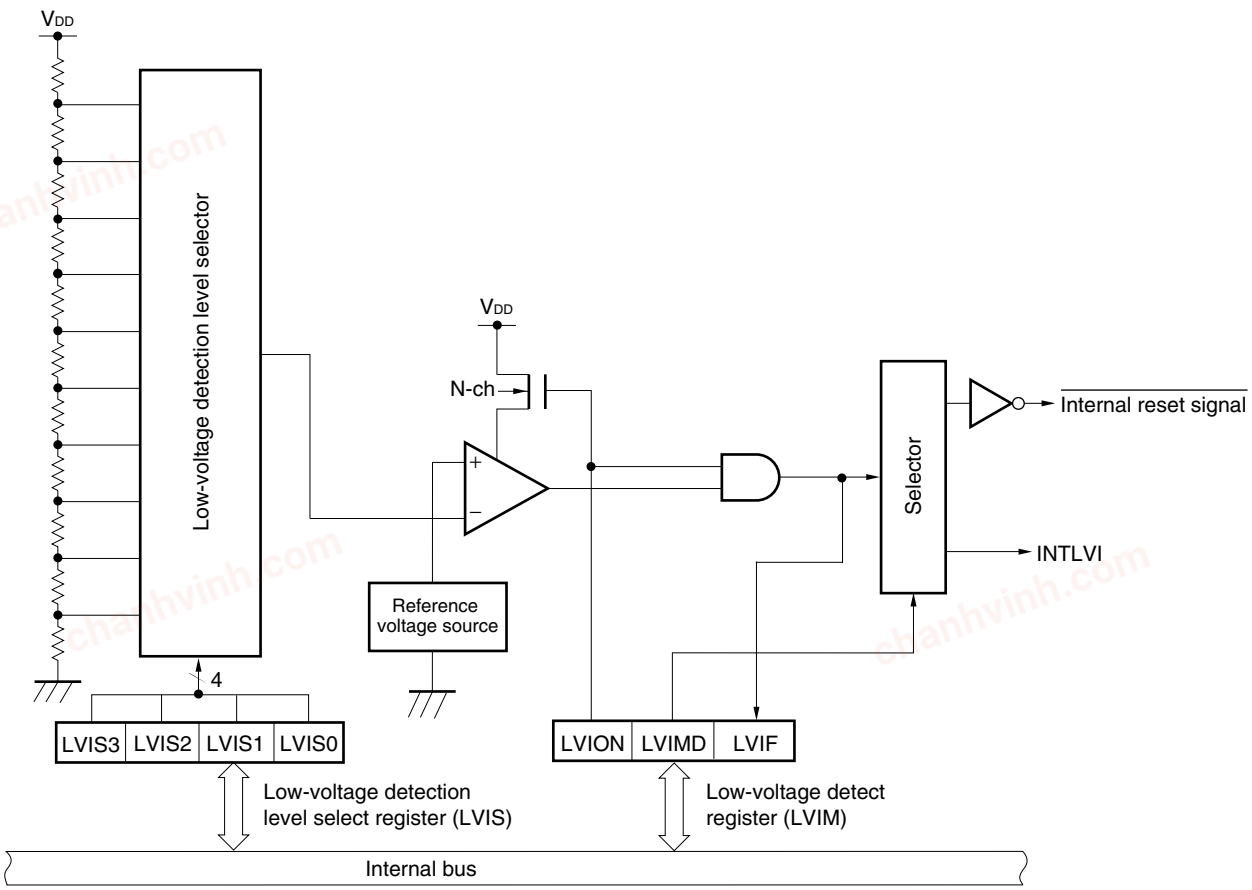
- Compares supply voltage (V_{DD}) and detection voltage (V_{LVI}), and generates an internal interrupt signal or internal reset signal when $V_{DD} < V_{LVI}$.
- Detection levels (ten levels) of supply voltage can be changed by software.
- Interrupt or reset function can be selected by software.
- Operable in STOP mode.

When the low-voltage detector is used to reset, bit 0 (LVIRF) of the reset control flag register (RESF) is set to 1 if reset occurs. For details of RESF, refer to **CHAPTER 12 RESET FUNCTION**.

14.2 Configuration of Low-Voltage Detector

The block diagram of the low-voltage detector is shown in Figure 14-1.

Figure 14-1. Block Diagram of Low-Voltage Detector



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14.3 Registers Controlling Low-Voltage Detector

The low-voltage detector is controlled by the following registers.

- Low-voltage detect register (LVIM)
- Low-voltage detection level select register (LVIS)

(1) Low-voltage detect register (LVIM)

This register sets low-voltage detection and the operation mode.

This register can be set by a 1-bit or 8-bit memory manipulation instruction.

Reset signal generation clears this register to 00H[Note 1].

Figure 14-2. Format of Low-Voltage Detect Register (LVIM)

Address: FF50H After reset: 00H[Note 1] R/W[Note 2]

Symbol	<7>	6	5	4	3	2	<1>	<0>
LVIM	LVION	0	0	0	0	0	LVIMD	LVIF

LVION[Note 3]	Enabling low-voltage detection operation
0	Disable operation
1	Enable operation

LVIMD	Low-voltage detection operation mode selection
0	Generate interrupt signal when supply voltage (V_{DD}) < detection voltage (V_{LVI})
1	Generate internal reset signal when supply voltage (V_{DD}) < detection voltage (V_{LVI})

LVIF[Note 4]	Low-voltage detection flag
0	Supply voltage (V_{DD}) ≥ detection voltage (V_{LVI}), or when operation is disabled
1	Supply voltage (V_{DD}) < detection voltage (V_{LVI})

Notes 1. For a reset by LVI, the value of LVIM is not initialized.

2. Bit 0 is a read-only bit.

3. When LVION is set to 1, operation of the comparator in the LVI circuit is started. Use software to instigate a wait of at least 0.2 ms from when LVION is set to 1 until the voltage is confirmed at LVIF.

4. The value of LVIF is output as the interrupt request signal INTLVI when LVION = 1 and LVIMD = 0.

Cautions 1. To stop LVI, follow either of the procedures below.

- **When using 8-bit manipulation instruction: Write 00H to LVIM.**
- **When using 1-bit memory manipulation instruction: Clear LVION to 0.**

2. Be sure to set bits 2 to 6 to 0.

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(2) Low-voltage detection level select register (LVIS)

This register selects the low-voltage detection level.

This register can be set by an 8-bit memory manipulation instruction.

Reset signal generation clears this register to 00H[Note].

Figure 14-3. Format of Low-Voltage Detection Level Select Register (LVIS)

Address: FF51H, After reset: 00H[Note] R/W

Symbol	7	6	5	4	3	2	1	0
LVIS	0	0	0	0	LVIS3	LVIS2	LVIS1	LVIS0

LVIS3	LVIS2	LVIS1	LVIS0	Detection level
0	0	0	0	V_{LVI0} (4.3 V ±0.2 V)
0	0	0	1	V_{LVI1} (4.1 V ±0.2 V)
0	0	1	0	V_{LVI2} (3.9 V ±0.2 V)
0	0	1	1	V_{LVI3} (3.7 V ±0.2 V)
0	1	0	0	V_{LVI4} (3.5 V ±0.2 V)
0	1	0	1	V_{LVI5} (3.3 V ±0.15 V)
0	1	1	0	V_{LVI6} (3.1 V ±0.15 V)
0	1	1	1	V_{LVI7} (2.85 V ±0.15 V)
1	0	0	0	V_{LVI8} (2.6 V ±0.1 V)
1	0	0	1	V_{LVI9} (2.35 V ±0.1 V)
Other than above				Setting prohibited

Note For a reset by LVI, the value of LVIS is not initialized.

Cautions 1. Bits 4 to 7 must be set to 0.

2. If a value other than the above is written during LVI operation, the value becomes undefined at the very moment it is written, and thus be sure to stop LVI (bit 7 of LVIM register (LVION) = 0) before writing.

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14.4 Operation of Low-Voltage Detector

The low-voltage detector can be used in the following two modes.

- Used as reset
  Compares the supply voltage (V_{DD}) and detection voltage (V_{LVI}), and generates an internal reset signal when $V_{DD} < V_{LVI}$, and releases internal reset when $V_{DD} \geq V_{LVI}$.

- Used as interrupt
  Compares the supply voltage (V_{DD}) and detection voltage (V_{LVI}), and generates an interrupt signal (INTLVI) when $V_{DD} < V_{LVI}$.

The operation is set as follows.

(1) When used as reset

- When starting operation

<1> Mask the LVI interrupt (LVIMK = 1).

<2> Set the detection voltage using bits 3 to 0 (LVIS3 to LVIS0) of the low-voltage detection level select register (LVIS).

<3> Set bit 7 (LVION) of LVIM to 1 (enables LVI operation).

<4> Use software to instigate a wait of at least 0.2 ms.

<5> Wait until "supply voltage (V_{DD}) ≥ detection voltage (V_{LVI})" at bit 0 (LVIF) of LVIM is confirmed.

<6> Set bit 1 (LVIMD) of LVIM to 1 (generates internal reset signal when supply voltage (V_{DD}) < detection voltage (V_{LVI})).

Figure 14-4 shows the timing of generating the internal reset signal of the low-voltage detector. Numbers <1> to <6> in this figure correspond to <1> to <6> above.

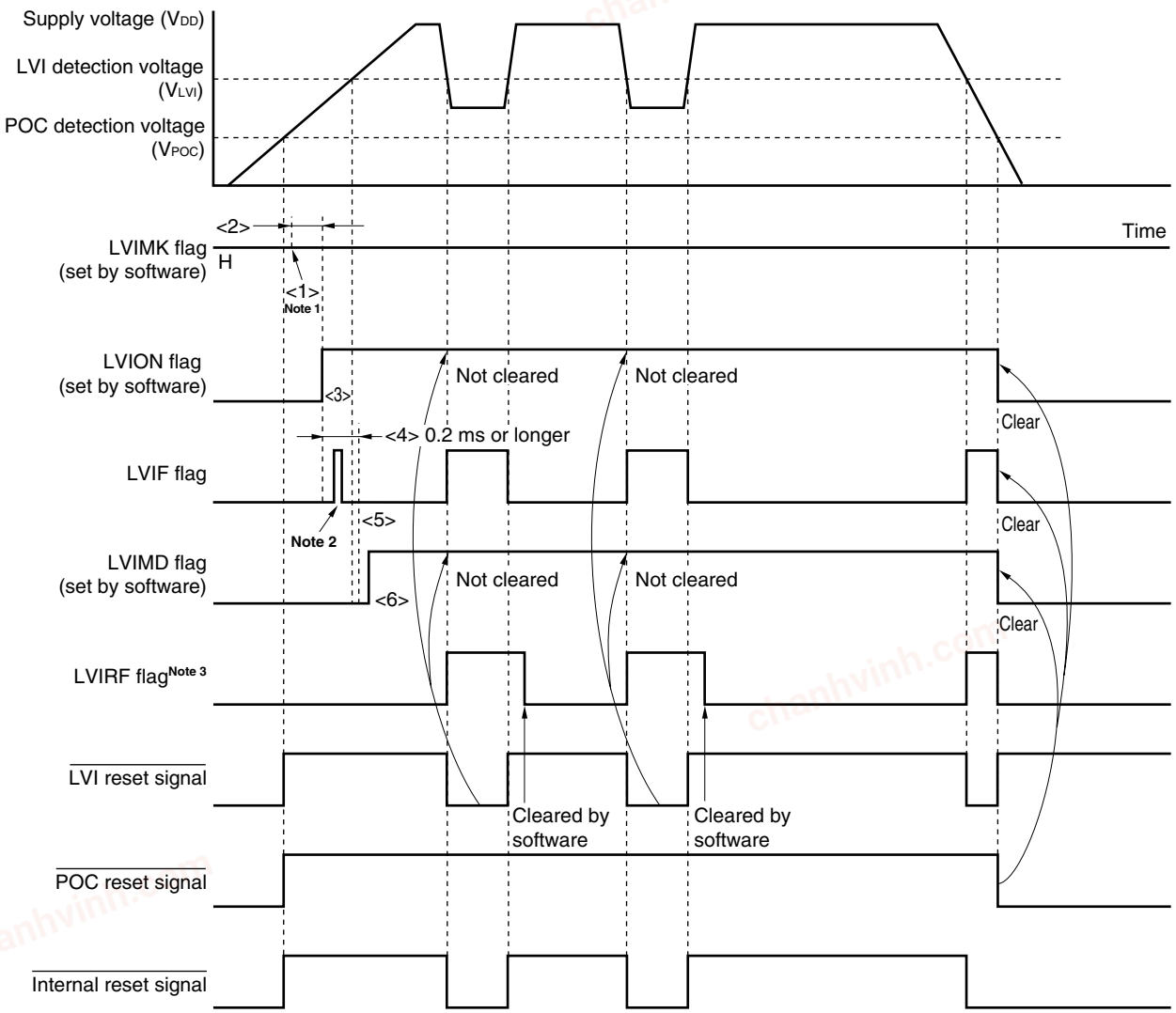
Cautions 1. <1> must always be executed. When LVIMK = 0, an interrupt may occur immediately after the processing in <3>.

2. If supply voltage (V_{DD}) ≥ detection voltage (V_{LVI}) when LVIMD is set to 1, an internal reset signal is not generated.

- When stopping operation
  Either of the following procedures must be executed.
  - When using 8-bit memory manipulation instruction: Write 00H to LVIM.
  - When using 1-bit memory manipulation instruction: Clear LVIMD to 0 and LVION to 0 in that order.

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Figure 14-4. Timing of Low-Voltage Detector Internal Reset Signal Generation



Notes 1. The LVIMK flag is set to “1” by reset signal generation.

2. The LVIF flag may be set (1).

3. LVIRF is bit 0 of the reset control flag register (RESF). For details of RESF, refer to **CHAPTER 12 RESET FUNCTION**.

Remark <1> to <6> in Figure 14-4 above correspond to <1> to <6> in the description of “when starting operation” in **14.4 (1) When used as reset**.

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(2) When used as interrupt

- When starting operation

<1> Mask the LVI interrupt (LVIMK = 1).

<2> Set the detection voltage using bits 3 to 0 (LVIS3 to LVIS0) of the low-voltage detection level select register (LVIS).

<3> Set bit 7 (LVION) of LVIM to 1 (enables LVI operation).

<4> Use software to instigate a wait of at least 0.2 ms.

<5> Wait until "supply voltage (V_{DD}) ≥ detection voltage (V_{LVI})" at bit 0 (LVIF) of LVIM is confirmed.

<6> Clear the interrupt request flag of LVI (LVIIF) to 0.

<7> Release the interrupt mask flag of LVI (LVIMK).

<8> Execute the EI instruction (when vector interrupts are used).

Figure 14-5 shows the timing of generating the interrupt signal of the low-voltage detector. Numbers <1> to <7> in this figure correspond to <1> to <7> above.

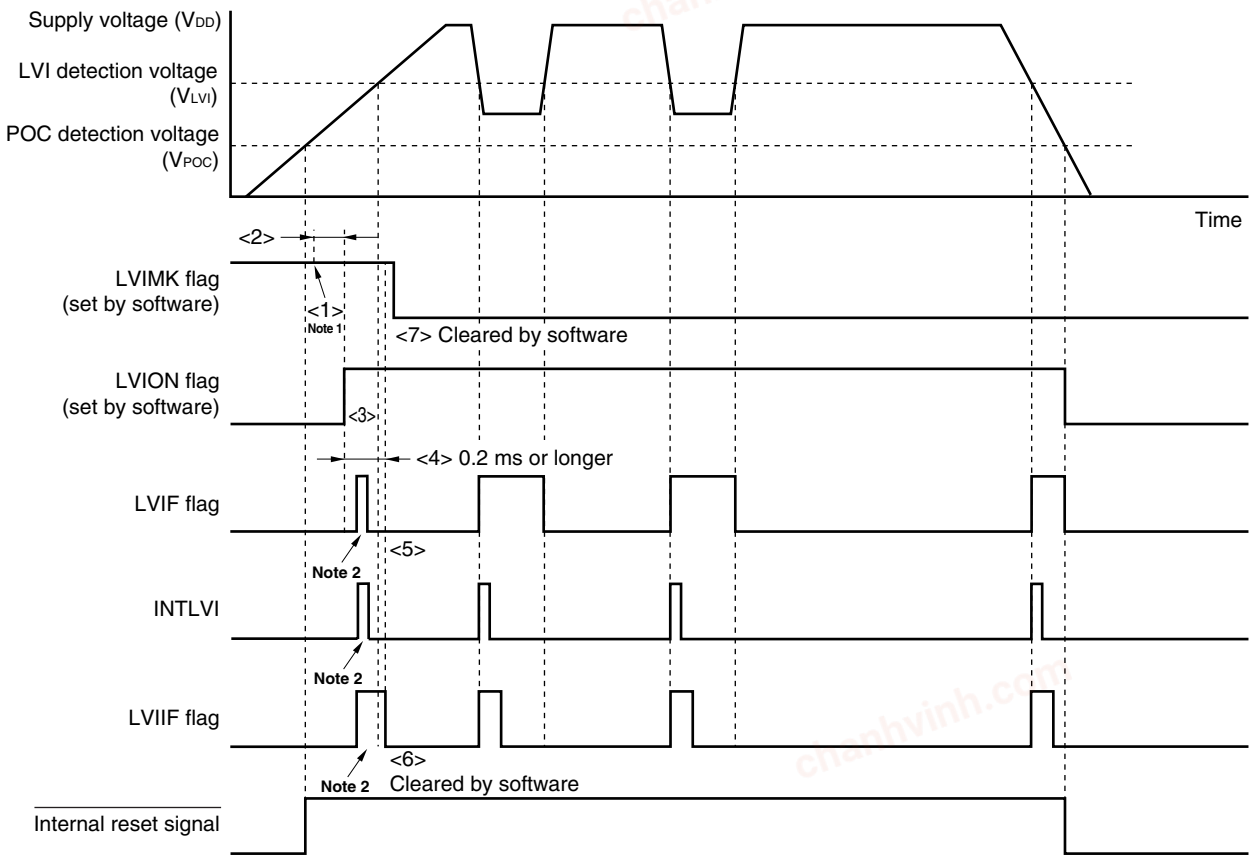
- When stopping operation

  Either of the following procedures must be executed.

  - When using 8-bit memory manipulation instruction: Write 00H to LVIM.
  - When using 1-bit memory manipulation instruction: Clear LVION to 0.

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Figure 14-5. Timing of Low-Voltage Detector Interrupt Signal Generation



Notes 1. The LVIMK flag is set to "1" by reset signal generation.

2. An interrupt request signal (INTLVI) may be generated, and the LVIF and LVIIF flags may be set to 1.

Remark <1> to <7> in Figure 14-5 above correspond to <1> to <7> in the description of "when starting operation" in **14.4 (2) When used as interrupt**.

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14.5 Cautions for Low-Voltage Detector

In a system where the supply voltage (V_{DD}) fluctuates for a certain period in the vicinity of the LVI detection voltage (V_{LVI}), the operation is as follows depending on how the low-voltage detector is used.

<1> When used as reset

The system may be repeatedly reset and released from the reset status.

In this case, the time from release of reset to the start of the operation of the microcontroller can be arbitrarily set by taking action (1) below.

<2> When used as interrupt

Interrupt requests may be frequently generated. Take (b) of action (2) below.

In this system, take the following actions.

<Action>

(1) When used as reset

After releasing the reset signal, wait for the supply voltage fluctuation period of each system by means of a software counter that uses a timer, and then initialize the ports (see **Figure 14-6**).

(2) When used as interrupt

(a) Perform the processing[Note] for low voltage detection. Check that "supply voltage (V_{DD}) ≥ detection voltage (V_{LVI})" in the servicing routine of the LVI interrupt by using bit 0 (LVIF) of the low-voltage detection register (LVIM). Clear bit 1 (LVIIF) of interrupt request flag register 0 (IF0) to 0.

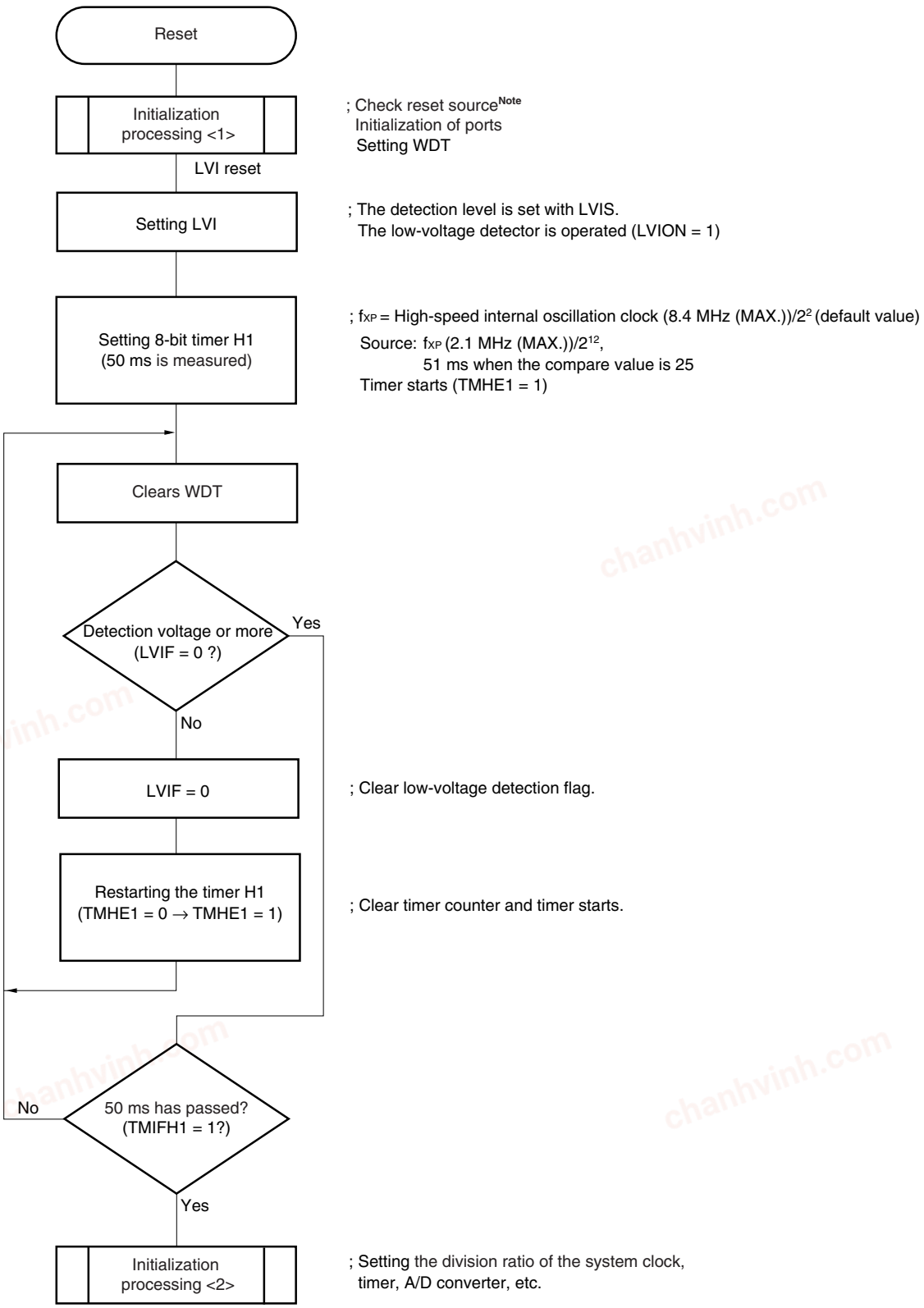
(b) In a system where the supply voltage fluctuation period is long in the vicinity of the LVI detection voltage, wait for the supply voltage fluctuation period, check that "supply voltage (V_{DD}) ≥ detection voltage (V_{LVI})" using the LVIF flag and clear LVIIF flag to 0.

Note For low voltage detection processing, the CPU clock speed is switched to slow speed and the A/D converter is stopped, etc.

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Figure 14-6. Example of Software Processing After Release of Reset (1/2)

• If supply voltage fluctuation is 50 ms or less in vicinity of LVI detection voltage

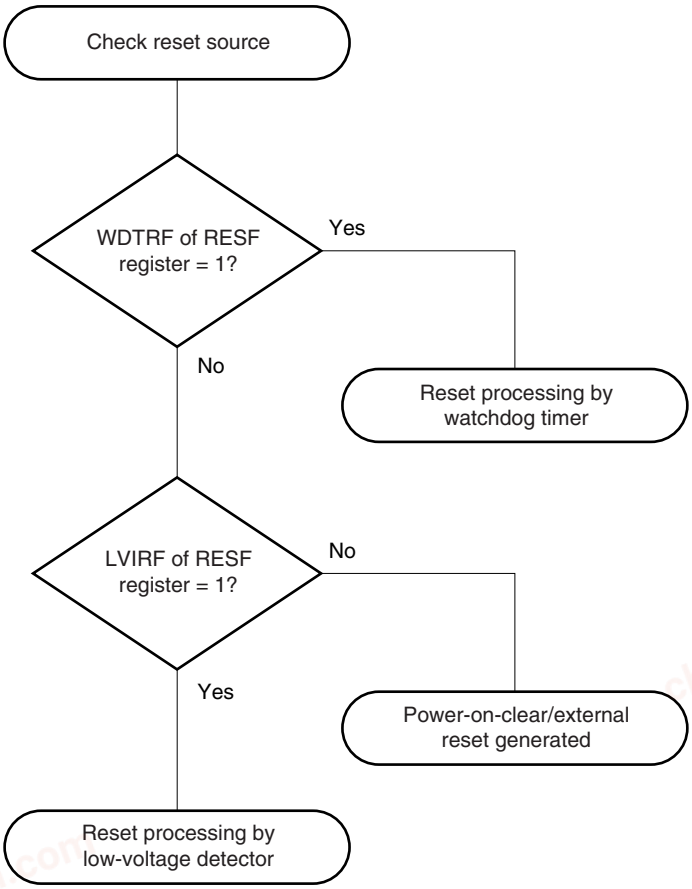


Note A flowchart is shown on the next page.

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Figure 14-6. Example of Software Processing After Release of Reset (2/2)

• Checking reset source



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CHAPTER 15 OPTION BYTE

15.1 Functions of Option Byte

The address 0080H of the flash memory of the 78K0S/KY1+ is an option byte area. When power is supplied or when starting after a reset, the option byte is automatically referenced, and settings for the specified functions are performed. When using the product, be sure to set the following functions by using the option byte.

(1) Selection of system clock source

- High-speed internal oscillation clock
- Crystal/ceramic oscillation clock
- External clock input

(2) Low-speed internal oscillation clock oscillation

- Cannot be stopped.
- Can be stopped by software.

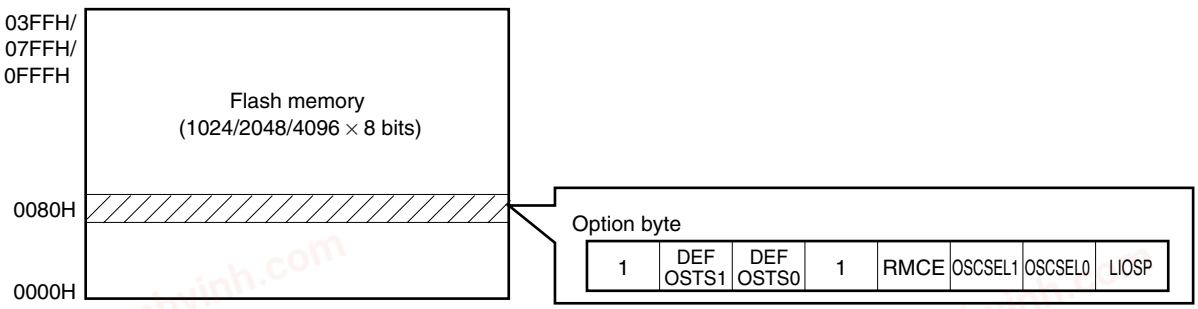
(3) Control of $\overline{\text{RESET}}$ pin

- Used as $\overline{\text{RESET}}$ pin
- $\overline{\text{RESET}}$ pin is used as an input port pin (P34) (refer to **15.3 Caution When the $\overline{\text{RESET}}$ Pin Is Used as an Input-Only Port Pin (P34)**).

(4) Oscillation stabilization time on power application or after reset release

- 2^{10}/fx
- 2^{12}/fx
- 2^{15}/fx
- 2^{17}/fx

Figure 15-1. Positioning of Option Byte



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15.2 Format of Option Byte

Format of option bytes is shown below.

Figure 15-2. Format of Option Byte (1/2)

Address: 0080H

7	6	5	4	3	2	1	0
1	DEFOSTS1	DEFOSTS0	1	RMCE	OSCSEL1	OSCSEL0	LIOCP

DEFOSTS1	DEFOSTS0	Oscillation stabilization time on power application or after reset release
0	0	2^{10}/fx (102.4 μs)
0	1	2^{12}/fx (409.6 μs)
1	0	2^{15}/fx (3.27 ms)
1	1	2^{17}/fx (13.1 ms)

Caution The setting of this option is valid only when the crystal/ceramic oscillation clock is selected as the system clock source. No wait time elapses if the high-speed internal oscillation clock or external clock input is selected as the system clock source.

RMCE	Control of $\overline{\text{RESET}}$ pin
1	$\overline{\text{RESET}}$ pin is used as is.
0	$\overline{\text{RESET}}$ pin is used as input port pin (P34).

Caution Because the option byte is referenced after reset release, if a low level is input to the $\overline{\text{RESET}}$ pin before the option byte is referenced, then the reset state is not released.
Also, when setting 0 to RMCE, connect the pull-up resistor.

OSCSEL1	OSCSEL0	Selection of system clock source
0	0	Crystal/ceramic oscillation clock
0	1	External clock input
1	×	High-speed internal oscillation clock

Caution Because the X1 and X2 pins are also used as the P23/ANI3[Note] and P22/ANI2[Note] pins, the conditions under which the X1 and X2 pins can be used differ depending on the selected system clock source.

(1) Crystal/ceramic oscillation clock is selected
The X1 and X2 pins cannot be used as I/O port pins or analog input pins of A/D converter[Note] because they are used as clock input pins.

(2) External clock input is selected
Because the X1 pin is used as an external clock input pin, P23/ANI3[Note] cannot be used as an I/O port pin or an analog input pin of A/D converter[Note].

(3) High-speed internal oscillation clock is selected
P23/ANI3[Note] and P22/ANI2[Note] pins can be used as I/O port pins or analog input pins of A/D converter[Note].

<R> **Note** μPD78F921x only

Remark × : don't care

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Figure 15-2. Format of Option Byte (2/2)

LIOCP	Low-speed internal oscillates
1	Cannot be stopped (oscillation does not stop even if 1 is written to the LSRSTOP bit)
0	Can be stopped by software (oscillation stops when 1 is written to the LSRSTOP bit)

Cautions 1. If it is selected that low-speed internal oscillator cannot be stopped, the count clock to the watchdog timer (WDT) is fixed to low-speed internal oscillation clock.

2. If it is selected that low-speed internal oscillator can be stopped by software, supply of the count clock to WDT is stopped in the HALT/STOP mode, regardless of the setting of bit 0 (LSRSTOP) of the low-speed internal oscillation mode register (LSRCM). Similarly, clock supply is also stopped when a clock other than the low-speed internal oscillation clock is selected as a count clock to WDT.

While the low-speed internal oscillator is operating (LSRSTOP = 0), the clock can be supplied to the 8-bit timer H1 even in the STOP mode.

Remarks 1. ( ): fx = 10 MHz

2. For the oscillation stabilization time of the resonator, refer to the characteristics of the resonator to be used.

3. An example of software coding for setting the option bytes is shown below.

```
OPB CSEG AT 0080H
DB 10010001B        ; Set to option byte
                    ; Low-speed internal oscillator cannot be stopped
                    ; The system clock is a crystal or ceramic resonator.
                    ; The RESET pin is used as an input-only port pin (P34).
                    ; Minimum oscillation stabilization time (2^10/fx)
```

4. For details on the timing at which the option byte is referenced, see **CHAPTER 12 RESET FUNCTION**.

15.3 Caution When the RESET Pin Is Used as an Input-Only Port Pin (P34)

Be aware of the following when re-erasing/-writing (by on-board programming using a dedicated flash memory programmer) an already-written device which has been set as “The RESET pin is used as an input-only port pin (P34)” by the option byte function.

Before supplying power to the target system, connect a dedicated flash memory programmer and turn its power on.

If the power is supplied to the target system beforehand, the flash memory programming mode cannot be switched to.

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CHAPTER 16 FLASH MEMORY

16.1 Features

The internal flash memory of the 78K0S/KY1+ has the following features.

- Erase/write even without preparing a separate dedicated power supply
- Capacity: 1/2/4 KB
  - Erase unit: 1 block (256 bytes)
  - Write unit: 1 block (at on-board/off-board programming time), 1 byte (at self programming time)
- Rewriting method
  - Rewriting by communication with dedicated flash memory programmer (on-board/off-board programming)
  - Rewriting flash memory by user program (self programming)
- Supports rewriting of the flash memory at on-board/off-board programming time through security functions
- Supports security functions in block units at self programming time through protect bytes

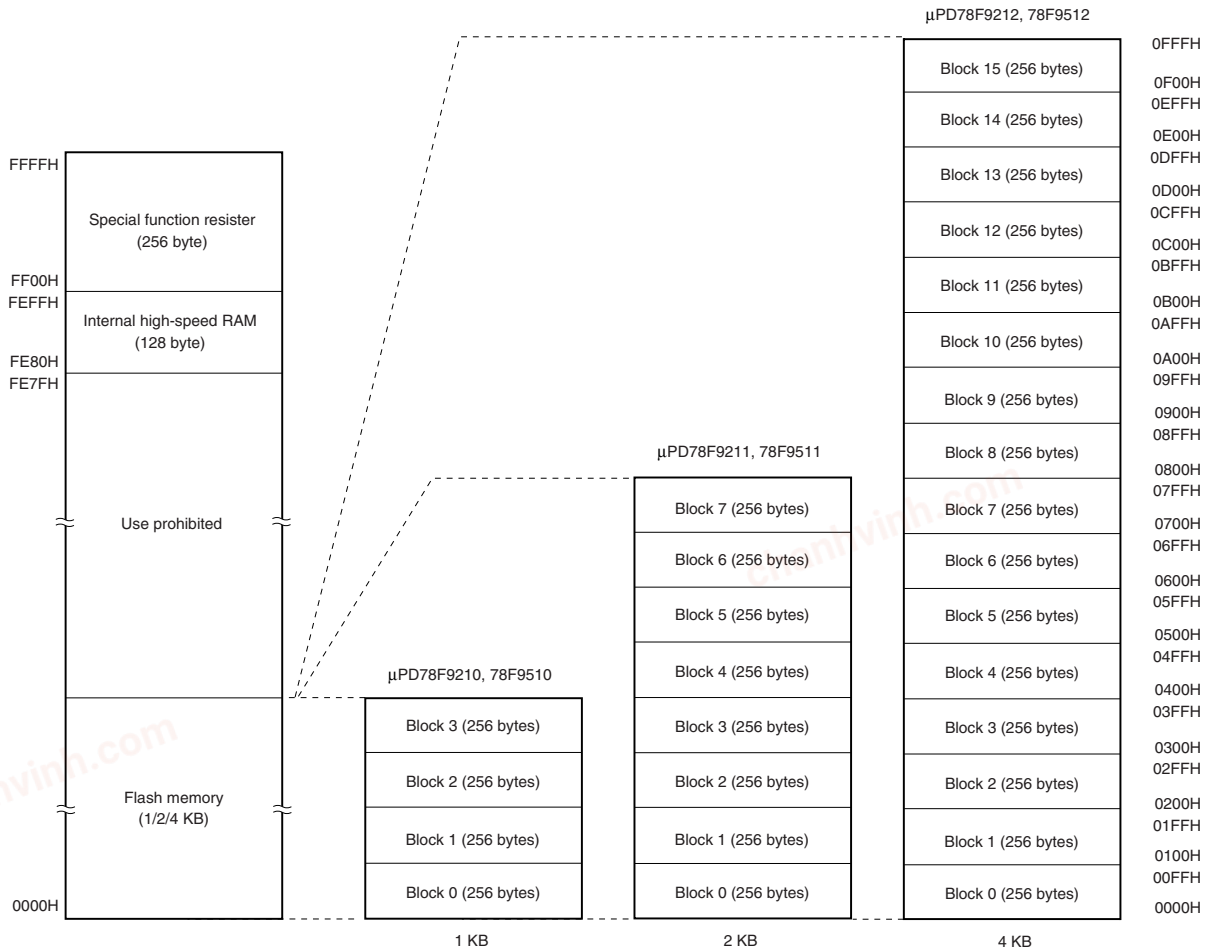
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16.2 Memory Configuration

The 1/2/4 KB internal flash memory area is divided into 4/8/16 blocks and can be programmed/erased in block units. All the blocks can also be erased at once, by using a dedicated flash memory programmer.

<R>

Figure 16-1. Flash Memory Mapping



16.3 Functional Outline

The internal flash memory of the 78K0S/KY1+ can be rewritten by using the rewrite function of the dedicated flash memory programmer, regardless of whether the 78K0S/KY1+ has already been mounted on the target system or not (on-board/off-board programming).

The function for rewriting a program with the user program (self programming), which is ideal for an application when it is assumed that the program is changed after production/shipment of the target system, is provided.

Refer to Table 16-1 for the flash memory writing control function.

In addition, a security function that prohibits rewriting the user program written to the internal flash memory is also supported, so that the program cannot be changed by an unauthorized person.

Refer to **16.7.3 Security settings** for details on the security function.

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Table 16-1. Rewrite Method

Rewrite Method	Functional Outline	Operation Mode
On-board programming	Flash memory can be rewritten after the device is mounted on the target system, by using a dedicated flash memory programmer.	Flash memory programming mode
Off-board programming	Flash memory can be rewritten before the device is mounted on the target system, by using a dedicated flash memory programmer and a dedicated program adapter board (FA series).	
Self programming	Flash memory can be rewritten by executing a user program that has been written to the flash memory in advance by means of on-board/off-board programming.	Self programming mode

Remarks 1. The FA series is a product of Naito Densei Machida Mfg. Co., Ltd.

2. Refer to the following sections for details on the flash memory writing control function.

- **16.7 On-Board and Off-Board Flash Memory Programming**
- **16.8 Flash Memory Programming by Self Programming**

16.4 Writing with Flash Memory Programmer

The following two types of dedicated flash memory programmers can be used for writing data to the internal flash memory of the 78K0S/KY1+.

- FlashPro5 (PG-FP5, FL-PR5)
<R> • QB-MINI2

Data can be written to the flash memory on-board or off-board, by using a dedicated flash memory programmer.

(1) On-board programming

The contents of the flash memory can be rewritten after the 78K0S/KY1+ have been mounted on the target system. The connectors that connect the dedicated flash memory programmer and the test pad must be mounted on the target system. The test pad is required only when writing data with the crystal/ceramic resonator mounted (refer to Figure 16-4 for mounting of the test pad).

(2) Off-board programming

Data can be written to the flash memory with a dedicated program adapter (FA series) before the 78K0S/KY1+ is mounted on the target system.

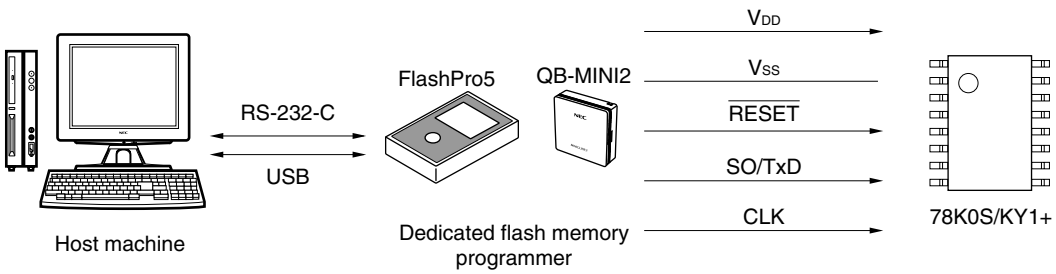
<R> **Remark** The FL-PR5 and FA series are products of Naito Densei Machida Mfg. Co., Ltd.

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16.5 Programming Environment

The environment required for writing a program to the flash memory is illustrated below.

<R> **Figure 16-2. Environment for Writing Program to Flash Memory (FlashPro5/QB-MINI2)**



<R> **Remark** For QB-MINI2, the name of the SO/TxD signal is DATA.

A host machine that controls the dedicated flash memory programmer is necessary. When using the PG-FP5 or FL-PR5, data can be written with just the dedicated flash memory programmer after downloading the program from the host machine.

UART is used for manipulation such as writing and erasing when interfacing between the dedicated flash memory programmer and the 78K0S/KY1+. To write the flash memory off-board, a dedicated program adapter (FA series) is necessary.

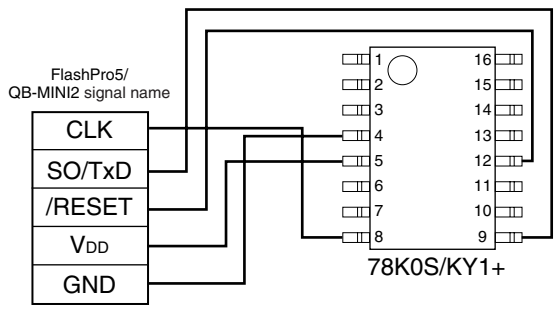
Download the latest firmware for flash memory programmer, programming GUI, and parameter file from the download site for development tools (http://www.necel.com/micro/en/ods/).

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<R> **Table 16-2. Wiring Between 78K0S/KY1+ and FlashPro5/QB-MINI2**

FlashPro5/QB-MINI2 Connection Pin			78K0S/KY1+ Connection Pin
Pin Name	I/O	Pin Function	Pin Name
CLK	Output	Clock to 78K0S/KY1+	X1/P23/ANI3
SO/TxD	Output	Receive signal/on-board mode signal	X2/P22/ANI2
/RESET	Output	Reset signal	$\overline{\text{RESET}}$/P34
V_{DD}	–	V_{DD} voltage generation/voltage monitor	V_{DD}
GND	–	Ground	V_{SS}

<R> **Figure 16-3. Communication with FlashPro5/QB-MINI2 (16-pin Plastic SSOP Products)**



<R> **Remark** For QB-MINI2, the name of the SO/TxD signal is DATA.

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16.6 Processing of Pins on Board

To write the flash memory on-board, connectors that connect the dedicated flash memory programmer must be provided on the target system. First provide a function that selects the normal operation mode or flash memory programming mode on the board.

When the flash memory programming mode is set, all the pins not used for programming the flash memory are in the same status as immediately after reset. Therefore, if the external device does not recognize the state immediately after reset, the pins must be processed as described below.

The state of the pins in the self programming mode is the same as that in the HALT mode.

16.6.1 X1 and X2 pins

The X1 and X2 pins are used as the serial interface of flash memory programming. Therefore, if the X1 and X2 pins are connected to an external device, a signal conflict occurs. To prevent the conflict of signals, isolate the connection with the external device.

Similarly, when a capacitor is connected to the X1 and X2 pins, the waveform during communication is changed, and thus communication may be disabled depending on the capacitor capacitance. Make sure to isolate the connection with the capacitor during flash programming.

Perform the following processing (1) and (2) when on-board programming is performed with the resonator mounted, when it is difficult to isolate the resonator, while a crystal or ceramic resonator is selected as the system clock.

(1) Mount the minimum-possible test pads between the device and the resonator, and connect the programmer via the test pad. Keep the wiring as short as possible (refer to **Figure 16-4** and **Table 16-3**).

(2) Set the oscillation frequency of the communication clock for writing using the programming GUI of the dedicated flash memory programmer. Research the series/parallel resonant and antiresonant frequencies of the resonator used, and set the oscillation frequency so that it is outside the range of the resonant frequency ±10% (refer to **Figure 16-5** and **Table 16-4**).

Figure 16-4. Example of Mounting Test Pads

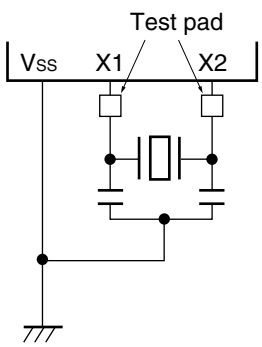
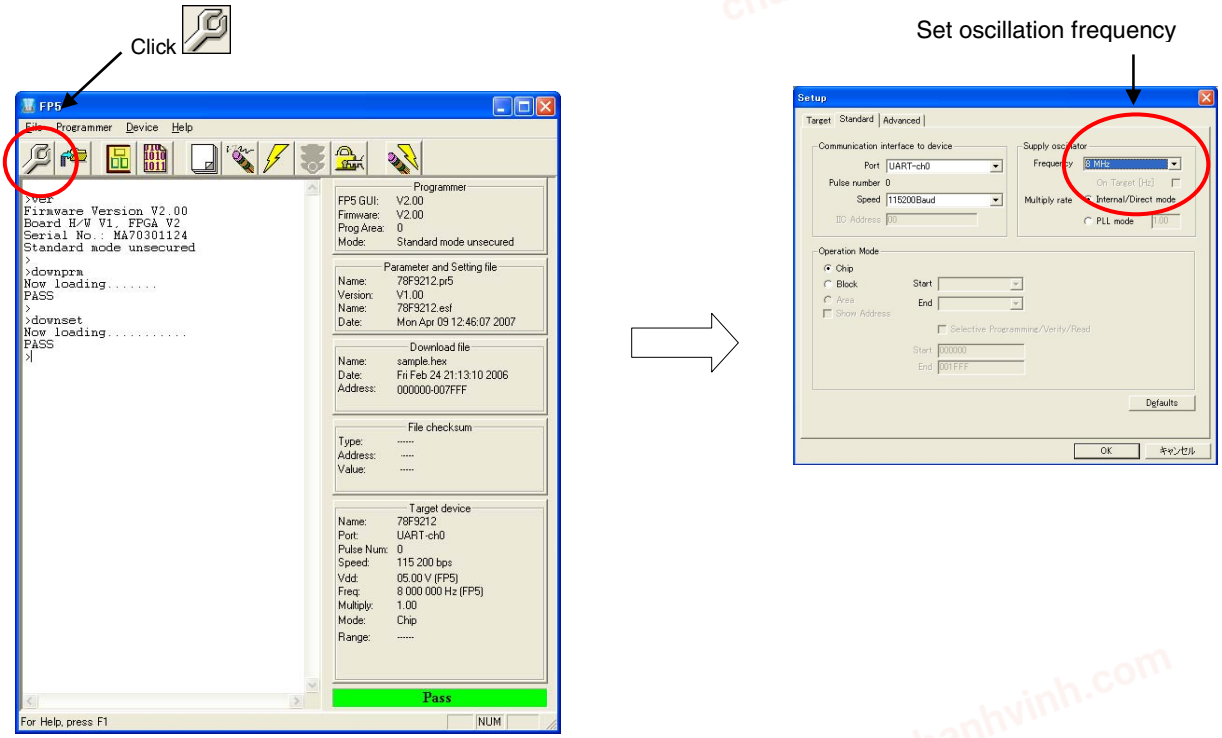


Table 16-3. Clock to Be Used and Mounting of Test Pads

Clock to Be Used		Mounting of Test Pads
High-speed internal oscillation clock		Not required
External clock		
Crystal/ceramic oscillation clock	Before resonator is mounted	
	After resonator is mounted	Required

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Figure 16-5. PG-FP5 Programming GUI Setting Example



(Main window) (Standard tab in Device setup window)

Table 16-4. Oscillation Frequency and PG-FP5 Programming GUI Setting Value Example

Oscillation Frequency	PG-FP5 Programming GUI Setting Value Example (Communication Frequency)
2 MHz ≤ fx < 4 MHz	8 MHz
4 MHz ≤ fx < 8 MHz	9 MHz
8 MHz ≤ fx < 9 MHz	10 MHz
9 MHz ≤ fx ≤ 10 MHz	8 MHz

Caution The above values are recommended values. Depending on the usage environment these values may change, so set them after having performed sufficient evaluations.

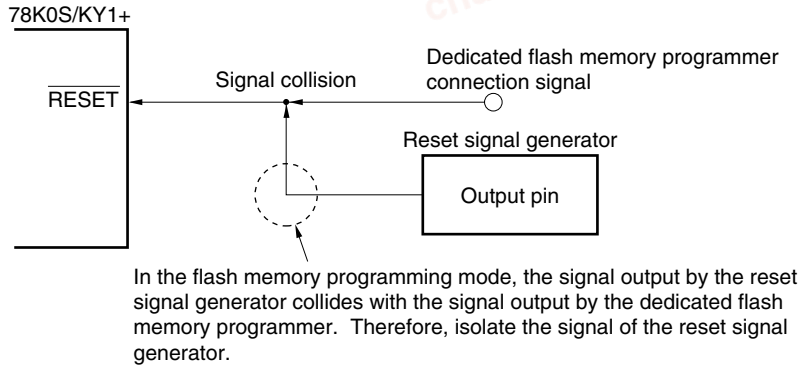
16.6.2 $\overline{\text{RESET}}$ pin

If the reset signal of the dedicated flash memory programmer is connected to the $\overline{\text{RESET}}$ pin that is connected to the reset signal generator on the board, signal collision takes place. To prevent this collision, isolate the connection with the reset signal generator.

If the reset signal is input from the user system while the flash memory programming mode is set, the flash memory will not be correctly programmed. Do not input any signal other than the reset signal of the dedicated flash memory programmer.

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Figure 16-6. Signal Collision ($\overline{\text{RESET}}$ Pin)



16.6.3 Port pins

When the flash memory programming mode is set, all the pins not used for flash memory programming enter the same status as that immediately after reset. If external devices connected to the ports do not recognize the port status immediately after reset, the port pin must be connected to V_{DD} or V_{SS} via a resistor.

The state of the pins in the self programming mode is the same as that in the HALT mode.

16.6.4 Power supply

Connect the V_{DD} pin to V_{DD} of the flash memory programmer, and the V_{SS} pin to V_{SS} of the flash memory programmer.

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16.7 On-Board and Off-Board Flash Memory Programming

16.7.1 Flash memory programming mode

To rewrite the contents of the flash memory by using the dedicated flash memory programmer, set the 78K0S/KY1+ in the flash memory programming mode. When the 78K0S/KY1+ are connected to the flash memory programmer and a communication command is transmitted to the microcontroller, the microcontroller is set in the flash memory programming mode.

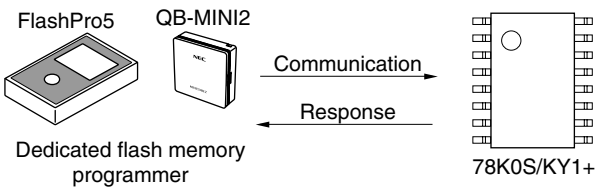
Change the mode by using a jumper when writing the flash memory on-board.

16.7.2 Communication commands

The dedicated flash memory programmer controls the 78K0S/KY1+ by using commands. The signals sent from the flash memory programmer to the 78K0S/KY1+ are called communication commands, and the commands sent from the 78K0S/KY1+ to the dedicated flash memory programmer are called response.

<R>

Figure 16-7. Communication Commands



Communication commands are listed in the table below. All these communication commands are issued from the flash memory programmer and the 78K0S/KY1+ perform processing corresponding to the respective communication commands.

Table 16-5. Communication Commands

Classification	Communication Command Name	Function
Erase	Batch erase (chip erase) command	Erases the contents of the entire memory
	Block erase command	Erases the contents of the memory of the specified block
Write	Write command	Writes to the specified address range and executes a verify check of the contents.
Checksum	Checksum command	Reads the checksum of the specified address range and compares with the written data.
Blank check	Blank check command	Confirms the erasure status of the entire memory.
Security	Security set command	Prohibits batch erase (chip erase) command, block erase command, and write command to prevent operation by third parties.

The 78K0S/KY1+ returns a response for the communication command issued by the dedicated flash memory programmer. The response name sent from the 78K0S/KY1+ are listed below.

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Table 16-6. Response Name

Command Name	Function
ACK	Acknowledges command/data.
NAK	Acknowledges illegal command/data.

16.7.3 Security settings

The operations shown below can be prohibited using the security setting command.

- Batch erase (chip erase) is prohibited
  Execution of the block erase and batch erase (chip erase) commands for entire blocks in the flash memory is prohibited. Once execution of the batch erase (chip erase) command is prohibited, all the prohibition settings can no longer be cancelled.

  Caution After the security setting of the batch erase is set, erasure cannot be performed for the device. In addition, even if a write command is executed, data different from that which has already been written to the flash memory cannot be written because the erase command is disabled.

- Block erase is prohibited
  Execution of the block erase command in the flash memory is prohibited. This prohibition setting can be cancelled using the batch erase (chip erase) command.

- Write is prohibited
  Execution of the write and block erase commands for entire blocks in the flash memory is prohibited. This prohibition setting can be cancelled using the batch erase (chip erase) command.

  Remark The security setting is valid when the programming mode is set next time.

The batch erase (chip erase), block erase, and write commands are enabled by the default setting when the flash memory is shipped. The above security settings are possible only for on-board/off-board programming. Each security setting can be used in combination.

Table 16-7 shows the relationship between the erase and write commands when the 78K0S/KY1+ security function is enabled.

Table 16-7. Relationship Between Commands When Security Function Is Enabled

Command / Security	Batch Erase (Chip Erase) Command	Block Erase Command	Write Command
When batch erase (chip erase) security operation is enabled	Disabled	Disabled	Enabled[Note]
When block erase security operation is enabled	Enabled		Enabled
When write security operation is enabled			Disabled

Note Since the erase command is disabled, data different from that which has already been written to the flash memory cannot be written.

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Table 16-8 shows the relationship between the security setting and the operation in each programming mode.

Table 16-8. Relationship Between Security Setting and Operation In Each Programming Mode

Programming Mode / Security Setting	On-Board/Off-Board Programming		Self Programming	
	Security Setting	Security Operation	Security Setting	Security Operation
Batch erase (chip erase)	Possible	Valid[Note 1]	Impossible	Invalid[Note 2]
Block erase				
Write				

Notes 1. Execution of each command is prohibited by the security setting.

2. Execution of self programming command is possible regardless of the security setting.

16.8 Flash Memory Programming by Self Programming

The 78K0S/KY1+ support a self programming function that can be used to rewrite the flash memory via a user program, making it possible to upgrade programs in the field.

Caution Self programming processing must be included in the program before performing self programming.

Remarks 1. For usage of self programming, refer to the examples from 16.8.4. onward.

2. To use the internal flash memory of the 78K0S/KY1+ as the external EEPROM™ for storing data, refer to **78K0S/Kx1+ EEPROM Emulation Application Note (U17379E)**.

16.8.1 Outline of self programming

To execute self programming, shift the mode from the normal operation of the user program (normal mode) to the self programming mode. Write/erase processing for the flash memory, which has been set to the register in advance, is performed by executing the HALT instruction during self programming mode. The HALT state is automatically released when processing is completed.

To shift to the self programming mode, execute a specific sequence for a specific register. Refer to **16.8.4 Example of shifting normal mode to self programming mode** for details.

Remark Data written by self programming can be referenced with the MOV instruction.

Table 16-9. Self Programming Mode

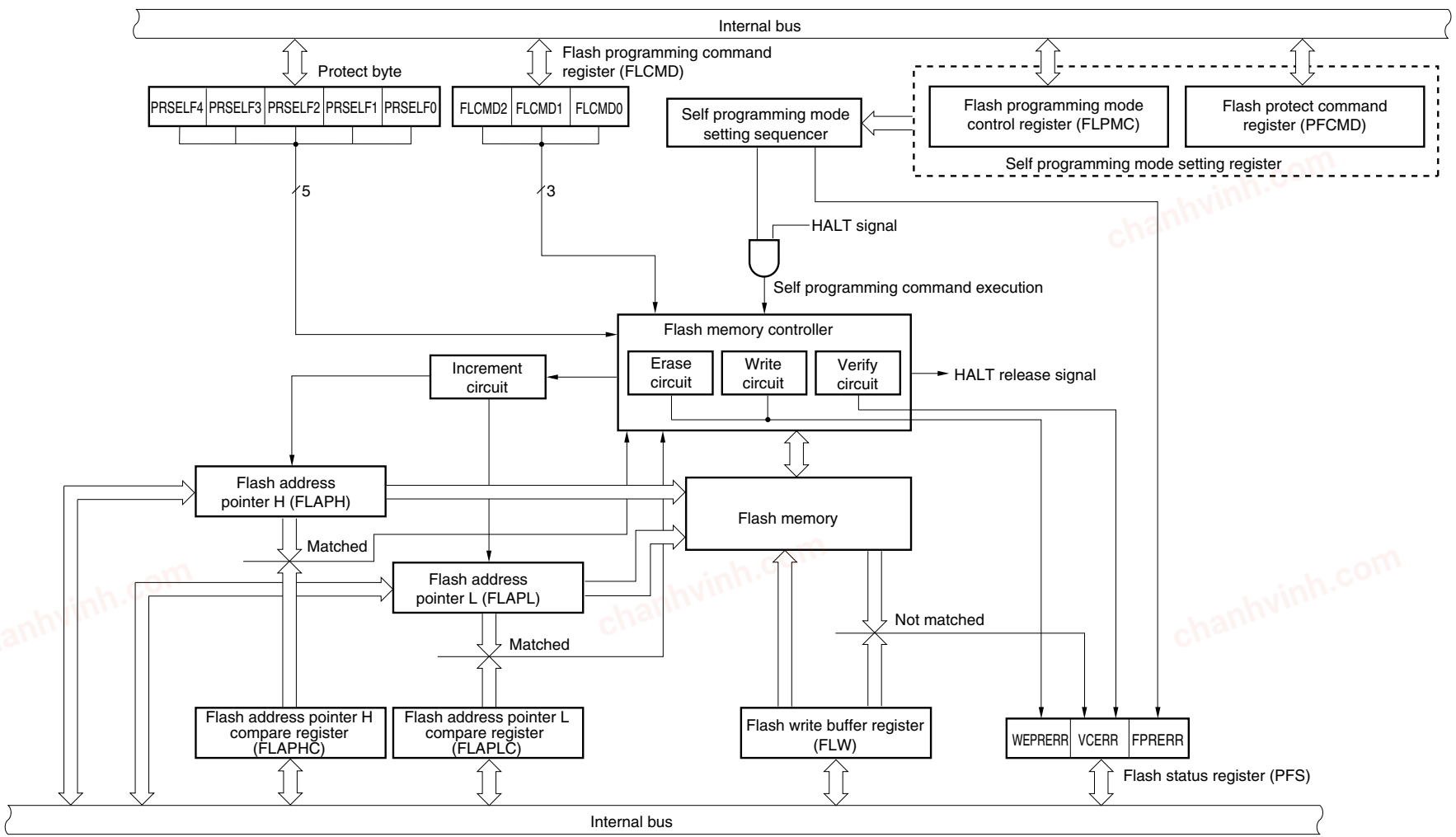
Mode	User Program Execution	Execution of Write/erase for Flash Memory with HALT Instruction
Normal mode	Enabled	–
Self programming mode	Enabled[Note]	Enabled

Note Maskable interrupt servicing is disabled during self programming mode.

Figure 16-8 shows a block diagram for self programming, Figure 16-9 shows the self programming state transition diagram, Table 16-10 lists the commands for controlling self programming.

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Figure 16-8. Block Diagram of Self Programming



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Figure 16-9. Self Programming State Transition Diagram

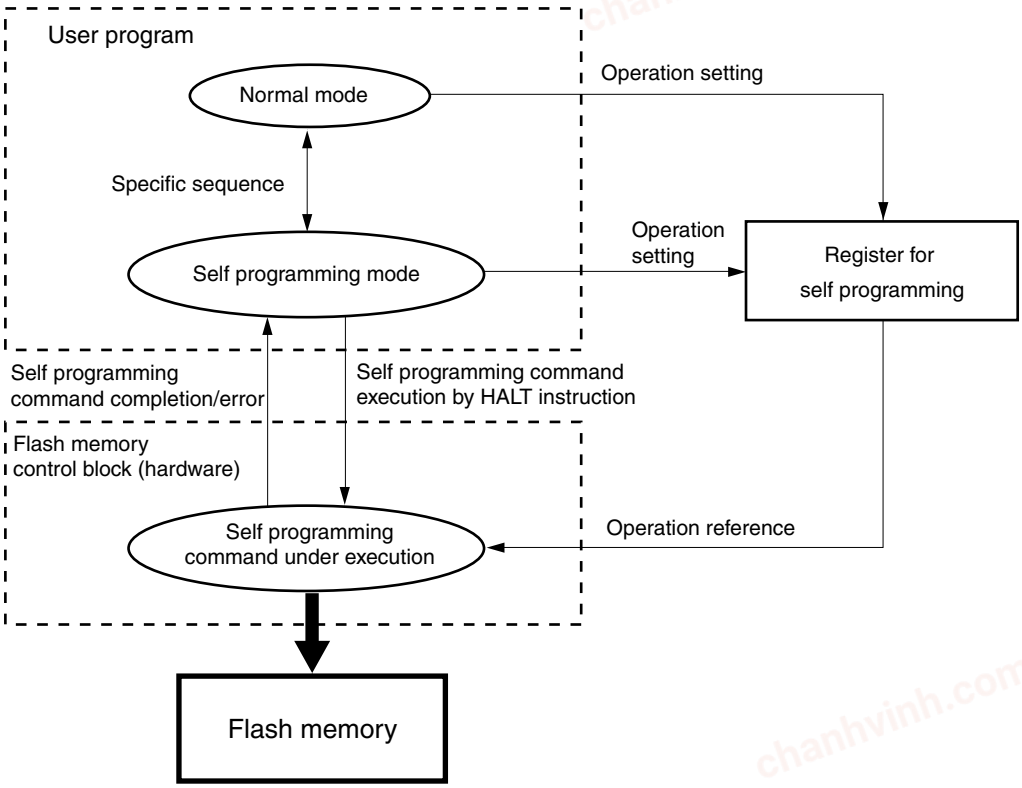


Table 16-10. Self Programming Controlling Commands

Command Name	Function	Time Taken from HALT Instruction Execution to Command Execution End
Internal verify 1	This command is used to check if data has been correctly written to the flash memory. It is used to check whether data has been written to an entire block.	Internal verify for 1 block (internal verify command executed once): 6.8 ms
Internal verify 2	This command is used to check if data has been correctly written to the flash memory. It is used to check whether data has been written to multiple addresses in the same block.	Internal verify of 1 byte: 27 μs
Block erasure[Note]	This command is used to erase a specified block. Specify the block number before execution.	8.5 ms
Block blank check	This command is used to check if data in a specified block has been erased. Specify the block number, then execute this command.	480 μs
Byte write	This command is used to write 1-byte data to the specified address in the flash memory. Specify the write address and write data, then execute this command.	150 μs

Note Set the number of retrials larger than the block erasure time divided by the time (8.5 ms) for one erase, in accordance with the time (MAX. value) required for flash memory block erasures.

Remark The internal verify 1 command can be executed by specifying an address in the same block, but internal verify 2 is recommended if data is written to multiple addresses in the same block.

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16.8.2 Cautions on self programming function

- No instructions can be executed while a self programming command is being executed. Therefore, clear and restart the watchdog timer counter in advance so that the watchdog timer does not overflow during self programming. Refer to Table 16-10 for the time taken for the execution of self programming.
- Interrupts that occur during self programming can be acknowledged after self programming mode ends. To avoid this operation, disable interrupt servicing (by setting MK0 to FFH, and executing the DI instruction) when shifting from the normal mode to the self programming mode with a specific sequence.
- RAM is not used while a self programming command is being executed.
- If the supply voltage drops or the reset signal is input while the flash memory is being written or erased, writing/erasing is not guaranteed.
- The value of the blank data set during block erasure is FFH.
- Set the CPU clock beforehand so that it is 1 MHz or higher during self programming.
- Execute self programming after executing the NOP and HALT instructions immediately after executing a specific sequence to set self programming mode. At this time, the HALT instruction is automatically released after 10 μs (MAX.) + 2 CPU clocks (f_{CPU}).
- If the clock of the oscillator or an external clock is selected as the system clock, execute the NOP and HALT instructions immediately after executing a specific sequence to set self programming mode, wait for 8 μs after releasing the HALT status, and then execute self programming.
- Check FPRERR using a 1-bit memory manipulation instruction.
- The state of the pins in self programming mode is the same as that in HALT mode.
- Since the security function set via on-board/off-board programming is disabled in self programming mode, the self programming command can be executed regardless of the security function setting. To disable write or erase processing during self programming, set the protect byte.
- Be sure to clear bits 4 to 7 of flash address pointer H (FLAPH) and flash address pointer H compare register (FLAPHC) to 0 before executing the self programming command. If self programming is executed with these bits set to 1, the device may malfunction.
- Clear the value of the FLCMD register to 00H immediately before setting to self programming mode and normal mode.

16.8.3 Registers used for self programming function

The following registers are used for the self programming function.

- Flash programming mode control register (FLPMC)
- Flash protect command register (PFCMD)
- Flash status register (PFS)
- Flash programming command register (FLCMD)
- Flash address pointers H and L (FLAPH and FLAPL)
- Flash address pointer H compare register and flash address pointer L compare register (FLAPHC and FLAPLC)
- Flash write buffer register (FLW)

The 78K0S/KY1+ has an area called a protect byte at address 0081H of the flash memory.

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(1) Flash programming mode control register (FLPMC)

This register is used to set the operation mode when data is written to the flash memory in the self programming mode, and to read the set value of the protect byte.

Data can be written to FLPMC only in a specific sequence (refer to **16.8.3 (2) Flash protect command register (PFCMD)**) so that the application system does not stop by accident because of malfunction due to noise or program hang-up.

This register is set with an 8-bit memory manipulation instruction.

Reset signal generation makes the contents of this register undefined.

Figure 16-10. Format of Flash Programming Mode Control Register (FLPMC)

Address: FFA2H After reset: Undefined[Note 1] R/W[Note 2]

Symbol	7	6	5	4	3	2	1	0
FLPMC	0	PRSELF4	PRSELF3	PRSELF2	PRSELF1	PRSELF0	0	FLSPM

FLSPM	Selection of operation mode during self programming mode
0	Normal mode This is the normal operation status. Executing the HALT instruction sets standby status.
1	Self programming mode Self programming commands can be executed by executing the specific sequence to change modes while in normal mode. Set a command, an address, and data to be written, then execute the HALT instruction to execute self programming.

PRSELF4	PRSELF3	PRSELF2	PRSELF1	PRSELF0	The set value of the protect byte is read to these bits.

Notes 1. Bit 0 (FLSPM) is cleared to 0 when reset is released. The set value of the protect byte is read to bits 2 to 6 (PRSELF0 to PRSELF4) after reset is released.

2. Bits 2 to 6 (PRSELF0 to PRSELF4) are read-only.

Cautions 1. Cautions in the case of setting the self programming mode, refer to 16.8.2 Cautions on self programming function.

2. Set the CPU clock beforehand so that it is 1 MHz or higher during self programming.

3. Execute self programming after executing the NOP and HALT instructions immediately after executing a specific sequence to set self programming mode. At this time, the HALT instruction is automatically released after 10 μs (MAX.) + 2 CPU clocks (f_{CPU}).

4. If the clock of the oscillator or an external clock is selected as the system clock, execute the NOP and HALT instructions immediately after executing a specific sequence to set self programming mode, wait for 8 μs after releasing the HALT status, and then execute self programming.

5. Clear the value of the FLCMD register to 00H immediately before setting to self programming mode and normal mode.

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(2) Flash protect command register (PFCMD)

If the application system stops inadvertently due to malfunction caused by noise or program hang-up, an operation to write the flash programming mode control register (FLPMC) may have a serious effect on the system. PFCMD is used to protect FLPMC from being written, so that the application system does not stop inadvertently.

Writing FLPMC is enabled only when a write operation is performed in the following specific sequence.

<1> Write a specific value to PFCMD (A5H)

<2> Write the value to be set to bit 0 (FLSPM) of the FLPMC (writing in this step is invalid)

<3> Write the inverted value of the value to be set to bit 0 (FLSPM) of the FLPMC (writing in this step is invalid)

<4> Write the value to be set to bit 0 (FLSPM) of the FLPMC (writing in this step is valid)

Caution Interrupt servicing cannot be executed in self programming mode. Disable interrupt servicing (by executing the DI instruction while MK0 = FFH) between the points before executing the specific sequence that sets self programming mode and after executing the specific sequence that changes the mode to the normal mode.

This rewrites the value of the register, so that the register cannot be written illegally.

Occurrence of an illegal write operation can be checked by bit 0 (FPRERR) of the flash status register (PFS). Check FPRERR using a 1-bit memory manipulation instruction.

A5H must be written to PFCMD each time the value of FLPMC is changed.

PFCMD can be set by an 8-bit memory manipulation instruction.

Reset signal generation makes PFCMD undefined.

Figure 16-11. Format of Flash Protect Command Register (PFCMD)

Address: FFA0H After reset: Undefined W

Symbol	7	6	5	4	3	2	1	0
PFCMD	REG7	REG6	REG5	REG4	REG3	REG2	REG1	REG0

(3) Flash status register (PFS)

If data is not written to the flash programming mode control register (FLPMC), which is protected, in the correct sequence (writing the flash protect command register (PFCMD)), FLPMC is not written and a protection error occurs. If this happens, bit 0 of PFS (FPRERR) is set to 1.

When FPRERR is 1, it can be cleared to 0 by writing 0 to it.

Errors that may occur during self programming are reflected in bit 1 (VCERR) and bit 2 (WEPRERR) of PFS. VCERR or WEPRERR can be cleared by writing 0 to them.

All the flags of the PFS register must be pre-cleared to 0 to check if the operation is performed correctly.

PFS can be set by a 1-bit or 8-bit memory manipulation instruction.

Reset signal generation clears PFS to 00H.

Caution Check FPRERR using a 1-bit memory manipulation instruction.

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Figure 16-12. Format of Flash Status Register (PFS)

Address: FFA1H After reset: 00H R/W

Symbol	7	6	5	4	3	2	1	0
PFS	0	0	0	0	0	WEPRERR	VCERR	FPRERR

1. Operating conditions of FPRERR flag

<Setting conditions>

- If PFCMD is written when the store instruction operation recently performed on a peripheral register is not to write a specific value (A5H) to FLPMC
- If the first store instruction operation after <1> is on a peripheral register other than FLPMC
- If the first store instruction operation after <2> is on a peripheral register other than FLPMC
- If a value other than the inverted value of the value to be set to FLPMC is written by the first store instruction after <2>
- If the first store instruction operation after <3> is on a peripheral register other than FLPMC
- If a value other than the value to be set to FLPMC (value written in <2>) is written by the first store instruction after <3>

Remark The numbers in angle brackets above correspond to the those in **(2) Flash protect command register (PFCMD)**.

<Reset conditions>

- If 0 is written to the FPRERR flag
- If the reset signal is generation

2. Operating conditions of VCERR flag

<Setting conditions>

- Erasure verification error
- Internal writing verification error

If VCERR is set, it means that the flash memory has not been erased or written correctly. Erase or write the memory again in the specified procedure.

Remark The VCERR flag may also be set if an erase or write protect error occurs.

<Reset conditions>

- When 0 is written to the VCERR flag
- When the reset signal generation

3. Operating conditions of WEPRERR flag

<Setting conditions>

- If the area specified by the protect byte to be protected from erasing or writing is specified by the flash address pointer H (FLAPH) and a command is executed to this area
- If 1 is written to a bit that has not been erased (a bit for which the data is 0).

<Reset conditions>

- When 0 is written to the WEPRERR flag
- When the reset signal generation

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(4) Flash programming command register (FLCMD)

This register is used to specify whether the flash memory is erased, written, or verified in the self programming mode.

This register is set by using a 1-bit or 8-bit memory manipulation instruction.

Reset signal generation clears this register to 00H.

Figure 16-13. Format of Flash Programming Command Register (FLCMD)

Address: FFA3H After reset: 00H R/W

Symbol	7	6	5	4	3	2	1	0
FLCMD	0	0	0	0	0	FLCMD2	FLCMD1	FLCMD0

FLCMD2	FLCMD1	FLCMD0	Command Name	Function
0	0	1	Internal verify 1	This command is used to check if data has been correctly written to the flash memory. It is used to check whether data has been written to an entire block. If an error occurs, bit 1 (VCERR) or bit 2 (WEPRERR) of the flash status register (PFS) is set to 1.
0	1	0	Internal verify 2	This command is used to check if data has been correctly written to the flash memory. It is used to check whether data has been written to multiple addresses in the same block. If an error occurs, bit 1 (VCERR) or bit 2 (WEPRERR) of the flash status register (PFS) is set to 1.
0	1	1	Block erase	This command is used to erase specified block. It is used both in the on-board mode and self programming mode.
1	0	0	Block blank check	This command is used to check if the specified block has been erased.
1	0	1	Byte write	This command is used to write 1-byte data to the specified address in the flash memory. Specify the write address and write data, then execute this command. If 1 is written to a bit that has not been erased (a bit for which the data is 0), then bit 2 (WEPRERR) of the flash status register (PFS) becomes 1.
Other than above[Note]			Setting prohibited	

Note If any command other than those above is executed, command execution may immediately be terminated, and bit 1 or 2 (WEPRERR or VCERR) of the flash status register (PFS) may be set to 1.

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(5) Flash address pointers H and L (FLAPH and FLAPL)

These registers are used to specify the start address of the flash memory when the memory is erased, written, or verified in the self programming mode.

FLAPH and FLAPL consist of counters, and they are incremented until the values match with those of FLAPHC and FLAPLC when the programming command is not executed. When the programming command is executed, therefore, set the value again.

These registers are set with a 1-bit or 8-bit memory manipulation instruction.

Reset signal generation makes these registers undefined.

Figure 16-14. Format of Flash Address Pointers H/L (FLAPH/FLAPL)

Address: FFA4H, FFA5H After reset: Undefined R/W

	FLAPH (FFA5H)								FLAPL (FFA4H)							
0	0	0	0	FLAP11	FLAP10	FLAP9	FLAP8	FLAP7	FLAP6	FLAP5	FLAP4	FLAP3	FLAP2	FLAP1	FLAP0

Caution Be sure to clear bits 4 to 7 of flash address pointer H (FLAPH) and flash address pointer H compare register (FLAPHC) to 0 before executing the self programming command. If the self programming command is executed with these bits set to 1, the device may malfunction.

(6) Flash address pointer H compare register and flash address pointer L compare register (FLAPHC and FLAPLC)

These registers are used to specify the address range in which the internal sequencer operates when the flash memory is verified in the self programming mode.

Set FLAPHC to the same value as that of FLAPH. Set the last address of the range in which verification is to be executed to FLAPLC.

These registers are set by a 1-bit or 8-bit memory manipulation instruction.

Reset signal generation clears these registers to 00H.

Figure 16-15. Format of Flash Address Pointer H/L Compare Registers (FLAPHC/FLAPLC)

Address: FFA6H, FFA7H After reset: 00H R/W

	FLAPHC (FFA6H)								FLAPLC (FFA7H)							
0	0	0	0	FLAPC11	FLAPC10	FLAPC9	FLAPC8	FLAPC7	FLAPC6	FLAPC5	FLAPC4	FLAPC3	FLAPC2	FLAPC1	FLAPC0

Cautions 1. Be sure to clear bits 4 to 7 of FLAPH and FLAPHC to 0 before executing the self programming command. If the value of these bits is 1 when executing the self programming command.

2. Set the number of the block subject to a block erase, verify, or blank check (same value as FLAPH) to FLAPHC.

3. Clear FLAPLC to 00H when a block erase is performed, and set this register to FFH when a blank check is performed.

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(7) Flash write buffer register (FLW)

This register is used to store the data to be written to the flash memory.

This register is set with an 8-bit memory manipulation instruction.

Reset signal generation clears these registers to 00H.

Figure 16-16. Format of Flash Write Buffer Register (FLW)

Address: FFA8H After reset: 00H R/W

Symbol	7	6	5	4	3	2	1	0
FLW	FLW7	FLW6	FLW5	FLW4	FLW3	FLW2	FLW1	FLW0

(8) Protect byte

This protect byte is used to specify the area that is to be protected from writing or erasing. The specified area is valid only in the self programming mode. Because self programming of the protected area is invalid, the data written to the protected area is guaranteed.

Figure 16-17. Format of Protect Byte (1/2)

Address: 0081H

7	6	5	4	3	2	1	0
1	PRSELF4	PRSELF3	PRSELF2	PRSELF1	PRSELF0	1	1

• μPD78F9210, 78F9510

PRSELF4	PRSELF3	PRSELF2	PRSELF1	PRSELF0	Status
0	1	1	1	0	Blocks 3 to 0 are protected.
0	1	1	1	1	Blocks 1 and 0 are protected. Blocks 2 and 3 can be written or erased.
1	1	1	1	1	All blocks can be written or erased.
Other than above					Setting prohibited

• μPD78F9211, 78F9511

PRSELF4	PRSELF3	PRSELF2	PRSELF1	PRSELF0	Status
0	1	1	0	0	Blocks 7 to 0 are protected.
0	1	1	0	1	Blocks 5 to 0 are protected. Blocks 6 and 7 can be written or erased.
0	1	1	1	0	Blocks 3 to 0 are protected. Blocks 4 to 7 can be written or erased.
0	1	1	1	1	Blocks 1 and 0 are protected. Blocks 2 to 7 can be written or erased.
1	1	1	1	1	All blocks can be written or erased.
Other than above					Setting prohibited

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Figure 16-17. Format of Protect Byte (2/2)

• μPD78F9212, 78F9512

PRSELF4	PRSELF3	PRSELF2	PRSELF1	PRSELF0	Status
0	1	0	0	0	Blocks 15 to 0 are protected.
0	1	0	0	1	Blocks 13 to 0 are protected. Blocks 14 and 15 can be written or erased.
0	1	0	1	0	Blocks 11 to 0 are protected. Blocks 12 to 15 can be written or erased.
0	1	0	1	1	Blocks 9 to 0 are protected. Blocks 10 to 15 can be written or erased.
0	1	1	0	0	Blocks 7 to 0 are protected. Blocks 8 to 15 can be written or erased.
0	1	1	0	1	Blocks 5 to 0 are protected. Blocks 6 to 15 can be written or erased.
0	1	1	1	0	Blocks 3 to 0 are protected. Blocks 4 to 15 can be written or erased.
0	1	1	1	1	Blocks 1 and 0 are protected. Blocks 2 to 15 can be written or erased.
1	1	1	1	1	All blocks can be written or erased.
Other than above					Setting prohibited

16.8.4 Example of shifting normal mode to self programming mode

The operating mode must be shifted from normal mode to self programming mode before performing self programming.

An example of shifting to self programming mode is explained below.

<1> Disable interrupts if the interrupt function is used (by setting the interrupt mask flag registers (MK0) to FFH and executing the DI instruction).
<2> Clear FLCMD (FLCMD = 00H).
<3> Clear the flash status register (PFS).
<4> Set self programming mode using a specific sequence.
- Write a specific value (A5H) to PFCMD.
- Write 01H to FLPMC (writing in this step is invalid).
- Write 0FEH (inverted value of 01H) to FLPMC (writing in this step is invalid).
- Write 01H to FLPMC (writing in this step is valid).

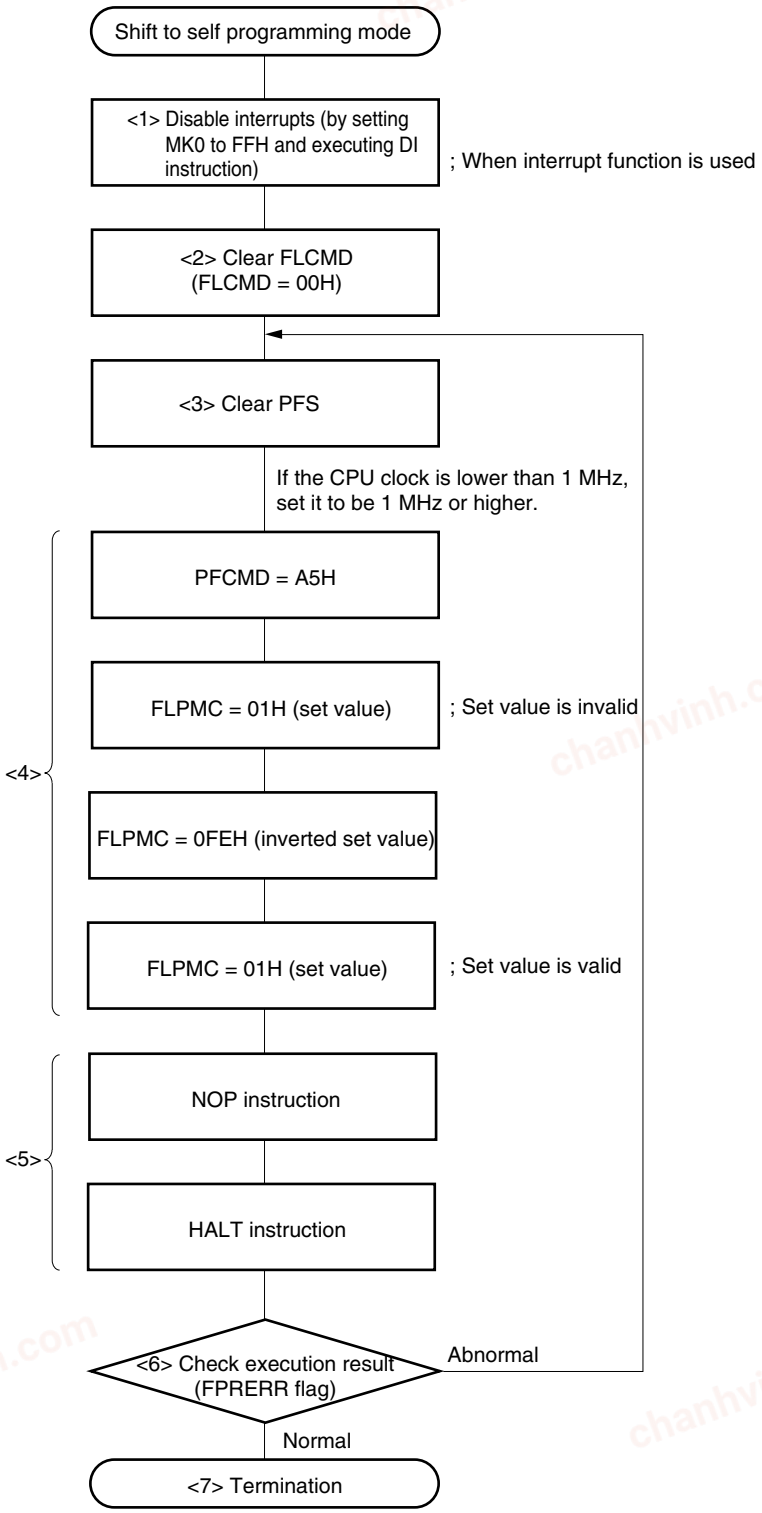
<5> Execute NOP instruction and HALT instruction.
<6> Check the execution result of the specific sequence using bit 0 (FPRERR) of PFS.
Abnormal → <3>, normal → <7>
<7> Mode shift is completed.

Note If the CPU clock is lower than 1 MHz, set it to be 1 MHz or higher.

Caution Be sure to perform the series of operations described above using the user program at an address where data is not erased or written.

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Figure 16-18. Example of Shifting to Self Programming Mode



Caution Be sure to perform the series of operations described above using the user program at an address where data is not erased or written.

Remark <1> to <7> in Figure 16-18 correspond to <1> to <7> in **16.8.4** (previous page).

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An example of the program that shifts the mode to self programming mode is shown below.

```
;----------------------------
;START
;----------------------------
       MOV      MK0,#11111111B     ; Masks all interrupts
       MOV      FLCMD,#00H         ; Clear FLCMD register

       DI

ModeOnLoop:                        ; Configure settings so that the CPU clock ≥ 1 MHz
       MOV      PFS,#00H           ; Clears flash status register
       MOV      PFCMD,#0A5H        ; PFCMD register control
       MOV      FLPMC,#01H         ; FLPMC register control (sets value)
       MOV      FLPMC,#0FEH        ; FLPMC register control (inverts set value)
       MOV      FLPMC,#01H         ; Sets self programming mode with FLPMC register
                                   ; control (sets value)

       NOP
       HALT
       BT       PFS.0,$ModeOLoop   ; Checks completion of write to specific registers
                                   ; Repeats the same processing when an error occurs

;----------------------------
;END
;----------------------------
```

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16.8.5 Example of shifting self programming mode to normal mode

The operating mode must be returned from self programming mode to normal mode after performing self programming.

An example of shifting to normal mode is explained below.

<1> Clear FLCMD (FLCMD = 00H).

<2> Clear the flash status register (PFS).

<3> Set normal mode using a specific sequence.

- Write the specific value (A5H) to PFCMD.
- Write 00H to FLPMC (writing in this step is invalid)
- Write 0FFH (inverted value of 00H) to FLPMC (writing in this step is invalid)
- Write 00H to FLPMC (writing in this step is valid)

<4> Check the execution result of the specific sequence using bit 0 (FPRERR) of PFS[Note].
Abnormal → <2>, normal → <5>

<5> Enable interrupt servicing (by executing the EI instruction and changing MK0) to restore the original state.

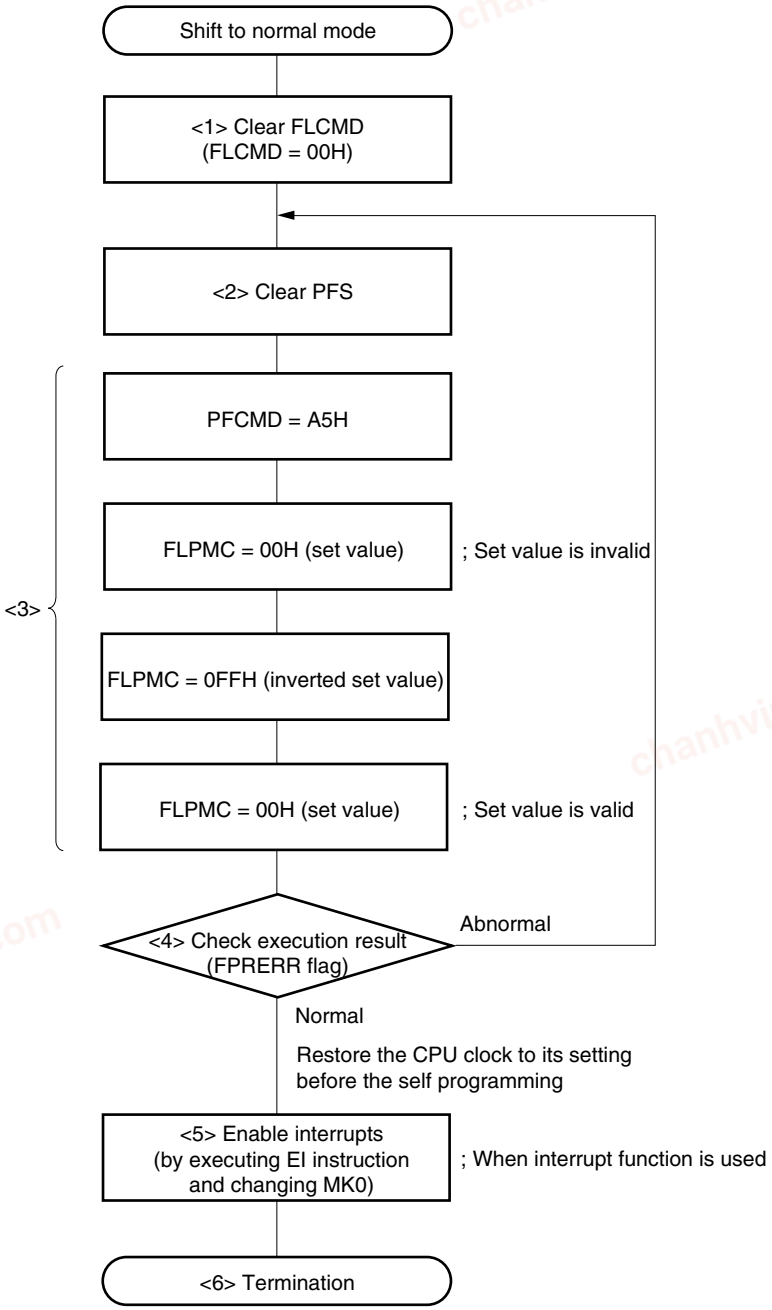
<6> Mode shift is completed

Note Restore the CPU clock to its setting before self programming, after normal completion of the specific sequence.

Caution Be sure to perform the series of operations described above using the user program at an address where data is not erased or written.

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Figure 16-19. Example of Shifting to Normal Mode



Caution Be sure to perform the series of operations described above using the user program at an address where data is not erased or written.

Remark <1> to <6> in Figure 16-19 correspond to <1> to <6> in **16.8.5** (previous page).

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An example of a program that shifts the mode to normal mode is shown below.

```
;----------------------------
;START
;----------------------------

       MOV      FLCMD,#00H         ; Clear FLCMD register

ModeOffLoop:
       MOV      PFS,#00H           ; Clears flash status register
       MOV      PFCMD,#0A5H        ; PFCMD register control
       MOV      FLPMC,#00H         ; FLPMC register control (sets value)
       MOV      FLPMC,#0FFH        ; FLPMC register control (inverts set value)
       MOV      FLPMC,#00H         ; Sets normal mode via FLPMC register control (sets value)

       BT       PFS.0,$ModeOffLoop ; Checks completion of write to specific registers
                                   ; Repeats the same processing when an error occurs
                                   ; Restore the CPU clock to its setting before the self
                                   ; programming, after normal completion of the specific
                                   ; sequence
       MOV      MK0,#INT_MK0       ; Restores interrupt mask flag

       EI

;----------------------------
;END
;----------------------------
```

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16.8.6 Example of block erase operation in self programming mode

An example of the block erase operation in self programming mode is explained below.

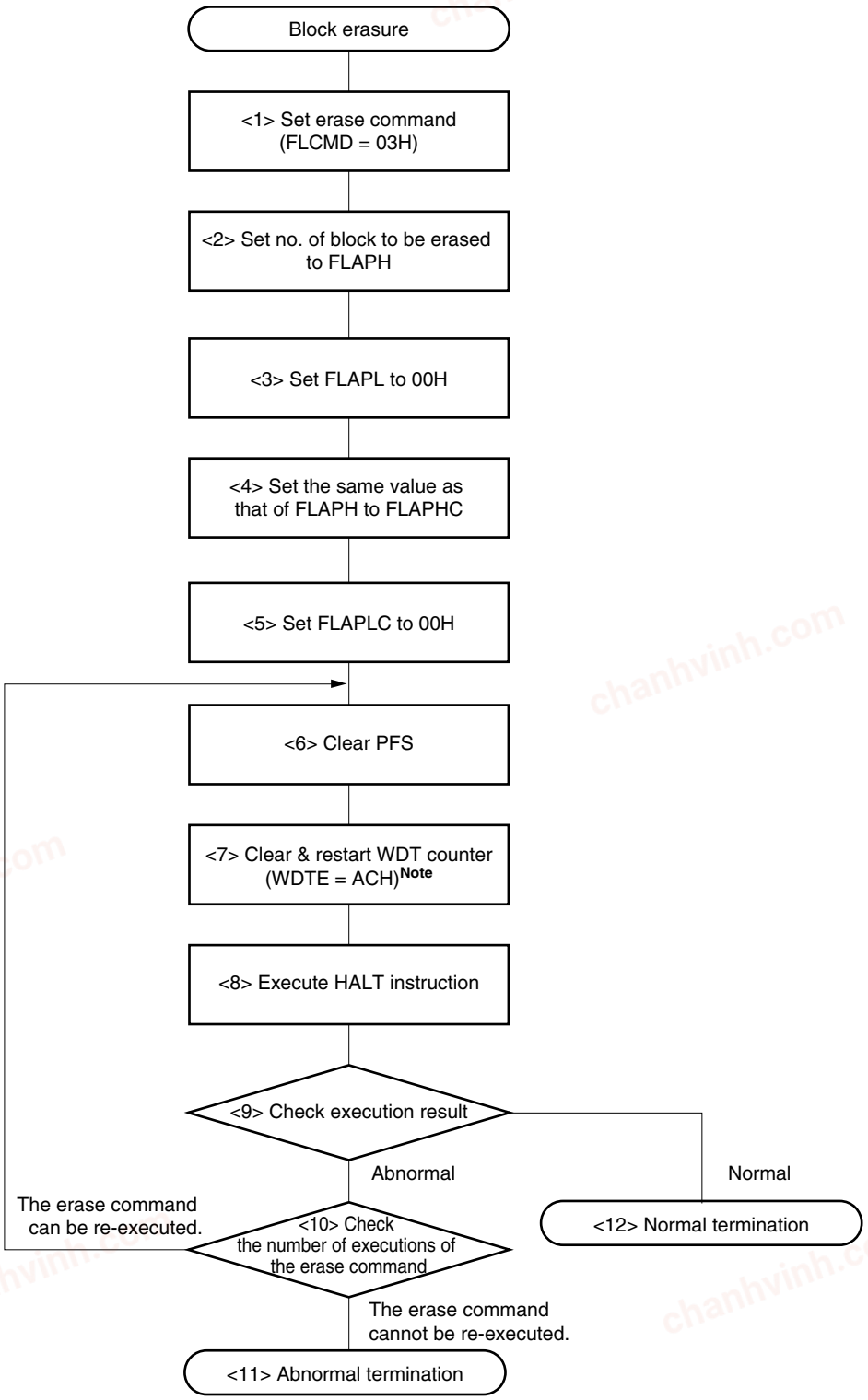
<1> Set 03H (block erase) to the flash program command register (FLCMD).
<2> Set the block number to be erased, to flash address pointer H (FLAPH).
<3> Set flash address pointer L (FLAPL) to 00H.
<4> Write the same value as FLAPH to the flash address pointer H compare register (FLAPHC).
<5> Set the flash address pointer L compare register (FLAPLC) to 00H.
<6> Clear the flash status register (PFS).
<7> Write ACH to the watchdog timer enable register (WDTE) (clear and restart the watchdog timer counter)[Note 1].
<8> Execute the HALT instruction then start self programming. (Execute an instruction immediately after the HALT instruction if self programming has been executed.)
<9> Check if a self programming error has occurred using bit 1 (VCERR) and bit 2 (WEPRERR) of PFS[Note 2].
Abnormal → <10>
Normal → <12>
<R> <10> If the number of times the erase command can be executed has not been exceeded, return to step <6> and re-execute the command. If the number of times the erase command can be executed has been exceeded, block erasure ends abnormally.
<11> Block erase processing is abnormally terminated.
<12> Block erase processing is normally terminated.

Notes 1. This setting is not required when the watchdog timer is not used.
<R> **2.** Separately check the WEPRERR bit to check for errors in executing the erase command on a write-prohibited area.

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<R>

Figure 16-20. Example of Block Erase Operation in Self Programming Mode



Note This setting is not required when the watchdog timer is not used.

Remark <1> to <12> in Figure 16-20 correspond to <1> to <12> in **16.8.6** (previous page).

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An example of a program that performs a block erase in self programming mode is shown below.

```
;----------------------------
;START
;----------------------------

<R>     MOV     B,#48           ; Specifies the number of times the erase command can be
                                ; executed.
                                ; (4.0 V to 5.5 V  Time for executing block erasure 100 times)

FlashBlockErase:
        MOV     FLCMD,#03H      ; Sets flash control command (block erase)
        MOV     FLAPH,#07H      ; Sets number of block to be erased (block 7 is specified here)
        MOV     FLAPL,#00H      ; Fixes FLAPL to "00H"
        MOV     FLAPHC,#07H     ; Sets erase block compare number (same value as that of FLAPH)
        MOV     FLAPLC,#00H     ; Fixes FLAPLC to "00H"

EraseRetry:
        MOV     PFS,#00H        ; Clears flash status register
        MOV     WDTE,#0ACH      ; Clears & restarts WDT
        HALT                    ; Self programming is started
        MOV     A,PFS
<R>     CMP     A,#00H          ; Checks execution result
        BZ      $StatusNormal   ; Normal termination
        DBNZ    B,$EraseRetry   ; Checks whether to re-execute the erase command.

;-------------------------------------------------------------------
;END (abnormal termination processing); Perform processing to shift to
     normal mode in order to return to normal processing
;-------------------------------------------------------------------
StatusError:


;-------------------------------------------------------------------
;END (normal termination processing)
;-------------------------------------------------------------------
StatusNormal:
```

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16.8.7 Example of block blank check operation in self programming mode

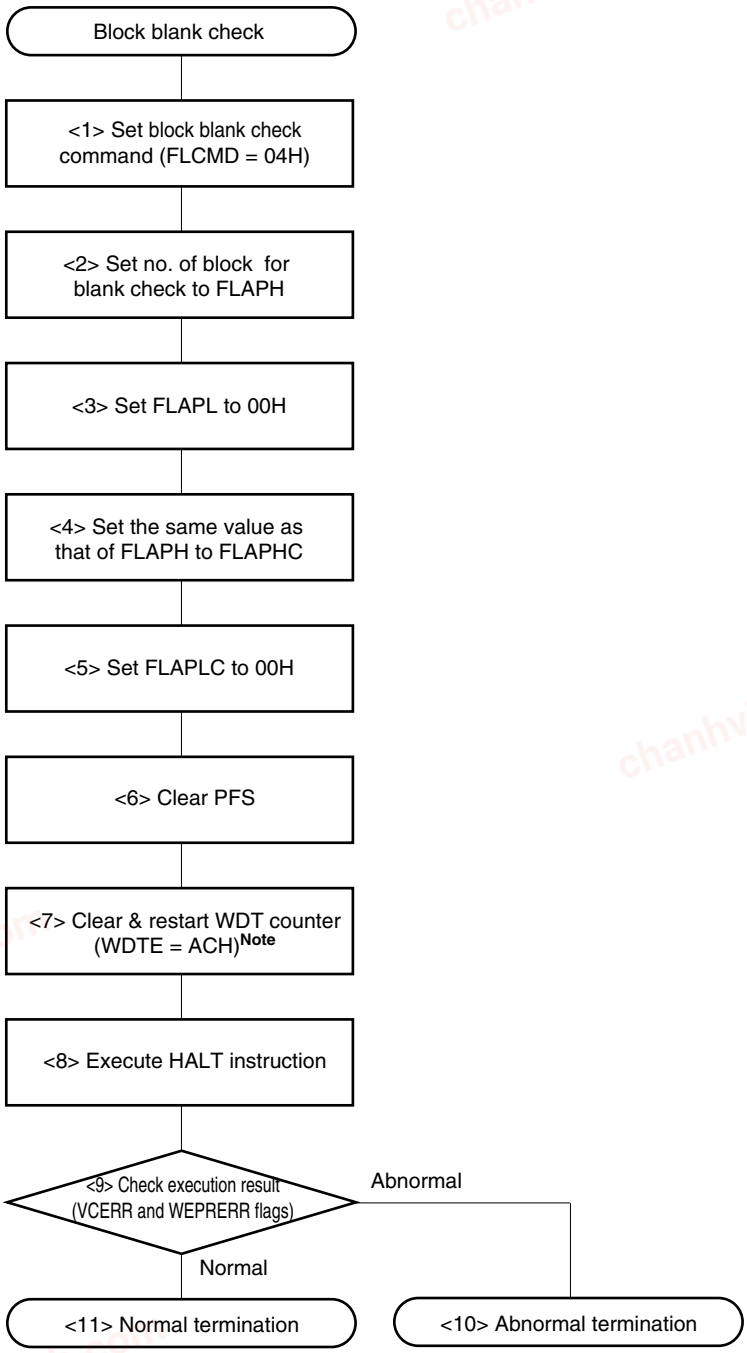
An example of the block blank check operation in self programming mode is explained below.

<1> Set 04H (block blank check) to the flash program command register (FLCMD).
<2> Set the number of block for which a blank check is performed, to flash address pointer H (FLAPH).
<3> Set flash address pointer L (FLAPL) to 00H.
<4> Write the same value as FLAPH to the flash address pointer H compare register (FLAPHC).
<5> Set the flash address pointer L compare register (FLAPLC) to FFH.
<6> Clear the flash status register (PFS).
<7> Write ACH to the watchdog timer enable register (WDTE) (clear and restart the watchdog timer counter)[Note].
<8> Execute the HALT instruction then start self programming. (Execute an instruction immediately after the HALT instruction if self programming has been executed.)
<9> Check if a self programming error has occurred using bit 1 (VCERR) and bit 2 (WEPRERR) of PFS.
Abnormal → <10>
Normal → <11>
<10> Block blank check is abnormally terminated.
<11> Block blank check is normally terminated.

Note This setting is not required when the watchdog timer is not used.

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Figure 16-21. Example of Block Blank Check Operation in Self Programming Mode



Note This setting is not required when the watchdog timer is not used.

Remark <1> to <11>in Figure 16-21 correspond to <1> to <11> in **16.8.7** (previous page).

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An example of a program that performs a block blank check in self programming mode is shown below.

```
;----------------------------
;START
;----------------------------

FlashBlockBlankCheck:
       MOV      FLCMD,#04H      ; Sets flash control command (block blank check)
       MOV      FLAPH,#07H      ; Sets number of block for blank check (block 7 is specified
                                ; here)
       MOV      FLAPL,#00H      ; Fixes FLAPL to "00H"
       MOV      FLAPHC,#07H     ; Sets blank check block compare number (same value as that of
                                ; FLAPH)
       MOV      FLAPLC,#0FFH    ; Fixes FLAPLC to "FFH"

       MOV      PFS,#00H        ; Clears flash status register
       MOV      WDTE,#0ACH      ; Clears & restarts WDT
       HALT                     ; Self programming is started
       MOV      A,PFS
       MOV      CmdStatus,A     ; Execution result is stored in variable
                                ; (CmdStatus = 0: normal termination, other than 0: abnormal
                                ; termination)

;----------------------------
;END
;----------------------------
```

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16.8.8 Example of byte write operation in self programming mode

An example of the byte write operation in self programming mode is explained below.

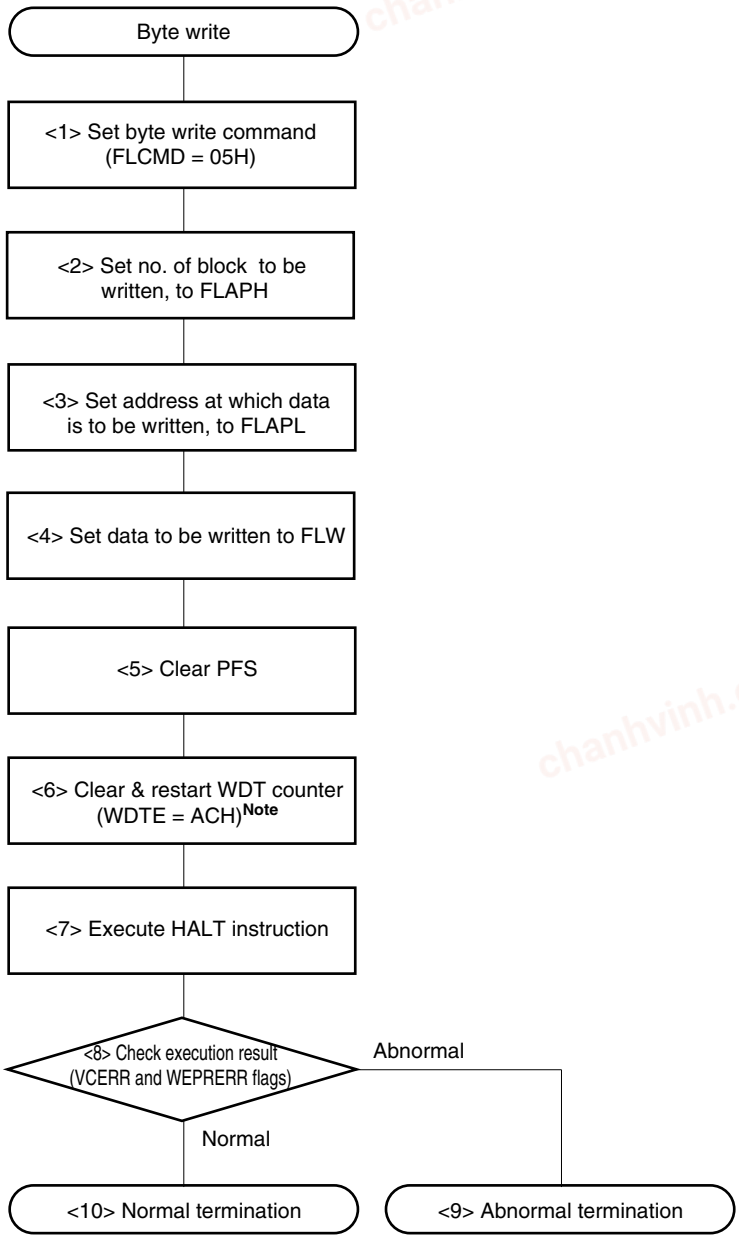
<1> Set 05H (byte write) to the flash program command register (FLCMD).
<2> Set the number of block to which data is to be written, to flash address pointer H (FLAPH).
<3> Set the address at which data is to be written, to flash address pointer L (FLAPL).
<4> Set the data to be written, to the flash write buffer register (FLW).
<5> Clear the flash status register (PFS).
<6> Write ACH to the watchdog timer enable register (WDTE) (clear and restart the watchdog timer counter)[Note].
<7> Execute the HALT instruction then start self programming. (Execute an instruction immediately after the HALT instruction if self programming has been executed.)
<8> Check if a self programming error has occurred using bit 1 (VCERR) and bit 2 (WEPRERR) of PFS.
Abnormal → <9>
Normal → <10>
<9> Byte write processing is abnormally terminated.
<10> Byte write processing is normally terminated.

Note This setting is not required when the watchdog timer is not used.

Caution If a write results in failure, erase the block once and write to it again.

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Figure 16-22. Example of Byte Write Operation in Self Programming Mode



Note This setting is not required when the watchdog timer is not used.

Remark <1> to <10> in Figure 16-22 correspond to <1> to <10> in **16.8.8** (previous page).

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An example of a program that performs a byte write in self programming mode is shown below.

```
;----------------------------
;START
;----------------------------
FlashWrite:
       MOV      FLCMD,#05H      ; Sets flash control command (byte write)
       MOV      FLAPH,#07H      ; Sets address to which data is to be written, with
                                ; FLAPH (block 7 is specified here)
       MOV      FLAPL,#20H      ; Sets address to which data is to be written, with
                                ; FLAPL (address 20H is specified here)
       MOV      FLW,#10H        ; Sets data to be written (10H is specified here)

       MOV      PFS,#00H        ; Clears flash status register
       MOV      WDTE,#0ACH      ; Clears & restarts WDT
       HALT                     ; Self programming is started
       MOV      A,PFS
       MOV      CmdStatus,A     ; Execution result is stored in variable
                                ; (CmdStatus = 0: normal termination, other than 0: abnormal
                                ; termination)

;----------------------------
;END
;----------------------------
```

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16.8.9 Example of internal verify operation in self programming mode

An example of the internal verify operation in self programming mode is explained below.

- Internal verify 1

<1> Set 01H (internal verify 1) to the flash program command register (FLCMD).
<2> Set the block number for which internal verify is performed, to flash address pointer H (FLAPH).
<3> Set 00H to the flash address pointer L (FLAPL).
<4> Write the same value as that of FLAPH to the flash address pointer H compare register (FLAPHC).
<5> Set FFH to the flash address pointer L compare register (FLAPLC).
<6> Clear the flash status register (PFS).
<7> Write ACH to the watchdog timer enable register (WDTE) (clear and restart the watchdog timer counter)[Note].
<8> Execute the HALT instruction then start self programming. (Execute an instruction immediately after the HALT instruction if self programming has been executed.)
<9> Check if a self programming error has occurred using bit 1 (VCERR) and bit 2 (WEPRERR) of PFS.
Abnormal → <10>
Normal → <11>
<10> Internal verify processing is terminated abnormally.
<11> Internal verify processing is terminated normally.

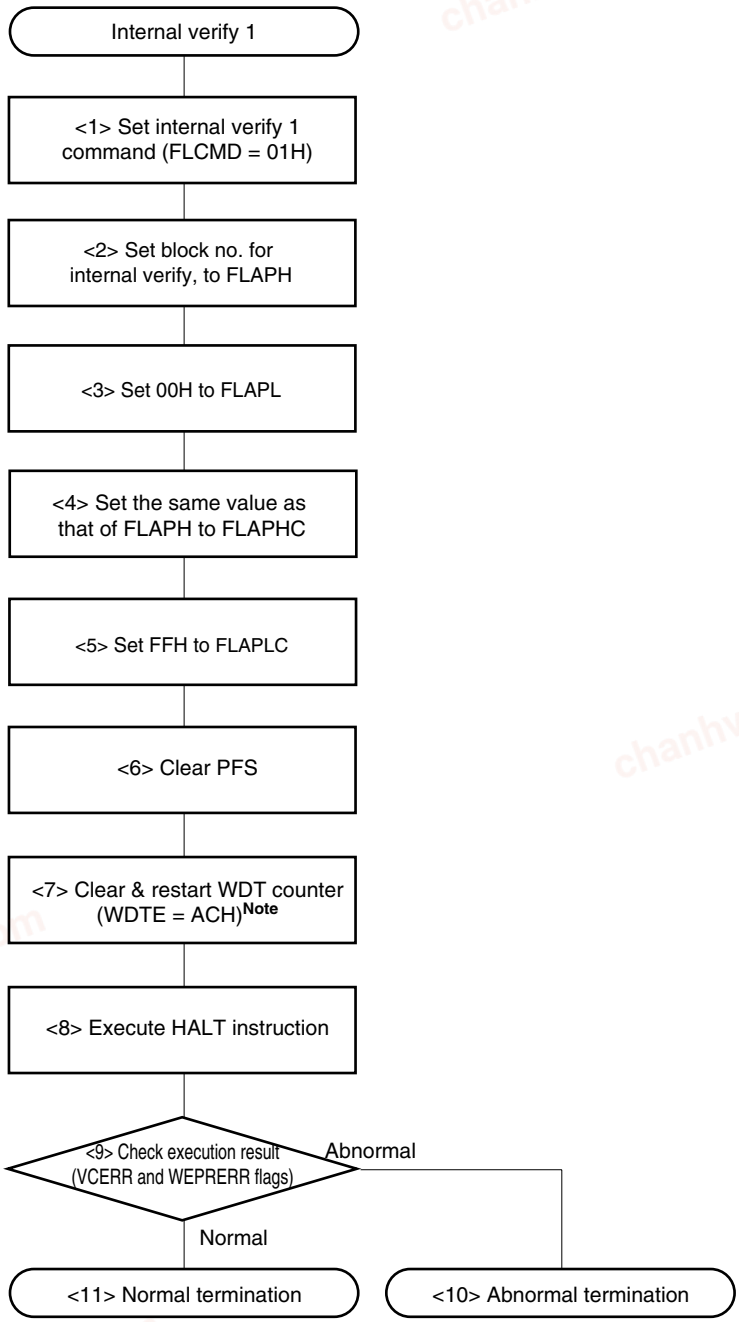
- Internal verify 2

<1> Set 02H (internal verify 2) to the flash program command register (FLCMD).
<2> Set the block number for which internal verify is performed, to flash address pointer H (FLAPH).
<3> Set the verify start address to the flash address pointer L (FLAPL).
<4> Write the same value as that of FLAPH to the flash address pointer H compare register (FLAPHC).
<5> Set the verify end address to the flash address pointer L compare register (FLAPLC).
<6> Clear the flash status register (PFS).
<7> Write ACH to the watchdog timer enable register (WDTE) (clear and restart the watchdog timer counter)[Note].
<8> Execute the HALT instruction then start self programming. (Execute an instruction immediately after the HALT instruction if self programming has been executed.)
<9> Check if a self programming error has occurred using bit 1 (VCERR) and bit 2 (WEPRERR) of PFS.
Abnormal → <10>
Normal → <11>
<10> Internal verify processing is terminated abnormally.
<11> Internal verify processing is terminated normally.

Note This setting is not required when the watchdog timer is not used.

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Figure 16-23. Example of Internal Verify 1 Operation in Self Programming Mode

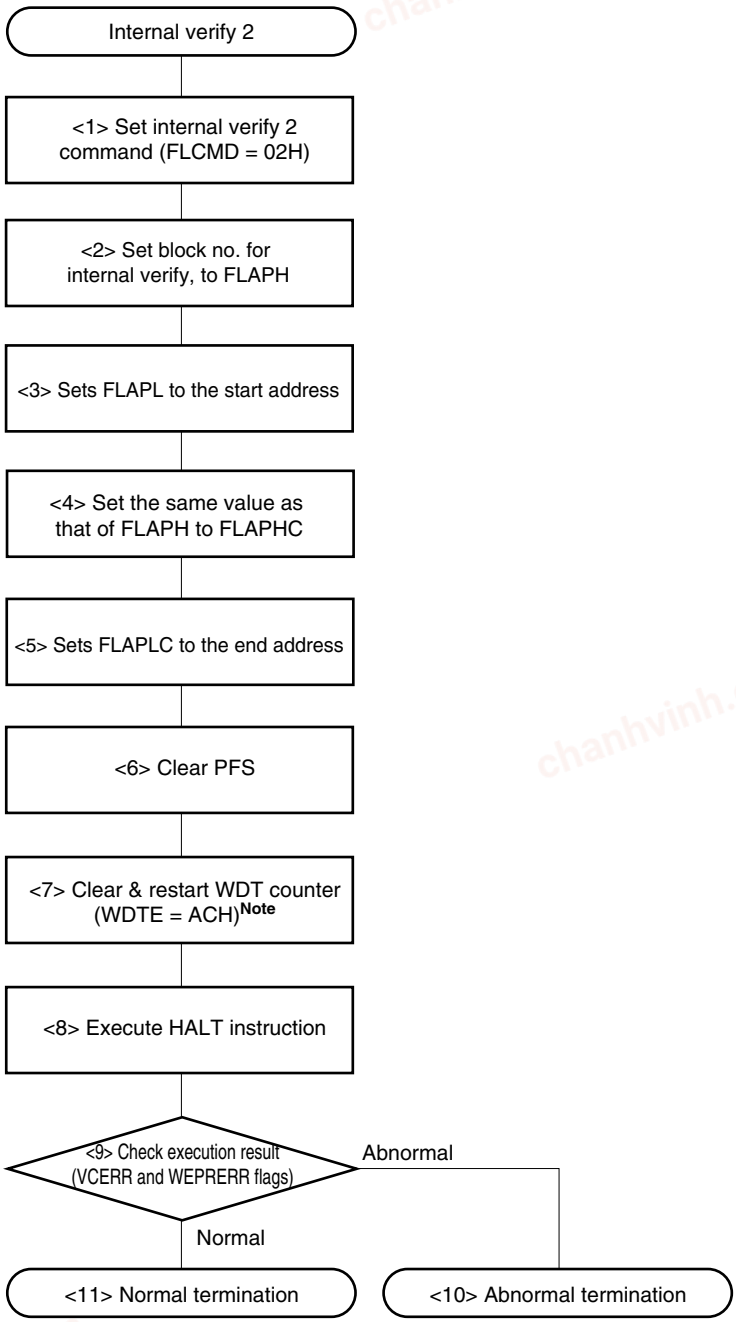


Note This setting is not required when the watchdog timer is not used.

Remark <1> to <11> in Figure 16-23 correspond to Internal verify 1 <1> to <11> in **16.8.9** (previous page).

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Figure 16-24. Example of Internal Verify 2 Operation in Self Programming Mode



Note This setting is not required when the watchdog timer is not used.

Remark <1> to <11> in Figure 16-24 correspond to Internal verify 2 <1> to <11> in **16.8.9** (the page before last).

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Example programs that perform internal verify 1 and 2 in self programming mode are shown below.

- Internal verify 1

```
;----------------------------
;START
;----------------------------
FlashVerify:
        MOV     FLCMD,#01H      ; Sets flash control command (internal verify 1)
        MOV     FLAPH,#07H      ; Sets block number for which internal verify is performed,
                                ; to FLAPH (Example: Block 7 is specified here)
        MOV     FLAPL,#00H      ; Sets 00H
        MOV     FLAPHC,#07H
        MOV     FLAPLC,#FFH     ; Sets FFH

        MOV     PFS,#00H        ; Clears flash status register
        MOV     WDTE,#0ACH      ; Clears & restarts WDT
        HALT                    ; Self programming is started
        MOV     A,PFS
        MOV     CmdStatus,A     ; Execution result is stored in variable
                                ; (CmdStatus = 0: normal termination, other than 0: abnormal
                                ; termination)

;----------------------------
;END
;----------------------------
```

- Internal verify 2

```
;----------------------------
;START
;----------------------------
FlashVerify:
        MOV     FLCMD,#02H      ; Sets flash control command (internal verify 2)
        MOV     FLAPH,#07H      ; Sets block number for which internal verify is
                                ; performed, to FLAPH (Example: Block 7 is specified here)
        MOV     FLAPL,#00H      ; Sets FLAPL to the start address for verify (Example: Address
                                ; 00H is specified here)
        MOV     FLAPHC,#07H
        MOV     FLAPLC,#20H     ; Sets FLAPLC to the end address for verify (Example: Address
                                ; 20H is specified here)

        MOV     PFS,#00H        ; Clears flash status register
        MOV     WDTE,#0ACH      ; Clears & restarts WDT
        HALT                    ; Self programming is started
        MOV     A,PFS
        MOV     CmdStatus,A     ; Execution result is stored in variable
                                ; (CmdStatus = 0: normal termination, other than 0: abnormal
                                ; termination)

;----------------------------
;END
;----------------------------
```

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16.8.10 Examples of operation when command execution time should be minimized in self programming mode

Examples of operation when the command execution time should be minimized in self programming mode are explained below.

(1) Erasure to blank check

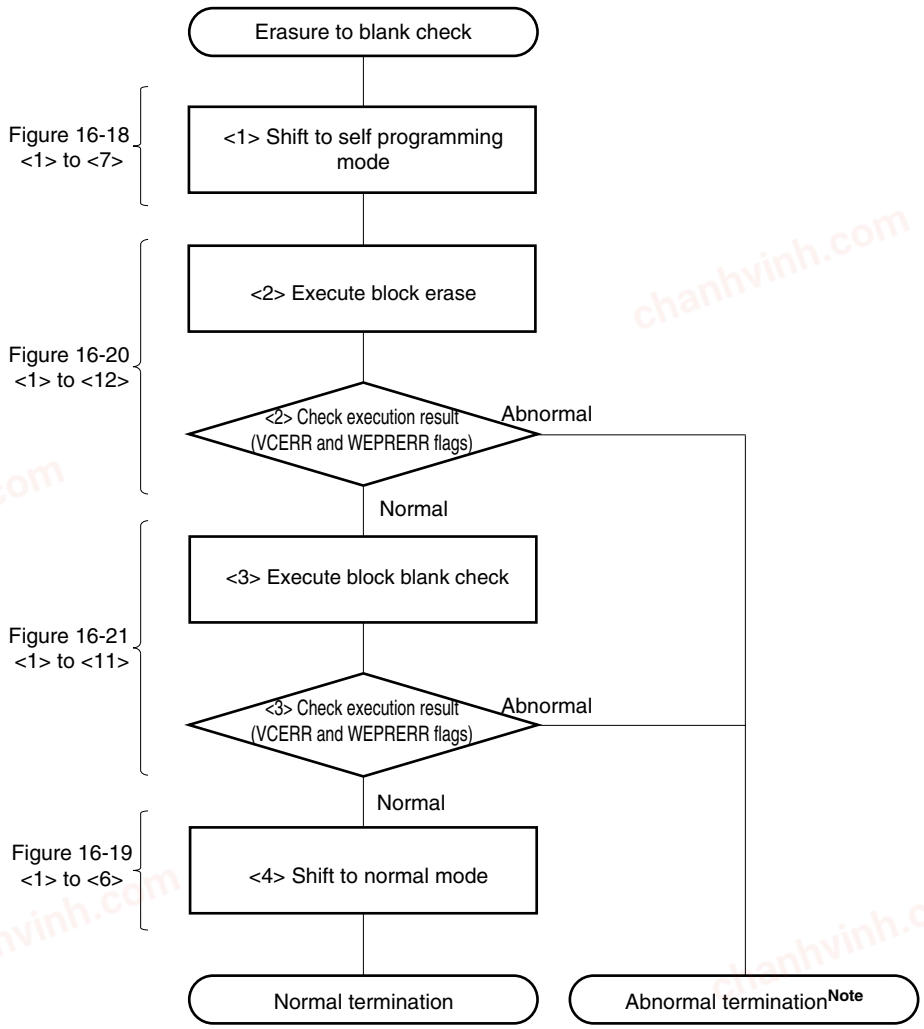
<1> Mode is shifted from normal mode to self programming mode (<1> to <7> in **16.8.4**)

<2> Execution of block erase → Error check (<1> to <12> in **16.8.6**)

<3> Execution of block blank check → Error check (<1> to <11> in **16.8.7**)

<4> Mode is shifted from self programming mode to normal mode (<1> to <6> in **16.8.5**)

Figure 16-25. Example of Operation When Command Execution Time Should Be Minimized (from Erasure to Blank Check)



Note Perform processing to shift to normal mode in order to return to normal processing.

Remark <1> to <4> in Figure 16-25 correspond to <1> to <4> in **16.8.10 (1)** above.

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An example of a program when the command execution time (from erasure to black check) should be minimized in self programming mode is shown below.

```
;---------------------------------------------------------------------
;START
;---------------------------------------------------------------------
        MOV     MK0,#11111111B   ; Masks all interrupts
        MOV     FLCMD,#00H       ; Clears FLCMD register

        DI

ModeOnLoop:                      ; Configure settings so that the CPU clock ≥ 1 MHz
        MOV     PFS,#00H         ; Clears flash status register
        MOV     PFCMD,#0A5H      ; PFCMD register control
        MOV     FLPMC,#01H       ; FLPMC register control (sets value)
        MOV     FLPMC,#0FEH      ; FLPMC register control (inverts set value)
        MOV     FLPMC,#01H       ; Sets self programming mode with FLPMC register control (sets
                                 ; value)

        NOP
        HALT
        BT      PFS.0,$ModeOnLoop ; Checks completion of write to specific registers
                                  ; Repeats the same processing when an error occurs

FlashBlockErase:
        MOV     FLCMD,#03H       ; Sets flash control command (block erase)
        MOV     FLAPH,#07H       ; Sets number of block to be erased (block 7 is specified
                                 ; here)
        MOV     FLAPL,#00H       ; Fixes FLAPL to "00H"
        MOV     FLAPHC,#07H      ; Sets erase block compare number (same value as that of
                                 ; FLAPH)
        MOV     FLAPLC,#00H      ; Fixes FLAPLC to "00H"

        MOV     WDTE,#0ACH       ; Clears & restarts WDT
        HALT                     ; Self programming is started
        MOV     A,PFS
        CMP     A,#00H
        BNZ     $StatusError     ; Checks erase error
                                 ; Performs abnormal termination processing when an error
                                 ; occurs.

FlashBlockBlankCheck:
        MOV     FLCMD,#04H       ; Sets flash control command (block blank check)
        MOV     FLAPH,#07H       ; Sets number of block for blank check (block 7 is specified
                                 ; here)
        MOV     FLAPL,#00H       ; Fixes FLAPL to "00H"
```

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```
        MOV     FLAPHC,#07H     ; Sets blank check block compare number (same value as of
                                ; FLAPH)
        MOV     FLAPLC,#0FFH    ; Fixes FLAPLC to "FFH"
        MOV     WDTE,#0ACH      ; Clears & restarts WDT
        HALT                    ; Self programming is started
        MOV     A,PFS
        CMP     A,#00H
        BNZ     $StatusError    ; Checks blank check error
                                ; Performs abnormal termination processing when an error
                                ; occurs.

        MOV     FLCMD,#00H      ; Clears FLCMD register
ModeOffLoop:
        MOV     PFS,#00H        ; Clears flash status register
        MOV     PFCMD,#0A5H     ; PFCMD register control
        MOV     FLPMC,#00H      ; FLPMC register control (sets value)
        MOV     FLPMC,#0FFH     ; FLPMC register control (inverts set value)
        MOV     FLPMC,#00H      ; Sets normal mode via FLPMC register control (sets value)

        BT      PFS.0,$ModeOffLoop ; Checks completion of write to specific registers
                                   ; Repeats the same processing when an error occurs
                                   ; Restore the CPU clock to its setting before the self
                                   ; programming, after normal completion of the specific
                                   ; sequence
        MOV     MK0,#INT_MK0    ; Restores interrupt mask flag

        EI

        BR      StatusNormal

;---------------------------------------------------------------------
;END (abnormal termination processing); Perform processing to shift to
      normal mode in order to return to normal processing
;---------------------------------------------------------------------
StatusError:

;---------------------------------------------------------------------
;END (normal termination processing)
;---------------------------------------------------------------------
StatusNormal:
```

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(2) Write to internal verify

<1> Mode is shifted from normal mode to self programming mode (<1> to <7> in **16.8.4**)

<2> Specification of source data for write

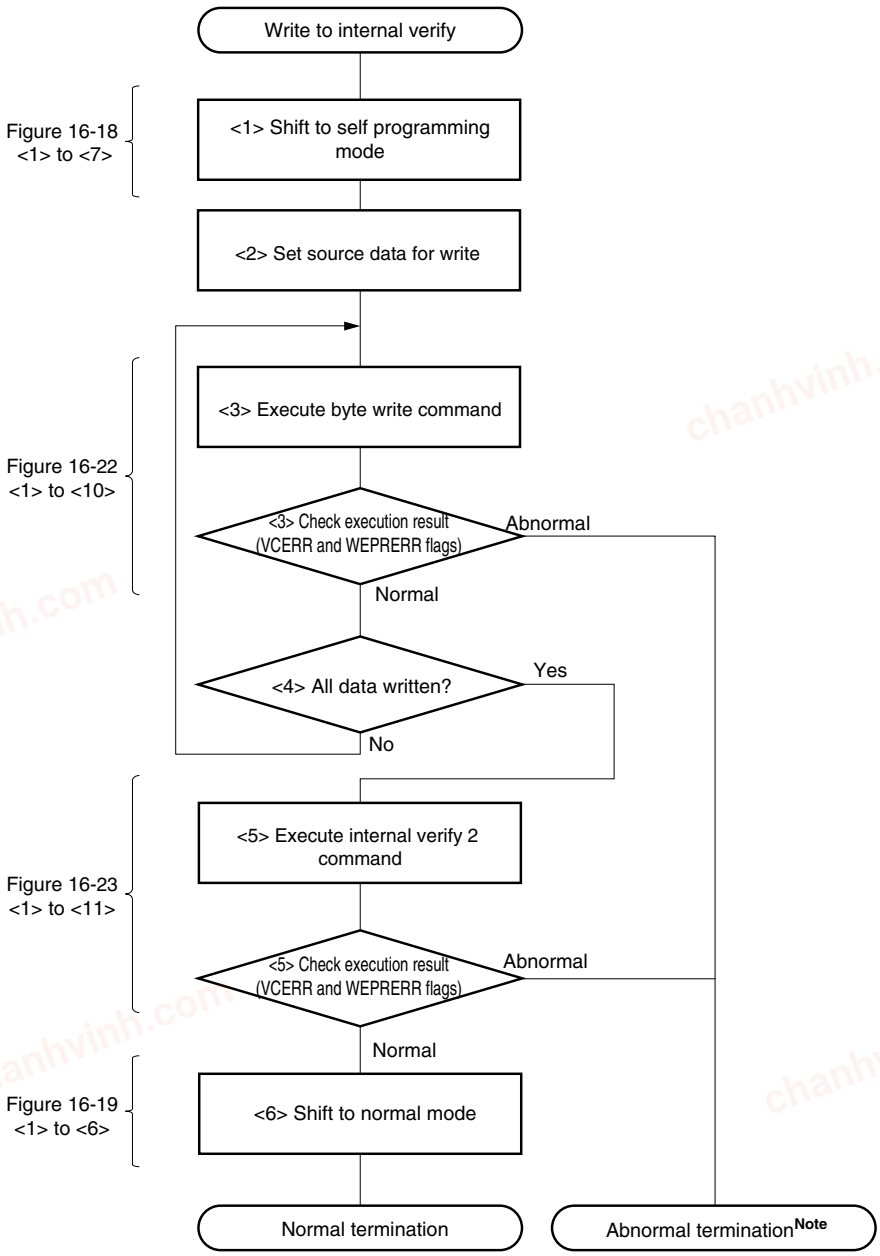
<3> Execution of byte write → Error check (<1> to <10> in **16.8.8**)

<4> <3> is repeated until all data are written.

<5> Execution of internal verify 2 → Error check (<1> to <11> in **16.8.9**)

<6> Mode is shifted from self programming mode to normal mode (<1> to <6> in **16.8.5**)

Figure 16-26. Example of Operation When Command Execution Time Should Be Minimized (from Write to Internal Verify)



Note Perform processing to shift to normal mode in order to return to normal processing.

Remark <1> to <6> in Figure 16-26 correspond to <1> to <6> in **16.8.10 (2)** above.

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An example of a program when the command execution time (from write to internal verify) should be minimized in self programming mode is shown below.

```
;---------------------------------------------------------------------
;START
;---------------------------------------------------------------------
        MOV     MK0,#11111111B   ; Masks all interrupts
        MOV     FLCMD,#00H       ; Clears FLCMD register
        DI

ModeOnLoop:                      ; Configure settings so that the CPU clock ≥ 1 MHz
        MOV     PFS,#00H         ; Clears flash status register
        MOV     PFCMD,#0A5H      ; PFCMD register control
        MOV     FLPMC,#01H       ; FLPMC register control (sets value)
        MOV     FLPMC,#0FEH      ; FLPMC register control (inverts set value)
        MOV     FLPMC,#01H       ; Sets self programming mode with FLPMC register control
                                 ; (sets value)

        NOP
        HALT
        BT      PFS.0,$ModeOnLoop ; Checks completion of write to specific registers
                                  ; Repeats the same processing when an error occurs

FlashWrite:
        MOVW    HL,#DataAdrTop   ; Sets address at which data to be written is located
        MOVW    DE,#WriteAdr     ; Sets address at which data is to be written
FlashWriteLoop:
        MOV     FLCMD,#05H       ; Sets flash control command (byte write)
        MOV     A,D
        MOV     FLAPH,A          ; Sets address at which data is to be written
        MOV     A,E
        MOV     FLAPL,A          ; Sets address at which data is to be written
        MOV     A,[HL]
        MOV     FLW,A            ; Sets data to be written

        MOV     WDTE,#0ACH       ; Clears & restarts WDT
        HALT                     ; Self programming is started
        MOV     A,PFS
        CMP     A,#00H
        BNZ     $StatusError     ; Checks write error
                                 ; Performs abnormal termination processing when an error
                                 ; occurs.

        INCW    HL               ; address at which data to be written is located + 1
        MOVW    AX,HL
        CMPW    AX,#DataAdrBtm   ; Performs internal verify processing
        BNC     $FlashVerify     ; if write of all data is completed
```

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```
        INCW    DE              ; Address at which data is to be written + 1
        BR      FlashWriteLoop

FlashVerify:
        MOVW    HL,#WriteAdr    ; Sets verify address

        MOV     FLCMD,#02H      ; Sets flash control command (internal verify 2)
        MOV     A,H
        MOV     FLAPH,A         ; Sets verify start address
        MOV     A,L
        MOV     FLAPL,A         ; Sets verify start address
        MOV     A,D
        MOV     FLAPHC,A        ; Sets verify end address
        MOV     A,E
        MOV     FLAPLC,A        ; Sets verify end address

        MOV     WDTE,#0ACH      ; Clears & restarts WDT
        HALT                    ; Self programming is started
        MOV     A,PFS
        CMP     A,#00H
        BNZ     $StatusError    ; Checks internal verify error
                                ; Performs abnormal termination processing when an error
                                ; occurs.

        MOV     FLCMD,#00H      ; Clears FLCMD register
ModeOffLoop:
        MOV     PFS,#00H        ; Clears flash status register
        MOV     PFCMD,#0A5H     ; PFCMD register control
        MOV     FLPMC,#00H      ; FLPMC register control (sets value)
        MOV     FLPMC,#0FFH     ; FLPMC register control (inverts set value)
        MOV     FLPMC,#00H      ; Sets normal mode via FLPMC register control (sets value)

        BT      PFS.0,$ModeOffLoop ; Checks completion of write to specific registers
                                   ; Repeats the same processing when an error occurs
                                   ; Restore the CPU clock to its setting before the self
                                   ; programming, after normal completion of the specific
                                   ; sequence
        MOV     MK0,#INT_MK0       ; Restores interrupt mask flag

        EI

        BR      StatusNormal

;---------------------------------------------------------------------
;END (abnormal termination processing); Perform processing to shift to
      normal mode in order to return to normal processing
;---------------------------------------------------------------------
StatusError:
```

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```
;-------------------------------------------------------------------
;END (normal termination processing)
;-------------------------------------------------------------------
StatusNormal:


;-------------------------------------------------------------------
; Data to be written
;-------------------------------------------------------------------
DataAdrTop:
        DB      XXH
        DB      XXH
        DB      XXH
        DB      XXH

          :
          :

        DB      XXH
DataAdrBtm:
;-------------------------------------------------------------------
```

Remark Internal verify 2 is used in the above program example. Use internal verify 1 to verify a whole block.

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16.8.11 Examples of operation when interrupt-disabled time should be minimized in self programming mode

Examples of operation when the interrupt-disabled time should be minimized in self programming mode are explained below.

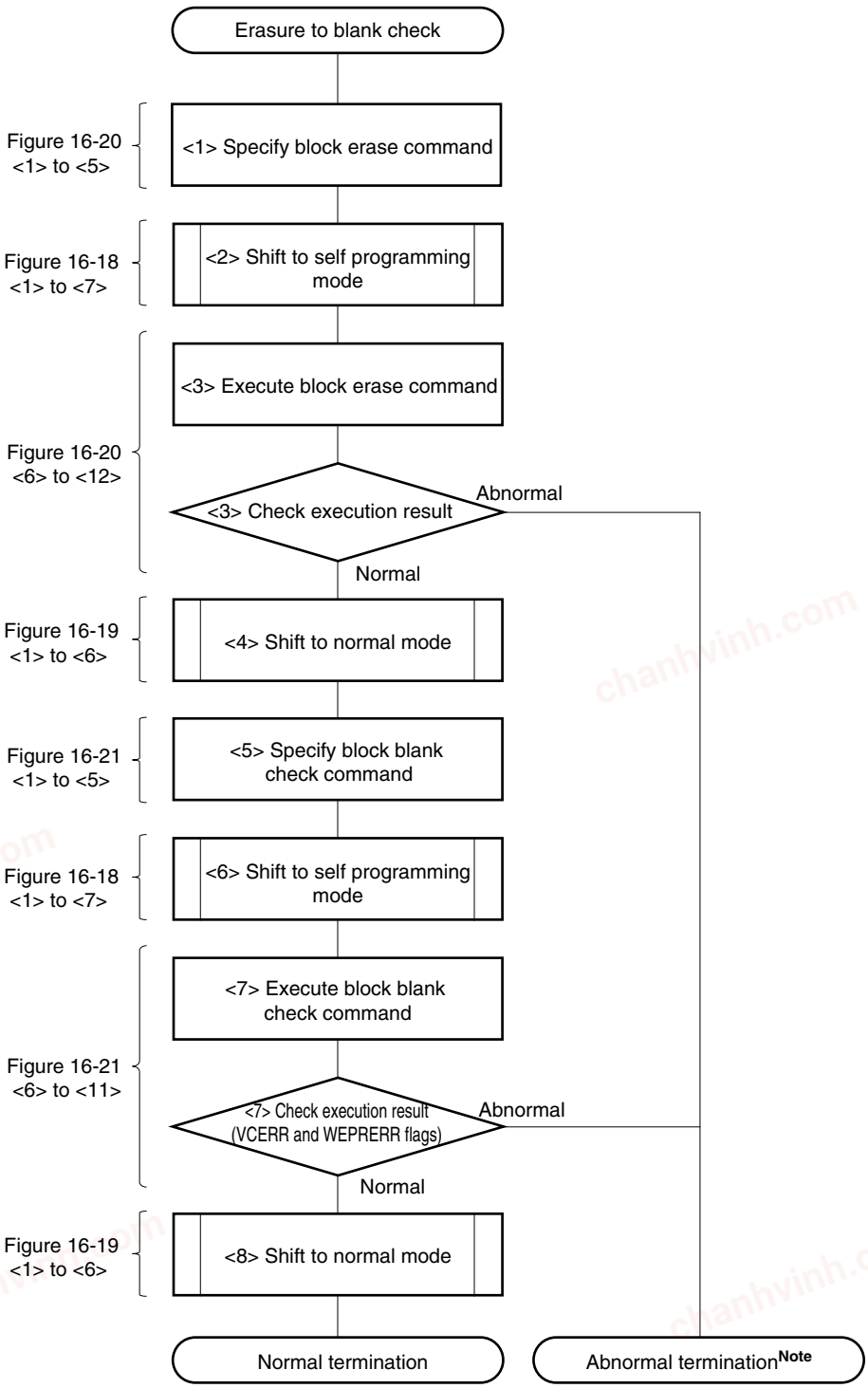
(1) Erasure to blank check

<1> Specification of block erase command (<1> to <5> in **16.8.6**)
<2> Mode is shifted from normal mode to self programming mode (<1> to <7> in **16.8.4**)
<3> Execution of block erase command → Error check (<6> to <12> in **16.8.6**)
<4> Mode is shifted from self programming mode to normal mode (<1> to <6> in **16.8.5**)
<5> Specification of block blank check command (<1> to <5> in **16.8.7**)
<6> Mode is shifted from normal mode to self programming mode (<1> to <7> in **16.8.4**)
<7> Execution of block blank check command → Error check (<6> to <11> in **16.8.7**)
<8> Mode is shifted from self programming mode to normal mode (<1> to <6> in **16.8.5**)

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<R>

Figure 16-27. Example of Operation When Interrupt-Disabled Time Should Be Minimized (from Erasure to Blank Check)



Note Perform processing to shift to normal mode in order to return to normal processing.

Remark <1> to <8> in Figure 16-27 correspond to <1> to <8> in **16.8.11 (1)** (previous page).

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An example of a program when the interrupt-disabled time (from erasure to blank check) should be minimized in self programming mode is shown below.

```
        ;---------------------------------------------------------------------
        ;START
        ;---------------------------------------------------------------------
<R>             MOV     B,#48           ; Specifies the number of times the erase command can be
                                        ; executed.
                                        ; (4.0 V to 5.5 V  Time for executing block erasure 100 times)
        FlashBlockErase:
                ; Sets erase command
                MOV     FLCMD,#03H      ; Sets flash control command (block erase)
                MOV     FLAPH,#07H      ; Sets number of block to be erased (block 7 is specified here)
                MOV     FLAPL,#00H      ; Fixes FLAPL to "00H"
                MOV     FLAPHC,#07H     ; Sets erase block compare number (same value as that of FLAPH)
                MOV     FLAPLC,#00H     ; Fixes FLAPLC to "00H"

                CALL    !ModeOn         ; Shift to self programming mode

<R>     EraseRetry:
                ; Execution of erase command
                MOV     PFS,#00H        ; Clears flash status register
                MOV     WDTE,#0ACH      ; Clears & restarts WDT
                HALT                    ; Self programming is started
                MOV     A,PFS
                CMP     A,#00H          ; Checks execution result
                BNZ     $RetryCheck     ; Checks erase error
                                        ; Performs abnormal termination processing when an error
                                        ; occurs.

                CALL    !ModeOff        ; Shift to normal mode


                ; Sets blank check command
                MOV     FLCMD,#04H      ; Sets flash control command (block blank check)
                MOV     FLAPH,#07H      ; Sets block number for blank check (block 7 is specified here)
                MOV     FLAPL,#00H      ; Fixes FLAPL to "00H"
                MOV     FLAPHC,#07H     ; Sets blank check block compare number (same value as that of
                                        ; FLAPH)
                MOV     FLAPLC,#0FFH    ; Fixes FLAPLC to "FFH"

                CALL    !ModeOn         ; Shift to self programming mode

                ; Execution of blank check command
                MOV     PFS,#00H        ; Clears flash status register
                MOV     WDTE,#0ACH      ; Clears & restarts WDT
                HALT                    ; Self programming is started
                MOV     A,PFS
```

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```
        CMP     A,#00H          ; Checks execution result
        BNZ     $StatusError    ; Checks blank check error
                                ; Performs abnormal termination processing when an error occurs

        CALL    !ModeOff        ; Shift to normal mode

        BR      StatusNormal
<R>     RetryCheck:
        DBNZ    B,$EraseRetry

;---------------------------------------------------------------------
;END (abnormal termination processing); Perform processing to shift to
      normal mode in order to return to normal processing
;---------------------------------------------------------------------
StatusError:


;---------------------------------------------------------------------
;END (normal termination processing)
;---------------------------------------------------------------------
StatusNormal:


;---------------------------------------------------------------------
;Processing to shift to self programming mode
;---------------------------------------------------------------------
ModeOn:
        MOV     MK0,#11111111B  ; Masks all interrupts
        MOV     FLCMD,#00H      ; Clears FLCMD register

        DI

ModeOnLoop:                     ; Configure settings so that the CPU clock ≥ 1 MHz
        MOV     PFS,#00H        ; Clears flash status register
        MOV     PFCMD,#0A5H     ; PFCMD register control
        MOV     FLPMC,#01H      ; FLPMC register control (sets value)
        MOV     FLPMC,#0FEH     ; FLPMC register control (inverts set value)
        MOV     FLPMC,#01H      ; Sets self programming mode via FLPMC register control (sets
                                ; value)

        NOP
        HALT
        BT      PFS.0,$ModeOnLoop ; Checks completion of write to specific registers
                                  ; Repeats the same processing when an error occurs

        RET
```

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```
;---------------------------------------------------------------------
; Processing to shift to normal mode
;---------------------------------------------------------------------
ModeOffLoop:
        MOV     FLCMD,#00H      ; Clears FLCMD register
        MOV     PFS,#00H        ; Clears flash status register
        MOV     PFCMD,#0A5H     ; PFCMD register control
        MOV     FLPMC,#00H      ; FLPMC register control (sets value)
        MOV     FLPMC,#0FFH     ; FLPMC register control (inverts set value)
        MOV     FLPMC,#00H      ; Sets normal mode via FLPMC register control (sets value)

        BT PFS.0,$ModeOffLoop   ; Checks completion of write to specific registers
                                ; Repeats the same processing when an error occurs.
                                ; After the specific sequence is correctly executed, restore
                                ; the CPU clock to its setting before the self programming
        MOV     MK0,#INT_MK0    ; Restores interrupt mask flag

        EI

        RET
```

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(2) Write to internal verify

<1> Specification of source data for write

<2> Specification of byte write command (<1> to <4> in **16.8.8**)

<3> Mode is shifted from normal mode to self programming mode (<1> to <7> in **16.8.4**)

<4> Execution of byte write command → Error check (<5> to <10> in **16.8.8**)

<5> Mode is shifted from self programming mode to normal mode (<1> to <6> in **16.8.5**)

<6> <2> to <5> is repeated until all data are written.

<7> The internal verify command is specified (<1> to <5> in **16.8.9**)

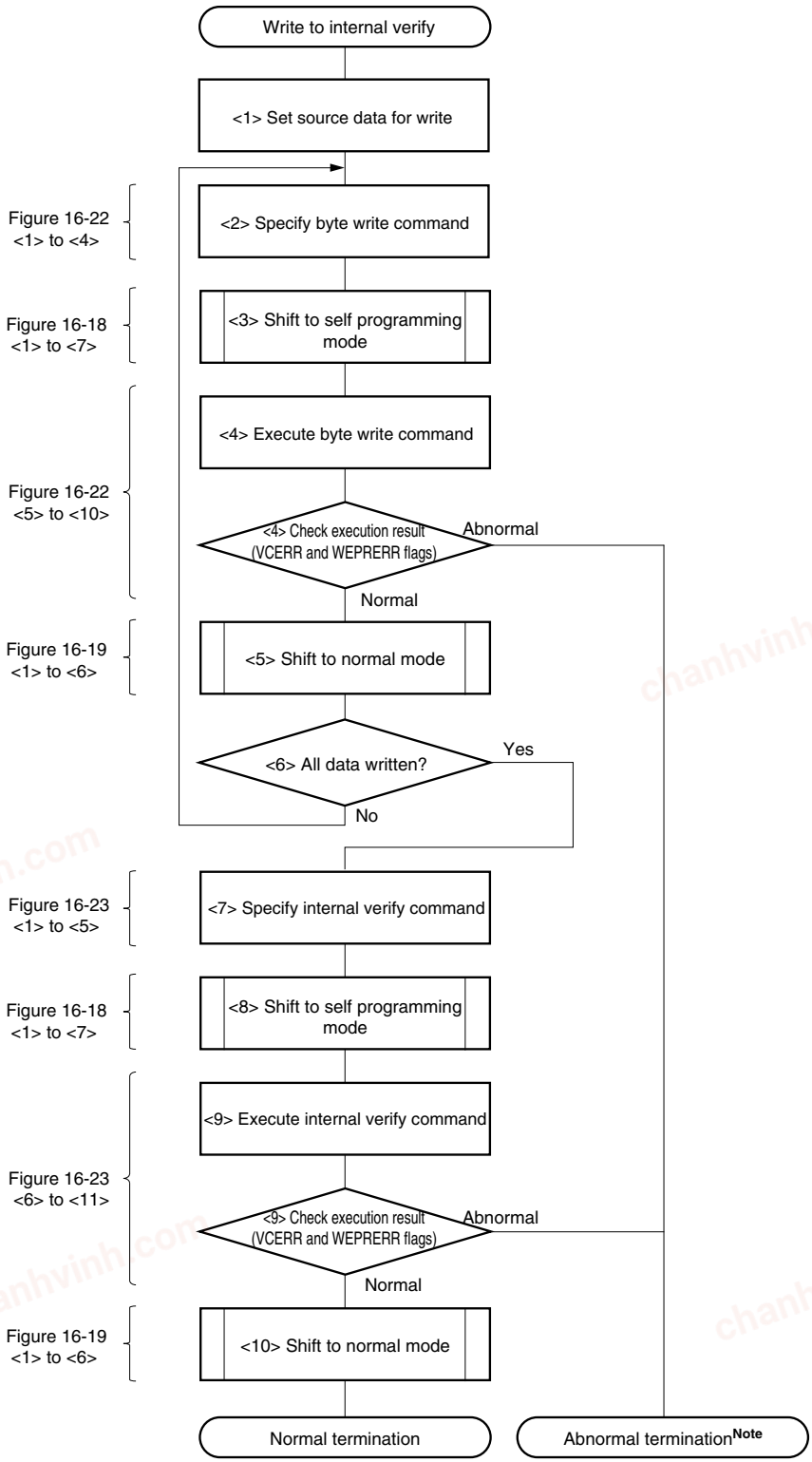
<8> Mode is shifted from normal mode to self programming mode (<1> to <7> in **16.8.4**)

<9> Execution of internal verify command → Error check (<6> to <11> in **16.8.9**)

<10> Mode is shifted from self programming mode to normal mode (<1> to <6> in **16.8.5**)

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Figure 16-28. Example of Operation When Interrupt-Disabled Time Should Be Minimized (from Write to Internal Verify)



Note Perform processing to shift to normal mode in order to return to normal processing.

Remark <1> to <10> in Figure 16-28 correspond to <1> to <10> in **16.8.11 (2)** (previous page).

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An example of a program when the interrupt-disabled time (from write to internal verify) should be minimized in self programming mode is shown below.

```
;---------------------------------------------------------------------
;START
;---------------------------------------------------------------------
       ; Sets write command
FlashWrite:
       MOVW     HL,#DataAdrTop  ; Sets address at which data to be written is located
       MOVW     DE,#WriteAdr    ; Sets address at which data is to be written

FlashWriteLoop:
       MOV      FLCMD,#05H      ; Sets flash control command (byte write)
       MOV      A,D
       MOV      FLAPH,A         ; Sets address at which data is to be written
       MOV      A,E
       MOV      FLAPL,A         ; Sets address at which data is to be written
       MOV      A,[HL]
       MOV      FLW,A           ; Sets data to be written

       CALL     !ModeOn         ; Shift to self programming mode

       ; Execution of write command
       MOV      PFS,#00H        ; Clears flash status register
       MOV      WDTE,#0ACH      ; Clears & restarts WDT
       HALT                     ; Self programming is started
       MOV      A,PFS
       CMP      A,#00H
       BNZ      $StatusError    ; Checks write error
                                ; Performs abnormal termination processing when an error
                                ; occurs.

       CALL     !ModeOff        ; Shift to normal mode

       MOV      MK0,#INT_MK0    ; Restores interrupt mask flag

       EI

       ; Judgment of writing all data
       INCW     HL              ; Address at which data to be written is located + 1
       MOVW     AX,HL
       CMPW     AX,#DataAdrBtm  ; Performs internal verify processing
       BNC      $FlashVerify    ; if write of all data is completed

       INCW     DE              ; Address at which data is to be written + 1
       BR       FlashWriteLoop

       ; Setting internal verify command
```

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```
FlashVerify:
        MOVW    HL,#WriteAdr    ; Sets verify address

        MOV     FLCMD,#02H      ; Sets flash control command (internal verify 2)
        MOV     A,H
        MOV     FLAPH,A         ; Sets verify start address
        MOV     A,L
        MOV     FLAPL,A         ; Sets verify start address
        MOV     A,D
        MOV     FLAPHC,A        ; Sets verify end address
        MOV     A,E
        MOV     FLAPLC,A        ; Sets verify end address

        CALL    !ModeOn         ; Shift to self programming mode

        ; Execution of internal verify command
        MOV     PFS,#00H        ; Clears flash status register
        MOV     WDTE,#0ACH      ; Clears & restarts WDT
        HALT                    ; Self programming is started
        MOV     A,PFS
        CMP     A,#00H
        BNZ     $StatusError    ; Checks internal verify error
                                ; Performs abnormal termination processing when an error occurs

        CALL    !ModeOff        ; Shift to normal mode

        BR      StatusNormal

;---------------------------------------------------------------------
;END (abnormal termination processing); Perform processing to shift to
      normal mode in order to return to normal processing
;---------------------------------------------------------------------
StatusError:


;---------------------------------------------------------------------
;END (normal termination processing)
;---------------------------------------------------------------------
StatusNormal:
```

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```
;---------------------------------------------------------------------
;Processing to shift to self programming mode
;---------------------------------------------------------------------
ModeOn:
        MOV     MK0,#11111111B  ; Masks all interrupts
        MOV     FLCMD,#00H      ; Clears FLCMD register

        DI

ModeOnLoop:                     ; Configure settings so that the CPU clock ≥ 1 MHz
        MOV     PFS,#00H        ; Clears flash status register
        MOV     PFCMD,#0A5H     ; PFCMD register control
        MOV     FLPMC,#01H      ; FLPMC register control (sets value)
        MOV     FLPMC,#0FEH     ; FLPMC register control (inverts set value)
        MOV     FLPMC,#01H      ; Sets self programming mode via FLPMC register control (sets
                                ; value)

        NOP
        HALT
        BT      PFS.0,$ModeOnLoop  ; Checks completion of write to specific registers
                                   ; Repeats the same processing when an error occurs

        RET


;---------------------------------------------------------------------
; Processing to shift to normal mode
;---------------------------------------------------------------------
ModeOffLoop:
        MOV     FLCMD,#00H      ; Clears FLCMD register
        MOV     PFS,#00H        ; Clears flash status register
        MOV     PFCMD,#0A5H     ; PFCMD register control
        MOV     FLPMC,#00H      ; FLPMC register control (sets value)
        MOV     FLPMC,#0FFH     ; FLPMC register control (inverts set value)
        MOV     FLPMC,#00H      ; Sets normal mode via FLPMC register control (sets value)

        BT      PFS.0,$ModeOffloop ; Checks completion of write to specific registers
                                   ; Repeats the same processing when an error occurs
                                   ; Restore the CPU clock to its setting before the self
                                   ; programming, after normal completion of the specific
                                   ; sequence
        MOV     MK0,#INT_MK0       ; Restores interrupt mask flag

        EI

        RET
```

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```
;---------------------------------------------------------------------
;Data to be written
;---------------------------------------------------------------------
DataAdrTop:
        DB      XXH
        DB      XXH
        DB      XXH
        DB      XXH

        :
        :

        DB      XXH
DataAdrBtm:
;---------------------------------------------------------------------
```

Remark Internal verify 2 is used in the above program example. Use internal verify 1 to verify a whole block.

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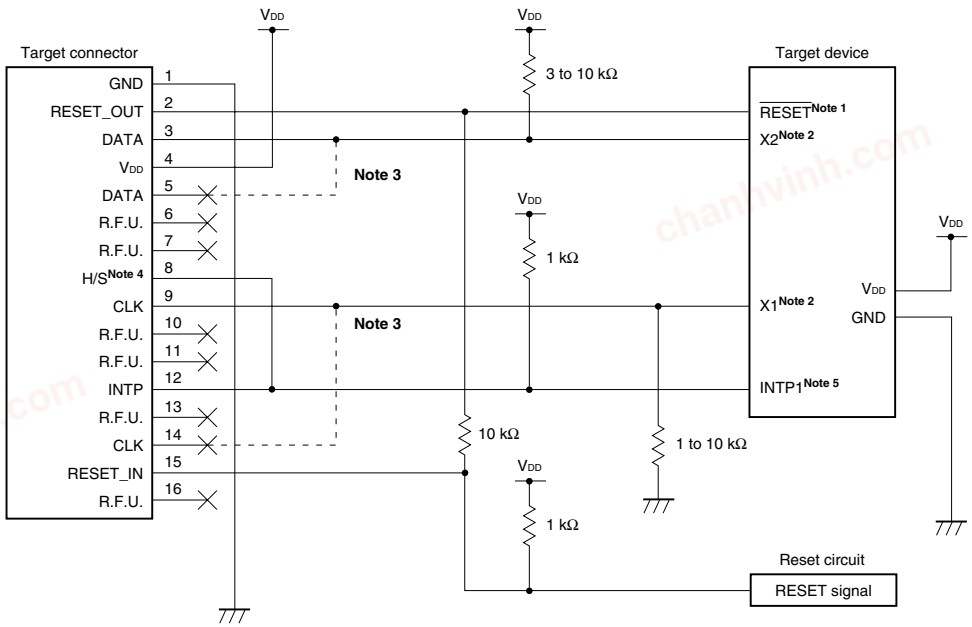
CHAPTER 17 ON-CHIP DEBUG FUNCTION

17.1 Connecting QB-MINI2 to 78K0S/KY1+

The 78K0S/KY1+ uses $\overline{\text{RESET}}$, X1, X2, INTP1, V_{DD}, and GND pins to communicate with the host machine via an on-chip debug emulator (QB-MINI2).

<R> **Caution The 78K0S/KY1+ has an on-chip debug function, which is provided for development and evaluation. Do not use the on-chip debug function in products designated for mass production, because the guaranteed number of rewritable times of the flash memory may be exceeded when this function is used, and product reliability therefore cannot be guaranteed. NEC Electronics is not liable for problems occurring when the on-chip debug function is used.**

Figure 17-1. Recommended Circuit Connection



Caution The constants described in the circuit connection example are reference values. If you perform flash programming aiming at mass production, thoroughly evaluate whether the specifications of the target device are satisfied.

Notes 1. The $\overline{\text{RESET}}$ pin is used to download the monitor program at debugger startup or to implement forced reset. Therefore, a pin that alternately functions as the $\overline{\text{RESET}}$ pin cannot be used. For reset pin connection, refer to **QB-MINI2 User's Manual (U18371E)**.

2. This is the pin connection when the X1 and X2 pins are not used in the target system. When using the X1 and X2 pins, refer to **17.1.2 Connection of X1 and X2 pins**.

3. No problem will occur if the dashed line portions are connected.

4. This pin is connected to enhance the accuracy of time measurement between run and break during debugging. Debugging is possible even if this pin is left open, but measurement error occurs in several ms units.

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Note 5. The INTP1 pin is used for communication between QB-MINI2 and the target device during debugging. When debugging is performed with QB-MINI2, therefore, the INTP1 pin and its alternate-function pin cannot be used. For INTP1 pin connection, refer to **17.1.1 Connection of INTP1 pin**.

Pins for communication depend on whether the monitor program has been written or not. (refer to **Table 17-1**) X1 and X2 pins can be used as I/O port pins or the pins for oscillation, after the monitor program has been written.

Table 17-1. Pins for communication with QB-MINI2

Before writing the monitor program	After writing the monitor program
X1, X2, $\overline{\text{RESET}}$, INTP1, V_{DD}, V_{SS}	$\overline{\text{RESET}}$, INTP1, V_{DD}, V_{SS}

17.1.1 Connection of INTP1 pin

The INTP1 pin is used only for communication between QB-MINI2 and the target device during debugging. Design circuits appropriately according to the relevant case among the cases shown below.

(1) INTP1 pin is not used in target system (as is illustrated in **Figure 17-1. Recommended Circuit Connection**)
→ See **Figure 17-2**.

(2) QB-MINI2 is used only for programming, not for debugging
→ See **Figure 17-3**.

(3) QB-MINI2 is used for debugging and debugging of the INTP1 pin is performed only with a real machine
→ See **Figure 17-4**.

Figure 17-2. Circuit Connection for the Case Where INTP1 Pin Is Not Used in Target System

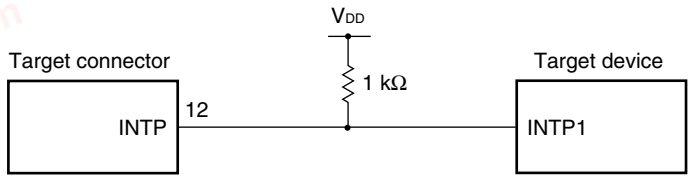
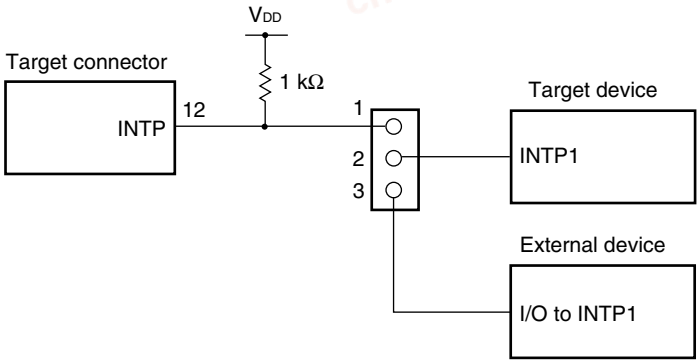


Figure 17-3. Circuit Connection for the Case Where QB-MINI2 Is Used Only for Programming



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Figure 17-4. Circuit Connection for the Case Where QB-MINI2 Is Used for Debugging and Debugging of INTP1 Pin Is Performed Only with Real Machine



* Jumper setting

When debugging with QB-MINI2 connected: 1-2 shorted

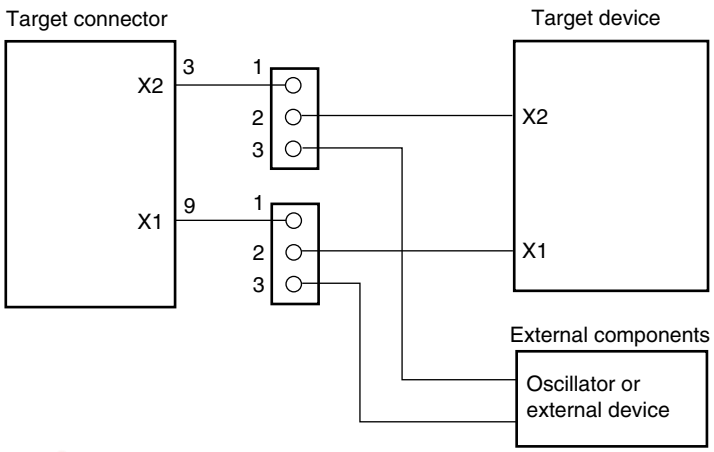
Other than above: 2-3 shorted

Caution If debugging is performed with a real machine running, without using QB-MINI2, write the user program using the QB-Programmer. Programs downloaded by the debugger include the monitor program, and such a program malfunctions if it is not controlled via QB-MINI2.

17.1.2 Connection of X1 and X2 pins

The X1 and X2 pins are used when the debugger is started for the first time (when downloading the monitor program) and when programming is performed with the QB-Programmer.

Figure 17-5. Circuit Connection for the Case Where X1 and X2 Pins Are Used in Target System



* Jumper setting

When debugger is started for the first time (downloading the monitor program) or when programming is performed with QB-Programmer: 1-2 shorted

Other than above: 2-3 shorted

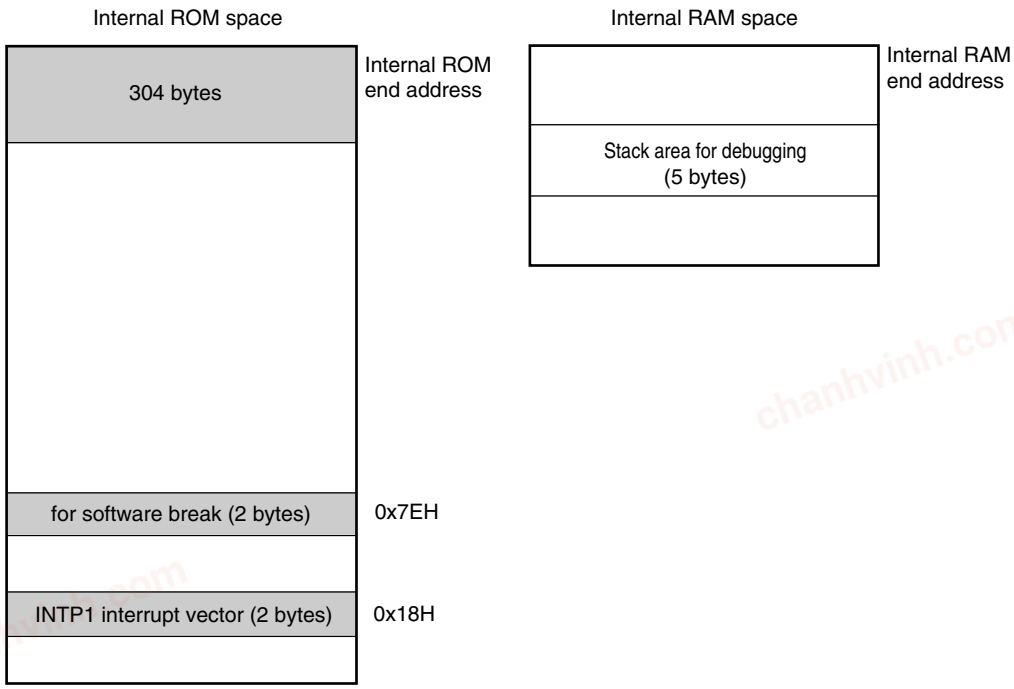
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17.2 Securing of user resources

The user must prepare the following to perform communication between QB-MINI2 and the target device and implement each debug function. For details of the setting, refer to **QB-MINI2 User's Manual (U18371E)**.

- Securement of memory space
  The shaded portions in Figure 17-6 are the areas reserved for placing the debug monitor program, so user programs cannot be allocated in these spaces.

Figure 17-6. Memory Spaces Where Debug Monitor Programs Are Allocated



- Securement of serial interface for communication
  The register settings, concerning the INTP1 pin used for communication between QB-MINI2 and the target device, performed by the debug monitor program must not be changed.

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CHAPTER 18 INSTRUCTION SET OVERVIEW

This chapter lists the instruction set of the 78K0S/KY1+. For details of the operation and machine language (instruction code) of each instruction, refer to **78K/0S Series Instructions User's Manual (U11047E)**.

18.1 Operation

18.1.1 Operand identifiers and description methods

Operands are described in "Operand" column of each instruction in accordance with the description method of the instruction operand identifier (refer to the assembler specifications for details). When there are two or more description methods, select one of them. Uppercase letters and the symbols #, !, $, and [ ] are key words and are described as they are. Each symbol has the following meaning.

- #: Immediate data specification
- !: Absolute address specification
- $: Relative address specification
- [ ]: Indirect address specification

In the case of immediate data, describe an appropriate numeric value or a label. When using a label, be sure to describe the #, !, $ and [ ] symbols.

For operand register identifiers, r and rp, either function names (X, A, C, etc.) or absolute names (names in parentheses in the table below, R0, R1, R2, etc.) can be used for description.

Table 18-1. Operand Identifiers and Description Methods

Identifier	Description Method
r rp sfr	X (R0), A (R1), C (R2), B (R3), E (R4), D (R5), L (R6), H (R7) AX (RP0), BC (RP1), DE (RP2), HL (RP3) Special function register symbol
saddr saddrp	FE20H to FF1FH Immediate data or labels FE20H to FF1FH Immediate data or labels (even addresses only)
addr16 addr5	0000H to FFFFH Immediate data or labels (only even addresses for 16-bit data transfer instructions) 0040H to 007FH Immediate data or labels (even addresses only)
word byte bit	16-bit immediate data or label 8-bit immediate data or label 3-bit immediate data or label

Remark For symbols of special function registers, see **Table 3-3 Special Function Registers**.

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18.1.2 Description of "Operation" column

A:	A register; 8-bit accumulator
X:	X register
B:	B register
C:	C register
D:	D register
E:	E register
H:	H register
L:	L register
AX:	AX register pair; 16-bit accumulator
BC:	BC register pair
DE:	DE register pair
HL:	HL register pair
PC:	Program counter
SP:	Stack pointer
PSW:	Program status word
CY:	Carry flag
AC:	Auxiliary carry flag
Z:	Zero flag
IE:	Interrupt request enable flag
( ):	Memory contents indicated by address or register contents in parentheses
×H, ×L:	Higher 8 bits and lower 8 bits of 16-bit register
∧:	Logical product (AND)
∨:	Logical sum (OR)
∀:	Exclusive logical sum (exclusive OR)
¯:	Inverted data
addr16:	16-bit immediate data or label
jdisp8:	Signed 8-bit data (displacement value)

18.1.3 Description of "Flag" column

(Blank):	Unchanged
0:	Cleared to 0
1:	Set to 1
×:	Set/cleared according to the result
R:	Previously saved value is stored

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18.2 Operation List

Mnemonic	Operand	Bytes	Clocks	Operation	Flag		
					Z	AC	CY
MOV	r, #byte	3	6	r ← byte			
	saddr, #byte	3	6	(saddr) ← byte			
	sfr, #byte	3	6	sfr ← byte			
	A, r Note 1	2	4	A ← r			
	r, A Note 1	2	4	r ← A			
	A, saddr	2	4	A ← (saddr)			
	saddr, A	2	4	(saddr) ← A			
	A, sfr	2	4	A ← sfr			
	sfr, A	2	4	sfr ← A			
	A, !addr16	3	8	A ← (addr16)			
	!addr16, A	3	8	(addr16) ← A			
	PSW, #byte	3	6	PSW ← byte	×	×	×
	A, PSW	2	4	A ← PSW			
	PSW, A	2	4	PSW ← A	×	×	×
	A, [DE]	1	6	A ← (DE)			
	[DE], A	1	6	(DE) ← A			
	A, [HL]	1	6	A ← (HL)			
	[HL], A	1	6	(HL) ← A			
	A, [HL + byte]	2	6	A ← (HL + byte)			
	[HL + byte], A	2	6	(HL + byte) ← A			
XCH	A, X	1	4	A ↔ X			
	A, r Note 2	2	6	A ↔ r			
	A, saddr	2	6	A ↔ (saddr)			
	A, sfr	2	6	A ↔ sfr			
	A, [DE]	1	8	A ↔ (DE)			
	A, [HL]	1	8	A ↔ (HL)			
	A, [HL, byte]	2	8	A ↔ (HL + byte)			

Notes 1. Except r = A.

2. Except r = A, X.

Remark One instruction clock cycle is one CPU clock cycle (f_{CPU}) selected by the processor clock control register (PCC).

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Mnemonic	Operand	Bytes	Clocks	Operation	Flag		
					Z	AC	CY
MOVW	rp, #word	3	6	rp ← word			
	AX, saddrp	2	6	AX ← (saddrp)			
	saddrp, AX	2	8	(saddrp) ← AX			
	AX, rp Note	1	4	AX ← rp			
	rp, AX Note	1	4	rp ← AX			
XCHW	AX, rp Note	1	8	AX ↔ rp			
ADD	A, #byte	2	4	A, CY ← A + byte	×	×	×
	saddr, #byte	3	6	(saddr), CY ← (saddr) + byte	×	×	×
	A, r	2	4	A, CY ← A + r	×	×	×
	A, saddr	2	4	A, CY ← A + (saddr)	×	×	×
	A, !addr16	3	8	A, CY ← A + (addr16)	×	×	×
	A, [HL]	1	6	A, CY ← A + (HL)	×	×	×
	A, [HL + byte]	2	6	A, CY ← A + (HL + byte)	×	×	×
ADDC	A, #byte	2	4	A, CY ← A + byte + CY	×	×	×
	saddr, #byte	3	6	(saddr), CY ← (saddr) + byte + CY	×	×	×
	A, r	2	4	A, CY ← A + r + CY	×	×	×
	A, saddr	2	4	A, CY ← A + (saddr) + CY	×	×	×
	A, !addr16	3	8	A, CY ← A + (addr16) + CY	×	×	×
	A, [HL]	1	6	A, CY ← A + (HL) + CY	×	×	×
	A, [HL + byte]	2	6	A, CY ← A + (HL + byte) + CY	×	×	×
SUB	A, #byte	2	4	A, CY ← A – byte	×	×	×
	saddr, #byte	3	6	(saddr), CY ← (saddr) – byte	×	×	×
	A, r	2	4	A, CY ← A – r	×	×	×
	A, saddr	2	4	A, CY ← A – (saddr)	×	×	×
	A, !addr16	3	8	A, CY ← A – (addr16)	×	×	×
	A, [HL]	1	6	A, CY ← A – (HL)	×	×	×
	A, [HL + byte]	2	6	A, CY ← A – (HL + byte)	×	×	×

Note Only when rp = BC, DE, or HL.

Remark One instruction clock cycle is one CPU clock cycle (f_{CPU}) selected by the processor clock control register (PCC).

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Mnemonic	Operand	Bytes	Clocks	Operation	Flag		
					Z	AC	CY
SUBC	A, #byte	2	4	A, CY ← A – byte – CY	×	×	×
	saddr, #byte	3	6	(saddr), CY ← (saddr) – byte – CY	×	×	×
	A, r	2	4	A, CY ← A – r – CY	×	×	×
	A, saddr	2	4	A, CY ← A – (saddr) – CY	×	×	×
	A, !addr16	3	8	A, CY ← A – (addr16) – CY	×	×	×
	A, [HL]	1	6	A, CY ← A – (HL) – CY	×	×	×
	A, [HL + byte]	2	6	A, CY ← A – (HL + byte) – CY	×	×	×
AND	A, #byte	2	4	A ← A ∧ byte	×		
	saddr, #byte	3	6	(saddr) ← (saddr) ∧ byte	×		
	A, r	2	4	A ← A ∧ r	×		
	A, saddr	2	4	A ← A ∧ (saddr)	×		
	A, !addr16	3	8	A ← A ∧ (addr16)	×		
	A, [HL]	1	6	A ← A ∧ (HL)	×		
	A, [HL + byte]	2	6	A ← A ∧ (HL + byte)	×		
OR	A, #byte	2	4	A ← A ∨ byte	×		
	saddr, #byte	3	6	(saddr) ← (saddr) ∨ byte	×		
	A, r	2	4	A ← A ∨ r	×		
	A, saddr	2	4	A ← A ∨ (saddr)	×		
	A, !addr16	3	8	A ← A ∨ (addr16)	×		
	A, [HL]	1	6	A ← A ∨ (HL)	×		
	A, [HL + byte]	2	6	A ← A ∨ (HL + byte)	×		
XOR	A, #byte	2	4	A ← A ∨̄ byte	×		
	saddr, #byte	3	6	(saddr) ← (saddr) ∨̄ byte	×		
	A, r	2	4	A ← A ∨̄ r	×		
	A, saddr	2	4	A ← A ∨̄ (saddr)	×		
	A, !addr16	3	8	A ← A ∨̄ (addr16)	×		
	A, [HL]	1	6	A ← A ∨̄ (HL)	×		
	A, [HL + byte]	2	6	A ← A ∨̄ (HL + byte)	×		

Remark One instruction clock cycle is one CPU clock cycle (f_{CPU}) selected by the processor clock control register (PCC).

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Mnemonic	Operand	Bytes	Clocks	Operation	Flag		
					Z	AC	CY
CMP	A, #byte	2	4	A – byte	×	×	×
	saddr, #byte	3	6	(saddr) – byte	×	×	×
	A, r	2	4	A – r	×	×	×
	A, saddr	2	4	A – (saddr)	×	×	×
	A, !addr16	3	8	A – (addr16)	×	×	×
	A, [HL]	1	6	A – (HL)	×	×	×
	A, [HL + byte]	2	6	A – (HL + byte)	×	×	×
ADDW	AX, #word	3	6	AX, CY ← AX + word	×	×	×
SUBW	AX, #word	3	6	AX, CY ← AX – word	×	×	×
CMPW	AX, #word	3	6	AX – word	×	×	×
INC	r	2	4	r ← r + 1	×	×	
	saddr	2	4	(saddr) ← (saddr) + 1	×	×	
DEC	r	2	4	r ← r – 1	×	×	
	saddr	2	4	(saddr) ← (saddr) – 1	×	×	
INCW	rp	1	4	rp ← rp + 1			
DECW	rp	1	4	rp ← rp – 1			
ROR	A, 1	1	2	$(CY, A_7 \leftarrow A_0, A_{m-1} \leftarrow A_m) \times 1$			×
ROL	A, 1	1	2	$(CY, A_0 \leftarrow A_7, A_{m+1} \leftarrow A_m) \times 1$			×
RORC	A, 1	1	2	$(CY \leftarrow A_0, A_7 \leftarrow CY, A_{m-1} \leftarrow A_m) \times 1$			×
ROLC	A, 1	1	2	$(CY \leftarrow A_7, A_0 \leftarrow CY, A_{m+1} \leftarrow A_m) \times 1$			×
SET1	saddr.bit	3	6	(saddr.bit) ← 1			
	sfr.bit	3	6	sfr.bit ← 1			
	A.bit	2	4	A.bit ← 1			
	PSW.bit	3	6	PSW.bit ← 1	×	×	×
	[HL].bit	2	10	(HL).bit ← 1			
CLR1	saddr.bit	3	6	(saddr.bit) ← 0			
	sfr.bit	3	6	sfr.bit ← 0			
	A.bit	2	4	A.bit ← 0			
	PSW.bit	3	6	PSW.bit ← 0	×	×	×
	[HL].bit	2	10	(HL).bit ← 0			
SET1	CY	1	2	CY ← 1			1
CLR1	CY	1	2	CY ← 0			0
NOT1	CY	1	2	$CY \leftarrow \overline{CY}$			×

Remark One instruction clock cycle is one CPU clock cycle (f_{CPU}) selected by the processor clock control register (PCC).

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Mnemonic	Operand	Bytes	Clocks	Operation	Flag		
					Z	AC	CY
CALL	!addr16	3	6	(SP – 1) ← (PC + 3)H, (SP – 2) ← (PC + 3)L, PC ← addr16, SP ← SP – 2			
CALLT	[addr5]	1	8	(SP – 1) ← (PC + 1)H, (SP – 2) ← (PC + 1)L, PCH ← (00000000, addr5 + 1), PCL ← (00000000, addr5), SP ← SP – 2			
RET		1	6	PCH ← (SP + 1), PCL ← (SP), SP ← SP + 2			
RETI		1	8	PCH ← (SP + 1), PCL ← (SP), PSW ← (SP + 2), SP ← SP + 3, NMIS ← 0	R	R	R
PUSH	PSW	1	2	(SP – 1) ← PSW, SP ← SP – 1			
	rp	1	4	(SP – 1) ← rpH, (SP – 2) ← rpL, SP ← SP – 2			
POP	PSW	1	4	PSW ← (SP), SP ← SP + 1	R	R	R
	rp	1	6	rpH ← (SP + 1), rpL ← (SP), SP ← SP + 2			
MOVW	SP, AX	2	8	SP ← AX			
	AX, SP	2	6	AX ← SP			
BR	!addr16	3	6	PC ← addr16			
	$addr16	2	6	PC ← PC + 2 + jdisp8			
	AX	1	6	PCH ← A, PCL ← X			
BC	$saddr16	2	6	PC ← PC + 2 + jdisp8 if CY = 1			
BNC	$saddr16	2	6	PC ← PC + 2 + jdisp8 if CY = 0			
BZ	$saddr16	2	6	PC ← PC + 2 + jdisp8 if Z = 1			
BNZ	$saddr16	2	6	PC ← PC + 2 + jdisp8 if Z = 0			
BT	saddr.bit, $addr16	4	10	PC ← PC + 4 + jdisp8 if (saddr.bit) = 1			
	sfr.bit, $addr16	4	10	PC ← PC + 4 + jdisp8 if sfr.bit = 1			
	A.bit, $addr16	3	8	PC ← PC + 3 + jdisp8 if A.bit = 1			
	PSW.bit, $addr16	4	10	PC ← PC + 4 + jdisp8 if PSW.bit = 1			
BF	saddr.bit, $addr16	4	10	PC ← PC + 4 + jdisp8 if (saddr.bit) = 0			
	sfr.bit, $addr16	4	10	PC ← PC + 4 + jdisp8 if sfr.bit = 0			
	A.bit, $addr16	3	8	PC ← PC + 3 + jdisp8 if A.bit = 0			
	PSW.bit, $addr16	4	10	PC ← PC + 4 + jdisp8 if PSW.bit = 0			
DBNZ	B, $addr16	2	6	B ← B – 1, then PC ← PC + 2 + jdisp8 if B ≠ 0			
	C, $addr16	2	6	C ← C – 1, then PC ← PC + 2 + jdisp8 if C ≠ 0			
	saddr, $addr16	3	8	(saddr) ← (saddr) – 1, then PC ← PC + 3 + jdisp8 if (saddr) ≠ 0			
NOP		1	2	No Operation			
EI		3	6	IE ← 1 (Enable Interrupt)			
DI		3	6	IE ← 0 (Disable Interrupt)			
HALT		1	2	Set HALT Mode			
STOP		1	2	Set STOP Mode			

Remark One instruction clock cycle is one CPU clock cycle (f_{CPU}) selected by the processor clock control register (PCC).

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18.3 Instructions Listed by Addressing Type

(1) 8-bit instructions

MOV, XCH, ADD, ADDC, SUB, SUBC, AND, OR, XOR, CMP, INC, DEC, ROR, ROL, RORC, ROLC, PUSH, POP, DBNZ

1st Operand \ 2nd Operand	#byte	A	r	sfr	saddr	!addr16	PSW	[DE]	[HL]	[HL + byte]	$addr16	1	None
A	ADD ADDC SUB SUBC AND OR XOR CMP		MOV[Note] XCH[Note] ADD ADDC SUB SUBC AND OR XOR CMP	MOV XCH	MOV XCH ADD ADDC SUB SUBC AND OR XOR CMP	MOV ADD ADDC SUB SUBC AND OR XOR CMP	MOV	MOV XCH	MOV XCH ADD ADDC SUB SUBC AND OR XOR CMP	MOV XCH ADD ADDC SUB SUBC AND OR XOR CMP		ROR ROL RORC ROLC	
r	MOV	MOV											INC DEC
B, C											DBNZ		
sfr	MOV	MOV											
saddr	MOV ADD ADDC SUB SUBC AND OR XOR CMP	MOV									DBNZ		INC DEC
!addr16		MOV											
PSW	MOV	MOV											PUSH POP
[DE]		MOV											
[HL]		MOV											
[HL + byte]		MOV											

Note Except r = A.

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(2) 16-bit instructions

MOVW, XCHW, ADDW, SUBW, CMPW, PUSH, POP, INCW, DECW

1st Operand \ 2nd Operand	#word	AX	rp[Note]	saddrp	SP	None
AX	ADDW SUBW CMPW		MOVW XCHW	MOVW	MOVW	
rp	MOVW	MOVW[Note]				INCW DECW PUSH POP
saddrp		MOVW				
sp		MOVW				

Note Only when rp = BC, DE, or HL.

(3) Bit manipulation instructions

SET1, CLR1, NOT1, BT, BF

1st Operand \ 2nd Operand	$addr16	None
A.bit	BT BF	SET1 CLR1
sfr.bit	BT BF	SET1 CLR1
saddr.bit	BT BF	SET1 CLR1
PSW.bit	BT BF	SET1 CLR1
[HL].bit		SET1 CLR1
CY		SET1 CLR1 NOT1

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(4) Call instructions/branch instructions

CALL, CALLT, BR, BC, BNC, BZ, BNZ, DBNZ

2nd Operand / 1st Operand	AX	!addr16	[addr5]	$addr16
Basic instructions	BR	CALL BR	CALLT	BR BC BNC BZ BNZ
Compound instructions				DBNZ

(5) Other instructions

RET, RETI, NOP, EI, DI, HALT, STOP

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CHAPTER 19 ELECTRICAL SPECIFICATIONS (Standard product, (A) grade product)

Absolute Maximum Ratings (T_A = 25°C)

Parameter	Symbol	Conditions	Ratings	Unit
Supply voltage	V_{DD}		–0.3 to +6.5	V
	V_{SS}		–0.3 to +0.3	V
Input voltage	V_I	P20 to P23, P32, P34, P40 to P47	–0.3 to V_{DD} + 0.3 Note 1	V
Output voltage	V_O		–0.3 to V_{DD} + 0.3 Note 1	V
Analog input voltage Note 2	V_{AN}		–0.3 to V_{DD} + 0.3 Note 1	V
Output current, high	I_{OH}	Per pin	–10.0	mA
		Total of P20 to P23, P32, P40 to P47	–44.0	mA
Output current, low	I_{OL}	Per pin	20.0	mA
		Total of P20 to P23, P32, P40 to P47	44.0	mA
Operating ambient temperature	T_A	In normal operation mode	–40 to +85	°C
		During flash memory programming		°C
Storage temperature	T_{stg}	Flash memory blank status	–65 to +150	°C
		Flash memory programming already performed	–40 to +125	°C

Notes 1. Must be 6.5 V or lower

<R> **2.** μPD78F921x only

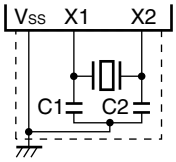
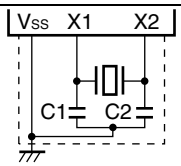
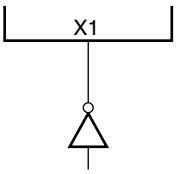
Caution Product quality may suffer if the absolute maximum rating is exceeded even momentarily for any parameter. That is, the absolute maximum ratings are rated values at which the product is on the verge of suffering physical damage, and therefore the product must be used under conditions that ensure that the absolute maximum ratings are not exceeded.

Remark Unless specified otherwise, the characteristics of alternate-function pins are the same as those of port pins.

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Standard product, (A) grade product T_A = –40 to +85°C

X1 Oscillator Characteristics (T_A = –40 to +85°C, V_{DD} = 2.0 to 5.5 V[Note 1], V_{SS} = 0 V)

Resonator	Recommended Circuit	Parameter	Conditions	MIN.	TYP.	MAX.	Unit
Ceramic resonator		Oscillation frequency (f_X)[Note 2]		2.0		10.0	MHz
Crystal resonator		Oscillation frequency (f_X)[Note 2]		2.0		10.0	MHz
External clock		X1 input frequency (f_X)[Note 2]	2.7 V ≤ V_{DD} ≤ 5.5 V	2.0		10.0	MHz
			2.0 V ≤ V_{DD} < 2.7 V	2.0		5.0	
		X1 input high-/low-level width (t_{XH}, t_{XL})	2.7 V ≤ V_{DD} ≤ 5.5 V	0.045		0.25	μs
			2.0 V ≤ V_{DD} < 2.7 V	0.09		0.25	

Notes 1. Use this product in a voltage range of 2.2 to 5.5 V because the detection voltage (V_{POC}) of the power-on-clear (POC) circuit is 2.1 V ±0.1 V.

2. Indicates only oscillator characteristics. Refer to **AC Characteristics** for instruction execution time.

Caution When using the X1 oscillator, wire as follows in the area enclosed by the broken lines in the above figures to avoid an adverse effect from wiring capacitance.

- **Keep the wiring length as short as possible.**
- **Do not cross the wiring with the other signal lines.**
- **Do not route the wiring near a signal line through which a high fluctuating current flows.**
- **Always make the ground point of the oscillator capacitor the same potential as V_{SS}.**
- **Do not ground the capacitor to a ground pattern through which a high current flows.**
- **Do not fetch signals from the oscillator.**

Remark For the resonator selection and oscillator constant, users are required to either evaluate the oscillation themselves or apply to the resonator manufacturer for evaluation.

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Standard product, (A) grade product T_A = –40 to +85°C

High-Speed Internal Oscillator Characteristics (T_A = –40 to +85°C, V_{DD} = 2.0 to 5.5 V[Note 1], V_{SS} = 0 V)

Resonator	Parameter	Conditions		MIN.	TYP.	MAX.	Unit
High-speed internal oscillator	Oscillation frequency (f_X = 8 MHz[Note 2]) deviation	2.7 V ≤ V_{DD} ≤ 5.5 V	T_A = –10 to +70°C			±3	%
			T_A = –40 to +85°C			±5	%
	Oscillation frequency (f_X)[Note 2]	2.0 V ≤ V_{DD} < 2.7 V		5.5			MHz

Notes 1. Use this product in a voltage range of 2.2 to 5.5 V because the detection voltage (V_{POC}) of the power-on-clear (POC) circuit is 2.1 V ±0.1 V.

2. Indicates only oscillator characteristics. Refer to **AC Characteristics** for instruction execution time.

Low-Speed Internal Oscillator Characteristics (T_A = –40 to +85°C, V_{DD} = 2.0 to 5.5 V[Note], V_{SS} = 0 V)

Resonator	Parameter	Conditions	MIN.	TYP.	MAX.	Unit
Low-speed internal oscillator	Oscillation frequency (f_{RL})		120	240	480	kHz

Note Use this product in a voltage range of 2.2 to 5.5 V because the detection voltage (V_{POC}) of the power-on-clear (POC) circuit is 2.1 V ±0.1 V.

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Standard product, (A) grade product T_A = –40 to +85°C

DC Characteristics (T_A = –40 to +85°C, V_{DD} = 2.0 to 5.5 V[Note], V_{SS} = 0 V) (1/2)

Parameter	Symbol	Conditions		MIN.	TYP.	MAX.	Unit
Output current, high	I_{OH}	Per pin	2.0 V ≤ V_{DD} ≤ 5.5 V			–5	mA
		Total of all pins	4.0 V ≤ V_{DD} ≤ 5.5 V			–25	mA
			2.0 V ≤ V_{DD} < 4.0 V			–15	mA
Output current, low	I_{OL}	Per pin	2.0 V ≤ V_{DD} ≤ 5.5 V			10	mA
		Total of all pins	4.0 V ≤ V_{DD} ≤ 5.5 V			30	mA
			2.0 V ≤ V_{DD} < 4.0 V			15	mA
Input voltage, high	V_{IH1}	P23 in external clock mode and pins other than P20 and P21		0.8V_{DD}		V_{DD}	V
	V_{IH2}	P23 in other than external clock mode, P20 and P21		0.7V_{DD}		V_{DD}	V
Input voltage, low	V_{IL1}	P23 in external clock mode and pins other than P20 and P21		0		0.2V_{DD}	V
	V_{IL2}	P23 in other than external clock mode, P20 and P21		0		0.3V_{DD}	V
Output voltage, high	V_{OH}	Total of output pins I_{OH} = –15 mA	4.0 V ≤ V_{DD} ≤ 5.5 V I_{OH} = –5 mA	V_{DD} – 1.0			V
		I_{OH} = –100 μA	2.0 V ≤ V_{DD} < 4.0 V	V_{DD} – 0.5			V
Output voltage, low	V_{OL}	Total of output pins I_{OL} = 30 mA	4.0 V ≤ V_{DD} ≤ 5.5 V I_{OL} = 10 mA			1.3	V
		2.0 V ≤ V_{DD} < 4.0 V I_{OL} = 400 μA				0.4	V
Input leakage current, high	I_{LIH}	V_I = V_{DD}	Pins other than X1			1	μA
Input leakage current, low	I_{LIL}	V_I = 0 V	Pins other than X1			–1	μA
Output leakage current, high	I_{LOH}	V_O = V_{DD}	Pins other than X2			1	μA
Output leakage current, low	I_{LOL}	V_O = 0 V	Pins other than X2			–1	μA
Pull-up resistance value	R_{PU}	V_I = 0 V		10	30	100	kΩ
Pull-down resistance value	R_{PD}	P22, P23, reset status		10	30	100	kΩ

Note Use this product in a voltage range of 2.2 to 5.5 V because the detection voltage (V_{POC}) of the power-on-clear (POC) circuit is 2.1 V ±0.1 V.

Remark Unless specified otherwise, the characteristics of alternate-function pins are the same as those of port pins.

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Standard product, (A) grade product T_A = –40 to +85°C

DC Characteristics (T_A = –40 to +85°C, V_{DD} = 2.0 to 5.5 V[Note 1], V_{SS} = 0 V) (2/2)

Parameter	Symbol	Conditions			MIN.	TYP.	MAX.	Unit
Supply current[Note 2]	I_{DD1}[Note 3]	Crystal/ceramic oscillation, external clock input oscillation operating mode[Note 6]	f_X = 10 MHz V_{DD} = 5.0 V ±10%[Note 4]	**Note 8**		6.1	12.2	mA
				Note 9		7.6	15.2	
			f_X = 6 MHz V_{DD} = 5.0 V ±10%[Note 4]	**Note 8**		5.5	11.0	mA
				Note 9			14.0	
			f_X = 5 MHz V_{DD} = 3.0 V ±10%[Note 5]	**Note 8**		3.0	6.0	mA
				Note 9		4.5	9.0	
	I_{DD2}	Crystal/ceramic oscillation, external clock input HALT mode[Note 6]	f_X = 10 MHz V_{DD} = 5.0 V ±10%[Note 4]	When peripheral functions are stopped		1.7	3.8	mA
				When peripheral functions are operating			6.7	
			f_X = 6 MHz V_{DD} = 5.0 V ±10%[Note 4]	When peripheral functions are stopped		1.3	3.0	mA
				When peripheral functions are operating			6.0	
			f_X = 5 MHz V_{DD} = 3.0 V ±10%[Note 5]	When peripheral functions are stopped		0.48	1	mA
				When peripheral functions are operating			2.1	
	I_{DD3}[Note 3]	High-speed internal oscillation operating mode[Note 7]	f_X = 8 MHz V_{DD} = 5.0 V ±10%[Note 4]	**Note 8**		5.0	10.0	mA
				Note 9		6.5	13.0	
	I_{DD4}	High-speed internal oscillation HALT mode[Note 7]	f_X = 8 MHz V_{DD} = 5.0 V ±10%[Note 4]	When peripheral functions are stopped		1.4	3.2	mA
				When peripheral functions are operating			5.9	
	I_{DD5}	STOP mode	V_{DD} = 5.0 V ±10%	When low-speed internal oscillation is stopped		3.5	20.0	μA
				When low-speed internal oscillation is operating		17.5	32.0	
			V_{DD} = 3.0 V ±10%	When low-speed internal oscillation is stopped		3.5	15.5	μA
				When low-speed internal oscillation is operating		11.0	26.0	

Notes 1. Use this product in a voltage range of 2.2 to 5.5 V because the detection voltage (V_{POC}) of the power-on-clear (POC) circuit is 2.1 V ±0.1 V.

2. Total current flowing through the internal power supply (V_{DD}). Peripheral operation current is included (however, the current that flows through the pull-up resistors of ports is not included).

3. These currents include peripheral operation currents.

4. When the processor clock control register (PCC) is set to 00H.

5. When the processor clock control register (PCC) is set to 02H.

6. When crystal/ceramic oscillation clock, external clock input is selected as the system clock source using the option byte.

7. When high-speed internal oscillation clock is selected as the system clock source using the option byte.

<R> **8.** μPD78F951x, and when A/D converter in μPD78F921x is stopped

<R> **9.** When A/D converter in μPD78F921x is operating

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Standard product, (A) grade product T_A = –40 to +85°C

AC Characteristics

Basic operation (T_A = –40 to +85°C, V_{DD} = 2.0 to 5.5 V[Note 1], V_{SS} = 0 V)

Parameter	Symbol	Conditions		MIN.	TYP.	MAX.	Unit
Cycle time (minimum instruction execution time)	T_{CY}	Crystal/ceramic oscillation clock, external clock input	4.0 V ≤ V_{DD} ≤ 5.5 V	0.2		16	μs
			3.0 V ≤ V_{DD} < 4.0 V	0.33		16	μs
			2.7 V ≤ V_{DD} < 3.0 V	0.4		16	μs
			2.0 V ≤ V_{DD} < 2.7 V	1		16	μs
		High-speed internal oscillation clock	4.0 V ≤ V_{DD} ≤ 5.5 V	0.23		4.22	μs
			2.7 V ≤ V_{DD} < 4.0 V	0.47		4.22	μs
			2.0 V ≤ V_{DD} < 2.7 V	0.95		4.22	μs
TI000 input high-level width, low-level width	t_{TIH}, t_{TIL}	4.0 V ≤ V_{DD} ≤ 5.5 V		2/fsam+ 0.1[Note 2]			μs
		2.0 V ≤ V_{DD} < 4.0 V		2/fsam+ 0.2[Note 2]			μs
Interrupt input high-level width, low-level width	t_{INTH}, t_{INTL}			1			μs
$\overline{\text{RESET}}$ input low-level width	t_{RSL}			2			μs

Notes 1. Use this product in a voltage range of 2.2 to 5.5 V because the detection voltage (V_{POC}) of the power-on-clear (POC) circuit is 2.1 V ±0.1 V.

2. Selection of fsam = f_{XP}, f_{XP}/4, or f_{XP}/256 is possible using bits 0 and 1 (PRM000, PRM001) of prescaler mode register 00 (PRM00). Note that when selecting the TI000 valid edge as the count clock, fsam = f_{XP}.

CPU Clock Frequency, Peripheral Clock Frequency

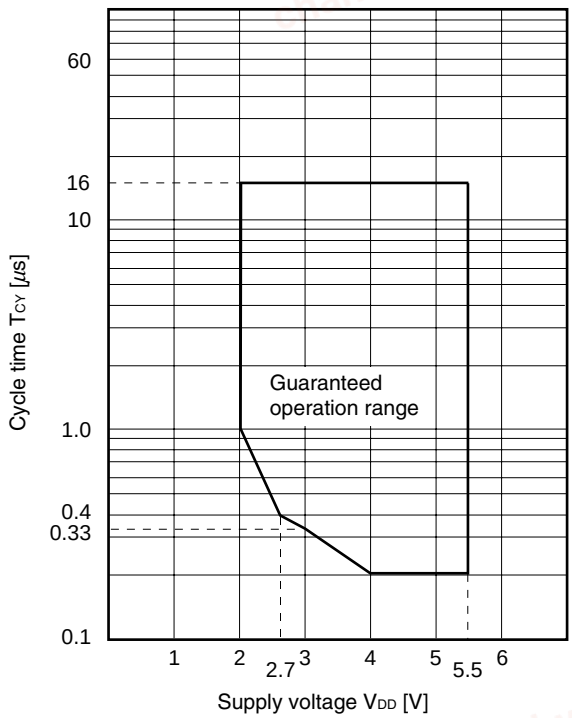
Parameter	Conditions	CPU Clock (f_{CPU})	Peripheral Clock (f_{XP})
Ceramic resonator, crystal resonator, external clock	4.0 V ≤ V_{DD} ≤ 5.5 V	125 kHz ≤ f_{CPU} ≤ 10 MHz	500 kHz ≤ f_{XP} ≤ 10 MHz
	3.0 V ≤ V_{DD} < 4.0 V	125 kHz ≤ f_{CPU} ≤ 6 MHz	
	2.7 V ≤ V_{DD} < 3.0 V	125 kHz ≤ f_{CPU} ≤ 5 MHz	
	2.0 V ≤ V_{DD} < 2.7 V[Note]	125 kHz ≤ f_{CPU} ≤ 2 MHz	500 kHz ≤ f_{XP} ≤ 5 MHz
High-speed internal oscillator	4.0 V ≤ V_{DD} ≤ 5.5 V	500 kHz (TYP.) ≤ f_{CPU} ≤ 8 MHz (TYP.)	2 MHz (TYP.) ≤ f_{XP} ≤ 8 MHz (TYP.)
	2.7 V ≤ V_{DD} < 4.0 V	500 kHz (TYP.) ≤ f_{CPU} ≤ 4 MHz (TYP.)	
	2.0 V ≤ V_{DD} < 2.7 V[Note]	500 kHz (TYP.) ≤ f_{CPU} ≤ 2 MHz (TYP.)	2 MHz (TYP.) ≤ f_{XP} ≤ 4 MHz (TYP.)

Note Use this product in a voltage range of 2.2 to 5.5 V because the detection voltage (V_{POC}) of the power-on-clear (POC) circuit is 2.1 V ±0.1 V.

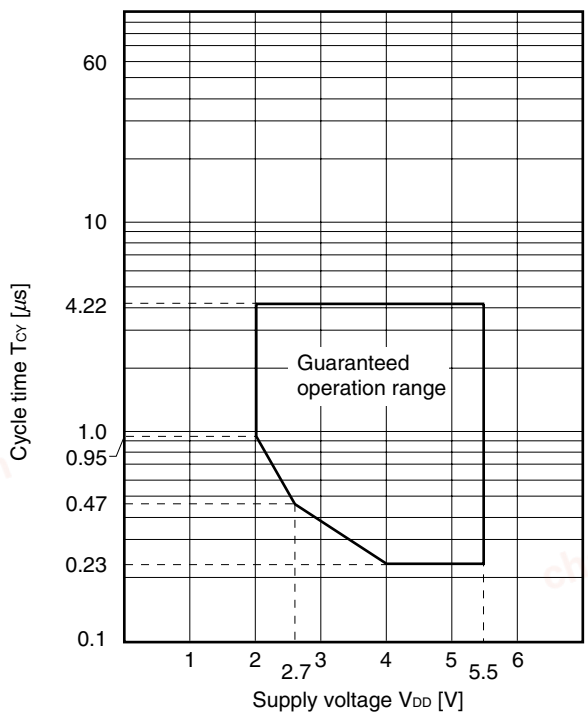
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Standard product, (A) grade product T_A = –40 to +85°C

T_{CY} vs. V_{DD} (Crystal/Ceramic Oscillation Clock, External Clock Input)



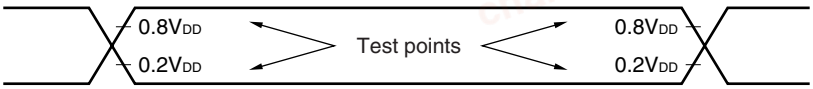
T_{CY} vs. V_{DD} (High-speed internal oscillator Clock)



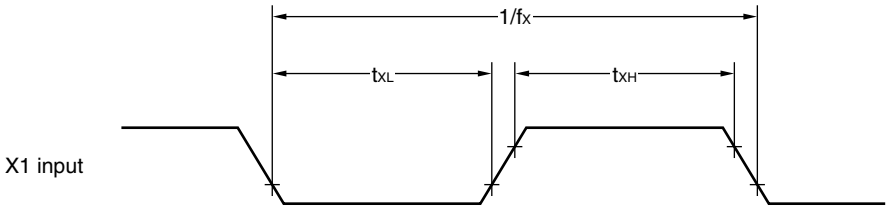
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Standard product, (A) grade product T_A = –40 to +85°C

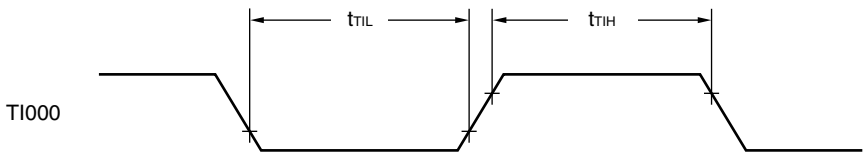
AC Timing Test Points (Excluding X1 Input)



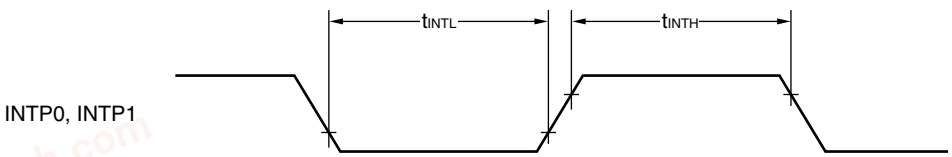
Clock Timing



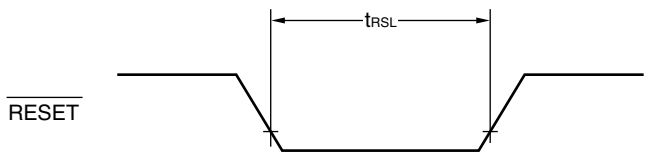
TI000 Timing



Interrupt Input Timing



$\overline{\text{RESET}}$ Input Timing



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Standard product, (A) grade product T_A = –40 to +85°C

A/D Converter Characteristics (T_A = –40 to +85°C, 2.7 V ≤ V_{DD} ≤ 5.5 V[Note 1], V_{SS} = 0 V[Note 2]) (μPD78F921x Only)

(1) A/D converter basic characteristics

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Resolution			10	10	10	bit
Conversion time	t_{CONV}	4.5 V ≤ V_{DD} ≤ 5.5 V	3.0		100	μs
		4.0 V ≤ V_{DD} < 4.5 V	4.8		100	μs
		2.85 V ≤ V_{DD} < 4.0 V	6.0		100	μs
		2.7 V ≤ V_{DD} < 2.85 V	14.0		100	μs
Analog input voltage	V_{AIN}		V_{SS}[Note 2]		V_{DD}	V

(2) A/D Converter Characteristics (high-speed internal oscillation clock)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Overall error[Notes 3, 4]	AINL			–0.1 to +0.2[Note 5]	–0.35 to +0.45	%FSR
Zero-scale error[Notes 3, 4]	Ezs			–0.1 to +0.2[Note 5]	–0.35 to +0.45	%FSR
Full-scale error[Notes 3, 4]	Efs			–0.1 to +0.2[Note 5]	–0.35 to +0.40	%FSR
Integral non-linearity error[Note 3]	ILE			±1[Note 5]	±3	LSB
Differential non-linearity error[Note 3]	DLE			±1[Note 5]	±1.5	LSB

(3) A/D Converter Characteristics (Crystal/Ceramic Oscillation Clock, External Clock)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Overall error[Notes 3, 4]	AINL	4.0 V ≤ V_{DD} ≤ 5.5 V		–0.20 to +0.35[Note 5]	–0.35 to +0.65	%FSR
		2.7 V ≤ V_{DD} < 4.0 V		±0.25[Note 5]	–0.35 to +0.55	%FSR
Zero-scale error[Notes 3, 4]	Ezs	4.0 V ≤ V_{DD} ≤ 5.5 V		–0.20 to +0.35[Note 5]	–0.35 to +0.65	%FSR
		2.7 V ≤ V_{DD} < 4.0 V		±0.25[Note 5]	–0.35 to +0.55	%FSR
Full-scale error[Notes 3, 4]	Efs	4.0 V ≤ V_{DD} ≤ 5.5 V		–0.20 to +0.35[Note 5]	–0.35 to +0.55	%FSR
		2.7 V ≤ V_{DD} < 4.0 V		±0.25[Note 5]	–0.35 to +0.50	%FSR
Integral non-linearity error[Note 3]	ILE	4.0 V ≤ V_{DD} ≤ 5.5 V		±1.5[Note 5]	±3.0	LSB
		2.7 V ≤ V_{DD} < 4.0 V		±1.5[Note 5]	±4.0	LSB
Differential non-linearity error[Note 3]	DLE	4.0 V ≤ V_{DD} ≤ 5.5 V		±1.0[Note 5]	±2.5	LSB
		2.7 V ≤ V_{DD} < 4.0 V		±1.0[Note 5]	±2.5	LSB

Notes 1. In μPD78F921x, V_{DD} functions alternately as the A/D converter reference voltage input. When using the A/D converter, stabilize V_{DD} at the supply voltage used (2.7 to 5.5 V).

2. In μPD78F921x, V_{SS} functions alternately as the ground potential of the A/D converter. Be sure to connect V_{SS} to a stabilized GND (= 0 V).

3. Excludes quantization error (±1/2 LSB).

4. This value is indicated as a ratio (%FSR) to the full-scale value.

5. A value when HALT mode is set by an instruction immediately after A/D conversion starts.

Caution The conversion accuracy may be degraded when the analog input pin is used as an alternate I/O port or if the level of a port that is not used for A/D conversion is changed during A/D conversion.

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Standard product, (A) grade product T_A = –40 to +85°C

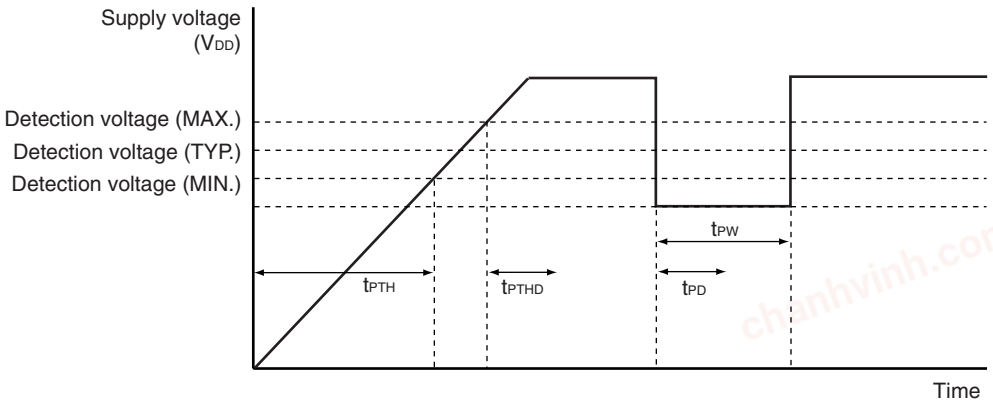
POC Circuit Characteristics (T_A = –40 to +85°C)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Detection voltage	V_{POC}		2.0	2.1	2.2	V
Power supply rise time	t_{PTH}	V_{DD}: 0 V → 2.1 V	1.5			μs
Response delay time 1 Note 1	t_{PTHD}	When power supply rises, after reaching detection voltage (MAX.)			3.0	ms
Response delay time 2 Note 2	t_{PD}	When power supply falls			1.0	ms
Minimum pulse width	t_{PW}		0.2			ms

Notes 1. Time required from voltage detection to internal reset release.

2. Time required from voltage detection to internal reset signal generation.

POC Circuit Timing



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Standard product, (A) grade product T_A = –40 to +85°C

LVI Circuit Characteristics (T_A = –40 to +85°C)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Detection voltage	V_{LVI0}		4.1	4.3	4.5	V
	V_{LVI1}		3.9	4.1	4.3	V
	V_{LVI2}		3.7	3.9	4.1	V
	V_{LVI3}		3.5	3.7	3.9	V
	V_{LVI4}		3.3	3.5	3.7	V
	V_{LVI5}		3.15	3.3	3.45	V
	V_{LVI6}		2.95	3.1	3.25	V
	V_{LVI7}		2.7	2.85	3.0	V
	V_{LVI8}		2.5	2.6	2.7	V
	V_{LVI9}		2.25	2.35	2.45	V
Response time[Note 1]	t_{LD}			0.2	2.0	ms
Minimum pulse width	t_{LW}		0.2			ms
Operation stabilization wait time[Note 2]	t_{LWAIT}			0.1	0.2	ms

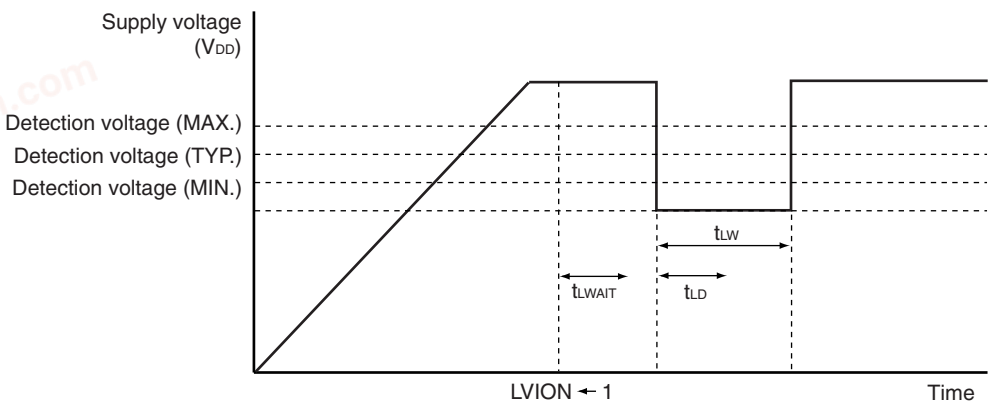
Notes 1. Time required from voltage detection to interrupt output or internal reset signal generation.

2. Time required from setting LVION to 1 to operation stabilization.

Remarks 1. $V_{LVI0} > V_{LVI1} > V_{LVI2} > V_{LVI3} > V_{LVI4} > V_{LVI5} > V_{LVI6} > V_{LVI7} > V_{LVI8} > V_{LVI9}$

2. $V_{POC} < V_{LVIm}$ (m = 0 to 9)

LVI Circuit Timing



Data Memory STOP Mode Low Supply Voltage Data Retention Characteristics (T_A = –40 to +85°C)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Data retention supply voltage	V_{DDDR}		2.0		5.5	V
Release signal set time	t_{SREL}		0			μs

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Standard product, (A) grade product T_A = –40 to +85°C

Flash Memory Programming Characteristics (T_A = –40 to +85°C, 2.7 V ≤ V_{DD} ≤ 5.5 V, V_{SS} = 0 V)

Parameter	Symbol	Conditions		MIN.	TYP.	MAX.	Unit
Supply current	I_{DD}	V_{DD} = 5.5 V				7.0	mA
Erasure count[Note 1] (per 1 block)	N_{ERASE}	T_A = –40 to +85°C		1000			Times
Chip erase time	T_{CERASE}	T_A = –10 to +85°C, N_{ERASE} ≤ 100	4.5 V ≤ V_{DD} ≤ 5.5 V			0.8	s
			3.5 V ≤ V_{DD} < 4.5 V			1.0	s
			2.7 V ≤ V_{DD} < 3.5 V			1.2	s
		T_A = –10 to +85°C, N_{ERASE} ≤ 1000	4.5 V ≤ V_{DD} ≤ 5.5 V			4.8	s
			3.5 V ≤ V_{DD} < 4.5 V			5.2	s
			2.7 V ≤ V_{DD} < 3.5 V			6.1	s
		T_A = –40 to +85°C, N_{ERASE} ≤ 100	4.5 V ≤ V_{DD} ≤ 5.5 V			1.6	s
			3.5 V ≤ V_{DD} < 4.5 V			1.8	s
			2.7 V ≤ V_{DD} < 3.5 V			2.0	s
		T_A = –40 to +85°C, N_{ERASE} ≤ 1000	4.5 V ≤ V_{DD} ≤ 5.5 V			9.1	s
			3.5 V ≤ V_{DD} < 4.5 V			10.1	s
			2.7 V ≤ V_{DD} < 3.5 V			12.3	s
Block erase time	T_{BERASE}	T_A = –10 to +85°C, N_{ERASE} ≤ 100	4.5 V ≤ V_{DD} ≤ 5.5 V			0.4	s
			3.5 V ≤ V_{DD} < 4.5 V			0.5	s
			2.7 V ≤ V_{DD} < 3.5 V			0.6	s
		T_A = –10 to +85°C, N_{ERASE} ≤ 1000	4.5 V ≤ V_{DD} ≤ 5.5 V			2.6	s
			3.5 V ≤ V_{DD} < 4.5 V			2.8	s
			2.7 V ≤ V_{DD} < 3.5 V			3.3	s
		T_A = –40 to +85°C, N_{ERASE} ≤ 100	4.5 V ≤ V_{DD} ≤ 5.5 V			0.9	s
			3.5 V ≤ V_{DD} < 4.5 V			1.0	s
			2.7 V ≤ V_{DD} < 3.5 V			1.1	s
		T_A = –40 to +85°C, N_{ERASE} ≤ 1000	4.5 V ≤ V_{DD} ≤ 5.5 V			4.9	s
			3.5 V ≤ V_{DD} < 4.5 V			5.4	s
			2.7 V ≤ V_{DD} < 3.5 V			6.6	s
Byte write time	T_{WRITE}	T_A = –40 to +85°C, N_{ERASE} ≤ 1000				150	μs
Internal verify	T_{VERIFY}	Per 1 block				6.8	ms
		Per 1 byte				27	μs
Blank check	T_{BLKCHK}	Per 1 block				480	μs
Retention years		T_A = 85°C[Note 2], N_{ERASE} ≤ 1000		10			Years

Notes 1. Depending on the erasure count (N_{ERASE}), the erase time varies. Refer to the chip erase time and block erase time parameters.

2. When the average temperature when operating and not operating is 85°C.

Remark When a product is first written after shipment, “erase → write” and “write only” are both taken as one rewrite.

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CHAPTER 20 ELECTRICAL SPECIFICATIONS ((A2) grade product)

Absolute Maximum Ratings (T_A = 25°C)

Parameter	Symbol	Conditions	Ratings	Unit
Supply voltage	V_{DD}		–0.3 to +6.5	V
	V_{SS}		–0.3 to +0.3	V
Input voltage	V_I	P20 to P23, P32, P34, P40 to P47	–0.3 to V_{DD} + 0.3 Note 1	V
Output voltage	V_O		–0.3 to V_{DD} + 0.3 Note 1	V
Analog input voltage	V_{AN}		–0.3 to V_{DD} + 0.3 Note 1	V
Output current, high	I_{OH}	Per pin	–7.0	mA
		Total of P20 to P23, P32, P40 to P47	–30.0	mA
Output current, low	I_{OL}	Per pin	14.0	mA
		Total of P20 to P23, P32, P40 to P47	30.0	mA
Total loss	P_T Note 2	T_A = –40 to +85°C	120	mW
		T_A = +85 to +125°C	90	mW
Operating ambient temperature	T_A	In normal operation mode	–40 to +125	°C
		During flash memory programming	–40 to +105	°C
Storage temperature	T_{stg}	Flash memory blank status	–65 to +150	°C
		Flash memory programming already performed	–40 to +125	°C

Note 1. Must be 6.5 V or lower

Caution Product quality may suffer if the absolute maximum rating is exceeded even momentarily for any parameter. That is, the absolute maximum ratings are rated values at which the product is on the verge of suffering physical damage, and therefore the product must be used under conditions that ensure that the absolute maximum ratings are not exceeded.

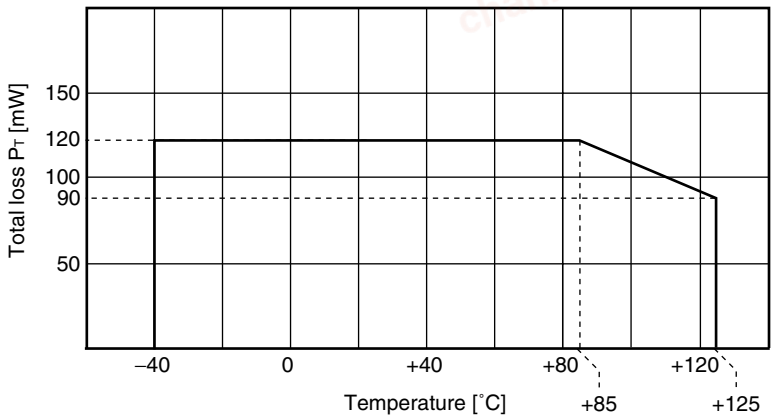
Remark Unless specified otherwise, the characteristics of alternate-function pins are the same as those of port pins.

(Note 2 is listed on the next page.)

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(A2) grade product T_A = –40 to +125°C

Note 2. This varies depending on the allowable total loss (see the figure below).



Use the following formula to perform design such that the sum of the power consumption of the device is less than or equal to the total loss P_T (use at 80% or less of the rated value is recommended).

• Total power consumption = $V_{DD} \times \{I_{DD} - \sum I_{OH}\} + \sum\{(V_{DD} - V_{OH}) \times I_{OH}\} + \sum(V_{OL} \times I_{OL})$

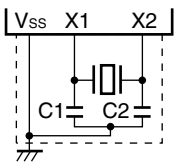
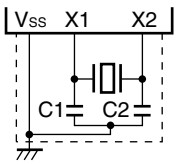
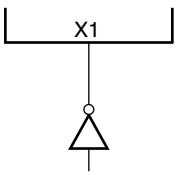
When guaranteeing the internal pull-up resistor, use the following formula to calculate its power consumption, and add the result to the result above.

• Power consumption of internal pull-up resistor = $\sum(V_{DD}/R_{PU} \times V_{DD})$

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(A2) grade product T_A = –40 to +125°C

X1 Oscillator Characteristics (T_A = –40 to +125°C, V_{DD} = 2.0 to 5.5 V[Note 1], V_{SS} = 0 V)

Resonator	Recommended Circuit	Parameter	Conditions	MIN.	TYP.	MAX.	Unit
Ceramic resonator		Oscillation frequency (f_X)[Note 2]		2.0		8.0	MHz
Crystal resonator		Oscillation frequency (f_X)[Note 2]		2.0		8.0	MHz
External clock		X1 input frequency (f_X)[Note 2]	2.7 V ≤ V_{DD} ≤ 5.5 V	2.0		8.0	MHz
			2.0 V ≤ V_{DD} < 2.7 V	2.0		5.0	
		X1 input high-/low-level width (t_{XH}, t_{XL})	2.7 V ≤ V_{DD} ≤ 5.5 V	0.057		0.25	μs
			2.0 V ≤ V_{DD} < 2.7 V	0.09		0.25	

Notes 1. Use this product in a voltage range of 2.26 to 5.5 V because the detection voltage (V_{POC}) of the power-on-clear (POC) circuit is 2.26 V (MAX.).

2. Indicates only oscillator characteristics. Refer to **AC Characteristics** for instruction execution time.

Caution When using the X1 oscillator, wire as follows in the area enclosed by the broken lines in the above figures to avoid an adverse effect from wiring capacitance.

- **Keep the wiring length as short as possible.**
- **Do not cross the wiring with the other signal lines.**
- **Do not route the wiring near a signal line through which a high fluctuating current flows.**
- **Always make the ground point of the oscillator capacitor the same potential as V_{SS}.**
- **Do not ground the capacitor to a ground pattern through which a high current flows.**
- **Do not fetch signals from the oscillator.**

Remark For the resonator selection and oscillator constant, users are required to either evaluate the oscillation themselves or apply to the resonator manufacturer for evaluation.

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(A2) grade product T_A = –40 to +125°C

High-Speed Internal Oscillator Characteristics (T_A = –40 to +125°C, V_{DD} = 2.0 to 5.5 V[Note 1], V_{SS} = 0 V)

Resonator	Parameter	Conditions		MIN.	TYP.	MAX.	Unit
High-speed internal oscillator	Oscillation frequency (f_X = 8 MHz[Note 2]) deviation	2.7 V ≤ V_{DD} ≤ 5.5 V	T_A = –10 to +70°C			±3	%
			T_A = –40 to +125°C			±5	%
	Oscillation frequency (f_X)[Note 2]	2.0 V ≤ V_{DD} < 2.7 V		5.5			MHz

Notes 1. Use this product in a voltage range of 2.26 to 5.5 V because the detection voltage (V_{POC}) of the power-on-clear (POC) circuit is 2.26 V (MAX.).

2. Indicates only oscillator characteristics. Refer to **AC Characteristics** for instruction execution time.

Low-Speed Internal Oscillator Characteristics (T_A = –40 to +125°C, V_{DD} = 2.0 to 5.5 V[Note], V_{SS} = 0 V)

Resonator	Parameter	Conditions	MIN.	TYP.	MAX.	Unit
Low-speed internal oscillator	Oscillation frequency (f_{RL})		120	240	495	kHz

Note Use this product in a voltage range of 2.26 to 5.5 V because the detection voltage (V_{POC}) of the power-on-clear (POC) circuit is 2.26 V (MAX.).

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(A2) grade product T_A = –40 to +125°C

DC Characteristics (T_A = –40 to +125°C, V_{DD} = 2.0 to 5.5 V[Note], V_{SS} = 0 V) (1/2)

Parameter	Symbol	Conditions		MIN.	TYP.	MAX.	Unit
Output current, high	I_{OH}	Per pin	2.0 V ≤ V_{DD} ≤ 5.5 V			–3.5	mA
		Total of all pins	4.0 V ≤ V_{DD} ≤ 5.5 V			–17.5	mA
			2.0 V ≤ V_{DD} < 4.0 V			–10.5	mA
Output current, low	I_{OL}	Per pin	2.0 V ≤ V_{DD} ≤ 5.5 V			7.0	mA
		Total of all pins	4.0 V ≤ V_{DD} ≤ 5.5 V			21.0	mA
			2.0 V ≤ V_{DD} < 4.0 V			10.5	mA
Input voltage, high	V_{IH1}	P23 in external clock mode and pins other than P20 and P21		0.8V_{DD}		V_{DD}	V
	V_{IH2}	P23 in other than external clock mode, P20 and P21		0.7V_{DD}		V_{DD}	V
Input voltage, low	V_{IL1}	P23 in external clock mode and pins other than P20 and P21		0		0.2V_{DD}	V
	V_{IL2}	P23 in other than external clock mode, P20 and P21		0		0.3V_{DD}	V
Output voltage, high	V_{OH}	Total of pins I_{OH} = –10.5 mA	4.0 V ≤ V_{DD} ≤ 5.5 V I_{OH} = –3.5 mA	V_{DD} – 1.0			V
		I_{OH} = –100 μA	2.0 V ≤ V_{DD} < 4.0 V	V_{DD} – 0.5			V
Output voltage, low	V_{OL}	Total of pins I_{OL} = 21 mA	4.0 V ≤ V_{DD} ≤ 5.5 V I_{OL} = 7 mA			1.3	V
		2.0 V ≤ V_{DD} ≤ 4.0 V I_{OL} = 400 μA				0.4	V
Input leakage current, high	I_{LIH}	V_I = V_{DD}	Pins other than X1			10	μA
Input leakage current, low	I_{LIL}	V_I = 0 V	Pins other than X1			–10	μA
Output leakage current, high	I_{LOH}	V_O = V_{DD}	Pins other than X2			10	μA
Output leakage current, low	I_{LOL}	V_O = 0 V	Pins other than X2			–10	μA
Pull-up resistance	R_{PU}	V_I = 0 V		10	30	120	kΩ
Pull-down resistance	R_{PD}	P22, P23, reset status		10	30	120	kΩ

Note Use this product in a voltage range of 2.26 to 5.5 V because the detection voltage (V_{POC}) of the power-on-clear (POC) circuit is 2.26 (MAX.).

Remark Unless specified otherwise, the characteristics of alternate-function pins are the same as those of port pins.

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(A2) grade product T_A = –40 to +125°C

DC Characteristics (T_A = –40 to +125°C, V_{DD} = 2.0 to 5.5 V[Note 1], V_{SS} = 0 V) (2/2)

Parameter	Symbol	Conditions			MIN.	TYP.	MAX.	Unit
Supply current[Note 2]	I_{DD1}[Note 3]	Crystal/ceramic oscillation, external clock input oscillation operating mode[Note 6]	f_X = 8 MHz V_{DD} = 5.0 V ±10%[Note 4]	When A/D converter is stopped		5.8	12.8	mA
				When A/D converter is operating		7.3	15.8	
			f_X = 6 MHz V_{DD} = 5.0 V ±10%[Note 4]	When A/D converter is stopped		5.5	12.2	mA
				When A/D converter is operating			15.2	
			f_X = 5 MHz V_{DD} = 3.0 V ±10%[Note 5]	When A/D converter is stopped		3.0	6.6	mA
				When A/D converter is operating		4.5	9.6	
	I_{DD2}	Crystal/ceramic oscillation, external clock input HALT mode[Note 6]	f_X = 8 MHz V_{DD} = 5.0 V ±10%[Note 4]	When peripheral functions are stopped		1.5	4.6	mA
				When peripheral functions are operating			7.6	
			f_X = 6 MHz V_{DD} = 5.0 V ±10%[Note 4]	When peripheral functions are stopped		1.3	4.2	mA
				When peripheral functions are operating			7.2	
			f_X = 5 MHz V_{DD} = 3.0 V ±10%[Note 5]	When peripheral functions are stopped		0.48	1.6	mA
				When peripheral functions are operating			2.7	
	I_{DD3}[Note 3]	High-speed internal oscillation operating mode[Note 7]	f_X = 8 MHz V_{DD} = 5.0 V ±10%[Note 4]	When A/D converter is stopped		5.0	12.2	mA
				When A/D converter is operating		6.5	15.2	
	I_{DD4}	High-speed internal oscillation HALT mode[Note 7]	f_X = 8 MHz V_{DD} = 5.0 V ±10%[Note 4]	When peripheral functions are stopped		1.4	4.4	mA
				When peripheral functions are operating			7.1	
	I_{DD5}	STOP mode	V_{DD} = 5.0 V ±10%	When low-speed internal oscillation is stopped		3.5	1200	μA
				When low-speed internal oscillation is operating		17.5	1300	
			V_{DD} = 3.0 V ±10%	When low-speed internal oscillation is stopped		3.5	600	μA
				When low-speed internal oscillation is operating		11.0	700	

Notes 1. Use this product in a voltage range of 2.26 to 5.5 V because the detection voltage (V_{POC}) of the power-on-clear (POC) circuit is 2.26 V (MAX.).

2. Total current flowing through the internal power supply (V_{DD}). Peripheral operation current is included (however, the current that flows through the pull-up resistors of ports is not included).

3. These currents include peripheral operation currents.

4. When the processor clock control register (PCC) is set to 00H.

5. When the processor clock control register (PCC) is set to 02H.

6. When crystal/ceramic oscillation clock, external clock input is selected as the system clock source using the option byte.

7. When the high-speed internal oscillation clock is selected as the system clock source using the option byte.

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(A2) grade product T_A = –40 to +125°C

AC Characteristics

Basic operation (T_A = –40 to +125°C, V_{DD} = 2.0 to 5.5 V[Note 1], V_{SS} = 0 V)

Parameter	Symbol	Conditions		MIN.	TYP.	MAX.	Unit
Cycle time (minimum instruction execution time)	T_{CY}	Crystal/ceramic oscillation clock, external clock input	4.0 V ≤ V_{DD} ≤ 5.5 V	0.25		16	μs
			3.0 V ≤ V_{DD} < 4.0 V	0.33		16	μs
			2.7 V ≤ V_{DD} < 3.0 V	0.4		16	μs
			2.0 V ≤ V_{DD} < 2.7 V	1		16	μs
		High-speed internal oscillation clock	4.0 V ≤ V_{DD} ≤ 5.5 V	0.23		4.22	μs
			2.7 V ≤ V_{DD} < 4.0 V	0.47		4.22	μs
			2.0 V ≤ V_{DD} < 2.7 V	0.95		4.22	μs
TI000 input high-level width, low-level width	t_{TIH}, t_{TIL}	4.0 V ≤ V_{DD} ≤ 5.5 V		2/fsam+ 0.1[Note 2]			μs
		2.0 V ≤ V_{DD} < 4.0 V		2/fsam+ 0.2[Note 2]			μs
Interrupt input high-level width, low-level width	t_{INTH}, t_{INTL}			1			μs
$\overline{\text{RESET}}$ input low-level width	t_{RSL}			2			μs

Notes 1. Use this product in a voltage range of 2.26 to 5.5 V because the detection voltage (V_{POC}) of the power-on-clear (POC) circuit is 2.26 V (MAX.).

2. Selection of fsam = f_{XP}, f_{XP}/4, or f_{XP}/256 is possible using bits 0 and 1 (PRM000, PRM001) of prescaler mode register 00 (PRM00). Note that when selecting the TI000 valid edge as the count clock, fsam = f_{XP}.

CPU Clock Frequency, Peripheral Clock Frequency

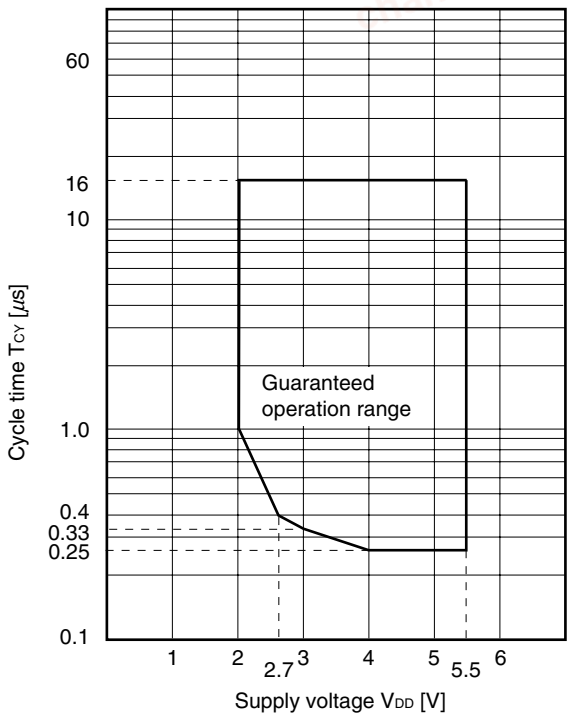
Parameter	Conditions	CPU Clock (f_{CPU})	Peripheral Clock (f_{XP})
Ceramic resonator, crystal resonator, external clock	4.0 V ≤ V_{DD} ≤ 5.5 V	125 kHz ≤ f_{CPU} ≤ 8 MHz	500 kHz ≤ f_{XP} ≤ 8 MHz
	3.0 V ≤ V_{DD} < 4.0 V	125 kHz ≤ f_{CPU} ≤ 6 MHz	
	2.7 V ≤ V_{DD} < 3.0 V	125 kHz ≤ f_{CPU} ≤ 5 MHz	
	2.0 V ≤ V_{DD} < 2.7 V[Note]	125 kHz ≤ f_{CPU} ≤ 2 MHz	500 kHz ≤ f_{XP} ≤ 5 MHz
High-speed internal oscillator	4.0 V ≤ V_{DD} ≤ 5.5 V	500 kHz (TYP.) ≤ f_{CPU} ≤ 8 MHz (TYP.)	2 MHz (TYP.) ≤ f_{XP} ≤ 8 MHz (TYP.)
	2.7 V ≤ V_{DD} < 4.0 V	500 kHz (TYP.) ≤ f_{CPU} ≤ 4 MHz (TYP.)	
	2.0 V ≤ V_{DD} < 2.7 V[Note]	500 kHz (TYP.) ≤ f_{CPU} ≤ 2 MHz (TYP.)	2 MHz (TYP.) ≤ f_{XP} ≤ 4 MHz (TYP.)

Note Use this product in a voltage range of 2.26 to 5.5 V because the detection voltage (V_{POC}) of the power-on-clear (POC) circuit is 2.26 V (MAX.).

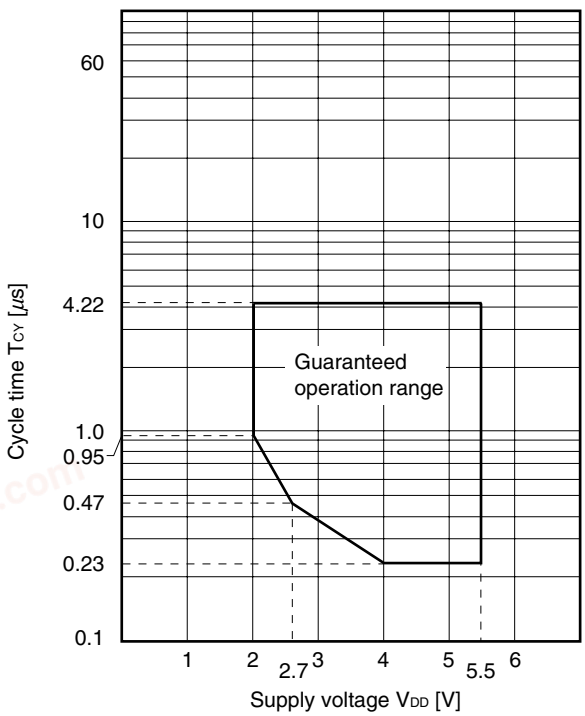
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(A2) grade product T_A = –40 to +125°C

T_{CY} vs. V_{DD} (Crystal/Ceramic Oscillation Clock, External Clock Input)



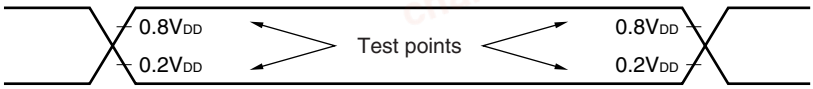
T_{CY} vs. V_{DD} (High-speed internal oscillator Clock)



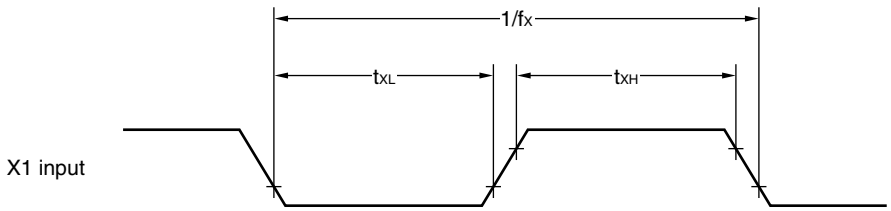
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(A2) grade product T_A = –40 to +125°C

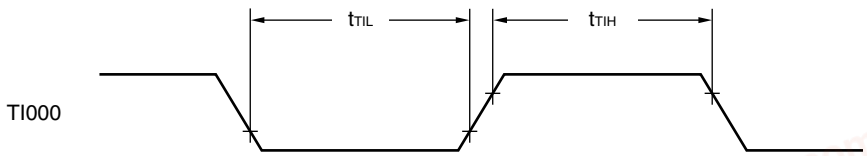
AC Timing Test Points (Excluding X1 Input)



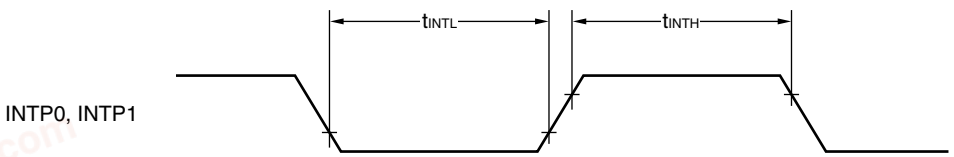
Clock Timing



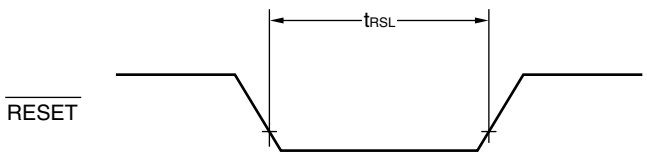
TI000 Timing



Interrupt Input Timing



$\overline{\text{RESET}}$ Input Timing



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(A2) grade product T_A = –40 to +125°C

A/D Converter Characteristics (T_A = –40 to +125°C, 2.7 V ≤ V_{DD} ≤ 5.5 V[Note 1], V_{SS} = 0 V[Note 2])

(1) A/D converter basic characteristics

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Resolution			10	10	10	bit
Conversion time	t_{CONV}	4.5 V ≤ V_{DD} ≤ 5.5 V	3.0		30	μs
		4.0 V ≤ V_{DD} < 4.5 V	4.8		30	μs
		2.85 V ≤ V_{DD} < 4.0 V	6.0		30	μs
		2.7 V ≤ V_{DD} < 2.85 V	14.0		30	μs
Analog input voltage	V_{AIN}		V_{SS}[Note 2]		V_{DD}	V

(2) A/D Converter Characteristics (high-speed internal oscillation clock)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Overall error[Notes 3, 4]	AINL			±0.3[Note 5]	–0.65 to +0.75	%FSR
Zero-scale error[Notes 3, 4]	Ezs			±0.3[Note 5]	–0.60 to +0.70	%FSR
Full-scale error[Notes 3, 4]	Efs			±0.3[Note 5]	–0.60 to +0.70	%FSR
Integral non-linearity error[Note 3]	ILE			±1.5[Note 5]	±4.0	LSB
Differential non-linearity error[Note 3]	DLE			±1.5[Note 5]	±2.5	LSB

(3) A/D Converter Characteristics (Crystal/Ceramic Oscillation Clock, External Clock)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Overall error[Notes 3, 4]	AINL	4.0 V ≤ V_{DD} ≤ 5.5 V		–0.25 to +0.40[Note 5]	–0.55 to +0.95	%FSR
		2.7 V ≤ V_{DD} < 4.0 V		±0.3[Note 5]	–0.70 to +0.95	%FSR
Zero-scale error[Notes 3, 4]	Ezs	4.0 V ≤ V_{DD} ≤ 5.5 V		–0.25 to +0.40[Note 5]	–0.55 to +0.95	%FSR
		2.7 V ≤ V_{DD} < 4.0 V		±0.3[Note 5]	–0.65 to +0.85	%FSR
Full-scale error[Notes 3, 4]	Efs	4.0 V ≤ V_{DD} ≤ 5.5 V		–0.25 to +0.40[Note 5]	–0.55 to +0.90	%FSR
		2.7 V ≤ V_{DD} < 4.0 V		±0.3[Note 5]	–0.65 to +0.85	%FSR
Integral non-linearity error[Note 3]	ILE	4.0 V ≤ V_{DD} ≤ 5.5 V		±1.5[Note 5]	±5.5	LSB
		2.7 V ≤ V_{DD} < 4.0 V		±1.5[Note 5]	±7.0	LSB
Differential non-linearity error[Note 3]	DLE	4.0 V ≤ V_{DD} ≤ 5.5 V		±1.0[Note 5]	±3.0	LSB
		2.7 V ≤ V_{DD} < 4.0 V		±1.0[Note 5]	±3.0	LSB

Notes 1. In μPD78F921x, V_{DD} functions alternately as the A/D converter reference voltage input. When using the A/D converter, stabilize V_{DD} at the supply voltage used (2.7 to 5.5 V).

2. In μPD78F921x, V_{SS} functions alternately as the ground potential of the A/D converter. Be sure to connect V_{SS} to a stabilized GND (= 0 V).

3. Excludes quantization error (±1/2 LSB).

4. This value is indicated as a ratio (%FSR) to the full-scale value.

5. A value when HALT mode is set by an instruction immediately after A/D conversion starts.

Caution The conversion accuracy may be degraded when the analog input pin is used as an alternate I/O port or if the level of a port that is not used for A/D conversion is changed during A/D conversion.

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(A2) grade product T_A = –40 to +125°C

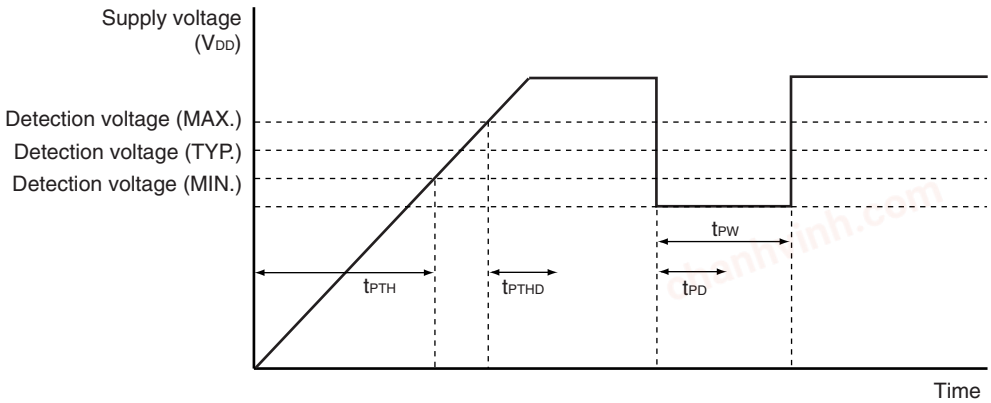
POC Circuit Characteristics (T_A = –40 to +125°C)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Detection voltage	V_{POC}		2.0	2.1	2.26	V
Power supply boot time	t_{PTH}	V_{DD}: 0 V → 2.1 V	1.5			μs
Response delay time 1 Note 1	t_{PTHD}	When power supply rises, after reaching detection voltage (MAX.)			3.0	ms
Response delay time 2 Note 2	t_{PD}	When power supply falls			1.0	ms
Minimum pulse width	t_{PW}		0.2			ms

Notes 1. Time required from voltage detection to internal reset release.

2. Time required from voltage detection to internal reset signal generation.

POC Circuit Timing



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(A2) grade product T_A = –40 to +125°C

LVI Circuit Characteristics (T_A = –40 to +125°C)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Detection voltage	V_{LVI0}		4.1	4.3	4.65	V
	V_{LVI1}		3.9	4.1	4.45	V
	V_{LVI2}		3.7	3.9	4.25	V
	V_{LVI3}		3.5	3.7	4.05	V
	V_{LVI4}		3.3	3.5	3.85	V
	V_{LVI5}		3.15	3.3	3.60	V
	V_{LVI6}		2.95	3.1	3.40	V
	V_{LVI7}		2.7	2.85	3.15	V
	V_{LVI8}		2.5	2.6	2.85	V
	V_{LVI9}		2.25	2.35	2.60	V
Response time[Note 1]	t_{LD}			0.2	2.0	ms
Minimum pulse width	t_{LW}		0.2			ms
Operation stabilization wait time[Note 2]	t_{LWAIT}			0.1	0.2	ms

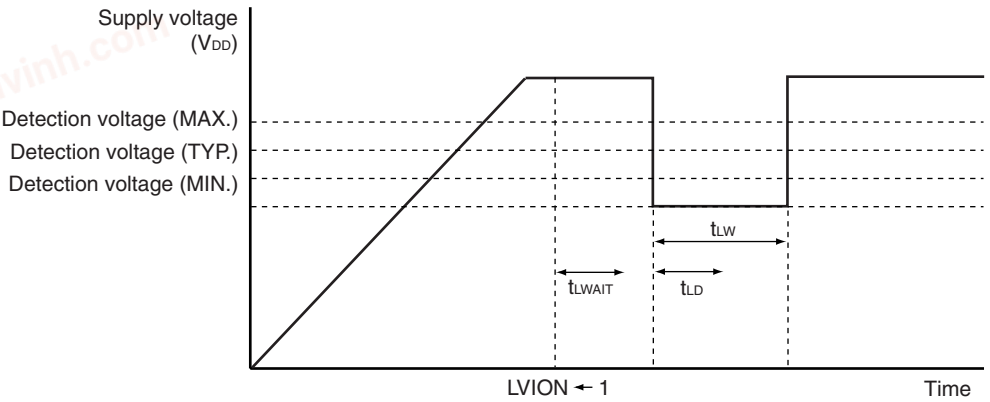
Notes 1. Time required from voltage detection to interrupt output or internal reset signal generation.

2. Time required from setting LVION to 1 to operation stabilization.

Remarks 1. $V_{LVI0} > V_{LVI1} > V_{LVI2} > V_{LVI3} > V_{LVI4} > V_{LVI5} > V_{LVI6} > V_{LVI7} > V_{LVI8} > V_{LVI9}$

2. $V_{POC} < V_{LVIm}$ (m = 0 to 9)

LVI Circuit Timing



Data Memory STOP Mode Low Supply Voltage Data Retention Characteristics (T_A = –40 to +125°C)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Data retention supply voltage	V_{DDDR}		2.0		5.5	V
Release signal set time	t_{SREL}		0			μs

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(A2) grade product T_A = –40 to +125°C

Flash Memory Programming Characteristics (T_A = –40 to +105°C, 2.7 V ≤ V_{DD} ≤ 5.5 V, V_{SS} = 0 V)

Parameter	Symbol	Conditions		MIN.	TYP.	MAX.	Unit
Supply current	I_{DD}	V_{DD} = 5.5 V				7.0	mA
Erasure count[Note 1] (per 1 block)	N_{ERASE}	T_A = –40 to +105°C		1000			Times
Chip erase time	T_{CERASE}	T_A = –10 to +105°C, N_{ERASE} ≤ 100	4.5 V ≤ V_{DD} ≤ 5.5 V			0.8	s
			3.5 V ≤ V_{DD} < 4.5 V			1.0	s
			2.7 V ≤ V_{DD} < 3.5 V			1.2	s
		T_A = –10 to +105°C, N_{ERASE} ≤ 1000	4.5 V ≤ V_{DD} ≤ 5.5 V			4.8	s
			3.5 V ≤ V_{DD} < 4.5 V			5.2	s
			2.7 V ≤ V_{DD} < 3.5 V			6.1	s
		T_A = –40 to +105°C, N_{ERASE} ≤ 100	4.5 V ≤ V_{DD} ≤ 5.5 V			1.6	s
			3.5 V ≤ V_{DD} < 4.5 V			1.8	s
			2.7 V ≤ V_{DD} < 3.5 V			2.0	s
		T_A = –40 to +105°C, N_{ERASE} ≤ 1000	4.5 V ≤ V_{DD} ≤ 5.5 V			9.1	s
			3.5 V ≤ V_{DD} < 4.5 V			10.1	s
			2.7 V ≤ V_{DD} < 3.5 V			12.3	s
Block erase time	T_{BERASE}	T_A = –10 to +105°C, N_{ERASE} ≤ 100	4.5 V ≤ V_{DD} ≤ 5.5 V			0.4	s
			3.5 V ≤ V_{DD} < 4.5 V			0.5	s
			2.7 V ≤ V_{DD} < 3.5 V			0.6	s
		T_A = –10 to +105°C, N_{ERASE} ≤ 1000	4.5 V ≤ V_{DD} ≤ 5.5 V			2.6	s
			3.5 V ≤ V_{DD} < 4.5 V			2.8	s
			2.7 V ≤ V_{DD} < 3.5 V			3.3	s
		T_A = –40 to +105°C, N_{ERASE} ≤ 100	4.5 V ≤ V_{DD} ≤ 5.5 V			0.9	s
			3.5 V ≤ V_{DD} < 4.5 V			1.0	s
			2.7 V ≤ V_{DD} < 3.5 V			1.1	s
		T_A = –40 to +105°C, N_{ERASE} ≤ 1000	4.5 V ≤ V_{DD} ≤ 5.5 V			4.9	s
			3.5 V ≤ V_{DD} < 4.5 V			5.4	s
			2.7 V ≤ V_{DD} < 3.5 V			6.6	s
Byte write time	T_{WRITE}	T_A = –40 to +105°C, N_{ERASE} ≤ 1000				150	μs
Internal verify	T_{VERIFY}	Per 1 block				6.8	ms
		Per 1 byte				27	μs
Blank check	T_{BLKCHK}	Per 1 block				480	μs
Total loss	P_T[Note 3]	T_A = –40 to +85°C				120	mW
		T_A = +85 to +105°C				110	mW
Retention years		T_A = 85°C[Note 2], N_{ERASE} ≤ 1000		10			Years

Notes 1. Depending on the erasure count (N_{ERASE}), the erase time varies. Refer to the chip erase time and block erase time parameters.

2. When the average temperature when operating and not operating is 85°C.

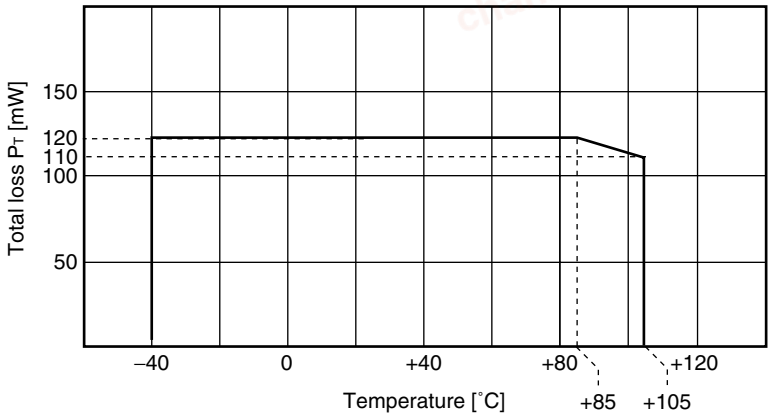
Remark When a product is first written after shipment, “erase → write” and “write only” are both taken as one rewrite.

(Note 3 is listed on the next page.)

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(A2) grade product T_A = –40 to +125°C

Note 3. This varies depending on the allowable total loss (see the figure below).



When guaranteeing the flash self programming, use the following formula to perform design such that the sum of the power consumption of the device is less than or equal to the total loss P_T (use at 80% or less of the rated value is recommended).

Total power consumption = $V_{DD} \times \{I_{DD} - \Sigma I_{OH}\} + \Sigma\{(V_{DD} - V_{OH}) \times I_{OH}\} + \Sigma(V_{OL} \times I_{OL})$

When guaranteeing the internal pull-up resistor, use the following formula to calculate its power consumption, and add the result to the result above.

Power consumption of internal pull-up resistor = $\Sigma(V_{DD}/R_{PU} \times V_{DD})$

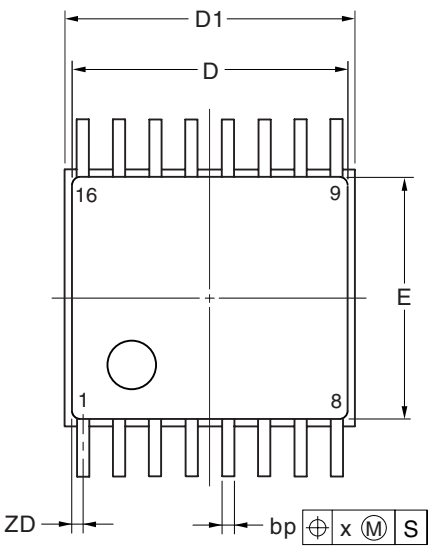
Remark During flash memory programming, I_{DD} = 7.0 mA (MAX.).

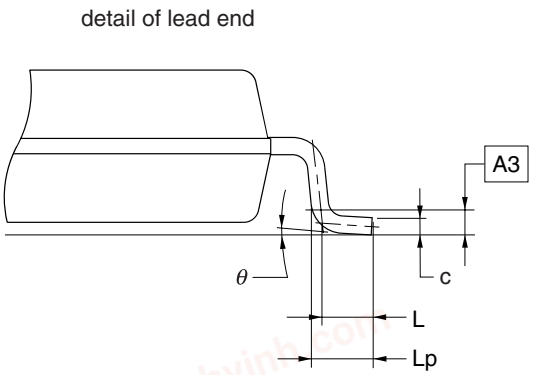
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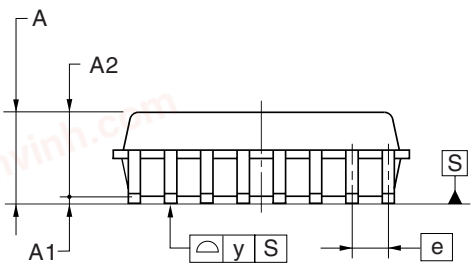
CHAPTER 21 PACKAGE DRAWING

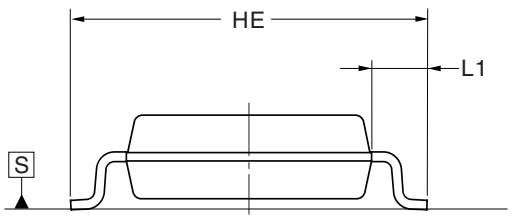
<R> • μPD78F9210MA-FAA-AX, 78F9211MA-FAA-AX, 78F9212MA-FAA-AX, 78F9210MA(A)-FAA-AX, 78F9211MA(A)-FAA-AX, 78F9212MA(A)-FAA-AX, 78F9210MA(A2)-FAA-AX, 78F9211MA(A2)-FAA-AX, 78F9212MA(A2)-FAA-AX

16-PIN PLASTIC SSOP (4.4x5.0)









(UNIT:mm)

ITEM	DIMENSIONS
D	5.00±0.15
D1	5.20±0.15
E	4.40±0.20
HE	6.40±0.20
A	1.725 MAX.
A1	0.125±0.05
A2	1.50
A3	0.25
e	0.65
bp	$0.22^{+0.08}_{-0.07}$
c	$0.15^{+0.03}_{-0.04}$
L	0.50
Lp	0.60±0.10
L1	1.00±0.20
x	0.13
y	0.10
θ	$3^{\circ}{}^{+5^{\circ}}_{-3^{\circ}}$
ZD	0.325

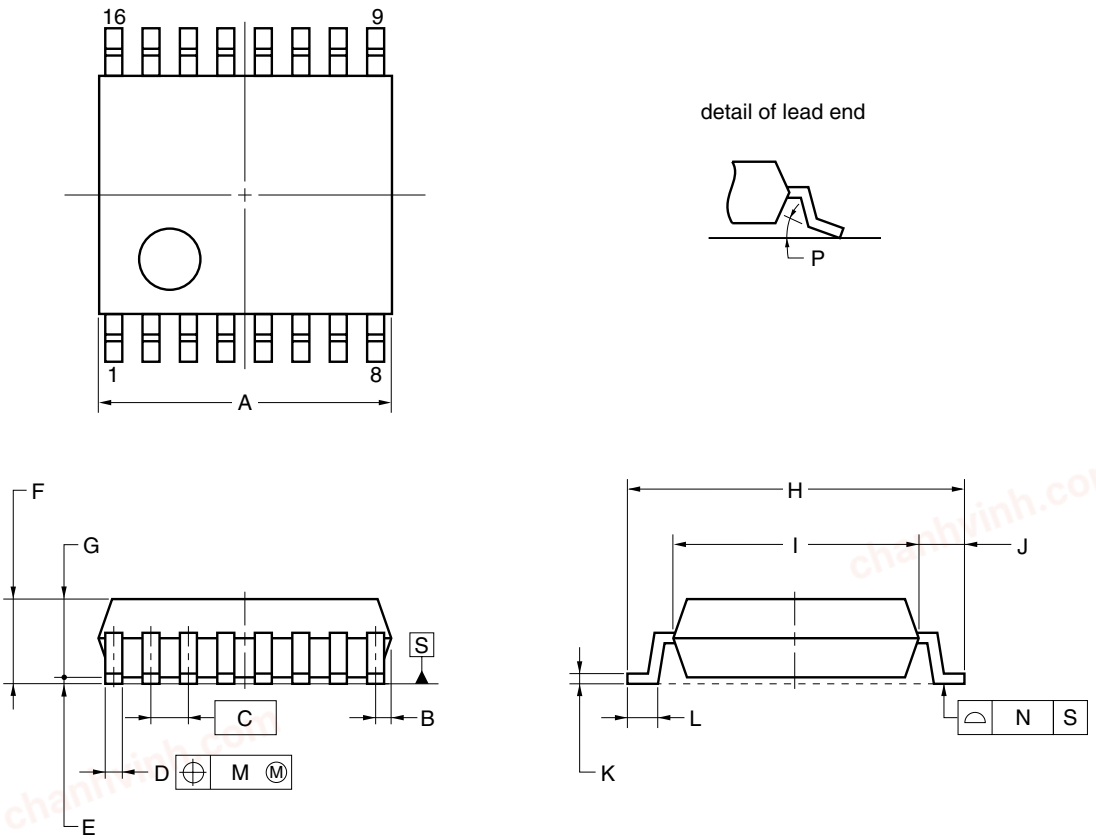
P16MA-65-FAA

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<R> • μPD78F9210GR-JJG-A, 78F9211GR-JJG-A, 78F9212GR-JJG-A, 78F9510GR-JJG-A, 78F9511GR-JJG-A, 78F9512GR-JJG-A, 78F9210GR(A)-JJG-A, 78F9211GR(A)-JJG-A, 78F9212GR(A)-JJG-A, 78F9210GR(A2)-JJG-A, 78F9211GR(A2)-JJG-A, 78F9212GR(A2)-JJG-A

16-PIN PLASTIC SSOP (5.72 mm (225))



NOTE

Each lead centerline is located within 0.10 mm of its true position (T.P.) at maximum material condition.

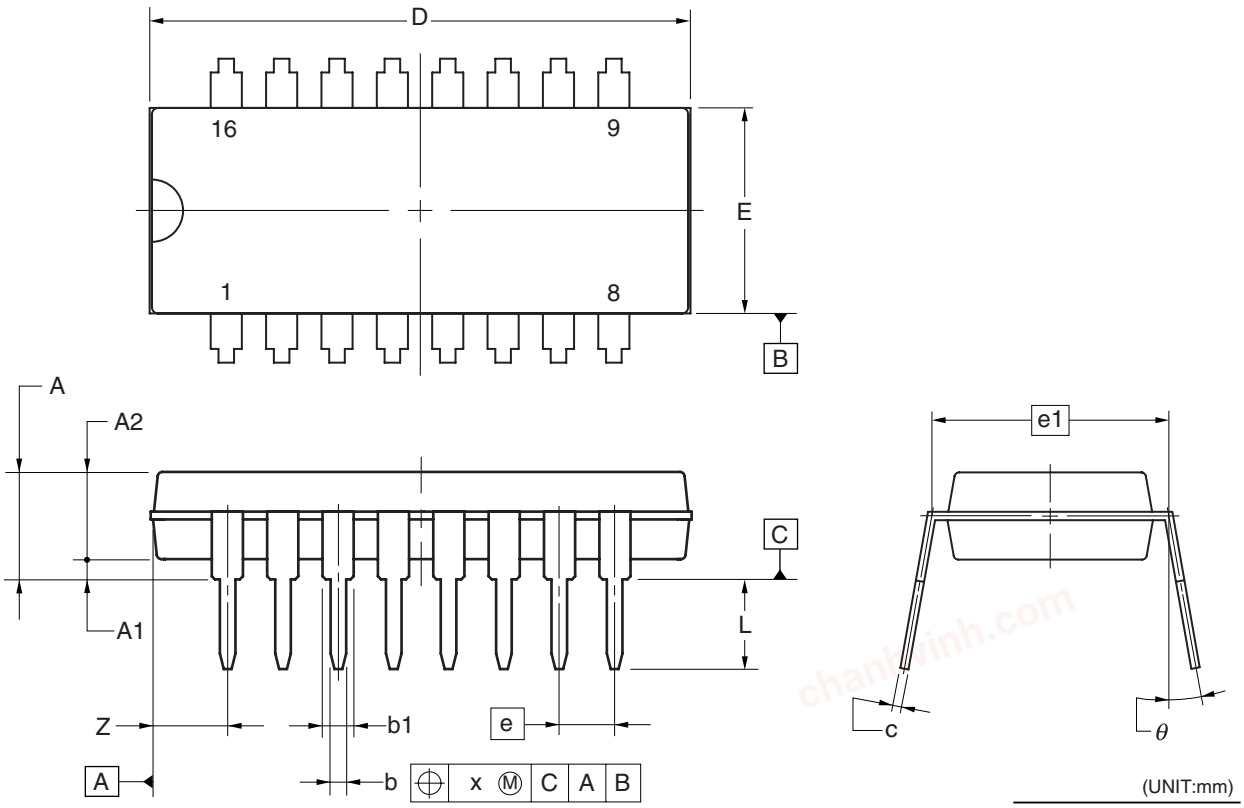
ITEM	MILLIMETERS
A	5.2±0.3
B	0.475 MAX.
C	0.65 (T.P.)
D	0.22±0.08
E	0.125±0.075
F	1.565±0.235
G	1.44
H	6.2±0.3
I	4.4±0.2
J	0.9±0.2
K	$0.17^{+0.08}_{-0.07}$
L	0.5±0.2
M	0.10
N	0.10
P	5°±5°

P16GM-65-225B-5

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• μPD78F9210CS-CAB-A, 78F9211CS-CAB-A, 78F9212CS-CAB-A

16-PIN PLASTIC SDIP (7.62mm(300))



(UNIT:mm)

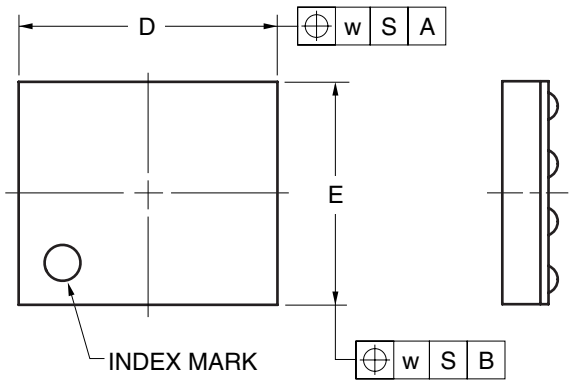
ITEM	DIMENSIONS
D	17.37±0.20
E	6.60±0.20
A	3.45±0.15
A1	0.65±0.10
A2	2.80
e	1.778
e1	7.62
b	0.50±0.10
b1	1.02±0.10
c	$0.25^{+0.10}_{-0.05}$
L	2.86±0.20
x	0.25
θ	0° to 15°
Z	2.387

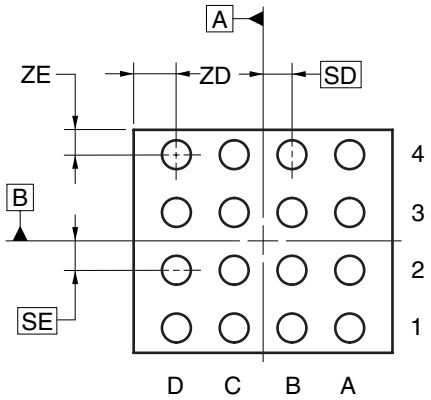
P16CS-70-CAB

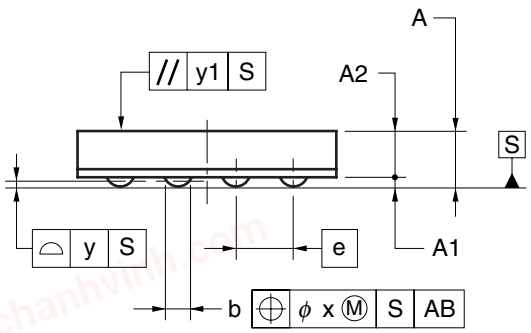
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• μPD78F9210FH-2A2-A, 78F9211FH-2A2-A, 78F9212FH-2A2-A

16-PIN FBGA (WAFER LEVEL BGA) (2.24x1.93)







(UNIT:mm)

ITEM	DIMENSIONS
D	2.24±0.05
E	1.93±0.05
w	0.20
A	0.48±0.04
A1	0.08±0.02
A2	0.40
e	0.50
SD	0.25
SE	0.25
b	0.26±0.05
x	0.05
y	0.08
y1	0.20
ZD	0.37
ZE	0.215

P16FH-50-2A2-1

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CHAPTER 22 RECOMMENDED SOLDERING CONDITIONS

These products should be soldered and mounted under the following recommended conditions.
For technical information, see the following website.

Semiconductor Device Mount Manual (http://www.necel.com/pkg/en/mount/index.html)

Caution For soldering methods and conditions other than those recommended below, contact an NEC Electronics sales representative.

Table 22-1. Surface Mounting Type Soldering Conditions (1/2)

<R> • **16-pin plastic SSOP (lead-free products)**

μPD78F9210MA-FAA-AX, 78F9211MA-FAA-AX, 78F9212MA-FAA-AX, 78F9210MA(A)-FAA-AX, 78F9211MA(A)-FAA-AX, 78F9212MA(A)-FAA-AX, 78F9210MA(A2)-FAA-AX, 78F9211MA(A2)-FAA-AX, 78F9212MA(A2)-FAA-AX

Soldering Method	Soldering Conditions	Recommended Condition Symbol
Infrared reflow	Package peak temperature: 260°C, Time: 60 seconds max. (at 220°C or higher), Count: 3 times or less, Exposure limit: 7 days[Note] (after that, prebake at 125°C for 10 to 72 hours)	IR60-107-3
Wave soldering	For details, contact an NEC Electronics sales representative.	–
Partial heating	Pin temperature: 350°C max., Time: 3 seconds max. (per pin row)	–

Note After opening the dry pack, store it at 25°C or less and 65% RH or less for the allowable storage period.

Caution Do not use different soldering methods together (except for partial heating).

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Table 22-1. Surface Mounting Type Soldering Conditions (2/2)

- **16-pin plastic SSOP (lead-free products)**

<R> μPD78F9210GR-JJG-A, 78F9211GR-JJG-A, 78F9212GR-JJG-A, 78F9510GR-JJG-A, 78F9511GR-JJG-A, 78F9512GR-JJG-A, 78F9210GR(A)-JJG-A, 78F9211GR(A)-JJG-A, 78F9212GR(A)-JJG-A, 78F9210GR(A2)-JJG-A, 78F9211GR(A2)-JJG-A, 78F9212GR(A2)-JJG-A

Soldering Method	Soldering Conditions	Recommended Condition Symbol
Infrared reflow	Package peak temperature: 260°C, Time: 60 seconds max. (at 220°C or higher), Count: 3 times or less, Exposure limit: 7 days[Note] (after that, prebake at 125°C for 20 to 72 hours)	IR60-207-3
Wave soldering	For details, contact an NEC Electronics sales representative.	–
Partial heating	Pin temperature: 350°C max., Time: 3 seconds max. (per pin row)	–

Note After opening the dry pack, store it at 25°C or less and 65% RH or less for the allowable storage period.

Caution Do not use different soldering methods together (except for partial heating).

- **16-pin plastic SDIP (lead-free products)**

μPD78F9210CS-CAB-A, 78F9211CS-CAB-A, 78F9212CS-CAB-A

Soldering Method	Soldering Conditions
Wave soldering (only for pins)	Solder bath temperature: 260°C, Time: 10 seconds max. (at 220°C or higher)
Partial heating	Pin temperature: 350°C max., Time: 3 seconds max. (per one pin)

Caution Only the pins of the THD are heated when performing wave soldering.
Make sure that flow solder does not come in contact with the package.

- **16-pin WLBGA (2.24 × 1.93) (lead-free products)**

μPD78F9210FH-2A2-A, 78F9211FH-2A2-A, 78F9212FH-2A2-A

Soldering Method	Soldering Conditions	Recommended Condition Symbol
Infrared reflow	Package peak temperature: 260°C, Time: 60 seconds max. (at 220°C or higher) Count: 3 times or less	IR60-00-3

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<R>

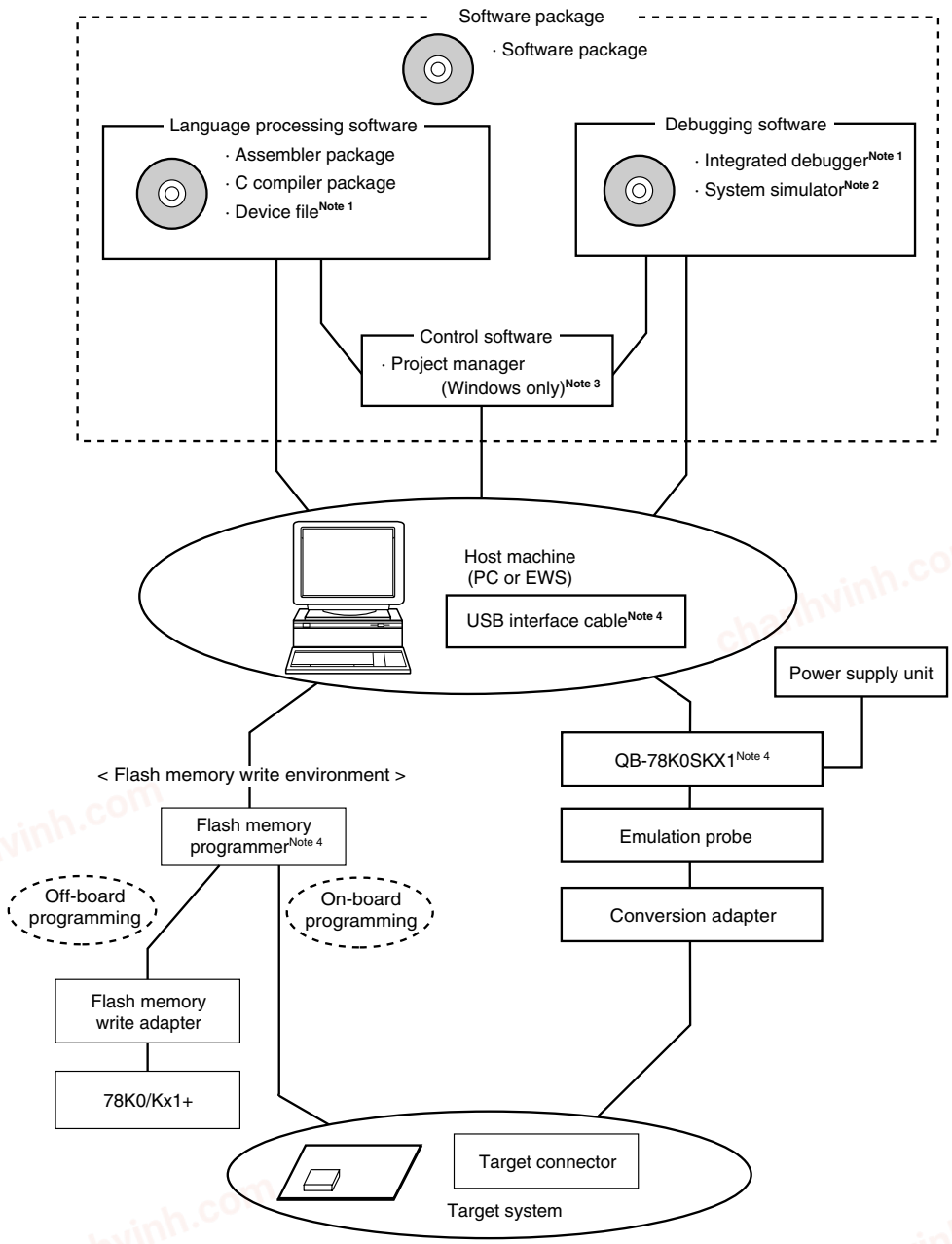
APPENDIX A DEVELOPMENT TOOLS

The following development tools are available for development of systems using the 78K0S/KY1+.
Figure A-1 shows the development tool configuration.

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Figure A-1. Development Tools (1/2)

(1) When using the in-circuit emulator QB-78K0SKX1



Notes 1. Download the device file for 78K0S/Kx1+ microcontrollers (DF789234) and the integrated debugger ID78K0S-QB from the download site for development tools (http://www.necel.com/micro/en/ods/).

2. SM+ for 78K0S (instruction simulation version) is included in the software package. SM+ for 78K0S/Kx1+ (instruction + peripheral simulation version) is not included.

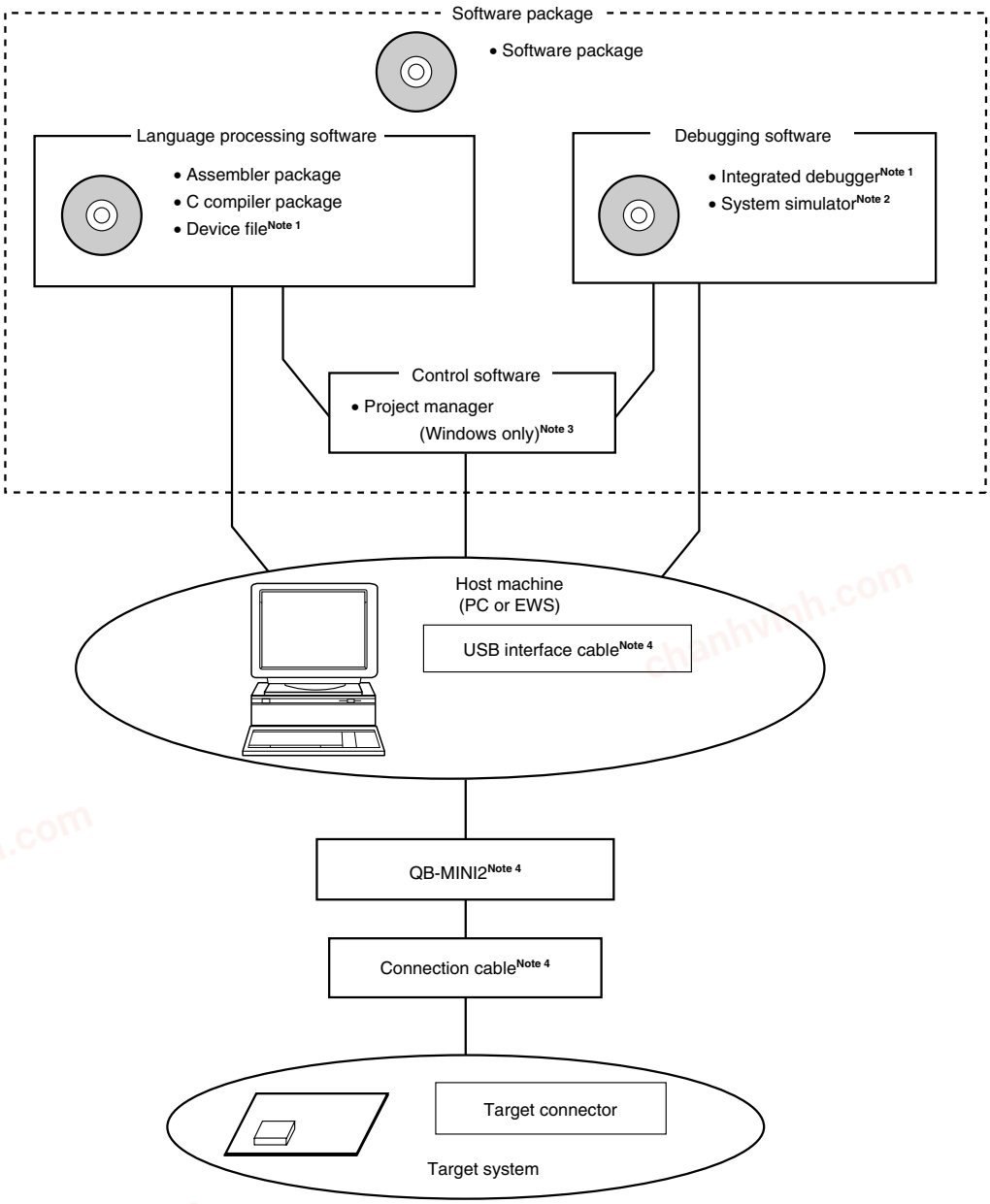
3. The project manager PM+ is included in the assembler package.
PM+ cannot be used other than with Windows™.

4. QB-78K0SKX1 is supplied with the integrated debugger ID78K0S-QB, a USB interface cable, the on-chip debug emulator with programming function QB-MINI2, a connection cable, and a target cable. Any other products are sold separately.

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Figure A-1. Development Tools (2/2)

(2) When using the on-chip debug emulator with programming function QB-MINI2



Notes 1. Download the device file for 78K0S/Kx1+ microcontrollers (DF789234) and the integrated debugger ID78K0S-QB from the download site for development tools (http://www.necel.com/micro/en/ods/).

2. SM+ for 78K0S (instruction simulation version) is included in the software package. SM+ for 78K0S/Kx1+ (instruction + peripheral simulation version) is not included.

3. The project manager PM+ is included in the assembler package.
PM+ cannot be used other than with Windows.

4. QB-MINI2 is supplied with USB interface cable and connection cable. Any other products are sold separately. In addition, download the software for operating the QB-MINI2 from the download site for development tools (http://www.necel.com/micro/en/ods/).

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A.1 Software Package

SP78K0S 78K0S microcontroller software package	Development tools (software) common to the 78K0S microcontrollers are combined in this package.

A.2 Language Processing Software

RA78K0S[Note 1] Assembler package	This assembler converts programs written in mnemonics into object codes executable with a microcontroller. This assembler is also provided with functions capable of automatically creating symbol tables and branch instruction optimization. This assembler should be used in combination with a device file (DF789234). **<Precaution when using RA78K0S in PC environment>** This assembler package is a DOS-based application. It can also be used in Windows, however, by using the Project Manager (PM+) on Windows. PM+ is included in assembler package.
CC78K0S[Note 1] C compiler package	This compiler converts programs written in C language into object codes executable with a microcontroller. This compiler should be used in combination with an assembler package and device file. **<Precaution when using CC78K0S in PC environment>** This C compiler package is a DOS-based application. It can also be used in Windows, however, by using the Project Manager (PM+) on Windows. PM+ is included in assembler package.
DF789234[Note 2] Device file	This file contains information peculiar to the device. This device file should be used in combination with a tool (RA78K0S, CC78K0S, ID78K0S-QB, and the system simulator). The corresponding OS and host machine differ depending on the tool to be used.

Notes 1. If the versions of RA78K0S and CC78K0S are Ver.2.00 or later, different versions of RA78K0S and CC78K0S can be installed on the same machine.

2. The DF789234 can be used in common with the RA78K0S, CC78K0S, ID78K0S-QB, and the system simulator. Download the DF789234 from the download site for development tools (http://www.necel.com/micro/en/ods/).

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A.3 Flash Memory Writing Tools

A.3.1 When using flash memory programmer PG-FP5 and FL-PR5

FL-PR5, PG-FP5 Flash memory programmer	This is a flash memory programmer dedicated to microcontrollers incorporating a flash memory.
FA-78F9212GR-JJG-RX Flash memory writing adapter	This is a flash memory writing adapter which is used in connection with the flash memory programmer.

Remarks 1. FL-PR5 and FA-78F9234MC-5A4-RX are products of Naito Densei Machida Mfg. Co., Ltd (http://www.ndk-m.co.jp/, e-mail: info@ndk-m.co.jp).

2. The flash memory writing adapter for 16-pin plastic SSOP (MA-FAA type) is under development. Please contact Naito Densei Machida Mfg. Co., Ltd. for the development status.

3. Use the latest version of the flash memory programming adapter.

A.3.2 When using on-chip debug emulator with programming function QB-MINI2

QB-MINI2 On-chip debug emulator with programming function	This is a flash memory programmer dedicated to microcontrollers with on-chip flash memory. It is available also as on-chip debug emulator which serves to debug hardware and software when developing application systems using the 78K0S/Kx1+ microcontrollers. When using this as flash memory programmer, it should be used in combination with a connection cable and a USB interface cable that is used to connect the host machine.
Target connector specifications	16-pin general-purpose connector (2.54 mm pitch)

Remark Download the software for operating the QB-MINI2 from the download site for development tools (http://www.necel.com/micro/en/ods/).

A.4 Debugging Tools (Hardware)

A.4.1 When using in-circuit emulator QB-78K0SKX1

QB-78K0SKX1 In-circuit emulator	This in-circuit emulator serves to debug hardware and software when developing application systems using the 78K0S/Kx1+ microcontrollers. It supports the integrated debugger (ID78K0S-QB). This emulator should be used in combination with a power supply unit and emulation probe, and the USB is used to connect this emulator to the host machine.
QB-50-EP-01T[Note] Emulation probe	This is a flexible type emulation probe and is used to connect the in-circuit emulator and target system.
QB-16GR-EA-01T[Note] Exchange adapter	This exchange adapter is used to perform pin conversion from the in-circuit emulator to target connector.
QB-16GR -NQ-01T[Note] Target connector	This target connector is used to mount on the target system.
Specifications of pin header on target system	0.635 mm × 0.635 mm (height: 6 mm)

(Note and Remarks are listed on the next page or later.)

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Note The part numbers of the exchange adapter and target connector and the packages of the target device are described below.

Package	Exchange Adapter	Target Connector
16-pin plastic SSOP (GR-JJG type)	QB-16GR-EA-01T	QB-16GR-NQ-01T
16-pin plastic SSOP (MA-FAA type)	Under development	Under development
16-pin plastic SDIP (CS-CAB type)	None	None
16-pin WLBGA (FH-2A2 type)		

Remarks 1. For the SDIP package, use the target cable.

2. The QB-78K0SKX1 is supplied with the integrated debugger ID78K0S-QB, a USB interface cable, the on-chip debug emulator QB-MINI2, and a connection cable.
Download the software for operating the QB-MINI2 from the download site for development tools (http://www.necel.com/micro/en/ods/) when using the QB-MINI2.

3. The packed contents of QB-78K0SKX1 differ depending on the part number, as follows.

Packed Contents / Part Number	In-Circuit Emulator	Emulation Probe	Exchange Adapter	Target Connector
QB-78K0SKX1-ZZZ	QB-78K0SKX1	None		
QB-78K0SKX1-T16GR		QB-50-EP-01T	QB-16GR-EA-01T	QB-16GR-NQ-01T

A.4.2 When using on-chip debug emulator with programming function QB-MINI2

QB-MINI2 On-chip debug emulator with programming function	This on-chip debug emulator serves to debug hardware and software when developing application systems using the 78K0S/Kx1+ microcontrollers. It is available also as flash memory programmer dedicated to microcontrollers with on-chip flash memory. When using this as on-chip debug emulator, it should be used in combination with a connection cable and a USB interface cable that is used to connect the host machine.
Target connector specifications	16-pin general-purpose connector (2.54 mm pitch)

Remark Download the software for operating the QB-MINI2 from the download site for development tools (http://www.necel.com/micro/en/ods/).

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A.5 Debugging Tools (Software)

ID78K0S-QB[Note] (supporting QB-78K0SKX1, QB-MINI2) Integrated debugger	This debugger supports the in-circuit emulators for the 78K0S/Kx1+ microcontrollers. The ID78K0S-QB is Windows-based software. Provided with the debug function supporting C language, source programming, disassemble display, and memory display are possible. It should be used in combination with the device file (DF789234).
SM+ for 78K0S SM+ for 78K0S/Kx1+[Note] System simulator	System simulator is Windows-based software. It is used to perform debugging at the C source level or assembler level while simulating the operation of the target system on a host machine. Use of system simulator allows the execution of application logical testing and performance testing on an independent basis from hardware development, thereby providing higher development efficiency and software quality. System simulator should be used in combination with the device file (DF789234). The following two types of system simulators supporting the 78K0S/Kx1+ microcontrollers are available. • SM+ for 78K0S (instruction simulation version) This can only simulate a CPU. It is included in the software package. • SM+ for 78K0S/Kx1+ (instruction + peripheral simulation version) This can simulate a CPU and peripheral hardware (ports, timers, serial interfaces, etc.).

Note Download the ID78K0S-QB from the download site for development tools (http://www.necel.com/micro/en/ods/).

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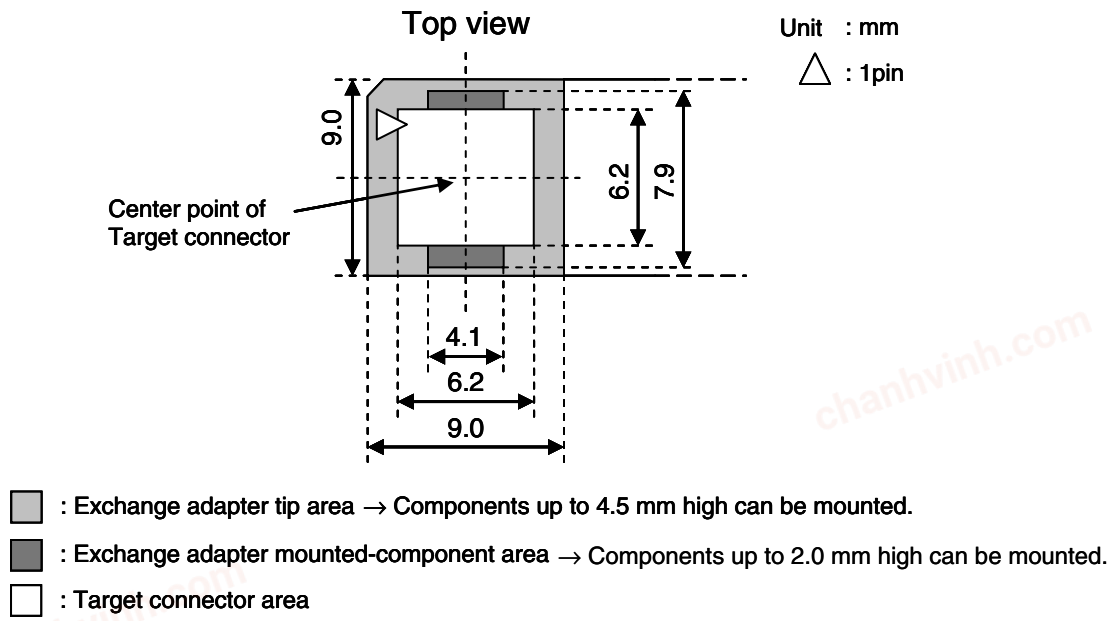
APPENDIX B NOTES ON DESIGNING TARGET SYSTEM

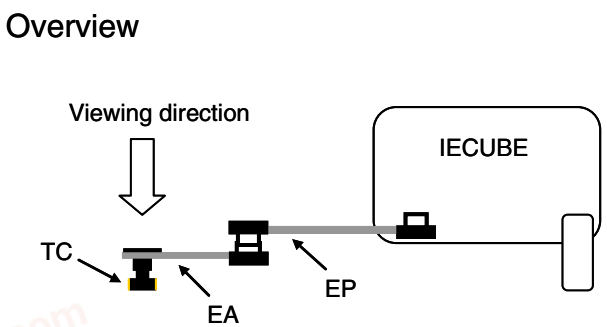
This chapter shows areas on the target system where component mounting is prohibited and areas where there are component mounting height restrictions when the QB-78K0SKX1 is used.

For the package drawings of the target connector, exchange adapter, and emulation probe, see the following website.

http://www.necel.com/micro/en/development/asia/iecube/outline_QB.html

Figure B-1. When using the 78K0S/Kx1+ emulation probe (For 16-Pin GR Package)

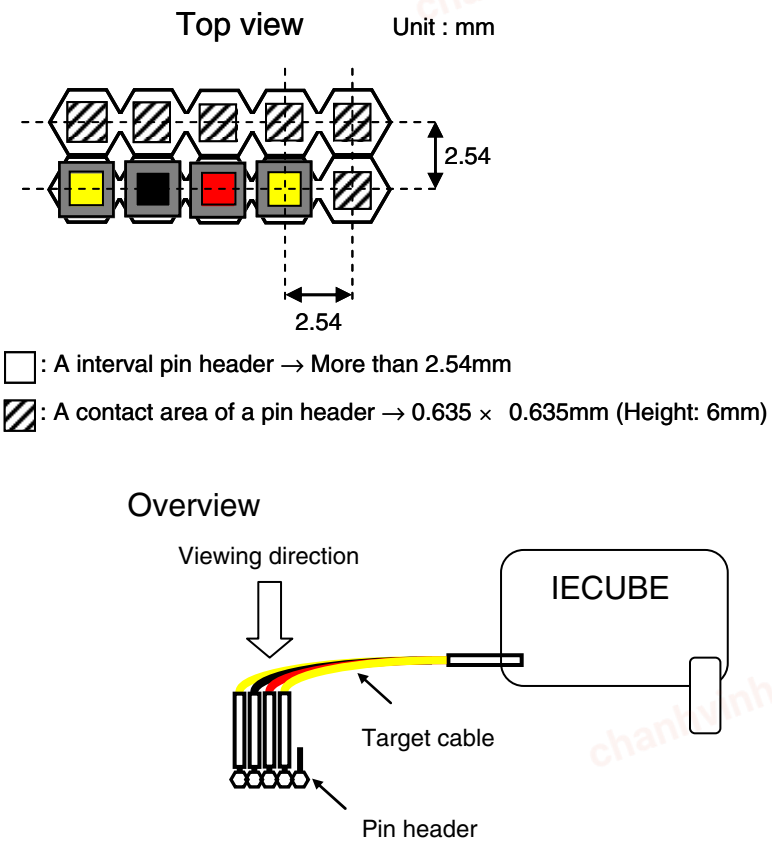




Note EP: Emulation probe
EA: Exchange adapter
TC: Target connector

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Figure B-2. When using the 78K0S/Kx1+ target cable (single track)



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APPENDIX C REGISTER INDEX

C.1 Register Index (Register Name)

[A]
A/D converter mode register (ADM) … 161
Analog input channel specification register (ADS) … 164

[C]
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C.2 Register Index (Symbol)

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ADCRH: 8-bit A/D conversion result register … 165
ADM: A/D converter mode register … 161
ADS: Analog input channel specification register … 164

[C]

CMP01: 8-bit timer H compare register 01 … 133
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[F]

FLAPH: Flash address pointer H … 240
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[P]

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TM00: 16-bit timer counter 00 … 92
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APPENDIX D LIST OF CAUTIONS

This appendix lists cautions described in this document.
“Classification (hard/soft)” in table is as follows.

Hard: Cautions for microcontroller internal/external hardware
Soft: Cautions for software such as register settings or programs

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Chapter	Classification	Function	Details of Function	Cautions	Page
Chapter 2	Hard	Pin functions	P22/X2/ANI2, P23/X1/ANI3 (μPD78F921x)	The P22/X2/ANI2, P23/X1/ANI3 pins are pulled down during reset.	pp. 24, 25, 27, 28 ☐
			P22/X2,P23/X1 (μPD78F951x)	The P22/X2, P23/X1 pins are pulled down during reset.	p. 26 ☐
Chapter 3	Soft	Memory space	SP: stack pointer	Since reset signal generation makes the SP contents undefined, be sure to initialize the SP before using the stack memory.	p. 40 ☐
				Stack pointers can be set only to the high-speed RAM area, and only the lower 10 bits can be actually set. Thus, if the stack pointer is specified to 0FF00H, it is converted to 0FB00H in the high-speed RAM area, since 0FF00H is in the SFR area and not in the high-speed RAM area. When the value is actually pushed onto the stack, 1 is subtracted from 0FB00H to become 0FAFFH, but since that value is not in the high-speed RAM area, it is converted to 0FEFFH, which is the same value as when 0FF00H is set to the stack pointer.	p. 40 ☐
Chapter 4	Hard	Port functions	P22,P23	The P22/X2/ANI2, P23/X1/ANI3 pins are pulled down during reset.	p. 57 ☐
			P34	Because the P34 pin functions alternately as the $\overline{\text{RESET}}$ pin, if it is used as an input port pin, the function to input an external reset signal to the $\overline{\text{RESET}}$ pin cannot be used. The function of the port is selected by the option byte. For details, refer to CHAPTER 15 OPTION BYTE. Also, since the option byte is referenced after the reset release, if low level is input to the $\overline{\text{RESET}}$ pin before the referencing, then the reset state is not released. When it is used as an input port pin, connect the pull-up resistor.	p. 66 ☐
			P21, P32	Because P21 and P32 are also used as external interrupt pins, the corresponding interrupt request flag is set if each of these pins is set to the output mode and its output level is changed. To use the port pin in the output mode, therefore, set the corresponding interrupt mask flag to 1 in advance.	p. 68 ☐
			PMC2: Port mode control register 2 (μPD78F921x only)	When PMC20 to PMC23 are set to 1, the port function on the P20/ANI0 to P23/ANI3 pins cannot be used. Moreover, be sure to set the pull-up resistor option registers (PU20 to PU23) to 0 for the pins set to A/D converter mode.	p. 70 ☐
			–	Although a 1-bit memory manipulation instruction manipulates 1 bit, it accesses a port in 8-bit units. Therefore, the contents of the output latch of a pin in the input mode, even if it is not subject to manipulation by the instruction, are undefined in a port with a mixture of inputs and outputs.	p. 72 ☐

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Chapter	Classification	Function	Details of Function	Cautions	Page
Chapter 5	Soft	Main clock	OSTS: Oscillation stabilization time select register	To set and then release the STOP mode, set the oscillation stabilization time as follows. Expected oscillation stabilization time of resonator ≤ Oscillation stabilization time set by OSTS	p. 78 ☐
				The wait time after the STOP mode is released does not include the time from the release of the STOP mode to the start of clock oscillation (“a” in the figure below), regardless of whether STOP mode was released by reset input or interrupt generation.	p. 78 ☐
				The oscillation stabilization time that elapses on power application or after release of reset is selected by the option byte. For details, refer to CHAPTER 15 OPTION BYTE.	p. 78 ☐
	Hard	Crystal/ ceramic oscillator	–	When using the crystal/ceramic oscillator, wire as follows in the area enclosed by the broken lines in Figure 5-6 to avoid an adverse effect from wiring capacitance. • Keep the wiring length as short as possible. • Do not cross the wiring with the other signal lines. Do not route the wiring near a signal line through which a high fluctuating current flows. • Always make the ground point of the oscillator capacitor the same potential as V_{SS}. Do not ground the capacitor to a ground pattern through which a high current flows. • Do not fetch signals from the oscillator.	p. 79 ☐
Chapter 6	Hard	16-bit timer/ event counter 00	TM00: 16-bit timer counter 00	Even if TM00 is read, the value is not captured by CR010.	pp. 92, 124 ☐
				When TM00 is read, count misses do not occur, since the input of the count clock is temporarily stopped and then resumed after the read.	pp. 92, 124 ☐
	Soft		CR000: 16-bit timer capture/ compare register 000	Set CR000 to other than 0000H in the clear & start mode entered on match between TM00 and CR000. This means a 1-pulse count operation cannot be performed when this register is used as an external event counter.	pp. 93, 124 ☐
				In the free-running mode and in the clear & start mode using the valid edge of the TI000 pin, if CR000 is set to 0000H, an interrupt request (INTTM000) is generated when CR000 changes from 0000H to 0001H after an overflow (FFFFH).	pp.93, 124 ☐
				If the new value of CR000 is less than the value of 16-bit timer counter 0 (TM00), TM00 continues counting, overflows, and then starts counting from 0 again. If the new value of CR000 is less than the old value, therefore, the timer must be reset to be restarted after the value of CR000 is changed.	pp. 93, 124 ☐
				The value of CR000 after 16-bit timer/event counter 00 has stopped is not guaranteed.	pp. 93, 125 ☐
	Hard			The capture operation may not be performed for CR000 set in compare mode even if a capture trigger is input.	pp. 93, 127 ☐
				When using P21 as the input pin (TI010) of the valid edge, it cannot be used as a timer output pin (TO00). When using P21 as the timer output pin (TO00), it cannot be used as the input pin (TI010) of the valid edge.	pp. 93, 100, 129 ☐
				If the register read period and the input of the capture trigger conflict when CR000 is used as a capture register, the capture trigger input takes precedence and the read data is undefined. Also, if the count stop of the timer and the input of the capture trigger conflict, the capture trigger is undefined.	pp. 93, 126 ☐
	Soft			Changing the CR000 setting may cause a malfunction. To change the setting, refer to 6.5 Cautions Related to 16-bit Timer/Event Counter 00 (17) Changing compare register during timer operation.	p. 93 ☐

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Chapter	Classification	Function	Details of Function	Cautions	Page
Chapter 6	Soft	16-bit timer/ event counter 00	CR010: 16-bit timer capture/ compare register 010	In the free-running mode and in the clear & start mode using the valid edge of the TI000 pin, if CR010 is set to 0000H, an interrupt request (INTTM010) is generated when CR010 changes from 0000H to 0001H after an overflow (FFFFH).	pp. 94, 124 ☐
				If the new value of CR010 is less than the value of 16-bit timer counter 00 (TM00), TM00 continues counting, overflows, and then starts counting from 0 again. If the new value of CR010 is less than the old value, therefore, the timer must be reset to be restarted after the value of CR010 is changed.	pp. 94, 124 ☐
				The value of CR010 after 16-bit timer/event counter 00 has stopped is not guaranteed.	pp. 94, 125 ☐
	Hard			The capture operation may not be performed for CR010 set in compare mode even if a capture trigger is input.	pp. 94, 127 ☐
				If the register read period and the input of the capture trigger conflict when CR010 is used as a capture register, the capture trigger input takes precedence and the read data is undefined. Also, if the timer count stop and the input of the capture trigger conflict, the capture data is undefined.	pp. 94, 126 ☐
	Soft			Changing the CR010 setting during TM00 operation may cause a malfunction. To change the setting, refer to 6.5 Cautions Related to 16-bit Timer/Event Counter 00 (17) Changing compare register during timer operation.	p. 95 ☐
			TMC00: 16-bit timer mode control register 00	16-bit timer counter 00 (TM00) starts operating as soon as values other than 0 and 0 (operation stop mode) are set to TMC002 and TMC003, respectively. Set TMC002 and TMC003 to 0 and 0 to stop operation.	pp. 95, 124 ☐
				The timer operation must be stopped before writing to bits other than the OVF00 flag.	pp. 96, 125 ☐
	Hard			If the timer is stopped, timer counts and timer interrupts do not occur, even if a signal is input to the TI000/TI010 pins.	pp. 96, 124 ☐
	Soft			Except when the valid edge of the TI000 pin is selected as the count clock, stop the timer operation before setting STOP mode or system clock stop mode; otherwise the timer may malfunction when the system clock starts.	pp. 96, 129 ☐
				Set the valid edge of the TI000 pin with bits 4 and 5 of prescaler mode register 00 (PRM00) after stopping the timer operation.	pp. 96, 125 ☐
				If the clear & start mode entered on a match between TM00 and CR000, clear & start mode at the valid edge of the TI000 pin, or free-running mode is selected, when the set value of CR000 is FFFFH and the TM00 value changes from FFFFH to 0000H, the OVF00 flag is set to 1.	p. 96 ☐
				Even if the OVF00 flag is cleared before the next count clock is counted (before TM00 becomes 0001H) after the occurrence of a TM00 overflow, the OVF00 flag is re-set and clearance becomes invalid.	pp. 96, 126 ☐
				The capture operation is performed at the fall of the count clock. An interrupt request input (INTTM0n0), however, occurs at the rise of the next count clock.	pp. 96, 127 ☐
			CRC00: Capture/ compare control register 00	The timer operation must be stopped before setting CRC00.	pp. 97, 125 ☐
				When the clear & start mode entered on a match between TM00 and CR000 is selected by 16-bit timer mode control register 00 (TMC00), CR000 should not be specified as a capture register.	pp. 97, 124 ☐
	Hard			To ensure the reliability of the capture operation, the capture trigger requires a pulse longer than two cycles of the count clock selected by prescaler mode register 00 (PRM00) (refer to Figure 6-18).	pp. 97, 127 ☐

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Chapter	Classification	Function	Details of Function	Cautions	Page
Chapter 6	Soft	16-bit timer/ event counter 00	TOC00: 16-bit timer output control register 00	Timer operation must be stopped before setting other than OSPT00.	pp. 98, 125 ☐
				If LVS00 and LVR00 are read, 0 is read.	pp. 98, 125 ☐
				OSPT00 is automatically cleared after data is set, so 0 is read.	pp. 98, 125 ☐
				Do not set OSPT00 to 1 other than in one-shot pulse output mode.	pp. 98, 125 ☐
	Hard			A write interval of two cycles or more of the count clock selected by prescaler mode register 00 (PRM00) is required, when OSPT00 is set to 1 successively.	pp. 98, 125 ☐
	Soft			When TOE00 is 0, set TOE00, LVS00, and LVR00 at the same time with the 8-bit memory manipulation instruction. When TOE00 is 1, LVS00 and LVR00 can be set with the 1-bit memory manipulation instruction.	p. 99 ☐
			PRM00: Prescaler mode register 00	Always set data to PRM00 after stopping the timer operation.	pp. 99, 125 ☐
				If the valid edge of the TI000 pin is to be set as the count clock, do not set the clear/start mode and the capture trigger at the valid edge of the TI000 pin.	pp. 99, 127 ☐
	Hard			In the following cases, note with caution that the valid edge of the TI0n0 pin is detected. <1> Immediately after a system reset, if a high level is input to the TI0n0 pin, the operation of 16-bit timer counter 00 (TM00) is enabled →If the rising edge or both rising and falling edges are specified as the valid edge of the TI0n0 pin, a rising edge is detected immediately after the TM00 operation is enabled. <2> If the TM00 operation is stopped while the TI0n0 pin is at high level, TM00 operation is then enabled after a low level is input to the TI0n0 pin →If the falling edge or both rising and falling edges are specified as the valid edge of the TI0n0 pin, a falling edge is detected immediately after the TM00 operation is enabled. <3> If the TM00 operation is stopped while the TI0n0 pin is at low level, TM00 operation is then enabled after a high level is input to the TI0n0 pin →If the rising edge or both rising and falling edges are specified as the valid edge of the TI0n0 pin, a rising edge is detected immediately after the TM00 operation is enabled.	pp. 100, 129 ☐
				The sampling clock used to eliminate noise differs when the valid edge of TI000 is used as the count clock and when it is used as a capture trigger. In the former case, the count clock is f_{XP}, and in the latter case the count clock is selected by prescaler mode register 00 (PRM00). The capture operation is not performed until the valid edge is sampled and the valid level is detected twice, thus eliminating noise with a short pulse width.	pp. 100, 129 ☐
				When using P21 as the input pin (TI010) of the valid edge, it cannot be used as a timer output pin (TO00). When using P21 as the timer output pin (TO00), it cannot be used as the input pin (TI010) of the valid edge.	pp. 100, 129 ☐
	Soft		Interval timer	Changing the CR000 setting during TM00 operation may cause a malfunction. To change the setting, refer to 6.5 Cautions Related to 16-bit Timer/Event Counter 00 (17) Changing compare register during timer operation.	p. 101 ☐
			External event counter	When reading the external event counter count value, TM00 should be read.	pp. 105, 129 ☐

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Chapter	Classification	Function	Details of Function	Cautions	Page
Chapter 6	Soft	16-bit timer/ event counter 00	Pulse width measurement	To use two capture registers, set the TI000 and TI010 pins.	pp. 106, 127 ☐
				The measurable pulse width in this operation example is up to 1 cycle of the timer counter.	pp. 106, 108, 110, 112 ☐
			Square-wave output	Changing the CR000 setting during TM00 operation may cause a malfunction. To change the setting, refer to 6.5 Cautions Related to 16-bit Timer/Event Counter 00 (17) Changing compare register during timer operation.	p. 114 ☐
			PPG output	Changing the CRC0n0 setting during TM00 operation may cause a malfunction. To change the setting, refer to 6.5 Cautions Related to 16-bit Timer/Event Counter 00 (17) Changing compare register during timer operation.	p. 116 ☐
				Values in the following range should be set to CR000 and CR010. 0000H < CR010 < CR000 ≤ FFFFH	pp. 117, 129 ☐
				The cycle of the pulse generated through PPG output (CR000 setting value + 1) has a duty of (CR010 setting value + 1)/(CR000 setting value + 1).	pp. 117, 129 ☐
			One-shot pulse output: software trigger	Do not set the OSPT00 bit to 1 again while the one-shot pulse is being output. To output the one-shot pulse again, wait until the current one-shot pulse output is completed.	pp. 119, 125 ☐
	Hard			When using the one-shot pulse output of 16-bit timer/event counter 00 with a software trigger, do not change the level of the TI000 pin or its alternate-function port pin. Because the external trigger is valid even in this case, the timer is cleared and started even at the level of the TI000 pin or its alternate-function port pin, resulting in the output of a pulse at an undesired timing.	pp. 119, 125 ☐
	Soft			Do not set 0000H to the CR000 and CR010 registers.	pp. 120, 122 ☐
				16-bit timer counter 00 starts operating as soon as a value other than 00 (operation stop mode) is set to the TMC003 and TMC002 bits.	pp. 121, 124 ☐
	Hard		One-shot pulse output: external trigger	Do not input the external trigger again while the one-shot pulse is output. To output the one-shot pulse again, wait until the current one-shot pulse output is completed.	pp. 121, 126 ☐
	Soft			Do not set the CR000 and CR010 registers to 0000H.	pp. 122, 126 ☐
				16-bit timer counter 00 starts operating as soon as a value other than 00 (operation stop mode) is set to the TMC002 and TMC003 bits.	pp. 123, 124 ☐
	Hard		Timer start errors	An error of up to one clock may occur in the time required for a match signal to be generated after timer start. This is because 16-bit timer counter 00 (TM00) is started asynchronously to the count clock.	p. 124 ☐
	Soft		One-shot pulse output	One-shot pulse output normally operates only in the free-running mode or in the clear & start mode at the valid edge of the TI000 pin. Because an overflow does not occur in the clear & start mode on a match between TM00 and CR000, one-shot pulse output is not possible.	p. 125 ☐
			Capture operation	When the CRC001 bit value is 1, capture is not performed in the CR000 register if both the rising and falling edges have been selected as the valid edges of the TI000 pin.	p. 127 ☐
				When the CRC001 bit value is 1, the TM00 count value is not captured in the CR000 register when a valid edge of the TI010 pin is detected, but the input from the TI010 pin can be used as an external interrupt source because INTTM000 is generated at that timing.	p. 127 ☐

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Chapter	Classification	Function	Details of Function	Cautions	Page
Chapter 6	Soft	16-bit timer/ event counter 00	Changing compare register during timer operation	With the 16-bit timer capture/compare register 0n0 (CR0n0) used as a compare register, when changing CR0n0 around the timing of a match between 16-bit timer counter 00 (TM00) and 16-bit timer capture/compare register 0n0 (CR0n0) during timer counting, the change timing may conflict with the timing of the match, so the operation is not guaranteed in such cases. To change CR0n0 during timer counting, INTTM000 interrupt servicing performs the following operation.	p. 128 ☐
				If CR010 is changed during timer counting without performing processing <1> above, the value in CR010 may be rewritten twice or more, causing an inversion of the output level of the TO00 pin at each rewrite.	p. 128 ☐
			External event counter	The timing of the count start is after two valid edge detections.	p. 129 ☐
	Hard		External clock limitation	When using an input pulse of the TI000 pin as a count clock (external trigger), be sure to input the pulse width which satisfies the AC characteristics. For the AC characteristics, refer to CHAPTER 19 and CHAPTER 20 ELECTRICAL SPECIFICATIONS.	p. 130 ☐
				When an external waveform is input to 16-bit timer/event counter 00, it is sampled by the noise limiter circuit and thus an error occurs on the timing to become valid inside the device.	p. 130 ☐
Chapter 7	Soft	8-bit timer H1	CMP01: 8-bit timer H compare register 01	CMP01 cannot be rewritten during timer count operation.	p. 133 ☐
			CMP11: 8-bit timer H compare register 11	In the PWM output mode, be sure to set CMP11 when starting the timer count operation (TMHE1 = 1) after the timer count operation was stopped (TMHE1 = 0) (be sure to set again even if setting the same value to CMP11).	p. 133 ☐
			TMHMD1: 8-bit timer H mode register 1	When TMHE1 = 1, setting the other bits of the TMHMD1 register is prohibited.	p. 135 ☐
				In the PWM output mode, be sure to set 8-bit timer H compare register 11 (CMP11) when starting the timer count operation (TMHE1 = 1) after the timer count operation was stopped (TMHE1 = 0) (be sure to set again even if setting the same value to the CMP11 register).	p. 135 ☐
	Hard		PWM output	In PWM output mode, the setting value for the CMP11 register can be changed during timer count operation. However, three operation clocks (signal selected using the CKS12 to CKS10 bits of the TMHMD1 register) or more are required to transfer the register value after rewriting the CMP11 register value.	p. 141 ☐
	Soft			Be sure to set the CMP11 register when starting the timer count operation (TMHE1 = 1) after the timer count operation was stopped (TMHE1 = 0) (be sure to set again even if setting the same value to the CMP11 register).	p. 141 ☐
				Make sure that the CMP11 register setting value (M) and CMP01 register setting value (N) are within the following range. 00H ≤ CMP11 (M) < CMP01 (N) ≤ FFH	p. 141 ☐
Chapter 8	Soft	Watchdog timer	WDTM: Watchdog timer mode register	Set bits 7, 6, and 5 to 0, 1, and 1, respectively. Do not set the other values.	p. 149 ☐
				After reset is released, WDTM can be written only once by an 8-bit memory manipulation instruction. If writing is attempted a second time, an internal reset signal is generated. However, at the first write, if “1” and “x” are set for WDCS4 and WDCS3 respectively and the watchdog timer is stopped, then the internal reset signal does not occur even if the following are executed. • Second write to WDTM • 1-bit memory manipulation instruction to WDTE • Writing of a value other than “ACH” to WDTE	p. 150 ☐

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Chapter	Classification	Function	Details of Function	Cautions	Page
Chapter 8	Soft	Watchdog timer	WDTM: Watchdog timer mode register	WDTM cannot be set by a 1-bit memory manipulation instruction.	p. 150 ☐
				When using the flash memory programming by self programming, set the overflow time for the watchdog timer so that enough overflow time is secured (Example 1-byte writing: 200 μs MIN., 1-block deletion: 10 ms MIN.).	p. 150 ☐
			WDTE: Watchdog timer enable register	If a value other than ACH is written to WDTE, an internal reset signal is generated.	p. 150 ☐
				If a 1-bit memory manipulation instruction is executed for WDTE, an internal reset signal is generated.	p. 150 ☐
				The value read from WDTE is 9AH (this differs from the written value (ACH)).	p. 150 ☐
	Hard		When "low-speed internal oscillator cannot be stopped" is selected by option byte	In this mode, operation of the watchdog timer cannot be stopped even during STOP instruction execution. For 8-bit timer H1 (TMH1), a division of the low-speed internal oscillation clock can be selected as the count source, so clear the watchdog timer using the interrupt request of TMH1 before the watchdog timer overflows after STOP instruction execution. If this processing is not performed, an internal reset signal is generated when the watchdog timer overflows after STOP instruction execution.	p. 151 ☐
			when "low-speed internal oscillator can be stopped by software" is selected by option byte	In this mode, watchdog timer operation is stopped during HALT/STOP instruction execution. After HALT/STOP mode is released, counting is started again using the operation clock of the watchdog timer set before HALT/STOP instruction execution by WDTM. At this time, the counter is not cleared to 0 but holds its value.	p. 153 ☐
Chapter 9	Soft	A/D converter (μPD78F921x only)	Sampling time and A/D conversion time	The above sampling time and conversion time do not include the clock frequency error. Select the sampling time and conversion time such that Notes 2 and 3 above are satisfied, while taking the clock frequency error into consideration (an error margin maximum of ±5% when using the high-speed internal oscillator).	p. 158 ☐
	Hard		Block diagram	In μPD78F921x, V_{SS} functions alternately as the ground potential of the A/D converter. Be sure to connect V_{SS} to a stabilized GND (= 0 V).	p. 159 ☐
				In μPD78F921x, V_{DD} functions alternately as the A/D converter reference voltage input. When using the A/D converter, stabilize V_{DD} at the supply voltage used (2.7 to 5.5 V).	p. 159 ☐
	Soft		ADM: A/D converter mode register	The above sampling time and conversion time do not include the clock frequency error. Select the conversion time taking the clock frequency error into consideration (an error margin maximum of ±5% when using the high-speed internal oscillator).	p. 163 ☐
				If a bit other than ADCS of ADM is manipulated while A/D conversion is stopped (ADCS = 0) and then A/D conversion is started, execute two NOP instructions or an instruction equivalent to two machine cycles, and set ADCS to 1.	p. 163 ☐
				A/D conversion must be stopped (ADCS = 0) before rewriting bits FR0 to FR2.	p. 163 ☐
				Be sure to clear bits 6, 2, and 1 to 0.	p. 163 ☐
			ADS: Analog input channel specification register	Be sure to clear bits 2 to 7 of ADS to 0.	p. 164 ☐
			ADCR: 10-bit A/D conversion result register	When writing to the A/D converter mode register (ADM) and analog input channel specification register (ADS), the contents of ADCR may become undefined. Read the conversion result following conversion completion before writing to ADM and ADS. Using timing other than the above may cause an incorrect conversion result to be read.	p. 164 ☐

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Chapter	Classification	Function	Details of Function	Cautions	Page
Chapter 9	Soft	A/D converter (μPD78F921x only)	PMC2: Port mode control register 2	If PMC20 to PMC23 are set to 1, the P20/ANI0/TI000/TOH1, P21/ANI1/TI010/TO00/INTP0, P22/ANI2, and P23/ANI3 pins cannot be used for any purpose other than the A/D converter function. Be sure to set the pull-up resistor option registers (PU20 to PU23) to 0 for the pins set to A/D converter mode.	p. 165 ☐
			A/D converter operations	Make sure the period of <1> to <4> is 1 μs or more.	pp. 166, 170 ☐
				It is no problem if the order of <1> and <2> is reversed.	pp. 166, 170 ☐
				<1> can be omitted. However, ignore the data resulting from the first conversion after <4> in this case.	p. 170 ☐
				The period from <5> to <8> differs from the conversion time set using bits 5 to 3 (FR2 to FR0) of ADM. The period from <7> to <8> is the conversion time set using FR2 to FR0.	p. 170 ☐
	Hard		Operating current in STOP mode	To satisfy the DC characteristics of the supply current in the STOP mode, clear bit 7 (ADCS) and bit 0 (ADCE) of the A/D converter mode register (ADM) to 0 before executing the STOP instruction.	p. 173 ☐
			Input range of ANI0 to ANI3	Observe the rated range of the ANI0 to ANI3 input voltage. If a voltage of V_{DD} or higher and V_{SS} or lower (even in the range of absolute maximum ratings) is input to an analog input channel, the converted value of that channel becomes undefined. In addition, the converted values of the other channels may also be affected.	p. 173 ☐
	Soft		Conflicting operations	ADCR, ADCRH read has priority. After the read operation, the new conversion result is written to ADCR, ADCRH.	p. 173 ☐
				ADM or ADS write has priority. ADCR, ADCRH write is not performed, nor is the conversion end interrupt signal (INTAD) generated.	p. 173 ☐
	Hard		Noise countermeasures	To maintain the 10-bit resolution, attention must be paid to noise input to the V_{DD} pin and ANI0 to ANI3 pins. <1> Connect a capacitor with a low equivalent resistance and a high frequency response to the power supply. <2> Because the effect increases in proportion to the output impedance of the analog input source, it is recommended that a capacitor be connected externally, as shown in Figure 9-19, to reduce noise. <3> Do not switch the A/D conversion function of the ANI0 to ANI3 pins to their alternate functions during conversion. <4> The conversion accuracy can be improved by setting HALT mode immediately after the conversion starts.	p. 173 ☐
			ANI0/P20 to ANI3/P23	The analog input pins (ANI0 to ANI3) are also used as I/O port pins (P20 to P23). When A/D conversion is performed with any of ANI0 to ANI3 selected, do not access P20 to P23 while conversion is in progress; otherwise the conversion resolution may be degraded.	p. 174 ☐
				If a digital pulse is applied to the pins adjacent to the pins currently used for A/D conversion, the expected value of the A/D conversion may not be obtained due to coupling noise. Therefore, do not apply a pulse to the pins adjacent to the pin undergoing A/D conversion.	p. 174 ☐

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Chapter	Classification	Function	Details of Function	Cautions	Page
Chapter 9	Hard	A/D converter (μPD78F9 21x only)	Input impedance of ANI0 to ANI3 pins	In this A/D converter, the internal sampling capacitor is charged and sampling is performed during sampling time. Since only the leakage current flows other than during sampling and the current for charging the capacitor also flows during sampling, the input impedance fluctuates during sampling and other statuses. If the shortest conversion time of the reference voltage is used, to perform sufficient sampling, it is recommended to make the output impedance of the analog input source 1 kΩ or lower, or attach a capacitor of around 0.01 μF to 0.1 μF to the ANI0 to ANI3 pins (see Figure 9-19). When writing the flash memory on-board, supply a stabilized analog voltage to the ANI2 and ANI3 pins, without attaching a capacitor. Because the communication pulse may change and the communication may fail if a capacitor is attached to remove noise.	p. 174 ☐
	Soft		Interrupt request flag (ADIF)	The interrupt request flag (ADIF) is not cleared even if the analog input channel specification register (ADS) is changed. Therefore, if an analog input pin is changed during A/D conversion, the A/D conversion result and ADIF for the pre-change analog input may be set just before the ADS rewrite. Caution is therefore required since, at this time, when ADIF is read immediately after the ADS rewrite, ADIF is set despite the fact A/D conversion for the post-change analog input has not ended. When A/D conversion is stopped and then resumed, clear ADIF before the A/D conversion operation is resumed.	p. 175 ☐
			Conversion results just after A/D conversion start	The first A/D conversion value immediately after A/D conversion starts may not fall within the rating range if the ADCS bit is set to 1 within 1 μs after the ADCE bit was set to 1, or if the ADCS bit is set to 1 with the ADCE bit = 0. Take measures such as polling the A/D conversion end interrupt request (INTAD) and removing the first conversion result.	p. 175 ☐
			A/D conversion result register (ADCR, ADCRH) read operation	When a write operation is performed to the A/D converter mode register (ADM) and analog input channel specification register (ADS), the contents of ADCR and ADCRH may become undefined. Read the conversion result following conversion completion before writing to ADM and ADS. Using a timing other than the above may cause an incorrect conversion result to be read.	p. 175 ☐
	Hard		Operating current at conversion waiting mode	The DC characteristic of the operating current during the STOP mode is not satisfied due to the conversion waiting mode (only the comparator consumes power), when bit 7 (ADCS) and bit 0 (ADCE) of the A/D converter mode register (ADM) are set to 0 and 1 respectively.	p. 175 ☐
Chapter 10	Soft	Interrupt functions	IF0: Interrupt request flag registers, MK0: Interrupt mask flag registers	Because P21 and P32 have an alternate function as external interrupt inputs, when the output level is changed by specifying the output mode of the port function, an interrupt request flag is set. Therefore, the interrupt mask flag should be set to 1 before using the output mode.	pp. 180, 181 ☐
			INTM0: External interrupt mode register 0	Be sure to clear bits 0, 1, 6, and 7 to 0.	p. 182 ☐
				Before setting the INTM0 register, be sure to set the corresponding interrupt mask flag (××MK× = 1) to disable interrupts. After setting the INTM0 register, clear the interrupt request flag (××IF× = 0), then clear the interrupt mask flag (××MK× = 0), which will enable interrupts.	p. 182 ☐
			Interrupt requests are held pending	Interrupt requests will be held pending while the interrupt request flag registers (IF0) or interrupt mask flag registers (MK0) are being accessed.	p. 184 ☐

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Chapter	Classification	Function	Details of Function	Cautions	Page
Chapter 10	Soft	Interrupt functions	Interrupt request pending	Multiple interrupts can be acknowledged even for low-priority interrupts.	p. 185 ☐
Chapter 11	Soft	Standby function	–	The LSRSTOP setting is valid only when “Can be stopped by software” is set for the low-speed internal oscillator by the option byte.	p. 187 ☐
	Hard		STOP mode	When shifting to the STOP mode, be sure to stop the peripheral hardware operation before executing STOP instruction (except the peripheral hardware that operates on the low-speed internal oscillation clock).	p. 188 ☐
			STOP mode, HALT mode	The following sequence is recommended for operating current reduction of the A/D converter in μPD78F921x when the standby function is used: First clear bit 7 (ADCS) and bit 0 (ADCE) of the A/D converter mode register (ADM) to 0 to stop the A/D conversion operation, and then execute the HALT or STOP instruction.	p. 188 ☐
			STOP mode	If the low-speed internal oscillator is operating before the STOP mode is set, oscillation of the low-speed internal oscillation clock cannot be stopped in the STOP mode (refer to Table 11-1).	p. 188 ☐
	Soft		OSTS: Oscillation stabilization time select register	To set and then release the STOP mode, set the oscillation stabilization time as follows. Expected oscillation stabilization time of resonator ≤ Oscillation stabilization time set by OSTS	p. 189 ☐
	Hard			The wait time after the STOP mode is released does not include the time from the release of the STOP mode to the start of clock oscillation (“a” in the figure below), regardless of whether STOP mode was released by reset signal generation or interrupt generation.	p. 189 ☐
	Soft			The oscillation stabilization time that elapses on power application or after release of reset is selected by the option byte. For details, refer to CHAPTER 15 OPTION BYTE.	p. 189 ☐
			HALT mode setting and operating statuses	Because an interrupt request signal is used to clear the standby mode, if there is an interrupt source with the interrupt request flag set and the interrupt mask flag clear, the standby mode is immediately cleared if set.	p. 190 ☐
			STOP mode setting and operating statuses	Because an interrupt request signal is used to clear the standby mode, if there is an interrupt source with the interrupt request flag set and the interrupt mask flag reset, the standby mode is immediately cleared if set. Thus, in the STOP mode, the normal operation mode is restored after the STOP instruction is executed and then the operation is stopped for 34 μs (TYP.) (after an additional wait time for stabilizing the oscillation set by the oscillation stabilization time select register (OSTS) has elapsed when crystal/ceramic oscillation is used).	p. 193 ☐
Chapter 12	Hard	Reset function	–	For an external reset, input a low level for 2 μs or more to the $\overline{\text{RESET}}$ pin.	p. 197 ☐
				During reset signal generation, the system clock and low-speed internal oscillation clock stop oscillating.	p. 197 ☐
				When the $\overline{\text{RESET}}$ pin is used as an input-only port pin (P34), the 78K0S/KY1+ is reset if a low level is input to the $\overline{\text{RESET}}$ pin after reset is released by the POC circuit, the LVI circuit and the watchdog timer and before the option byte is referenced again. The reset status is retained until a high level is input to the $\overline{\text{RESET}}$ pin.	p. 197 ☐
				The LVI circuit is not reset by the internal reset signal of the LVI circuit.	p. 198 ☐
			Timing of reset by overflow of watchdog timer	The watchdog timer is also reset in the case of an internal reset of the watchdog timer.	p. 200 ☐

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Chapter	Classification	Function	Details of Function	Cautions	Page
Chapter 12	Soft	Reset function	RESF: Reset control flag register	Do not read data by a 1-bit memory manipulation instruction.	p. 204 ☐
Chapter 13	Soft	Power-on-clear circuit	Functions of power-on-clear circuit	If an internal reset signal is generated in the POC circuit, the reset control flag register (RESF) is cleared to 00H.	p. 205 ☐
	Hard			Use these products in the following voltage range because the detection voltage (V_{POC}) of the power-on-clear (POC) circuit is the supply voltage range. Standard product, (A) grade product: 2.2 to 5.5 V, (A2) grade product: 2.26 to 5.5 V	p. 205 ☐
	Soft		Cautions for power-on-clear circuit	In a system where the supply voltage (V_{DD}) fluctuates for a certain period in the vicinity of the POC detection voltage (V_{POC}), the system may be repeatedly reset and released from the reset status. In this case, the time from release of reset to the start of the operation of the microcontroller can be arbitrarily set by taking the following action.	p. 207 ☐
Chapter 14	Soft	Low-voltage detector	LVIM: Low-voltage detect register	To stop LVI, follow either of the procedures below. • When using 8-bit manipulation instruction: Write 00H to LVIM. • When using 1-bit memory manipulation instruction: Clear LVION to 0.	p. 210 ☐
				Be sure to set bits 2 to 6 to 0.	p. 210 ☐
			LVIS: Low-voltage detection level select register	Bits 4 to 7 must be set to 0.	p. 211 ☐
				If a value other than the above is written during LVI operation, the value becomes undefined at the very moment it is written, and thus be sure to stop LVI (bit 7 of LVIM register (LVION) = 0) before writing.	p. 211 ☐
			When used as reset	<1> must always be executed. When LVIMK = 0, an interrupt may occur immediately after the processing in <3>.	p. 212 ☐
				If supply voltage (V_{DD}) ≥ detection voltage (V_{LVI}) when LVIM is set to 1, an internal reset signal is not generated.	p. 212 ☐
			Cautions for low-voltage detector	In a system where the supply voltage (V_{DD}) fluctuates for a certain period in the vicinity of the LVI detection voltage (V_{LVI}), the operation is as follows depending on how the low-voltage detector is used. <1> When used as reset The system may be repeatedly reset and released from the reset status. In this case, the time from release of reset to the start of the operation of the microcontroller can be arbitrarily set by taking action (1) below. <2> When used as interrupt Interrupt requests may be frequently generated. Take (b) of action (2) below.	p. 216 ☐
Chapter 15	Hard	Option byte	Oscillation stabilization time on power application or after reset release	The setting of this option is valid only when the crystal/ceramic oscillation clock is selected as the system clock source. No wait time elapses if the high-speed internal oscillation clock or external clock input is selected as the system clock source.	p. 220 ☐
			Control of $\overline{\text{RESET}}$ pin	Because the option byte is referenced after reset release, if a low level is input to the $\overline{\text{RESET}}$ pin before the option byte is referenced, then the reset state is not released. Also, when setting 0 to RMCE, connect the pull-up resistor.	p. 220 ☐

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Chapter	Classification	Function	Details of Function	Cautions	Page
Chapter 15	Hard	Option byte	Selection of system clock source	Because the X1 and X2 pins are also used as the P23/ANI3 and P22/ANI2 pins, the conditions under which the X1 and X2 pins can be used differ depending on the selected system clock source. (1) Crystal/ceramic oscillation clock is selected The X1 and X2 pins cannot be used as I/O port pins because they are used as clock input pins. (2) External clock input is selected Because the X1 pin is used as an external clock input pin, P23/ANI3 cannot be used as an I/O port pin. (3) High-speed internal oscillation clock is selected P23/ANI3 and P22/ANI2 can be used as I/O port pins.	p. 220 ☐
			Low-speed internal oscillates	If it is selected that low-speed internal oscillator cannot be stopped, the count clock to the watchdog timer (WDT) is fixed to low-speed internal oscillation clock.	p. 221 ☐
				If it is selected that low-speed internal oscillator can be stopped by software, supply of the count clock to WDT is stopped in the HALT/STOP mode, regardless of the setting of bit 0 (LSRSTOP) of the low-speed internal oscillation mode register (LSRCM). Similarly, clock supply is also stopped when a clock other than the low-speed internal oscillation clock is selected as a count clock to WDT. While the low-speed internal oscillator is operating (LSRSTOP = 0), the clock can be supplied to the 8-bit timer H1 even in the STOP mode.	p. 221 ☐
			Caution when the $\overline{\text{RESET}}$ pin is used as an input-only port pin (P34)	Be aware of the following when re-erasing/-writing (by on-board programming using a dedicated flash memory programmer) an already-written device which has been set as “The $\overline{\text{RESET}}$ pin is used as an input-only port pin (P34)” by the option byte function. Before supplying power to the target system, connect a dedicated flash memory programmer and turn its power on. If the power is supplied to the target system beforehand, the flash memory programming mode cannot be switched to.	p. 221 ☐
Chapter 16	Soft	Flash memory	PG-FP5 programming GUI setting value example	The above values are recommended values. Depending on the usage environment these values may change, so set them after having performed sufficient evaluations.	p. 228 ☐
			Security settings	After the security setting of the batch erase is set, erasure cannot be performed for the device. In addition, even if a write command is executed, data different from that which has already been written to the flash memory cannot be written because the erase command is disabled.	p. 231 ☐
			Self programming function	Self programming processing must be included in the program before performing self programming.	p. 232 ☐
				No instructions can be executed while a self programming command is being executed. Therefore, clear and restart the watchdog timer counter in advance so that the watchdog timer does not overflow during self programming. Refer to Table 16-10 for the time taken for the execution of self programming.	p. 235 ☐
				Interrupts that occur during self programming can be acknowledged after self programming mode ends. To avoid this operation, disable interrupt servicing (by setting MK0 to FFH, and executing the DI instruction) when shifting from the normal mode to the self programming mode with a specific sequence.	p. 235 ☐
				RAM is not used while a self programming command is being executed.	p. 235 ☐
				If the supply voltage drops or the reset signal is input while the flash memory is being written or erased, writing/erasing is not guaranteed.	p. 235 ☐

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Chapter	Classification	Function	Details of Function	Cautions	Page
Chapter 16	Soft	Flash memory	Self programming function	The value of the blank data set during block erasure is FFH.	p. 235 ☐
				Set the CPU clock beforehand so that it is 1 MHz or higher during self programming.	p. 235 ☐
				Execute self programming after executing the NOP and HALT instructions immediately after executing a specific sequence to set self programming mode. At this time, the HALT instruction is automatically released after 10 μs (MAX.) + 2 CPU clocks (f_{CPU}).	p. 235 ☐
				If the clock of the oscillator or an external clock is selected as the system clock, execute the NOP and HALT instructions immediately after executing a specific sequence to set self programming mode, wait for 8 μs after releasing the HALT status, and then execute self programming.	p. 235 ☐
				Check FPRERR using a 1-bit memory manipulation instruction.	p. 235 ☐
				The state of the pins in self programming mode is the same as that in HALT mode.	p. 235 ☐
				Since the security function set via on-board/off-board programming is disabled in self programming mode, the self programming command can be executed regardless of the security function setting. To disable write or erase processing during self programming, set the protect byte.	p. 235 ☐
				Be sure to clear bits 5 to 7 of flash address pointer H (FLAPH) and flash address pointer H compare register (FLAPHC) to 0 before executing the self programming command. If self programming is executed with these bits set to 1, the device may malfunction.	p. 235 ☐
				Clear the value of the FLCMD register to 00H immediately before setting to self programming mode and normal mode.	p. 235 ☐
			FLPMC: Flash programming mode control register	Cautions in the case of setting the self programming mode, refer to 16.8.2 Cautions on self programming function.	p. 236 ☐
				Set the CPU clock beforehand so that it is 1 MHz or higher during self programming.	p. 236 ☐
				Execute self programming after executing the NOP and HALT instructions immediately after executing a specific sequence to set self programming mode. At this time, the HALT instruction is automatically released after 10 μs (MAX.) + 2 CPU clocks (f_{CPU}).	p. 236 ☐
				If the clock of the oscillator or an external clock is selected as the system clock, execute the NOP and HALT instructions immediately after executing a specific sequence to set self programming mode, wait for 8 μs after releasing the HALT status, and then execute self programming.	p. 236 ☐
				Clear the value of the FLCMD register to 00H immediately before setting to self programming mode and normal mode.	p. 236 ☐
			PFCMD: Flash protect command register	Interrupt servicing cannot be executed in self programming mode. Disable interrupt servicing (by executing the DI instruction while MK0 = FFH) between the points before executing the specific sequence that sets self programming mode and after executing the specific sequence that changes the mode to the normal mode.	p. 237 ☐
			PFS: Flash status register	Check FPRERR using a 1-bit memory manipulation instruction.	p. 237 ☐
			FLAPH, FLAPL: Flash address pointers H and L	Be sure to clear bits 4 to 7 of FLAPH and FLAPHC to 0 before executing the self programming command. If the value of these bits is 1 when executing the self programming command.	p. 240 ☐

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Chapter	Classification	Function	Details of Function	Cautions	Page
Chapter 16	Soft	Flash memory	FLAPHC, FLAPLC: Flash address pointer H/L compare registers	Be sure to clear bits 4 to 7 of FLAPH and FLAPHC to 0 before executing the self programming command. If the value of these bits is 1 when executing the self programming command.	p. 240 ☐
				Set the number of the block subject to a block erase, verify, or blank check (same value as FLAPH) to FLAPHC.	p. 240 ☐
				Clear FLAPLC to 00H when a block erase is performed, and FFH when a blank check is performed.	p. 240 ☐
			Shifting to self programming mode	Be sure to perform the series of operations described above using the user program at an address where data is not erased or written.	pp. 242, 243, 245, 246 ☐
			Shifting to normal mode		
			Byte write	If a write results in failure, erase the block once and write to it again.	p. 254 ☐
Chapter 17	Hard	On-chip debug function	Connecting QB-MINI2 to 78K0S/KY1	The 78K0S/KY1+ has an on-chip debug function, which is provided for development and evaluation. Do not use the on-chip debug function in products designated for mass production, because the guaranteed number of rewritable times of the flash memory may be exceeded when this function is used, and product reliability therefore cannot be guaranteed. NEC Electronics is not liable for problems occurring when the on-chip debug function is used.	p. 279 ☐
				The constants described in the circuit connection example are reference values. If you perform flash programming aiming at mass production, thoroughly evaluate whether the specifications of the target device are satisfied.	p. 279 ☐
			Circuit Connection for the Case Where QB-MINI2 Is Used for Debugging and Debugging of INTP1 Pin Is Performed Only with Real Machine	If debugging is performed with a real machine running, without using QB-MINI2, write the user program using the QB-Programmer. Programs downloaded by the debugger include the monitor program, and such a program malfunctions if it is not controlled via QB-MINI2.	p. 281 ☐
Chapter 19	Hard	Electrical specifications (Standard product, (A) grade product)	Absolute maximum ratings	Product quality may suffer if the absolute maximum rating is exceeded even momentarily for any parameter. That is, the absolute maximum ratings are rated values at which the product is on the verge of suffering physical damage, and therefore the product must be used under conditions that ensure that the absolute maximum ratings are not exceeded.	p. 293 ☐
			X1 oscillator characteristics	When using the X1 oscillator, wire as follows in the area enclosed by the broken lines in the above figures to avoid an adverse effect from wiring capacitance. • Keep the wiring length as short as possible. • Do not cross the wiring with the other signal lines. • Do not route the wiring near a signal line through which a high fluctuating current flows. • Always make the ground point of the oscillator capacitor the same potential as V_{SS}. • Do not ground the capacitor to a ground pattern through which a high current flows. • Do not fetch signals from the oscillator.	p. 294 ☐

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Chapter	Classification	Function	Details of Function	Cautions	Page
Chapter 19	Hard	Electrical specifications (Standard product, (A) grade product)	A/D converter (μPD78F921x only)	The conversion accuracy may be degraded when the analog input pin is used as an alternate I/O port or if the level of a port that is not used for A/D conversion is changed during A/D conversion.	p. 301 ☐
Chapter 20	Hard	Electrical specifications ((A2) grade product)	Absolute maximum ratings	Product quality may suffer if the absolute maximum rating is exceeded even momentarily for any parameter. That is, the absolute maximum ratings are rated values at which the product is on the verge of suffering physical damage, and therefore the product must be used under conditions that ensure that the absolute maximum ratings are not exceeded.	p. 305 ☐
			X1 oscillator characteristics	When using the X1 oscillator, wire as follows in the area enclosed by the broken lines in the above figures to avoid an adverse effect from wiring capacitance. • Keep the wiring length as short as possible. • Do not cross the wiring with the other signal lines. • Do not route the wiring near a signal line through which a high fluctuating current flows. • Always make the ground point of the oscillator capacitor the same potential as V_{SS}. • Do not ground the capacitor to a ground pattern through which a high current flows. • Do not fetch signals from the oscillator.	p. 307 ☐
			A/D converter (μPD78F921x only)	The conversion accuracy may be degraded when the analog input pin is used as an alternate I/O port or if the level of a port that is not used for A/D conversion is changed during A/D conversion.	p. 314 ☐
Chapter 22	Hard	Recommended soldering conditions	–	For soldering methods and conditions other than those recommended below, contact an NEC Electronics sales representative.	p. 323 ☐
				Do not use different soldering methods together (except for partial heating).	pp. 323, 324 ☐
				Only the pins of the THD are heated when performing wave soldering. Make sure that flow solder does not come in contact with the package.	p. 324 ☐

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APPENDIX E REVISION HISTORY

E.1 Major Revisions in This Edition

Page	Description
Throughout	Addition of the SSOP package products (MA-FAA type)
	Addition of μPD78F951x products (without A/D converter)
p. 6	Modification of **Related Documents**
p. 16	Modification of **1.2 Ordering Information**
p. 20	Modification of **1.4 78K0S/Kx1+ Product Lineup**
pp. 44 to 46	Modification of **Table 3-3 Special Function Registers**
p. 224	**16.4 Writing with Flash Memory Programmer** • Deletion of FlashPro4 and addition of QB-MINI2 • Modification of **Remark**
p. 225	Modification of and addition of **Remark** to **Figure 16-2 Environment for Writing Program to Flash Memory (FlashPro5/QB-MINI2)**
p. 226	Modification of **Table 16-2 Wiring Between 78K0S/KY1+ and FlashPro5/QB-MINI2**
p. 226	Modification of and addition of **Remark** to **Figure 16-3 Wiring diagram with FlashPro5/QB-MINI2 (16-pin Plastic SSOP Products)**
p. 230	Modification of **Figure 16-7 Communication Commands**
pp. 248 to 250	**16.8.6 Example of block erase operation in self programming mode** • Modification of description and addition of **Note 2** • Modification of **Figure 16-20 Example of Block Erase Operation in Self Programming Mode** • Modification of an example of a program
pp. 269 to 271	**16.8.11 Examples of operation when interrupt-disabled time should be minimized in self programming mode** • Modification of **Figure 16-27 Example of Operation When Interrupt-Disabled Time Should Be Minimized (from Erasure to Blank Check)** • Modification of an example of a program
p. 279	Modification of **Caution** in **17.1 Connecting QB-MINI2 to 78K0S/KY1+**
p. 325	Modification of **APPENDIX A DEVELOPMENT TOOLS**

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E.2 Revision History up to Previous Editions

The following table shows the revision history up to this edition. The “Applied to:” column indicates the chapters of each edition in which the revision was applied.

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Edition	Description	Applied to:
2nd edition	Addition of settings for port mode register 4 (PM4) when using 78K0S/KU1+	Throughout
	Deletion of high-speed internal oscillation mode register (HSRCM)	
	Addition of Part Number to **1.3 Ordering Information**	**CHAPTER 1 OVERVIEW**
	Modification of **Type 36** in **Figure 2-1 Pin I/O Circuits**	**CHAPTER 2 PIN FUNCTIONS**
	Addition of **Note 4** to **Table 3-3 Special Function Registers (1/2)**	**CHAPTER 3 CPU ARCHITECTURE**
	Addition of **Remarks 1, 2** in **Table 4-1 Port Functions**	**CHAPTER 4 PORT FUNCTIONS**
	Addition of **Figure 4-3 Block Diagram of P22**	
	Modification of operation stop time in the following figures. • **Figure 5-8 Timing Chart of Default Start by High-Speed internal Oscillator** • **Figure 5-10 Timing Chart of Default Start by Crystal/Ceramic Oscillator** • **Figure 5-12 Timing of Default Start by External Clock Input**	**CHAPTER 5 CLOCK GENERATORS**
	Addition of **Cautions** to **6.2 Configuration of 16-bit Timer/Event Counter 00 (1) 16-bit timer counter 00 (TM00), (2) 16-bit timer capture/compare register 000 (CR000),** and **(3) 16-bit timer capture/compare register 010 (CR010)**	**CHAPTER 6 16-BIT TIMER/EVENT COUNTER 00**
	Addition of **Cautions** in **Figure 6-5 Format of 16-bit Timer Mode Control Register 00 (TMC00)**	
	Addition of **Caution 6** to **Figure 6-7 Format of 16-bit Timer Output Control Register 00 (TOC00)**	
	Modification of **Caution 3** and addition of **Caution 4** in **Figure 6-8 Format of Prescaler Mode Register 00 (PRM00)**	
	Addition of **(1) INTTM000 generation timing immediately after operation starts** : The setting value +2 of CR000 to 1 **Figure 6-17 External Event Counter Operation Timing (with Rising Edge Specified)**	
	Modification of **Note** in **Figure 6-24 Control Register Settings for Pulse Width Measurement with Free-Running Counter and Two Capture Registers (with Rising Edge Specified)**	
	Modification and addition to **6.5 Cautions Related to 16-bit Timer/Event Counter 00**	

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Edition	Description	Applied to:
2nd edition	Modification of **Table 8-1 Loop Detection Time of Watchdog Timer**	**CHAPTER 8 WATCHDOG TIMER**
	Addition of **Caution 4** and modification to **Figure 8-2 Format of Watchdog Timer Mode Register (WDTM)**	
	Modification of **Figure 8-4 Status Transition Diagram When "Low-Speed Internal Oscillator Cannot Be Stopped" Is Selected by Option Byte**	
	Modification of **Figure 8-5 Status Transition Diagram When "Low-Speed Internal Oscillator Can Be Stopped by Software" Is Selected by Option Byte**	
	Modification of operation stop time in the following figures • **Figure 8-6 Operation in STOP Mode (WDT Operation Clock: Clock to Peripheral Hardware)** • **Figure 8-7 Operation in STOP Mode (WDT Operation Clock: Low-Speed Internal Oscillation Clock)**	
	Addition of **Note** to and modification of **Figure 9-1 Timing of A/D Converter Sampling and A/D Conversion**	**CHAPTER 9 A/D CONVERTER**
	Addition of **Note 1** and **Remark 2** to and modification of **Table 9-1 Sampling Time and A/D Conversion Time**	
	Modification of **Figure 9-2 Block Diagram of A/D Converter**	
	Modification of **Note 5**, addition of **Notes 1, 2**, and **Remark 2** to, and modification of **Figure 9-3 Format of A/D Converter Mode Register (ADM)**	
	Modification of **Figure 9-11 Relationship Between Analog Input Voltage and A/D Conversion Result**	
	Modification of **9.6 (1) Operating current in STOP mode, (4) Noise countermeasures,** and **(6) Input impedance of ANI0 to ANI3 pins**	
	Modification of capacitor value in **Figure 9-19 Analog Input Pin Connection**	
	Modification of **Figure 9-21 Internal Equivalent Circuit of ANIn Pin** and **Table 9-4 Resistance and Capacitance Values (Reference Values) of Equivalent Circuit**	
	Modification of description on operation stop time in **11.1.1 (2) STOP mode**	**CHAPTER 11 STANDBY FUNCTION**
	Modification of **Note** in **Figure 11-3 HALT Mode Release by Reset Input**	
	Modification of operation stop time in the following figures. • **Figure 11-4 Operation Timing When STOP Mode Is Released** • **Figure 11-5 STOP Mode Release by Interrupt Request Generation**	
	Modification of **Note** in **Figure 11-6 STOP Mode Release by Reset Input**	
	Modification of the following figures • **Figure 12-1 Block Diagram of Reset Function** • **Figure 12-2 Timing of Reset by $\overline{\text{RESET}}$ Input** • **Figure 12-3 Timing of Reset by Overflow of Watchdog Timer** • **Figure 12-4 Reset Timing by $\overline{\text{RESET}}$ Input in STOP Mode**	**CHAPTER 12 RESET FUNCTION**
	Addition of **Note 1** to **Figure 14-2 Format of Low-Voltage Detect Register (LVIM)**	**CHAPTER 14 LOW-VOLTAGE DETECTOR**
	Addition of **Note** to **Figure 14-3 Format of Low-Voltage Detection Level Select Register (LVIS)**	
	Addition of **Note** to **14.5 Cautions for Low-Voltage Detector <Action> (2) When used as interrupt**	
	Revision of **CHAPTER 16 FLASH MEMORY**	**CHAPTER 16 FLASH MEMORY**

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Edition	Description	Applied to:
2nd edition	Modification or addition of values in the following characteristics in **CHAPTER 18 ELECTRICAL SPECIFICATIONS (TARGET VALUES)** • Absolute maximum ratings Output current high, output current low, and operating ambient temperature • X1 oscillator characteristics • DC characteristics • AC characteristics (1) Basic operation Cycle time (minimum instruction execution time) • A/D converter characteristics • Flash memory programming characteristics	**CHAPTER 18 ELECTRICAL SPECIFICATIONS (TARGET VALUES)**
	Modification of **19.1 Package drawing of the 78K0S/KU1+** and **19.2 Package drawing of the 78K0S/KY1+**	**CHAPTER 19 PACKAGE DRAWING**
	Modification of **Figure A-1 Development Tools**	**APPENDIX A DEVELOPMENT TOOLS**
	Modification of device file names and **Remark** in **A.2 Language Processing Software**	
	Addition of project manager name to **A.3 Control Software**	
	Addition of PG-FPL2 to **A.4 Flash Memory Writing Tools**	
	Modification of emulation board name used when the IE-78K0S-NS or IE-78K0S-NS-A is used, and addition of **Specification of pin header on target system** to **A.5.1 When using in-circuit emulator IE-78K0S-NS or IE-78K0S-NS-A**	
	Addition of **A.5.2 When using in-circuit emulator QB-78K0SKX1MINI**	
	Modification of system simulator name, device file name, and **Remark** in and addition of ID78K0S-QB to **A.6 Debugging Tools (Software)**	
3rd edition	Description of 78K0S/KU1+ is deleted	Throughout
	Modification of operating temperature range	
	Addition of part number to **1.3 Ordering Information**	**CHAPTER 1 OVERVIEW**
	Addition of **Note** to **P22/X2/ANI2, P23/X1/ANI3, and P34/$\overline{\text{RESET}}$** in **2.1 Pin Function List**	**CHAPTER 2 PIN FUNCTIONS**
	Addition of description to **2.2.1 P20 to P23 (Port 2)**	
	Addition of description to **2.2.2 P32, P34 (Port 3)**	
	Addition of description to **2.2.4 $\overline{\text{RESET}}$**	
	Addition of description to **2.2.5 X1 and X2**	
	Modification of description example in **3.4.1 Direct addressing**	**CHAPTER 3 CPU ARCHITECTURE**
	Modification of description and description example in **3.4.2 Short direct addressing**	
	Addition of Illustration to **3.4.6 Based addressing**	
	Addition of Illustration to **3.4.7 Stack addressing**	
	Addition of **Note** to **P22/X2/ANI2, P23/X1/ANI3, and P34/$\overline{\text{RESET}}$** in **Table 4-1 Port Functions**	**CHAPTER 4 PORT FUNCTIONS**
	Addition of description to and modification of **Cautions** in **4.2.2 Port 3**	
	Addition of description to **(2) In input mode** in **4.4.1 Writing to I/O port** and **4.4.3 Operations on I/O port**	
	Modification of description in **(2) External event counter** in **6.1 Functions of 16-bit Timer/Event Counter 00**	**CHAPTER 6 16-BIT TIMER/EVENT COUNTER 00**
	Modification of **Caution 2** in **Figure 6-2 Format of 16-bit Timer Counter 00 (TM00)**	

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Edition	Description	Applied to:
3rd edition	Modification of **Caution 2** in **Figure 6-5 Format of 16-bit Timer Mode Control Register 00 (TMC00)**	**CHAPTER 6 16-BIT TIMER/EVENT COUNTER 00**
	Modification of description in **6.4.3 Pulse width measurement operations**	
	Addition of **Caution** to **(1), (2), (3), and (4)** in **6.4.3 Pulse width measurement operations**	
	Modification of **Figure 6-20 Configuration Diagram for Pulse Width Measurement by Free-Running Counter**	
	Modification of **Figure 6-21 Timing of Pulse Width Measurement Operation by Free-Running Counter and One Capture Register (with Both Edges Specified)** and **Note**	
	Modification of **Figure 6-23 Timing of Pulse Width Measurement Operation with Free-Running Counter (with Both Edges Specified)** and **Note**	
	Modification of **Note** in **Figure 6-25 Control Register Settings for Pulse Width Measurement with Free-Running Counter and Two Capture Registers (with Rising Edge Specified)**	
	Modification of **Figure 6-27 Timing of Pulse Width Measurement Operation by Means of Restart (with Rising Edge Specified)**	
	Modification of <3> and <4> in **(2) 16-bit timer counter 00 (TM00) operation** of **6.5 Cautions Related to 16-bit Timer/Event Counter 00**	
	Addition of <1> to **(19) External event counter** of **6.5 Cautions Related to 16-bit Timer/Event Counter 00**	
	Modification of description in **(2) 8-bit timer H compare register 11 (CMP11)** of **7.2 Configuration of 8-bit Timer H1**	**CHAPTER 7 8-BIT TIMER H1**
	Modification of **Caution 1** in **7.4.2 Operation as PWM output mode**	
	Modification of **(e) Operation by changing CMP11 (CMP11 = 02H → 03H, CMP01 = A5H)** in **Figure 7-10 Operation Timing in PWM Output Mode**	
	Addition of description to **Caution 2** in **Figure 8-2 Format of Watchdog Timer Mode Register (WDTM)**	**CHAPTER 8 WATCHDOG TIMER**
	Modification of **Figure 9-1 Timing of A/D Converter Sampling and A/D Conversion**	**CHAPTER 9 A/D CONVERTER**
	Modification of **Table 9-1 Sampling Time and A/D Conversion Time** and **Note 1**	
	Modification of **Figure 9-3 Format of A/D Converter Mode Register (ADM)** and **Note 2**	
	Modification of **(6) Input impedance of ANI0 to ANI3 pins** in **9.6 Cautions for A/D Converter**	
	Modification of **10.1 Interrupt Function Types**	**CHAPTER 10 INTERRUPT FUNCTIONS**
	Modification of **10.4.2 Multiple interrupt servicing**	
	Addition of **Caution** to **Example 1** in **Figure 10-9 Example of Multiple Interrupts (1/2)**	
	Addition of **Example 3** to **Figure 10-9 Example of Multiple Interrupts (1/2)**	
	Modification of reset signal in **Figure 11-3 HALT Mode Release by Reset Signal Generation**	**CHAPTER 11 STANDBY FUNCTION**
	Modification of description in **External interrupt** of **Table 11-4 Operating Statuses in STOP Mode**	
	Modification of description in and addition of **Note** to **(a) Release by unmasked interrupt request** in **(2)** of **11.2.2 STOP mode**	
	Modification of reset signal in **Figure 11-6 STOP Mode Release by Reset Signal Generation**	

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Edition	Description	Applied to:
3rd edition	Modification of **Figure 12-1 Block Diagram of Reset Function**	**CHAPTER 12 RESET FUNCTION**
	Addition of delay time of internal reset signal generation to **Figure 12-2 Timing of Reset by $\overline{\text{RESET}}$ Input** and **Figure 12-4 Reset Timing by $\overline{\text{RESET}}$ Input in STOP Mode**	
	Modification of **Figure 13-3 Example of Software Processing After Release of Reset**	**CHAPTER 13 POWER-ON-CLEAR CIRCUIT**
	Modification of **Figure 14-1 Block Diagram of Low-Voltage Detector**	**CHAPTER 14 LOW-VOLTAGE DETECTOR**
	Modification of **Note 1** in **Figure 14-2 Format of Low-Voltage Detect Register (LVIM)**	
	Modification of **Note** in **Figure 14-3 Format of Low-Voltage Detection Level Select Register (LVIS)**	
	Modification of INTLVI and **Note 2** in **Figure 14-5 Timing of Low-Voltage Detector Interrupt Signal Generation**	
	Modification of **(2)** in **<Action>** of **14.5 Cautions for Low-Voltage Detector**	
	Modification of **Figure 14-6 Example of Software Processing After Release of Reset (1/2)**	
	Modification of description and configuration in **CHAPTER 15 OPTION BYTE**	**CHAPTER 15 OPTION BYTE**
	Modification of **Caution** in **Figure 15-2 Format of Option Byte (1/2)**	
	Addition of **Remarks 3, 4** to **Figure 15-2 Format of Option Byte (2/2)**	
	Modification of and addition to **16.1 Features**	**CHAPTER 16 FLASH MEMORY**
	Figure 16-2 Environment for Writing Program to Flash Memory is divided into two figures, in the case of FlashPro4 and in the case of PG-FPL2	
	Modification of **Caution** in **Table 16-5 Oscillation Frequency and PG-FP4 GUI Software Setting Value Example**	
	Deletion of **16.7.1 Flash memory programming mode**	
	Modification of **16.7.2 Communication commands**	
	Modification of and Addition to **16.8.2 Cautions on self programming function**	
	Addition of **<Setting conditions>** in **3. Operating conditions of WEPRERR flag** of **16.8.3 Registers used for self programming function (3)**	
	Addition of description to **Figure 16-15 Format of Flash Programming Command Register (FLCMD)**	
	Modification of **Caution** in **Figure 16-16 Format of Flash Address Pointer H/L (FLAPH/FLAPL)**	
	Modification of **Caution 2** in **Figure 16-17 Format of Flash Address Pointer H/L Compare Registers (FLAPHC/FLAPLC)**	
	Complete revision of **CHAPTER 18 ELECTRICAL SPECIFICATIONS (TARGET VALUES)**, and addition of chapters	**CHAPTER 18 ELECTRICAL SPECIFICATIONS ((T) product, (S) product, (R) product, (A) product) to CHAPTER 20 ELECTRICAL SPECIFICATIONS (TARGET VALUES) ((A2) product)**

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Edition	Description	Applied to:
3rd edition	Addition of **CHAPTER 22 PACKAGE MARKING INFORMATION**	**CHAPTER 22 PACKAGE MARKING INFORMATION**
	Addition of **CHAPTER 23 RECOMMENDED SOLDERING CONDITIONS**	**CHAPTER 23 RECOMMENDED SOLDERING CONDITIONS**
	Addition of **APPENDIX C LIST OF CAUTIONS**	**APPENDIX C LIST OF CAUTIONS**
4th edition	Description of (T) product, (S) product, (R) product and (T2) product deleted	Throughout
	Modification of **1.4 78K0S/Kx1+ Product Lineup**	**CHAPTER 1 OVERVIEW**
	Addition of **Caution 2** to **3.2.1 (3) Stack pointer (SP)**	**CHAPTER 3 CPU ARCHITECTURE**
	Addition of **Caution** to **Figure 4-10 Format of Port Mode Control Register 2**	**CHAPTER 4 PORT FUNCTIONS**
	Addition of **6.5 (23) External clock limitation**	**CHAPTER 6 16-BIT TIMER/EVENT COUNTER 00**
	Modification of description in **9.2 (1) ANI0 to ANI3 pins**	**CHAPTER 9 A/D CONVERTER**
	Addition of **Caution** to **Figure 9-9 Format of Port Mode Control Register 2 (PMC2)**	
	Addition of **9.6 (10) Operating current at conversion waiting mode**	
	Addition of **Caution 2** to **14.3 (2) Low-voltage detection level select register (LVIS)**	**CHAPTER 14 LOW-VOLTAGE DETECTOR**
	Addition of **15.3 Caution When the RESET Pin Is Used as an Input-Only Port Pin (P34)**	**CHAPTER 15 OPTION BYTE**
	Addition of description to **16.6.1 X1 and X2 pins**	**CHAPTER 16 FLASH MEMORY**
	Addition of **Remark 1** to **16.8 Flash Memory Programming by Self Writing**	
	Modification of description of internal verify 1, and addition of description and **Remark** of internal verify 2 in **Table 16-11 Self Programming Controlling Commands**	
	Partial modification of and addition to **16.8.2 Cautions on self programming function**	
	Addition of **Cautions 2, 3** and **5** to, and modification of **Caution 4** in **Figure 16-12 Format of Flash Programming Mode Control Register (FLPMC)**	
	Modification of **Caution** in, and addition of description of FPRERR to **16.8.3 (2) Flash protect command register (PFCMD)**	
	Addition of **Caution** to **16.8.3 (3) Flash status register (PFS)**	
	Modification of description and **Note** of internal verify 1, and addition of description of internal verify 2 in **Figure 16-15 Format of Flash Programming Command Register (FLCMD)**	
	Addition of description to **16.8.4 Example of shifting normal mode to self programming mode** and **16.8.5 Example of shifting self programming mode to normal mode**	
	Addition of description of internal verify 1 and internal verify 2 to **16.8.9 Example of internal verify operation in self programming mode**	

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Edition	Description	Applied to:
4th edition	Following modifications to **CHAPTER 18 ELECTRICAL SPECIFICATIONS (Standard product, (A) grade product)** • Maximum values of input leakage current, high, input leakage current, low, output leakage current, high and output leakage current, low • Maximum value of supply current in STOP mode (I_{DD5}) • Addition of **CPU Clock Frequency, Peripheral Clock Frequency** • **Caution** in **A/D Converter Characteristics**	**CHAPTER 18 ELECTRICAL SPECIFICATIONS (Standard product, (A) grade product)**
	Addition of **CPU Clock Frequency, Peripheral Clock Frequency** and **Caution** to **A/D Converter Characteristics** and modification of **Note 3** in **Flash Memory Programming Characteristics**, in **CHAPTER 19 ELECTRICAL SPECIFICATIONS ((A2) grade product)**	**CHAPTER 19 ELECTRICAL SPECIFICATIONS (TARGET VALUES) ((A2) grade product)**
	Deletion of **CHAPTER 22 PACKAGE MARKING INFORMATION**	**CHAPTER 22 PACKAGE MARKING INFORMATION**
	Modification of **A.4 Flash Memory Writing Tools**	**APPENDIX A DEVELOPMENT TOOLS**
	Addition of **A.5.1 When using in-circuit emulator QB-78K0SKX1 (under development)** and **A.5.2 When using in-circuit emulator QB-MINI2**	
5th edition	Addition of SDIP (μPD78F9210CS-CAB-A, μPD78F9211CS-CAB-A, μPD78F9212CS-CAB-A) and WLBGA (μPD78F9210FH-2A2-A, μPD78F9211FH-2A2-A, μPD78F9212FH-2A2-A) packages	Throughout
	Modification of **1.1 Features**	**CHAPTER 1 OVERVIEW**
	Addition of **Note 2** to **5** in **1.4 78K0S/Kx1+ Product Lineup**	
	9.1 Functions of A/D Converter • Addition of **Note 4** to **Table 9-1 Sampling Time and A/D Conversion Time**	**CHAPTER 9 A/D CONVERTER**
	9.3 Registers Used by A/D Converter • Addition of **Note 5** to **Figure 9-3 Format of A/D Converter Mode Register (ADM)**	
	9.6 Cautions for A/D Converter • Addition of description to **Note 2** to **(6) Input impedance of ANI0 to ANI3 pins**	
	Modification of **Caution 3**	**CHAPTER 12 RESET FUNCTION**
	16.4 Writing with Flash Memory Programmer • Addition of **FlashPro5** to Dedicated flash memory programmer • Deletion of **PG-FPL2** from Dedicated flash memory programmer • Modification of **Remark**	**CHAPTER 16 FLASH MEMORY**
	16.5 Programming Environment • Modification of **Figure 16-2 Environment for Writing Program to Flash Memory (FlashPro4/FlashPro5/ QB-MINI2)** and Addition of **Note** • Modification of **Table 16-2 Wiring Between 78K0S/KY1+ and FlashPro4/FlashPro5/QB-MINI2** and Addition of **Note 2** • Modification of **Figure 16-3 Wiring diagram with FlashPro4/FlashPro5/QB-MINI2** • Deletion of **PG-FPL2** from Dedicated flash memory programmer	

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Edition	Description	Applied to:
5th edition	Modification of **Figure 16-7 Communication Commands**	**CHAPTER 16 FLASH MEMORY**
	Addition of **Note** in **Table 16-10 Self Programming Controlling Commands**	
	Addition of this chapter	**CHAPTER 17 ON-CHIP DEBUG FUNCTION**
	Modification of **AC Characteristics CPU Clock Frequency, Peripheral Clock Frequency**	**CHAPTER 20 ELECTRICAL SPECIFICATIONS (TARGET VALUES) ((A2) grade product)**
	Addition of SDIP and WLBGA packages	**CHAPTER 21 PACKAGE DRAWING**
	Addition of SDIP and WLBGA packages	**CHAPTER 22 RECOMMENDED SOLDERING CONDITIONS**
	Modification of **Figure A-1. Development Tools**	**APPENDIX A DEVELOPMENT TOOLS**
	A.4 Flash Memory Writing Tools • Addition of **FlashPro5** • Deletion of **PG-FPL2**	
	A.5.1 When using in-circuit emulator QB-78K0SKX1 • Deletion of description **under development**	
	Deletion of old edition to **A.5.3 When using in-circuit emulator IE-78K0S-NS or IE-78K0S-NS-A** and **A.5.4 When using in-circuit emulator QB-78K0SKX1MINI**	
	Modification of **A.6 Debugging Tools (Software)**	
	Modification of this chapter	**APPENDIX B Notes on Designing Target System**

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